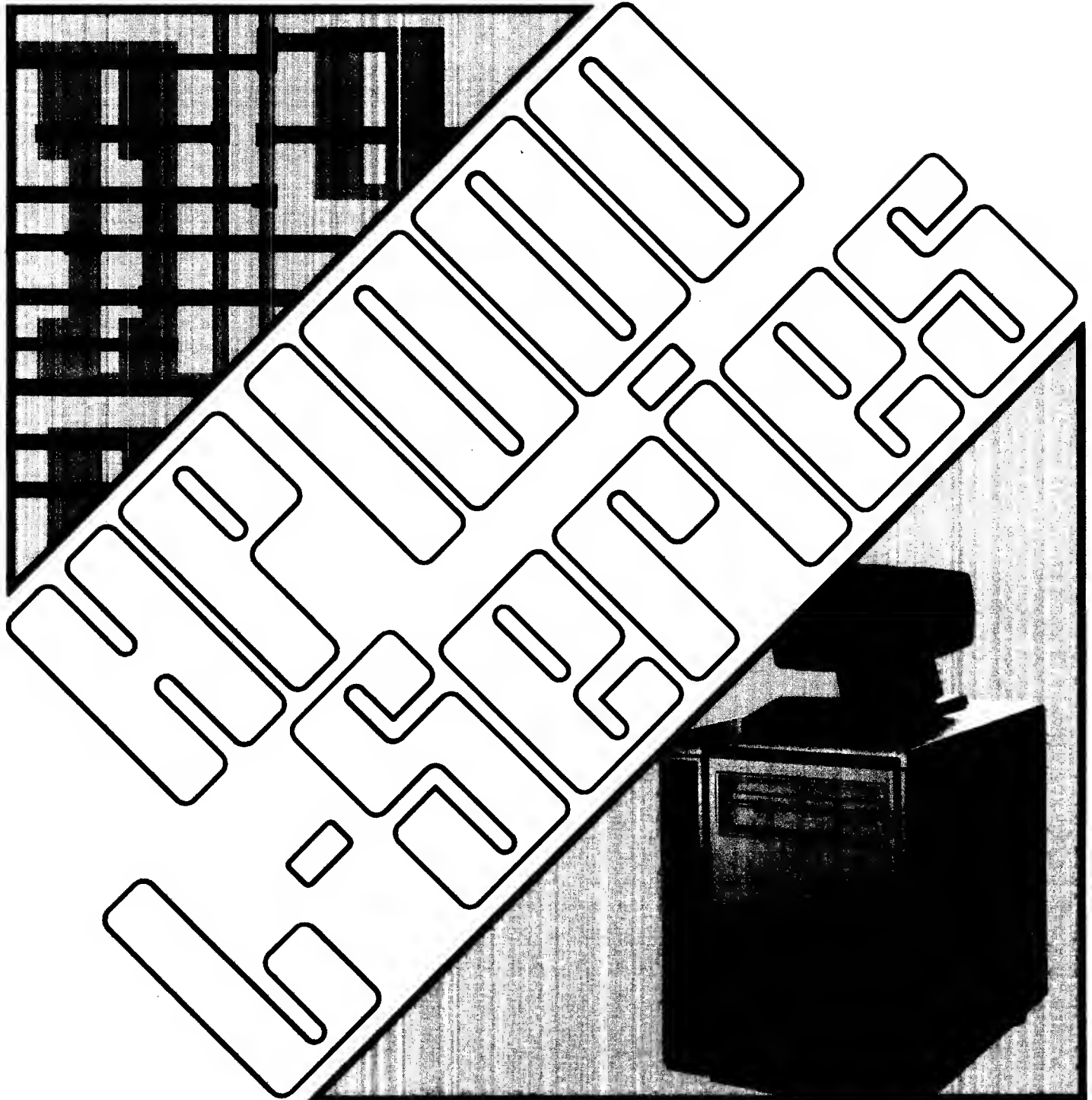


HP 1000 L-Series Computer

Engineering and Reference Documentation



HP 1000 L-SERIES COMPUTER ENGINEERING AND REFERENCE DOCUMENTATION



**HEWLETT
PACKARD**

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SAFETY CONSIDERATIONS

GENERAL - This product and relation documentation must be reviewed for familiarization with safety markings and instructions before operation.

SAFETY SYMBOLS



Instruction manual symbol: the product will be marked with this symbol when it is necessary for the user to refer to the instruction manual in order to protect the product against damage.



Indicates hazardous voltages.



Indicates earth (ground) terminal (sometimes used in manual to indicate circuit common connected to grounded chassis).

WARNING

The **WARNING** sign denotes a hazard. It calls attention to a procedure, practice, or the like, which, if not correctly performed or adhered to, could result in injury. Do not proceed beyond a **WARNING** sign until the indicated conditions are fully understood and met.

CAUTION

The **CAUTION** sign denotes a hazard. It calls attention to an operating procedure, practice, or the like, which, if not correctly performed or adhered to, could result in damage to or destruction of part or all of the product. Do not proceed beyond a **CAUTION** sign until the indicated conditions are fully understood and met.

CAUTION

STATIC SENSITIVE DEVICES

Some of the semiconductor devices used in this equipment are susceptible to damage by static discharge. Depending on the magnitude of the charge, device substrates can be punctured or destroyed by contact or mere proximity to a static charge. These charges are generated in numerous ways such as simple contact, separation of materials, and normal motions of persons working with static sensitive devices.

When handling or servicing equipment containing static sensitive devices, adequate precautions must be taken to prevent device damage or destruction. Only those who are thoroughly familiar with industry accepted techniques for handling static sensitive devices should attempt to service the cards with these devices. In all instances, measures must be taken to prevent static charge buildup on work surfaces and persons handling the devices. Cautions are included through this manual where handling and maintenance involve static sensitive devices.

SAFETY EARTH GROUND - This is a safety class I product and is provided with a protective earthing terminal. An uninterrupted safety earth ground must be provided from the main power source to the product input wiring terminals, power cord, or supplied power cord set. Whenever it is likely that the protection has been impaired, the product must be made inoperative and be secured against any unintended operation.

BEFORE APPLYING POWER - Verify that the product is configured to match the available main power source per the input power configuration instructions provided in this manual.

If this product is to be energized via an auto-transformer (for voltage reduction) make sure the common terminal is connected to the earth terminal of the main power source.

SERVICING

WARNING

Any servicing, adjustment, maintenance, or repair of this product must be performed only by qualified personnel.

Adjustments described in this manual may be performed with power supplied to the product while protective covers are removed. Energy available at many points may, if contacted, result in personal injury.

Capacitors inside this product may still be charged even when disconnected from its power source.

To avoid a fire hazard, only fuses with the required current rating and of the specified type (normal blow, time delay, etc.) are to be used for replacement.

WARNING

EYE HAZARD

Eye protection must be worn when removing or inserting integrated circuits held in place with retaining clips.

NOTICE

Many of the schematic diagrams and parts lists in this document contain the generic number of IC packs. These are for your convenience in referring to pack diagrams and general operating conditions in semiconductor manufacturer's catalogs. The generic number, however, should not be used to order replacement parts. Many parts used in Hewlett-Packard equipment are purchased with special specifications and tolerances, or may undergo special testing and treatment (such as burn-in). Replacement parts therefore must be ordered using the Hewlett-Packard part number to insure that the replacement part will restore the equipment to its proper operating condition.

PREFACE

This document contains engineering and reference information for the Hewlett-Packard HP 1000 L-Series Computer.

The L-Series computer hardware is available as printed circuit cards, computer units (boxes containing several printed circuit cards), and computer systems (boxes containing several printed circuit cards plus peripheral devices). This document is intended to assist you in arranging any of the L-Series combinations into unique, special-purpose computing systems.

Information is provided for the processor card, memory, power supply, battery backup, and backplane. The input/output (I/O) interfaces (Parallel Interface, Asynchronous Serial Interface, etc.) are not covered in this document; information concerning these items is provided in separate manuals. See the HP 1000 Computer Reference Manual, part number 02103-90007, for a documentation map of all available L-Series manuals.

The content of this document is as follows:

- Section I - HP 1000 L-Series Computer
- Section II - Processor Card
- Section III - 64Kbyte Memory
- Section IV - Power Supply
- Section V - Battery Backup
- Section VI - Backplane
- Section VII - Point-of-Load Regulator
- Section VIII - Expanded Memory
- Appendix A - Self-Test, Loaders, and VCP Programs
- Appendix B - Application Information for 25 KHz Power
- Cross-Reference Index

PREFACE

Section I contains information covering the HP 1000 L-Series computer at the system level, the box level, and the card (printed circuit) level.

In addition, power, ventilation, and assembly information are provided for those customers who wish to purchase and assemble individual cards into unique, special-purpose systems.

The remaining sections contain specifications, theory of operation information, parts list, and parts location information. Block diagrams, schematic diagrams, and parts location diagrams are provided. Additional diagrams, such as photographs of each card or assembly, are provided as necessary.

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HP 1000 L-SERIES COMPUTER	SECTION I
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1.1 INTRODUCTION

The HP 1000 L-Series Computer and Computer System are low-cost versions of the HP 1000 Computer family and, as such, are designed to deliver full minicomputer power to a variety of cost-critical applications.

1.2 PHYSICAL DESCRIPTION

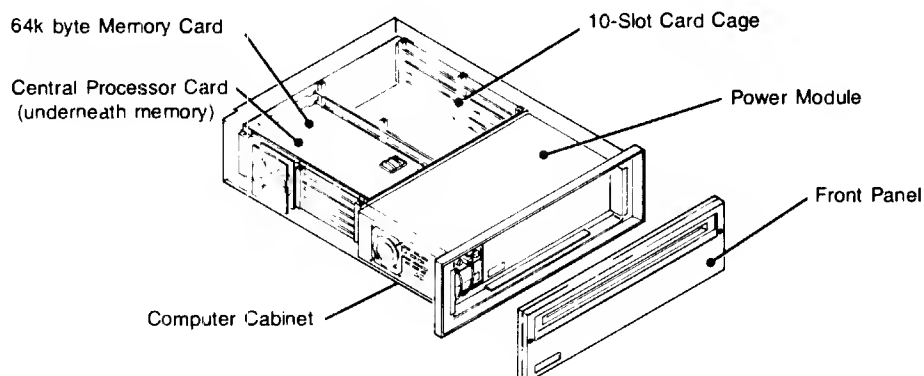
The L-Series computer hardware is available as printed circuit boards, computer units (boxes containing several printed circuit boards), and computer systems (boxes containing several printed circuit boards plus peripheral devices). This document is intended to assist you in arranging any of the L-Series combinations into unique, special-purpose computing systems.

Figure 1-1 illustrates L-Series boards, computers, and systems. Figure 1-2 contains a block diagram of the HP 1000 L-Series Computer.

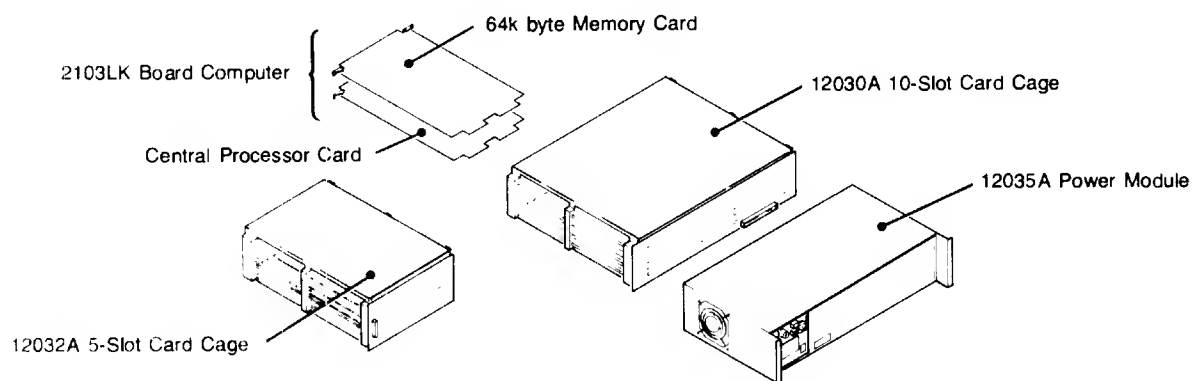
1.3 ELECTRICAL DESCRIPTION

The L-Series computer architecture is based on a "distributed intelligence" design using two custom silicon-on-sapphire (SOS) integrated circuit (IC) chips. The central processor unit (CPU) chip can execute most of the HP 1000 Computer Series instruction set (see the L-Series Computer Reference Manual, part no. 02103-90007). The CPU chip, in conjunction with other logic on the processor card, performs several system-level functions including memory protect, power fail/auto restart, time-base generation, parity error interrupt, and extensive self-tests.

2103L (box) Computer



2103LK Board Computer and Integration Accessories



I/O Interfaces, expanded memory, and other plug-in accessories

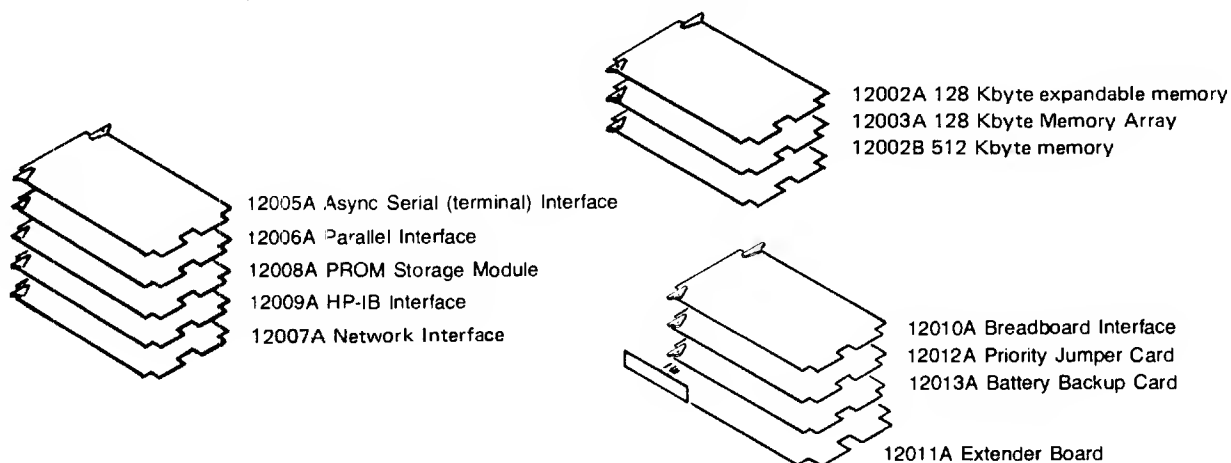


Figure 1-1. HP 1000 L-Series Computers (Sheet 1 of 2)

HP 1000 L-Series Computer Systems, Models 9 and 10

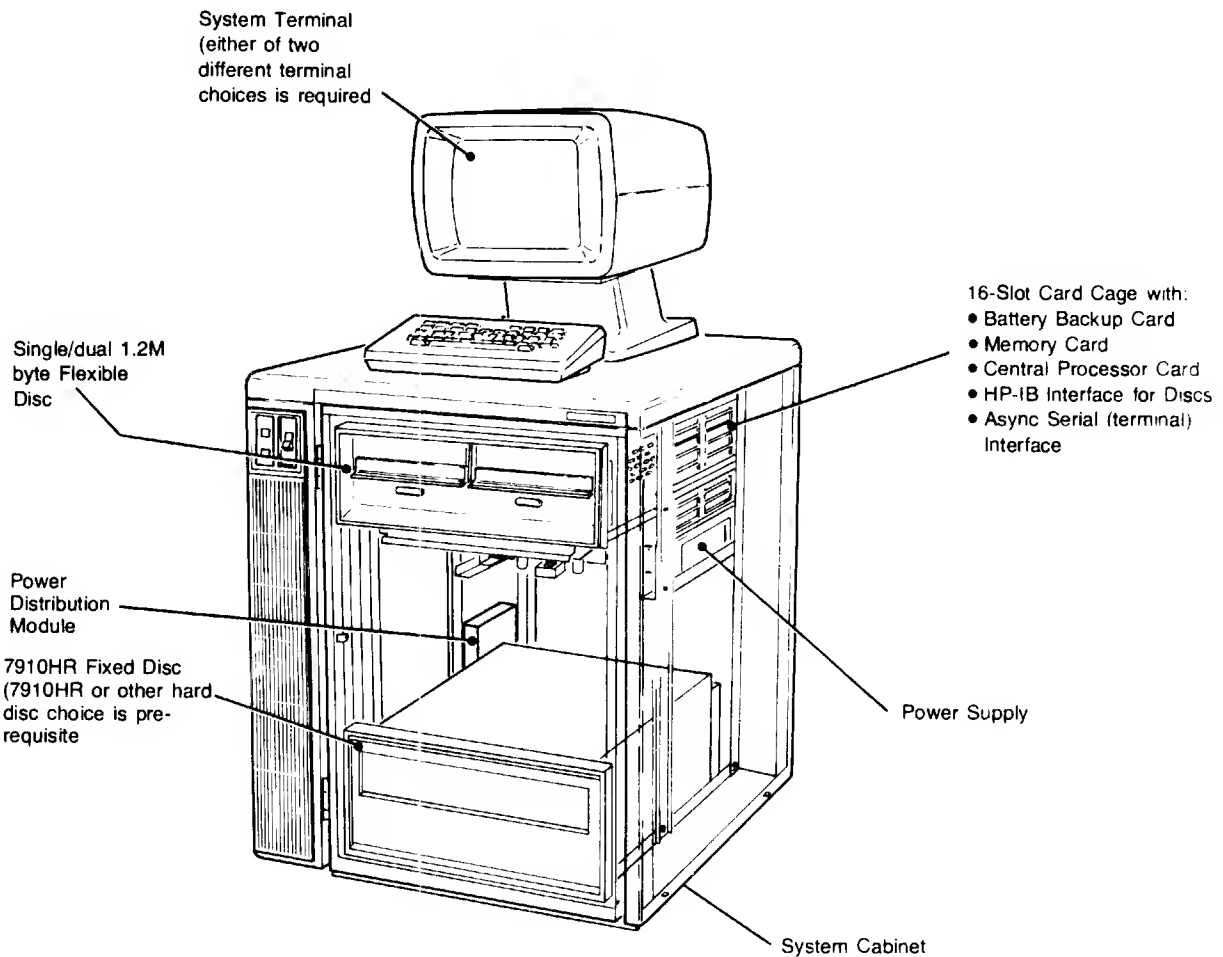
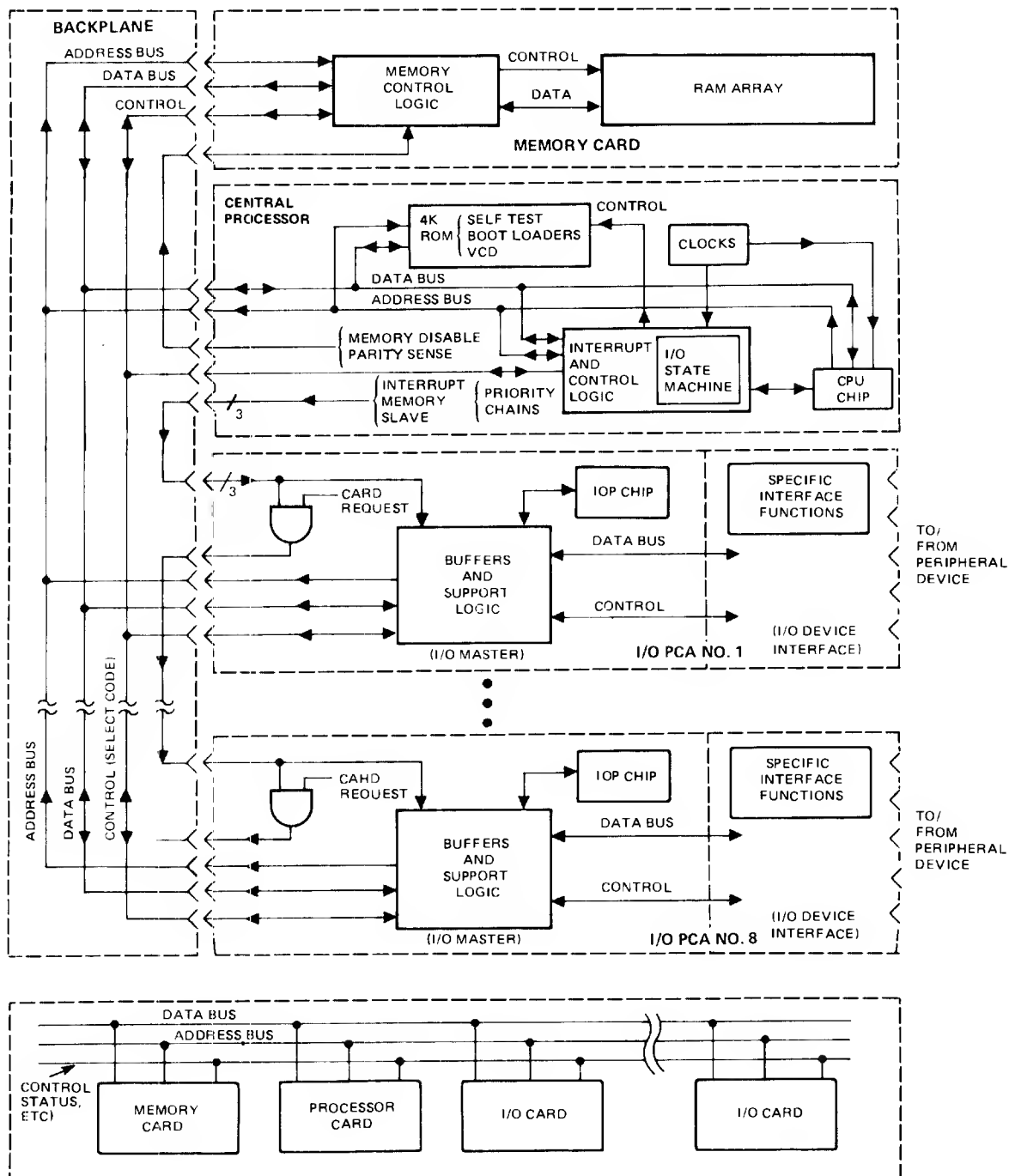


Figure 1-1. HP 1000 L-Series Computers (Sheet 2 of 2)



7700-459-1

Figure 1-2. HP 1000 L-Series Computer Block Diagram

All I/O instructions referencing select codes greater than octal 17 are executed by input/output processor (IOP) chips located on the individual I/O interface cards. A common backplane links the processor, memory, and I/O cards, allowing the IOP chips to monitor the flow of instructions over the backplane. They can, however, execute only those instructions that apply to I/O.

Because each I/O card is capable of operating independently of the processor, the L-Series can perform direct memory access (DMA) I/O transfers very efficiently. During DMA, an I/O card interacts with the processor card only on DMA initiation and completion; otherwise, the entire high-speed transfer is handled by the I/O card, leaving the processor card free to perform other tasks. This results in significant gains in overall system throughput.

1.4 SYSTEM SUPPORT FEATURES

1.4.1 VIRTUAL CONTROL PANEL

The Virtual Control Panel (VCP) is an interactive program located in a ROM (the VCP ROM) on the processor card. Because the L-Series does not have a conventional front panel, the VCP provides the capability of allowing a peripheral device, such as a terminal, to function as a virtual control panel (via an I/O interface card). In addition, when the L-Series is operating as an unattended, terminal-less node in a multi-computer network, a remote computer can function as a virtual control panel (again, via an I/O interface card).

The virtual control panel makes use of the L-Series slave mode feature. That is, the processor card is in slave mode when a device is operating as a virtual control panel.

The VCP program allows the peripheral device or remote computer to control execution of a program, access processor registers (A, B, P, etc.), examine or change memory, and then convey this information back to the remote device.

Slave, or VCP mode, can be entered in any one of three ways:

- a. After power up, when the boot loading program is directed to the VCP ROM in lieu of a boot routine.
- b. When an interface card requests slave mode.

c. Certain instructions can cause slave mode to be entered, as follows:

- 1) A HALT instruction causes an I/O interface card to do a Slave Request.
- 2) A CLC 3 instruction causes a Slave Request after four instructions are executed. The CLC 3 instruction is used by the VCP program to allow an operator (using the device connected to the I/O interface card) to single step through instructions.

The VCP ROM code is listed in Appendix A.

1.4.2 SELF-TEST CAPABILITY

The L-Series contains built-in self-test capability. Each time power comes up, the CPU chip, in conjunction with the processor card, executes a sequence that applies all possible combinations to the address bus, reads the address lines onto the data lines, reads the data lines back into the processor, and checks this input data against what was sent out. Any errors cause the processor to freeze, with the processor status lights indicating that the self-test has failed. The processor freeze is necessary because any failure of the data or address bus will prevent the computer from operating correctly, and thus must be repaired immediately.

Upon completion of the loop-back portion of the self-test built into the CPU chip, control is passed to the VCP ROMs, which contain the remainder of the self-test. Memory, all installed I/O interfaces, and much of the processor card circuitry is given a basic functional check.

The self-test procedure provides a reasonable probability that the minimum set of capabilities necessary to run a system is present when the system is booted in.

See the following manuals for a complete description of the self-test feature:

HP 1000 L-Series Computer System Installation and Service Manual, part number 02145-90003. (This manual covers the complete L-Series system, including peripheral devices.)

HP 1000 L-Series Computer Installation and Service Manual, part number 02103-90001. (This manual covers the L-Series computer only, excluding the peripheral devices.)

A listing of the self-test program contained in the ROMs on the processor card is given in Appendix A.

1.5 L-SERIES CARDS

The following information is of interest to customers who purchase L-Series cards. These customers will need to provide voltage, current, and ventilation as specified in the following paragraphs. Backplane information covering such items as connector pinouts, card cage layouts, and card cage assembly drawings is included in Section VI of this document.

1.5.1 POWER REQUIREMENTS

NOTE

Power requirements for I/O interface cards (Parallel Interface, Asynchronous Serial Interface, etc.) are provided in individual manuals covering these cards.

<u>CARD</u>	<u>VOLTAGE</u>	<u>CURRENT</u>		<u>POWER</u>	
		STANDBY	OPERATING	STANDBY	OPERATING
Processor Card	+5V	0mA	2962mA	0W	14.81W
	+5M	250mA	250mA	1.28W	1.28W
	+12V	0mA	36mA	0W	.43W
Memory, 12002A	+5V	0	2.4A	0	12.4W
	+5M	420mA	630mA	2.1W	3.2W
Memory, 12002B	+5V	0	2.4A	0	12.4W
	+5M	620mA	1.0A	3.2W	5.1W
Memory Array, 12003A	+5V	0	900mA	0	4.6W
	+5M	260mA	500mA	1.3W	2.3W
Memory, 12004A	+5V	0mA	1300mA	0W	6.50W
	+5M	757mA	757mA	3.79W	3.79W
	+12M	48mA	273mA	0.58W	3.28W
	-12M	20mA	20mA	0.24W	0.24W

REQUIRED REGULATION

+5 VOLTS +/- 0.25 VOLT (5%)

+12 VOLTS +/- 0.60 VOLT (5%)

-12 VOLTS +/- 1.2 VOLT (10%)

REGULATION SUPPLIED BY 12035A

DC voltages, Tolerances, and Periodic and Random Deviation
(No Load to Full Load):

+5 VOLTS	+/- 2%	50mV, nom., 300mV, max
+12 VOLTS	+/- 3%	100mV, max.
-12 VOLTS	+/- 6%	100mV, max.

If memory is to be sustained during power failure, the "M" (memory) voltages must be isolated from the processor and I/O voltages. If this feature is not desired, the +5M, +12M, and -12M may be common with the +5V, +12V, and -12V, respectively.

Additional power requirement information may be obtained from the HP 1000 L-Series Product Data Book. The current edition of the data book can be obtained from your local Hewlett-Packard Sales and Service Office.

NOTE

The current requirements for planned additions to your computer should be considered when designing your power supply.

1.5.2 VENTILATION REQUIREMENTS

Air intake may be from either the left or right side of the card cage. Vents are provided in the sides of the various card cage assemblies for this purpose. See the appropriate assembly drawing in Section VI of this document for the type of card cage you are using.

Air flow requirements in cubic feet per minute (cfm) can be computed as follows:

$$\text{cfm required} = \text{watts} \times 0.22$$

where 0.22 is a constant to provide the total cfm required so that the temperature rise should not exceed 10 degrees Celsius from ambient, and where maximum ambient is 55 degrees Celsius.

1.5.3 CARD CAGE AND BACKPLANE ASSEMBLIES

Information for assembling cards into the three card cages available with the HP 1000 L-Series is provided in Section VI of this document.

PROCESSOR CARD	SECTION II
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2.1 INTRODUCTION

The most important component on the processor card (figure 2-1) is a 64-pin silicon-on-sapphire (SOS) CMOS chip (CPU chip) that handles instruction execution, slave mode processing, and interrupt servicing functions. In this document, the terms "CPU chip" and "CPU" are used interchangeably and both terms refer to the CPU chip.

2.2 OVERVIEW

The CPU chip executes a major portion of the computer's instruction set pertaining to arithmetics and system control. The processor card also contains 4K of ROM firmware providing power up self-test, boot loader, and Virtual Control Panel (VCP) capabilities.

Four Field Programmable Logic Arrays (FPLA's) form the nucleus of a state machine which executes low select code I/O instructions and aids in handling interrupts.

Since the L-Series Computer is a synchronous machine, all of the clocks are generated on the processor card. The 40% duty cycle clocks are derived from a very stable crystal oscillator which doubles as an accurate time base for the time base generator.

Eight miniature LEDs are used to report operating or error status and eight switches allow easy selection of boot loaders and auto-restart options. Refer to the HP 1000 L-Series Computer Installation and Service Manual, part number 02103-90003 for a discussion of the LEDs and switches.

The balance of the processor card circuitry is composed of Schottky and low-power Schottky integrated circuits of the 7400 series TTL. These components are used to interface the CPU chip to the backplane and to the state machine on the processor card that handles the low select code I/O instructions.

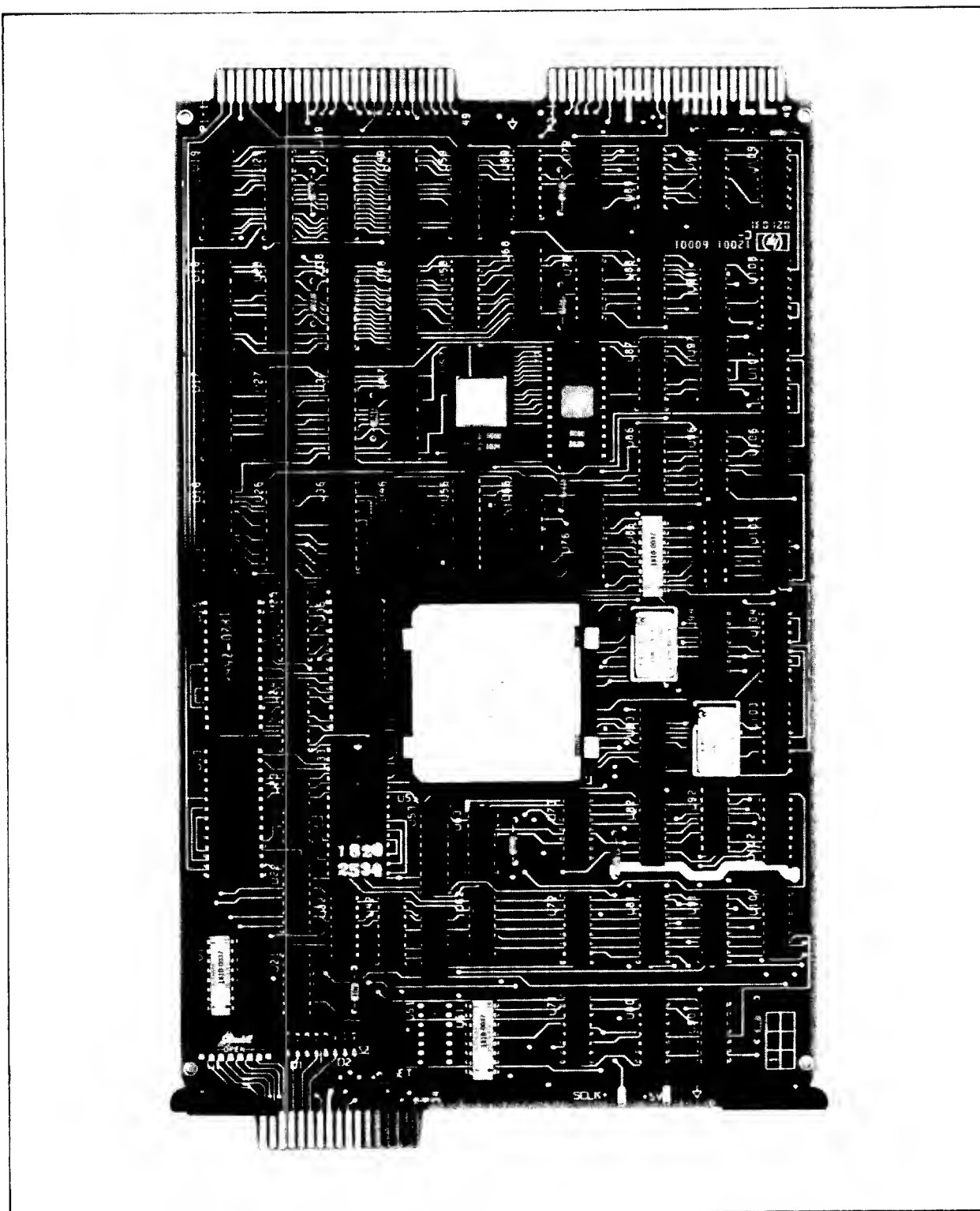


Figure 2-1. Processor Card (12001-60001)

2.2.1 SYSTEM ENVIROMENT

The system environment of the HP 1000 L-Series Computer is shown in figure 2-2. Note that the memory card is located immediately above the processor card and that all I/O cards are placed below the processor in descending interrupt and DMA priority. The processor card may go in any card slot as long as these rules are preserved. Empty slots between cards are not permitted in order to guarantee interrupt and DMA priority. See Section VI, figure 6-3, for card slot priorities.

Once plugged into the backplane, the processor card needs no further connection or cabling.

2.3 PROCESSOR CARD FUNCTIONAL THEORY OF OPERATION

The following paragraphs contain a functional description of the processor card. A functional description of the CPU chip is presented starting with paragraph 2.4.

A functional block diagram of the processor card is shown in figure 2-3.

2.3.1 MEMORY ACCESSING

All memory requests from the processor card, except for an interrupt trap cell fetch, are initiated by the CPU chip. The memory request may access either RAM on the memory card or ROM on the processor card. Since DMA operations by the I/O cards and memory requests by the processor card use the same protocols, RAM on the memory card may be accessed by all I/O channels and the processor. However, the ROM on the processor card can be accessed only by the CPU chip.

Because of the distributed intelligence concept of the HP 1000 L-Series, the processor card and all I/O cards latch the instruction off the data bus during each instruction fetch. The CPU chip and the processor card are responsible for the execution of their instruction set and, likewise, each I/O interface card must perform the I/O instructions pertaining to it. In addition, remote processors may reside as part of the L-Series system and execute those instructions not recognized by the CPU chip, the processor card, or any I/O interface card.

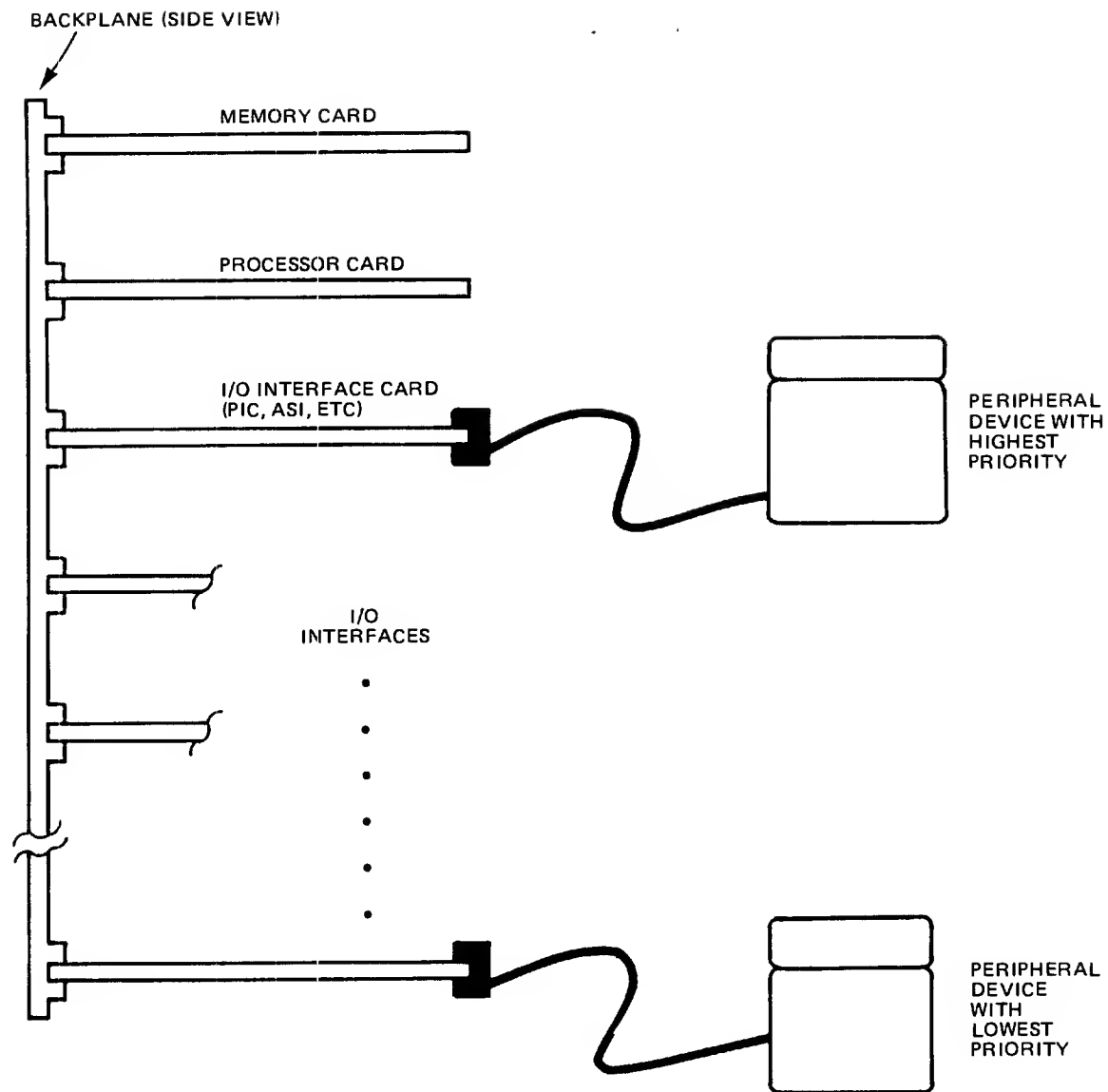
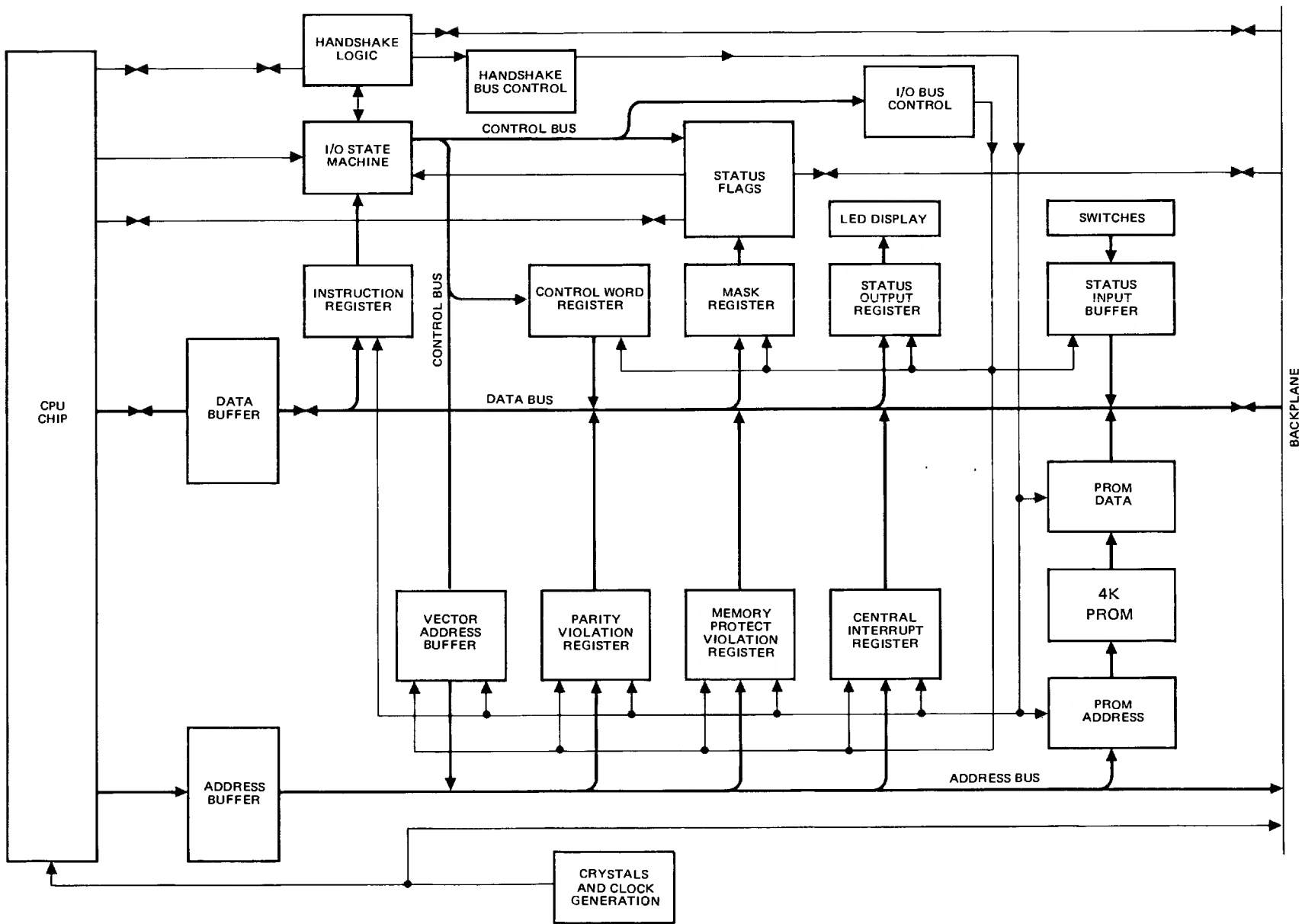


Figure 2-2. Processor Card in Typical System Environment

Figure 2-3. Processor Card Functional Block Diagram



Direct Memory Access (DMA) by the I/O cards is usually given higher priority than any memory access request from the CPU chip. If DMA is in process or pending, the processor card withholds the next CPU memory access until the current series of DMA is completed. The processor can momentarily suspend this hierarchy if the CPU chip was denied access to memory for thirty-two consecutive DMA memory accesses. This arrangement grants DMA nearly the full memory access bandwidth yet permits the processor to guarantee reasonable interrupt latency in DMA intensive environments.

When there are no active or pending DMA requests, the CPU initiates its memory request to the memory card. In a memory read transaction, the addressed data is returned at the end of the memory cycle. In the case of a memory write request, the data to be stored is sent to memory card at the same time as the address at the start of the memory cycle. A memory read request is distinguished from a write request by the sense of the most significant bit (AB15) in the address sent to the memory card.

ROM on the processor card is accessed by the CPU chip in relatively the same fashion, except that the memory card has been disabled and the ROMs have been enabled under program control or by the appropriate control word to the CPU chip during a slave transfer. This CPU access to ROM has no effect on DMA since the memory card is disabled only during the time it takes the CPU to access the memory card while the CPU is not in a memory cycle accessing ROM.

The A and B registers in the CPU chip are treated as physical memory locations 0 and 1, respectively, for instruction fetching. Any reference to those locations by the program counter is treated as an instruction fetch from the appropriate CPU chip register. When a program or DMA addresses the 0 or 1 memory location, it is addressing those memory locations and not the A or B register. Neither the program nor DMA should utilize these two memory locations since data stored there will be altered in the course of an instruction fetch from the A or B registers.

2.3.2 INTERRUPT PROCESSING

2.3.2.1 Interrupt Requests

There are two types of interrupt requests in the HP 1000 L-Series Computer. System level interrupts may be generated by the processor card to handle system level problems such as power fail and parity error. I/O interrupts may be requested by the individual I/O cards to cause processing to service the needs of that I/O channel.

The processor card receives all system level and I/O interrupt requests and determines which interrupt will be serviced. Three basic levels of importance define the relative priority of interrupt requests. A level one interrupt request has no restrictions in obtaining interrupt service. Level two and three requests are collectively enabled/disabled by a STC/CLC 4, the interrupt

inhibit flag. Level three interrupt requests may be further enabled/disabled by a STF/CLF 1, the interrupt system flag. In addition, interrupt masks are available to mask off any or all of the level three interrupt requests. A hardware signal from the CPU chip called Temporarily Disable Interrupt will cause one of the level two and all level three requests from interrupting following certain instructions and slave mode transfers.

The interrupt system flag is set/cleared with the STF/CLF 1 instruction, and affects level three interrupt requests. When the flag is set, the Time Base Generator (TBG) and any unmasked I/O interrupt request will receive service. The interrupt system flag allows the programmer to prevent TBG and I/O interrupts from interfering with selected portions of a program. This flag is cleared on power-up and in response to a CLC 0 instruction.

The Temporarily Disable Interrupt (TDI-) signal is utilized to resolve complications that would arise if an interrupt occurred while executing an indirect jump instruction. For the next instruction cycle following a jump, indirect (JMP,I); a jump to subroutine, indirect (JSB,I); an I/O group instruction; or enabling the bootstrap ROMs in slave mode processing; the processor will hold off the power fail interrupt request and all level three requests. Up to three levels of indirect jumps will keep these requests disabled. The power fail interrupt request is included in this group to simplify the power fail, auto-restart routine because it would not be necessary to save the status of an incomplete indirect jump sequence. The TDI- signal is asserted at power-up and de-asserted after the first instruction fetch unless that instruction falls into one of the above classifications.

The interrupt inhibit flag can disable all but the two highest priority interrupt requests: parity error and unimplemented instruction. The flag can be set/cleared by STC/CLC 4 in software. This feature can be used to prevent level two and three interrupt requests from delaying the preservation of system status in the event of power-down or from confusing system status restoration during power-up. The interrupt inhibit flag is automatically cleared on power-up. Typically, the flag should be set upon entering a power-up routine during auto-restart or at the start of a power-down routine at power fail. In addition, the interrupt inhibit flag should be set at the beginning of any interrupt service routine and not cleared until the central interrupt register has been recovered. Entry into the power-down routine via a power fail interrupt causes the interrupt inhibit flag to be set.

There are six system level interrupt requests. In order of priority, they are:

- a. Parity error.
- b. Unimplemented instruction.
- c. Memory protect.
- d. Special interrupt.

e. Power fail.

f. Time base generator.

There can be as many I/O interrupt requests as there are I/O interface cards in the system since each I/O card has interrupt capability. The priority of I/O interrupt requests among the I/O cards is a function of the card's physical placement from the processor; the closest card has the highest priority and cards below it have descending priority independent of the select codes assigned. I/O interrupt requests have lower priority than TBG and both are maskable.

A parity error interrupt request occurs when the memory card signals a parity error during a processor memory access if the parity system had been enabled. The parity system is enabled/disabled by a STC/CLC 5 command in software. The current sense of parity is made even/odd by STF/CLF 5 and the default at power-up is odd parity. Parity error takes precedence over other system level problems because incorrect data reaching the CPU chip may be construed erroneously as an unimplemented instruction or a memory protect violation. Therefore, any parity error occurring during a processor access to memory is considered catastrophic and is serviced immediately.

An unimplemented instruction interrupt request is made when the CPU chip signals that the last instruction fetched was not recognized by the chip or by any other system card. This interrupt provides a straightforward entry to software routines for the execution of instruction codes not recognized by the computer hardware. This request must receive immediate service in order to recover the instruction code that caused it. The unimplemented instruction interrupt is never inhibited and concedes priority only to a parity error.

A memory protect interrupt request is made when the CPU chip signals that the last instruction fetched has violated the memory protection rules while memory protect is enabled. The memory protect feature is enabled with a STC 7 instruction and an OTA/B 7 is used to load the memory protect fence from the A or B register. All memory locations below the fence address are considered protected and can not be written into. I/O instructions are also affected. Any I/O instruction except those referring to select code 1 but not including HALT 1, will trigger a memory protect interrupt request if memory protect is enabled. This will insure that a user program will not interfere with the operating system's handling of I/O. The memory protect interrupt request can only be inhibited by the interrupt inhibit flag.

A special interrupt request is a user-defined high priority interrupt request from either the backplane or the frontplane. This is the only general purpose system level interrupt whose application is assigned by the user. This interrupt request has lower priority than memory protect and can only be inhibited by the interrupt inhibit flag.

A power fail interrupt request is made after the power supply has signalled a power fail warning. This warning indicates that line power has been cut off and that regulated power will soon be lost. The power fail interrupt request

may be denied by either the interrupt inhibit flag or a temporary interrupt disable.

A time base generator (TBG) interrupt request is initiated every ten milliseconds to update any real time clocks in software. The TBG signal originates from the CPU chip and is accurate to within 4.3 seconds per day. This level three interrupt is maskable and requires the interrupt system to be enabled, that interrupts not be temporarily disabled, and that level two and three interrupts are not inhibited.

I/O interrupt requests come from the I/O interface cards. Collectively, these requests may be inhibited by the same signals which inhibit TBG interrupt requests. TBG commands higher priority than I/O requests when both request interrupt service. The interrupt mask is used to disable I/O requests by select code groups.

The following chart shows pictorially the relative priority and the qualifiers required by each interrupt request.

```
level 1
parity error during a CPU memory access
unimplemented instruction

*****interrupt inhibit flag (STC/CLC 4)
level 2
memory protect violation
special interrupt request
-----Temporarily Disable Interrupt (TDI-)
power fail

*****interrupt system flag (STF/CLF 0)
level 3
-----interrupt mask
time base generator
I/O interrupt requests
```

2.3.2.2 Interrupt Service

An interrupt is acknowledged by fetching an instruction from the memory location whose address matches the select code of the interrupt requestor. Service of simultaneous interrupt requests is accomplished on a priority basis. The highest priority system level interrupts are serviced first, before any I/O interrupts, which are serviced according to their location from the processor (see Section VI, figure 6-3 for an illustration of slot priority).

The CPU chip handles interrupts on a generalized basis without knowing which request it is servicing. The processor card receives all requests but only informs the CPU chip that there is an interrupt pending. At the end of the current instruction execution, the CPU will acknowledge the interrupt. All of

the normal protocols used for an instruction fetch are used except that the instruction address and MEMGO- are driven by the highest priority requesting device instead of the CPU. The processor card is responsible for providing the vector address if a system level interrupt is being serviced. Service of an I/O interrupt is accomplished by the requesting I/O card when it drives its select code onto the address bus as the vector address.

Interrupt servicing on the HP 1000 L-Series is performed by executing an instruction located in the trap cell accessed by the vector address. The vector address is the address at which interrupt servicing begins. System level interrupts are associated with vector addresses 4 through 17 octal while vector addresses 20 to 77 octal are reserved for all possible I/O card select codes. Therefore, the vector address is equivalent to the select code assigned to that I/O channel. The trap cell is the first instruction of each interrupt service routine and is stored in the vector address locations. A JSB instruction is normally found in the trap cells to cause program execution to branch to the appropriate service routine and then to return to the original program at the completion of the subroutine.

An I/O state machine on the processor card handles interrupts associated with I/O select codes and vector addresses 4, 5, 6, 7, 10, and 17. These are the power fail, parity error, time base generator, memory protect violation, unimplemented instruction, and special interrupts, respectively. For example, suppose the CPU chip detects the presence of an unimplemented instruction and informs the processor that such a condition exists. The state machine qualifies this as a valid interrupt request and asks the CPU chip for an interrupt. The CPU will acknowledge the interrupt and proceed to do an instruction fetch minus the instruction address and a MEMGO-. The I/O state machine will supply the vector address 10 octal and the MEMGO- to start the interrupt service with the instruction at that address.

An interrupt handled by the I/O interface cards begins with an interrupt request. The highest priority I/O request waits until it receives an interrupt acknowledge signal (IAK-) simultaneously with a deasserted ICHOD- on the backplane. ICHOD- is the interrupt chain disable output of the next higher priority interrupting device. Since all system level interrupts have priority over I/O interrupts, ICHOD- is deasserted by the processor card when there are no system level interrupt requests pending. The authorized I/O card will put its select code on the address bus as the vector address and begin the memory cycle with a MEMGO-.

The interrupt acknowledge signal IAK- normally occurs at the end of the current instruction cycle and before the next instruction fetch. Only in the case of an unimplemented instruction or a memory protect violation will the CPU chip behave differently. An unimplemented instruction has an instruction cycle which can not be completed, so the CPU chip will report that status to the processor and wait for an interrupt request. For an instruction which causes a memory protect violation, the CPU chip must immediately inform the processor that there is a violation. The processor will block any CPU attempts to write to memory during the current instruction cycle by converting

all memory writes to memory reads. This insures that no memory locations below the memory protect fence are destroyed before the interrupt is serviced. If the violation was due to the presence of an I/O instruction when memory protect is enabled, the instruction is not executed before the interrupt is serviced.

Interrupt latency is the time between the interrupt request and its acknowledgement. This time is normally less than the time it takes to execute the current instruction but may be lengthened by concurrent DMA intervention on the backplane. Since DMA has priority over the processor for memory accesses, any interrupt acknowledgement will also be delayed until current DMA is completed. Depending on DMA utilization of the backplane, interrupt latency can vary from microseconds (typical) to nearly a millisecond during complete DMA monopolization of the backplane. For applications where short latency times are desirable, DMA should be suspended or operated at lower transfer rates.

2.3.3 I/O PROCESSING

2.3.3.1 I/O Accessing

Most of the I/O group instructions are executed by the processor card I/O state machine or by the IOP chip on the interface cards. Instructions such as STC/CLC and STF/CLF can be executed by the appropriate interface card without interaction with the CPU chip. Other I/O instructions such as SFS/SFC, LIA/B, MIA/B, and OTA/B do affect the operation of the CPU and hence require a set of I/O protocols to handle this situation. A third set of I/O instructions involving the overflow bit in the CPU chip is executed solely by the CPU without involving the IOP chip.

I/O accessing to the appropriate I/O channel is made by select code. Select codes 20 to 77 octal are the valid codes for the interface cards. All lower select codes, 0 through 17 octal, are reserved for system level I/O processing, which includes the enable/disable interrupt system and output to the status register instructions. These low select code I/O instructions are generally handled by the processor I/O state machine or by the CPU chip.

Interaction between the various processors in the HP 1000 L-Series is facilitated by I/O handshakes. This effectively places the CPU chip into slave mode so that its internal registers may be read or altered by the I/O executor to accomplish the execution of the instruction. A single handshake is required for the I/O executor to inform the CPU chip to increment the program counter if the conditional skip is true. A double handshake is necessary if any data is passed into or out of the CPU. The first handshake passes a control word to the CPU chip to tell it how to process the data transfer which takes place during the second handshake. This allows the A or B registers to be loaded from or merged with an I/O buffer, or to be copied into an I/O buffer.

Suppose that an I/O interface card with select code 27 receives a SFS 27 instruction and that its flag had been previously set. That I/O card asserts IORQ- as soon as it has recognized the instruction and determined that the conditional skip is true. The CPU will eventually respond with an IOGO- assertion to affirm that it has received the I/O handshake request. The I/O card will de-assert IORQ- to signal that the control word will be available on the data bus on the second rising edge of SCLK-. That control word will contain the command to cause the CPU chip to increment the program counter again. The program counter is always incremented at the end of an instruction fetch to point to the next instruction; incrementing it once more during a conditional skip will effectively cause execution to pass over the next instruction.

If an LIA 27 instruction has appeared on the backplane, the affected I/O interface card will assert IORQ- and wait for IOGO- also. Upon releasing IORQ-, it informs the CPU that the next I/O handshake will require information on the data bus to be loaded into the A register. IORQ- is asserted again one state after its previous de-assertion to begin the second half of the double handshake. After the re-assertion of IOGO- to the second IORQ-, the interface card puts the data word on the backplane data bus. The CPU loads the A register with this data on the second rising edge of SCLK- after the de-assertion of the second IORQ-. Operation of the LIB, MIA/B, or OTA/B instructions is similar, except for the direction or destination of the data flow.

Like processor accesses to memory, the completion of an I/O handshake is subject to DMA action on the backplane. DMA is automatically suspended for an instruction fetch but may be resumed thereafter by I/O cards unaffected by the instruction. The affected I/O card will issue an IORQ- but the processor will be unable to respond with an IOGO- until all pending DMA is completed. At that time, the assertion of IOGO- will suspend DMA until the end of the current I/O access.

2.3.3.2 Processor Card I/O Functions

Six program-accessible registers are resident on the processor card:

- a. An input status register which provides information about which boot loader was selected by the processor card switches, the status of memory power, and the status of interrupt mask bit one. An LIA/B 1 or MIA/B 1 is used to load or merge the contents of the input status register into the A or B register.
- b. An output status register which drives seven of the processor card's eight status LEDs and a bank switching bit that selects which 1K of processor card ROM is in use. For processors equipped with 32K ROMs, an additional bank switching bit is provided in the output status register to account for the extra ROM addressing bit. An OTA/B 1 will place the contents of the A or B register into the output status register.

- c. A parity error register which records the address of any word read with a parity error. This register stores the address of every memory read initiated by the processor and holds the address when a parity error is signalled. The register may also be written to by an OTA/B 5 and read from via an LIA/B 5 or MIA/B 5.
- d. A memory protect violation register which records the address of the instruction that violated the memory protect rules. This register also stores the address of every instruction fetch and freezes that information when a memory protect violation occurs. Data may be placed into this register in software by an OTA 7,C or an OTB 7,C. Note that OTA/B 7 without the clear bit, writes to the memory protect fence and not to the violation register. LIA 7,C; LIB 7,C; MIA 7,C; MIB 7,C are used to read from the memory protect violation register.
- e. A central interrupt register which records the select code of the interrupt most recently serviced. This register can also be loaded by OTA/B 4 and read by LIA/B 4 or MIA/B 4 in software.
- f. An interrupt mask register which stores interrupt mask bit one which controls time base generator interrupts. Other bits of the interrupt mask register are on the I/O interface cards. This register is loaded by OTA/B 0 and read by LIA/B 0 or MIA/B 0 in software.

These registers allow many of the system features of the HP 1000 to be included as part of the processor rather than having them occupy separate I/O cards.

Several system level flags are maintained on the processor card:

- a. The interrupt system flag, when cleared, prohibits level three (time base generator and I/O) interrupts.
- b. The interrupt inhibit flag, when cleared, prohibits level two and three (priority, memory protect, power-fail, time base generator, and I/O) interrupts.
- c. The global register flag, when cleared, enables the use of the the global register on the I/O interface cards.
- d. The parity sense flag, when cleared, informs the memory card to use odd parity.
- e. The parity system flag, when set, enables parity interrupts.
- f. The time base generator flag, when set, indicates that 10 msec have elapsed since the last time base tick.

At power-up, the interrupt system, parity sense, parity system, and the time base generator flags are cleared while interrupt inhibit and the global register flags are automatically set.

The processor card registers may be accessed and the system level flags may be modified in software. The commands used are basically the low select code (0-7) I/O group instructions. The processor card I/O state machine utilizes the same protocols used by the I/O interface cards to handshake with the CPU chip. Table 2-1 lists the I/O instructions executed by the processor card.

Table 2-1. Processor Card Instructions

INSTRUCTION	FUNCTION
CLC 0 (Clear Control 0)	Causes system reset (CRS-)
STF/CLF 0 (Set/Clear Flag 0)	Turn interrupt system on/off
SFS/SFC 0 (Skip if Flag Set/Clear 0)	Skip the next instruction if the interrupt system is on/off
OTA/B 0 (Output A/B 0)	Output the A or B register to the interrupt mask register
LIA/B 1 (Load Into A/B 1)	Load the A or B register with the contents of the input status register
MIA/B 1 (Merge Into A/B 1)	Merge the A or B register with the contents of the input status register
OTA/B 1 (Output A/B 1)	Output the A or B register to the output status register
STF/CLF 2 (Set/Clear Flag 2)	Disable/enable the global register
SFS/SFC 2 (Skip if Flag Set/Clear 2)	Skip the next instruction if the global register is disabled/enabled
OTA/B 2 (Output A/B 2)	Output the A or B register to the global register
STC/CLC 4 (Set/Clear Control 4)	Set/Clear interrupt inhibit flag
SFS/SFC 4 (Skip if Flag Set/Clear 4)	Skip the next instruction if the power is up/going down
LIA/B 4 (Load Into A/B 4)	Load the A or B register with the contents of the central interrupt register

Table 2-1. Processor Card Instructions (Continued)

INSTRUCTION	FUNCTION
MIA/B 4 (Merge Into A/B 4)	Merge the A or B register with the contents of the central interrupt register
OTA/B 4 (Output A/B 4)	Output the A or B register to the central interrupt register
STC/CLC 5 (Set/Clear Control 5)	Enable/disable parity interrupts
STF/CLF 5 (Set/Clear Flag 5)	Generate and detect even/odd parity
SFS/SFC 5 (Skip if Flag Set/Clear 5)	Skip the next instruction if even/odd parity is being generated and detected
LIA/B 5 (Load Into A/B 5)	Load the A or B register with the contents of the parity error register
MIA/B 5 (Merge Into A/B 5)	Merge the A or B register with the contents of the parity error register
OTA/B 5 (Output A/B 5)	Output the A or B register to the parity error register
CLC 6 (Clear Control 6)	Clear any pending time base generator interrupt request (Also shuts off TBG in chip)
STF/CLF 6 (Set/Clear Flag 6)	Set/clear the time base generator flag
SFS/SFC 6 (Skip if Flag Set/Clear 6)	Skip the next instruction if the time base generator flag is set/clear
LIA/B 7,C (Load Into A/B 7,C)	Load the A or B register with the contents of the memory protect violation register

Table 2-1. Processor Card Instructions (Continued)

INSTRUCTION	FUNCTION
MIA/B 7,C (Merge Into A/B 7,C)	Merge the A or B register with the contents of the memory protect violation register
OTA/B 7,C (Output A/B 7,C)	Output the A or B register to the memory protect violation register
OTA/B 7 (Output A/B 7)	Output the A or B register to the memory protect fence

2.4 CPU CHIP FUNCTIONAL THEORY OF OPERATION

The CPU chip handles the majority of the computer's instruction execution duties and provides control signals for the processor card. The names, whether they are input to or output from the chip, and the functions of all chip signals are presented in table 2-2.

Table 2-2. CPU Chip Signal Definitions

BCLK+	(Input, high true)
FULL NAME:	CPU Clock
FUNCTION:	Master synchronizing clock for the CPU chip.

Table 2-2. CPU Chip Signal Definitions (Continued)

BTN-	(Output, low true)
FULL NAME:	Boot Enable
FUNCTION:	Asserted to indicate that, for the current memory reference, the CPU is accessing the ROM.
FCH-	(Output, low true)
FULL NAME:	Fetch
FUNCTION:	Asserted to indicate that the current memory access is an instruction fetch.
(IA0+) - (IA14+)	(Output, high true)
FULL NAME:	Internal Address bus 0 through 14
FUNCTION:	A 15-bit bus used to transfer the address for all memory transfers.
(ID0+) - (ID15+)	(Bidirectional, high true)
FULL NAME:	Internal Data bus 0 through 15
FUNCTION:	A 16-bit bus used to transfer data into or out of the CPU chip.
IIAK+	(Output, high true)
FULL NAME:	Internal Interrupt Acknowledge
FUNCTION:	Asserted to indicate that the subsequent non-DMA memory access is an instruction fetch in response to an interrupt.
IIOGO+	(Output, high true)
FULL NAME:	Internal Handshake Request Acknowledge
FUNCTION:	The I/O handshake request acknowledge signal generated by the CPU.

Table 2-2. CPU Chip Signal Definitions (Continued)

IIORQ+	(Input, high true)
FULL NAME:	Internal I/O Handshake Request
FUNCTION:	I/O handshake signal asserted to indicate that the processor card or an interface card requires CPU chip service.
INT+	(Input, high true)
FULL NAME:	Interrupt Request
FUNCTION:	Asserted to signal that the processor should service an interrupt upon completion of the current instruction.
I/OG+	(Output, high true)
FULL NAME:	I/O Group Instruction
FUNCTION:	Asserted after an instruction fetch to signal that the instruction is in the I/O group and references select codes 0, 2, 4, 5, 6, 7, or HLT 01.
IPON+	(Input, high true)
FULL NAME:	Internal Power On
FUNCTION:	Asserted when all system power voltages have reached their prescribed levels.
MEM+	(Output, high true)
FULL NAME:	Memory Request
FUNCTION:	Asserted to drive MEMGO- signal to indicate a memory request.
MGO-	(Output, low true)
FULL NAME:	Memory Go
FUNCTION:	Asserted to signal that a memory cycle may begin.

Table 2-2. CPU Chip Signal Definitions (Continued)

MND+	(Input, high true)
FULL NAME:	Memory End
FUNCTION:	When asserted, indicates that the memory cycle is complete.
MPF+	(Output, high true)
FULL NAME:	Memory Protect Enabled
FUNCTION:	Asserted to indicate that the memory protect system is enabled.
MPV+	(Output, high true)
FULL NAME:	Memory Protect Violation
FUNCTION:	Asserted to indicate that the current instruction is one that will cause a memory protect violation.
READ+	(Output, high true)
FULL NAME:	Memory Read
FUNCTION:	Asserted to indicate that the CPU is reading data from the internal data bus (IDB); otherwise, the CPU is driving the internal data bus.
SLK-	(Output, low true)
FULL NAME:	Slave Acknowledge
FUNCTION:	Asserted to acknowledge that the CPU has entered the slave mode.
SLV+	(Input, high true)
FULL NAME:	Slave Request
FUNCTION:	Driven by a SLAVE- signal from an I/O interface card which is requesting the CPU to enter the slave mode.

Table 2-2. CPU Chip Signal Definitions (Continued)

TBT+	(Output, high true)
FULL NAME:	Time Base Generator Tick
FUNCTION:	Asserted for one cycle of SCLK- to indicate that the time base generator circuitry has counted off 10 msec.
TDI-	(Output, low true)
FULL NAME:	Temporarily Disable Interrupts
FUNCTION:	Asserted to indicate that certain interrupts should be held off.
UIT+	(Output, high true)
FULL NAME:	Unimplemented Instruction Trap
FUNCTION:	Asserted to indicate an unimplemented instruction has been detected.

2.4.1 CPU CHIP DATA PATHS

A simplified block diagram of the CPU chip is shown in figure 2-4. The basic operation of the chip is structured around five buses. Internal Bus 2 is the primary data bus and is connected to the external data bus (ID0+ through ID15+). This bus provides one set of 16 input lines to the Arithmetic Logic Unit (ALU). Bus 3 is the internal address bus and is connected to the external address pins (IA0+ through IA14+). Bus 4 provides the other set of 16 inputs to the ALU. The output of the ALU, which is examined by the status logic, feeds the T register and is shown on the diagram as the A bus; the output of the T register is shown as the T bus.

The buses are controlled by the signals shown in figure 2-4. All connections shown in the figure are actually bidirectional transmission gates (some, however, are used only in one direction). B23 connects Bus 2 to Bus 3; this transmission may occur in either direction. B34 performs a similar function for Bus 3 and Bus 4. BT2 and BT4 enable the T bus onto Bus 2 or Bus 4, respectively. R/W (Read/Write) indicates the direction of the data bus drivers. A 1 signifies that the data is driven from the external bus to the internal data bus (Bus 2) and a 0 signifies that the data is driven from the internal bus to the external data bus. The internal address bus (Bus 3) drivers are always enabled to drive the lower 15 bits of this bus onto the external address bus. The signal ZB2 forces zeros on all lines of the internal data bus Bus 2.

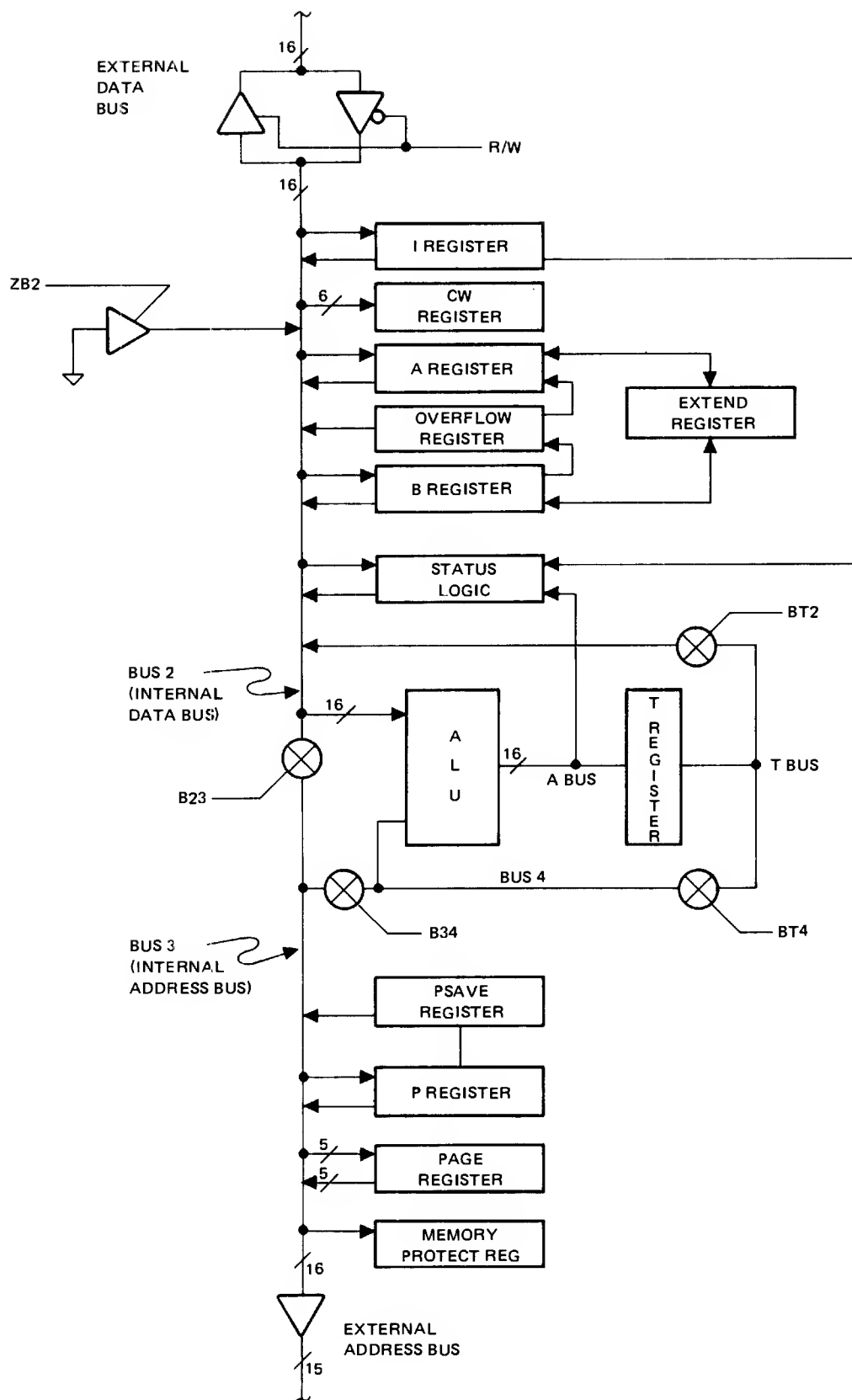


Figure 2-4. CPU Chip Functional Block Diagram

2.4.2 CPU CHIP REGISTERS

2.4.2.1 Instruction Register

The instruction, or I register, reads from and writes onto Bus 2. The I register is a 16-bit latch register which passes data on the signal LDI when the internal clock signal (INTCLK) is high. The four least significant bits of the I register (IR3 - IR0) form a down counter that counts when the signal CLKI is asserted. This 4-bit counter is used to keep track of the number of shifts in the double register shift operations and the number of iterations in the multiply and divide instructions. The I register is not accessible to the programmer.

All 16 bits of the I register go to the IR logic for instruction decoding. When the RDI signal is asserted, bit 15 (direct/indirect) and bits 0 through 9 (page address) of the I register are driven onto their respective bits of Bus 2, and IR10 is driven onto bits 10 through 14 of Bus 2. This allows the page offset in an MRG instruction to be ANDed with the page register (see next paragraph) to generate the effective memory reference address.

2.4.2.2 Page Register

The page register is a 5-bit D flip-flop register used to store the current page address. The five bits are from the program counter. This register is not accessible to the programmer.

In order to form the address desired by the instruction, it is necessary to merge the explicit page address (bits IR9 - IR0) with the page. This is accomplished by ANDing in the ALU, the page register contents and the address contained in the I register. For this reason, when the I register is read onto Bus 2, bit 10 (the bit that specifies zero or current page) is read onto Bus 2 bits 14 through 10 (which are the location of the page bits in the page register). If IR10 is a 1 (current page), the AND in the ALU results in a merge of the explicit and page address information. If IR10 is a 0 (page zero), the AND causes the page bits to be zeroed, resulting in an address which is on page zero.

The operations described above are demonstrated in figure 2-5.

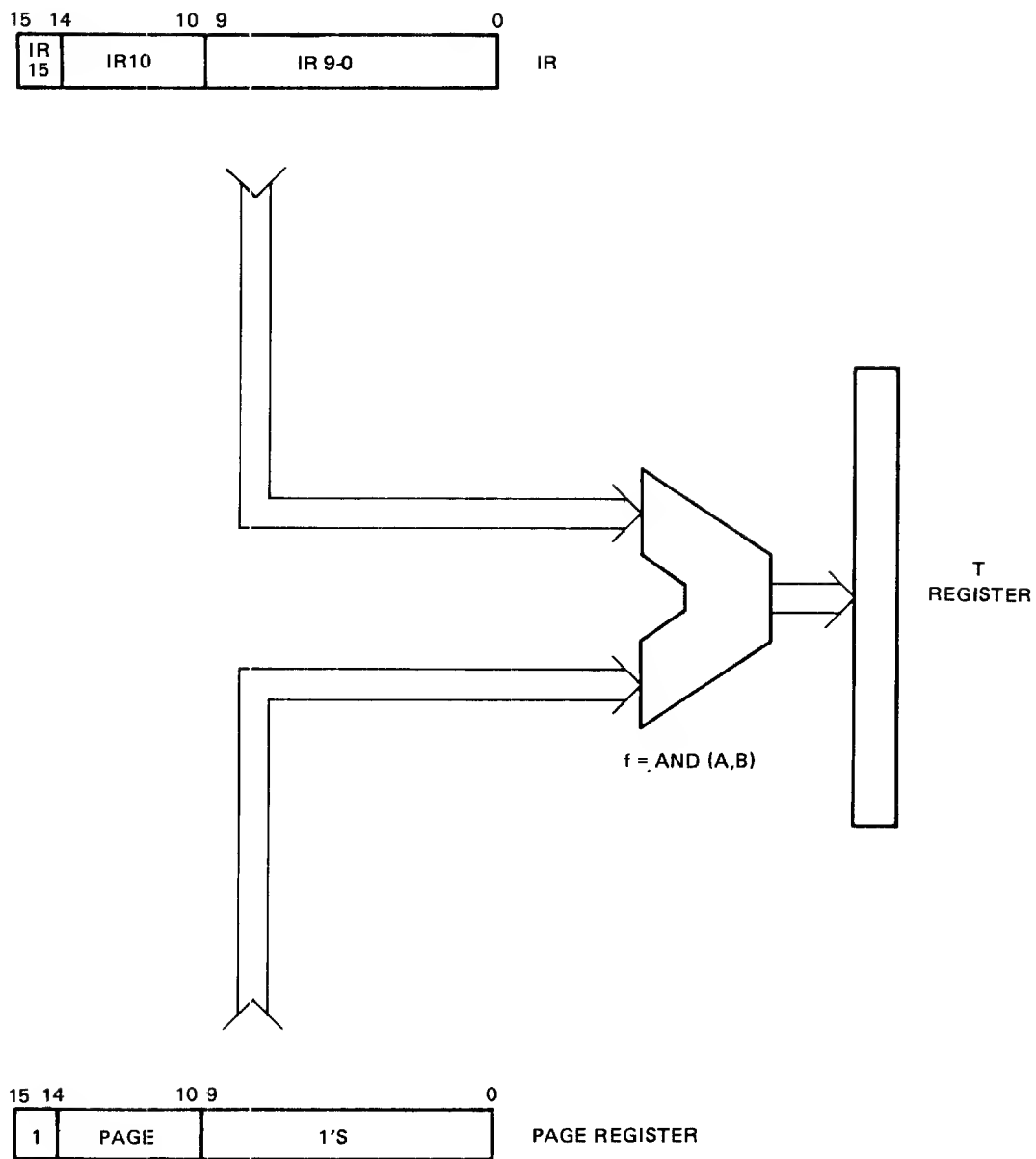


Figure 2-5. ANDing the Page Register and I Register Contents

2.4.2.3 Control Word Register

The control word (CW) register is a 5-bit register that holds the CPU Control Word when the CPU is in slave mode. The CW register bits CW0 through CW4 are loaded from Bus 2 bits 4 through 8, respectively. The CW register is not accessible to the programmer.

In a sense, the CW register is an auxiliary instruction register in that when the CPU is in slave mode, or has just decoded an I/O instruction, the CW register holds the word which specifies which of the I/O operations is to be executed. Additionally, the CW register indicates whether or not the CPU should do another cycle on completion of the current transfer.

Of the five bits in the CW register, four specify the current operation and one signifies looping. The register is loaded or cleared by the LDCW signal on the falling edge of INTCLK. The decision to load or clear depends on whether the signal IIORQ is asserted. If the CPU decodes an I/O instruction which requires interaction between, for example, an I/O card and the CPU, the requesting card generates the IIORQ signal (an I/O handshake signal) and the CW register is loaded. If the CPU decodes an I/O instruction which requires no interaction with the CPU (i.e., STF, CLF, etc.), no card asserts the IIORQ signal and the CW register is cleared.

All zeros in the CW register signify a NOP, no loop, and cause the CPU to fall through the I/O and slave processing states and continue execution.

2.4.2.4 A and B Registers

The A and B registers are the system accumulators. They are 16-bit, bidirectional shift registers which can perform four operations as follows:

- LOAD (from Bus 2)
- SHIFT LEFT 1
- SHIFT RIGHT 1
- SHIFT LEFT 4

Coupled with the shift logic, these four operations can perform all the shift functions required for the L-series instruction set. The A and B registers also serve as operand/accumulator registers for multiply and divide.

The A and B registers are clocked at the end of the state time by the signals ACLK and BCLK. They are enabled onto bus Bus 2 by the signals RDA and RDB.

The A register may be addressed as memory location 00000 (octal) by any Memory Reference Group or Extended Arithmetic Group instruction; the B register may be addressed as memory location 00001 (octal) by any Memory Reference Group or Extended Arithmetic Group instruction.

2.4.2.5 Extend (E) Register

The extend (E) register is a 1-bit register used to link the A and B registers by rotate instructions or to indicate a carry from the most significant bit (bit 15) of the A and B registers by certain arithmetic instructions.

The E register may be set, cleared, complemented, and tested under program control, and may be accessed in slave mode as bit 11 of the status register.

2.4.2.6 Overflow (O) Register

The overflow (O) register is a 1-bit register used to indicate that an arithmetic instruction has caused the A and B registers (accumulators) to exceed the maximum positive or negative number which can be contained in these registers.

The O register may be set, cleared, and tested under program control, and may be accessed in slave mode as bit 6 of the status register.

2.4.2.7 T Register

The T register is a 16-bit temporary holding register connected to the output of the ALU. Because the A and B registers read from and write to the same bus (Bus 2), the results must be stored temporarily to allow the bus to be turned around. This is the function of the T register.

The contents of the T register can be enabled directly onto Bus 2 and indirectly onto Bus 3. Bit 15 of the T register may be examined by the state machine in order to determine status conditions or for making state branches.

The T register is not accessible to the programmer.

2.4.2.8 P Register

The P register is a 16-bit register that holds the program counter during instruction fetches and the memory address for all memory reference instructions. It also provides temporary storage for operands in multiply and divide. The P register is capable of being loaded from Bus 3 and of

incrementing by one. Operation of the register is controlled by the LDINC signal. When LDINC = 1, the P register will drive the bus on the rising edge of CLKP. When LDINC = 0, the register increments (the register is a synchronous counter).

Associated with the P register is logic which notifies the CPU control section when the P register points to the A or B registers. This is important because the handling of references to A and B as memory locations 0 and 1, respectively, are handled differently from references to other memory locations.

2.4.2.9 PSAVE Register

The PSAVE register is a 15-bit register that acts as temporary storage for the current contents of the P register when P is used for other purposes. For example, the P register holds the effective memory address yielded by an MRG when the fetch of the operand occurs and the PSAVE register holds the old P (i.e., the next instruction fetch address). The PSAVE register is a transparent latch register which is loaded directly from the P register and can drive its output onto Bus 3. Because the information that the PSAVE register stores is an address, when reading PSAVE a 0 is driven onto Bus 3, bit 15.

The PSAVE register is not accessible to the programmer.

2.4.2.10 Memory Protect Fence Register

The memory protect fence register is used to define the first word of unprotected memory in the L-Series computer system. All locations greater than or equal to the address stored in the fence are unprotected. The fence is loaded from the A register by the instruction OTA 7 (note that this is specifically not OTA 7,C).

In the L-Series computer system, the fence consists of the 16-bit memory protect fence register and a comparator which looks at the contents of the register and the data on Bus 3. If the address on the bus is less than the value in the register, the signal ADVIO is generated. This signal is clocked into a storage flip-flop (BADVIO) whenever the P register is loaded. Thus, the output of this flip-flop indicates whether or not the address value currently in the P register is one which could potentially cause a violation.

2.4.3 ARITHMETIC LOGIC UNIT

The Arithmetic Logic Unit (ALU) is 16 bits wide and performs all the logical and arithmetic operations necessary for instruction execution. Operations are specified by control bits provided by the control structure and are as follows:

C1	C2	C3	C4	C5	CE	FUNCTION
1	0	0	X	0	0	PASS 2 (Pass Bus 2)
0	0	1	0	0	0	PASS 4 (Pass Bus 4)
0	1	1	X	0	0	NEGATE (Bus 4)
1	0	1	X	1	0	AND
1	0	1	1	0	0	OR
1	0	1	0	0	0	XOR
1	0	1	0	0	1	ADD
1	1	1	0	0	1	SUBTRACT (Bus 2 - Bus 4)
0	0	1	0	0	1	INCREMENT (Bus 4)
1	1	0	0	0	1	DECREMENT (Bus 2)
0	1	1	X	0	1	COMPLEMENT (2's - Bus 4)

The ALU generates the Carry Out (COUT) signal if the operation (ADD, SUB, INC, DEC, COMP) generates a carry from the Most Significant Bit (MSB).

2.4.4 STATUS LOGIC

The status logic is random logic used to control the contents of the E and O registers, and to control incrementing of the P register as needed when executing instructions which cause a skip. In addition, the ALU generates the signals ONES and ZEROS if the ALU output is all ones (177777B) or all zeros (000000B), respectively. These are used by the status logic to cause ASG instructions and the ISZ instruction to skip as well as by the state machine for the DIV instruction.

The function to be loaded into the E register is determined by three encoded signals GE1, E2, and E3. These signals specify one of eight operations; they are decoded by the E register in the status area of the CPU. The functions specified by these signals are:

GE1	E2	E3	FUNCTION
0	0	0	NOP
0	0	1	Load E register depending on IR bits 6 and 7 (PE3, CME, CLE, CCE in ASG).
0	1	0	Load E register with the appropriate bit of Bus 2 if an SRG shift with E.
0	1	1	Invalid code.
1	0	0	Load E register with carry out of ALU.
1	0	1	Load E register with control word register, bit 0.
1	1	0	Clear E register if IR5, otherwise a NOP.
1	1	1	Invalid code.

The O register is controlled in a similar fashion by signals OVf1, OVf2, and OVf3. The functions specified are:

OVf1	OVf2	OVf3	FUNCTION
0	0	0	NOP
0	0	1	Clear overflow.
0	1	0	Invalid code.
0	1	1	Clear overflow.
1	0	0	Set O if current ALU operation causes an overflow.
1	0	1	Set overflow.
1	1	0	Set O if current ALU operation causes an overflow.
1	1	1	Set O if B215 + B214 is true, otherwise NOP.

2.4.5 CONTROL STRUCTURE

The CPU control structure is implemented by a synchronous state machine (see figure 2-6). The machine consists of a next state Custom Logic Array (CLA) and associated next state register. These two elements maintain the state of the machine. Corresponding to each state are outputs which are generated by the output CLA. Instruction decoding is performed by the instruction register CIA and IR logic.

2.4.6 NEXT STATE CLA

The next state CLA computes the next state of the CPU based on the present state and various external inputs. The exact next state is generated in one of two forms: it is generated explicitly and loaded into the state register, or the signal INC is generated which causes the register to be incremented. Due to the circuit used to implement the CLA, terms cannot be shared among output functions. Thus, there is one CLA term required for every logic one in each output vector from the CLA. In the general case, then, if a state transition can be made from the present state by incrementing the value in the state register, then only one term is required for that function regardless of how many ones there are in the resulting vector.

2.4.7 NEXT STATE COUNTER/REGISTER

This 6-bit register provides the state storage for the machine. It is clocked on the falling edge of INTCLK and either loads or increments depending on the state of the signal INC. When enabled to increment, the register acts as a synchronous counter.

The carry in to the incrementer is normally high, and when selected the state gets incremented by one. In one case, however, it is necessary to stall the state counter for one state to accommodate a large propagate delay path. In this case, the carry in is zero, the increment adds zero, and the state does not change. The carry in to the incrementer is from a flip-flop clocked on the same edge as the state counter. This flip-flop outputs data ones from the next state CLA.

2.4.8 OUTPUT CLA/OUTPUT CLA LATCHES

The implementation of the output CLA is the same as that of the next state CLA, and, like the next state CLA, the output CLA does not share terms.

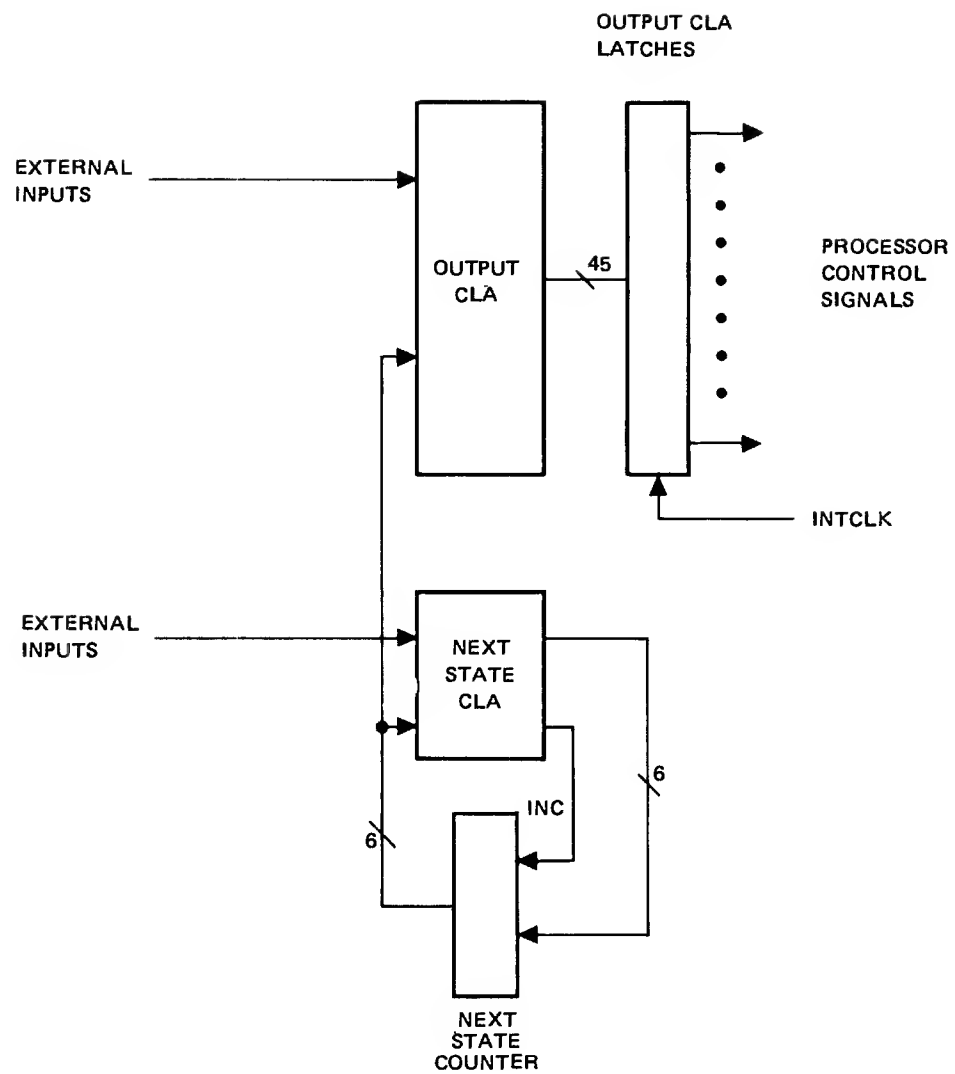


Figure 2-6. CPU Control Structure

The output CLA monitors the contents of the next state register and external (to the state machine) inputs and determines what control signals are necessary for the operation of the data path elements during the next state. The output CLA outputs are stored in latches in order to provide an orderly transition from one state's control signals to the next. The output CLA latches pass data when the INTCLK signal is high.

2.4.9 INSTRUCTION REGISTER CLA

The instruction register CLA performs high level instruction decoding by encoding into four blocks, as follows:

MRG (not A/B addressable)

MRG (A/B addressable)

ASG, SRG, I/O

Extended Arithmetic Unit (EAU)

The instruction register CLA also decodes certain low select code (0 - 7) I/O instructions which are used to control functions within the CPU (i.e., load memory protect fence, clear overflow, etc.).

2.4.10 CPU TIMING

The CPU timing is controlled by a 454 nsec period clock called INTCLK. INTCLK has a 40 percent duty cycle and is illustrated in figure 2-7. This clock defines the basic state time of the processor. Conceptually, a state starts with the rising edge of INTCLK and ends on the following rising edge. Due to the magnitude of the system delays, however, preparation for the current state occurs in the previous state (see figure 2-7).

In figure 2-7, point A marks the beginning of the previous state. The output CLA latches are transparent and the control signals for this state are asserted. Propagation delays through the next state CLA dictate that in order to make a state branch after the current state, all inputs to the next state CLA must be stable at this point.

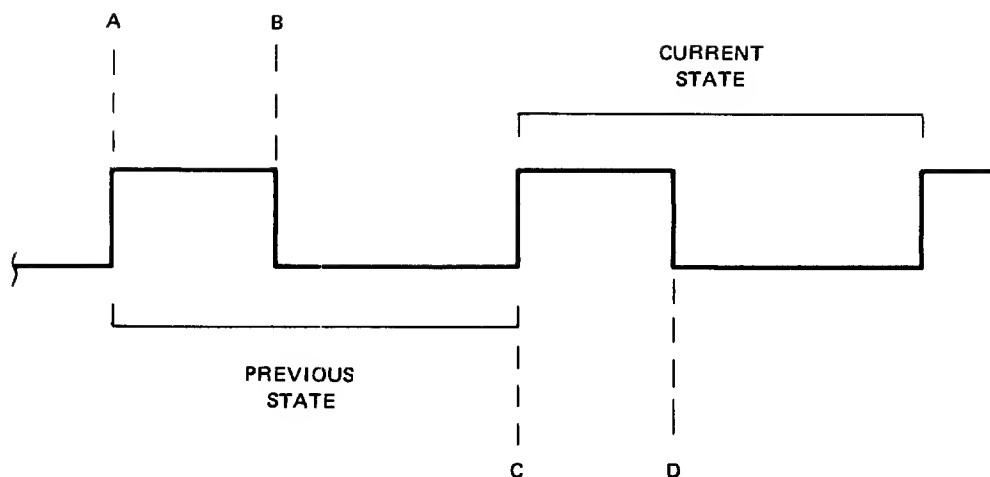


Figure 2-7. INTCLK Clock Timing Diagram

Point B marks the "middle" of the previous state. It is here that P, PSAVE, memory protect fence, and the control word register are clocked and the instruction register latches its data. Also, the next state CLA, given the values of the state variables corresponding to the previous state and the external inputs, has generated the appropriate signals to control the next state counter. Recall that this means that either the explicit values for the state variables corresponding to the current state or the signal INC have been generated. The falling edge of INTCLK loads the appropriate value into the next state counter. Note that the CPU still acts as if it is in the previous state because the defining signals (the outputs of the output CLA latches) remain unchanged. With the appearance of the new state variables at the next state counter's outputs, the output CLA begins generation of the control signals necessary to implement the current state. At this point, the synchronizing flip-flops for the signals PON, INT, and SLAVE are clocked. INT and SLAVE are not clocked in states A and B.

2.4.11 STATE DIAGRAM

The operation of the CPU is illustrated by the state diagram shown in figure 2-8. The basic blocks of this state diagram are shown in figure 2-9. Each state is represented by the rectangle shown in figure 2-9A. The state is denoted by one or two letters, which in the state diagram will replace i in figure 2-9A (e.g., state A is indicated by Ta). The rectangle is partitioned into four parts, corresponding to four groups of signals, and any signal that appears in the rectangle always occurs when the machine is in the state. The upper right partition contains all bus control signals, such as R/W, B23, etc. The lower right partition indicates all register controls, such as RDA, INCP, LDPS, etc.

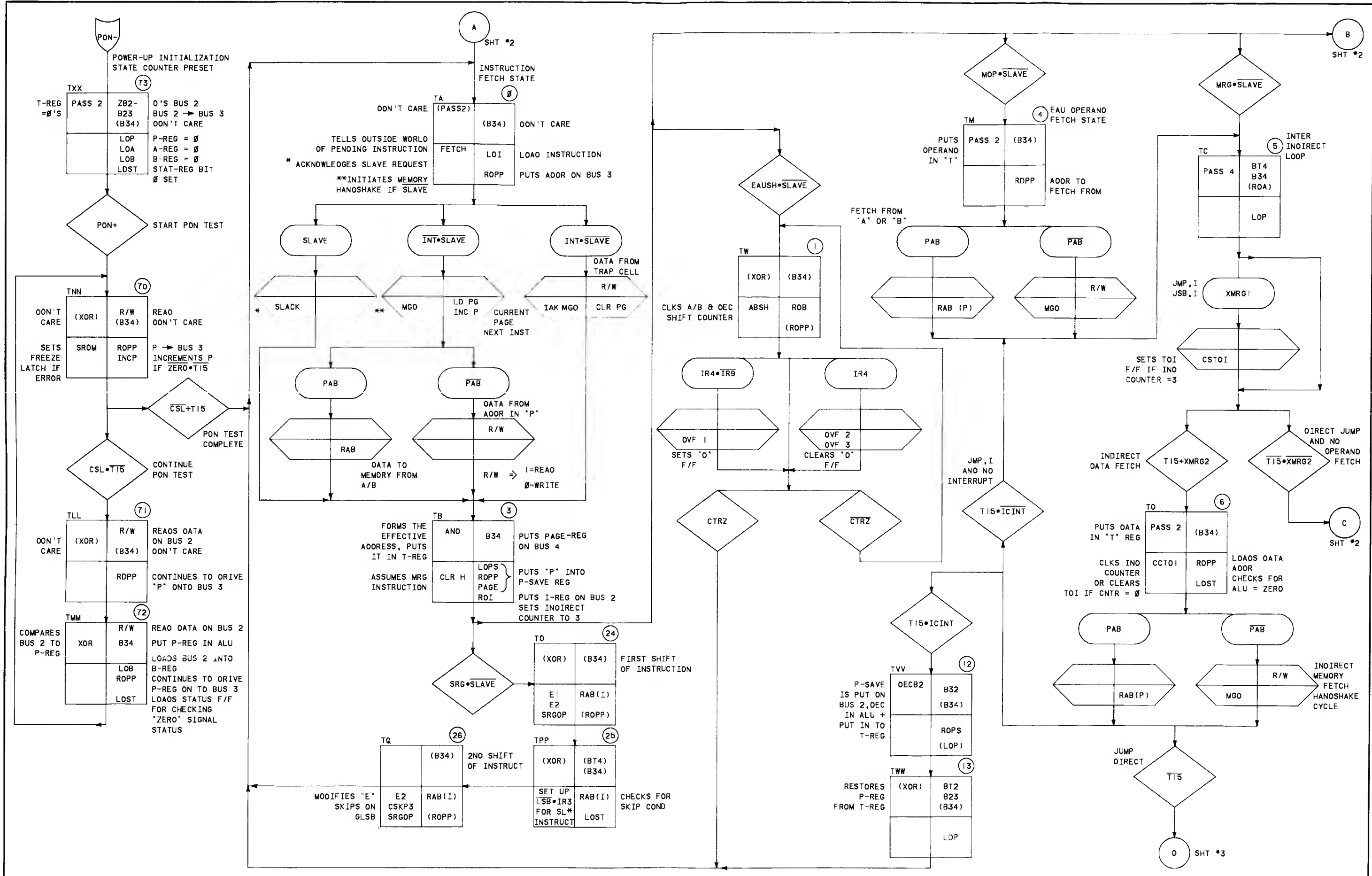
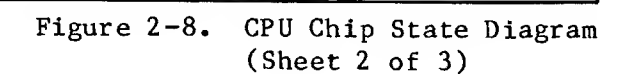
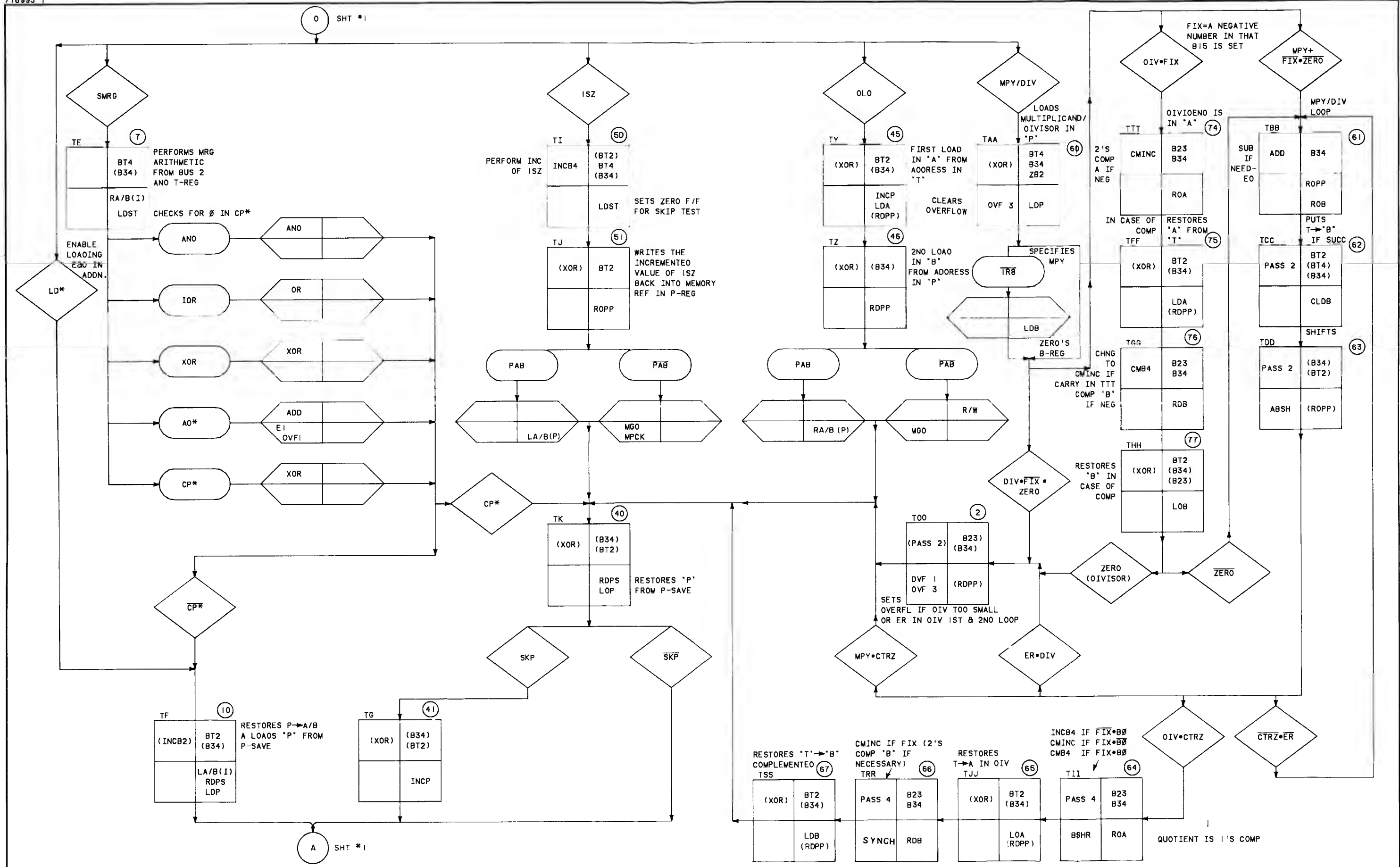


Figure 2-8. CPU Chip State Diagram
(Sheet 1 of 3)



Figure 2-8. CPU Chip State Diagram
(Sheet 3 of 3)

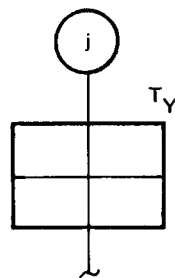
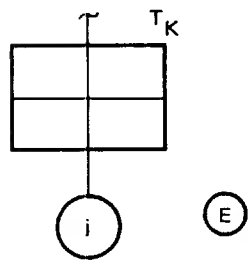
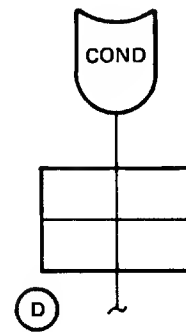
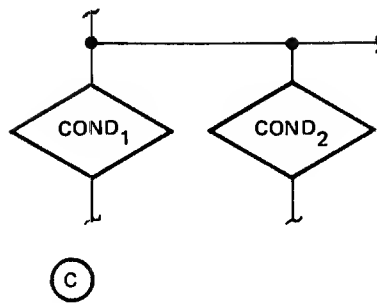
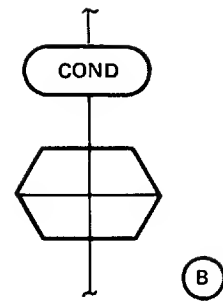
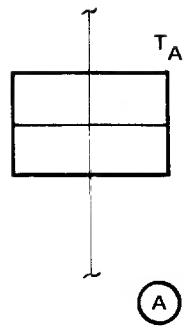


Figure 2-9. State Diagram Blocks

The lower left partition is for miscellaneous control signals; and the upper left partition indicates the ALU function in the state, which, if empty, is a don't care.

The hexagonal structure in figure 2-9B indicates signals that are active in a state only if the signal COND in the oval is true by point B (the middle) of the previous state. The structure in B always directly follows a rectangle, and its signals are conditional in the state of the rectangle so the hexagon has no state symbol. Note that although the hexagonal structures follow the rectangles in the state diagram, this in no way implies time sequencing; that is, conditional signals are asserted at the same time as control signals if their conditioning signal is true.

The diamond in figure 2-9C indicates a state branch condition from the state it follows. The branch is taken if the signal COND is true at point C of the state above the branch, and the set of branch conditions below any state must be mutually exclusive and collectively exhaustive.

Figure 2-9D shows a forcing condition. If COND is true, the state counter is forced to the state below the symbol. The machine remains in this state until the condition becomes false, at which time it enters the state following the forcing condition. All such structures must have conditions which are mutually exclusive.

The structure in figure 2-9E is used for connections from one part of the state diagram to another. There will be at least two such circles with the same letter for j, and they will thus be connected.

The state machine moves from state to state in the diagram as shown by the arrows, diverging at the branching points.

2.4.12 MEMORY PROTECT SYSTEM

The memory protect system provides the capability of protecting a selected block of memory of any size, from a settable fence address downward, against alteration by programmed instructions except those directly involving the A and B registers. Any programmed instruction except JMP may freely address the A and B registers as locations 00000 and 00001 (octal), respectively.

The memory protect logic, when enabled by an STC 07 instruction, also prohibits the execution of all I/O instructions except those referencing I/O select codes 01 and 03. This feature limits the control of I/O operations to interrupt control only. Thus, by programming the system to direct all I/O interrupts to an executive program residing in protected memory, the executive program can have exclusive control of the I/O system.

The memory protect logic is disabled automatically by any interrupt (except when the interrupt location contains an I/O instruction) and must be re-enabled by an STC 07 instruction at the end of each interrupt subroutine.

Programming rules pertaining to the use of memory protect are as follows (assuming that an STC 07 instruction has been given):

- a. Location 00002 is the lower boundary of protected memory. (Locations 00000 and 00001 are the A and B register addresses.)
- b. JMP instructions may not reference the A or B register directly; however, a JSB instruction may do so, and JMP A,I and JMP B,I are legal.
- c. The upper boundary (memory address) is loaded into the fence register from the A or B register by an OTA 07 or OTB 07 instruction, respectively. Memory locations below but not including this address are protected. To execute an OTA 07 or OTB 07, the external logic must perform an I/O handshake with the CPU and pass it the control word 1010 for OTA 07 and 1011 for OTB 07.
- d. Assertion of the signal MPV+ will occur if a JMP, JSB, ISZ, STA, STB, or DST instruction either directly or indirectly addresses a location in protected memory, or if any I/O instruction is attempted (excluding those addressing select codes less than 10 octal). It is up to the processor card logic to generate an interrupt upon assertion of MPV+.
- e. Any instruction not mentioned in step d above is legal even if the instruction directly references a protected memory address. In addition, indirect addressing through protected memory by those instructions listed in step d is legal provided that the ultimate effective address is outside the protected memory area.

The signal MPF+ is asserted whenever the memory protect system is enabled and is used by I/O processors to inhibit execution of I/O instructions. If the instruction causing the memory protect violation is a JMP or JSB, the program counter will be loaded with the new value, and a subsequent JSB will not reveal the address of the violating instruction. If the violating instruction attempts to store into protected memory, the CPU will attempt the write, and it is left to the external logic to insure that no memory contents are altered. The CPU will inhibit execution of any special I/O instruction which causes a memory protect violation.

2.5 PROCESSOR CARD DETAILED THEORY OF OPERATION

The following paragraphs contain detailed theory of operation information for the processor card. Refer, as necessary, to the schematic diagrams (drawing numbers 12001-60001-51, 12001-60001-52, 12001-60001-53, and 12001-60001-54) located at the end of this section.

The processor card acts as an interface between the CPU chip and the L-Series backplane. It plays the role of an arbiter in determining whether the CPU or the I/O interface cards have control of the backplane address and data busses at any given time. This applies to memory accessing as well as interrupt servicing.

2.5.1 MEMORY ACCESSING

The CPU chip initiates all processor accesses to memory. The CPU chip informs the processor by using the MEM+, MGO-, and READ+ memory request signals. The processor card then waits 318 nsec, from the edge which caused the assertion of MEM+, to the assertion of MEMGO- on the backplane. U89.6 is output of the buffer which converts the CPU MEM+ signal to a backplane MEMGO- signal. An open collector buffer was used because any I/O interface may also drive MEMGO- in initiating a DMA cycle. The memory cycle delay (U96 and U105 located at 22A of drawing 12001-60001-52) is necessary to allow time for the address and data busses to be valid on the backplane at the start of a memory cycle.

The CPU chip access of memory may be further delayed if a memory cycle is currently in process due to concurrent DMA activity. U107.13 (at 23B of drawing page 52) determines the go-ahead condition for the processor to start a new memory cycle. Whenever MRQ- or BUSY- are asserted on the backplane, the processor cannot gain control of the backplane busses.

MGO- is used by the processor to set the mycycle flip-flop (U104 located at 25B of drawing page 52) whenever a memory cycle is requested by the CPU chip. Since concurrent DMA may pre-empt a CPU memory request, the processor must keep track of which memory cycles are the result of a processor MEMGO-.

READ+ is used by the processor to control the direction of data flow between the CPU and the backplane. For READ+ de-asserted, a write to memory is desired. U97 (located at 24B of drawing page 52) is an AND-OR-INVERT gate which generates the signal WRITE- for the three cases when it is desired for the processor to drive data onto the backplane data bus. A memory write is one of those cases. The second case involves placing the A or B register

contents on the backplane data bus during the second half of an OTA/B double handshake. The third case is that of an A/B instruction fetch in which the instruction to be executed must be placed on the data bus from "memory" locations 0 or 1, corresponding to the A or B registers respectively.

MEMGO- is the backplane signal used by the memory card or the processor card ROMs to begin a new memory cycle. MEMGO- is asserted at the start of the long half cycle but may be aborted prior to the start of the next short half cycle. For example, the processor card requests a memory cycle with MEMGO-, but MRQ- may be asserted by an I/O interface card, on the same edge of the clock as the MEMGO- assertion, to signal that a DMA memory request is being made. The processor card must yield to DMA by de-asserting MEMGO- as soon as possible.

There are two types of memory accesses. Access to RAM memory on the memory card is mutually exclusive of access to processor card ROM memory. Both DMA and the CPU may utilize the memory on the memory card, but only the CPU has the means for using the processor card ROMs. A backplane signal named MEMDIS- is used by the processor to disable the memory card while accessing ROM. MEMDIS- is asserted only during a processor MEMGO- so that DMA may continue accessing the memory card when the CPU is not accessing memory. The CPU chip determines which memory accesses are referencing ROM by asserting BTN- (boot ROM enable) when MGO- is asserted. The processor card uses BTN- in generating MEMDIS- to disable the memory card, to cause a powered-down ROM to become active, to enable the ROM data buffers, and to allow the ROM memory handshake logic (simulates the memory card's BUSY- and VALID- signals) to begin its sequence.

A long half cycle after the assertion of MEMGO-, the memory card or the ROM handshake logic will respond with the assertion of BUSY- to signal that the memory request has been honored. BUSY- will be asserted by the memory card for two clock cycles, unless a refresh cycle occurs during the current memory access. Concurrent refreshing will add one or two extra states to the duration of BUSY-. In the case of processor ROM accessing, BUSY- is asserted for three clock cycles to allow sufficient time for the 450nsec devices to access data.

During the last clock cycle of BUSY-, a signal called VALID- is asserted to indicate the presence of valid data on the rising edge of VALID-. This is true for both a memory read or an instruction fetch from either the memory card or the processor ROMs. VALID- is used by the processor card to generate the signal to clock the data-in register, to cause the assertion of MND+ (CPU memory cycle end) to inform the CPU chip that the requested data is ready, and to turn off the mycycle flip-flop.

The basic memory cycle begins with MEMGO- and leads to a response of BUSY- and VALID- from the memory card controller or from the processor ROM accessing logic. With the assertion of several other control signals, such as WRITE- and MEMDIS-, during the memory reference, many variations of the basic memory cycle may be created. The following paragraphs and timing diagrams will describe each of these variations. It will be assumed that the processor accesses to memory will occur immediately following a DMA cycle to show how

DMA and the processor interleave memory cycles. In the absence of DMA, the portions of the given waveforms left of the assertion of MEMGO- should be in their de-asserted or tri-stated levels.

2.5.1.1 Memory Data Read

Figure 2-10 is a timing diagram of the backplane signals for a memory data read initiated by the processor card. The processor sends the address to the memory card during the assertion of MEMGO-. Note that WE- (write enable) is de-asserted during MEMGO- to inform the memory card that data is to come from the memory card. WE- is the buffered version of WRITE- discussed above. The requested data is available at the rising edge of VALID-. If a parity error occurs during this memory read, the PE- (parity error) signal will be asserted during the time that data is valid on the backplane.

2.5.1.2 Memory Write Initiated by the Processor Card

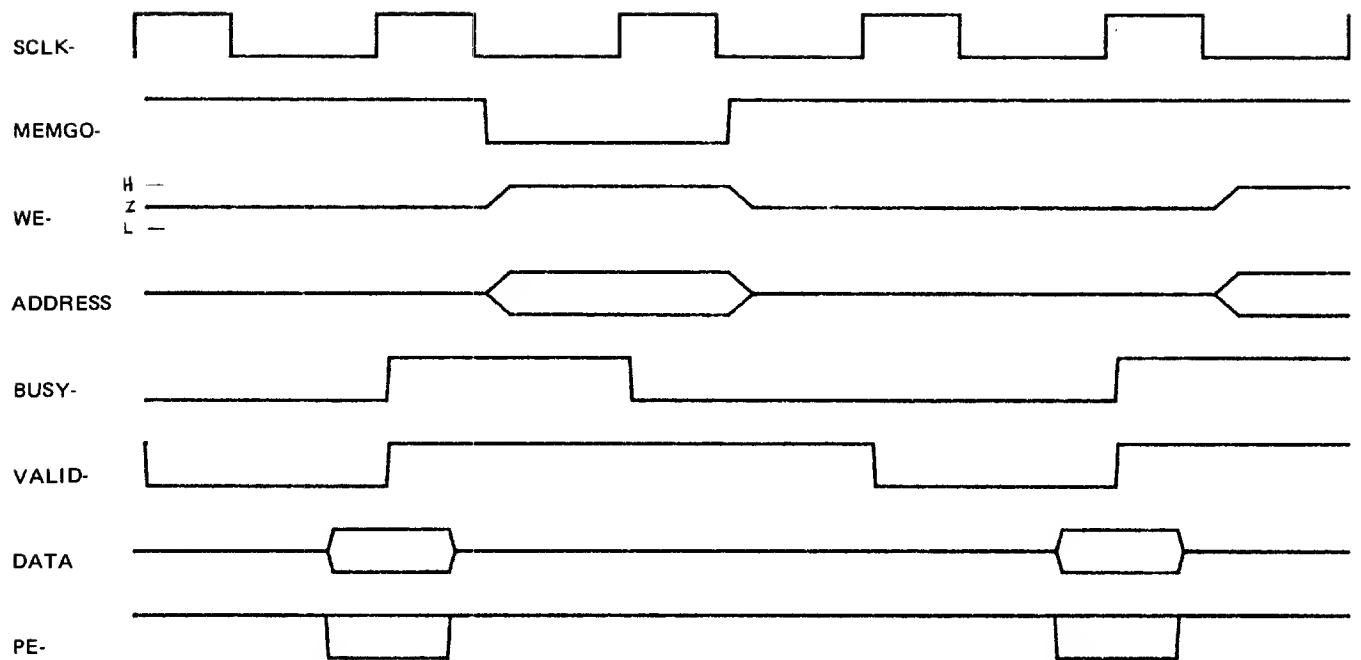
The backplane timing diagram for a memory write initiated by the processor card is shown in figure 2-11. In a memory write, the WE- signal is asserted and the data to be written into memory must be available on the backplane during MEMGO-.

2.5.1.3 Instruction Fetch from Memory

The backplane timing diagram for an instruction fetch from memory is shown in figure 2-12. The set of waveforms appear similar to that for a memory read except that the backplane signal RNI- (read next instruction) is asserted by the processor during the time that BUSY- is asserted. The RNI- signal is the bus-arbitrated form of the CPU chip's FCH- (instruction fetch) signal. Upon the assertion of RNI-, all I/O processors are forced to examine the data bus during that memory cycle to interpret the instruction.

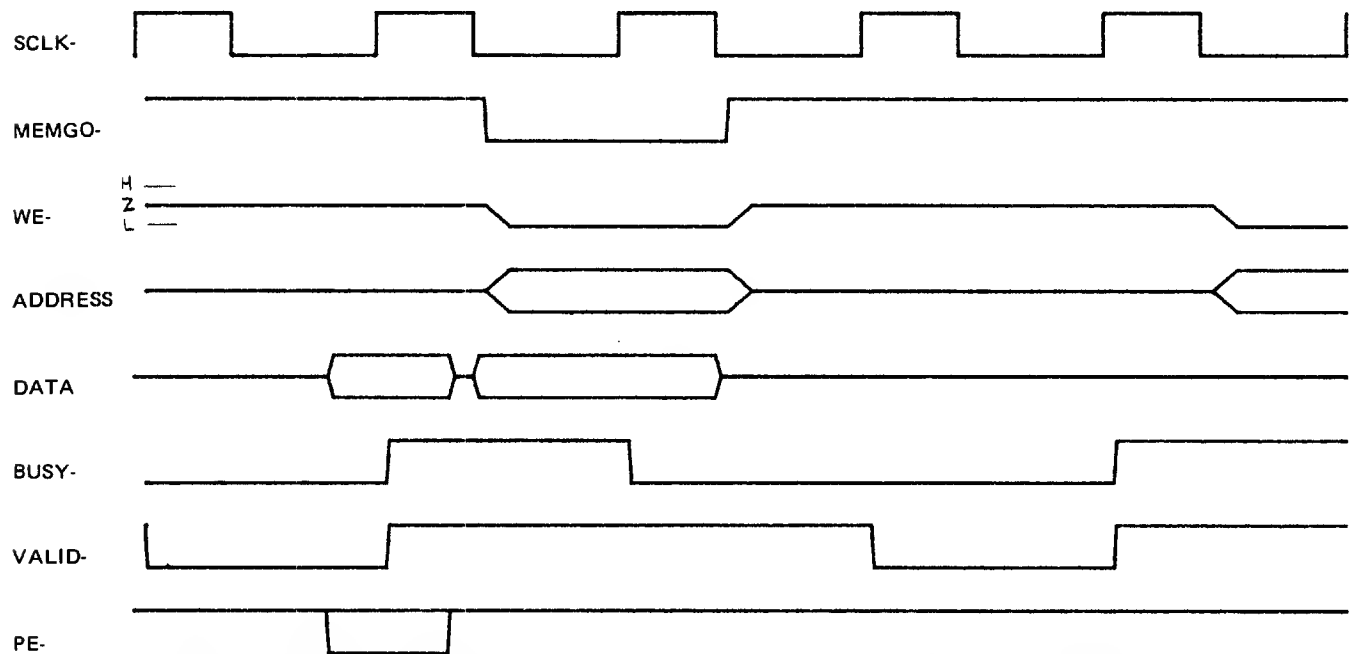
2.5.1.4 Instruction Fetch from the A or B Registers

Figure 2-13 contains the backplane timing diagram for an instruction fetch from the A or B registers. The A and B registers are treated as memory locations 0 and 1 respectively. If the program counter was pointing to either 0 or 1, the data in the A or B register will be treated as an instruction. In this case, neither the processor card ROMs nor the memory card is being



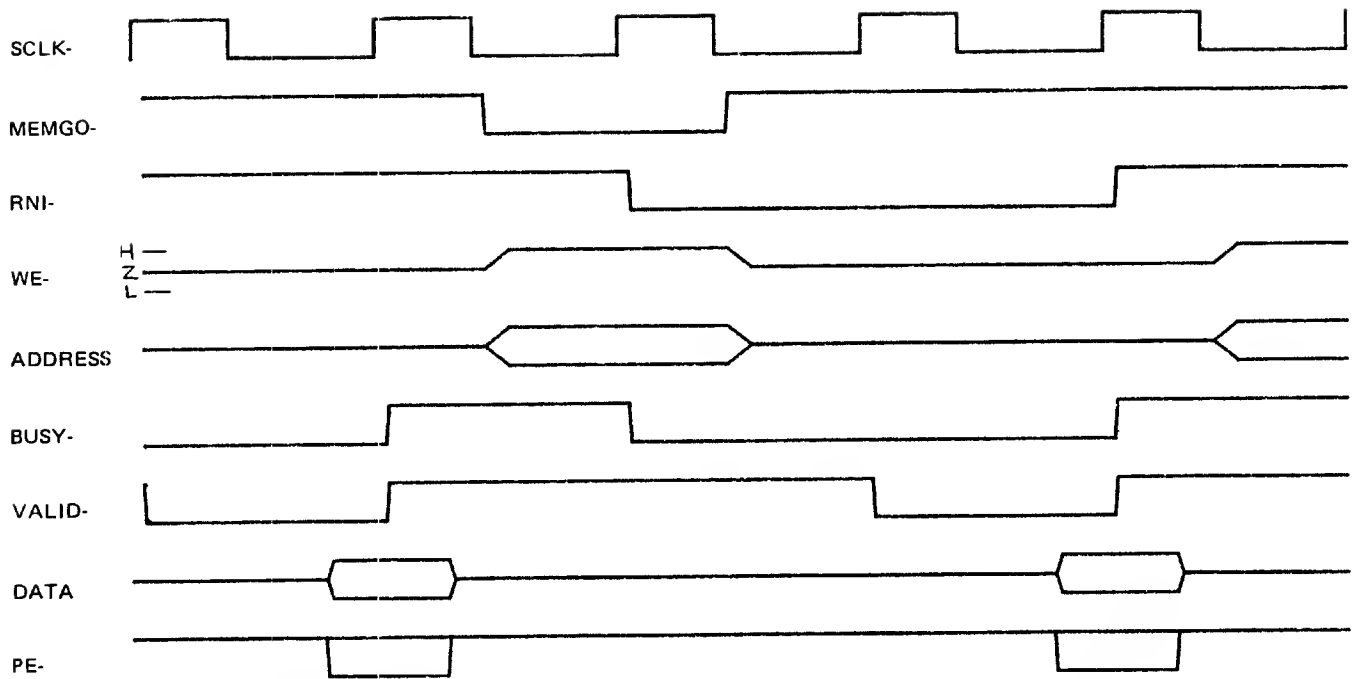
NOTES: MEMGO- occurs after completion of the current DMA cycle.
WE- is HI during MEMGO-.

Figure 2-10. Memory Read Initiated by the Processor Card



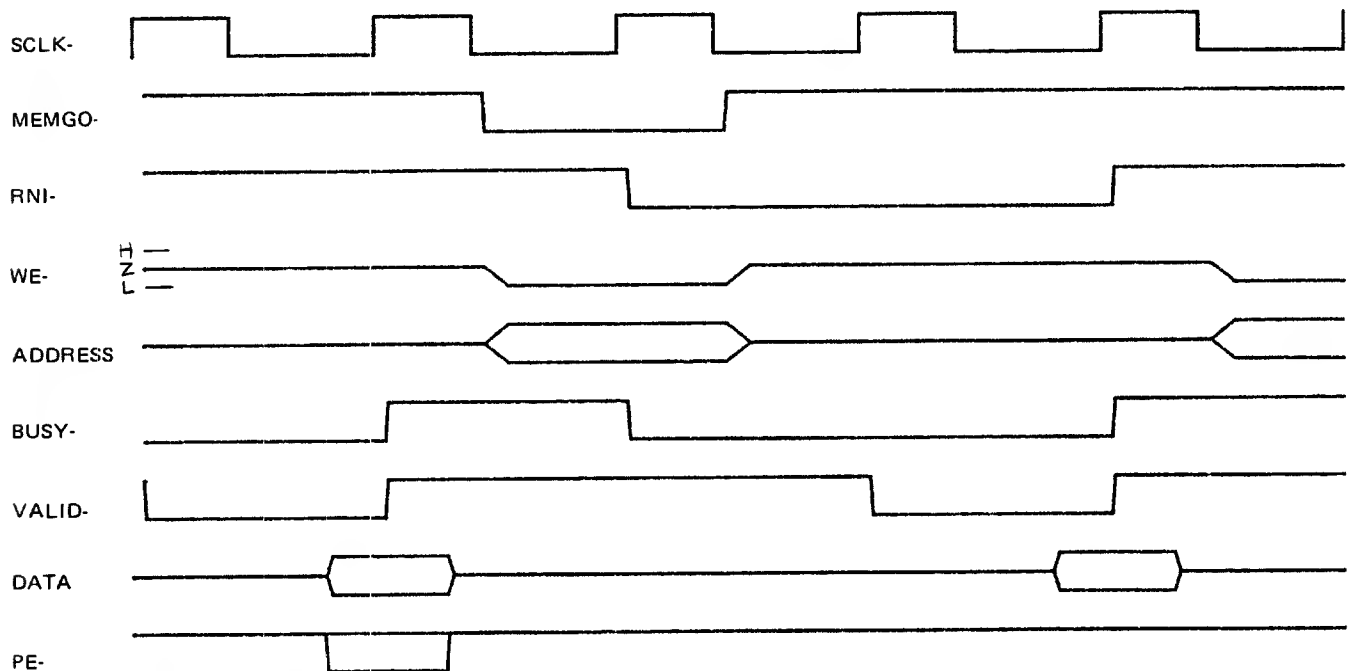
NOTES: MEMGO- occurs after completion of the current DMA cycle.
WE- is asserted during MEMGO-.

Figure 2-11. Memory Write Initiated by the Processor Card



NOTES: MEMGO- occurs after completion of the current DMA cycle.
RNI- asserted before and during VALID-.

Figure 2-12. Instruction Fetch from Memory



NOTES: MEMGO- occurs after completion of the current DMA cycle.
WE- asserted during MEMGO-. RNI- asserted before and during VALID-.

Figure 2-13. Instruction Fetch from the A/B Register

accessed so the problem arises as to how a memory cycle can be generated such that the I/O processors can treat an A/B instruction fetch like any other instruction fetch. To signal that an A/B instruction fetch is occurring, the CPU chip leaves its READ+ signal de-asserted while asserting FCH-. This forces the processor card to initiate a memory write into the memory card's locations 0 or 1. This action causes the appropriate memory handshake to be generated. Since the memory card does not drive the data bus on the rising edge of VALID- for a memory write, the processor card will drive the contents of the A or B register onto the backplane data bus at that time. Since RNI- has been asserted during the entire memory cycle, the overall result appears just like a regular instruction fetch from memory.

2.5.1.5 ROM Data Read

Figure 2-14 contains the backplane timing diagram for a ROM data read. The backplane memory handshake resembles that of a memory read from RAM with the addition of the MEMDIS- signal. MEMDIS- prevents the memory card from responding to the current MEMGO-. The processor card generates MEMDIS- from the presence of BTN- at the CPU chip output.

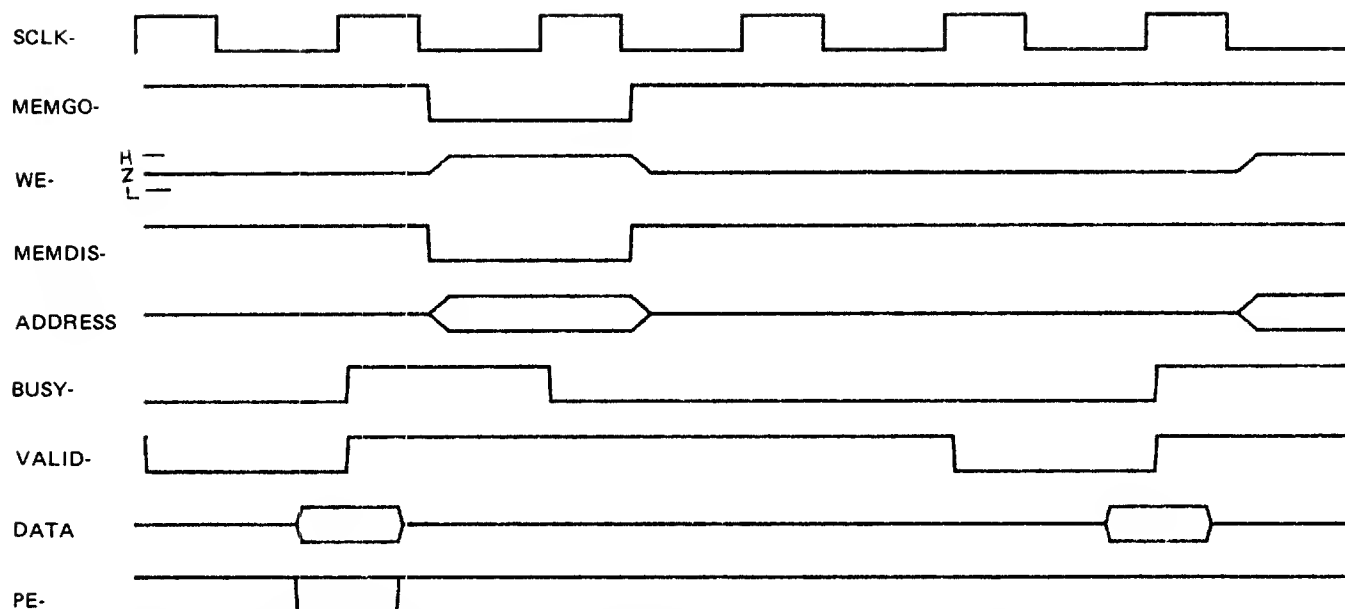
2.5.1.6 Instruction Fetch from ROM

The backplane timing diagram for an instruction fetch from ROM is shown in figure 2-15. The only difference between an instruction fetch from ROM and an instruction fetch from memory is the assertion of MEMDIS- during MEMGO-.

2.5.2 PROCESSOR MEMORY ACCESS AND DMA

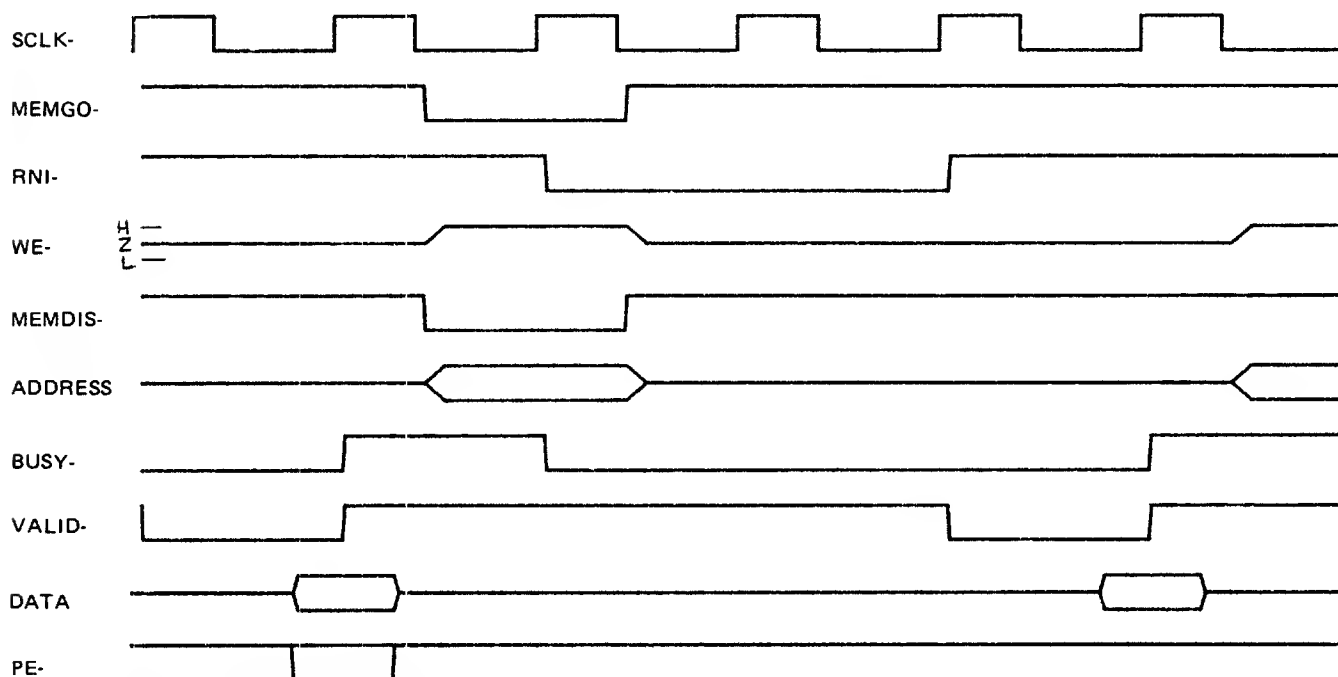
In normal operation, the processor card is the lowest priority memory requestor. It can only obtain a memory cycle when all pending DMA requests have been serviced. Thus, it is conceivable for the CPU to be frozen for long periods of time if considerable DMA activity was stealing every memory cycle from the CPU. Although no L-Series I/O interface card has a DMA bandwidth high enough to saturate the backplane memory bandwidth, several of these cards, each performing DMA, could monopolize the backplane. This condition is unfavorable in achieving reasonable interrupt latency or performing a power-fail routine before power goes down.

The processor card resolves this problem using a DMA memory cycle counter to force the I/O interfaces to give the CPU one memory cycle after a number of consecutive full-bandwidth DMA memory cycles. For example, suppose the CPU



NOTES: MEMGO- occurs after completion of the current DMA cycle.
MEMDIS- asserted during MEMGO-.

Figure 2-14. ROM Data Read



NOTES: MEMGO- occurs after completion of the current DMA cycle.
MEMDIS- asserted during MEMGO-. RNI- asserted before and during VALID-.

Figure 2-15. Instruction Fetch from ROM

just fetched an instruction not affecting the I/O interfaces. Shortly after the de-assertion of RNI-, the I/O cards will begin DMA memory cycle stealing. Suppose that every memory cycle was taken by DMA and that the processor wanted a memory cycle (for the operand of the current instruction or for the next instruction fetch) after the fifth DMA memory cycle. U73 (located at 25A of drawing number 12001-60001-52) is a dual four-bit binary counter hardwired to signal that thirty-two consecutive DMA memory cycles has occurred since the CPU desired a memory cycle. At that time, a signal called CPUTURN- is asserted on the backplane to command the I/O processors to grant a memory cycle to the CPU. The counter is reset after the CPU is granted the memory cycle. In addition to this special case, CPUTURN- is also asserted with every instruction fetch, at the same time as RNI-.

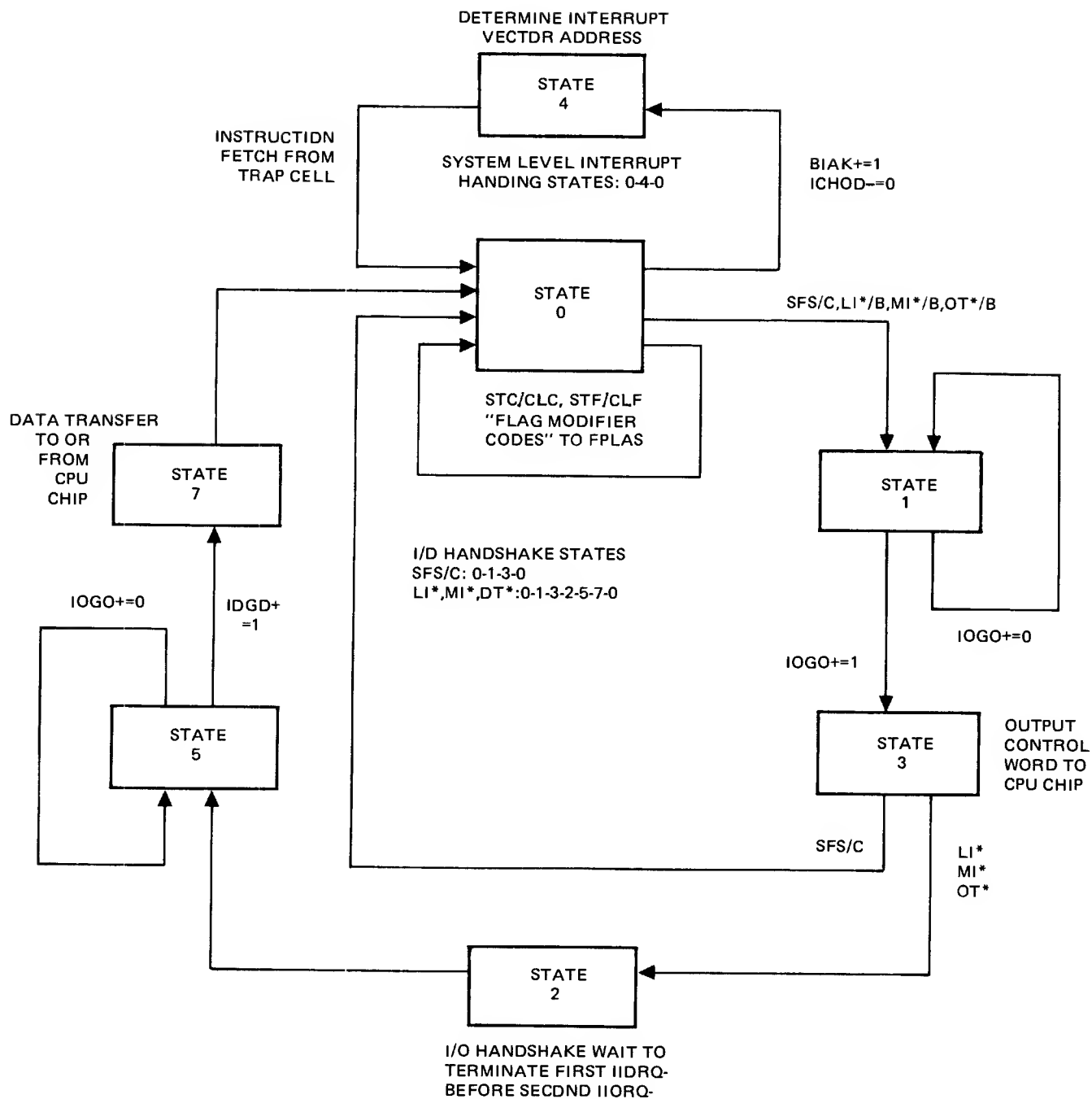
2.5.3 I/O STATE MACHINE

Management of many of the low select code I/O functions centers around four field programmable logic arrays (FPLA's). These IC's are U13, U15, U33, and U35 on drawing number D-12001-60001-53. U35 performs instruction decoding, determines interrupt priorities, generates the next machine state, and outputs commands to control other IC's. U33 and U13 form a large register which stores flag status information for the low select codes. The flags in these two FPLA's are changed generally in response to a "flag modifier code" generated by U35 and transmitted over the five bit processor I/O control bus (QD0-4). U15 is the interrupt status FPLA which determines if a pending interrupt may become an interrupt request.

The processor card has an eight bit instruction register which contains enough bits to identify the type of I/O instruction to be performed and the select code affected. Like the instruction register in the CPU chip and on the I/O interface cards, this register is updated with every instruction fetch. The instruction is passed to the master FPLA U35 through data selectors. The output of these data selectors is typically the contents of the instruction register except during interrupt processing. Thus, half of the inputs to the master FPLA are devoted to examination of the instruction.

While monitoring the instruction stream, the master FPLA determines whether a low select code flag is to be altered or an I/O handshake is required to interact with the CPU chip. Instruction decoding always occurs when the present state of the FPLA sequencer is in state zero (S2,S1,S0 state variables = 000). Register U53 is clocked with SCLK+, making the master FPLA U35 a synchronous state machine with three state variables and five output variables. This FPLA is coded such that the the odd states (where S0=1) are the I/O handshake states.

Suppose a STC/CLC or STF/CLF instruction appeared during the course of program execution. Since only the least significant three bits of the select code are revealed to the master FPLA, the state machine does not have the ability to



NOTES: IIDRQ- IS ASSERTED DURING ODD STATES (1, 3, 5, 7)
 THE FPLA STATE MACHINE ON THE PROCESSDR CARD ONLY
 HANDLES CERTAIN INTERRUPTS AND I/O INSTRUCTIONS OF
 SELECT CODE 17 OCTAL OR LESS

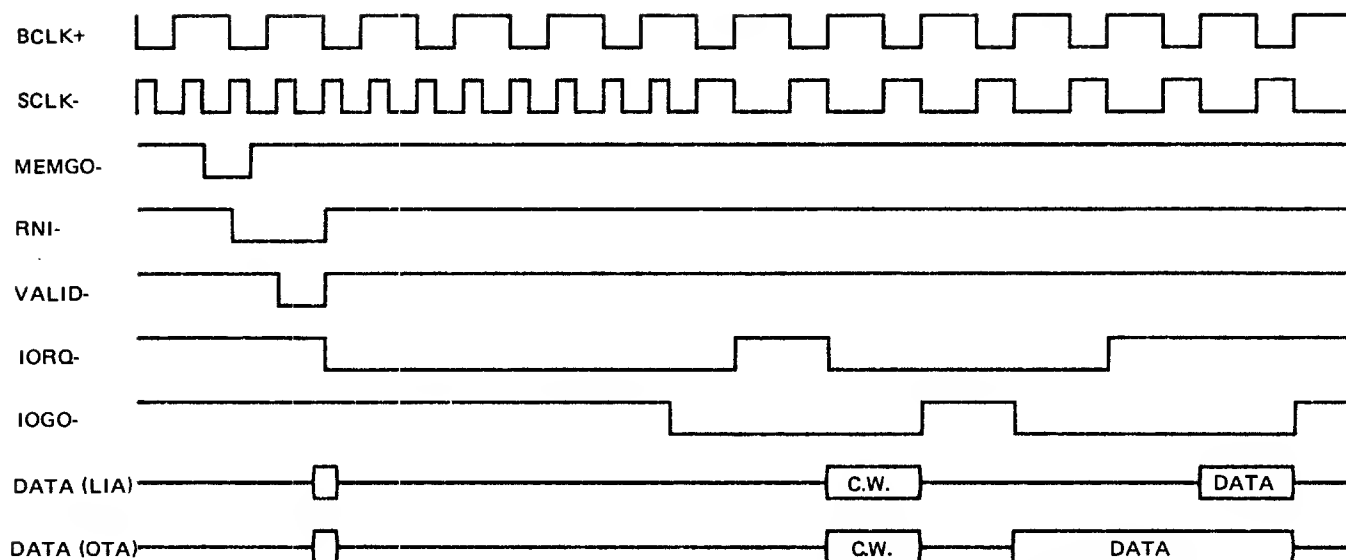
Figure 2-16. State Transition Diagram for FPLA U35

decipher whether or not the I/O instruction affected select codes 0-7 octal or 10-77 octal. Since the CPU chip has a complete 16-bit instruction register, it is able to identify whether select codes 0-7 are affected, and if so, it asserts the IOG+ control signal to the processor card I/O state machine. Following the assertion of IOG+, the state machine examines the STC/CLC or STF/CLF instruction and places a "flag modifier code" on the QD bus to update the appropriate status flag in the low select code flag status FPIA's U13 and U33. The state machine remains in state zero.

As soon as the master FPIA receives a SFS/SFC instruction, it requests flag status information from the flag status FPIA's. FPIA U13 responds by sending a logic "1" to the master FPIA via the FLG+ signal if the appropriate flag is set. The master FPIA utilizes this bit of information to determine if the conditional skip is true. If a skip is to be performed, the master FPIA makes a transition to state one after receipt of IOG+ from the CPU chip. Since state variable S0 is now a 1, IIORQ-, the I/O handshake request to the CPU, gets asserted. The state machine idles in state one until it receives IOGO-, the I/O handshake acknowledgement signal from the CPU chip. The state machine proceeds to state three, at which time it sends the "INC P" (increment program counter) control word to the CPU chip to implement the skip. The state three condition is decoded by a 3 to 8 decoder U52 and is used to enable the control word onto the data bus one cycle later. The state machine returns to state zero, which effectively removes IIORQ-.

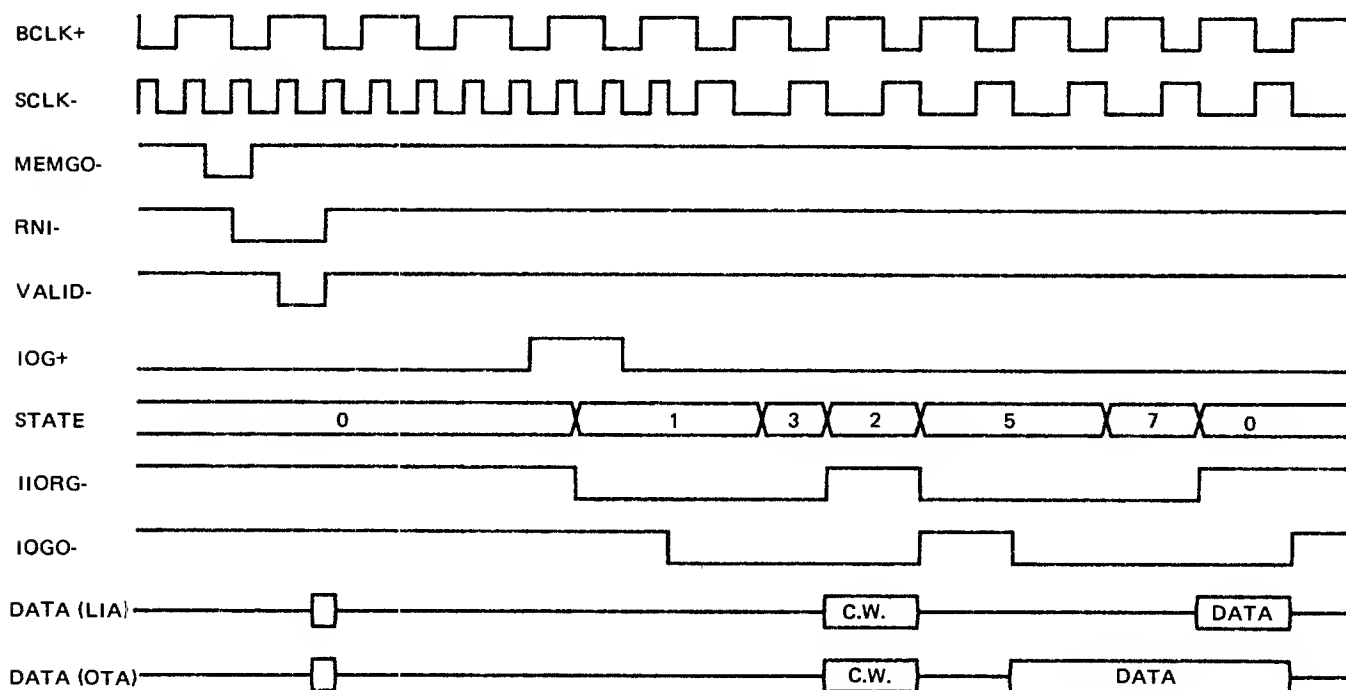
Instructions such as LIA/B, MIA/B, and OTA/B for the low select codes involve data transfers between the A or B registers in the CPU chip and data registers on the processor card or global registers on the I/O interface cards. For these instructions, the first IIORQ-/IOGO- handshake proceeds in the same fashion as for a true conditional skip except that a different control word is passed to the CPU chip. That control word will inform the CPU chip of the direction of the data transfer and what to do with the data if the A or B register is the destination of the transfer. To implement the double handshake, the state machine makes a transition from state three to state two instead of going to state zero. It remains in state two for one cycle of the clock before going on to state five to re-assert IIORQ-. After an IOGO-response is received, the state machine proceeds to state seven for one clock cycle before returning to state zero. If the instruction was an LIA/B or MIA/B, the master FPIA would direct the register selector U22 (3 to 8 decoder) to enable the output control of the appropriate register during the second half of the double handshake. For an OTA/B instruction, another 3 to 8 decoder (U23) serves to generate the latch signal for the appropriate processor card register to load data from the address bus at the end of the second I/O handshake.

Refer to figure 2-17 for a timing diagram showing the backplane I/O handshake protocols between an I/O interface card and the CPU. The state transition of the processor card I/O state machine is shown in the time domain in figure 2-18. The backplane protocols for an I/O handshake are the same for either case. Note how the state machine transitions relate to the other signals.



NOTES: For a true conditional skip, omit the second set of IORQ-/IOGO- handshakes.

Figure 2-17. I/O Handshake for an OTA/B, MIA/B, or LIA/B Instruction



NOTES: For a true conditional skip, omit the second set of IIORG-/IOGO- handshakes.

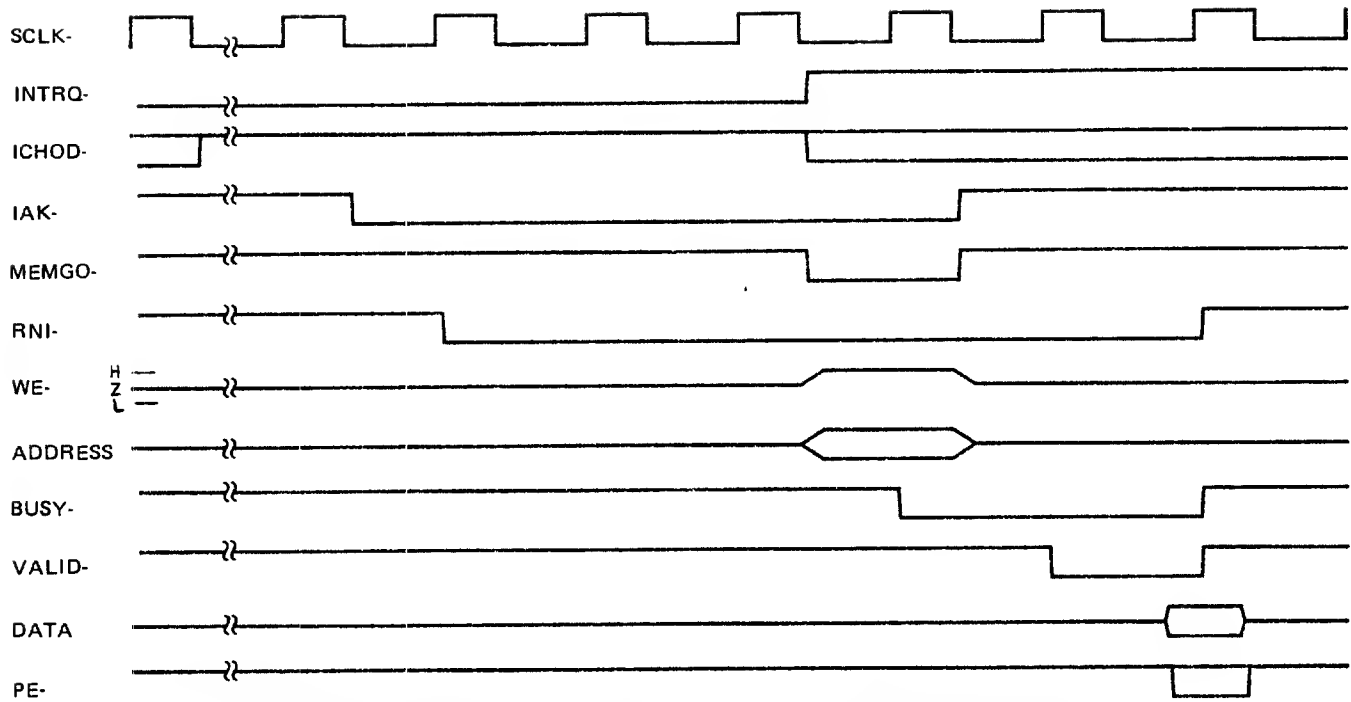
Figure 2-18. I/O Handshake for an I/O Instruction Handled by the Processor

During an I/O handshaking process, the backplane clocks SCLK- and FCLK- are reduced in frequency to match that of the CPU chip's clock. Since the CPU chip expects data transfers to occur relative to its own clock, all external clocks must be identical to the CPU chip's clock during the course of an I/O handshake. A detailed discussion of the L-Series clocks appear in section 2.5.6.

The master FPIA also handles interrupt processing for all system level requests. When an interrupt is acknowledged by the CPU, the master FPIA begins to examine the pending interrupts rather than interpret instructions. Data selectors U25 and U24 are used to switch between instruction and pending interrupt information. The state machine goes to state four to determine the highest priority pending interrupt and generate the vector address at which interrupt servicing begins. The presence of state four is detected by U52 (3 to 8 decoder) and is used to enable the interrupt address onto the backplane at buffers U19 and U28 (see drawing D-12001-60001-51) and to assert MEMGO- to begin the memory cycle. The state machine returns to state zero after one clock cycle at state four.

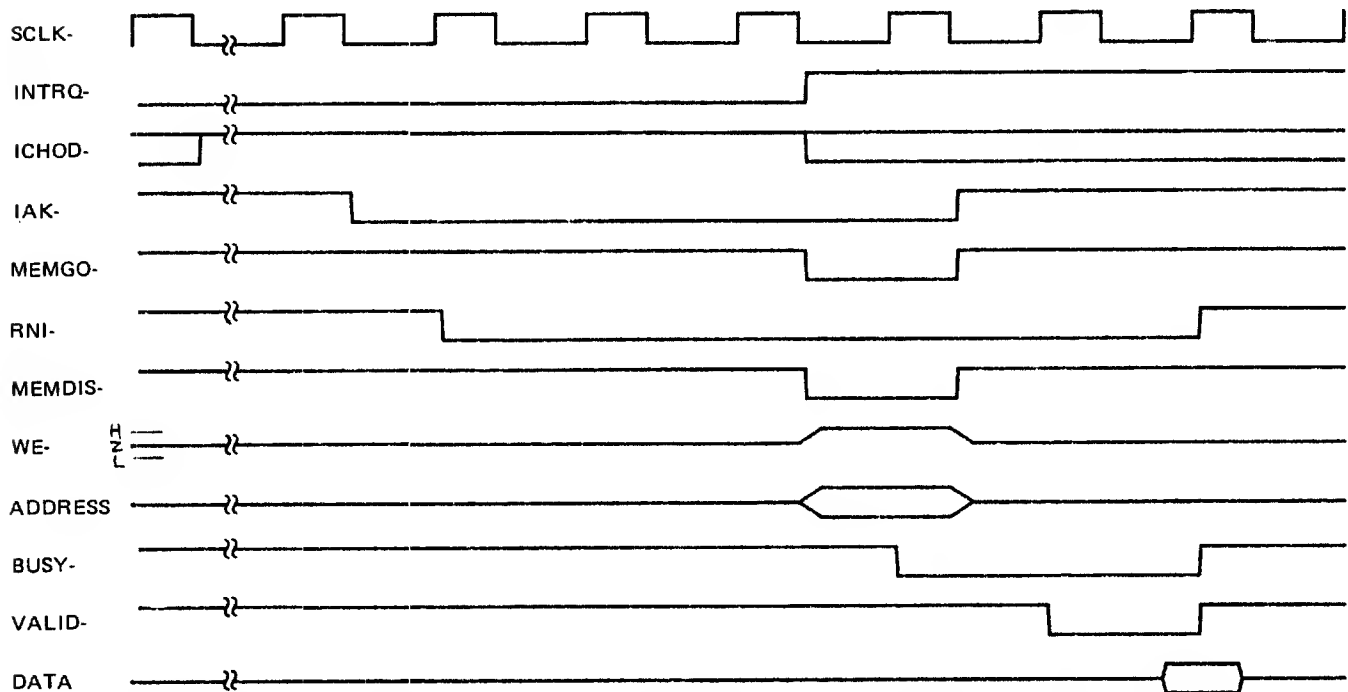
Figure 2-19 shows an I/O interrupt serviced with the trap cell fetch from main memory. INTRQ- (interrupt request) is asserted by an I/O interface card to request an interrupt. When IAK- (interrupt acknowledge) is received by the I/O card and ICHOD- (interrupt disable output of the next highest priority I/O card) is de-asserted, that I/O card will assert MEMGO- and drive its select code onto the address bus as the vector address of the trap cell fetch. This memory cycle is an instruction fetch because the processor card has provided for the assertion of RNI- on the backplane. Figure 2-20 is a timing diagram for an I/O interrupt service from processor card ROM. The only difference is that MEMDIS- is asserted on the backplane to disable main memory during this memory cycle.

Figure 2-21 is a timing diagram for service of a system level interrupt from main memory. There are no backplane interrupt requests because all of the system level interrupt requests are generated by the processor card. When IAK- appears on the backplane, it is accompanied with the assertion of ICHOD- by the processor card. This disables the highest priority I/O interface card from responding to IAK-, which in turn, effectively disables all I/O cards from responding because of the interrupt priority chain. One clock cycle after the master FPIA goes into state four, a signal called VAEN- (vector address enable) is asserted. State four is decoded by U52 (located at 32B of drawing 12001-60001-53), then delayed one clock cycle by U42 (located at 33B of the same drawing), then becomes VAEN-. The vector address is determined by the master FPIA during state four but is not available on the QD bus until the following clock cycle. The VAEN- signal is used to cause the assertion of MEMGO- and to simultaneously enable the vector address buffers onto the backplane address bus. The memory cycle is an instruction fetch since RNI- is also asserted. Figure 2-22 shows the timing diagram for the service of a system level interrupt from ROM.



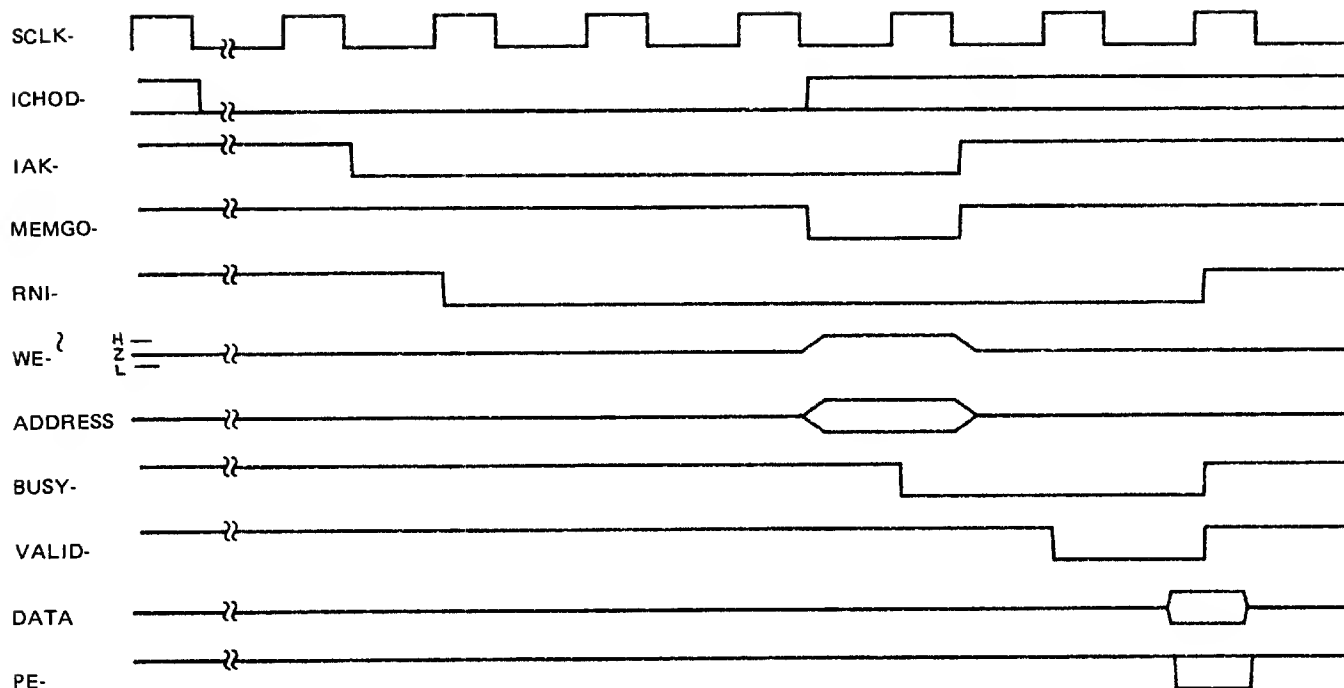
NOTES: ICHOD- is de-asserted so that the interrupting I/O card can assert MEMGO- and provide the vector address (its select code) following the assertion of IAK-.

Figure 2-19. Service of an I/O Interrupt



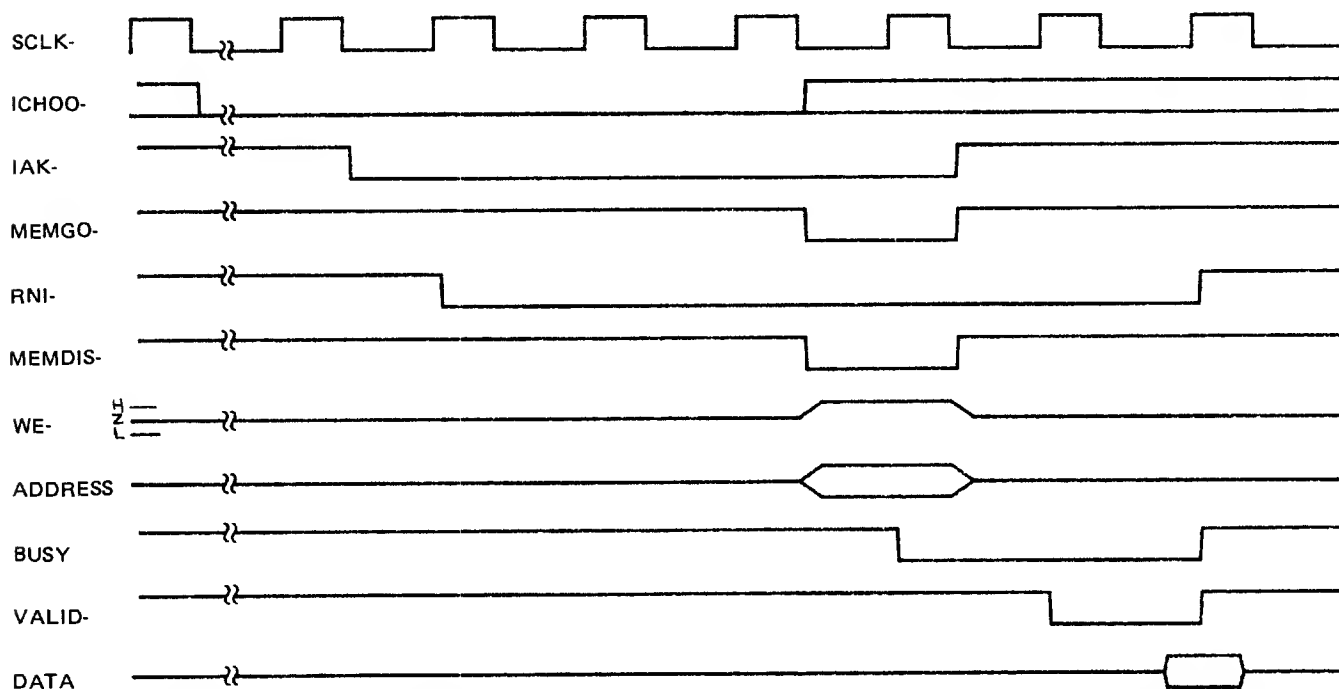
NOTES: Same as above except that MEMDIS- is asserted to select ROM.

Figure 2-20. Service of an I/O Interrupt in ROM



NOTES: ICHOD- is asserted to disable I/O cards from responding to IAK-. The processor card asserts MEMGO- and provides the vector address.

Figure 2-21. Service of a System Level Interrupt



NOTES: Same as above except that MEMDIS- is asserted to select ROM.

Figure 2-22. Service of a System Level Interrupt in ROM

FPLA's U33 and U13 contain the low select code flag status information. The master FPLA executes the STC/CLC and STF/CLF instructions by generating five-bit codes informing U33 and U13 how to modify one of their status flags. Flag status can only be altered during state one when EN+ is high, corresponding to the short half cycle of SCLK+. Some flags may be altered at any time in response to directly hardwired signals. A summary of the operation of the flag status FPLA's U33 and U13 appears below.

The flag information contained in U33 is:

PSFF+ = parity system on or off
 **ON by CLC 0 or STC 5
 *OFF by CLC 5 or on power-up or immediately after parity error during CPU access to memory

FRZM- = freeze memory protect violation address register
 **OPEN LATCH by STC 7
 *CLOSE LATCH by CLC 7 or on power-up or immediately after a memory protect violation that is not a result of a parity error

PMPI+ = pending memory protect interrupt
 *****SET by memory protect violation that is not a result of a parity error
 *CLEARED on interrupt service to vector address 7 (memory protect violation servicing) or CLC 0 or on power-up

IIFF- = interrupt inhibit flag
 ***INHIBIT by CLC 4 or on interrupt service to vector address 4 (power fail interrupt servicing)
 *UNINHIBIT by STC 4 or CLC 0 or on power-up

PECF- = parity error on CPU access to memory
 *****SET by parity error on CPU access to memory when the parity system is turned on
 *CLEARED on interrupt service to vector address 5 (parity error servicing) or CLC 5 or on power-up

UTIF+ = unimplemented instruction trap flag
 *****SET when CPU chip signals UIT which is not a result of a parity error
 *CLEARED on interrupt service to vector address 10 octal (unimplemented instruction servicing) or on power-up

PCRS+ = control reset (used to generate CRS- on backplane)
 ****ASSERTED only during CLC 0
 *DE-ASSERTED otherwise

CSP+ = clear special interrupt
*HI only on interrupt service to vector address 17 octal
 (to service special interrupt) or CLC 0 or on power-up
*LO otherwise

The flag information contained in U13 is:

STATE+ = delayed power fail warning

GEN+ = global register flag
**GR ENABLED by CLF 2
*GR DISABLED by STF 2 or CLC 0 or on power-up

PTST- = part one of self test (checks address and data bus integrity)
**ON at power-up
*OFF on the first instruction fetch by the CPU

PS- = parity sense flag
*LO, EVEN PARITY by STF 5
**HI, ODD PARITY by CLF 5 or on power-up

PTBI+ = pending time base generator interrupt
*****SET by STF 6 or TBT (time base tick from CPU every 10msec)
*CLEARED by interrupt service to vector address 6 (time base
 interrupt servicing) or CLC 0 or on power-up

PPFI+ = pending power fail interrupt
*****SET by assertion of PFW- by power supply
*CLEARED by interrupt service to vector address 4 (power fail
 interrupt servicing) or on power-up

ISFF+ = interrupt system flag
**ENABLED by STF 0
*DISABLED by CLF 0 or CLC 0 or on power-up

FLG+ = low select code flag set/clear detection
*HI if a) ISFF+ is HI (interrupt system enabled) when
 conditional skip refers to flag 0
 or b) GEN+ is HI (GR enabled) when conditional skip
 refers to flag 2
 or c) PFW+ is LO (AC power is good) when conditional
 skip refers to flag 4
 or d) PS- is LO (even parity) when conditional skip
 refers to flag 5
 or e) PTBI+ is HI (pending time base interrupt) when
 conditional skip refers to flag 6
*LO if none of the above cases are satisfied

FPLA U15 is responsible for determining if a pending interrupt request may become a qualified interrupt. Interrupt requests may be inhibited, disabled or masked off.

INT+ = interrupt request to CPU chip

*HI if a) PECF- is LO (parity error)
or b) UTIF+ is HI (unimplemented instruction)
or c) PMPI+ is HI (memory protect violation) and
IIFF- is HI (level 2 and 3 interrupts uninhibited)
or d) SPRQ- is LO (special interrupt request) and
IIFF- is HI
or e) PPFI+ is HI (power fail) and
IIFF- is HI and
TDI- is HI (interrupts not temporarily disabled)
or f) PTBI+ is HI (time base interrupt request) and
IIFF- is HI and
TDI- is HI and
ISFF+ is HI (level 3 interrupts enabled) and
interrupt mask bit 1 is LO
or g) INTRQ+ is HI (I/O interrupt request)
IIFF- is HI and
TDI- is HI and
ISFF+ is HI

*LO if none of the cases above are satisfied

SPINT+= the latched version of SPRQ- (special interrupt request)

*****SET by SPRQ-

*CLEARED by interrupt service to vector address 17 octal
(to service special interrupt)

ICHOD-= interrupt chain disable output

*HI if the interrupt to be serviced is an I/O interrupt

*LO if the interrupt to be serviced is a system level
interrupt handled by the processor card. This
signal disables all I/O cards from responding to
the interrupt acknowledge

SLV+ = qualified slave request

*HI if a) SLAVE+ is HI and
PECF- is HI (parity error) and
UTIF+ is LO (unimplemented instruction) and
IIFF- is LO (level 2 and 3 interrupts inhibited)
or b) SLAVE+ is HI and
PECF- is HI (parity error) and
UTIF+ is LO (unimplemented instruction) and
PMPI+ is LO (memory protect violation) and
SPINT+ is LO (special interrupt request)

*LO if none of the cases above are satisfied

PFIF+ = qualified power fail interrupt
MPIF+ = qualified memory protect violation interrupt
TBIF+ = qualified time base generator interrupt
SPIF+ = qualified special interrupt

2.5.4 VIRTUAL CONTROL PANEL (SLAVE MODE) PROCESSING

When the CPU is in slave mode, its internal registers are accessible to external devices through certain I/O interface cards. The Parallel Interface card, Asynchronous Interface card, and the HDLC (DS network) Interface card are the interface cards which may request slave mode processing. Since slave mode processing involves direct interaction between the requesting device and the CPU, the processor card merely provides buffering, signal timing, and bus arbitration for the handshake signals and data transfers.

Slave mode processing abides by the same protocols used for the execution of I/O instructions that require interaction between the I/O processors and the central processor. Whereas an instruction causes an I/O processor to initiate an I/O handshake, slave mode processing is performed in response to some external event not related to the program flow. The I/O handshake of an I/O instruction occurs during the execution of that instruction but the I/O handshake of slave mode processing occurs between instructions. Thus, slave mode uses IORQ- and IOGO-, but operates independently of the program.

A slave mode request, SLAVE-, is made over the backplane by the interface card configured for slave mode processing. Only one I/O interface card can be selected as the slave mode interface at any given time and that card must have its select code set to 20 (octal). As soon as the current instruction has been completed, the CPU chip will acknowledge the slave request and SCHOD- (slave chain output disable) will be deasserted to inform the slave requesting interface card to start the I/O handshake(s).

Any device with input/output capabilities and connected to an interface card configured to allow slave mode processing becomes the L-Series Computer's Virtual Control Panel. This device will provide the means to access the CPU registers and memory locations in a manner similar to a hardware front panel. If a terminal is the Virtual Control Panel device, the keyboard replaces the front panel switches for register selection and data entry, while the display replaces the hardware status and data output indicators. Unlike a hardware front panel, the Virtual Control Panel may be located remotely far away from the computer.

Operator interaction using a terminal is accomplished by a program located in the processor card ROMs. The code for this program is listed in Appendix A of

this document. See Section 1.4.1 for a description of the Virtual Control Panel.

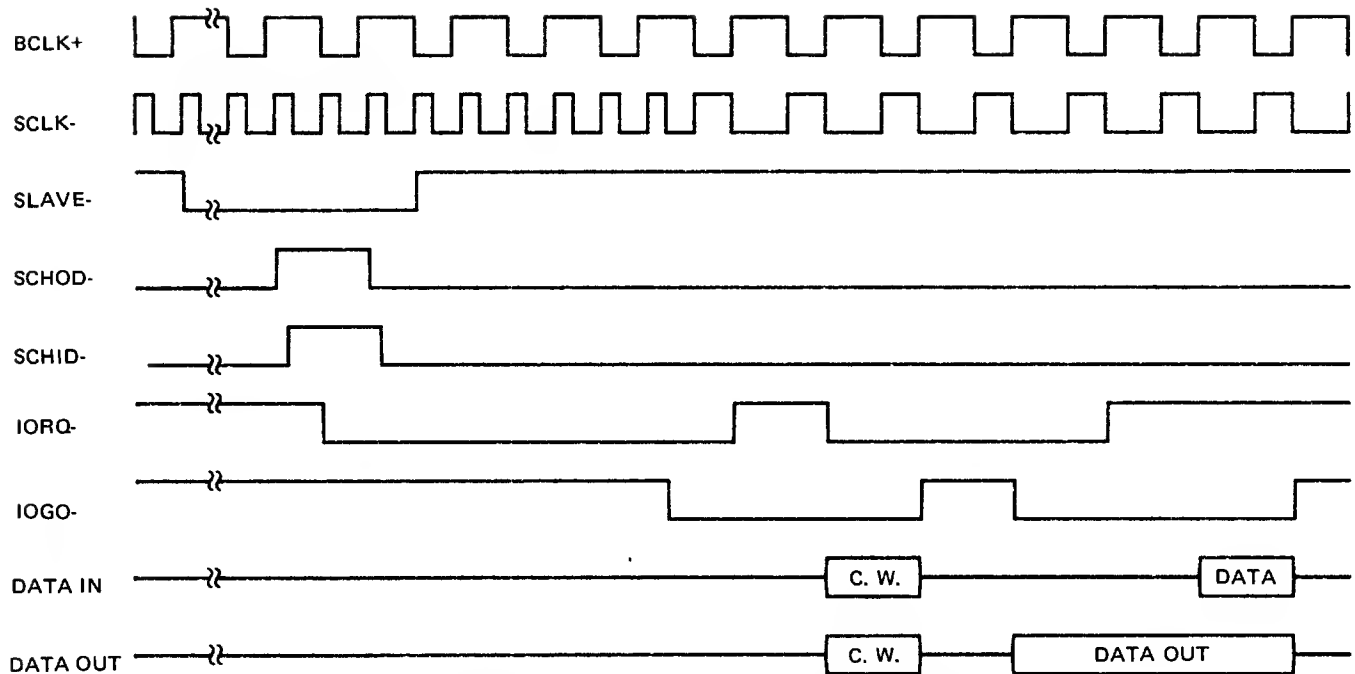
Refer to figure 2-23 for a timing diagram of the backplane protocol used during slave mode processing.

2.5.5 POWER ON SELF-TEST AND BOOT LOADERS

The CPU chip will initiate a bus integrity test for the processor card and backplane address and data buses at power up, as soon as DC power is at the proper voltages. This test will insure that the two buses are fully reliable before any processing begins. Beginning at address 0, the CPU chip drives the address bus. At power-up, before the first instruction fetch, the processor card drives the data bus with the same information that it receives on the address bus. The data bus is then read by the CPU chip to determine if the data bus is identical to the address bus. If the two buses agree, the CPU proceeds to the next address until all patterns on the address and data buses have been checked. If shorted printed circuit traces are present on either bus, the CPU freezes to prevent further processing. All of the status LEDs on the processor card remain on to indicate that the card is receiving DC power but fails the bus integrity test.

Part two of the power on self-test consists of system functionality tests. This portion of the self-test is executed from the processor card ROMs so that it is not necessary to assume that RAM memory is fully functional. If any part of the testing fails, the processor will freeze to prevent further processing and the status LEDs will indicate which subsystem was under test at the time of the failure. In chronological order, the self-test examines the RAM memory of the memory card, the CPU chip instruction set, the processor card I/O instructions and interrupt handling, and the I/O master section of all I/O interfaces installed in the backplane.

Following the successful completion of the self-test, the L-Series will automatically execute one of three power on options selectable via the processor card switches (positions 1 through 3). If the virtual control panel option is selected and a terminal is the peripheral device, the computer will output the CPU register status to the CRT and wait for a virtual control panel command from the keyboard. At this time, one of four boot loaders may be invoked (disc via HP-IB, network link, PROM I/O, or 264x/2671 cartridge tape). If the bootstrap loader is the option selected, the L-Series will automatically boot load from disc, network, or PROM I/O at the completion of self-test. If the auto-restart option is selected (assuming battery backup is installed), the computer will resume program execution beginning at the point it left off when power was removed. These power on options permit the L-Series to be used in a variety of applications ranging from a simple stand alone controller to a node in a complex network.



NOTES: Same handshake protocols as an I/O handshake.
Some slave mode transfers require only one set of IORQ-/IOGO- handshakes.

Figure 2-23. Slave Transfer Protocols

See the HP 1000 L-Series Reference Manual, part number 02103-90007 for a discussion of the bootstrap loader; Section I of this document for a discussion of the Virtual Control Panel; and the HP 1000 L-Series Computer Installation and Service Manual, part number 02103-90003 for discussion of the power fail recovery procedure.

2.5.6 L-SERIES CLOCKS

The L-Series processor generates four different clocks for use by the memory and I/O interface cards.

FCLK- (Fast Clock) has a nominal frequency of 22.016 MHz (period=45 ns) and a duty cycle of 50%. It is used by the memory card to clock logic operating at frequencies higher than that required by the processor. Its frequency is reduced by a factor of two to 11.008 MHz (period=90 ns) during I/O or slave mode handshakes. For both frequencies, a rising edge of FCLK- accompanies every transition of RCLK+, SCLK-, and BCLK+.

RCLK+ (Refresh Clock) has a nominal frequency of 4.4 MHz (period=227ns) and a duty cycle of 60%. It is used by the memory card to time refresh cycles. Its frequency remains at 4.4 MHz during I/O handshakes.

SCLK- (System Clock) has a nominal frequency of 4.4 MHz (period=227ns) and a duty cycle of 40%. It is used by every L-Series card to synchronize all backplane transactions. All backplane timing guarantees and requirements are referenced to SCLK-. Its frequency is that of FCLK- divided by five. SCLK- is 2.2 MHz (period=454ns) during I/O handshakes. SCLK- is always phase locked to FCLK- and, most of the time, to RCLK+.

CCLK- (Communications Clock) has a nominal frequency of 14.7456 MHz (period=67.8ns) and a duty cycle of 50%. It is used by all serial interface cards, and by any interface requiring a fixed frequency for state machine or counting operations. This frequency is a convenient multiple (times 16) of the frequency used by the baud rate generator integrated circuits (see the Asynchronous Serial Interface Reference Manual, part number 12005-90001).

BCLK+ (CPU Clock) has a nominal frequency of 2.2 MHz (period=454ns) and a duty cycle of 60%. It is used only by the CPU chip and various processor board to CPU chip interface logic devices.

All of the clocks are derived from two crystal oscillators on the processor board. The backplane CCLK- is the buffered version of a 14.7456 MHz crystal oscillator. The output of a 22.016 MHz crystal oscillator is buffered and then divided down to create FCLK-, RCLK+, SCLK-, and BCLK+. Since the time base generator in the CPU chip is dependent on an accurate BCLK+, it is necessary for the 22.016 MHz oscillator to be as stable to its nominal frequency as possible. A device with 50 parts per million (0.005% variation) stability was chosen so that time may be kept to within 4.32 seconds per day.

A buffered version of the 22MHz oscillator is used in edge-triggering every flip-flop in the clock generation circuitry. This insures that the 22MHz clock is an integer multiple of any clock (except CCLK-) found on the processor or on the backplane. U71b and U72a,b form the nucleus of the clock generation logic. Collectively, they constitute a state machine implementation of a divide by five counter. The following chart shows the state transition for the three flip-flops:

U72.5	U71.9	U72.9
Q1	Q2	Q3
-----	-----	-----
0	0	0
0	0	1
0	1	1
1	1	1
1	1	0

The next state after the fifth state (110) is the first state (000), so the counter repeats itself every 227.1 nsec given that the time between states is 45.4 nsec (22MHz clock). The Q output of U71b (pin 9) is L0 for two states

the memory card as RCLK+ and to the clock selector circuitry. The clock select multiplexer U91 chooses between two pairs of clocks to output as the backplane FCLK- and SCLK- clock signals.

U81a is a JK flip-flop configured as a toggle flip-flop. It is clocked with the 22MHz clock so its output (pin 5) is 11MHz. U81b is used to generate a 2.2016 MHz version (half the frequency) of RCLK+. The Q output of U81b(pin 9) is called BCLK- and has a frequency of 2.2016 MHz and a duty cycle of 40%. BCLK- is synchronized to RCLK+ so that every rising edge of BCLK- is accompanied by a falling edge of RCLK+.

The clock select logic is essentially a flip-flop (U71a) that is set (Q=SEL=1) whenever a slower clock is required. When SEL=1, the data selector U91 selects a pair of half-speed clocks. On power-up, SEL=0 so that FCLK-=22MHz and SCLK-=4.4MHz. Following the assertion of IOGO- on the backplane, SEL becomes 1 and the data selector chooses the appropriate signals to make FCLK-=11MHz and SCLK-=2.2MHz. To distinguish between the two modes, FCLK[1]-=22MHz and FCLK[2]-=11MHz, and similarly for SCLK-. SEL returns to 0 following the assertion of MEMGO- or BUSY- on the backplane, or upon a hardware reset (PON+ low). All transitions between regular and half-speed clocks occur at the falling edge (or start of short half cycle) of BCLK- to maintain phase synchronization between BCLK- and SCLK-.

The CPU chip receives the 2.2MHz BCLK+ (inverted form of BCLK-) as its operational clock. The memory card utilizes RCLK+ to time its refresh counters. The backplane gets both FCLK- and SCLK-. The processor card runs on SCLK+, a buffered and inverted version of SCLK-.

2.6 PARTS LOCATIONS

Parts locations for the processor card are shown in figure 2-24.

2.7 PARTS LIST

The parts lists for the processor card is shown in table 2-3. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

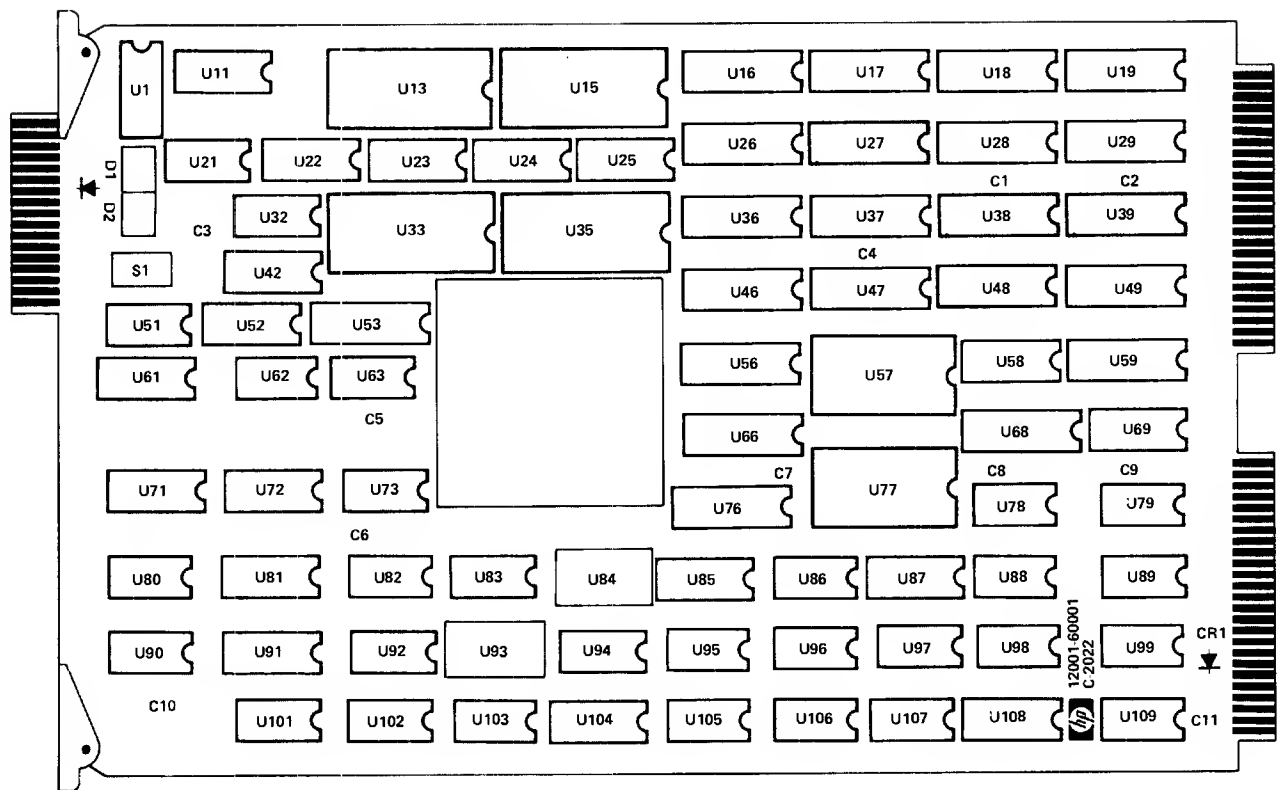


Figure 2-24. Processor Card Parts Locations

Table 2-3. Processor Card Parts List

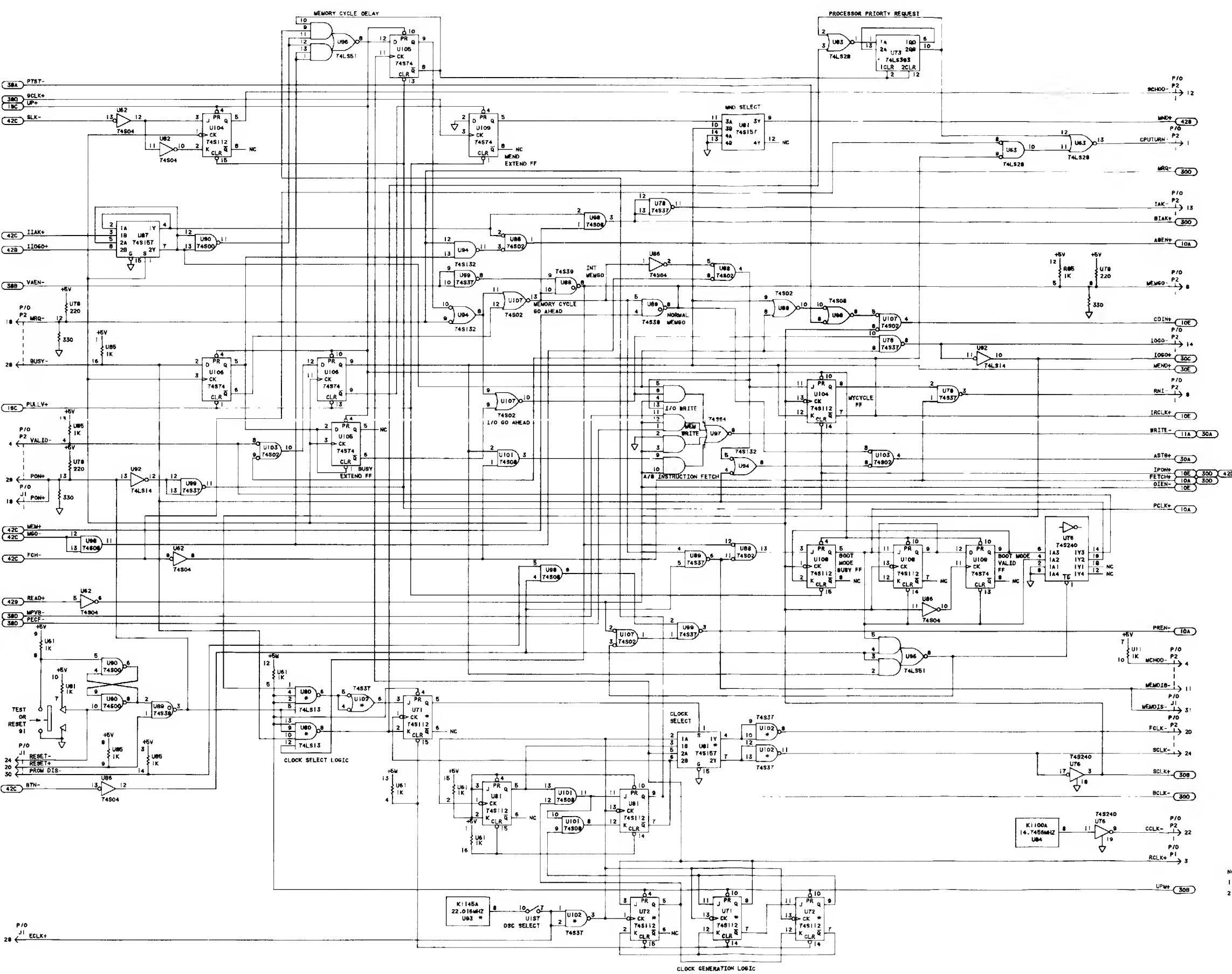
Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12001-60001	9	1	ASSEMBLY-CPU	28480	12001-60001
C1-C11	0160-4842	6	34	CAPACITOR-FXD 22UF +80-20% 50VDC CER	28480	0160-4842
CR1	1901-1080	1	1	DIODE-SCHOTTKY 1N5817 20V 1A	28480	1901-1080
D1	1990-0652	8	2	LED-VISIBLE LUM-INT=200UCD IF=5MA-MAX	28480	1990-0652
D2	1990-0652	8	2	LED-VISIBLE LUM-INT=200UCD IF=5MA-MAX	28480	1990-0652
E1	0360-1682	0	2	TERMINAL-STUD SGL-TUR PRESS-MTG	28480	0360-1682
E2	0360-1682	0	2	TERMINAL-STUD SGL-TUR PRESS-MTG	28480	0360-1682
S1	3101-2155	9	1	SWITCH-PS SPOT MDM .5A 120VAC	28480	3101-2155
U1	3101-2243	6	1	SWITCH-OIP 8-ROCKER	28480	3101-2243
U11	1810-0037	3	3	NETWORK-RES 16-DIP1.0K OHM X 8	11236	761-3-R1K
U13	1A20-2334	8	1	IC MISC TTL 8	18324	8281001 PROGRAMMED
U15	1A20-2568	0	1	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	28480	1820-2568
U16	1A20-1730	6	3	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8273N
U17	1A20-2024	3	6	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U18	1A20-2102	8	6	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U19	1A20-2024	3	3	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U21	1A20-0681	4	2	IC GATE TTL 8 NAND QUAD 2-INP	01295	8N74800N
U22	1A20-1240	3	3	IC DCOR TTL 8 3-TO-8-LINE 3-INP	01295	8N748138N
U23	1A20-1240	3	3	IC DCOR TTL 8 3-TO-8-LINE 3-INP	01295	8N748138N
U24	1A20-1015	0	2	IC MUXR/OATA=8EL TTL 8 2-TO-1-LINE QUAD	01295	8N748158N
U25	1A20-1015	0	2	IC MUXR/OATA=8EL TTL 8 2-TO-1-LINE QUAD	01295	8N748158N
U26	1A20-1730	6	6	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8273N
U27	1A20-1624	7	4	IC FF TTL L8 OCTL 1-INP	01295	8N748241N
U28	1A20-2024	3	3	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U29	1A20-2102	8	3	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U32	1A20-0685	8	1	IC GATE TTL 8 NAND TPL 3-INP	01295	8N74810N
U33	1A20-2534	0	1	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	28480	1820-2534
U35	1A20-2335	9	1	IC MISC TTL 8	18324	8281001 PROGRAMMED
U36	1A20-2024	3	3	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U37	1A20-1997	7	2	IC FF TTL L8 0-TYPE POS-EDGE-TRIG RRL-IN	01295	8N74L8374N
U38	1A20-2102	8	3	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U39	1A20-2102	8	3	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U42	1A20-1196	8	3	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8174N
U46	1A20-1624	7	3	IC 8FR TTL 8 OCTL 1-INP	01295	8N748241N
U47	1A20-1624	7	3	IC 8FR TTL 8 OCTL 1-INP	01295	8N748241N
U48	1A20-2102	8	3	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U49	1A20-2102	8	3	IC LCH TTL L8 0-TYPE OCTL	01295	8N74L8373N
U52	1A20-1240	3	3	IC DCOR TTL 8 3-TO-8-LINE 3-INP	01295	8N748138N
U53	1A20-1730	6	6	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8273N
U55	1A85-6001	6	1	21 LC	28480	1A85-6001
U56	1A20-1997	7	2	IC FF TTL L8 0-TYPE POS-EDGE-TRIG PRL-IN	01295	8N74L8374N
U57	5090-1624	2	1	IC-PTST-L	28480	5090-1624
U58	1A20-1196	8	3	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8174N
U59	1A20-2024	3	3	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U61	1810-0037	3	3	NETWORK-RES 16-DIP1.0K OHM X 8	11236	761-3-R1K
U62	1A20-0683	6	2	IC INV TTL 8 HEX 1-INP	01295	8N74804N
U63	1A20-1273	2	1	IC 8FR TTL L8 NOR QUAD 2-INP	01295	8N74L828N
U66	1A20-1624	7	3	IC 8FR TTL 8 OCTL 1-INP	01295	8N748241N
U68	1A20-2024	3	3	IC ORVR TTL L8 LINE ORVR OCTL	01295	8N74L8244N
U69	1A20-1196	8	3	IC FF TTL L8 0-TYPE POS-EDGE-TRIG COM	01295	8N74L8174N
U71	1A20-0629	0	5	IC FF TTL 8 J-K NEG-EDGE-TRIG	01295	8N748112N
U72	1A20-0629	0	5	IC FF TTL 8 J-K NEG-EDGE-TRIG	01295	8N748112N
U73	1A20-1989	7	1	IC CNTR TTL L8 8IN DUAL 4-8IT	07263	74L8393PC
U76	1A20-1633	8	1	IC 8FR TTL 8 INV OCTL 1-INP	01295	8N748240N
U77	5090-1625	3	1	IC-RTST-M	28480	5090-1625
U78	1A20-1450	7	3	IC 8FR TTL 8 NAND QUAD 2-INP	01295	8N74837N
U79	1810-0182	9	1	NETWORK-RES 14-DIR MULTI-VALUE	28480	1810-0182
U80	1A20-1415	4	1	IC SCHMITT-TRIG TTL L8 NAND DUAL 4-INP	01295	8N74L813N
U81	1A20-0629	0	5	IC FF TTL 8 J-K NEG-EDGE-TRIG	01295	8N748112N
U82	1A20-0693	8	5	IC FF TTL 8 0-TYPE POS-EDGE-TRIG	01295	8N74874N
U83	1A20-0693	8	5	IC FF TTL 8 0-TYPE POS-EDGE-TRIG	01295	8N74874N
U84	1A13-0129	0	1	IC OSC HYBRID	34344	K1100A
U85	1A10-0037	3	3	NETWORK-RES 16-DIP1.0K OHM X 8	11236	761-3-R1K
U86	1A20-0683	6	2	IC INV TTL 8 HEX 1-INP	01295	8N74804N
U87	1A20-1077	4	2	IC MUXR/OATA=8EL TTL 8 2-TO-1-LINE QUAD	01295	8N748157N
U88	1A20-1322	2	3	IC GATE TTL 8 NOR QUAD 2-INP	01295	8N74802N
U89	1A20-1451	8	1	IC GATE TTL 8 NAND QUAD 2-INP	01295	8N74838N
U90	1A20-0681	4	2	IC GATE TTL 8 NAND QUAD 2-INP	01295	8N74800N
U91	1A20-1077	4	2	IC MUXR/OATA=8EL TTL 8 2-TO-1-LINE QUAD	01295	8N748157N
U92	1A20-1416	5	1	IC SCHMITT-TRIG TTL L8 INV HEX 1-INP	01295	8N74L814N
U93	1A13-0166	5	1	IC OSC HYBRID	34344	K1145A-22.016MHZ
U94	1A20-1307	3	1	IC SCHMITT-TRIG TTL 8 NAND QUAD 2-INP	01295	8N748132N
U96	1A20-1210	7	1	IC GATE TTL L8 AND-OR-INV DUAL 2-INP	01295	8N74L851N

Table 2-3. Processor Card Parts List (Continued)

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
U97	1820-0691	6	1	IC GATE TTL 8 AND-OR=INV	01295	8N74864N
U98	1A20-1367	5	2	IC GATE TTL 8 AND QUAD 2-INP	01295	8N74808N
U99	1820-1450	7		IC 8PR TTL 8 NAND QUAD 2-INP	01295	8N74837N
U101	1A20-1367	5		IC GATE TTL 8 AND QUAD 2-INP	01295	8N74808N
U102	1A20-1450	7		IC 8PR TTL 8 NAND QUAD 2-INP	01295	8N74837N
U103	1A20-1322	2		IC GATE TTL 8 NOR QUAD 2-INP	01295	8N74802N
U104	1820-0629	0		IC FF TTL 8 J-K NEG-EDGE-TRIG	01295	8N748112N
U105	1820-0693	8		IC FF TTL 8 D-TYPE POS-EDGE-TRIG	01295	8N74874N
U106	1A20-0693	8		IC FF TTL 8 D-TYPE POS-EDGE-TRIG	01295	8N74874N
U107	1A20-1322	2		IC GATE TTL 8 NOR QUAD 2-INP	01295	8N74802N
U108	1820-0629	0		IC FF TTL 8 J-K NEG-EDGE-TRIG	01295	8N748112N
U109	1A20-0693	8		IC FF TTL 8 D-TYPE POS-EDGE-TRIG	01295	8N74874N
MISCELLANEOUS PARTS						
	0403-0289	3	1	EXTR-PC BD RED POLYC .063-BD-TMKN8	28480	0403-0289
	1200-0541	1	2	SOCKET-IC 24-CONT DIP DIP-8LDR	28480	1200-0541
	1200-0638	7	1	SOCKET-IC 14-CONT DIP DIP-8LDR	28480	1200-0638
	1200-0845	8	2	RETAINER-SUBSTRATE STEEL; NICKEL PLATE	28480	1200-0845
	1200-0848	1	1	SOCKET-888TR 64-CONT CERAMIC DIP-8LDR	28480	1200-0848
	1200-0875	4	2	SOCKET-IC 4-CONT DIP DIP-8LDR	28480	1200-0875
	1258-0124	7	1	PIN-PROGRAMING DUMPER .30 CONTACT	91506	8136-475G1

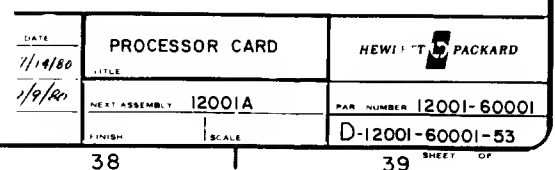
D-12001-60001-52			
SYM	REVISIONS	APPROVED	DATE
A	AS ISSUED		
B	CIRCUIT CHANGES A-2001		
C	CIRCUIT CHANGES C-2022		

A
B
C
D
E

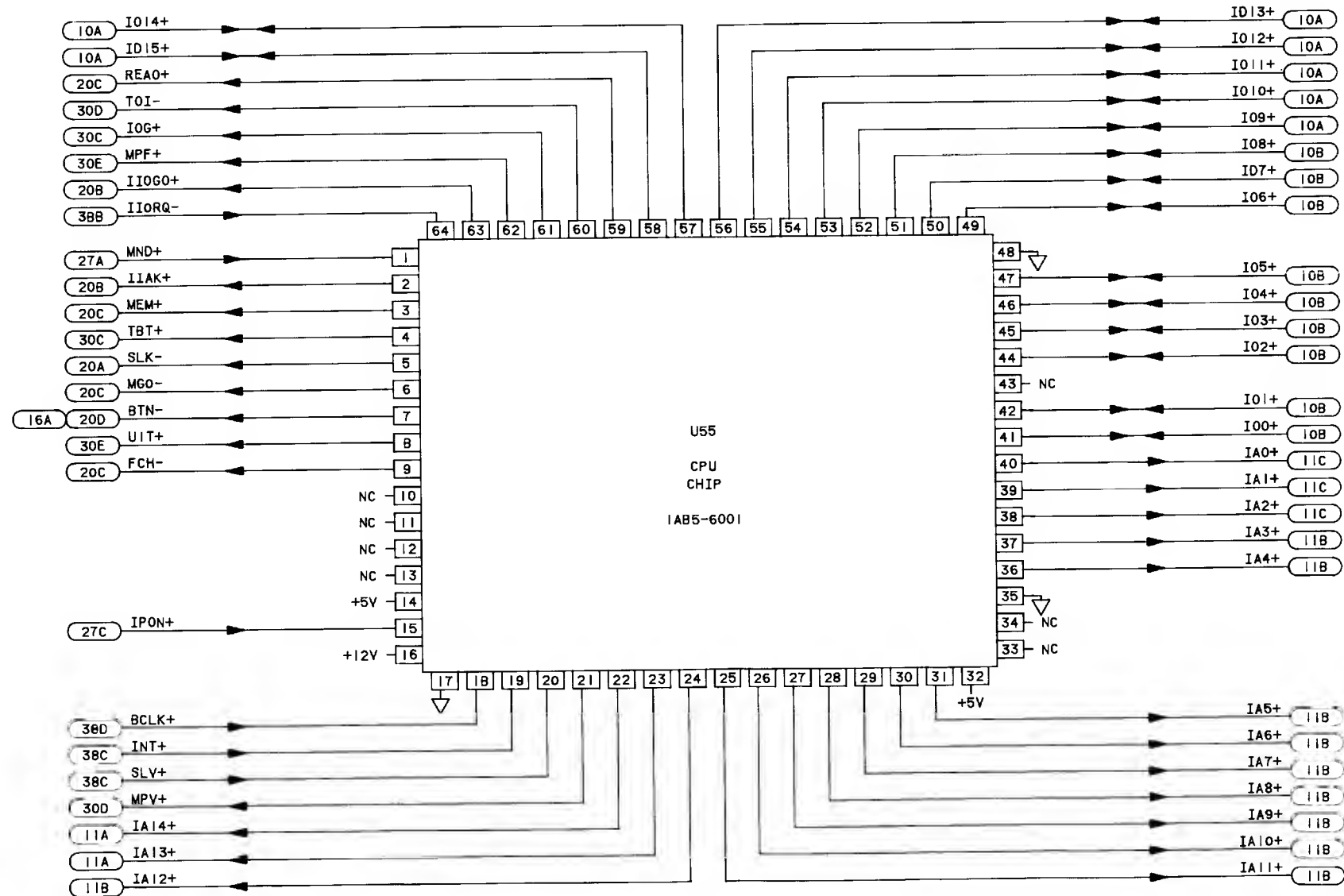


NOTES:
1. * DENOTES DEVICES THAT MUST BE CONNECTED TO +5V.
2. O DENOTES OPEN COLLECTOR OUTPUT.

PROCESSOR CARD		HEWLETT-PACKARD	
FILE	12001A	PART NUMBER	12001-60001
FINISH	SCALE		D-12001-60001-52
		SHEET OF	



SYM	REVISIONS	APPROVED	DATE
A	AS ISSUED		
B	CKT CHANGES DATE CODE A-2001		
C	CKT CHANGES DATE CODE C-2022		



PROCESSOR CARO	HEWLETT PACKARD
12001A	12001-60001
D-12001-60001-54	

64K BYTE MEMORY	SECTION III
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3.1 INTRODUCTION

A 65,536 byte random access memory is the main memory for the HP 1000 L-Series Computer System. The memory system, which includes the memory control circuits as well as the memory array itself, is contained on one circuit card and plugs directly into the L-Series backplane. The circuit card is shown in figure 3-1.

3.2 OVERVIEW

3.2.1 SYSTEM ENVIRONMENT

The system environment of the HP 1000 L-Series Computer System is shown in Section II, figure 2-2. The memory card can be plugged into any slot in the L-Series backplane with two important restrictions:

- a. The memory card must be located immediately above the processor card.
- b. No input/output (I/O) cards can be located above the memory card.

The above suggests that the memory and processor cards will always occupy the highest priority card slots in the card cage. This is true, but it should be noted that ANY two slots may be occupied by the memory and processor as long as no I/O cards are plugged into the higher priority slots (see Section VI, figure 6-3 for slot priorities).

Once it is plugged into the backplane, the memory card needs no further For reliable data retention, the RAMs must be refreshed completely every 2 msec. The refresh function is accomplished by periodically generating a refresh read pulse internal to the memory controller. The refresh period is determined by a refresh counter which is clocked by SCLK.

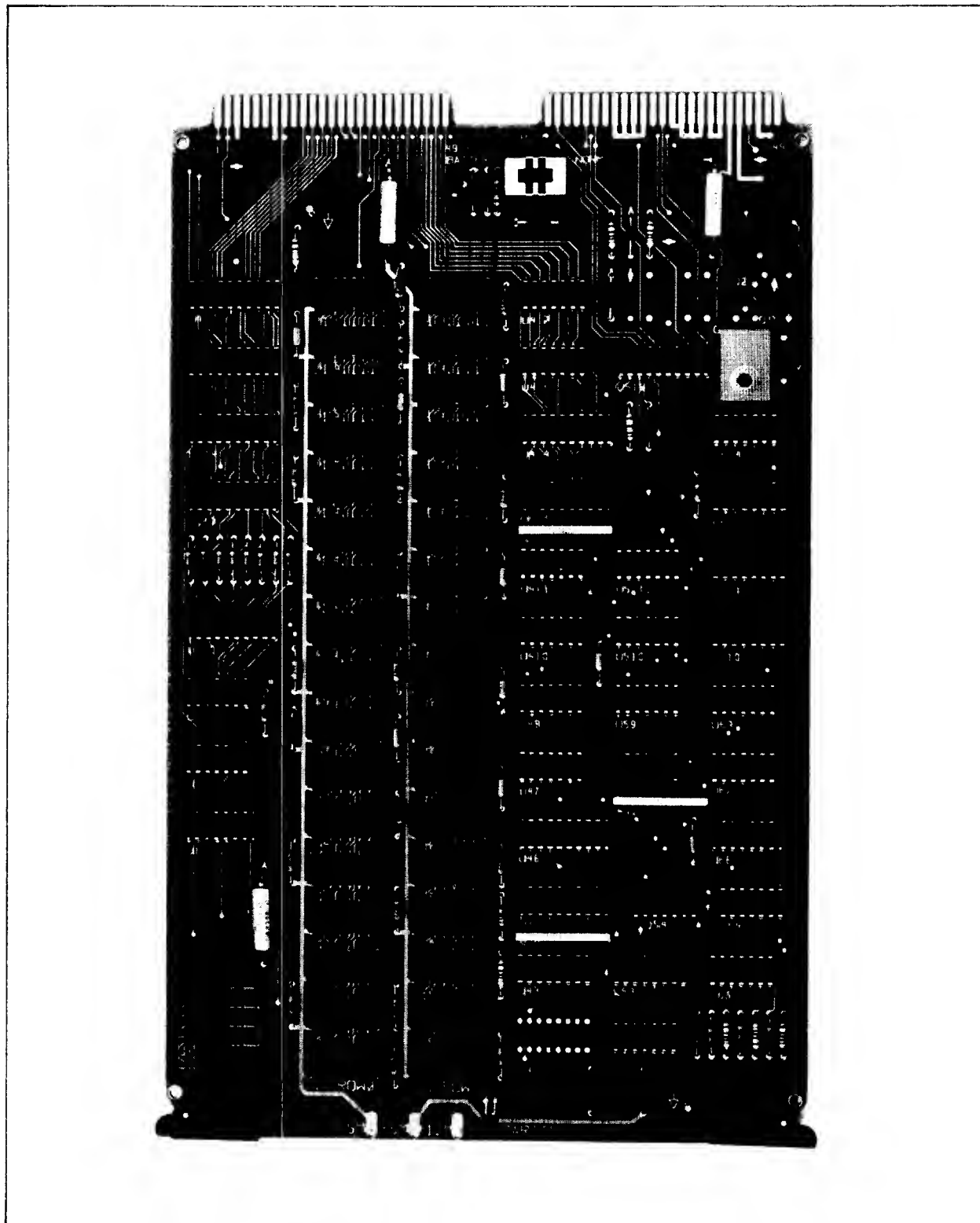


Figure 3-1. HP 1000 L-Series Memory Card

3.2.2 BASIC MEMORY OPERATION

There are three modes of operation of the memory:

- a. Write cycle.
- b. Read cycle.
- c. Refresh cycle.

Whenever the term "memory cycle" is used in this document, however, it will refer to either a read or a write cycle, and not to a refresh cycle. Memory cycles always are initiated by a stimulus external to the memory card; refresh cycles, on the other hand, are initiated by the memory itself. The memory may function in only one of the three modes at any given time.

3.2.2.1 Write Cycle

A basic write cycle is shown in figure 3-2. A write cycle is initiated when the memory controller receives a MEMGO pulse from the external interface along with the highest order bit of the address bus (Read/Write) cleared (low). At the beginning of the next short-half-cycle (SHC) of the SCLK, the memory controller will assert the BUSY control signal to hold off any other requests for a memory cycle. Shortly after this time, the controller will internally latch the data to be written and also the address to which it will be written.

The parity of the data to be written is generated from the data present on the backplane data bus and is set up to be written into memory along with the data. After the data and address are latched, the memory controller then writes the data into the memory array. At the beginning of the next SHC of SCLK, the memory controller asserts the VALID control line for one SCLK period to signal the completion of the write cycle. The BUSY signal is deasserted at the same time as VALID is deasserted and this completes the handshake.

The length of the write cycle is always three complete SCLK cycles, and because the controller needs no additional handshake overhead, the write cycle time of the memory is 3 times (1 SCLK period).

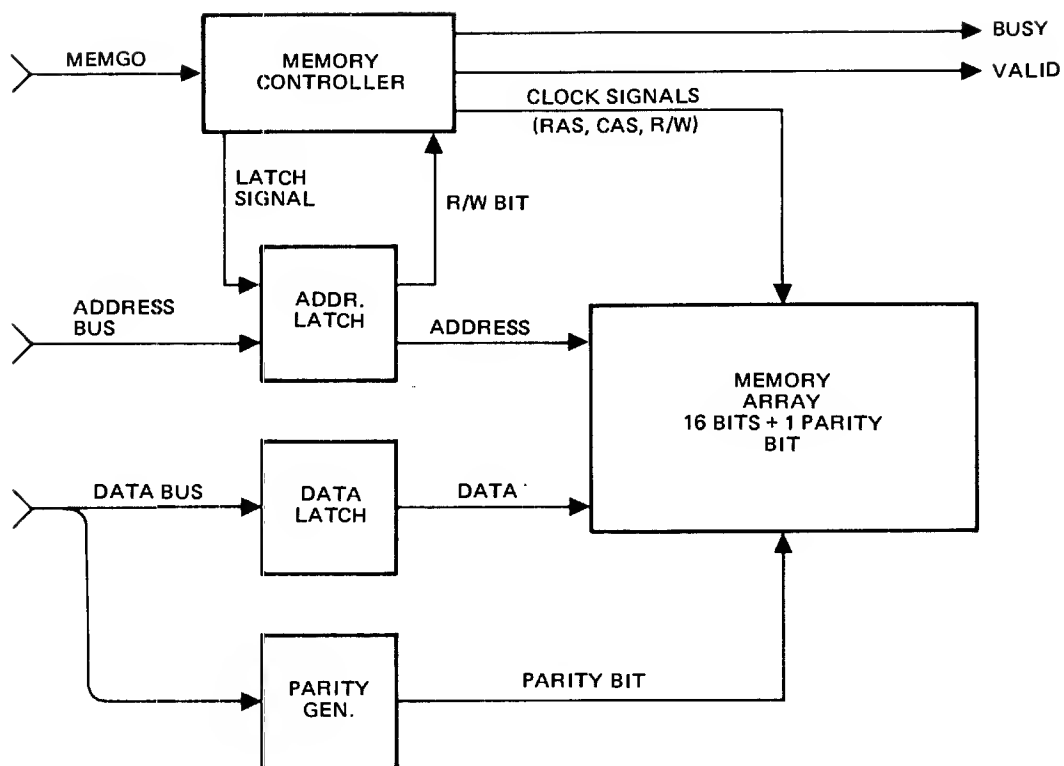


Figure 3-2. Basic Write Cycle

3.2.2.2 Read Cycle

A read cycle is shown in figure 3-3.

A read cycle is initiated when the memory controller receives a MEMGO- and the highest order bit of the address bus (Read/Write) is set (high). On the next short-half-cycle (SHC) of SCLK, the BUSY handshake signal is asserted to hold off any further requests for a memory cycle. A short time later, the address of the data to be read is latched into the address buffer. At the beginning of the next SHC, VALID is asserted to signal that the desired data is available on the backplane. The data becoming valid on the backplane is actually referenced to the trailing edge of the VALID pulse and it is this trailing edge that is used to clock the data out of memory.

While the data is valid on the backplane, the parity detector examines the data for correct parity and if it is found to be incorrect, a parity error is asserted by the memory controller. The BUSY handshake signal is de-asserted at the same time that VALID is de-asserted but the data is held on the backplane for one SHC of SCLK to satisfy data hold time requirements. The length of a read cycle is always three SCLK cycles, which is identical to the write cycle time.

3.2.2.3 Refresh Cycle

The dynamic random-access memory (RAM) elements require refreshing in order to retain data. Refresh is accomplished by issuing a read strobe pulse (RAS) to all the RAMs at regular intervals. The 16K RAMs are organized internally as a 128-by-128 matrix with the refresh function being accomplished one row at a time. The memory controller performs the refreshing by addressing each row separately and issuing a refresh read pulse. This refreshing occurs at all times that the memory has power applied to it.

Refresh cycles interleave with the memory cycles so that their function is transparent to the processor card. In the event that a memory cycle and a refresh cycle are attempted concurrently, the pending refresh cycle will hold off the requested external access cycle until the pending cycle completes. Because a refresh cycle also takes exactly three SCLK cycles to complete, the longest any requested cycle is held off is only three SCLK cycles.

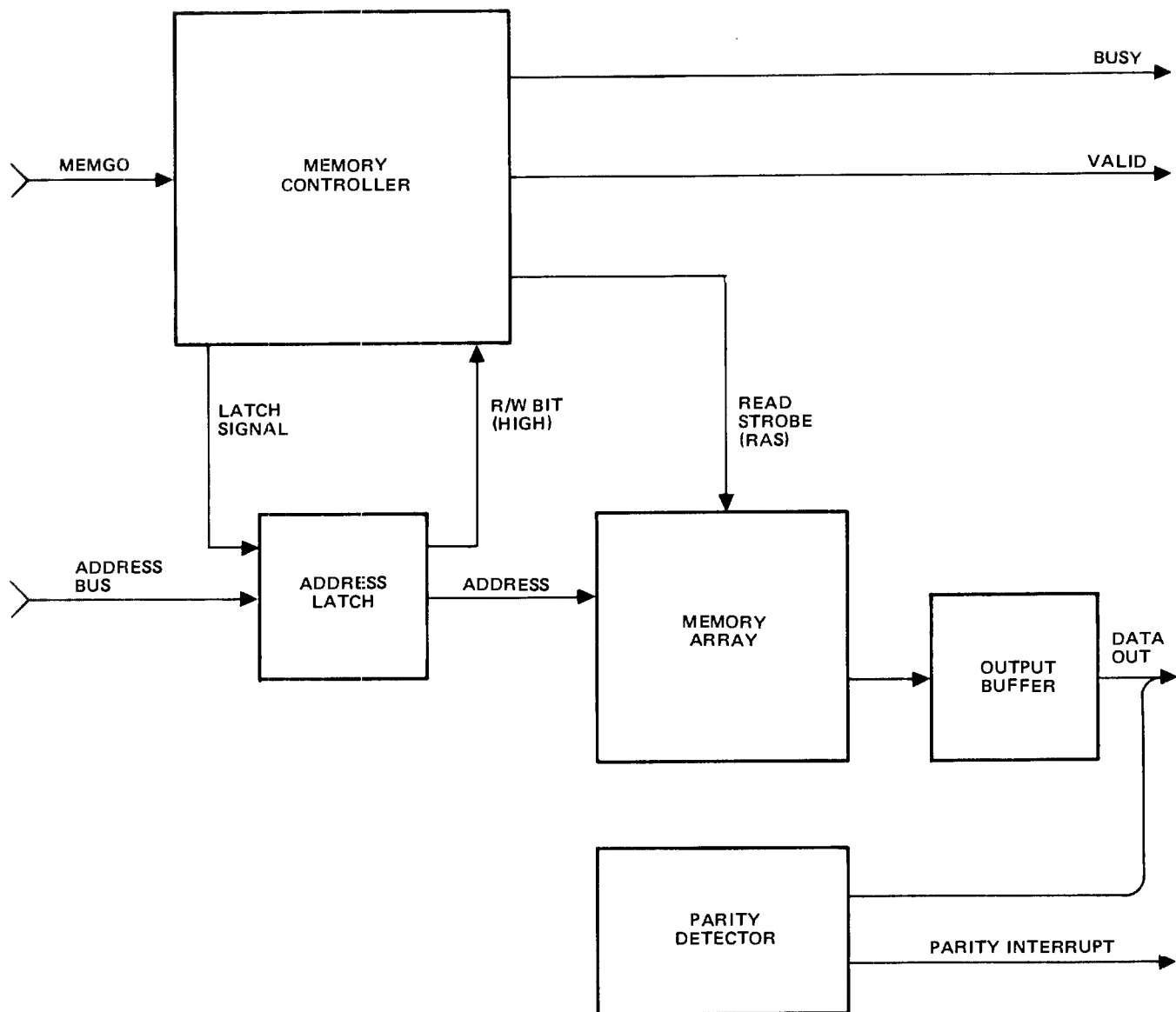


Figure 3-3. Basic Read Cycle

3.3 SPECIFICATIONS

3.3.1 POWER REQUIREMENTS

The worst case power requirements for the memory are listed below:

VOLTAGE	CURRENT		POWER	
	STANDBY	OPERATING	STANDBY	OPERATING
+12M	48mA	273mA	0.58W	3.28W
-12M	20mA	20mA	0.24W	0.24W
+5M	757mA	757mA	3.79W	3.79W
+5V	0mA	1300mA	0W	6.50W

The above current figures were obtained by calculating the RMS values as follows:

$$I_{RMS} = \sum I_{typ} + \sqrt{\sum (I_{max} - I_{typ})^2}$$

The +12M current is a measured worst case value (memory running at maximum access rate) plus 15 percent.

3.3.2 MEMORY CYCLE TIME

Memory cycles require three System Clock (SCLK) cycles for completion, thus the memory cycle time is 3 x (1 SCLK period). For a SCLK period of 227 nsec, therefore, the memory cycle time is 681 nsec. The memory card will operate with an SCLK period as short as 180 nsec without any modification.

3.3.3 MEMORY REFRESH PERIOD

For reliable data retention, the RAMs must be refreshed completely every 2 msec. The refresh function is accomplished by periodically generating a refresh read pulse internal to the memory controller. The refresh period is determined by a refresh counter which is clocked by SCLK.

Because the RAMs must be refreshed every 2 milliseconds, the refresh counter must count the correct number of SCLK cycles to refresh the 128 row addresses in these 2 milliseconds. If refreshing is done at a slower rate, data integrity is not guaranteed. If refreshing is done at a faster rate, memory is still maintained but the efficiency of the memory system decreases. This is due to the fact that memory cycles cannot occur when a refresh cycle is executing, thus, refresh cycles occurring too frequently decrease the amount of time available for memory cycles. Of course, any change in the SCLK period will produce a corresponding change in the refresh period.

3.3.4 DATA/ADDRESS LATCHES

Data and addresses sent to the memory are latched into buffers before any memory cycle begins. This is necessary because memory cycles may be attempted while a refresh cycle is in progress. In this case, addresses and data may be present only while the MEMGO pulse is asserted on the backplane. Because the memory cycle will be suspended while the refresh cycle is executed, there must be a way to store the address and data for the attempted memory cycle. The address and data latches serve this purpose. In this way, when the refresh cycle completes, the necessary data will be available for servicing the requested memory cycle. Although the latches are not really necessary for memory cycles occurring during the absence of refresh cycles, they still perform the latching function. This assures, however, that the data is held at the RAM inputs during a write cycle.

3.3.5 PARITY GENERATION/DETECTION

A parity generator/detector circuit is used to generate parity information for data that is stored into memory and to check for correct parity for data being accessed from memory. The parity circuit monitors the data bus directly without any buffering, thus parity of data being accessed from memory is checked directly on the backplane.

On a write cycle, parity is generated at the time the address/data latches are frozen. When the 16 data bits are written into memory a short time later, a 17th bit (parity bit) also is stored. This parity bit is either set or cleared, depending on the data pattern. The sense of parity is set ODD under normal operating conditions, that is, the sum of all SET bits in the data word AND the parity bit is equal to an odd decimal number.

On a read cycle, the parity of the accessed data as it appears on the backplane is checked. If the parity is not ODD, the parity detector will generate a parity error (PE-) signal on the backplane which may be received by both the processor and the I/O cards. This informs the card which is requesting data from memory that the data presently on the backplane contains an error.

The memory will complete the data transfer regardless of whether a parity error occurs or not. That is, memory will continue to perform read (or write) cycles as long as they are requested by the processor or an I/O card. It is up to the card receiving the PE- signal to determine what action will be taken.

3.3.6 PARITY SENSE

Although the parity sense is set to ODD under normal operating conditions, it may be changed to EVEN sense under program control. This provides a means by which the parity generation/detection function may be tested for diagnostic purposes.

The sense of parity at any time is determined by the PS- line on the backplane. The PS- line is driven only by the processor. Parity sense is set to EVEN if the PS- line is low, and to ODD if the line is high.

The function of the parity circuit may be verified by writing a data location with a given parity, then changing the parity sense and accessing the same data location. The PE- line should go low during the access to signify that a parity error has occurred.

It is obvious, then, that assuming there are no hardware malfunctions, data can be accessed from memory without parity errors only if the parity sense during the access of data is the same as when that data was written into memory.

3.3.7 PARITY INDICATOR

A green LED is located on the front edge of the memory card and indicates the status of the parity checking operation of the memory. At power-on, the LED is turned on and will remain on under normal operating conditions. If, during any memory access (read cycle), a parity error is detected in the accessed data, the LED will be turned off when the PE- signal occurs. The PE- signal actually resets a flip-flop which drives the LED so that the LED will remain off after the PE signal occurs.

Operation of memory is not interrupted when the parity indicator LED is off so that it is possible for memory operation to continue. The LED is meant only to be an indication that a parity error has occurred sometime in the past. The LED may be reset under program control, or by performing a system power-on.

3.3.8 STANDBY MODE

When AC line power to the computer is interrupted, data stored in the RAM memory array is lost. If it is desired that data be retained during power interruptions, then power must be maintained on the memory card.

The memory card requires four source voltages for normal operation:

- +12M
- 12M
- +5M
- +5V

Only those voltages designated with an "M" are necessary for the memory to sustain data. The +5V source is necessary only for data transfers to and from memory. Whenever the +5V source is removed, the memory will automatically assume a standby mode and will maintain any stored data as long as the memory (M) voltages are present.

When +5V is re-applied after a power interruption, the memory automatically assumes fully operational status.

3.3.9 POWER SUPPLY CONFIGURATION

The memory card works with the power supply and battery backup option to route the necessary memory voltages to the memory and processor cards. A slide switch located at the rear of the memory card is used to select two modes of power supply operation: BATTERY and NORM.

With the slide switch set to NORM, the +12M and +5M voltages are connected directly to the +12V and +5V voltages, respectively. The -12M voltage is connected to -12V through a diode (cathode to -12V). Also, the MLOST- line on the backplane is shorted to ground. This assumes that the battery backup option is not installed in the computer so that memory voltages are derived directly from the main voltages. Thus, when AC line power fails, memory power also fails because there is no battery backup to sustain memory.

With the slide switch set to BATTERY, the memory voltages are separated from the main voltages and it is assumed that the battery backup option is installed in the computer. Also, the MLOST- line is no longer shorted to ground. Thus, when AC line power fails, memory power is sustained by the battery pack.

During normal operation (no power failure) with the battery backup option installed, the memory voltages still are derived from the main voltages but the connection between them is on the battery backup board. The batteries then are in a charge mode. See Section V of this document for more information about the battery backup board.

3.4 INTERFACE REQUIREMENTS

3.4.1 BACKPLANE INTERFACE

The memory card interacts with the rest of the computer system solely through the rear backplane connectors which carry all control signals, clock signals, data, and power.

The control signals can be divided into three main groups: handshake signals, handshake inhibit signals, and initialization signals. These signals are responsible for the initiation and termination of memory cycles, as well as the operational status of the memory card.

The clock signals, Fast Clock (FCLK), Refresh Clock (RCLK), and Slow Clock (SCLK) synchronize memory operation to the computer system and drive the refresh circuit counter.

Finally, although the memory card uses power, it also furnishes power to the memory voltages on the backplane whenever the battery backup option is not installed in the computer system. This is accomplished by a switch that connects the processor voltages directly to the memory voltages.

3.4.1.1 Main Handshake Signals

The main handshake signals consist of MEMGO-, BUSY-, and VALID-. MEMGO- is asserted by the processor or an I/O card to request a memory cycle. BUSY- is asserted by the memory to acknowledge receipt of MEMGO- and also to hold off any further memory requests until the pending cycle completes. VALID- is asserted by the memory to signify that the requested data is presently available on the backplane (read cycle), or that the data sent to memory has been written (write cycle). See figure 3-4 for timing details of these signals.

3.4.1.2 Handshake Inhibit Signals

The memory card can be inhibited from acknowledging memory requests initiated by MEMGO-. This is necessary when the processor executes virtual control panel code or self-test code directly from ROM's on the processor card, or when data transfers are requested from a remote memory.

Two signals are used to inhibit memory operation: REMEM- and MEMDIS-. The inhibit function is accomplished by asserting either inhibit signal at the same time that MEMGO- is asserted.

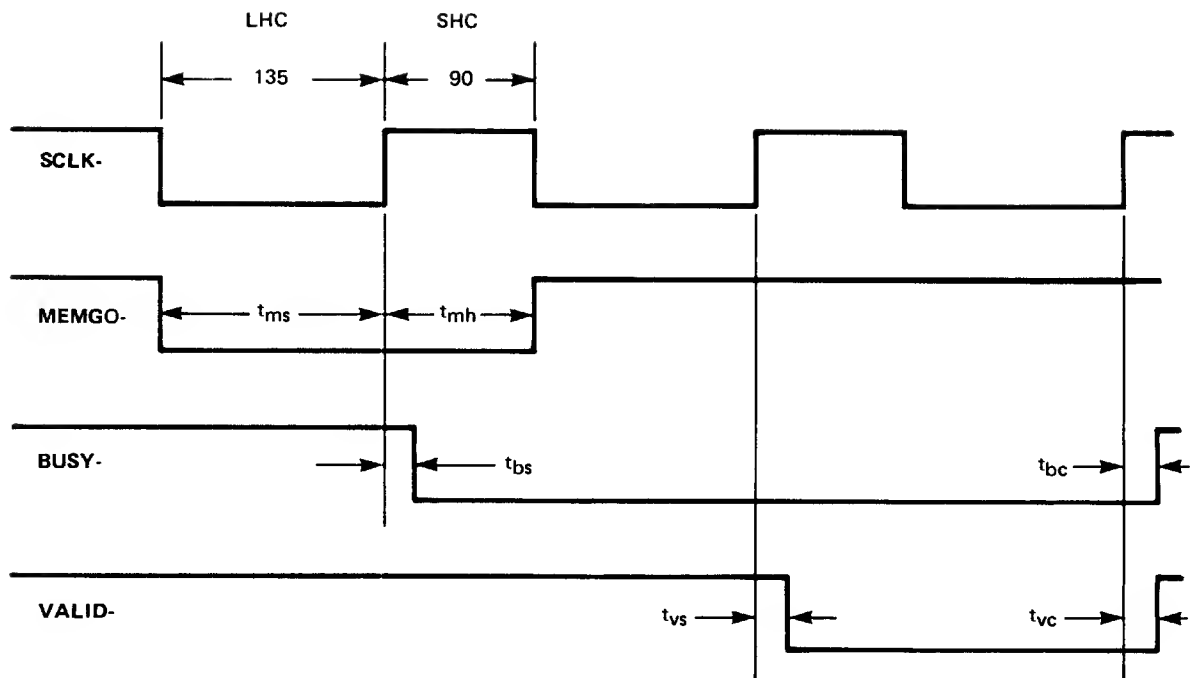
Figure 3-5 shows the timing of the inhibit signals, MEMGO-, and SCLK-. The only restriction on using either inhibit signal is that it must be active at the rising edge of SCLK- whenever MEMGO- is asserted.

3.4.1.3 Clock Signals

The memory requires the two system clocks, FCLK- and SCLK-, for memory cycle and refresh cycle timing. There are four restrictions that must be observed on these clock signals for proper memory operation:

- a. FCLK- must be exactly five times the rate of SCLK-.
- b. SCLK- must be synchronous with FCLK such that all transitions of SCLK- occur on the rising edge of FCLK-.
- c. SCLK- must have a waveform that is high for two FCLK- cycles and low for three FCLK- cycles (40 percent duty cycle).
- d. The period of FCLK- must not be less than 36 nsec. This produces an SCLK- period of not less than 180 nsec.

Please note that if the above restrictions are observed, memory speed can be altered merely by changing clock speed. If the SCLK- period is changed from 227 nsec, then the refresh counter must be modified to correct the refresh rate. (See paragraphs 3.3.3 and 3.7.8). There is no upper limit imposed on the FCLK- period.



MEMGO-SET UP TIME

$$t_{ms} > 10ns$$

MEMGO- HOLD TIME

$$120ns < t_{mh} < 225ns$$

BUSY- ASSERTION, CLEAR

$$0ns < t_{bs} < 70ns$$

VALID- ASSERTION, CLEAR

$$0ns < t_{vs} < 49ns$$

ALL TIMING RELATIVE TO
SCLK- ON BACKPLANE

Figure 3-4. Handshake Timing

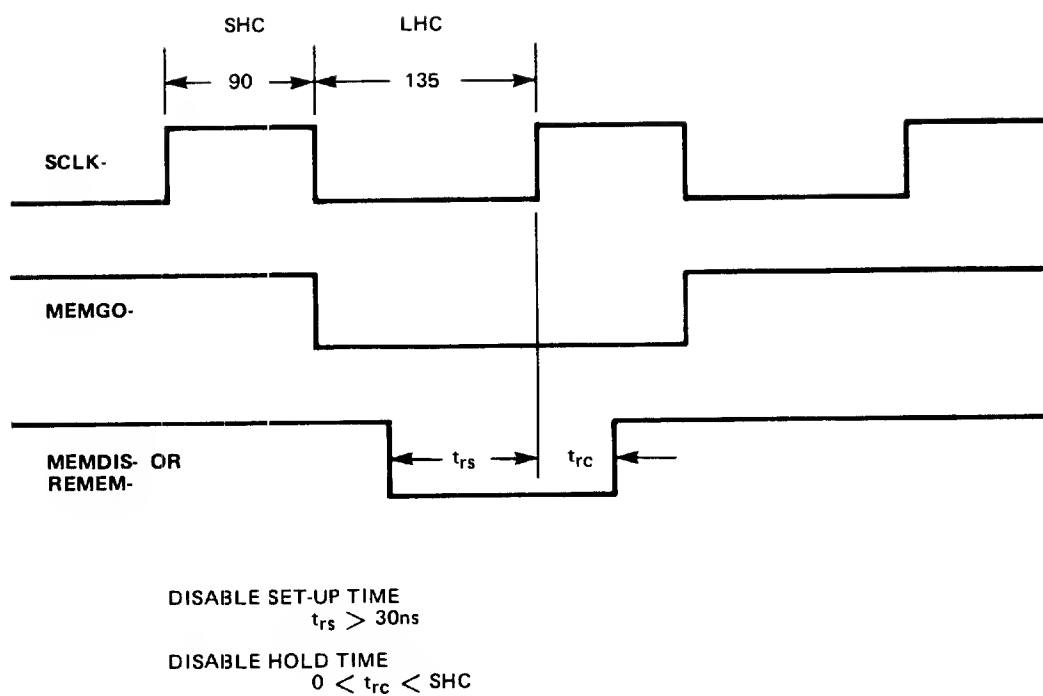


Figure 3-5. Handshake Disable Timing

3.4.1.4 Initialization Signals

The memory monitors two control signals on the backplane for initialization purposes: PON+ (Power On) and CRS- (Control Reset).

PON+ is received by the memory through a D-type flip-flop. While this control signal is false (low), the memory will ignore any requests for a memory cycle. If the memory voltages are still present, however, memory refresh will still function and retain data stored in memory.

When the CRS- line is asserted (low), the parity valid indicator (LED) will be turned on.

3.4.1.5 Power Sequencing Requirement

Because of the type of RAMs used in memory, it is necessary that -5M be present at the RAMs before +12M is applied.

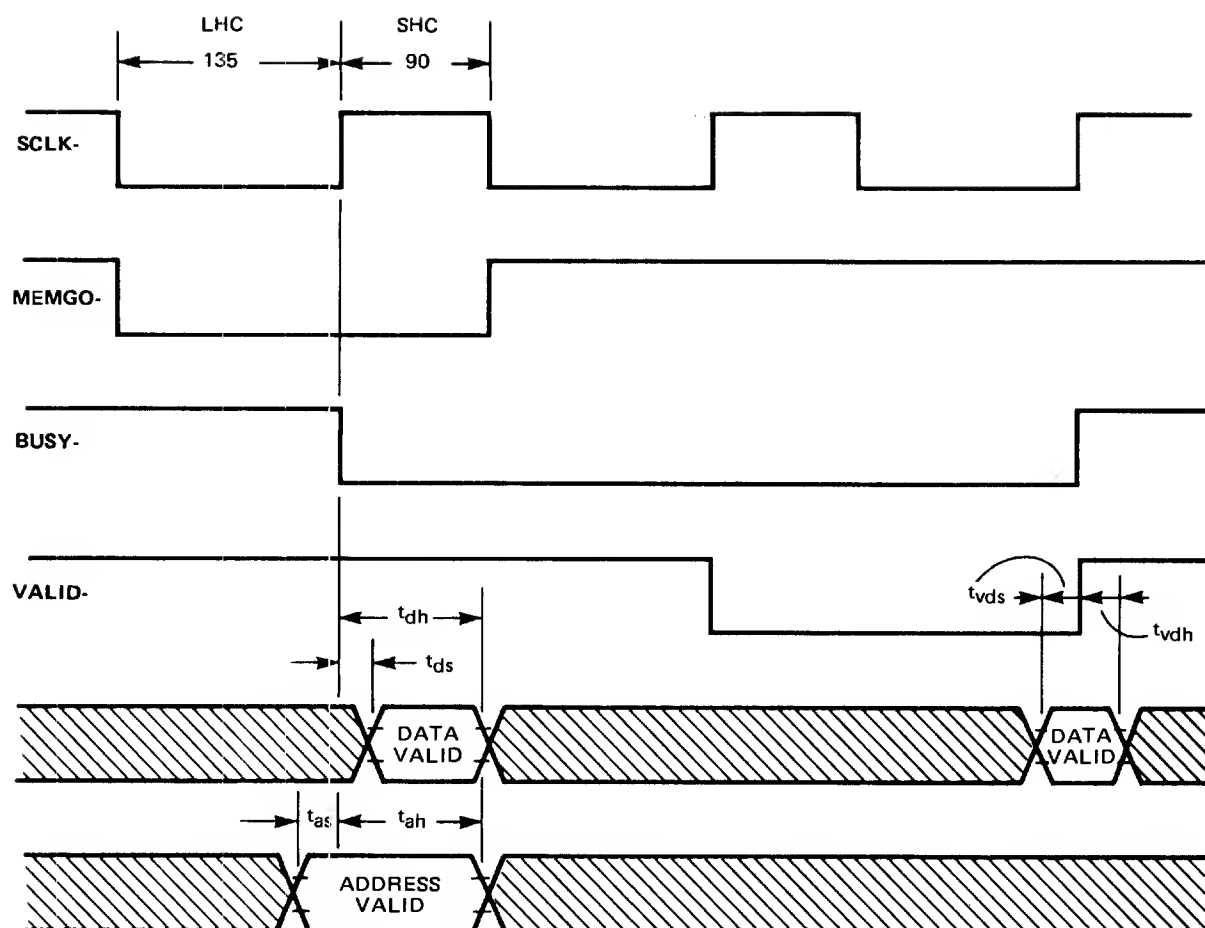
3.5 OPERATING CHARACTERISTICS

3.5.1 INITIALIZATION

When the memory card is installed in the computer system and power is applied (PON high), the memory array must be initialized by writing data into every location. This is necessary because the data bits in the memory array assume random states on an initial power turn-on so that incorrect parity will exist in many locations. It is the responsibility of the processor to write data (any data) into all memory locations so that correct parity is established in all locations.

3.5.2 INPUT DATA/ADDRESS SET-UP REQUIREMENT

When data is to be written to (or read from) memory, it is necessary to supply the address of the location where the data is to be written (or accessed). Also, in the case of a write, the data to be stored must be supplied on the data bus. A certain set-up requirement must be observed to guarantee proper memory operation under all conditions. See figure 3-6 for timing details.



DATA SET-UP TIME - $t_{ds} < 33ns$	} WRITE CYCLE
DATA HOLD TIME - $t_{dh} \geq 90ns$	
ADDRESS SET-UP TIME - $t_{as} > 7ns$	} READ/WRITE CYCLE
ADDRESS HOLD TIME - $t_{ah} > 63ns$	
DATA VALID ON BACKPLANE - $t_{vds} = t_{vdh} = 50ns$	} READ CYCLE

Figure 3-6. Read/Write Cycle

3.5.3 WRITING DATA INTO MEMORY

To write data into memory, the memory requires four items from the external environment:

- a. A MEMGO- signal to initiate the memory write cycle.
- b. The address of the memory location to which the data will be stored.
- c. Address bus bit 15 (R/W) cleared (low).
- d. The data to be written.

In response, the memory will assert the following signals:

- a. A BUSY- signal to acknowledge the receipt of MEMGO- and to hold off any further requests for a memory cycle.
- b. A VALID- signal to signify that the data has been accepted and the write cycle is complete.

The above sequence of events is detailed in figure 3-6. It should be noted that the write cycle is the same whether it is a processor or DMA write.

3.5.4 READING DATA FROM MEMORY

To read data from memory, the memory requires three items from the external environment:

- a. A MEMGO- signal to initiate the memory read cycle.
- b. The address of the memory location from which the data will be read.
- c. Address bus bit 15 (R/W) set (high).

In response, the memory will perform the following:

- a. Assert the BUSY- signal to acknowledge the receipt of MEMGO- and to hold off any further requests for a memory cycle.
- b. Assert the VALID- signal to signify that the requested data is available on the backplane data bus.
- c. The memory drives the requested data onto the backplane data bus. The data is available +/- 50 nsec referenced to the trailing edge of VALID-

(assuming an SCLK period of 180 nsec). The set-up and hold time increase with increases in the SCLK period.

The above sequence of events is detailed in figure 3-6. It should be noted that the read cycle is the same whether it is a processor or DMA read.

3.5.5 RECOVERY FROM PARITY ERRORS

Whenever a parity error occurs in data that is accessed from memory, the memory will notify the card requesting the memory cycle that a parity error has occurred by asserting the PE- signal on the backplane. Also, the parity indicator LED on the memory card will be reset (turned off). The memory is still able to perform any subsequent memory cycles without any resetting. The only resetting that should be done, as far as the memory is concerned, is to reset the parity indicator LED. This can be done under program control by issuing a CLC to select code 0. The indicator can also be reset by turning off and re-applying AC power to the system, regardless of the presence or absence of the battery back-up option.

3.6 FUNCTIONAL THEORY OF OPERATION

A functional block diagram of the memory card is shown in figure 3-7. The following paragraphs describe the function of each block.

3.6.1 INTERFACE BUFFERS

The interface buffers are composed of two sections of an S240 and are used to receive the clock signals (SCLK-, RCLK+, and FCLK-) and the handshake disable signal (REMEM-) from the backplane. They also are used to assert the handshake signals VALID- and BUSY- on the backplane during memory cycles.

3.6.2 ADDRESS LATCH

The address latch, composed of two S373 transparent latches, receives the address bits and the R/W bit (bit 15 of the address bus) from the backplane. The primary function of this latch is to store the address bits of a requested memory cycle while a refresh cycle is executing.

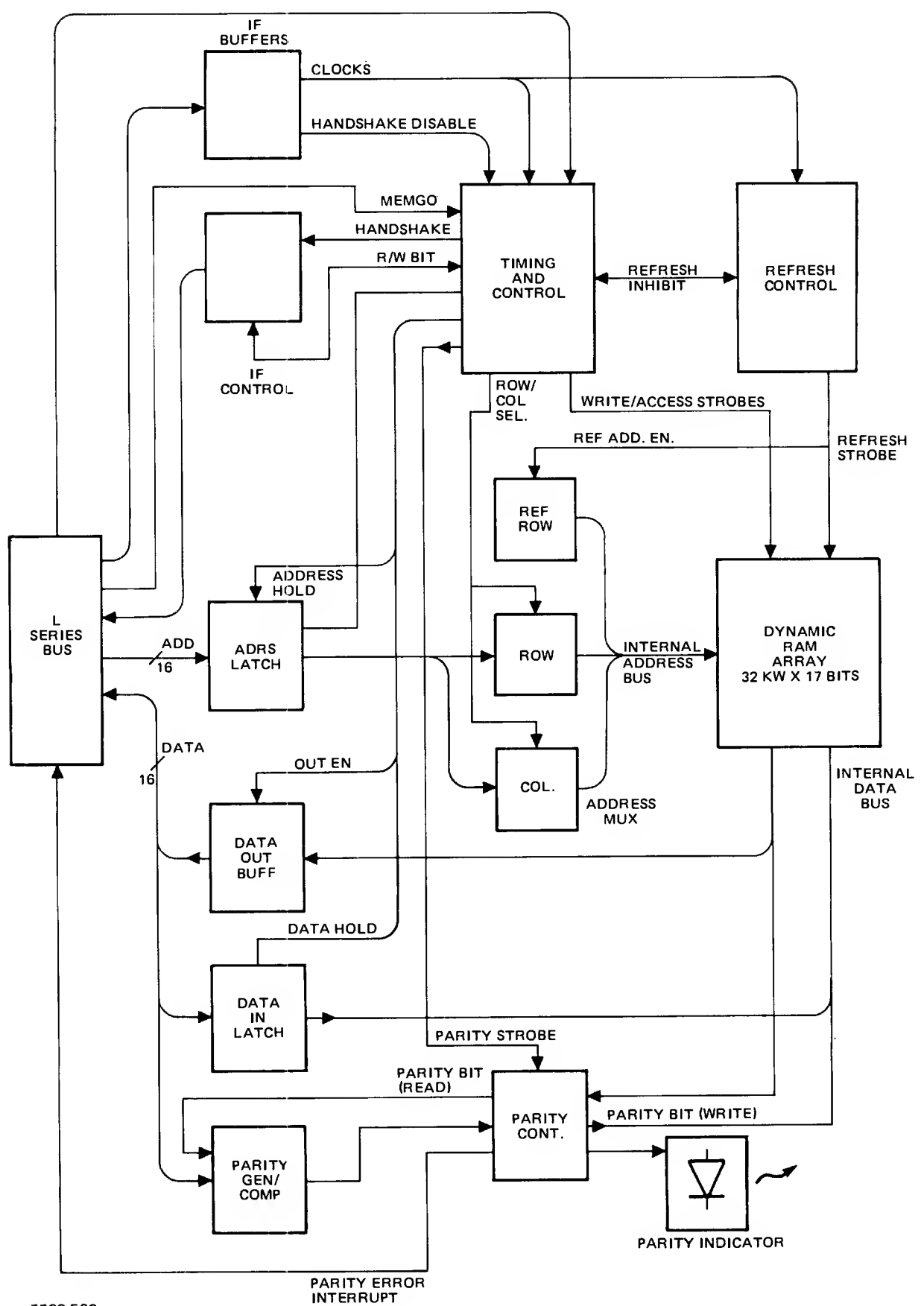


Figure 3-7. Memory Functional Block Diagram

3.6.3 DATA-IN LATCH

The data-in latch, composed of two S374 latches, receives the data bits from the backplane to be stored in memory. The primary function of this latch is to store the data bits of a requested memory cycle while a refresh cycle is executing.

3.6.4 DATA-OUT BUFFER

The data-out buffer, composed of two S241 bus drivers, drives the backplane data bus with the requested data during read cycles.

3.6.5 PARITY GENERATOR/COMPARATOR

The parity generator/comparator is composed of two S280 parity detectors and is used to detect correct parity of data being accessed. Also, working in conjunction with the parity control circuit, the generator/comparator generates the parity bit to be stored with data on write cycles.

3.6.6 PARITY CONTROL

The parity control circuit is used to control:

- a. The writing of generated parity bits during write cycles.
- b. The presenting of parity bits for comparison on read cycles.
- c. The parity indicator LED.

3.6.7 PARITY INDICATOR

The parity indicator LED indicates if a parity error has occurred. If the LED is ON, the parity is valid; if OFF, a parity error has occurred.

3.6.8 ADDRESS MULTIPLEXER

The address multiplexer is composed of three 240-type bus drivers and is used to present the row and column addresses to the RAMs during memory cycles, and the refresh row address during refresh cycles.

3.6.9 DYNAMIC RAM ARRAY

The dynamic RAM array is the main memory array used for the storage of data. It is composed of 34 16K-bit RAMs ($K = 1024$) which store the 16 bits of each data word plus a parity bit for a total of 32,768 words of memory.

3.6.10 TIMING AND CONTROL

Timing and control is a general term and refers to all the circuitry needed to:

- a. Control the actions of storing and retrieving data.
- b. Latching in data and addresses.
- c. Issuing the parity error signal.
- d. Controlling row-to-column multiplexing for the RAMs.
- e. Supplying read/write strobes to memory.
- f. Supplying the handshake control signals.

3.6.11 REFRESH CONTROL

The refresh control circuitry generates refresh row addresses and periodic refresh cycles for the retention of data in the RAMs.

3.7 THEORY OF OPERATION

The following paragraphs contain detailed theory of operation for the memory. Refer to the schematic diagram (drawing numbers D-12004-60001-51 and D-12004-60001-52, located at the rear of this section), as necessary.

3.7.1 INTERFACE BUFFERS

The interface buffers consist of two sections of a 74S240 line driver (U516). One section (permanently enabled by a ground connection at U516-19) receives REMEM- and the three clock signals FCLK-, RCLK+ and SCLK- from the backplane and buffers these signals for use on the memory card.

The other section of the buffer drives the BUSY- and VALID- handshake signals to the backplane. This buffer normally presents a high impedance to the backplane. When the handshake signals are to be asserted on the backplane, the IBUSY+ signal occurs first and gates itself onto the backplane through U52-6. When BUSY- and VALID- are de-asserted, the buffer is held enabled by CAS+ (U52-5), which is de-asserted one SHC later. The reason for this is that when BUSY- and VALID- are de-asserted, the backplane is driven to the inactive states for these signals much faster than if it were allowed to return to the inactive state by the pull-up on the processor alone.

These signals are shown in the timing diagram in figure 3-8.

3.7.2 ADDRESS LATCH

The address latch consists of two 74S373 transparent latches (U116 and U117). These latches are frozen at the beginning of every requested memory cycle, whether a refresh cycle is in progress or not. That is, whenever a memory cycle is requested, the address latch will latch the address bits while they are available on the backplane regardless of whether the memory is idle or performing a refresh.

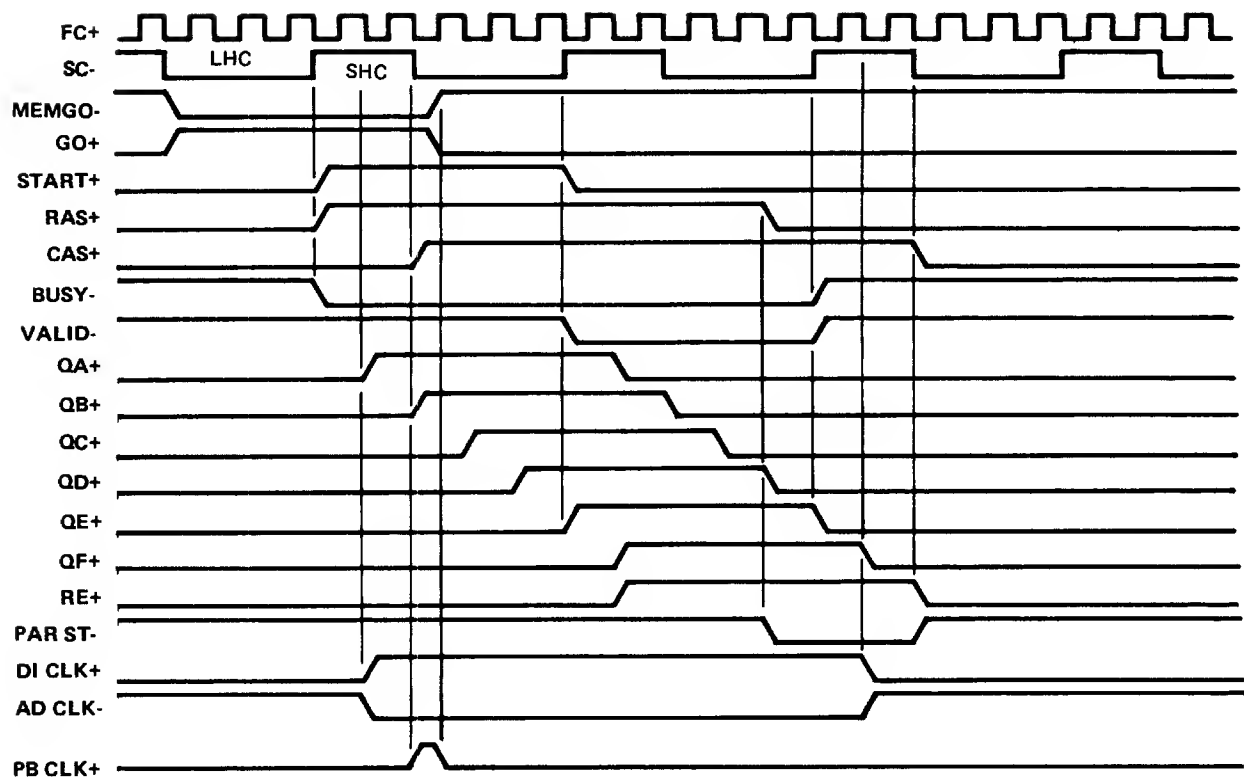


Figure 3-8. Memory Cycle Timing

The sequence of events is as follows: a MEMGO- pulse is received at U49-11 and appears inverted at U49-13. The resulting MEMGO+ signal appears at the J input of the BUSY flip-flop, U53-11. On the falling edge of SCLK+, the BUSY flip-flop sets (U53-9 goes high), which asserts BUSY- on the backplane and also sets the J input of the DI flip-flop (U43-11) high. On the falling edge of FCLK+, which occurs one FCLK cycle after the falling edge of SCLK+, the output of the DI flip-flop sets (U43-9 high, U43-7 low). The AD CLK- line, coming from U43-7, goes low and freezes the address latches at this point.

The K input to the DI flip-flop (U43-12) is connected to the complementary output of the BUSY flip-flop (U53-7). As a result, since the DI flip-flop is clocked by FCLK+, its output will follow the corresponding output of the BUSY flip-flop delayed by one FCLK cycle. The AD CLK- line, therefore, will be asserted (low) one FCLK cycle after BUSY is asserted and will be de-asserted one FCLK cycle after BUSY is de-asserted.

3.7.3 DATA-IN LATCH

The data-in latch consists of two 74S374 latches (U46 and U414). These latches are controlled by the DI CLK+ signal from the DI flip-flop (U43, described in paragraph 3.7.2).

The data-in latch receives the data bits from the backplane to be stored in memory. The operation is the same as the address latch, described in paragraph 3.7.2.

3.7.4 DATA-OUT BUFFER

The data-out buffer consists of two 74S241 line drivers (U44 and U413), and drives the requested data onto the backplane data bus during read cycles. The buffer is enabled to drive the backplane by both the RE+ and RE- control signals from the RE flip-flop at U43-5 and U43-6, respectively. These outputs only occur during read cycles and are generated as described in the following paragraphs.

A MEMGO- pulse is sent to the memory card to initialize a read cycle. At the next falling edge of SCLK+, the BUSY flip-flop (U53) is set. One FCLK later, the DI flip-flop (U43) sets, latching in the address of the requested data. Note that bit 15 (R/W) of the address bus is used to signify whether the requested memory cycle is a write or read cycle. In the case of a read cycle, this line is asserted high. This line is routed to the "out enable" AND gate (U417-4), which enables the RE flip-flop for operation during this memory cycle.

On the falling edge of FCLK+, corresponding with the next falling edge of SCLK+, the VALID flip-flop (U610) sets (enabled by QD from the shift register at U66). The IVALID+ signal appears at U417-5, setting the "out enable" AND gate high, enabling the RE flip-flop. One FCLK cycle later, the RE flip-flop sets and the data-out buffers drive the requested data onto the backplane.

The RE flip-flop remains set as long as the DI flip-flop remains set. When the BUSY flip-flop is reset towards the end of the memory cycle, its complementary output (U53-7) goes high, enabling the K input on the DI flip-flop (U43-12). On the next falling edge of FCLK+, the DI flip-flop resets and its complementary output (U43-7) goes high, enabling the K input of the RE flip-flop (U43-2). The next falling edge of FCLK+ resets the RE flip-flop and the data-out buffer is disabled.

Thus, the data-out buffer is disabled two FCLK cycles after the reset of BUSY and one FCLK cycle after the reset of DI CLK+.

Note that RE is de-asserted two FCLK cycles after VALID- is de-asserted. Because the trailing edge of VALID- is used to clock data from the memory, the data is held on the backplane for these two FCLK cycles to satisfy data hold-time requirements.

3.7.5 PARITY CIRCUIT

The general term "parity circuit" refers to all the circuitry necessary for the memory card to perform the parity generation and detection function, the writing of correct parity into memory during write cycles, and the control of the parity indicator LED.

The main part of the circuit consists of two 74S280 parity generator/detector circuits (U47 and U416). These circuits monitor data on the backplane constantly; and create the necessary information for checking the parity of accessed data and writing the parity bit for stored data. The following paragraphs describe the parity generation and detection sequence; figure 3-8 shows the timing.

3.7.5.1 Parity Generation

The parity generator circuit generates the parity bit which is stored with the data during any write cycle. When the PS- line (U47-4) is low, the sense of the parity generator is said to be EVEN, that is, the generator will insure that the summation of all set data bits in a data word PLUS the corresponding parity bit will equal an even decimal number in any given location in memory. The two S280 parity generators each have two outputs, labeled E (even) and O (odd). These outputs are true (high) whenever the parity of the data on the inputs is even or odd, respectively. Because each generator monitors eight

data lines, the four outputs of the generators (two E and two O outputs) must be combined to generate parity for the 16-bit data word.

The E output of either generator will be true whenever there is an even number of ones at their respective data inputs. Note that the PS line forms one input for the parity generator at U47. Since this line is high for normal operation, the only way the E output will be high on this generator is if there are an ODD number of data bits on its remaining inputs. Therefore, if both E outputs are true, this signifies that there is an odd number of data bits set (an even number on U416 and an odd number on U47). This is the condition for ODD parity, and as a result, the parity generator must not set the parity bit.

A similar argument holds for the O outputs, U416 will have its O output set if there an odd number of bits set. U47 will have its O output set only if there are an EVEN number of data bits set (because the PS line also is high). This again is the condition for ODD parity and the parity bit must not be set.

Because the occurrence of either pair of outputs being true signifies that the parity bit should be clear, or, in Boolean terms,

$$\left(\begin{matrix} E & . & E \\ A & & B \end{matrix} \right) + \left(\begin{matrix} O & . & O \\ A & & B \end{matrix} \right) := \bar{P}$$

this function is implemented by a 74S51 (U411). The output at U411-6 is false (low) whenever the data has odd parity and true for even parity. The parity bit written into memory is set whenever the data has even parity, thus preserving the odd parity requirement. Note that the PS- line is high for odd parity, which is normal operation.

When a MEMGO- pulse is received by the memory card, the data to be written is available after the beginning of the next SHC of SCLK. Data must be valid on the backplane by the falling edge of FCLK+ occurring midway into the SHC. It is at this point that the data is latched into the input buffers. The next FCLK cycle is used to allow the parity generator to perform the comparison and present the parity bit at U411-6. On the next rising edge of SCLK+, the PB CLK+ line (U417-8) goes high, clocking the D flip-flop at U57-11. The parity bit that was generated is now latched at U57-9 and is available at the parity RAM input.

3.7.5.2 Parity Detection

When data is driven onto the backplane by the memory, it is monitored by the parity detector circuits for correct parity. The parity comparison described under parity generation (starting with paragraph 3.7.5.1) for a write cycle, is the same as the parity detection performed on a read cycle (described here) with one important exception: The parity bit in memory on a write cycle is presented to the detector at U416-4; the parity bit on a read cycle is enabled to the detector by RE+ at U417-1.

As discussed under parity generation, the parity bit is set when the two generators detect different summation senses, that is, the E output is true on one generator when the O output is true on the other generator, and vice versa. On a read out of memory of stored data, if the senses are opposite, the parity bit presented to U416 will be set and change its sense to match that of U47. Thus, the output of U411-6 will go low during the data access.

Similarly, if the senses are the same during the access, the parity bit will be low when presented to U416 and will not change its sense. The output at U411-6 will again be low.

This output is used to generate the PE- signal. U411-6 will always be low when the parity of accessed data is correct.

During a data access from memory, the RE+ signal is asserted to enable the data-out buffers (U44, U413). This signal also enables the parity interrupt circuit at U59-13 and U63-13. The data will have settled by the time the row-address-strobe (RAS+) pulse is de-asserted and this event is used to generate the parity strobe (PAR ST-). The PAR ST- signal comes from U410-6, being initiated by the trailing edge of RAS+ and terminated by the trailing edge of CAS-.

If the parity of the output data is incorrect, U411-6 will be high and U59-11 will be low. On the leading edge of PAR ST-, the output at U49-10 will go high and be gated onto the backplane at P2-10 (PE-). Also, the parity indicator flip-flop (U49-6) will be reset, turning off the parity indicator LED.

On the trailing edge of the PAR ST- signal, the PE- signal will be de-asserted but the parity indicator flip-flop (U49) will stay reset. This flip-flop can only be reset by U64-11 going high by either a CRS- or PON-.

3.7.6 ADDRESS MULTIPLEXER

The address multiplexer is composed of two 74S240 drivers (U113 and U114) and one LS240 driver (U110). These drivers provide the refresh row address, and the row and column address to the RAM address lines. The triple, 3-input NAND gate (U17) provides an interlock to prevent more than one driver from driving the RAM address bus simultaneously.

During refresh cycles, the row and column address drivers are disabled by the RC- signal appearing at U17-2 and U17-5. The RC+ signal enables the refresh row address driver to drive the bus with the refresh address from U19.

At times other than during refresh cycles, the row and column address drivers are enabled (not simultaneously) to drive the address bus. The selection of which driver is enabled is done by the CAS+ and CAS signals. At all times

that CAS is not asserted, the row address driver is enabled. During a memory cycle, as the address of the desired memory location appears on the backplane, the low-order seven bits (bits 0-6) appear directly at the RAM array through the enabled row address driver. When the CAS signal is asserted, the row address driver is disabled and the column driver is enabled, presenting the next seven bits of the memory address (bits 7-13) and the CAS- signal to the RAM array. The cross coupling on U17 at U17-3, U17-12, U17-1, and U17-6 is an interlock preventing the enabling of one driver until the other driver is disabled.

3.7.7 DYNAMIC RAM ARRAY

The dynamic array is composed of 34 RAM elements which are the storage elements on the memory card. Each RAM is a 16K x 1 array, thus 16 of them form a 16K times 16 or a 16K, 16-bit word memory array. Because a parity bit is needed for each word, a 17th RAM is needed for 16K words plus 16K parity bits. As a result, 17 RAM elements are needed for each 16K words of memory.

The array is arranged in two rows of 17 RAMs each, thus each row contains 16K words of memory. The address multiplexer can only address 16K words of memory (14 bits), however, so there must be a way of selecting which row is being addressed during memory cycles. This is accomplished by address bus bit 14. This bit appears at U54-1 and U59-1. When refresh cycles are not occurring, this bit controls the selection of the two memory rows. When bit 14 is clear, the input at U63-4 is high, enabling the RAS signal to row 0. When bit 14 is set, the input at U63-1 is high, enabling the RAS signal to row 1. See paragraph 3.7.8 for operation during refresh cycles.

For the reading or writing of data in memory, the RAM elements require the address bits of the desired location, the row address strobe (RAS), column address strobe (CAS), and the write enable signal (WE).

The address bits are supplied to the RAM elements as described in paragraph 3.7.6. The RAS signal occurs during every memory cycle, being generated by U54-11 by the ORing of the START pulse and the QD output of shift register U66. This signal is routed to either row as described in the previous paragraph. The CAS signal is generated by U53-5 during memory cycles and occurs one SHC after RAS. CAS is presented to the RAMs by U114-3. The write enable signal is derived from address bus bit 15 and appears as a positive true signal at U63-10. This signal is set up at the time the address is valid on the backplane. It must be valid at the RAMs by the time CAS- is presented to the RAMs. The write enable signal is disabled from the RAMs during refresh cycles by U63-9 being low. If the write enable signal is not asserted, the RAM array defaults to read mode.

3.7.8 MEMORY REFRESH CIRCUIT

The refresh circuit provides refresh row addresses and refresh pulses at regular intervals to sustain data in memory.

The refresh intervals are generated by a 74LS390 (U16). The RAM elements must be refreshed every two milliseconds and because there are 128 row addresses in each memory row, the refresh circuit must produce 128 refresh cycles every two milliseconds. (During refresh cycles, corresponding RAMs in each memory row are refreshed simultaneously.) The 128 refresh cycles every two msec necessitates a refresh cycle every 16 microseconds. Since the refresh counter is clocked by RCLK (U16-1), and RCLK has a period of 227 nsec, a divide-by-70 count is required. The outputs of U16 are monitored by U510-12 and 13 for the correct count and a reset is generated through U54-8. The output at U16-13 then has a positive transition every 16 usec, and this edge is used to initiate refresh cycles at the Refresh Pending (RP) flip-flop at U611-13.

Refer to figure 3-9 for the following discussion.

When a negative edge occurs at U611-13, the RP flip-flop sets and, if BUSY is not asserted, a high will appear at the input to the Refresh Start (RS) flip-flop at U613-11. On the next falling edge of SCLK-, the RS flip-flop sets and immediately sets the Refresh Cycle (RC) flip-flop. In addition, a pulse is sent from U59-8 to enable the START flip-flop to start the shift register sequence.

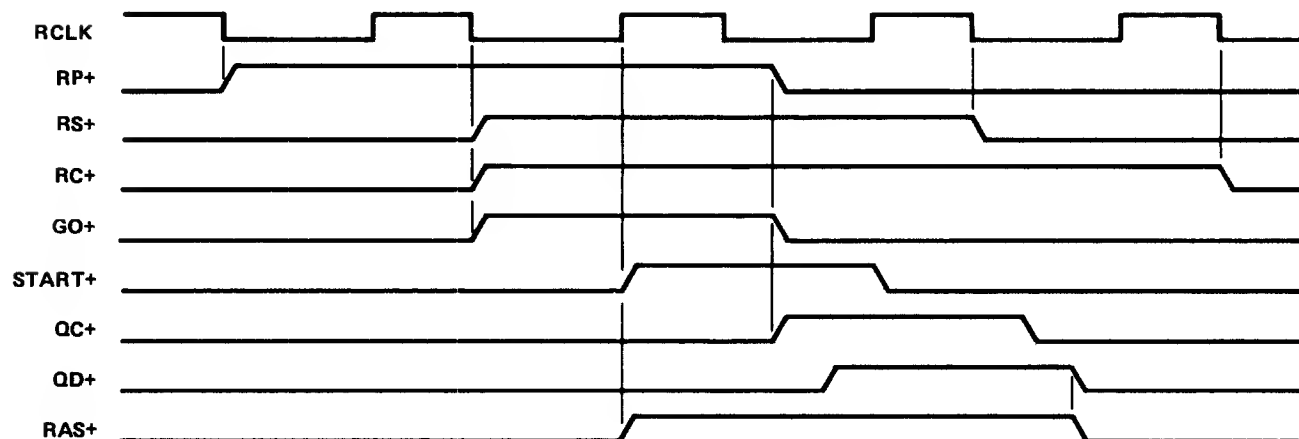


Figure 3-9. Memory Refresh Cycle

Once the RC flip-flop sets, the memory is inhibited from performing memory cycles by the following inhibit points: U53-15 and U610-15 asserted low and U69-9 asserted high. RC+ also goes to U17-10 to clock the Refresh Address counter (U19) and enable the Refresh Row address driver. Note that the occurrence of each refresh cycle increments U19.

As the START pulse occurs and progresses through the shift register at U66 (clocked by FCLK), the RAS+ pulse is generated at U54-11 and appears at both memory rows through U63. When the Qc output of the shift register occurs, it resets the Refresh Pending flip-flop at Q11-14. This sets up the inputs of the Refresh Start flip-flop to be reset on the next falling edge of SCLK-. After this occurs, the K input of the Refresh Cycle flip-flop gets set and on the next falling edge of SCLK-, the RC flip-flop resets, ending the refresh cycle.

Note that the output of NAND gate U64-8 normally stays high at all times. This insures that the refresh circuit attains the proper state on the initial power turn-on.

3.7.9 MAIN CONTROL CIRCUIT

All cycles of the memory, whether memory or refresh cycles, are initiated by the AND-OR invert gate U64. The Boolean equation below will aid in understanding the combinational function of this gate.

$$(\overline{\text{MEMGO}} + \overline{\text{MEGO}} + \overline{\text{PONB}} + \overline{\text{RS}}) \cdot (\overline{\text{REMEM}} + \overline{\text{PONB}} + \overline{\text{RS}}) \cdot$$

$$(\overline{\text{RCB}} + \overline{\text{RS}}) \cdot (\overline{\text{PONB}} + \overline{\text{RS}}) = \text{GO}+$$

The + or - at the end of each term signifies the active state of that signal at the input of U64.

The appearance of the Refresh Signal (RS-) in all groups in the equation indicates that when a refresh cycle starts, the GO+ signal is asserted regardless of the condition of the other signals (including the power-on signal PONB).

The PONB- signal in term four prevents any cycles except refresh cycles from occurring during power down.

The REMEM+ signal in the second term prevents any memory cycles from occurring while it is asserted.

Memory cycles are initiated by MEMGO- (in term one in the above equation) under normal conditions, and by MEGO- (also in term one) when a memory cycle is held off by a refresh cycle (this is explained in paragraph 3.7.11).

When a GO+ signal is received by the START flip-flop at U610-11, START+ will be asserted on the next falling edge of SCLK+, enabling the input of the shift register at U66-3. The shift register, which is clocked by FCLK-, produces shifted pulses which are used to generate the RAS signal, enable the inputs of the various control flip-flops, and provide resets for the refresh circuit, the START flip-flop, and the MEGO flip-flop.

3.7.10 MEMORY CYCLE SEQUENCE

When a memory access is initiated, an I/O card or the processor card asserts MEMGO-, which appears at U69-12. If no refresh cycle is occurring, then GO+ appears at U69-8 and enables the START flip-flop. On the rising edge of the next SHC, the START flip-flop sets and enables shift register U66. At this time, the address for the desired memory location is valid on the backplane and is set up through U116, U117, and U113 to the inputs of the RAMs.

When the START+ signal is asserted, the RAS+ signal appears at U54-11 and then, through U63, is asserted at the RAMs, strobing in the row address. BUSY- is asserted on the same SCLK+ edge as START+, being enabled by MEMGO- through U49-13.

One FCLK cycle later, the DI+ and AD CLK- signals are asserted, latching in the data and address and holding them for the duration of the memory cycle. On the falling edge of SCLK-, the parity bit is clocked to the parity RAM at U57-9 and CAS+ is generated by U53. This signal then disables U113 and enables U114, presenting the column address and the CAS- signals to the RAMs.

When the QE signal appears at the shift register (U66) output, the START flip-flop is reset. At the same time, VALID- is asserted on the backplane to signify that data is about to become valid (on the backplane). One FCLK cycle later, RE+ is asserted, enabling the accessed data to the backplane. When the QD output of the shift register resets, the RAS+ signal is released, causing the PAR ST- signal to be asserted at U410-6. This signal will cause a parity interrupt to be generated if data parity is incorrect.

BUSY- is released on the next SHC of SCLK. The VALID- signal also is released, clocking data out of the memory card. RE+ and CAS+ are released one SHC later to satisfy data hold time requirements.

3.7.11 MEMORY CYCLES OCCURRING DURING REFRESH CYCLES

Refer to figure 3-10 for timing information concerning the signals in the following discussion.

Whenever a refresh cycle is in progress, the memory cannot service a request for a memory cycle. Instead, the memory card must store the data and address for the requested memory cycle, allow the refresh cycle to complete, and then perform the suspended memory cycle.

When a refresh cycle is in progress, the MEGO flip-flop (U611) is enabled to monitor requests for memory cycles. This results from U410-10 being low, allowing SCLK+ to clock the MEGO flip-flop. When a MEMGO- is received, the MEGO flip-flop is set and it immediately sets the BUSY flip-flop. This prevents any subsequent requests for memory cycles until the present cycle is serviced.

As in a normal memory cycle, the DI+ and AD CLK- signals occur one FCLK cycle after BUSY is set and latch in the data and address.

After the refresh cycle completes, a memory cycle is initiated immediately (U69-11 goes low because the MEGO flip-flop (U611) is set). The memory cycle proceeds in normal fashion, with the MEGO flip-flop being reset on the QD pulse from the shift register (U66). Note that QD could not reset MEGO during the refresh cycle because U59-4 was held low at this time.

3.7.12 REFRESH CYCLES OCCURRING DURING MEMORY CYCLES

When a memory cycle is in progress, refresh cycles are held off. This results from the BUSY- signal appearing at U510-1, disabling the RP signal from appearing at the Refresh Start flip-flop (U613).

When the BUSY signal is released at the end of the memory cycle, RS and RC are asserted at the next falling edge of SCLK- so that a refresh cycle can start immediately.

Refresh cycles can only be held off for one memory cycle by the above sequence, and thus cannot be held off indefinitely by recurring memory cycles.

See figure 3-11 for timing details of refresh cycles occurring during memory cycles.

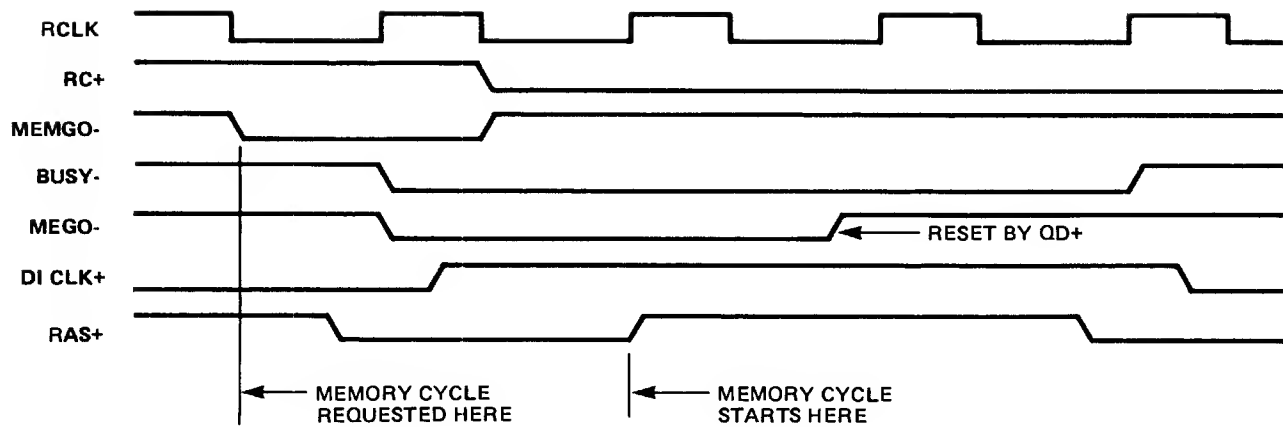


Figure 3-10. Refresh Cycle Holding off Memory Cycle

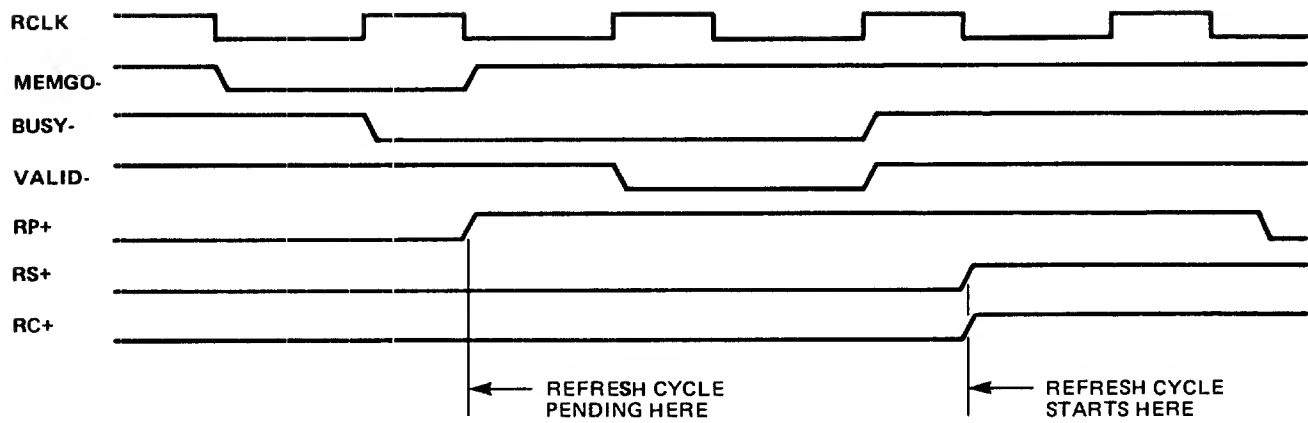


Figure 3-11. Memory Cycle Holding Off Refresh Cycle

3.7.13 PON INITIALIZATION

The PON+ signal is received by the memory card through a D type flip-flop (U57). When power is initially applied to the memory card, an RC time delay consisting of R12, C2, and U64 insures that the PON flip-flop initializes to the clear state.

Before PON+ appears on the backplane, the memory card is held in a reset state, that is, memory cycles cannot be initiated. Refresh cycles are performed, however, and will continue to do so in the absence of PON+ as long as +5M is present.

When PON+ appears on the backplane, it is clocked into the memory card by the refresh signal at U57-3. This enables the memory card for normal operation.

3.7.14 TEST POINTS AND DIAGNOSTIC FUNCTIONS

The memory card contains three power supply test points to verify the status of the -5M, +5M, and +12M voltages. These test points are located at the front of the memory card (see figure 3-12) and are isolated by series resistors to prevent accidental loading of the supply voltages.

TTL signals may be applied to the four locations listed below to check the refresh circuit function on the memory card.

LOCATION	DESIGNATION	DESCRIPTION
U54-1	REF DIS-	A ground on this test point will cause the refresh circuit to stop functioning. Used with EXT RO- to vary refresh oscillator rate.
U510-4	EXT RO-	An external oscillator may be applied at this point (with a ground connected to REF DIS-). The external oscillator will then be considered the refresh oscillator by the memory.
U17-9	OSC-	A ground on this point will not stop refresh cycles but will prevent the generation of incremental row addresses.
U67-3	INIT-	A ground on this point will reset the refresh counter and refresh generator to their initial state.

3.8 PARTS LOCATIONS

Parts locations for the memory card are shown in figure 3-12.

3.9 PARTS LIST

The parts list for the memory board is shown in table 3-1. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

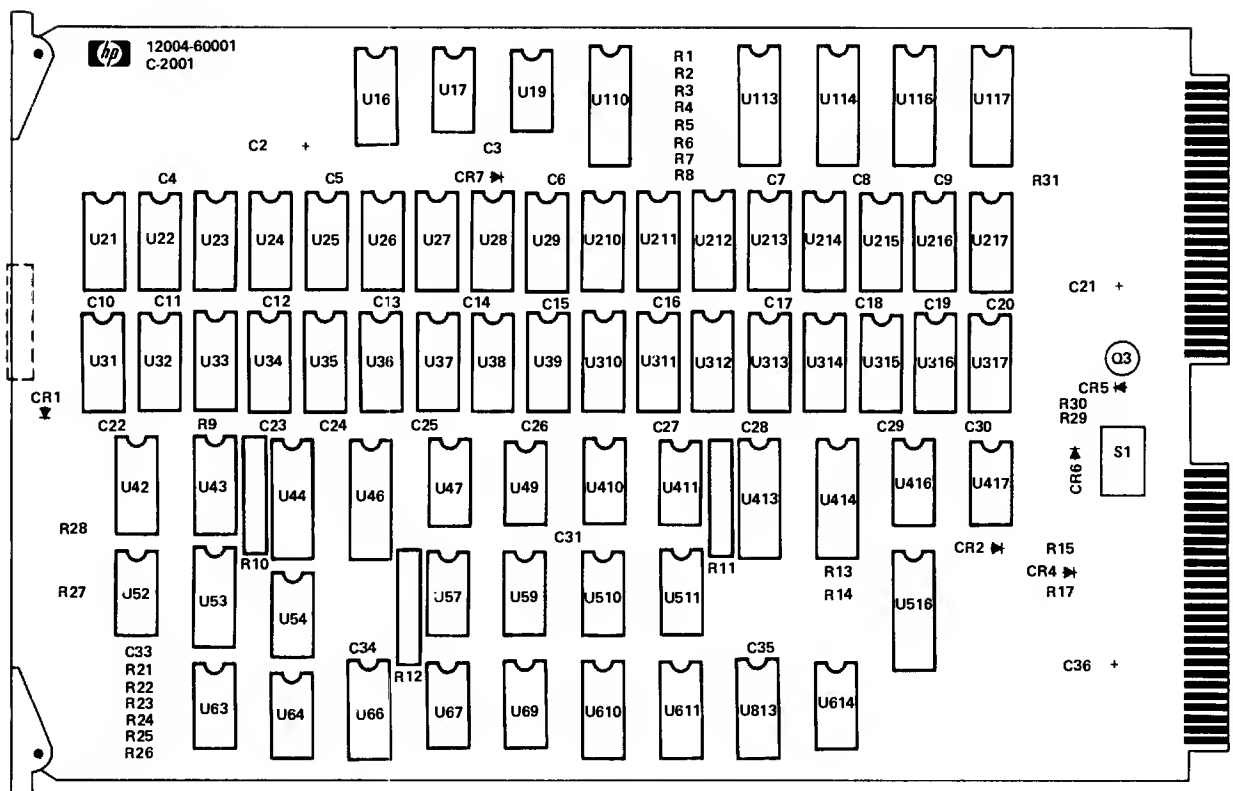


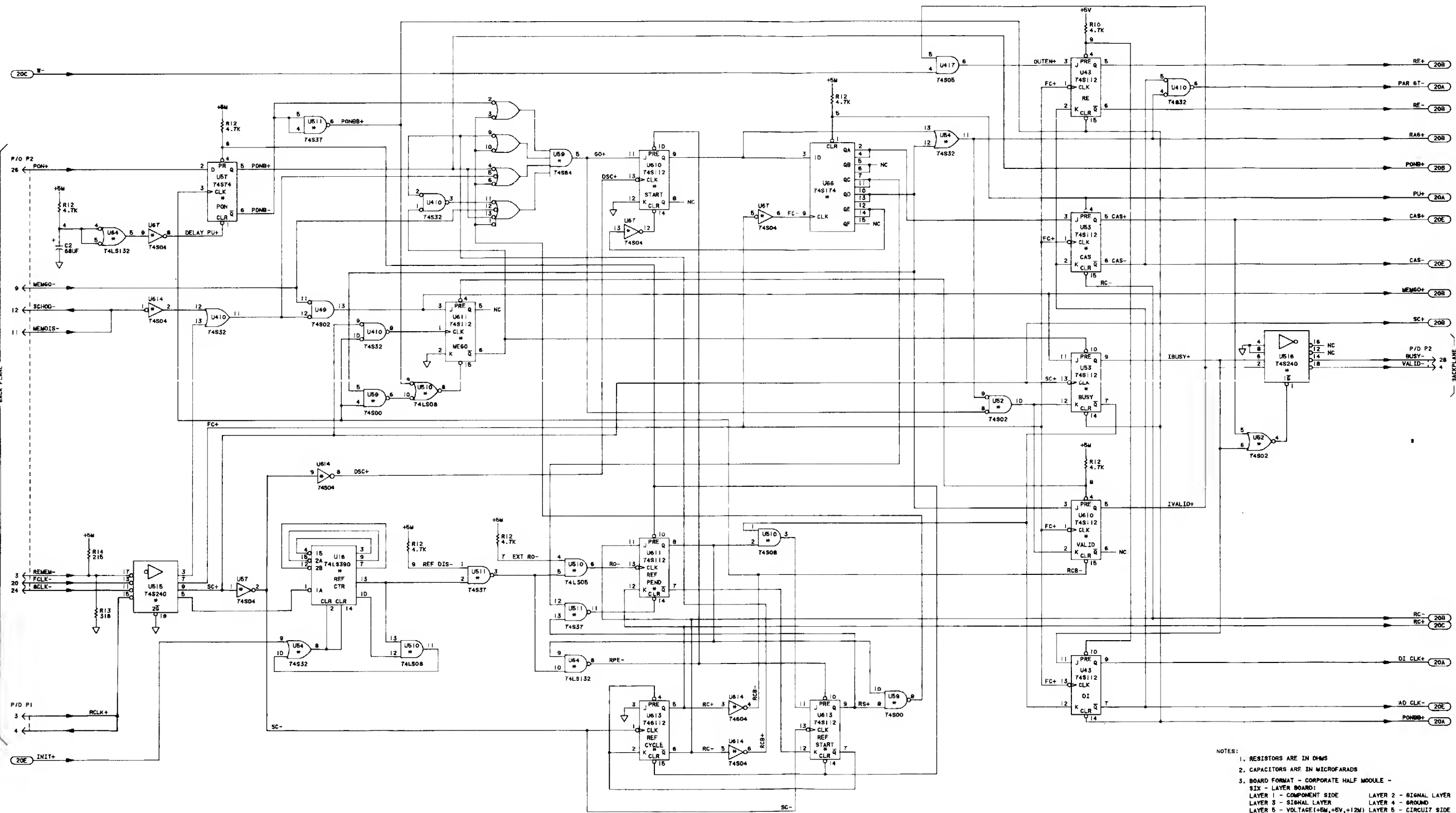
Figure 3-12. Memory Card Parts Locations

Table 3-1. Memory Card Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12004-64001	2	1	ASSEMBLY-64KB MEMORY	28480	12004-64001
C3	0160-4842	6	31	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C4	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C5	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C6	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C7	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C8	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C9	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C10	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C11	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C12	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C13	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C14	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C15	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C16	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C17	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C18	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C19	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C20	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C22	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C23	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C24	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C25	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C26	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C27	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C28	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C29	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C30	0160-4042	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C31	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C33	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C34	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C35	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
CR1	1990-0485	5	1	LED-VISIBLE LUM-INTE800UCD IF=30MA=MAX	28480	5082-4984
CR2	1901-0731	7	1	DIODE-PWR RECT 400V 1A	28480	1901-0731
CR4	1902-3105	8	1	DIODE-ZNR 5.6V 2% DO-35 PD= 4W	28480	1902-3105
CR5	1902-3114	8	1	DIODE-ZNR 6.19V 2% DO-35 PD= 4W	28480	1902-3114
CR7	1901-1080	1	1	DIODE-SCHOTTKY 1N5817 20V 1A	28480	1901-1080
Q3	1A54-0215	1	1	TRANSISTOR NPN SI PD=350MA FT=300MHZ	04713	2N3904
R1	0757-0294	9	11	RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R2	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R3	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R4	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R5	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R6	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R7	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R8	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R9	0693-3447	4	6	RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R10	0693-0279	5	3	NETWORK RES 10-SIP4.7K OHM X 9	01121	2104472
R11	1A10-0279	5		NETWORK RES 10-SIP4.7K OHM X 9	01121	2104472
R12	1A10-0279	5		NETWORK RES 10-SIP4.7K OHM X 9	01121	2104472
R13	0693-3444	1	1	RESISTOR 316 1% .125W F TC=0+-100	24546	C4-1/B-T0-316R-F
R14	0693-3441	8	2	RESISTOR 215 1% .125W F TC=0+-100	24546	C4-1/B-T0-215R-F
R15	0693-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R17	0693-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R21	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R22	0693-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R23	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R24	0693-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R25	0757-0294	9		RESISTOR 17.8 1% .125W F TC=0+-100	19701	MF4C1/B-T0-17RB-F
R26	0693-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/B-T0-422R-F
R27	0757-0280	3	2	RESISTOR 1K 1% .125W F TC=0+-100	24546	C4-1/B-T0-1001-F
R28	0757-0280	3		RESISTOR 1K 1% .125W F TC=0+-100	24546	C4-1/B-T0-1001-F
R29	0757-0417	8	1	RESISTOR 562 1% .125W F TC=0+-100	24546	C4-1/B-T0-562R-F
R30	0693-3441	8		RESISTOR 215 1% .125W F TC=0+-100	24546	C4-1/B-T0-215R-F
R31	0693-3155	1	1	RESISTOR 4.64K 1% .125W F TC=0+-100	24546	C4-1/B-T0-4641-F

Table 3-1. Memory Card Parts List (Continued)

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
S1	3101-0642	5	1	SWITCH=SLIDE, DPDT	28480	3101-0642
U16	1A20-1991	1	1	IC CNTR TTL L8 DECD DUAL 4=BIT	01295	8N74LS390N
U17	1A20-0685	8	1	IC GATE TTL 8 NAND TPL 3=INP	01295	8N74810N
U19	1A20-1989	7	1	IC CNTR TTL L8 BIN DUAL 4=BIT	07263	74LS393PC
U21	1A18-0341	8	30	IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U22	1A1A-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U23	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U24	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U25	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U26	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U27	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U28	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U29	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U31	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U32	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U33	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U34	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U35	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U36	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U37	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U38	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U39	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U43	1A20-0629	0	5	IC FF TTL 5 J=K NEG-EDGE=TRIG	01295	8N748112N
U44	1A20-1624	7	2	IC RFR TTL 8 DCTL 1=INP	01295	8N748291N
U46	1A20-1677	0	2	IC FF TTL 5 D=TYPE DCTL	01295	8N748374N
U47	1A20-1638	3	2	IC GEN TTL 5 PAR GEN 9=BIT	01295	8N748280N
U49	1A20-1322	2	2	IC GATE TTL 5 NDR QUAD 2=INP	01295	8N74802N
U52	1A20-1322	2		IC GATE TTL 5 NDR QUAD 2=INP	01295	8N74802N
U53	1A20-0629	0		IC FF TTL 5 J=K NEG-EDGE=TRIG	01295	8N748112N
U54	1A20-1449	4	2	IC GATE TTL 5 DR QUAD 2=INP	01295	8N74832N
U57	1A20-0693	8	1	IC FF TTL 5 D=TYPE PDS-EDGE=TRIG	01295	8N74874N
U59	1A20-06A1	4	1	IC GATE TTL 8 NAND QUAD 2=INP	01295	8N74800N
U63	1A20-1451	8	1	IC GATE TTL 8 NAND QUAD 2=INP	01295	8N74838N
U64	1A20-1425	6	1	IC SCHMITT=TRIG TTL L3 NAND QUAD 2=INP	01295	8N74LS132N
U66	1A20-1076	3	1	IC FF TTL 5 D=TYPE PDS-EDGE=TRIG CLEAR	01295	8N748174N
U67	1A20-06A3	6	2	IC INV TTL 5 HEX 1=INP	01295	8N74804N
U69	1A20-0691	6	1	IC GATE TTL 5 AND=DR=INV	01295	8N74864N
U110	1A20-1917	1	1	IC RFR TTL L3 LINE DRVR DCTL	01295	8N748240N
U113	1A20-1633	8	3	IC RFR TTL 5 INV DCTL 1=INP	01295	8N748240N
U114	1A20-1633	8		IC BFR TTL 5 INV DCTL 1=INP	01295	8N748240N
U116	1A20-2184	6	2	IC LCM TTL 5 DCTL	50364	748373N
U117	1A20-2184	6		IC LCM TTL 5 DCTL	50364	748373N
U210	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U211	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U212	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U213	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U214	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U215	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U216	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U217	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U310	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U311	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U312	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U313	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U314	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U315	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U316	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U317	1A18-0341	8		IC NMDS 16384=BIT RAM DYN 200=NS 3=8	0003J	UPD4160=2
U410	1A20-1449	4		IC GATE TTL 5 DR QUAD 2=INP	01295	8N74832N
U411	1A20-115A	2	1	IC GATE TTL 5 AND=DR=INV DUAL 2=INP	01295	8N74851N
U413	1A20-1624	7		IC BFR TTL 5 DCTL 1=INP	01295	8N748241N
U414	1A20-1677	0		IC FF TTL 5 D=TYPE DCTL	01295	8N748374N
U416	1A20-1638	3		IC GEN TTL 5 PAR GEN 9=BIT	01295	8N748280N
U417	1A20-1167	5	1	IC GATE TTL 5 AND QUAD 2=INP	01295	8N74808N
U510	1A20-1201	6	1	IC GATE TTL L8 AND QUAD 2=INP	01295	8N74LS08N
U511	1A20-1450	7	1	IC BFR TTL 5 NAND QUAD 2=INP	01295	8N74837N
U516	1A20-1633			IC BFR TTL 5 INV DCTL 1=INP	01295	8N748240N
U610	1A20-0629			IC FF TTL 5 J=K NEG-EDGE=TRIG	01295	8N748112N
U611	1A20-0629			IC FF TTL 5 J=K NEG-EDGE=TRIG	01295	8N748112N
U613	1A20-0629			IC FF TTL 5 J=K NEG-EDGE=TRIG	01295	8N748112N
U614	1A20-06A3			IC INV TTL 5 HEX 1=INP	01295	8N74804N



NOTES:

1. RESISTORS ARE IN OHMS
2. CAPACITORS ARE IN MICROFARADS
3. BOARD FORMAT - CORPORATE HALF MODULE -
SIX - LAYER BOARD:
LAYER 1 - COMPONENT SIDE
LAYER 2 - SIGNAL LAYER
LAYER 3 - SIGNAL LAYER
LAYER 4 - GROUND
LAYER 5 - VOLTAGE (+5V, +12V)
LAYER 6 - CIRCUIT SIDE
4. * DESIGNATES IC'S POWERED BY +5V

POWER SUPPLY	SECTION IV
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4.1 INTRODUCTION

The Hewlett-Packard HP 12035A Power Supply provides the necessary regulated voltages and power control logic signals for the HP 1000 L-Series Computer System.

4.2 PHYSICAL CHARACTERISTICS

The HP 12035A Power Supply consists of three assemblies, as follows:

A1	D-12035-60002-51	250W Mother Board
A1A1	D-12035-60003-51	Driver Board
A1A2	D-12035-60004-51	Logic Board

In addition to the assemblies listed above, the L-Series Computer System includes a battery back-up card. This assembly is covered in Section V of this document.

The power supply slides into the front of a 5-1/4 inch high rack as shown in figure 4-1. A male connector on the rear of the power supply mates with female connectors on the computer backplane. A front power panel contains a power cord receptacle (J1), a fuse post (F1), line selector switch (S2), a 25kHz output jack, an external fan power jack (J3), and the power control logic connector (J4).

4.2.1 INPUT POWER CONNECTOR

The input power connector (J1) is a standard 3-pin power cord receptacle. The connector is UL/CSA listed and is rated at 15 amperes.

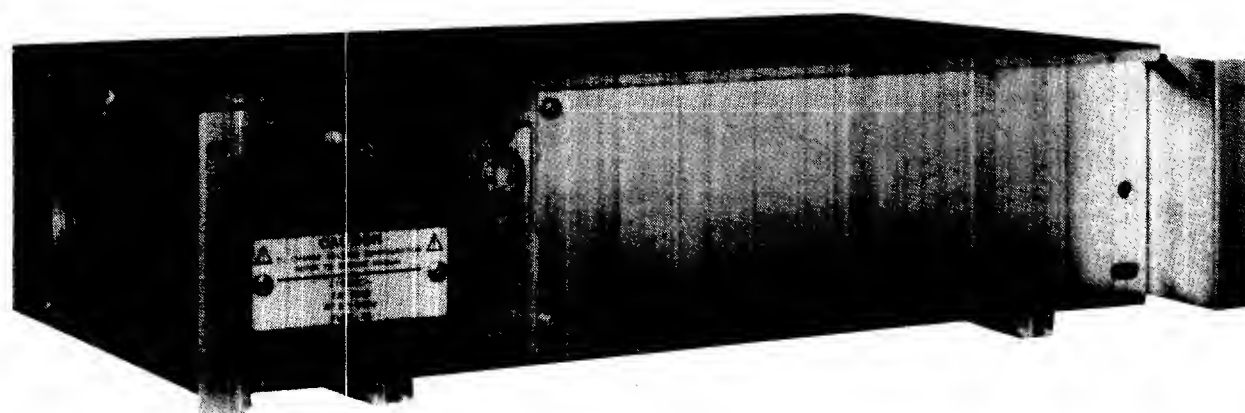


Figure 4-1. HP 12035A Power Supply

4.2.2 BACKPLANE INTERFACE OUTPUT CONNECTOR

The backplane interface connector is a dual male connector designed to mate with one 20-pin female connector one 4-pin female connector.

Pin assignments for the backplane interface connector are as follows:

PIN	SIGNAL NAME
1	-12V MEMORY VOLTAGE SENSE
2	+12V MEMORY VOLTAGE SENSE
3	+12V LOGIC (4A MAX)
4	-12V LOGIC (2A MAX)
5	+5V MEMORY VOLTAGE SENSE
6	NOT USED
7	NOT USED
8	POWER ON (PON) SIGNAL
9	POWER FAIL WARNING (PFW) SIGNAL
10	+5V LOGIC (30A)
11	
12	
13	
14	
15	DC COMMON, 25kHz COMMON, AND CHASSIS GROUND
16	
17	
18	
19	
20	
21	
22	
23	25kHz PHASE 2, 14VRMS (TO GND)
24	25kHz PHASE 1, 14VRMS (TO GND)

4.2.3 SINGLE-PHASE 25KHZ OUTPUT CONNECTOR

The front-panel mounted, single-phase 25kHz output connector (J13) is a 3-pin connector (part number 1251-2164) rated at 15 amperes. For best regulation, shielded 14 gauge, twisted pair wire is recommended.

4.2.4 POWER CONTROL CONNECTOR

The power control connector (J4) is used for the external logic signals Line Power Up (LPU), Power Supply Up (PSU), and the SYNC signal used when power supplies are connected in parallel for both CPU's and peripherals. The pin assignments are as follows:

PIN	SIGNAL NAME
1	N/C
2	N/C
3	100kHz SYNCHRONIZATION INPUT
4	LOGIC GROUND
5	LINE POWER UP (LPU)
6	N/C
7	POWER SUPPLY UP (PSU)
8	SHIELD GROUND
9	N/C

4.2.5 EXTERNAL FAN CONNECTOR

The external fan connector (J3) provides 115V -25%/+10%, 15 watts maximum, for an external fan. Phasing is unnecessary.

4.2.6 INDICATORS

Three LED indicators are located at the lower right hand corner of the front of the power supply and can be observed through an oval aperture. These indicators indicate the status of the power supply under normal and malfunctioning conditions, as shown on the next page.

NOTE

A lit indicator is shown as an asterisk, an unlit indicator is shown as a zero.

LINE	FAULT	OPER.	
(GREEN)	(RED)	(GREEN)	
0	0	0	No line voltage. Check for blown fuse, no line cord, poor line cord connection, or dead line voltage circuit.
*	0	0	AC line voltage but no DC voltage at the output of the supply. Check to see if the Test-Operate switch is in the OPER position. If OK, replace the drive board or the logic board.
*	*	0	Line voltage present but a fault has occurred such as an over voltage or over current condition. Check the line voltage versus the line voltage range selected. Also check for shorted outputs. The AC switch must be cycled (turned OFF then back ON) to restore normal operation after the fault is corrected.
*	0	*	Normal operation. All six DC voltages and maximum load currents are within specified limits.

4.3 SPECIFICATIONS

Specifications for the HP 12035A Power Supply are listed in table 4-1.

Table 4-1. Specifications

INPUT VOLTAGE: 2 ranges, selectable at power supply front panel. 115V Selector Position: 86 to 127 VRMS, 47 to 66 Hz 230V Selector Position: 195 to 253 VRMS, 47 to 66 Hz
POWER FACTOR: 0.65, full load
SURGE CURRENT: Less than 15 amperes from cold start. Less than 20 amperes after one minute down time, then restart.
INPUT CURRENT, FUSING: 3AG normal blow; 7.0 amperes for 115V range, 3.0 amperes for 230V range.
POWER INPUT, NO LOAD: Less than 40 watts (includes internal fan).
EXTERNAL FAN POWER: Up to 15 watts @ 86 to 127 VRMS.

Table 4-1. Specifications (Continued)

<p>TRANSIENT SUSCEPTIBILITY:</p> <p>Positive or negative spikes on the differential or common mode of up to 1KV with 30 nsec rise and 375 nsec duration, at a repetition rate of once per hour, will not cause damage nor interruption to operation.</p> <p>Longer transients of up to 500V with rise time of 250 nsec and duration of up to 50 usec at repetition rates not to exceed 10 per year will not cause damage. Hard shutdown may occur; this can be reset by cycling the power switch.</p>
<p>CONDUCTED RFI BACK ON LINE INPUT:</p> <p>Below Level A VDE conducted and radiated RFI specifications.</p>
<p>POWER INTERRUPTIONS:</p> <p>Line voltage detector monitors the peak-to-peak value of line voltage. At nominal line voltage on either range, the Power Fail Warning (PFW low) will be generated if the line voltage drops to zero for 20 msec or greater (approximately one cycle).</p> <p>At other line voltages, the minimum dropout times to PFW are as follows:</p> <p>86VAC: greater than 5 msec</p> <p>195VAC: greater than 10 msec</p> <p>230VAC: greater than 25 msec</p>
<p>LINE VOLTAGE SAG:</p> <p>An instantaneous drop in line voltage within the allowable range may cause PFW to go low, but Power On (PON) will not be pulled low. Such a sag must exceed -30% drop to generate PFW. Steady state sags below minimum range will generate PFW continuously low, although a critical boundary condition can cause PFW to cycle at a 3 msec low minimum and a maximum repetition rate of 120 pps. Under these conditions, PON will remain high.</p>

Table 4-1. Specifications (Continued)

LINE VOLTAGE SURGE:

Surge voltages of up to 1.5 times the 115V or 230V range for 0.5 cycle every 5 seconds will not disturb normal operation, and will not generate power fail warning signals.

LINE OVER-VOLTAGE:

Application of line voltage of 2 times nominal for more than one second will blow the input fuse. The power supply can withstand this malfunction for up to 100 times during its life before component failure, if not repeated at less than one hour intervals. This feature is primarily to protect against inadvertent application of a 220/230V line while configured to 115V range.

OUTPUT VOLTAGES, CURRENTS, TOLERANCES, AND PARD:

(PARD = Periodic And Random Deviation, 10Hz to 500kHz, measured with differential probes (HP 1806A/180, or equivalent) at output connector.)

DC OUTPUT VOLTAGES, TOLERANCES, AND PARD:

+5V +/-2% PARD 50mV nominal; 300mV maximum

+12V +/-6% PARD 100mV maximum

-12V +/-6% PARD 100mV maximum

AC OUTPUTS: 25kHz SINE-WAVE POWER:

1. SPLIT PHASE, 3 pins on rear connector, 19.5VRMS +/-8% each phase with conditional output up to 5ARMS maximum.
2. SINGLE PHASE, 2 pins on front connector, 27VRMS +/-8% conditionally up to 12ARMS maximum (one line is chassis ground).

NOTE: Refer to appendix B for application information.

Table 4-1. Specifications (Continued)

<p>MAXIMUM POWER/CURRENT OUTPUT RATINGS:</p> <p>HP 2103L: +5V @ 25 ADC +12V @ 4 ADC -12V @ 2 ADC 25kHz (either port or sum of both) 70 watts</p> <p>HP 1000 L-Series System: +5V @ 30 ADC +12V @ 3 ADC -12V @ 1.5 ADC 25kHz (either port or sum of both) 140 watts</p>
<p>INLET TEMPERATURE:</p> <p>HP 2103L: 0 to 55 degrees Centigrade to 15,000 feet (4572 metres)</p> <p>HP 1000 L-Series System: 0 to 55 degrees Centigrade to 10,000 feet (3048 metres), with linear derating to 45 degrees Centigrade at 15,000 feet (4572 metres).</p>
<p>MINIMUM INLET AIR FLOW RATE:</p> <p>Minimum flow rate of 20 CFM @ 200 feet/minute velocity (43 BTU/hour)</p>
<p>SYNCHRONIZATION INPUT:</p> <p>1 to 12V peak-to-peak, 100nsec minimum pulse width at 100kHz +/-1% synchronizes internal switching frequency to external clock.</p>
<p>POWER CONTROL LOGIC SIGNALS (INPUTS):</p> <p>LPU (Line Power Up), High True. Can be connected in parallel with other supplies in system (+5V logic level).</p> <p>PSU (POWER SUPPLY UP), High True. Can be connected in parallel with other supplies in system (+5V logic level).</p>

Table 4-1. Specifications (Continued)

LOGIC SIGNALS FOR CPU USE (OUTPUTS):

PFW (Power Fail Warning), Low True; warns CPU of failing power. All voltages are held within specified tolerance for 5 msec after this signal goes low. 100mA sink capability, open collector TTL. Rise and fall times less than 50 nsec.

PON (POWER ON), High True; goes high after all DC voltages are up and within regulation. Stays high for 5 msec after PFW goes low at which time all output voltages must be within their tolerances. 100mA sink capability, open collector TTL. Rise and fall times less than 50 nsec.

SHORT CIRCUIT PROTECTION:

All DC and AC power outputs are fault protected for short circuits. Supply will shut down, lighting the FAULT light, if the output is shorted. To reset, the AC power switch must be cycled (turned OFF for 5 seconds, then ON). If the output short persists upon re-turn on, the FAULT light will come back on.

OUTPUT UNDER-VOLTAGE AND OVER-VOLTAGE PROTECTION:

+5V output is sensed for over voltage. If +5V exceeds 6.5V, supply will shut down. (This can occur if the Vout potentiometer setting is too high.) To reset, the AC power switch must be turned OFF, then ON.

4.4 BINARY SIGNAL LEVELS

Most of the logic used in the power supply is implemented with standard CMOS or Schottky TTL devices. Schottky TTL high logic levels are approximately +2.5 to +4.5 Vdc; low logic levels are approximately 0.0 to +0.8 Vdc. CMOS levels are less than 1 Vdc (logic low) or greater than 11 Vdc (logic high). The actual values measured will vary due to the type of device, the load, and the condition of the device. When using positive logic, a high is "true" and a low is "false".

4.5 THEORY OF OPERATION

The HP 12035A power supply provides three DC output voltages for DC power to the backplane, and two sine-wave high frequency (25kHz) power output ports to power the system peripherals. The power supply operates from 50 to 60 Hz primary power over a wide range of input voltages (see table 4-1) selected by a two-position selector switch on the front panel.

A functional block diagram of the power supply is shown in figure 4-2. Also see the schematic diagram, drawings 12035-60002, 12035-60003, and 12035-60004, located at the rear of this section.

The basic operation is described in the following paragraphs (refer to the mother board schematic diagram, 12035-60002).

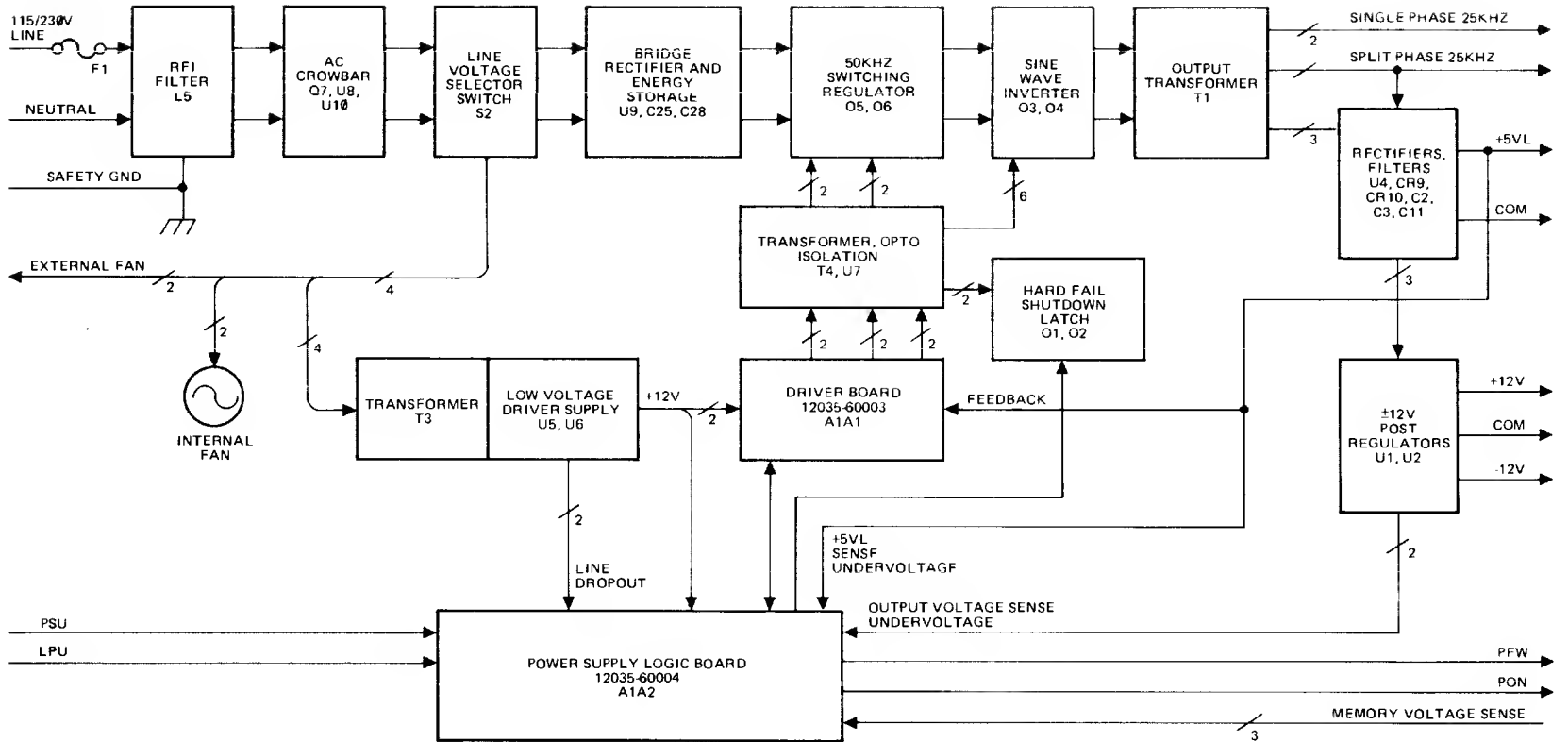
4.5.1 MOTHERBOARD (PART NUMBER 12035-60002)

The schematic diagram for the motherboard is shown in drawing 12035-60002. A photograph of the motherboard is shown in figure 4-3. The motherboard contains a low voltage driver supply, RFI filter, input AC crowbar, bridge rectifier, 50kHz switching regulator, sine-wave inverter, and an output rectification section consisting of rectifiers, filters, and post regulators.

4.5.1.1 Low Voltage Driver Supply

The low voltage driver supply powers the drivers and regulation loop so that this circuitry can be referenced to system ground (i.e., isolated from the line and neutral). The dual primary step-down transformer, T3, also functions as a 2-to-1 step-down auto transformer for operating 115V fans when operating on 195 to 253 VRMS line potentials. It is designed to power the internal 115V fan and one external fan of equal power (+/-5 watts) for cooling the card cage.

Figure 4-2. HP 12035 Power Supply Functional Block Diagram



7700-561

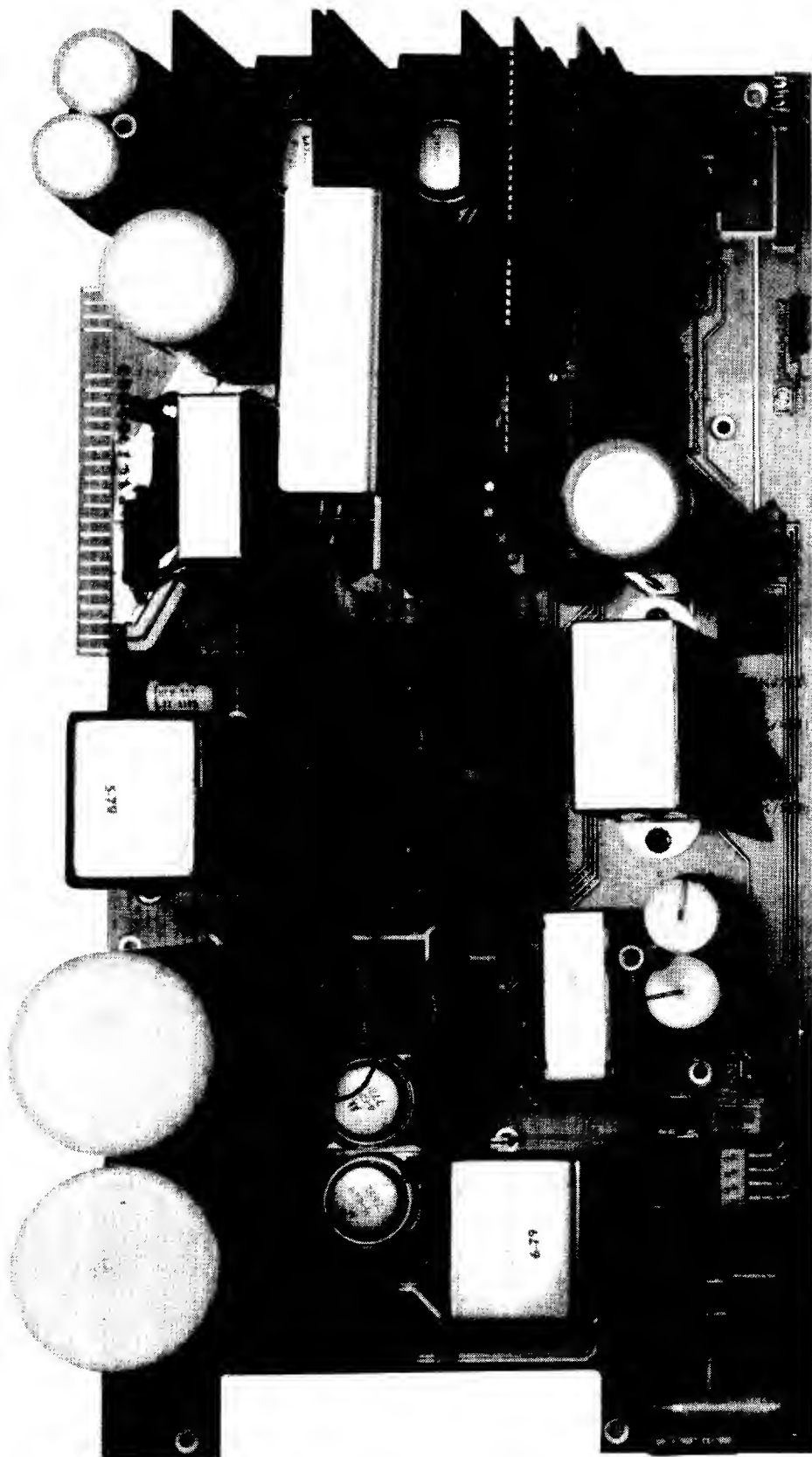


Figure 4-3. Motherboard (12035-60002)

The design is a conventional capacitive input bridge supply with one exception: A sensor is required for the computer to recognize power cycle dropouts and low line conditions. An additional single rectifier diode, CR5, combined with a capacitor, C14, and circuitry on the logic card provide this detection. The differential voltage is sensed across C14 with a discharge time constant of 55 msec with the discharge path on the logic card. As long as 50/60 Hz is present, the full-wave rectifier will charge the capacitive input filter, C17, with 100/120 Hz pulses of current through CR5 in parallel with C14. If a cycle should drop out, C14 will be discharged. Reverse polarity across C14 will turn on a differential comparator on the logic board, thus providing a warning signal, Soft Fail Shutdown (SFS), to the CPU.

The output of the capacitive input filter is 17 to 35 VDC over the line variations, which feeds a +12V three-terminal regulator U5. The current consumption of the driver and logic board from this supply is approximately 250 mA.

4.5.1.2 Input Crowbar, RFI Filter and Line Rectifier

The principle of a line switching power supply uses direct rectification of the line voltage without an input transformer to reduce size and weight of the supply. To utilize the two line ranges of nominally 115V and 230V RMS, a bridge rectifier is switched from a full-wave bridge to a full-wave doubler into a pair of electrolytic input filter capacitors (C25, C28). Switch S2 provides this switching function as well as the switching of the primaries of T3 from series to parallel for the two ranges. This results in nominally 300 VDC across the two large energy storage electrolytic capacitors C25 and C28 in series. The switching regulator uses this voltage as the input to transform down to +150 by pulse-width modulation at 50 kHz. This 50 kHz load current flows through C25 and C28. Because their 50 kHz impedance consists mostly of the equivalent series resistance at that frequency (which is not particularly low), some 50 kHz voltage (ripple) appears across these storage capacitors. To keep this high frequency ripple from conducting back into the mains, a differential RFI filter is incorporated. This consists of a dual choke, L5, and a capacitor, C29, across the input. Two capacitors (C30, C31) from line and neutral to case ground also are used to attenuate the common mode capacitively-coupled high frequency.

An AC crowbar consisting of a triac (Q7) and a pulse-rated (watt-second) resistor (R31) in series is connected across the line to neutral. The triac is triggered by an opto-coupled SCR (U8) through bridge rectifier U10, to provide full-wave triggering of the triac, thus providing 1/2 cycle response (8.33 to 10 ms for 60/50 Hz, respectively) time.

The purpose of the AC crowbar is to blow the input fuse (normal blow 3AG) upon sensing an over-voltage condition across the two storage capacitors or into the sine-wave inverter. (See paragraphs 4.5.1.3 and 4.5.1.4). The worst case fuse is the 7 ampere fuse used on the 115V line which must hold for low line of 86 VRMS and full power output (approximately 7.0 amperes RMS). This 7 ampere

3AG normal blow fuse will blow in approximately 70 msec at a nominal voltage of 230 VRMS. The peak blowing current is 46 amperes with the triac actuated. With the normal drops via the input line impedance, the voltage is dropped significantly to stop charging the storage capacitors to a voltage that would exceed their surge voltage rating, thus protecting against capacitor failures. The over voltage is sensed by two 200V zener diodes (CR16, CR18) which limit the voltage to an absolute maximum of 420V. The 200V zener diodes the SCR opto diode (U8) to allow isolation and power gain so that small diodes can be used. This circuit thus protects against inadvertent application of 230 VRMS at the input to the supply while on the 115V selected range.

Another mode of over voltage is encountered if the switching regulator transistors (Q5, Q6) fail to turn off (shorted emitter to collector). This causes the inverter input voltage to increase by a factor of about 2, which would cause the +5 volt logic voltage to increase to approximately 10 volts, causing severe damage to the logic loads. Another zener diode of 200V (CR17) is used back to the opto SCR from the output of the switching regulator. Because this failure could happen under normal operation due to a defective transistor, a transient over voltage of the +5V logic could be possible, even though the fuse will be blown. For this reason, pulse-rated ("Transorb") zener diodes are used on all cards with the +5V logic voltage.

4.5.1.3 Switching Regulator

The switching regulator consists of the high voltage power switching transistors Q5 and Q6, diode CR13, inductor L4 and two series 5uF output capacitors C24 and C27. The driver transformer (T4) is a dual unit which isolates the drive circuitry on the driver board from the line-operated power switches, and provides the base currents with variable on and off times. Diodes CR14 and CR15 are used across the base-to-emitter junctions of the power transistor switches (Q5, Q6) to provide a bi-directional termination for the driver transformer(s) to sink the turn off current (IB2) after the stored charge has been removed from Q5 and Q6. The primary of the driver transformer is driven by a tri-level waveform which consists of a turn-on base current of 250mA minimum for a period of time between zero and ten microseconds, determined by the feedback control voltage. At the end of the "on" period the drive current reverses (in less than 100 nsec) to an equal current for a nearly equal amount of time in the reverse polarity direction. This allows -250mA minimum to flow from the switching transistor base to remove the minority carriers stored, and turn the transistor off quickly. This takes between 1.0 to 2.5 microseconds to accomplish, depending on transistor characteristics and the particular loading conditions of the supply. The turn-off time is made slightly longer than the turn on time in the driving tri-level waveform to assure proper turn off.

The areas of the turn-on and turn-off waveforms are approximately the same and of opposite polarity, such that when passed through the driver transformer they do not cause appreciable residual flux, which would lower the transformer's permeability. The net result of using this tri-level waveform is to allow suitable drive to the switching transistors while maintaining low transient losses, and also allowing small driver transformers to be used. Small transformers help to reduce common mode EMI coupling by maintaining a low primary-to-secondary capacitance.

At full control voltage, the drive waveform to each switching transistor is a square wave with equal on and off times. This allows each switching transistor to provide a 0 to 50 percent duty cycle to control the input-voltage-to-output-voltage ratio of infinite step down up to 2-to-1 step down. To allow up to 1-to-1 transformation, however, the switching transistors are in parallel and are driven 180 degrees out of phase, such that when one unit is fully off, the other is fully on, and vice versa. This causes the switching rate to increase to 50kHz, yet each device is only operating at 25kHz. The parallel combination and the 180 degrees drive relationship then provide a switching regulator capable of a 0 to 100 percent duty cycle (or 1:0 to 1:1 transformation of V_{in}/V_{out}). This allows regulation over a very large variation in input line voltage.

The ratio for the 115V range is 86V to 127V or 1.48 to 1, and for the 230V range 195 to 253V or 1.30 to 1. Zero to full load variations add to this ratio requirement of the switching regulator to make it necessary to regulate over a 2 to 1 range of input voltage to output voltage.

The energy storage elements for the switching regulator are the inductor L4, and the two series-connector capacitors C24 and C27. The input of L4 is switched to +300V during the on-time and released during the off-time. When released, L4 tries to hold the current constant by producing counter EMF (reversing the polarity of voltage across L4), and causing CR13 to conduct. CR13, called a "catch diode", is a fast-recovery rectifier which conducts the inductor current during the off time. The load is taken off the output capacitors C24 and C27. Bleeder resistors across each of these capacitors minimize capacitive and load imbalances to provide a centertapped voltage supply for the half-bridge inverter that follows. The voltage across this center-tapped capacitor output will be about 150 to 170 VDC depending on load conditions and will have a few volts of 50kHz ripple under full load. The capacitors are of polypropylene dielectric construction to provide the low losses required for this application. Ripple currents of up to 4 amperes peak flow through these capacitors at 25kHz (full sine wave, 60 percent duty cycle).

For prevention of over current of the switching transistors while in the on-state, and of the SCR's in the sine-wave inverter (see paragraph 4.5.1.4) a parallel combination of two current sensing resistors, R20 and R21, is provided in the common leg, sensing the inductor current during the turn-on portion of the duty cycle. If this peak current flowing through the parallel sense resistors exceeds the forward voltage required to turn on the LED of the opto-isolator U7, the opto transistor is driven, which removes the drive to

the T4 primaries, and lights the FAULT LED (red). This condition is latched by Q1 and Q2, which requires the +12 volt low voltage bias supply to be turned off to release the latch (AC input switch recycling).

4.5.1.4 Sine-Wave Inverter

The sine-wave inverter consists of Q3 and Q4, which are high-frequency switching integrated thyristor rectifiers (ITR's, which are SCR's with integral reverse rectifiers across them) dual resonator inductor L3; resonator capacitor C19; current limiting capacitor C18; the output transformer T1; and the driver trigger transformer T2. The ITR's are triggered with a 7.5 to 8.5 usec trigger pulse of greater than 50mA, typically 100mA at 25kHz repetition rate, synchronized with the 50kHz switching regulator driver.

The frequency of resonance is set at about 1.35 times for ITR self-commutation turn off and to prevent excess dissipation.

The inverter is triggered immediately upon AC line turn on with the +12V bias supply. The switching regulator drive is delayed and ramped up at a rate of approximately six volts per millisecond. At turn off the drive is ramped down to provide a down ramp of 30 volts per millisecond from the switching regulator. This degausses the output transformer, so that upon subsequent turn on the output transformer will not be driven into saturation. The turn on "ramp-up" reduces the output surge current required to charge the rectifier-filter sections for +5 and +/-12 volt outputs. In addition to the ramp-up, C18 provides current limiting on the sine-wave inverter. Capacitors C20 and C22, and R16 and R19 are networks across the ITR's which limit the rate of voltage rise so as not to exceed 750 volts per usec.

The rate of current rise is a sine function limited by the resonance of the L3 inductor and C19, the resonating capacitor. The "Q" of the dual inductor L3 is in excess of 5 at the operating frequency to maintain low losses and good waveform purity.

Gate trigger current can be measured by utilizing the T2 transformer secondary loops and a clip-on current oscilloscope probe. External synchronization using test point E5 on the driver board should be used to observe the phase relationship between the two SCR triggers.

CAUTION

When making these measurements make sure that exposed metal of the current probe does not touch the SCR heat sink or circuit components. This circuitry is NOT ISOLATED from the primary line voltage.

4.5.1.5 Output Rectifiers, Post Regulators

Two secondary windings on T1, the output transformer, provide the AC voltages required for +5V and +/-12V rectification. A third winding provides a 25kHz sine-wave output port at about 27 VRMS for external point of load rectification and regulation. This winding is available at a front panel connector (J13). The single-phase output is grounded on one side for safety reasons. A twisted, shielded pair of 18 to 14 gauge wire is recommended for the transmission cable to minimize voltage drops and losses in regulation.

The +5V logic voltage is capable of providing 30 amperes output (150 watts), and uses Schottky rectifiers (CR9, CR10) for the highest possible efficiency. A center-tapped, full-wave rectifier circuit is used to minimize drops and the number of rectifiers required.

The forward voltage drops of the Schottky rectifiers, which vary with the +5V load current, are compensated by the loop feedback to the regulator and compared with a voltage reference. The loop then increases the inverter AC output to compensate for forward drops in the Schottky rectifiers and other DC drops in the 5V, 30 amp DC output circuit. The AC output and the rectified DC output from the U4 bridge rectifier vary as a function of +5VDC loading. For this reason and to reduce +/-12 volt load regulation and ripple variations, post regulators are used to regulate the +12 and -12 volt outputs. U1 and U2, two terminal fixed voltage regulators, regulate the +12 volt and -12 volt logic outputs, respectively.

The input voltage to the +12 and -12 volt regulators is rectified with a bridge rectifier used as two center-tapped rectifiers of opposite polarity. The winding feeding the bridge has its center tap terminated to the horizontal mounting frame of T1, which is +5V common ground. The positive and negative outputs of the bridge feed choke input filters to maintain 180 degrees conduction of the rectifiers and maintain a sine-wave with low harmonic content. Output surge current limiting at turn on is controlled by the current limiting capacitor C18 on the output of the inverter, and the ramp-up rate controlled by the driver board circuitry.

4.5.2 DRIVER BOARD (PART NO. 12035-60003)

The schematic diagram for the driver board is shown in drawing 12035-60003. A photograph of the driver board is shown in figure 4-4. The driver board contains a phase-lock type of oscillator (U14) operating at approximately 96kHz (adjustable by R5); a divide-by-4 counter stage (U24), a tri-level trigger generator and driver for the ITR's; a two-phase, tri-level waveform generator, duty cycle control and drivers for the switching regulator; and a

voltage regulator loop with low time constant reference and adjustment (R6) for the +5V.

4.5.2.1 VCO and Phase-Locked Loop Synchronization

A CMOS 4046 voltage controlled oscillator (VCO) and phase locked loop integrated circuit (U14) is used to provide a temperature stable frequency oscillator (approximately 0.03 percent per degree Centigrade), which is adjustable from 93 to 130kHz with potentiometer R5. Normally, this is set to about 96 kHz and is divided by 4 by counter U24 and connected to square-wave buffer (U23). The output of the square wave buffer is available at test point E2, and normally reads 24kHz, one fourth of the VCO frequency. Synchronization is provided by the phase-locked loop phase detector input to U24. The pre-amplifier into the detector accepts inputs from 300mV to the Vdd supply (12V) as a lockable input source. The loop filter consists of R23, C12, R8 and C13. The lock-up range is about 2:1; far in excess of what is necessary. It is designed to synchronize on a crystal-derived clock in the 100kHz range, and yet free run at an adjusted frequency approximately 5 percent below the synchronized input frequency.

4.5.2.2 SCR Gate Drive

The SCR gate drive circuit is used for triggering the ITR's. The square wave from U14 is divided by a divide-by-four (U24). The Q outputs from U24 (see figure 4-5) are buffered by U23 and drive differentiator capacitors C4 and C5, and the 22K ohm resistors in U43. (The time (T) is 16.5 usec.) The differentiators are set to zero by CR1 and CR5 at the end of each cycle. Each differentiator feeds an input of two voltage comparators (U21A, U21B) which are referenced on the opposite inputs with approximately 7.1 VDC. The sharp-rising waveform from the differentiator turns on the comparator output for a period equal to about 0.5T, at which time the voltage on the differentiator output decays to the 7.1 volt level. This forms a pulse at each output for each transition of the 25kHz square wave, which are equal and opposite in phase. These pulses are fed to the complementary CMOS drivers (U31, U41) which drive each end of the SCR trigger transformer (T2, located on the mother board). This results in a tri-level waveform as shown in figure 4-5. Each SCR will trigger only with positive current pulses. Therefore, each SCR will trigger on alternate polarities of the tri-level waveform.

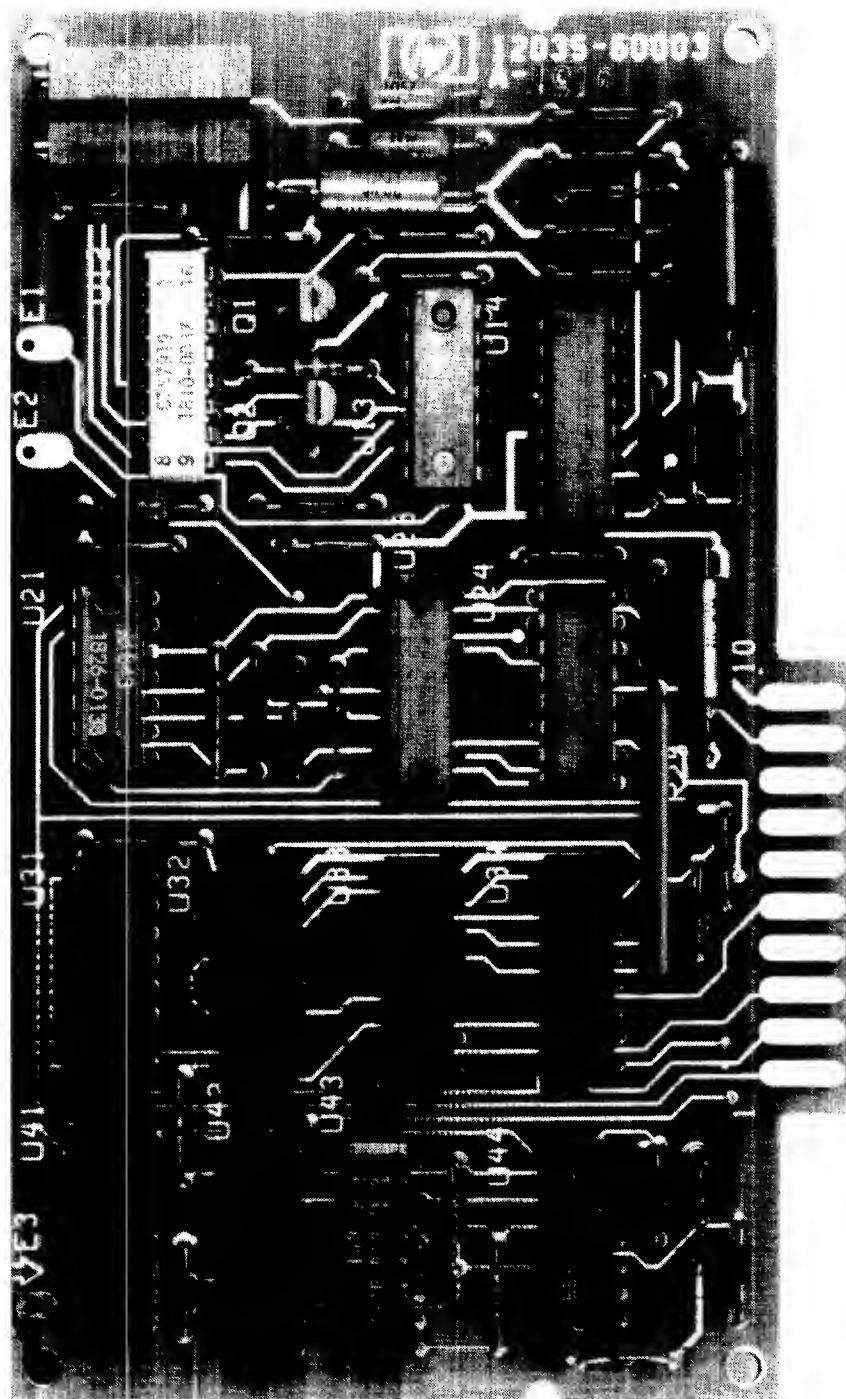


Figure 4-4. Driver Board (12035-60003)

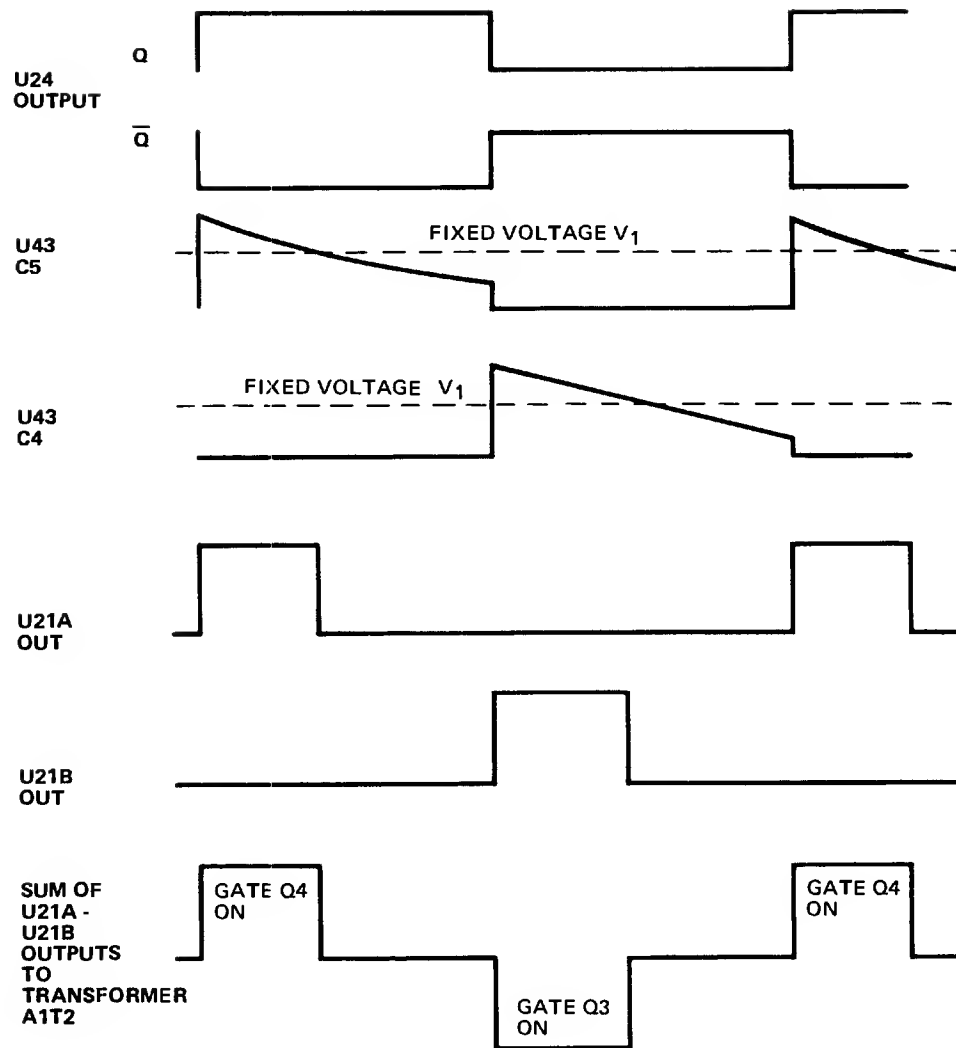


Figure 4-5. SCR Drive Waveforms

4.5.2.3 Switching Regulator Tri-Level Drive

The switching regulator transistors (Q5 and Q6 on the mother board) require a pulse-width controlled waveform that will provide a forward base current for a controlled period of time followed immediately with a reverse base current to turn the device off quickly by pulling out the minority carrier stored charge in the base region. In order to couple this drive to the bases of the switching transistors with small transformers, the time on must be approximately equal to the time off, or, in other words, the waveform must be symmetrically about zero volts to eliminate DC magnetizing current in the core and prevent core saturation.

To generate these waveforms both integrating and differentiating networks are used. In contrast to the SCR drive, the integrating networks provide the "on" time while the differentiating networks provide the "off" time. The same voltage reference is used on all comparators. Figure 4-6 shows the waveform generation.

In order to provide 0 to 100 percent duty cycle, each drive will provide 0 to 50 percent duty cycle phased 180 degrees out of phase at 25kHz with the other. Each switching transistor operates at 25kHz, yet the overall switching rate for the circuit is 50kHz. Storage time in the high-voltage switching transistors in this circuit is unimportant because the control will compensate for storage time and there is a complete one-half cycle to turn the device off in the worst case.

The value of L4 is 1.0 mHenrys at 3 amperes DC. This limits the peak current to less than 3 amperes for the "worst case" off time. Both of the switching transistors Q5 and Q6 must conduct this current as well as the "catch diode" CR13.

Polypropylene capacitors C21 and C27 are used for the switching regulator output to maintain low losses with large current charges at high frequencies.

4.5.2.4 Loop Regulator

To provide the loop gain and the stabilized reference voltage, a μ A723 voltage regulator integrated circuit (U13) is used. The internal reference voltage is 7.15V nominally. A potentiometer (R6) is used to reduce this reference down to +5V and to eliminate production variations. The 723 differential amplifier then amplifies the difference between the +5V (25 ampere) logic output to the adjusted reference divider by the gain (approximately 1000) of U13. The output of U13 then feeds a two-stage transistor amplifier (Q1, Q2) to provide a low output impedance on the control line at the proper voltage level and range of voltage swing. C6 and R17 form a noise filter to prevent "impulse" type noise on the control line of the waveform generator.

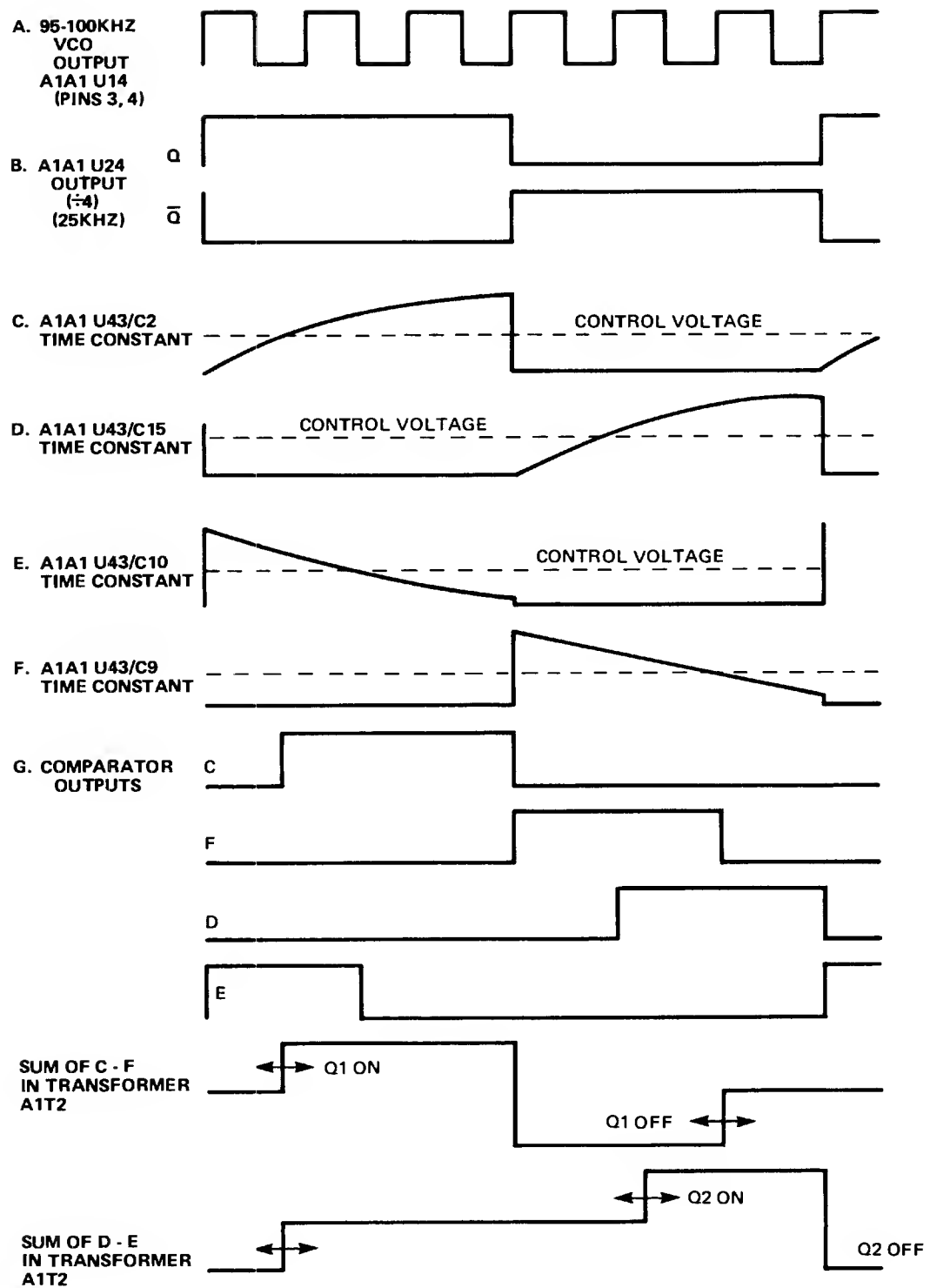


Figure 4-6. Two-Phase Switching Regulator Waveforms

A major loop roll-off corner frequency is formed by the output capacitor and choke input filter on the Schottky rectifier output of the +5V logic output. With load, this corner frequency changes considerably. At no load, the corner frequency is approximately 0.5Hz and at full load moves up to approximately 30Hz. To stabilize the loop, a 22uf capacitor (C8) in series with a 215-ohm resistor (R18) at the high impedance compensation node of U13, starts to roll the loop gain off at about .01Hz and is taken out at about 10Hz by R18. The final post amplifier roll-off is accomplished by the +5V output filter (L6 and C11 on the mother board in parallel with the load on the +5VDC output.)

The open-loop DC gain is in excess of 70db, which provides the very tight regulation of the +5V to within 10mV from no load to full load, typically when measured at the output capacitor on the copper strips.

4.5.2.5 Soft and Hard Fail Shutdown

Soft fail shutdown is an organized shutdown wherein the battery backup system and a power-fail software routine save the memory information. The stored charge in the input line rectifier capacitors allow the supply output to carry over the regulated voltage for a minimum of 5msec after the loss of primary power to allow the execution of the power-fail routine. The power supply will recover from a soft fail shutdown by itself without operator intervention. Once the condition causing soft fail shutdown has returned within limits the supply will ramp up to within specifications and issue the Power On (PON) logic signal.

The soft fail shutdown line is a normally high (+12V) level and goes low upon shutdown, staying low until released by the sensor pulling it down. Sensors on the soft fail shut down include line drop out and brown out level sensing, as well as Line Power Up (LPU), an external peripheral power supply sense input.

Hard fail shutdown is sudden and abrupt. It is used for catastrophic component failures or human-induced failures that would damage hardware if shutdown was not done immediately. Over-current on the inverter or switching regulator, over-voltage on the +5V logic bus, or undervoltage on the post regulated outputs (including short circuits) will cause hard fail shutdown. Hard fail shutdown lights a red LED at the right lower corner of the front panel of the supply. The hard fail shutdown is a latched condition. If the cause is well known, such as accidentally shorting out a DC output supply, then the AC switch can be recycled immediately to set the supply in operation again. If the cause is not known, the supply should be separated from the load before recycling the switch. If one of the outputs has been shorted or held low by the load, the supply will come up after removing the load, and cycling the AC power switch. The loads then can be resistance checked with an ohmmeter to find the shorted load. If the loop has gone out of control, the +5V output will ramp up to 6.5V maximum then quickly issue a hard fail shutdown, which causes the output to go to zero and the red light to light. Internal component failures of Schottky rectifiers, post regulators and other

components can also cause hard fail shutdown. The fast shutdown prevents further over stress and damage to other components.

Two other LED light sources are at the front panel lower right corner. A green one on the left of the hard fail shutdown red LED, indicates that AC power is present and that the +12V internal supply is operating. The green LED to the right of the red hard fail FAULT light, indicates that the PON logic signal has been issued and the supply is up and regulating.

4.5.3 LOGIC BOARD (PART NUMBER 12035-60004)

The schematic diagram for the logic board is shown in drawing 12035-60004. A photograph of the logic board is shown in figure 4-7. The logic board contains under-voltage limit comparators, line drop-out detector, Soft Fail Shutdown and Hard Fail Shutdown; and the Line Power Up, Power Supply Up, Power On, and Power Fail Warning logic.

The logic board monitors the line voltage and drop-out condition; the output DC voltages for under-voltage conditions; and the conditions of other supplies in a system interconnection. It then outputs the Power On Signal (PON); and the Power Fail Warning (PFW) signal.

Built in timing on this card provides the carry over time between PFW and PON going low and PON going true at turn on. It provides this delay to allow variations in the output to settle down before the computer is turned on.

4.5.3.1 Under-Voltage Limit Comparators

Two quad comparator packages, U8 and U9, provide the comparison of six output voltages with low limit references. One comparator in U9 provides accurate thresholding for the carry-over time constant, and the other comparator in U8 provides the line drop-out detector function. To make the low limit comparison reasonably accurate, a reference voltage is required for each voltage to be checked. In addition, negative output voltages must be checked with positive quadrant comparators, which require DC translation. U1 and reference diode CR2 with its associated resistors form the stable reference voltage from which all the references are derived. Potentiometer R1 allows adjustment to 4.8V via test point E1 to E7 (Gnd). This sets up one of the reference voltages used for the +/-12V supplies. The -12V supply uses CR10, a two-percent zener diode to translate the voltage into a positive voltage that can be compared by the unipolar comparator.

A voltage divider from E1 to ground in resistor package U7R provides the various positive voltages needed for the lower limits of +5L, +5M, +12L, and +12M. A resistive voltage divider consisting of a 1K resistor in U4 and

resistors R17 and R18 are used to translate the -12V memory bias voltage.

Outputs of comparators on the + and -12VL, +12VM, -5VM, and +5VM are open collector ORed and pulled up by a 3.16K resistor in U4R. This line is called DCC and is available at test point E5. The comparator on the +5VL line feeds a 100K pull-up resistor (U4R) and a 1 uf capacitor (C2) to ground forming, a 100msec a 100ms time constant on the rising waveform into NAND gate U5. The other input to the NAND is DCC. After inversion through another cell of U5 acting as an inverter, the signal becomes DCU. This signal goes true (high) when all supply outputs have exceeded their limits and settled out (which is provided by the 100 msec time delay).

4.5.3.2 Line Drop-Out Detector, SFS and HFS

The detection of line drop-outs is provided by an RC time constant on the motherboard in the +12INT supply and a differential amplifier (U8) on the logic card. The RC time constant as described in paragraph 4.5.3.1 is detected by the differentially-connected operational amplifier U8 on the logic board. The resistor network for the differential connection is incorporated in the U7 package. The absolute value of the voltage on the filter capacitor in the low voltage supply causes an imbalance in the differential amplifier under minimum line voltage conditions which also produces an output. The output is a "soft fail" shutdown described in paragraph 4.5.2.5. Capacitor C6 around the operational amplifier in the form of positive feedback provides dynamic hysteresis and forms a one-shot multivibrator when the differential threshold is exceeded. This causes the output low SFS pulse width to always be greater than 2 msec. At power supply turn on, SFS goes high as soon as the +12VINT supply comes up.

The logic formed by U5 and U6 gate packages and the discrete diode logic "OR" gate generates the soft fail and hard fail shutdown (described in paragraph 4.5.2.5) from the DCC (E5) and line dropout detector (LDD) signals. To prevent hard fail shutdown occasionally with soft fail shutdown, a delayed disable signal is required to the switching regulator drivers to provide a more controlled soft fail shutdown. This is provided by U5 which generates the disable signal from the line dropout detector.

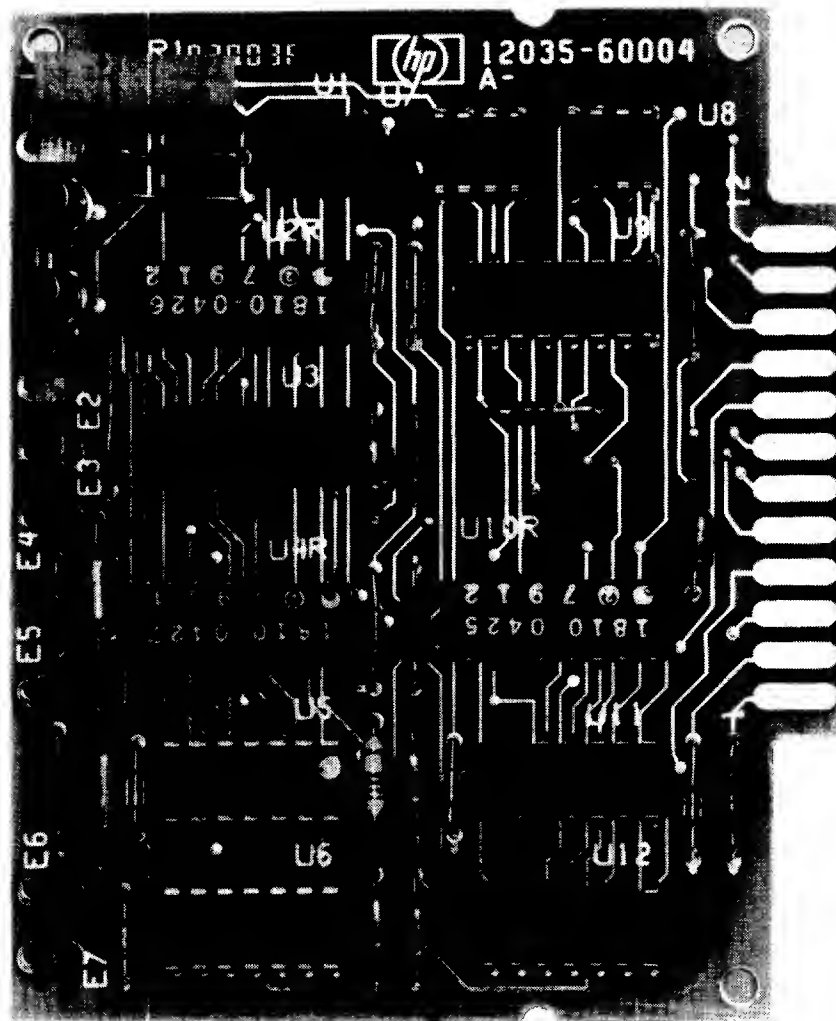


Figure 4-7. Logic Board (12035-60004)

4.5.3.3 LPU, PSU, PON, and PFW Logic

The LPU (Line Power Up) and PSU (Power Supply Up) signals are provided for an ANDing function if several supplies are used in a system. If this option is used, and if any supply in the system is without primary power none of the supplies in the system will come up (Soft fail shutdown). LPU provides this function. It is an open-collector line requiring 2mA maximum sink current, and can be ORed with similar lines. It is a bi-directional line and can be "daisy chained" to several system power supplies. When the primary power is turned off or removed from the input, the line will sink up to 6mA.

Under the conditions where an external supply sinks the LPU line, SFS (Soft Fail Shutdown, low true) will be pulled low and PFW (Power Fail Warning) will be held low at the CPU backplane. LPU is a TTL-compatible level (0.4V maximum, low; 2.2V minimum, high). PFW is an open-collector output with the pull-up resistor on the CPU. A sink capability of 100mA is provided at standard TTL levels on PFW. The rise and fall times must be less than 50 nsec and they must be free of noise. To provide this feature, U3, a Schmitt trigger, and the corresponding RC networks are used. SFS is also pulled low by the line dropout detector as described in paragraph 4.5.2.5, which in turn pulls PFW low. Upon PFW going low, the carry-over time is generated by R11, C8, and U9. This pulls DCC low causing DCU and PSU to go low. PSU warns external power supplies that the CPU power is off and the logic I/O buses will be unreliable. In turn, PON will be pulled low which turns the CPU off.

In the time between PFW low and PON going low, the CPU has had time to execute the power fail routine (guaranteed 5msec from PFW to PON going low). PON is conditioned to maintain less than 50 nsec rise and fall time, with up to 100mA sink current at TTL levels with no noise. Again, the Schmitt trigger (U3) with corresponding RC time constants perform this feature. An external low on PSU will also halt the CPU by pulling PON low. The electrical characteristics of PSU are similar to LPU. If primary power is not present on the power supply, PSU will also be held low, sinking up to 6mA (200 ohms maximum).

4.6 TROUBLE DIAGNOSIS

SYMPTOM	POSSIBLE FAULT
Blows fuse (3AG, 7A)	Line voltage selector switch (AlS2) set to wrong range. Shorted AlQ5 or AlQ6. Shorted AlCR13. Defective AlQ3 or AlQ4. Connector J3, or AlQ1, AlQ2, AlQ3, or AlQ4 pin jack open. Shorted triac AlQ7. Shorted opto-isolator AlU7. Shorted AlU10. Defective driver board (12035-60003).
FAULT light comes on upon turn on	Shorted Schottky rectifier, AlCR9 or AlCR10. +5VL shorted to ground. ITR's AlQ3 or AlQ4 shorted. Bridge rectifier AlU4 shorted. 25kHz outputs shorted. +5V ADJ set too high.

SYMPTOM

POSSIBLE FAULT

LINE light does not come on	Line voltage not getting to unit.
	Check driver board loading 12VINT (A1U5).
	Check logic board loading 12VINT (A1U5).
	A1CR5 open.
	A1U6 open.
OPER light does not come on	LPU is being held low (logic board).
	DC voltages did not come up.
FAULT light comes on after power supply has operated long enough to warm up.	Leaky Schottky rectifier A1CR9 or A1CR10.
	Slow turn off of A1Q5 or A1Q6.
	Overloaded output(s).
	Output loads increase with operating time.
	Defective driver board.

4.7 PARTS LOCATIONS

Parts locations for the HP 12035A power supply are shown in figures 4-8 through 4-10.

4.8 PARTS LIST

The parts lists for the power supply are shown in tables 4-2 through 4-5. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

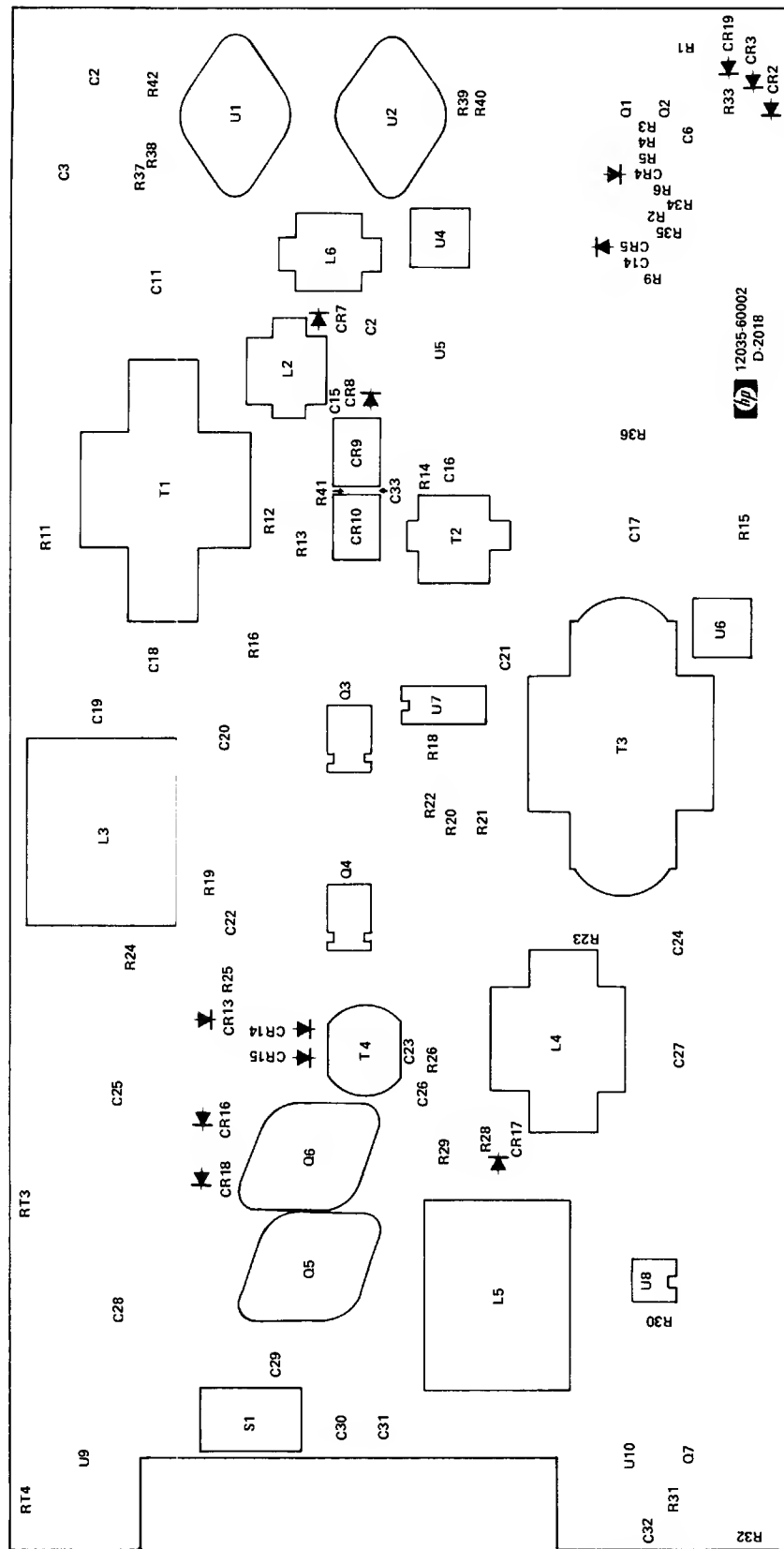


Figure 4-8. Motherboard Parts Locations

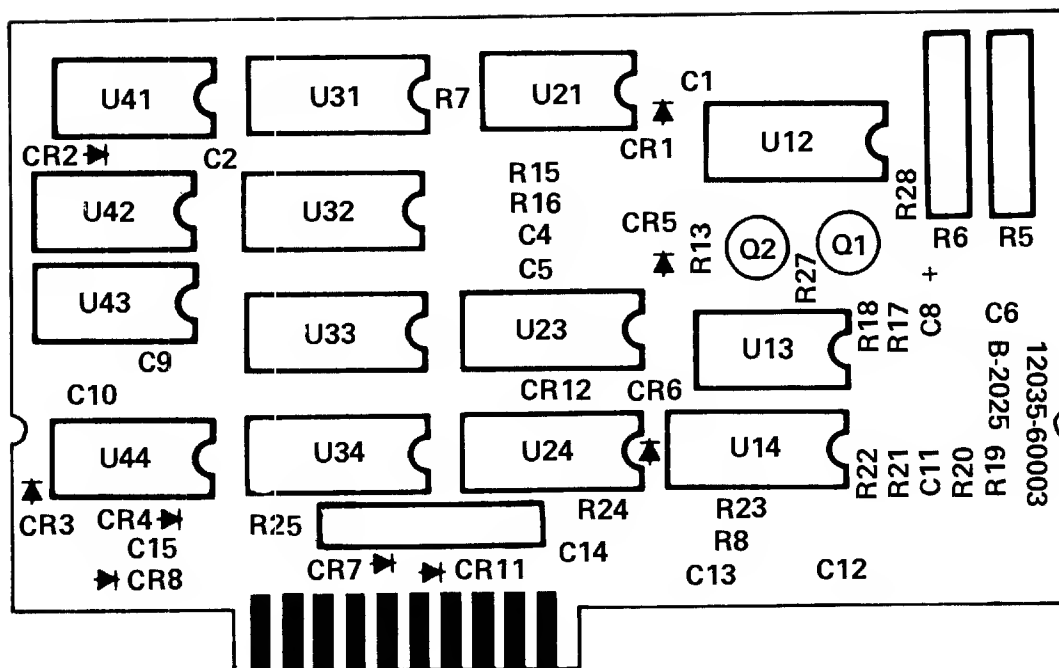


Figure 4-9. Driver Board Parts Locations

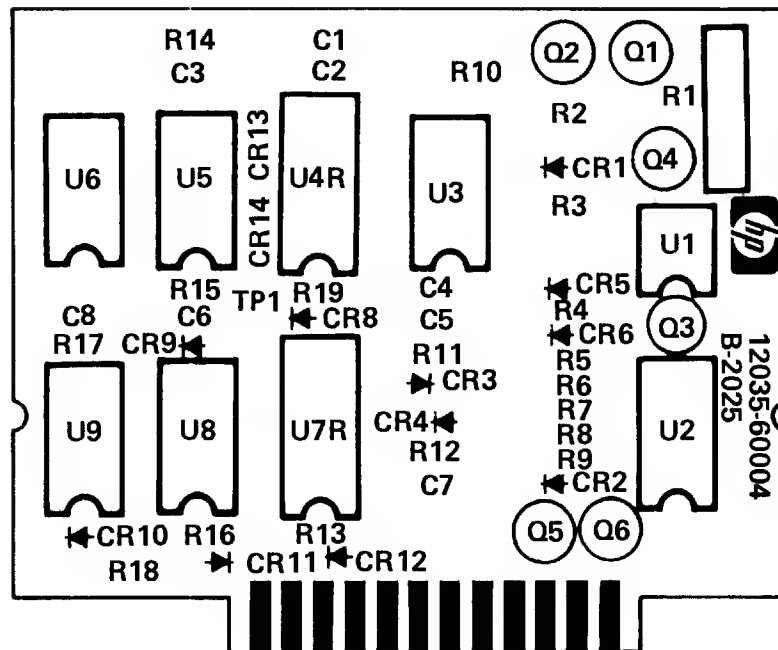


Figure 4-10. Logic Board Parts Locations

Table 4-2. Power Supply Replaceable Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12035-60005	3	1	POWER I/O PANEL	28480	12035-60005
C1	0160-3451	1	1	CAPACITOR=FXD .01UF +80-20% 100VDC CER	28480	0160-3451
D1	0302-0501	6	3	CONNECTOR=8GL CNT QDISC=FEM TAB	28480	0302-0501
	1251-3812	2	1	CONNECTOR 9-PIN W MINTR RECT	28480	1251-3812
	1251-4687	1	2	CONTACT=CONN U/W=UTIL FEM CRP	28480	1251-4687
	1251-5227	7	1	CONNECTOR 2-PIN UTILITY	28480	1251-5227
	1251-5361	0	5	CONTACT=CONN U/W=MINTR=RECT FEM CRP	28480	1251-5361
	1251-5910	5	1	CONNECTOR 4-PIN F POST TYPE	28480	1251-5910
	1251-5917	2	4	CONTACT=CONN U/W=PORT=TYPE FEM CRP	28480	1251-5917
	2110-0564	6	1	FUSEHOLDER BODY 12A MAX FOR UL	H9027	031-1657
	2110-0565	9	1	FUSEHOLDER CAP 12A MAX FOR UL	28480	2110-0565
	2110-0569	3	1		28480	2110-0569
	2110-0614	9	1	FUSE 7A 250V NTD 1.25X.25 UL	28480	2110-0614
	12035-60006	4	1	FAN ASSEMBLY	28480	12035-60006
	1251-3656	2	1	CONNECTOR 2-PIN F UTILITY	28480	1251-3656
	1251-4341	4	2	CONTACT=CONN U/W=UTIL FEM CRP	28480	1251-4341
	3160-0340	4	1	FAN=T8AX 36=CFM 115V 50/60=HZ 1.5KV=DIEL	28480	3160-0340

Table 4-3. Motherboard Replaceable Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12035-60002	0	1	POWER SUPPLY MOTHER BOARD ASSEMBLY	28480	12035-60002
C2	0180-2727	4	2	CAPACITOR-FXD 1900UF+75-10% ROVOC AL	00853	300M8192U0408
C3	0180-2727	4	2	CAPACITOR-FXD 1900UF+75-10% ROVOC AL	00853	300M8192U0408
C11	0180-2932	3	1	CAPACITOR-FXD .015F+75-0% 7.5VOC AL	28480	0180-2932
C18	0180-0128	3	1	CAPACITOR-FXD 2.2UF +20% 50VOC CER	28480	0180-0128
C16	0180-0576	5	3	CAPACITOR-FXD .1UF +20% 50VOC CER	28R80	0180-0576
C17	0180-2180	3	1	CAPACITOR-FXD 2600UF+75-10% 50VOC AL	00853	500262U050A82A
C18	0180-04573	0	2	CAPACITOR-FXD .22UF +20% 400VOC	28480	0180-04573
C19	0180-04573	0	2	CAPACITOR-FXD .22UF +20% 400VOC	28480	0180-04573
C20	0180-0183	8	2	CAPACITOR-FXD 1000PF +20% 250VAC(RM8)	28480	0180-0183
C22	0180-0183	8	2	CAPACITOR-FXD 1000PF +20% 250VAC(RM8)	28480	0180-0183
C23	0180-0576	5	3	CAPACITOR-FXD .1UF +20% 50VOC CER	28480	0180-0576
C28	0180-0785	6	2	CAPACITOR-FXD .1UF +20% 50VOC CER	28480	0180-0785
C25	0180-0R31	3	2	CAPACITOR-FXD 1150UF+75-10% 200VOC AL	00853	5001151U2008B2A
C26	0180-0576	5	3	CAPACITOR-FXD .1UF +20% 50VOC CER	28480	0180-0576
C27	0180-0785	6	2	CAPACITOR-FXD .1UF +20% 50VOC CER	28480	0180-0785
C28	0180-0431	3	1	CAPACITOR-FXD 1150UF+75-10% 200VOC AL	00853	5001151U2008B2A
C29	0180-0065	5	2	CAPACITOR-FXD .1UF +20% 250VAC(RM8)	28480	0180-0065
C30	0180-0281	7	2	CAPACITOR-FXD 2200PF +20% 250VAC(RM8)	C0633	PME271Y422
C31	0180-0281	7	2	CAPACITOR-FXD 2200PF +20% 250VAC(RM8)	C0633	PME271Y422
C32	0180-0065	5	2	CAPACITOR-FXD .1UF +20% 250VAC(RM8)	28480	0180-0065
C33	0180-0181	4	1	CAPACITOR-FXD .01UF +20% 200VOC PDLVE	28480	0180-0181
CR2	1990-0485	5	2	LED-VISIBLE LUM-INT=800UCO IF=30MA-MAX	28480	5082-R984
CR3	1990-0486	6	1	LED-VISIBLE LUM-INT=1MCD IF=20MA-MAX	28480	5082-4684
CR9	1901-0884	1	2	DIODE-PWR RECT 35V DO-5	28480	1901-0884
CR10	1901-0884	1	2	DIODE-PWR RECT 35V DO-5	28R80	1901-0884
CR13	1901-1087	8	1	DIODE-PWR RECT 600V 3A 200NS	04713	MR856
CR19	1990-0485	5	2	LED-VISIBLE LUM-INT=800UCO IF=30MA-MAX	28R80	5082-R984
J2A	1251-5666	8	1	CONNECTOR R-PIN M PD8T TYPE	28480	1251-5666
J2B	1251-5665	7	2	CONNECTOR 10-PIN M PD8T TYPE	28480	1251-5665
J2C	1251-5665	7	1	CONNECTOR 10-PIN M PD8T TYPE	28480	1251-5665
J3	1251-5843	3	1	CONNECTOR-PC EDGE 10-COND/ROW 2-ROW8	28480	1251-5843
J4	1251-5908	1	1	CONNECTOR 2-PIN M UTILITY	28480	1251-5908
J5	1251-5841	1	1	CONNECTOR-PC EDGE 15-COND/ROW 2-ROWS	28480	1251-5841
J6	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28480	1251-5153
J7	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28R80	1251-5153
J8	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28480	1251-5153
J9	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28480	1251-5153
J10	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28480	1251-5153
J12	1251-3305	8	1	CONNECTOR 4-PIN M POST TYPE	28480	1251-3305
J22	1251-5153	8	6	CONNECTOR-SGL CONT QDI8C-M .25-IN-88C-8Z	28480	1251-5153
L1	9140-0326	0	2	INDUCTOR 50UH 10% .875DX1.125LG	28480	9140-0326
L2	9140-0326	0	2	INDUCTOR 50UH 10% .875DX1.125LG	28480	9140-0326
L3	9140-0337	3	1	INDUCTOR-FIXED DUAL TOROID; 100 UH+10%	28480	9140-0337
L4	9140-0336	2	1	INDUCTOR-FIXED SWITCHING INDUCTOR; 1.0	28480	9140-0336
L5	9140-0346	4	1	INDUCTOR-FIXED DUAL TOROID; 1.0 MM PER	28480	9140-0346
L6	9140-0342	0	1	INDUCTOR 25UH 1.7DX.8LG	28480	9140-0342
Q1	1A53-0036	2	1	TRANSISTOR PNP 6I PD=310MW FT=250MHZ	28480	1A53-0036
Q2	1A54-0467	5	1	TRANSISTOR NPN 2N4401 SI TD=92 PD=310MW	03508	2N4401
Q3	1A84-0287	0	2	THYRISTOR-SCR	28480	1A84-0287
Q4	1A84-0287	0	2	THYRISTOR-SCR	28480	1A84-0287
Q5	1A54-0855	5	2	TRANSISTOR NPN TD=3 PD=150W	28480	1A54-0855
Q6	1A54-0855	5	2	TRANSISTOR NPN TD=3 PD=150W	28480	1A54-0855
Q7	1A84-0277	8	1	THYRISTOR-TRIAC TD=220AB	03508	8C141M5
R11	0811-3570	6	1	RESISTOR 6.8 5% 5W PW TC=0+-50	28480	0811-3570
R15	0764-0042	0	1	RESISTOR 2.2K 5% 2W MD TC=0+-200	28480	0764-0042
R20	0811-1553	1	1	RESISTOR .68 5% 2W PW TC=0+-800	75042	8MM2=11/16-J
R21	0811-1552	0	1	RESISTOR .56 5% 2W PW TC=0+-800	75042	8MM2=9/16-J
R24	0764-0040	8	2	RESISTOR 39K 5% 2W MD TC=0+-200	28480	0764-0040
R25	0764-0040	8	2	RESISTOR 39K 5% 2W MD TC=0+-200	28480	0764-0040
R26	0757-0R01	0	3	RESISTOR 100 1% .125W F TC=0+-100	24546	C4=1/8-T0-101-F
R27	0757-0R01	0	3	RESISTOR 100 1% .125W F TC=0+-100	24546	C4=1/8-T0-101-F
R31	0811-3108	6	1	RESISTOR 2 10% PWH	28480	0811-3108
R32	0757-0R01	0	3	RESISTOR 100 1% .125W F TC=0+-100	24546	C4=1/8-T0-101-F
RR1	2100-3154	7	1	RESISTOR-TRMR 1K 10% C SIOE-A0J 17-TRN	02111	43P102
RT3	0A37-0208	5	2		28480	0837-0208
RT4	0A37-0208	5	2		28480	0837-0208

Table 4-3. Motherboard Replaceable Parts List (Continued)

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
S1	3101-2373	3	1	SWITCH=SLIDE DP2T PC	28480	3101-2373
T1	9100-4126	4	1	TRANSFORMER INVERTER, 106 V 25 KHZ	28480	9100-4126
T2	9100-4126	2	1	TRANSFORMER SCR GATE TRIGGER, 4 VRMS 25	28480	9100-4126
T3	9100-4127	3	1	TRANSFORMER=POWER 115/230V 50-60HZ	28480	9100-4127
T4	9100-4125	1	1	TRANSFORMER DUAL DRIVER, PC MTG, 20 KHZ	28480	9100-4125
U1	1A13-0123	4	1	IC 78HG V RGLTR TD-3	07263	UA78HGKC
U2	1A13-0127	8	1		28480	1A13-0127
U4	1906-0079	6	1	DIODE-FW BRDG 100V 10A	27777	VJ148X
U5	1A26-0147	9	1	IC 7812 V RGLTR TD-220	04713	MC7812CP
U6	1906-0062	7	2	DIODE-FW BRDG 600V 6A	28480	1906-0062
U7	1990-0664	2	1	OPTO-ISOLATOR LED=PXSTR IF=40MA=MAX	28480	1990-0664
U8	1990-0690	2	1	OPTO-ISOLATOR LED=PHOTOSCR IF=60MA=MAX	03508	M11C6
U9	1906-0062	7		DIODE-FW BRDG 600V 6A	28480	1906-0062
U10	1906-0226	5	1	DIODE-FW BRDG 800V 1A	28480	1906-0226
W1	8159-0005	0	2	WIRE 22AWG W PVC 1X22 80C	28480	8159-0005
W2	8159-0005	0		WIRE 22AWG W PVC 1X22 80C	28480	8159-0005

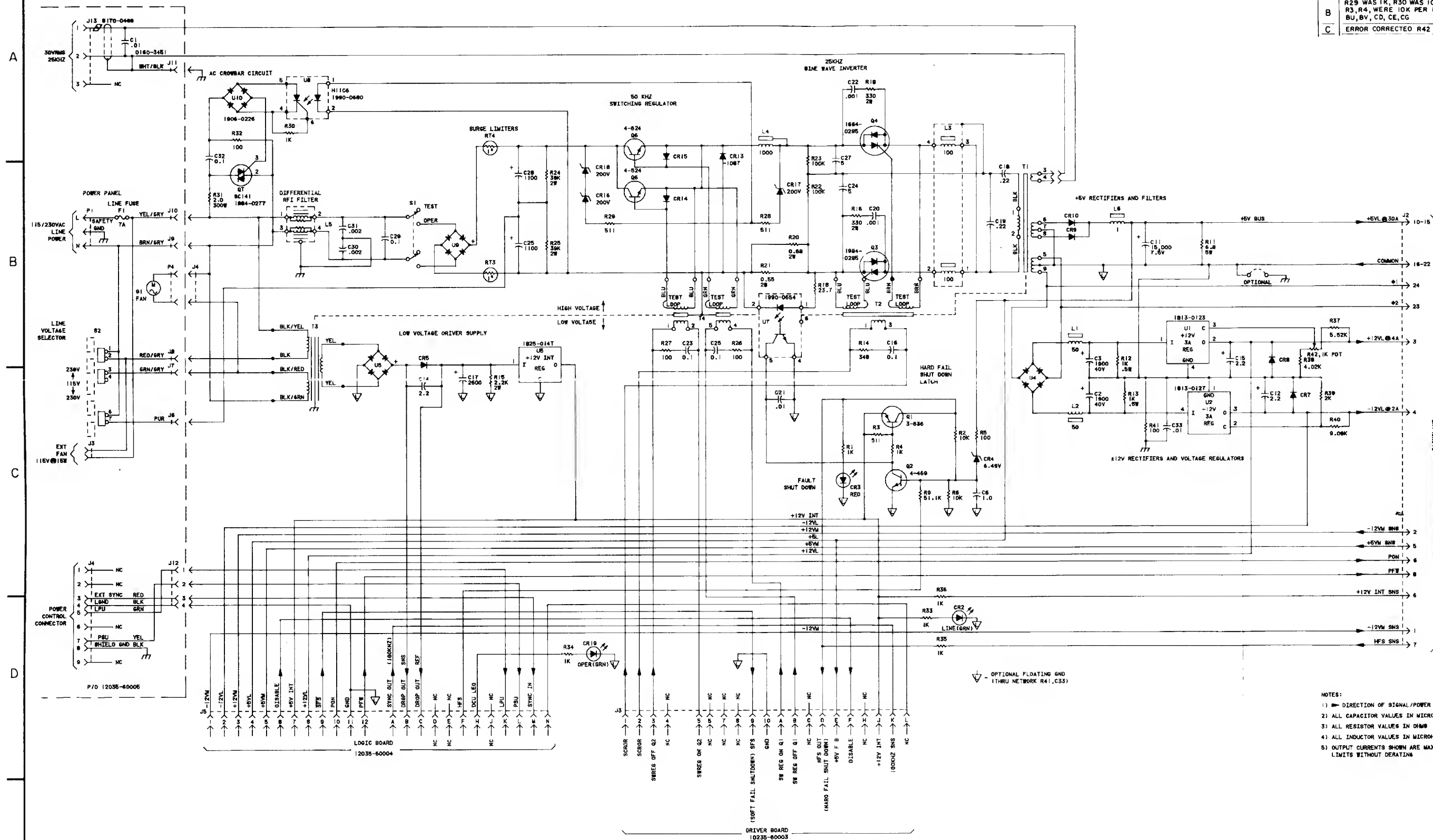
Table 4-4. Driver Board Replaceable Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12035-60003	1	1	POWER SUPPLY DRIVER BOARD	28480	12035-60003
C12	0160-0164	7	1	CAPACITOR-FXD .039UF +-10% 200VDC POLYE	28480	0160-0164
Q1	1854-0215	1	2	TRANSISTOR NPN 8I P0=350MW FT=300MHZ	04713	2N3904
Q2	1854-0215	1		TRANSISTOR NPN 8I P0=350MW FT=300MHZ	04713	2N3904
R5	2100-3161	6	1	RESISTOR-TRMR 20K 10% C SIDE=ADJ 17-TRN	02111	43P203
R6	2100-3109	2	1	RESISTOR-TRMR 2K 10% C SIDE=ADJ 17-TRN	02111	43P202
R25	1810-0125	0	1	NETWORK-RES 8-SIP4.7K OHM X 7	28480	1810-0125
U12	1A10-0040	8	1	NETWORK-RES 16-DIP MULTI-VALUE	28480	1810-0040
U13	1820-0439	0	1	IC V RGLTR 14-DIP=P	07263	723PC
U14	1820-1188	8	1	IC PL LOOP 16-DIP=P	01928	CD4046AP
U21	1826-0138	8	2	IC COMPARATOR GP QUAD 14-DIP=P	01295	LM339N
U23	1A20-1266	3	7	IC 8FR CMOS NON-INV HEX	07263	40097PC
U24	1820-1964	8	1	IC FF CMOS J-K PDS=EDGE-TRIG DUAL	01928	CD40278E
U31	1820-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U32	1820-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U33	1820-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U34	1A20-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U41	1A20-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U42	1A20-1266	3		IC 8FR CMOS NON-INV HEX	07263	40097PC
U43	1A10-0212	6	1	NETWORK-RES 16-DIP22.0K OHM X 8	01121	3166223
U44	1826-0138	8		IC COMPARATOR GP QUAD 14-DIP=P	01295	LM339N

Table 4-5. Logic Board Replaceable Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12035-60004	2	1	POWER SUPPLY LOGIC	28480	12035-60004
Q1	1855-0421	3	2	TRANSISTOR J-FET 2N5114 P-CHAN D-MODE	17856	2N5114
Q2	1A55-0421	3		TRANSISTOR J-FET 2N5114 P-CHAN D-MODE	17856	2N5114
Q3	1854-0467	5	4	TRANSISTOR NPN 2N4401 81 TO-92 PD=310MW	03508	2N4401
Q4	1854-0467	5		TRANSISTOR NPN 2N4401 81 TO-92 PD=310MW	03508	2N4401
Q5	1854-0467	5		TRANSISTOR NPN 2N4401 81 TO-92 PD=310MW	03508	2N4401
Q6	1854-0467	5		TRANSISTOR NPN 2N4401 81 TO-92 PD=310MW	03508	2N4401
R1	2100-3154	7	1	RESISTOR-TRMR 1K 10% C 810E-A0J 17-TRN	02111	43P102
U1	1826-0346	0	1	IC OP AMP GP DUAL 8-DIP-P	27014	LM358N
U2	1820-1778	2	2	IC SCHMITT-TRIG CMOS HEX	27014	MM74C914N
U3	1A20-177A	2		IC SCHMITT-TRIG CMOS HEX	27014	MM74C914N
U4	1810-0427	5	1	NETWORK-RES 16-DIP MULTI-VALUE	28480	1810-0427
U5	1820-1747	5	1	IC GATE CMOS NAND QUAD 2-INP	04713	MC14011UCP
U6	1820-1965	9	1	IC GATE CMOS NOR TPL 3-INP	04713	MC140258CP
U7	1810-0425	3	1	NETWORK-RES 16-DIP MULTI-VALUE	28480	1810-0425
U8	1826-0138	8	2	IC COMPARATOR GP QUAD 14-DIP-P	01295	LM339N
U9	1826-0138	8		IC COMPARATOR GP QUAD 14-DIP-P	01295	LM339N

SYM	REVISIONS	APPROVED	DATE
A	AS ISSUED		
B	R3 WAS 5.0, DELETED RT1, RT2, R28 WAS 5.11K, R29 WAS 1K, R30 WAS 10K, R21 WAS .68A, R3, R4, WERE 10K PER PRCS		
C	BU, BV, CD, CE, CG		
	ERROR CORRECTED R42 MISSING		



HP 12035A
POWER SUPPLY
MOTHERBOARD

HEWLETT PACKARD

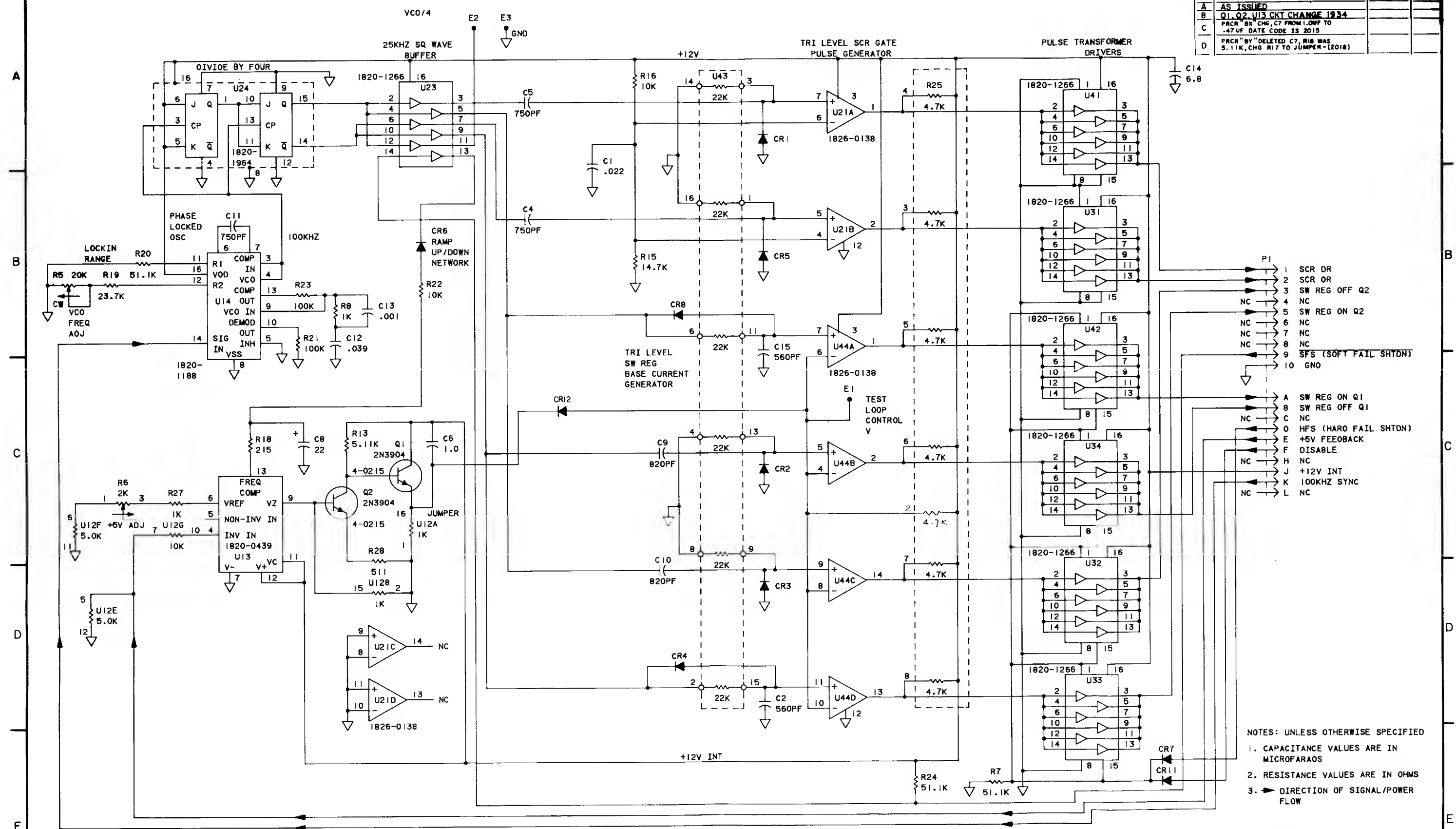
NEXT ASSEMBLY 12035A

PART NUMBER 12035-60002

FINISH: SCALE

D-12035 - 60002 - 51

REV	DESCRIPTION	DATE	BY	CHKD
A	AS ISSUED			
B	Q1, Q2, U13 CKT CHANGE 1934			
C	PRCR "BX" CHG, C7 FROM 1.0UF TO .47UF DATE CODE IS 2015			
D	PRCR "BY" DELETED C7, R18 WAS 5.11K, CHG R17 TO JUMPER - (2018)			



NOTES: UNLESS OTHERWISE SPECIFIED

1. CAPACITANCE VALUES ARE IN MICROFARADS
2. RESISTANCE VALUES ARE IN OHMS
3. ➔ DIRECTION OF SIGNAL/POWER FLOW

HP 12035A POWER SUPPLY DRIVER BOARD		HEWLETT-PACKARD
TITLE	NEXT ASSEMBLY 12035-60002	PART NUMBER 12035-60003
FINISH	SCALE	D-12035-60003-51

BATTERY BACKUP	SECTION V
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5.1 INTRODUCTION

The Hewlett-Packard HP 12013A Battery Backup system is a non-interruptible power supply that provides memory voltages to maintain data during the absence of AC line power. The battery backup system is contained on one circuit card and plugs directly into the L-Series backplane (i.e, the battery backup card is not part of the power supply). The circuit card is shown in figure 5-1.

5.2 OVERVIEW

The purpose of a memory support battery backup system is to act as an non-interruptible power supply and protect computer memory from AC line power disturbances.

The following kinds of AC line power disturbances exist:

- Voltage sag, which is a drop in AC line voltage longer than 5 msec but not longer than 5 seconds.
- Power interruption, which is a complete loss of power for longer than 5 msec but not longer than 0.5 second.
- Power outage, which is a complete loss of power for more than 0.5 second.

All the components of the battery backup (six batteries, battery regulators, and control logic) are on one circuit card.

The batteries contain enough power to support memory for one hour. Because the memory 5 volt supply range is 4.75 to 5.25 volts, and the batteries provide 6.0 to 7.5 volts, regulation of the battery voltage is required. Linear regulation is used, because it provides noise-free regulation which is necessary in the card cage.

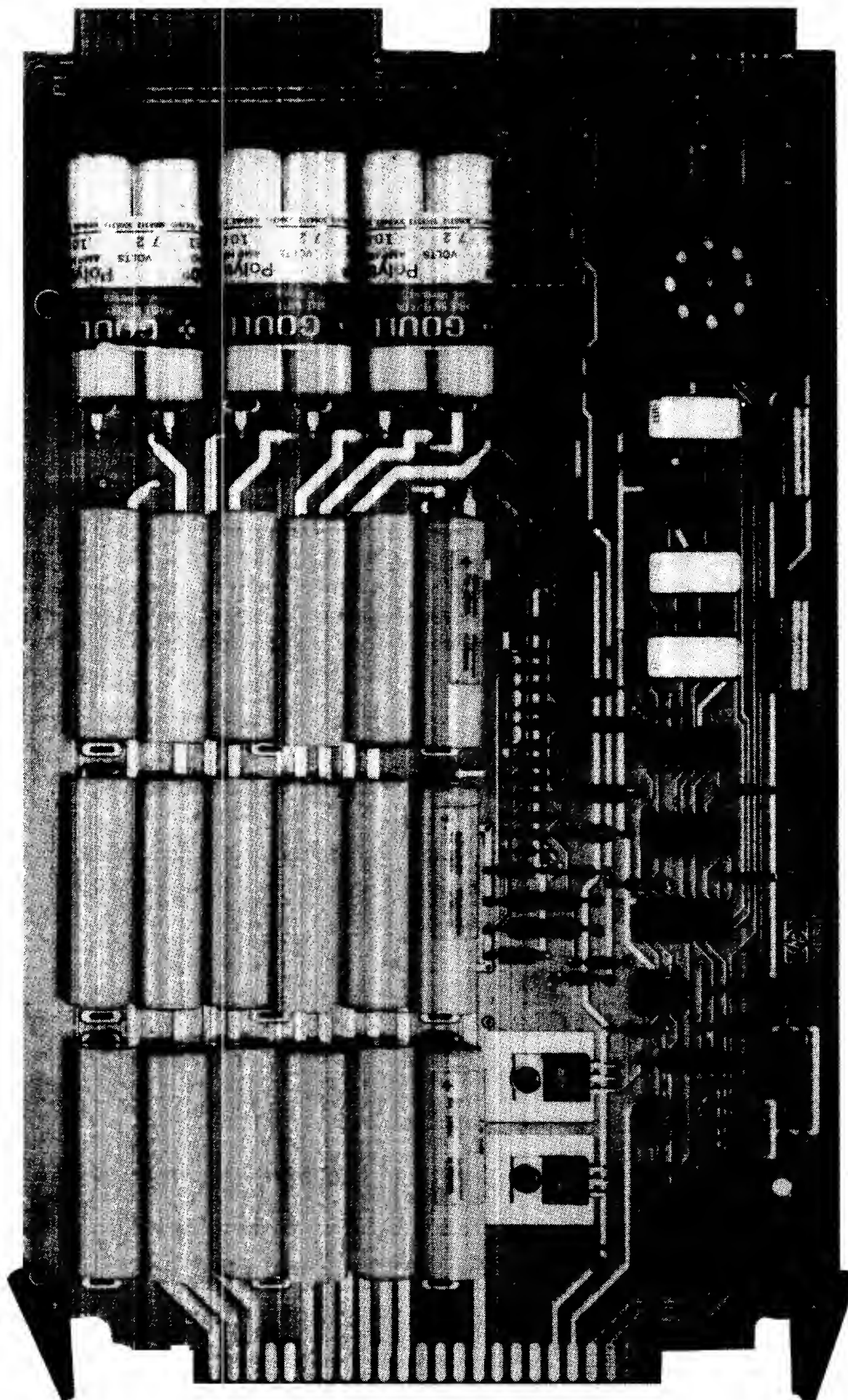


Figure 5-1. HP 1000 L-Series Battery Backup Card

When AC line power is present, the batteries are being charged and the memory voltages are supplied by the main power supply. A relay is used to control this connection. After two cycles of AC line power loss, the main power supply causes the processor to execute a power fail sequence, and causes the battery backup card to supply power to memory. After the battery regulator circuit is enabled, the relay opens and memory now is supported from batteries.

5.3 SPECIFICATIONS

Specifications for the battery backup card are listed in table 5-1.

Table 5-1. Specifications

OUTPUT VOLTAGES	
+5M:	5.25 to 4.75 volts
+12M:	11.4 to 12.6 volts
-12M:	-6.0 to -8.4 volts
OUTPUT CURRENT	
+5M:	1500 mA maximum
+12M:	500 mA maximum
-12M:	110 mA maximum
OVER-VOLTAGE LIMITS	
+5M:	7 volts maximum
+12M:	15 volts maximum
-12M:	-15 volts maximum
ACTUAL LOAD - MEMORY OPERATIONAL	
+5 volts:	
	750 mA maximum (memory board)
	250 mA maximum (CPU board)
	50mA maximum (power supply logic)
TOTAL	1050 mA maximum
+12 volts:	290 mA maximum (memory board)
-12 volts:	20 mA maximum (memory board)

Table 5-1. Specifications (Continued)

ACTUAL LOAD - MEMORY IN STANDBY		
+5 volts:	1050 mA maximum	
+12 volts:	72 mA maximum	
-12 volts:	20 mA maximum	
MEMORY SUPPORT TIME - MAXIMUM LOAD		
<u>Configuration</u>	<u>Support Time</u>	<u>Memory Size</u>
12002A	1 hr 56 min	128KB
12002A and one 12003A	1 hr 23 min	256KB
12002A and two 12003A	1 hr 4 min	384KB
12002A and three 12003A	53 min	512KB
12002B	1 hr 29 min	512KB
12004A	1 hr 9 min	64KB
BATTERY CAPACITY		
7.2 volts:	1500 mAh	
14.4 volts:	110 mAh	
-7.2 volts:	110 mAh	
BATTERY CHARGE CURRENT		
7.2 volts:	150 mA from +12V	
14.4 volts:	22 mA from +12V	
-7.2 volts:	11 mA from -12V	
BATTERY CHARGE POWER		
+12V:	2.17 watts	
-12V:	0.13 watts	
BATTERY CHARGE TIME		
Batteries must charge 14 minutes for every 1 minute of discharge (15 minute discharge requires 210 minute recharge, 60 minute discharge requires 840 minute recharge, etc.)		

5.4 INTERFACE REQUIREMENTS

5.4.1 INTERFACE SIGNALS

The L-Series backplane provides all interface signal lines needed for operation of the battery backup, as follows:

SIGNAL	CONNECTOR AND PIN NUMBER
PFW	P1, PIN 7
MLOST	P1, PIN 5
+12M	P2, PIN 39
+5M	P2, PINS 45, 46
-12M	P2, PIN 40
+12V	P2, PINS 41, 42
+5V	P2, PINS 35, 36, 37, 38
-12V	P2, PINS 43, 44
GROUND	P2, PINS 29, 30, 31, 32, 33, 34

5.4.2 EXTERNAL CONNECTOR

Interface connector J1 is used for fast charge of batteries or to connect the batteries to external devices. The battery backup connections to J1 are as follows:

BATTERY NUMBER AND VOLTAGE	J1 PIN NUMBER
1 - +5 volts	2
2 - +12 volts	4
3 - +5 volts	6
4 - +12 volts	8
5 - +12 volts	10
6 - -7.2 volts	12

5.4.3 REMOTE/OFF/ON SWITCH

A REMOTE/OFF/ON switch is located on the battery backup card (see figure 5-1).

In the REMOTE position, the remote input is connected to the battery backup card control circuits so that memory is not sustained if power is turned off.

In the OFF position, the relays and regulators are disabled and the memory voltages are a subset of the processor voltages. If AC line power is lost with the switch in the OFF position, memory voltages will not be sustained and data in memory will be lost.

In the ON position, the battery board is enabled upon loss of AC line power, memory voltages are sustained and data in memory is not lost.

5.4.4 AUDIO ALARM

An audio alarm is used to indicate that the memory is on the battery backup system (AC line power lost), and to indicate when the MLOST signal is low (memory or CPU configured incorrectly).

When the memory is on battery backup, the alarm sounds for one second on and 9 seconds off. If the computer is configured incorrectly, the alarm sounds continuously.

Additionally, a two-second alarm is sounded upon power-up if memory data has been lost.

5.4.5 POWER SUPPLY INTERFACE

When AC line power is lost, the HP 12035A Power Supply asserts the PFW (Power Fail Warning) signal. This signal indicates that there is a minimum of 5 msec of regulated DC power. The PFW signal is used to turn on the battery backup and to separate memory power from the CPU power.

5.4.6 CENTRAL PROCESSOR UNIT INTERFACE

If memory voltages fall below the regulation level, the MLOST signal is asserted by the battery backup. The MLOST signal will be asserted for one second after PON is valid. MLOST is used by the CPU to determine if memory data has been lost. If data has not been lost, an auto restart is performed; if data has been lost, memory is cleared and the boot program is entered.

5.5 FUNCTIONAL THEORY OF OPERATION

A functional block diagram of the battery backup is shown in figure 5-2.

5.5.1 BATTERY CHARGER

The HP 12013A Battery Backup card contains six nickel-cadmium batteries: three of 7.2 volt, 500 mAh, and three of 7.2 volt, 100 mAh.

The batteries are charged at a 0.1C rate. This charge rate is low enough so that the batteries can withstand the overcharge rate indefinitely, yet is high enough to provide an "overnight" charge. Five of the battery charge currents are limited by a series resistor to the power supply +12 volts through connector J2, pins 41 and 42. The sixth battery charge current is limited by a series resistor to the power supply -12 volts through connector J2, pins 43 and 44.

5.5.2 VOLTAGE REGULATORS

The battery backup card contains two voltage regulators. One regulates +5 volts, the other +12 volts. Both regulators are designed to operate with a 500 mvolt Vin/Vout differential, and are enabled upon loss of AC line power.

There are no adjustments for the regulators; the reference for each regulator is 2.5 volts +/- 25 mvolts.

5.5.3 NORMAL OPERATION (AC LINE POWER PRESENT)

During normal operation, AC line power is present and the battery backup is in a charge mode. The regulators are disabled and relays short +5M to +5V (J2, pins 45 and 46 to J2, pins 35, 36, 37 and 38), and +12M to +12V (J2, pin 39 to J2, pins 41 and 42). Upon PFW going low, the regulators are enabled and the relays open (removing the shorts).

When PFW goes high (AC line power returns), the regulators are disabled and the relays close, shorting +5M to +5V and +12M to +12V again.

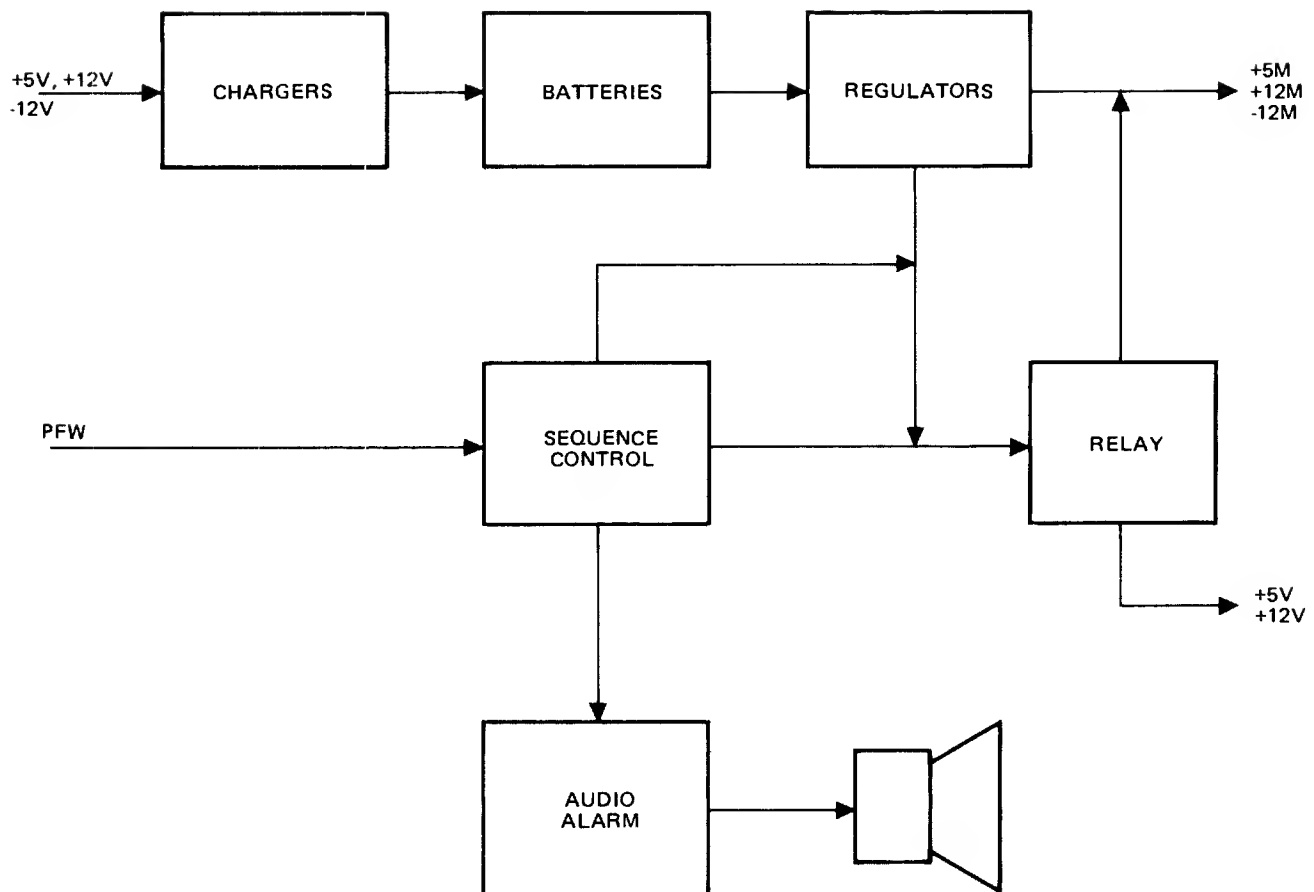


Figure 5-2. Battery Backup Functional Block Diagram

5.5.4 -12 VOLTS

The -12 volts is supplied through a diode to -12 volts on the CPU card, or to -7.2 volts on the battery backup card. This voltage is re-regulated on the memory board down to -5 volts.

5.6 THEORY OF OPERATION

The following paragraphs contain a detailed theory of operation for the battery backup. All components referred to in these paragraphs are shown on the schematic diagram located at the end of this section.

5.6.1 BATTERY CHARGER

Batteries BT4, BT5, and BT6 for the +5 volt regulators are charged through resistor/diode combinations to +12M. For example, BT6 is charged through R26 and CR14 (see the schematic diagram). The resistor limits the current to 61 mA when the battery is fully charged to 7.2 volts. The diode prevents the battery from being discharged through the resistor when the battery backup and the computer are both turned off. Batteries BT4 and BT5 are charged in the same manner using the combinations R29/CR16 and R13/CR11, respectively. Diodes CR13, CR15, and CR12 are used to isolate the batteries so that each is charged individually.

Batteries BT2 and BT3 for the +12 volt regulator also are charged through resistor/diode combination to +12M. BT2 charges through R7 and CR6; BT3 charges through R8 and CR10. While the batteries are charging, relay K3 configures the batteries in parallel (7.2 volts). Resistors R7 and R8 limit the charging current to 17 mA. When operational, relay K3 configures the batteries in series for 14.4 volts.

Battery BT1 output is used for -12 volts and is not regulated. This battery is charged through CR1 and R1 from -12M. Resistor R1 limits the charging current to 17 mA.

5.6.2 +5 VOLT REGULATOR

Operational amplifier U7 and transistors Q3 and Q4 are used for the +5 volt regulation. U7 is used as the error amplifier; pin 3 is the 2.5 volt reference input. The output of the regulator (from Q3) is divided by R30 and R32; this voltage is the negative feedback and is applied to U7, pin 2. The

error amplifier adjusts its output (U7, pin 1) to control the base drive transistor Q4 and series pass transistor Q3. The output of U7 (pin 1) will drive Q4 and Q3 until U7, pin 2 is equal to the reference voltage (U7, pin 3). At this point, the collector of Q3 is at +5 volts and U7 pins 2 and 3 are both 2.5 volts.

The output of the error amplifier (U7, pin 1) is used to turn on the base drive transistor Q4. The higher the output at pin 1, the more Q4 turns on, lowering its collector voltage, and raising the collector voltage of Q3. The base current of Q4 is limited by R33 to a maximum of 1.0 mA. Under minimum voltage conditions, Q4 may go into saturation.

Transistor Q4 controls the base drive of the series pass transistor Q3. The base current of Q3 is limited by R31 to 60 mA. The output of Q3 is the +5 volt regulator output. This output is filtered by capacitor C3.

Over-voltage protection is provided by the 5-volt Transorb CR8. CR8 will limit the output voltage to a safe level (7.0 volts) if there is a component failure or if there is an external over-voltage condition. If the power level exceed 1500 watts for more than 8 msec, CR8 will fail (shorts).

Over-current protection is provided by current sense resistor R11 and comparator U3 (pins 8, 9, and 14). U3, pin 8 monitors the current of batteries BT4, BT5, and BT6. If the voltage into U3, pin 3 from the voltage divider R21/R22 exceeds 160 mvolts, then U3, pin 14 lowers +5 volt regulator reference voltage at U7, pin 3, and the regulator will turn off.

5.6.3 +12 VOLT REGULATOR

Operational amplifier U7 and transistors Q2 and Q5 are used for the +12 volt regulation. U7 is used as the error amplifier; pin 5 is the 2.5 volt reference input. The output of the regulator (from Q2) is divided by R35 and R36; this voltage is the negative feedback and is applied to U7, pin 6. The error amplifier adjusts its output (U7, pin 7) to control the base drive transistor Q5 and series pass transistor Q2. The output of U7 (pin 7) will drive Q2 and Q5 until U7, pin 6 is equal to the reference voltage (U7, pin 5). At this point, the collector of Q2 is at +12 volts and U7 pins 5 and 6 are both 2.5 volts.

The output of the error amplifier (U7, pin 7) is used to turn on the base drive transistor Q5. The higher the output at pin 7, the more Q5 turns on, lowering its collector voltage, and raising the collector voltage of Q2. The base current of Q5 is limited by R34 to a maximum of 1.0 mA. Under minimum voltage conditions, Q5 may go into saturation.

Transistor Q5 controls the base drive of the series pass transistor Q2. The base current of Q2 is limited by R37 to 60 mA. The output of Q2 is the +12 volt regulator output. This output is filtered by capacitor C2.

Over-voltage protection is provided by the 12-volt Transorb CR9. CR9 will limit the output voltage to a safe level (15.0 volts) if there is a component failure or if there is an external over-voltage condition. If the power level exceed 1500 watts for more than 8 msec, CR9 will fail (short).

Over-current protection is provided by current sense resistor R9 and comparator U3 (pins 10, 11, and 13). U3, pin 10 monitors the current of batteries BT2, and BT3. If the voltage into U3, pin 11 from the voltage divider R17/R18 exceeds 160 mvolts, then U3, pin 13 lowers +12 volt regulator reference voltage at U7, pin 5, and the regulator will turn off.

5.6.4 -12 VOLT OUTPUT

Negative 7.2 volts is provided for the memory -12M voltage. Transistor Q1 is used as a switch. If +12M is present, diode CR3 will have 9.0 volts across it and Q1 base/emitter resistor R2 will have 10 volts across it (10 mA base drive). Transistor Q1 will turn on. If +12 volts is not present, the voltage across CR3 and R2 will be lower and Q1 will turn off. This switching circuit is necessary to prevent the battery from being discharged when the computer is turned off.

5.6.5 RELAY LOGIC

Relays K1, K2, and K3 are momentary type relays and are normally closed (pin 4 to 1). Relay K3 is used to connect batteries BT2 and BT3 in series or parallel (see paragraph 5.6.1).

Relay K1 is used to provide a path for the computer power supply to provide memory with +12 volts. Relay K1 is used for the power supply to provide memory with +5 volts.

All three relays (K1, K2, and K3) are driven by U5.

Switch S1 is used to switch the battery backup to ON, OFF, or REMOTE. When S1 is ON, the relays are connected to CR7 and R5. If power is lost, CR7 is used to power the relays; R5 limits the current and holds the relays on. The relays will not activate unless 12 volts is present. Thus, the battery backup will stay off, even if S1 is ON, if the card is plugged into a computer with its power off.

5.6.6 CONTROL SEQUENCE LOGIC

The battery backup card uses the PFW signal to control the operation of the regulator, relays, and audio alarm.

Table 5-2 shows a power down sequence and table 5-3 shows a power up sequence. CR21, R24, and C9 provide an RC time delay of 3 msec for relays K1 and K2 (table 5-2, step 6). CR22, R16, and C6 provide 3 msec delay (table 5-3, step 4) to keep regulators on until primary regulation of the power is restored. U3, pins 1 and 2 form an OR gate. If PFW (U3-1) or the batteries are less than 1 volt per cell (U3-2), then relay K3 is opened. This turns the 12-volt regulator off, relays K1 and K2 lose power (+12M), and the battery backup turns off.

The data path formed by P1-7, U3-6, U4-12, U5-1, and K3 is used to enable the regulators. Data path P1-7, U4-9, U4-3, U5-2, K2, and K1 is used to connect power supply voltages to the memory.

Logic levels for sequence control are 0 to +12 volts; 2.5 volts is the threshold.

When AC line power is present, the regulators on the battery backup card are disabled. Diodes CR17 (5 volt regulator) and CR19 (12 volt regulator) are grounded by relay K3, the anodes of the diodes clamp the voltage of the base drive transistors (Q4 and Q5) to approximately 1.0 volts. Because of diodes CR15 and CR20, greater than 2 volts is required to turn on the base drive transistors.

5.6.7 AUDIO ALARM/MLOST SIGNAL

The audio alarm (DS1) is driven by U1. When the battery backup is operating, U5, pin 11 enables the timing components C1, R3, and R4. The timer is on for 1 second, off for 9.

The reset on U1 (pin 4) is used to produce a continuous tone if the MLOST signal or the MLOST timer is low. U2 is the MLOST timer. If the +5M voltage drops to less than 4.66 volts, the MLOST timer goes low and the continuous tone is produced. The timer resets itself after about 2 seconds.

Table 5-2. AC Line Power Down Sequence

1. Power Fail Warning (PFW) goes low.
2. Delay of 100 usec.
3. Alarm timer is enabled; alarm will sound in 9 seconds.
4. Relay K3 configures BT2 and BT3 in series (14.4 volts). One msec to complete.
5. Regulators are enabled.
6. Delay of 3 msec.
7. Relays K1 and K2 disconnect memory load from processor load. Three msec to complete.
8. Battery backup is enabled.

Table 5-3. AC Line Power Up Sequence

1. Power Fail Warning (PFW) goes high.
2. Delay of 100 usec.
3. Relays K1 and K2 connect memory load to processor load.
4. Delay of 3 msec.
5. Alarm timer is disabled.
6. Relay K3 configures BT2 and BT3 in parallel for charge operation.
7. Regulators are disabled.
8. Memory is now powered from HP 12035A Power Supply (AC primary power).

5.7 PARTS LOCATIONS

Parts locations for the HP 12013A Battery Backup are shown in figure 5-3.

5.8 PARTS LIST

The parts list for the battery backup is shown in table 5-4. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

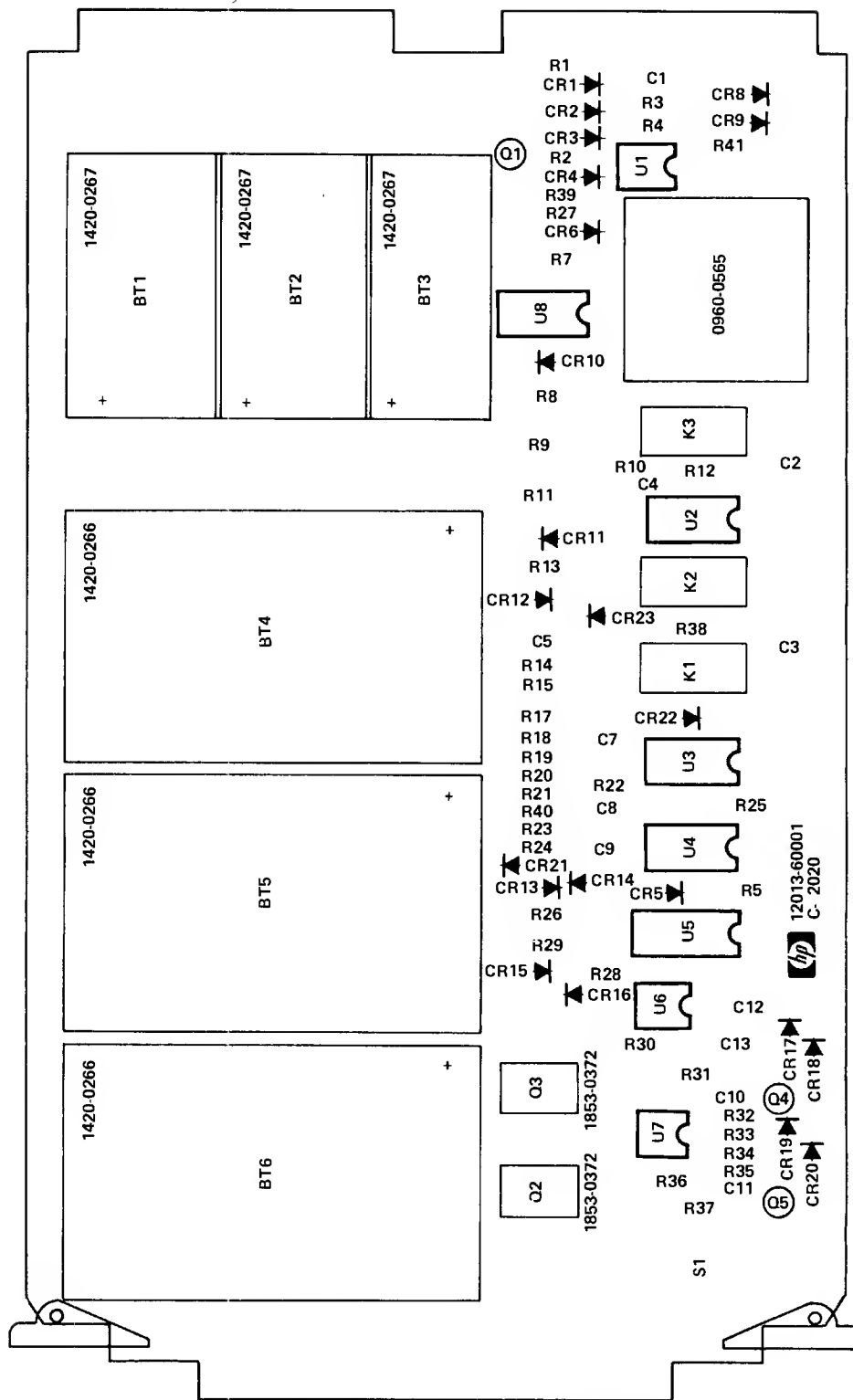
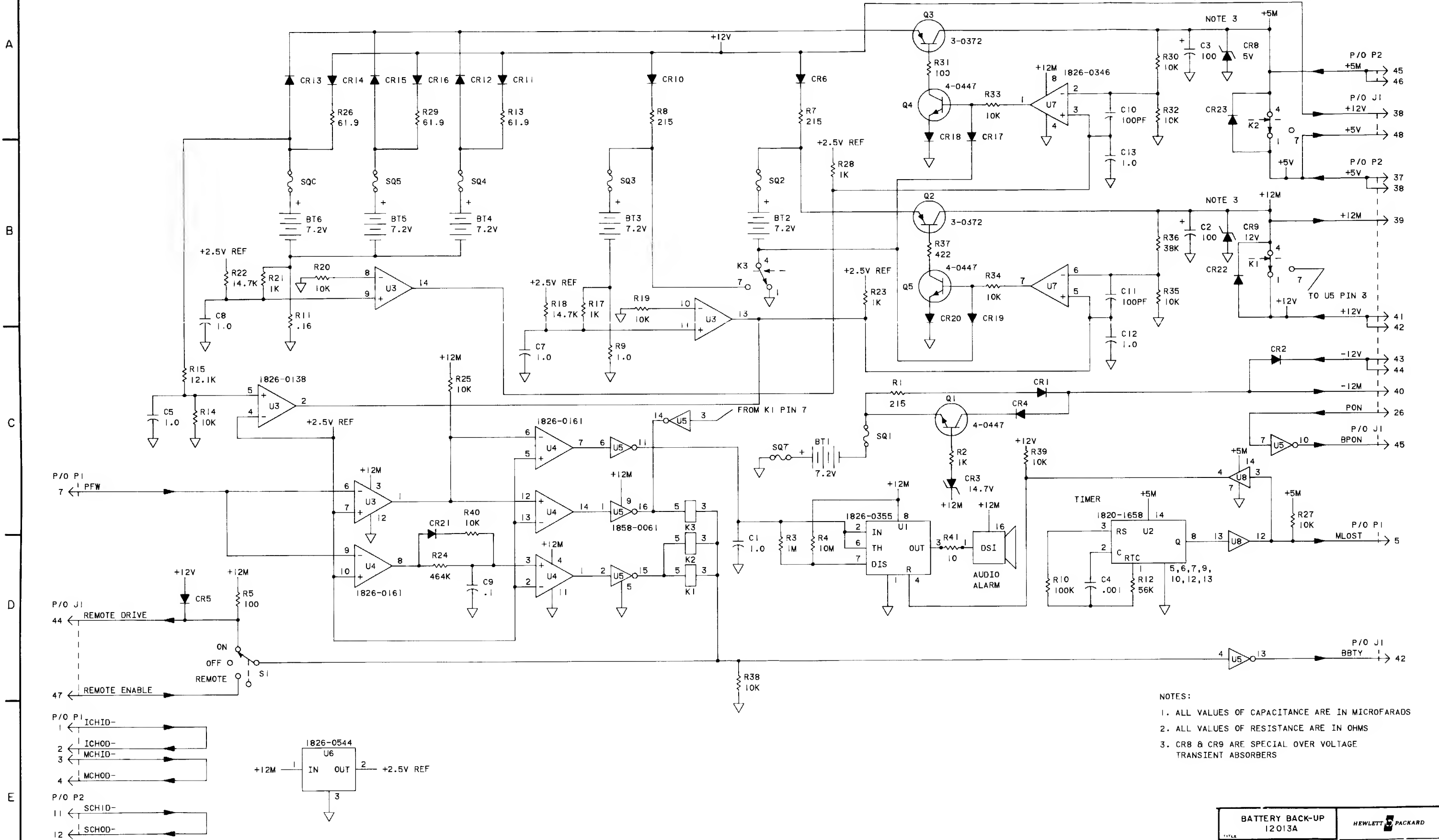


Figure 5-3. HP 12013A Battery Backup Parts Locations

Table 5-4. Battery Backup Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12013-60001	3	1	BATTERY BACKUP	28480	12013-60001
C2	0180-2374	7	2	CAPACITOR-FXO 100UF+-10% 20VDC TA	56289	150D107X9020X2
C3	0180-2374	7		CAPACITOR-FXO 100UF+-10% 20VDC TA	56289	150D107X9020X2
CR8	1902-0939	9	1	DIODE-ZNR 5V P=5W TC=+.06% IRL300UA	11961	1N5908
CR9	1902-0941	3	1	DIODE-ZNR 12V P=5W TC=+.084% IRL2UA	11961	1.58E15A
C912	1901-1080	1	5	DIODE-8CHOTTKY 1N5817 20V 1A	28480	1901-1080
CR13	1901-1080	1		DIODE-8CHOTTKY 1N5817 20V 1A	28480	1901-1080
CR15	1901-1080	1		DIODE-8CHOTTKY 1N5817 20V 1A	28480	1901-1080
CR22	1901-1080	1		DIODE-8CHOTTKY 1N5817 20V 1A	28480	1901-1080
C923	1901-1080	1		DIODE-8CHOTTKY 1N5817 20V 1A	28480	1901-1080
K1	0490-0694	7	3	RELAY-9EED 1C 1A 30VDC 12VDC-COIL	28480	0490-0694
K2	0490-0694	7		RELAY-9EED 1C 1A 30VDC 12VDC-COIL	28480	0490-0694
K3	0490-0694	7		RELAY-REED 1C 1A 30VDC 12VDC-COIL	28480	0490-0694
Q1	1854-0477	7	3	T9AN818T09 NPN 2N2222A 81 TO-18 P=500MW	04713	2N2222A
Q2	1853-0372	9	2	TRANSISTOR PNP 81 TO-220AB P=60W	04713	MJE5195
Q3	1853-0372	9		T9AN818T09 PNP 81 TO-220AB P=60W	04713	MJE5195
Q4	1854-0477	7		TRANSISTOR NPN 2N2222A 81 TO-18 P=500MW	04713	2N2222A
Q5	1854-0477	7		T9AN818T09 NPN 2N2222A 81 TO-18 P=500MW	04713	2N2222A
Q1	0698-3401	0	3	RESISTOR 215 1% .5W F TC=0+-100	28480	0698-3401
Q7	0698-3401	0		RESISTOR 215 1% .5W F TC=0+-100	28480	0698-3401
R8	0698-3401	0		RESISTOR 215 1% .5W F TC=0+-100	28480	0698-3401
R9	0811-1666	7	1	RESISTOR 1 5% 2W PW TC=0+-800	75042	BMM2-1R0-J
R11	0811-3291	8	1	RESISTOR .12 5% 2W PW TC=0+-800	28480	0811-3291
R13	0757-1002	9	3	RESISTOR 61.9 1% .5W F TC=0+-100	28480	0757-1002
Q26	0757-1002	9		RESISTOR 61.9 1% .5W F TC=0+-100	28480	0757-1002
R29	0757-1002	9		RESISTOR 61.9 1% .5W F TC=0+-100	28480	0757-1002
Q31	0757-0198	2	1	RESISTOR 100 1% .5W F TC=0+-100	28480	0757-0198
Q37	0698-3405	4	1	RESISTOR 422 1% .5W F TC=0+-100	28480	0698-3405
B1	3101-1513	1	1	SWITCH-TOGGLE 3-POSITION 2 PC	28480	3101-1513
U1	1820-2466	7	1	IC TIMER CMOS	32293	ICM7555TPA
U2	1820-1658	7	1	IC TIMER CMOS	04713	MC145418CP
U3	1826-013A	8	1	IC COMPARTOR GP QUAD 14-DIP-P	01295	LM339N
U4	1826-0161	7	1	IC OP AMP GP QUAD 14-DIP-P	04713	MLM324P
U5	1858-0061	3	1	TRANSISTOR ARRAY 16-PIN PLSTC DIP	13606	ULN-2004A
U6	1826-0544	0	1	V PEF 8-DIP-C	04713	MC1403U
U7	1826-0346	0	1	IC OP AMP GP QUAL 8-DIP-P	27014	LM358N
UA	1820-0668	7	1	IC BFR TTL NON-INV HEX 1-INP	01295	8N7407N
				MISCELLANEOUS PARTS		
	0403-0289	3	1	EXTR-PC BD REG POLYC .063-BD-TMKN8	28480	0403-0289
	0960-0565	8	1	AUDIO INDICATOR	28480	0960-0565
	1420-0266	3	3	BATTERY	28480	1420-0266
	1420-0267	4	3	BATTERY	28480	1420-0267
				1420-0266		
				7.2V .45A-MR	MICD	
				1420-0267		
				7.2V .1A-MR	MICD	

D-12013-60001-51		REVISED	DATE
SYM	AS ISSUED		
A	PFW CKT CHANGES		
B			
C	PRCR 85, CIRCUIT CHG R15 WAS 13.3K (8-2020)		



- NOTES:
1. ALL VALUES OF CAPACITANCE ARE IN MICROFARADS
 2. ALL VALUES OF RESISTANCE ARE IN OHMS
 3. CR8 & CR9 ARE SPECIAL OVER VOLTAGE TRANSIENT ABSORBERS

BATTERY BACK-UP 12013A		HEWLETT-PACKARD	
NEXT ASSEMBLY	12013A	PART NUMBER	12013-60001
FINISH	SCALE	- 12013-60001-51	

BACKPLANE	SECTION VI
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6.1 INTRODUCTION

The L-series backplane provides a link between the L-Series Computer System processor, memory, interface cards and power supply.

In this document, the backplane will be viewed from two different aspects: physical and logical.

Physically, the backplane is merely a mother board for the processor, memory and interface cards. It is a printed circuit card, on which the traces carry the power, ground and interconnecting signals between all the cards in an L-Series Computer System. See figure 6-1 for the physical layouts of the one-by-five and two-by-five backplanes.

The logical backplane defines protocols for the communications between all cards in the system. The definition, function, and timing of the backplane signals, and the protocols for their interaction are all considered to be part of the logical backplane.

Thus, the physical backplane houses a set of communications channels, whereas the logical backplane defines protocols for that communication.

This section covers both aspects of the L-Series backplane, and is intended to provide all the information needed to design a hardware interface to the backplane and thereby successfully integrate a design of arbitrary function into the L-Series computer.

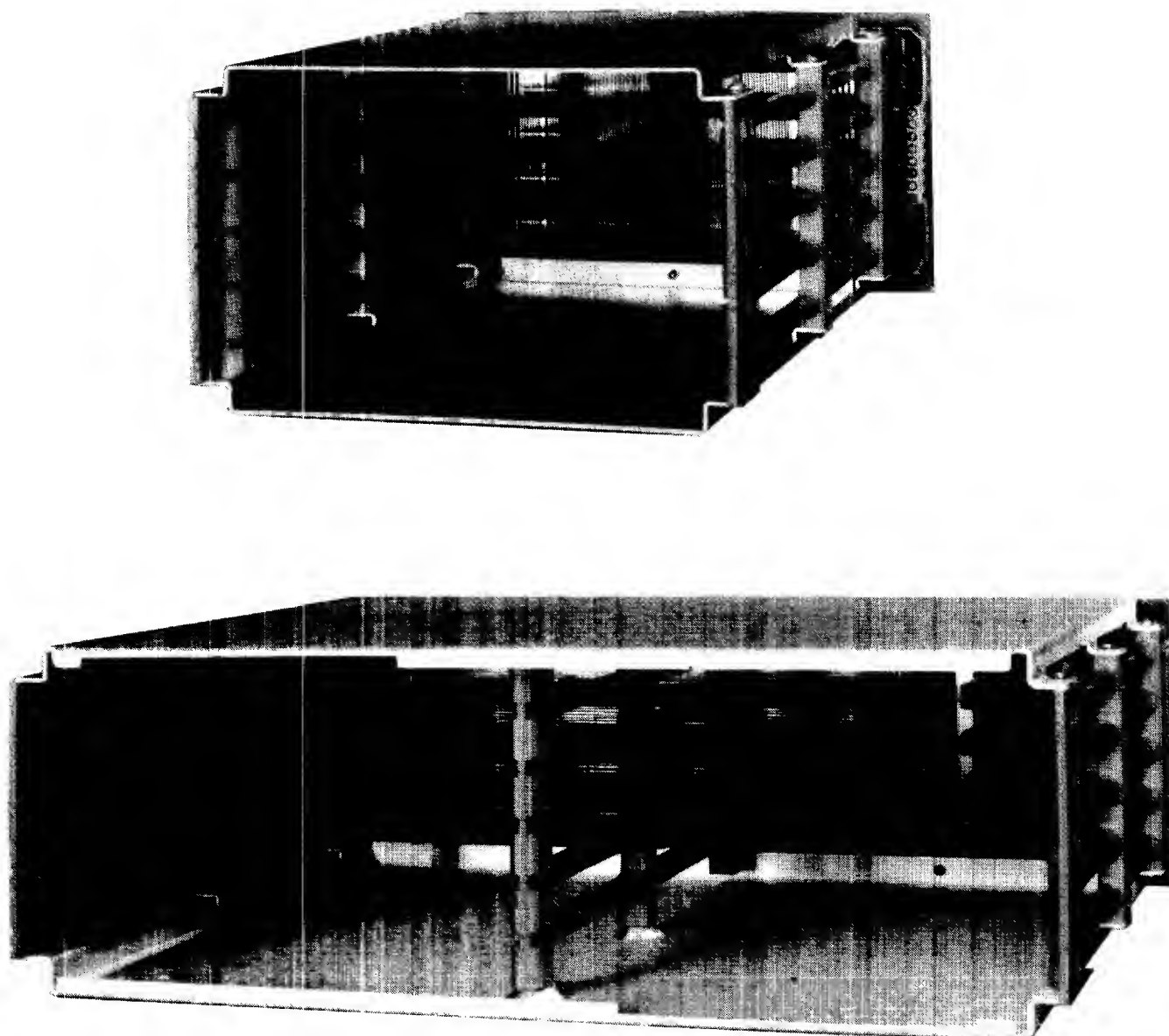


Figure 6-1. HP 1000 L-Series Backplanes

6.2 OVERVIEW

6.2.1 SYSTEM ENVIRONMENT OVERVIEW

An L-Series backplane (side view) is shown in figure 6-2 integrated into a system environment. Note that there are two types of connections to the backplane, labeled A and B. These are used as follows:

A. POWER SUPPLY CONNECTOR

A 24-pin socket which accepts control signals and voltages from the power supply.

B. CARD SLOTS

Each card plugs into a set of dual 50-pin sockets, for a total of 100 connections. These pins carry signals, power, and ground connections between the card and the backplane. The backplane shown in figure 6-2 has a total of 16 card slots.

Details on these interconnections are presented in paragraph 6.3, SPECIFICATIONS.

L-Series cards can be plugged into any backplane card slot subject to the following constraints.

- a. The battery backup card must go in a top slot to give the batteries adequate clearance.
- b. The memory card must go directly above the processor card.
- c. All I/O cards must go below the processor card.
- d. Any unused slot between two cards must be filled with a priority jumper card.

The terms "above" and "below" are not to be taken quite literally here. The term "above" refers to a higher priority slot and "below" refers to a lower priority slot. The backplane slots are numbered from XA1, the highest priority slot in order down to XAn, the nth highest priority slot. (See figure 6-3 for slot priority information.)

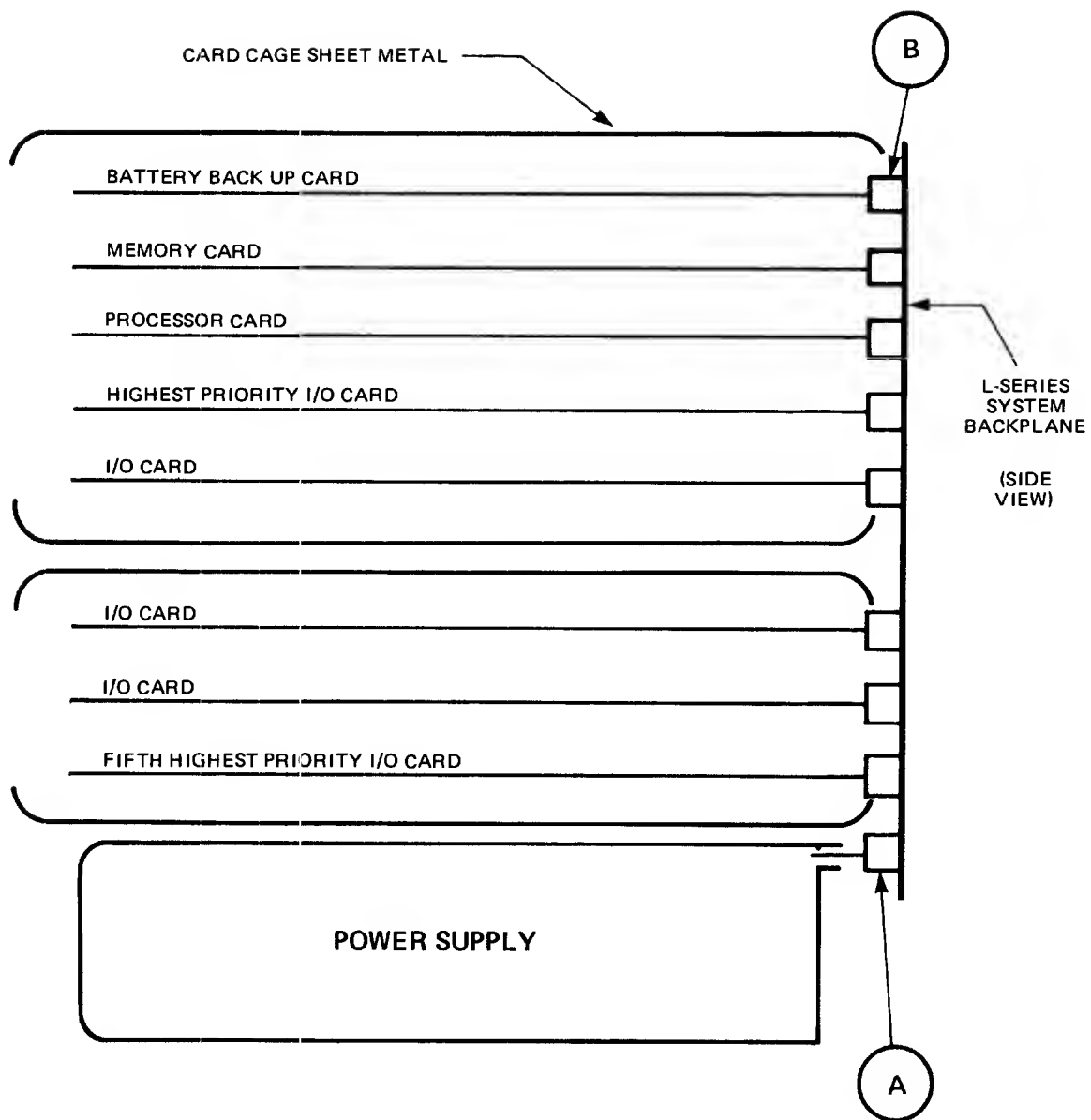


Figure 6-2. Backplane in Typical System Environment

6.2.2 INTERNAL SPECIFICATIONS OVERVIEW

The L-Series backplane is currently offered in three different configurations as shown in figures 6-3, 6-4, and 6-5.

The backplane in figure 6-3 is arranged in two stacks of eight slots, called a "2-by-8" configuration and is designed for the L-Series system. Figure 6-4 shows the "2-by-5" configuration which is designed for the 5-1/4 inch 2103L box. Figure 6-5 shows the "1-by-5" configuration which is designed for small controller type applications.

The three diodes on each backplane are on the +5V, +12V and -12V lines from the HP 12035A Power Supply. They are transient voltage suppressors, with a clamping action response of one picosecond, and the capability of handling a surge current of 50 amperes. They serve to protect the components on the cards plugged into the backplane from any power supply over-voltage or transient spike.

The physical backplane distinguishes between four types of traces.

- a. Bus line: This line is common to the same pin on each set of card sockets. Examples are WE- and CRS-.
- b. Power Supply line: This line comes from the power supply and runs to the same pin on each set of card sockets. Examples are PFW and PONT+.
- c. Ground and Voltage lines: This line comes from the power supply and typically has two or more pin assignments on each set of card sockets. Grounds and voltages are typically carried on much wider traces than other signals. Examples are +5V and +12V.
- d. Chained lines: This is a set of lines which connect every pair of adjacent card sockets. Each of these lines is common to exactly two sockets. Examples are ICHID-, ICHOD-, SCHID-, and SCHOD-.

The distinction between these four types of lines is important when determining backplane compatibility.

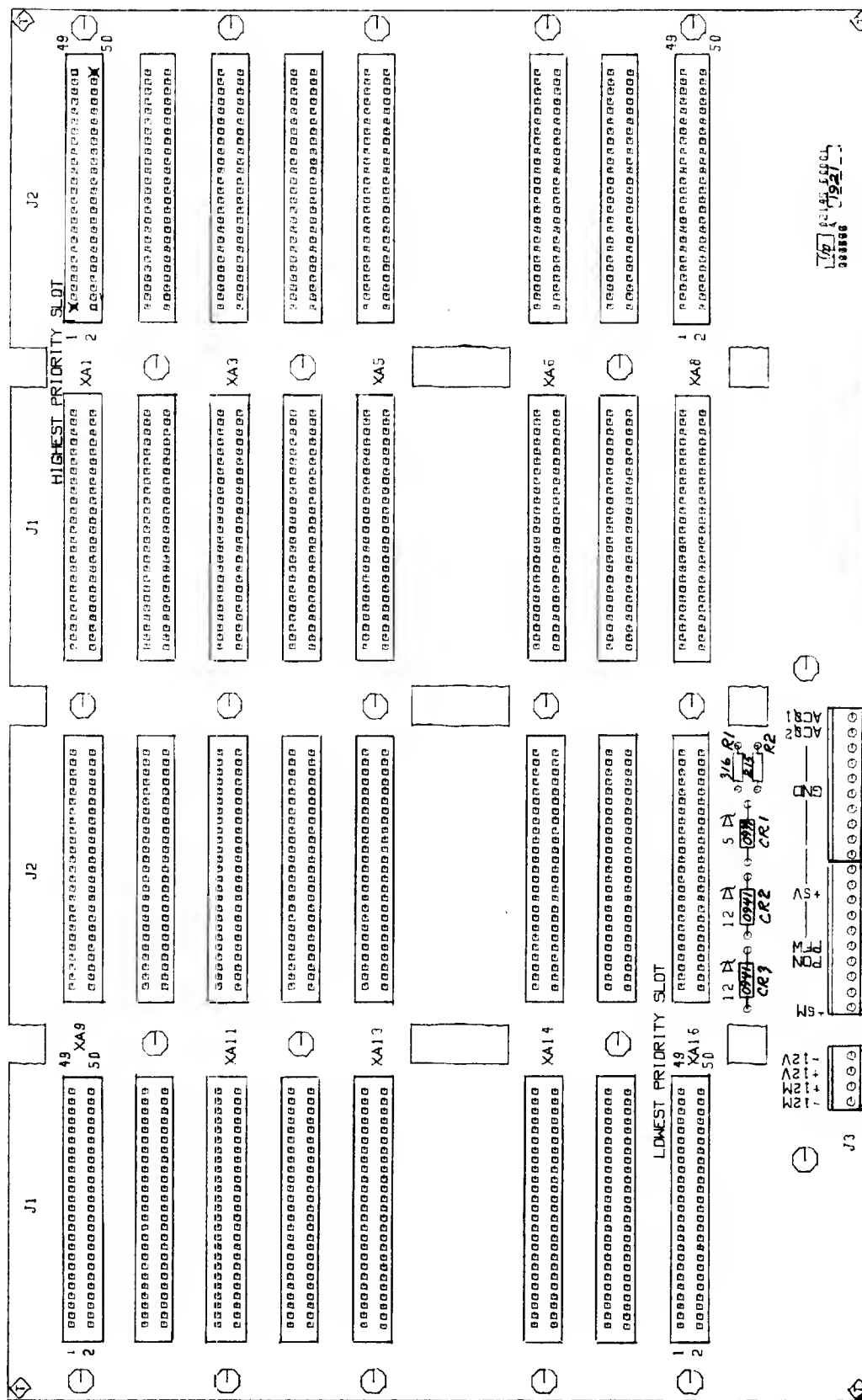


Figure 6-3. Two-by-Eight Backplane

6.2.3 BACKPLANE INTERFACE HARDWARE

All backplane interface hardware can be broken down into four categories as listed below. It may be helpful to become familiar with one or more of these categories.

6.2.3.1 Processor Interface

This interface is responsible for generating all backplane clocks, and, in addition, such signals as RNI (Read Next Instruction) and IAK (Interrupt Acknowledge). The processor interface information is presented in Section II of this document.

6.2.3.2 Memory Interface

This interface is responsible for generating such signals as PE (memory Parity Error) and VALID (data bus Valid). The memory interface information is presented in Section III.

6.2.3.3 I/O Master Interface

The I/O Master interface consists of an IOP chip and its support logic. This circuitry is located on every L-series I/O card and serves to standardize the I/O interface to the backplane by performing all the functions (I/O instruction recognition and execution, interrupt processing, DMA control) common to all I/O cards.

6.2.3.4 Passive Interfaces

Passive interfaces include those that supply, monitor or use power lines, or monitor signals without ever generating signals or interacting on the backplane. These interfaces include the L-series Interface for Logic Analyzers and the Battery Backup card.

6.3 SPECIFICATIONS

6.3.1 GENERAL HARDWARE SPECIFICATIONS

The 2 by 5 and 2 by 8 backplanes use a six-layer printed circuit card. One +5V plane and a ground plane minimize signal crosstalk and permit the traces to maintain a consistent characteristic impedance throughout their length. Most of the logic used to drive the backplane signals is Schottky TTL, and because of the high switching speeds characteristic of this logic family, good noise immunity is necessary for the backplane.

The use of the four remaining layers is roughly as follows: One layer is used for the set of signals running vertically between the five slots in each stack; two are used for the set of signals running horizontally to connect the stacks; and the last layer is used for the miscellaneous voltages. This layout provides all the signal traces with a steady characteristic impedance of 47 to 51 ohms. This provides a good match with the output impedances of the backplane drivers, which are in the range of 25 to 100 ohms. That is, all impedances are matched within a 2 to 1 ratio.

The 1 by 5 backplane uses a two-layer printed circuit card. The complexity of this physical backplane is reduced considerably because the two layers used to interconnect the two stacks in the 2 by 5 configuration are eliminated in the 1 by 5 configuration. Due to the maximum trace length of 3.2 inches on this backplane, no noise problems are encountered.

6.3.2 POWER SUPPLY INTERCONNECT

A 24-pin connector is used to connect to the power supply for the 2 by 5 and 2 by 8 configurations. The female connector is soldered along the bottom of the backplane. The male connector is rigidly attached to the power supply module in such a manner that it plugs in as the power supply module is slid into place. The connectors are rated at 7 amperes/pin. Pin assignments for the power supply connector are as shown in table 6-1.

The paths on the backplane extending from the power supply connector carry relatively high currents, and therefore must be as broad as possible. Ground and +5V, the most used levels, are transferred over whole planes. Other voltages are carried on traces as much as 200 mils wide. The width of each trace was selected so that it could withstand relatively large current surges without much voltage fluctuation (inductance is the key parameter here) and so that it would experience a temperature rise of less than 10 degrees C at the maximum current rating of the power supply.

Table 6-1. Power Supply Connector Pin Assignments

PIN NUMBER	SIGNAL NAME
1	-12V MEMORY VOLTAGE SENSE
2	+12V MEMORY VOLTAGE SENSE
3	+12V LOGIC (4A MAX)
4	-12V LOGIC (2A MAX)
5	+5V MEMORY VOLTAGE SENSE
6	NOT USED
7	NOT USED
8	POWER ON (PON) SIGNAL
9	POWER FAIL WARNING (PFW) SIGNAL
10	} +5V LOGIC (30A)
11	
12	
13	
14	
15	} DC COMMON, 25kHz COMMON
16	
17	
18	
19	
20	
21	
22	
23	25kHz PHASE 2, 14VRMS (TO GND)
24	25kHz PHASE 1, 14VRMS (TO GND)

6.3.3 CARD SOCKET INTERCONNECTS

Each card in the L-Series has two 50-pin tongues, P1 and P2, which plug into a set of 50 pin sockets on the backplane, J1 and J2 respectively. The card cage is constructed with card guides, in such a manner that the cards will slide in and then snap into place in the backplane connectors. The cards must be inserted component side up as shown in figure 6-6. The odd numbered fingers will then be on the top, and the even numbered ones on the bottom. The pin assignments for these 100 connections are given in figure 6-7. For signal definitions, see table 6-37.

6.3.4 BACKPLANE LOADING RULES

Backplane loading rules were established in order to provide guidelines for the selection of bus drivers and backplane signal drivers, and in order to insure that these drivers are not overloaded. These rules take into account the drive capabilities and loading of certain industry standard parts such as the S and LS 240 and 241. Because there may be a maximum of 18 I/O interface cards in any given system, each card must adhere strictly to the rules in order to prevent possible overloading. These loading rules were established assuming a maximum of 20 cards in a system. Note that the I/O Master is designed such that all backplane lines except the data bus are buffered and cannot be used in the unbuffered form by I/O interface logic external to the I/O Master.

6.3.4.1 DC Loading

DC loading rules are made to insure that a device driving any given backplane line can handle sufficient current to keep all the inputs connected to that line at the required voltage level. Low state load on a given line is the sum of I_{IL} maximum for all receivers plus I_{OZL} for all tri-state drivers. High state load is the sum of I_{IH} for all receivers plus I_{OZH} for all tri-state drivers.

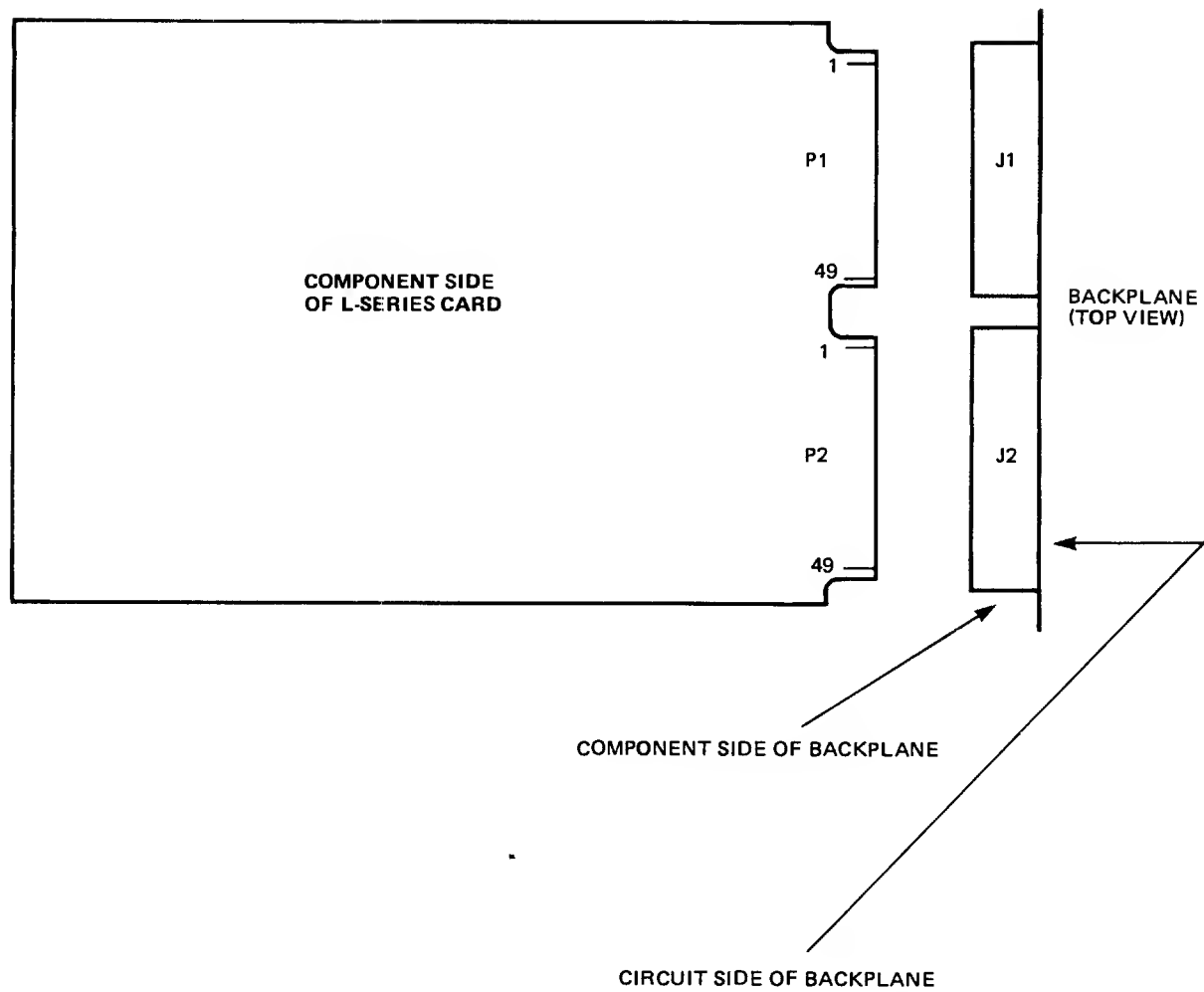


Figure 6-6. Card Socket Interconnects

J1				J2			
1	* ICHID-	ICHOD-	2	1	CPUTURN-	ISOGND	2
3	**MCHID-	MCHOD-	4	3	REMEM-	VALID-	4
5	ML0ST-	MCHODOC-	6	5	IORQ-	INTRQ-	6
7	PFW-	SPARE 1	8	7	MP+	RNI-	8
9	SC0+	SC1+	10	9	MEMGO-	PE-	10
11	SC2+	SC3+	12	11	***SCHID-	SCHOD-	12
13	GND	GND	14	13	IAK-	IOGO-	14
15	COTURN-	GND	16	15	ISOGND	SLAVE-	16
17	SC4+	SC5+	18	17	ISOGND	MRQ-	18
19	AB0+	AB1+	20	19	ISOGND	FCLK-	20
21	AB2+	AB3+	22	21	ISOGND	CCLK-	22
23	AB4+	AB5+	24	23	SPRQ-	SCLK-	24
25	AB6+	AB7+	26	25	CRS-	PON+	26
27	AB8+	AB9+	28	27	ISOGND	BUSY-	28
29	AB10+	AB11+	30	29	GND	GND	30
31	AB12+	AB13+	32	31	GND	GND	32
33	AB14+	WE-	34	33	GND	GND	34
35	DB0+	DB1+	36	35	+5V	+5V	36
37	DB2+	DB3+	38	37	+5V	+5V	38
39	DB4+	DB5+	40	39	+12M	-12M	40
41	DB6+	DB7+	42	41	+12V	+12V	42
43	DB8+	DB9+	44	43	-12V	-12V	44
45	DB10+	DB11+	46	45	+5M	+5M	46
47	DB12+	DB13+	48	47	25kHz 02	25kHz 02	48
49	DB14+	DB15+	50	49	25kHz 01	25kHz 01	50

* - Above the processor card, this signal is called PS-.

** - Above the processor card, this signal is called RCLK+.

*** - Above the processor card, this signal is called MEMDIS-.

Figure 6-7. Card Slot Pinouts

6.3.4.2 Actual Worst Case Loading

Actual worst case loading for the address bus, select code bus 0-4, and the data bus is as follows:

ADDRESS BUS, AND SELECT CODE BUS 0 - 4:

	Low State Load	High State Load
64Kbyte dynamic RAM	.4mA	20uA
L-series Processor	1.7mA	150uA
I/O Master (times 18)	7.2mA	360uA
	-----	-----
TOTAL	9.3mA	530uA

DATA BUS:

	Low State Load	High State Load
64Kbyte dynamic RAM	2.5mA	150uA
L-series Processor	3.4mA	280uA
I/O Master (times 18)	17.5mA	1800uA
	-----	-----
TOTAL	23.4mA	2.23mA

The design rules and guidelines are shown in table 6-2.

Table 6-2. Design Rules/Guidelines

! Design Rules/Guidelines	! Address Bus, ! ! SC Bus 0-4 !	! Data Bus !	! All Other ! ! Bussed ! ! Lines !	! Chained ! ! Lines !
! Maximum allowable load	!	!	!	!
! per card - high state	! 130uA	! 250uA	! 60uA	! 400uA
! Maximum allowable load	!	!	!	!
! per card - low state	! 1.2mA	! 1.2mA	! 1mA	! 10mA
! Minimum allowable drive	!	!	!	!
! capability - high state	! 2.6mA	! 5.0mA	! 1.2mA	! 1mA
! Minimum allowable drive	!	!	!	!
! capability - low state	! 24mA	! 24mA	! 20mA	! 20mA

6.3.4.3 AC Loading

Every connection made to any given line places a capacitive load on that line due to PC board trace capacitance and due to the integrated circuit input or output capacitance. Care must be taken to insure that any given line is not capacitively overloaded as this results in slowing its switching speed down below a tolerable point. Typical delays are in the range of 2ns/50pF for a line driven by an LS240/241 and 4ns/50pF for an LS373/374.

The AC loading specifications, as with the DC loading rules, should be strictly adhered to for the I/O interfaces, but can be used merely as guidelines for processor and memory cards. Signal timing calculations are made considering actual worst case loads as shown in table 6-3. Again, a 20-slot system is assumed.

6.3.4.4 Data Bus

Each card may not exceed 60pF load per line.

6.3.4.5 All Other Lines

Each card may not exceed 25pF load per line.

6.4 INTERFACE REQUIREMENTS

The following paragraphs deal exclusively with the logical backplane. The protocols and conventions used by all L-Series cards to interact over the backplane are classified and described. An important feature of the L-Series computer is its distributed intelligence. Every interface card in the system has the capability of handling its own memory accesses (DMA), of decoding its own instructions, and of forcing the central processor into slave mode processing. Each of these three capabilities and the protocols with which they are implemented are described. You may find it helpful, while working through each handshake protocol, to refer to the glossary of signal definitions in table 6-37.

Table 6-3. Capacitance Data on 20-Slot System

PIN	SIGNAL	C IN pF L
J1 - 1,2	ICHID, ICHOD	40
J1 - 3,4	MCHID, MCHOD	25
J1 - 5	MLOST	200
J1 - 6	MCHODOC	850
J1 - 7	PFW	200
J1 - 9,10,11,12,17	SC0 - SC4	400
J1 - 18	SC5	900
J1 - 19,20,...,34	ADDRESS BUS	500
J1 - 35,36,...,50	DATA BUS	1300
J2 - 1	CPUTURN	400
J2 - 3	REMEM	600
J2 - 4	VALID	550
J2 - 5	IORQ	580
J2 - 6	INTRQ	650
J2 - 7	MP	500
J2 - 8	RNI	500
J2 - 9	MEMGO	550
J2 - 10	PE	500
J2 - 11,12	SCHID, SCHOD	30
J2 - 13	IAK	500
J2 - 14	IOGO	500
J2 - 16	SLAVE	740
J2 - 18	MRQ	550
J2 - 20	FCLK	500
J2 - 22	CCLK	620
J2 - 23	SPRQ	250
J2 - 24	SCLK	500
J2 - 25	CRS	500
J2 - 26	PON	550
J2 - 28	BUSY	400
NOTE: All capacitances shown are worst case figures.		

6.4.1 MEMORY ACCESS PROTOCOL

Every card that accesses memory uses the same handshake protocol. This approach greatly simplifies the operation of multichannel DMA. The DMA feature of every L-Series I/O interface allows input or output operations to proceed without processor intervention, significantly easing the processing requirements on the CPU. The processor is the lowest-priority DMA device because if any other card pulls on the open-collector line MRQ (Memory Request), the processor is held off from doing a memory cycle. The processor may be locked out entirely for up to 72 usec by high speed interfaces using adjacent memory cycles. In order to prevent being locked out entirely, the processor can assert the CPUTURN- signal which informs the interface cards not to reassert MRQ after their current memory request is satisfied. For more information on CPUTURN-, refer to the definition in table 6-37.

A priority scheme is used in the L-Series to resolve contention between interfaces wanting memory cycles. An interface wanting a memory cycle will assert MRQ-, MCHOD-, and MCHODOC-. The first signal, MRQ-, will disable the processor from taking the next memory cycle. MCHOD- is part of a priority chain which will ripple down, disabling all lower-priority interfaces. MCHODOC- is a look-ahead on this chain. It is used as the top of the chain for the stack of lowest-priority slots. Although MRQ- may be asserted by one or more interfaces at any given time, MEMGO- may only be asserted by the one interface that gets the memory cycle. An interface determines if it is entitled to a memory cycle (to assert MEMGO-) by monitoring certain backplane signals. It can initiate a memory cycle on any falling edge of SCLK- when BUSY- is high, its MCHID- is high, and its MRQ- has been asserted for at least one cycle. This stipulation means that contention among I/O cards for memory always has one cycle of SCLK in which to be resolved, namely, the cycle which occurs just before the assertion of MEMGO-.

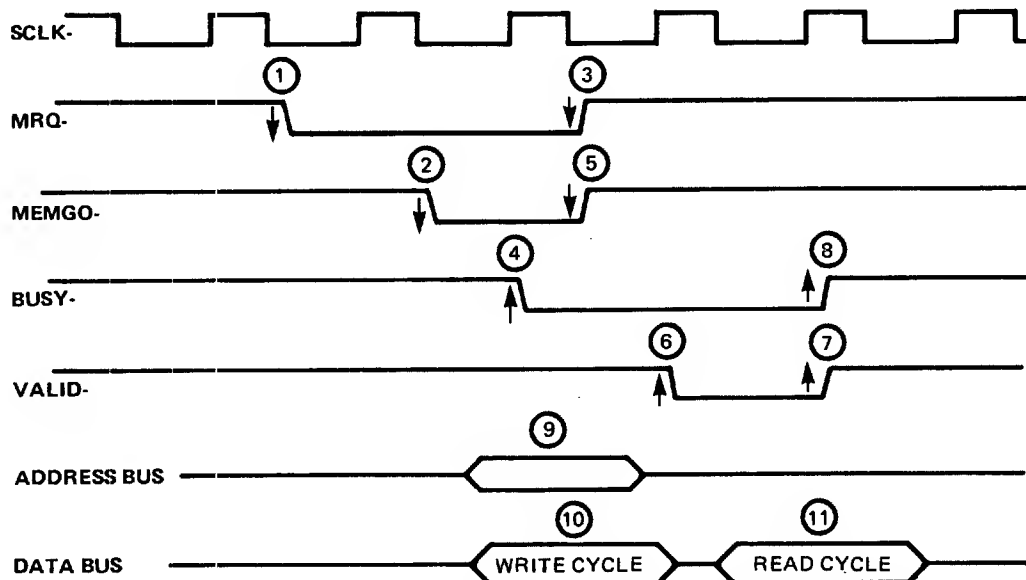
The processor card begins its access to memory by asserting MEMGO- on the falling edge of SCLK-. If an I/O interface card desiring a DMA transfer asserts MRQ- on that same edge, the processor card must immediately relinquish its claim to accessing memory by releasing MEMGO- prior to the next rising edge of SCLK-. Therefore, contention between the processor and any I/O interface for memory is resolved during the long half cycle between the falling and rising edges of SCLK-. MEMGO- will be asserted at the completion of all current DMA requests. Refer to table 6-18 for the aborted MEMGO-timing specifications.

6.4.2 MEMORY HANDSHAKE TIMING

Memory handshake timing is shown in figure 6-8.

6.4.3 INTERRUPT PROTOCOL

The L-series interrupt system is identical in function to that of its predecessor 2100-series computers, with a multi-level vectored system. In the L-Series, interrupt priority is determined by physical proximity to the processor on the interrupt priority chain only, similar to the 2100-series convention. There is a difference, however; in the 2100-series, the physical slot location determines a device's select code (and hence its interrupt vector address), whereas in the L-Series the select code is independent of a card's physical location. The select code is determined by setting six switches, one per select code bit, on each I/O interface.



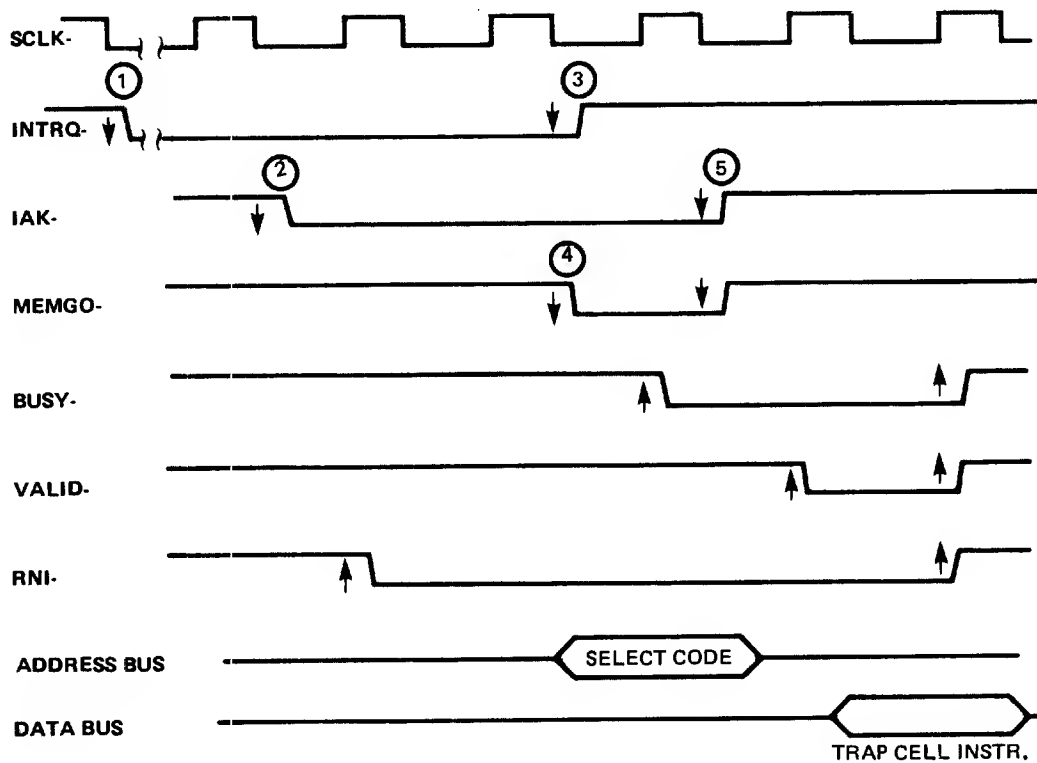
1. An interface card asserts MRQ- to request a memory cycle. (MCHOD- and MCHODOC- are asserted simultaneously to hold off all lower priority cards).
2. An interface card asserts MEMGO-, if one cycle after the assertion of MRQ-, it still has priority; i.e., its MCHID- is high. If MRQ- is not asserted, the MEMGO- is from the processor card, or an interface card during an interrupt cycle.
3. An interface card releases MRQ- at the end of the short half cycle when MEMGO- is released.
4. The memory asserts BUSY-, once MEMGO- has been asserted, in order to hold off other memory cycles until this cycle can be completed.
5. MEMGO- is released one cycle after being asserted.
6. The memory asserts VALID- during the last cycle of BUSY-.
7. The release of VALID- signals that data is valid on backplane.
8. The release of BUSY- signals that a new memory cycle can begin.
9. The address bus is driven by the interface card during the assertion of MEMGO-.
10. In the case of a memory write cycle, the interface data is valid on the backplane shortly after the address bus.
11. In the case of a memory read cycle, the memory guarantees valid data on the rising edge of VALID-.

Figure 6-8. Memory Handshake Timing

An interrupt request occurs when a card's CONTROL flip-flop is set and the FLAG flip-flop gets set by either the interface itself or the execution of an STF instruction. This will cause the interface to assert the interrupt-requesting signal INTRQ- on the backplane. INTRQ- is a common signal (open collector, wired-OR) used by all interfaces to notify the processor that any one of the interfaces would like an interrupt. An interrupt acknowledgement, IAK-, from the processor card, is triggered by an interrupt request from any of the I/O interfaces. When the CPU chip reaches the state where it is ready to fetch the next instruction, and if the interrupt system is enabled and interrupts are not temporarily being held off, then the processor will assert IAK-.

Because interrupt servicing is accomplished with the help of a memory cycle, the handshake in figure 6-9 is similar to that in figure 6-8. Since it is transparent to the memory whether or not an interrupt is being serviced, BUSY- and VALID- have exactly the same function in the two timing diagrams. MEMGO- has the same function as in a normal memory cycle except that during its assertion, the address bus is driven with the interface card's select code. The data which is read from this location in memory is used as the next instruction executed by the processor. This instruction will normally be a jump (JSB, I) to the location of some interrupt service routine. When an interface card asserts INTRQ-, it also pulls on ICHOD-. ICHOD- will disable all lower-priority cards from requesting interrupt service. If a high-priority card preempts the request, ICHID- will go low, disabling the requesting card. The lower-priority card should maintain its request until its ICHID- goes back up and the card can be serviced.

If any contention exists between an IAK- assertion and an MRQ- assertion, the DMA request will win. Both IAK- and MRQ- assertions may occur simultaneously on the falling edge of SCLK-, but IAK- will be deasserted prior to the next rising edge of SCLK-. The assertion of IAK will be permitted at the completion of all current DMA requests. Refer to table 6-11 for the aborted IAK- timing specifications.



1. An interface card pulls on INTRQ- to request interrupt service.
2. When the processor has reached the appropriate state and if the interrupt system is enabled, and interrupts are not temporarily being held off, then it will acknowledge the interrupt request by asserting IAK-.
3. As soon as the interface card asserts MEMGO, it knows its interrupt will be serviced so it releases INTRQ-.
4. The interface card asserts MEMGO- to initiate a memory cycle, and during the one cycle of SCLK it holds MEMGO- low, it drives the lower 6 bits of the address bus with its select code, and the upper 9 bits with zeros.
5. The processor releases IAK- upon the assertion of BUSY-.

Figure 6-9. Interrupt Timing

6.4.4 INTERRUPT LATENCY

For this discussion, interrupt latency is defined as the time from the user's interrupt request to the assertion of IAK by the processor. In the best case, the interrupt can be serviced as soon as it is received, which with a 227 SCLK is 880 nsec. Generally, the interrupt cannot be serviced until a DMA cycle completes or until an instruction has finished executing. In addition, interrupts are temporarily held off for one instruction time after a JMP,I, JSB,I, or I/O instruction is executed. Therefore, worst case interrupt latency is highly dependent on the software which is running at the time of the interrupt. Assuming no more than three channels of DMA self-configure at once, and no more than three adjacent instructions that hold off interrupts are executed back-to-back, the maximum interrupt latency is 830 usec.

MINIMUM	TYPICAL	MAXIMUM
-----	-----	-----
0.88 usec	1.6 usec	830 usec

6.4.5 REMOTE MEMORY ACCESS

All I/O interface cards have the capability of accessing a remote memory (i.e., a memory other than that plugged into the backplane directly above the processor card). In order to access the remote memory, an interface card must assert REMEM- with MEMGO-. The assertion of REMEM- will signal the local memory to ignore MEMGO-. Instead, a cycle with the remote memory will be initiated. This function is reserved for use by future processors. It is not currently used in the L-Series.

6.4.6 EXPANDED MEMORY ACCESS

To facilitate DMA access to expanded memory, each L-Series I/O card has been designed with a 5-bit Address Extension Bus (SCO-4) that is driven onto the backplane simultaneously with the address bus during a memory access.

6.4.7 I/O TRANSFER PROTOCOL

The L-Series I/O structure is such that I/O instructions are not executed by the CPU; instead, they are decoded by the interface card to which they apply, then executed by that interface card in conjunction with the CPU. The instruction decoding and executing capability of the interface card is provided by a Silicon-On-Sapphire (SOS) chip, the IOP chip, located on each interface card. The I/O handshake uses the two signals IORQ-, I/O request by an interface card, and IOGO-, go ahead signal from the processor card.

The processor card's IOGO- may be preempted by concurrent DMA activity. Both IOGO- and MRQ- are asserted on the falling edge of SCLK-; thus the processor may come into contention with an I/O interface card if both signals occur simultaneously. The DMA activity has higher priority than the processor so that IOGO- must be deasserted prior to the next rising edge of SCLK-. When all concurrent DMA has completed, then IOGO- may be asserted on the backplane to complete the I/O handshake. Figure 6-10 illustrates a normal I/O handshake. For more information on a preempted I/O handshake and aborted IOGO-, refer to the timing specifications in table 6-14.

6.4.8 I/O INSTRUCTION EXECUTION

The I/O instructions may be broken down into three groups in terms of their execution requirements, as follows:

A. Data Transfer I/O instructions - OTA/B, LIA/B, MIA/B

This group requires a double handshake as shown in figure 6-10. In the first half of the handshake, a control word is transferred from the interface card to the processor card. In the second half of the handshake, the data is transferred either into or out of the A or B register, according to which of the six instructions above is being executed. I/O transfers over the backplane have lower priority than DMA transfers, and can be preempted. DMA transfers can occur while an I/O instruction is in the process of being executed, i.e., between the two halves of the handshake.

B. Status Sensing Instructions - SFS, SFC

This group requires, at most, a single handshake during which a control word from the interface card to the processor (signaling the program counter) is transferred. If no skip is required, no handshake occurs.

C. Status Altering Instructions - STC, CLC, STF, CLF

This group requires no interaction with the CPU. The interface card executes these instructions itself, and never needs to assert IORQ-.

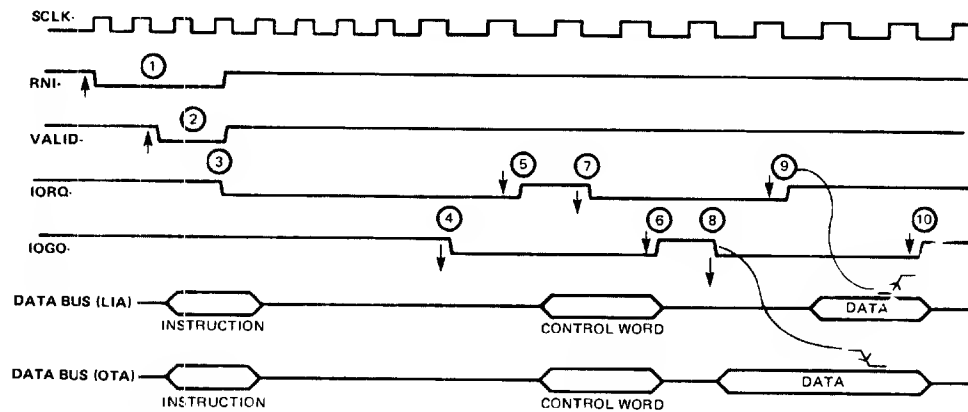
6.4.9 SLAVE MODE TRANSFERS

An interface card may force the processor card to enter an I/O handshake by pulling down the open-collector line SLAVE-. Once in slave mode, the interface has the capability of accessing the internal CPU registers, and does so with the use of the same handshake signals as in the I/O transfer protocol as illustrated in figure 6-11. Once the slave mode has been entered, an interface card may keep the processor in that mode as long as desired by setting a bit in the control word (transferred during the first half of the handshake) which signals that another double handshake will occur. Note that the slave chain (SCHID-, SCHOD-) operates differently from the other chains in that its quiescent state is low or disabled. It is enabled only for one cycle at a time, during which the highest priority interface card pulling on SLAVE- must assert IORQ-, thereby entering slave mode. See figure 6-11 for slave mode operation.

The control words which are sent to the CPU by an interface card during an I/O instruction (requiring a handshake), and during all slave mode processing are made up of five bits using bits 8 through 4 of the data bus. These control words are defined below:

	Data Bus Bit				
	8*	7	6	5	4
NOP	X	0	0	0	0
Load Program Counter	X	0	0	0	1
Load A	X	0	0	1	0
Load B	X	0	0	1	1
Clear O	X	0	1	0	0
Set O	X	0	1	0	1
OR into A/B	X	0	1	1	0
Increment Program Counter	X	0	1	1	1
Read E and O	X	1	0	0	0
Enable ROMs	X	1	0	0	1
Read A	X	1	0	1	0
Read B	X	1	0	1	1
Clear E	X	1	1	0	0
Set E	X	1	1	0	1
Read P	X	1	1	1	0
Read and Increment P	X	1	1	1	1

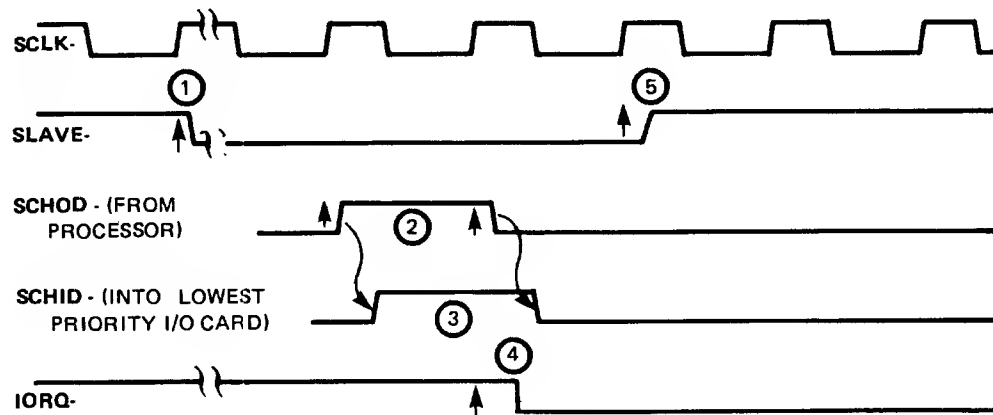
* Loop for next control word if X=1; last handshake if X=0.



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1. Processor asserts RNI- to inform all system cards that an instruction is being fetched from memory.
2. Memory asserts VALID- to inform all system cards that data on the backplane will soon be valid. Each interface should now latch the instruction off the data bus, and decode it to see if it is an I/O instruction to its select code.
3. An interface card pulls on IORQ- to signal that it recognized the I/O instruction and needs the CPU in order to execute it.
4. The processor asserts IOGO- to indicate that it is ready to receive a command from the interface card.
5. The interface card releases IORQ- to signal the processor that the control word will be available on the data bus on the second rising edge of SCLK-.
6. The processor releases IOGO- when it has clocked the command off the backplane.
7. The interface card reasserts IORQ- one cycle after it was released if another handshake is needed in order to transfer a data word.
8. The processor reasserts IOGO- in order to indicate that it is ready to receive an operand in the case of an input operation, or that data will be valid on next falling edge in the case of an output operation.
9. The interface card releases IORQ- to indicate that it has latched an operand off the backplane in the case of an output operation, or that an operand will be valid on the backplane on second rising edge in the case of an input operation.
10. The processor releases IOGO- to indicate that it has clocked data off the backplane in the case of an input operation, or that the handshake is complete in the case of an output operation.

Figure 6-10. I/O Handshake



1. An interface card asserts SLAVE- to request the processor to enter slave mode.
2. When the processor has completed executing the current instruction, it acknowledges the assertion of SLAVE- by de-asserting SCHOD- for one cycle.
3. Worse case, the SCHID/SCHOD priority chain has propagated down to the lowest-priority interface card by the end of that cycle, so that the last SCHID- will go high for one cycle.
4. The interface card received the enabling signal when its SCHID- signal went high, and can now pull on IORQ- in order to initiate the I/O handshake. The rest of the I/O handshake can then proceed exactly as shown in figure 6-10.
5. The interface card de-asserts SLAVE- once it has asserted IORQ-.

Figure 6-11. Slave Mode Timing

6.5 SIGNAL TIMING SPECIFICATIONS

The L-Series cards can be categorized into four types for backplane timing: memory, processor, analysis interface, and I/O Master. Each of these four types of cards has its timing requirements for the signals it receives and its timing guarantees for the signals it generates. In order to insure the basic integrity of all backplane interactions, it is necessary only to ascertain that all requirements are satisfied by the guarantees. All timing guarantees take into account the signal propagation delay due to line length and loading.

In tables 6-4 through 6-36, timing specifications are given in terms of both requirements and guarantees. All backplane signals are listed in alphabetical order.

Please make note of the following abbreviations which are used. All times are given in nanoseconds unless otherwise indicated.

DEFINITION OF TERMS USED IN TIMING SPECIFICATIONS

AI	- Analysis Interface 10285A Interface between the L-Series computer and a logic analyzer.
BB	- Battery Backup The L-series Battery Back-Up Card (part number 12013-60001).
C	- Cycle One cycle of Slow Clock (SCLK).
f	- Frequency The number of cycles per unit time of a given signal.
I/O	- I/O Master The L-series I/O Master consists of an SOS IOP chip and some TTL logic which together performs all the backplane I/O interfacing functions in the L-Series computer.
LHC	- Long Half Cycle The Long Half Cycle refers to the time period when SCLK- is low.
M	- Memory The L-series 64Kbyte dynamic RAM card (12004A).
P	- Processor The 12001A processor card with SOS central processor unit (CPU) chip.

DEFINITION OF TERMS USED IN TIMING SPECIFICATIONS

PS - Power Supply (HP 12035A)

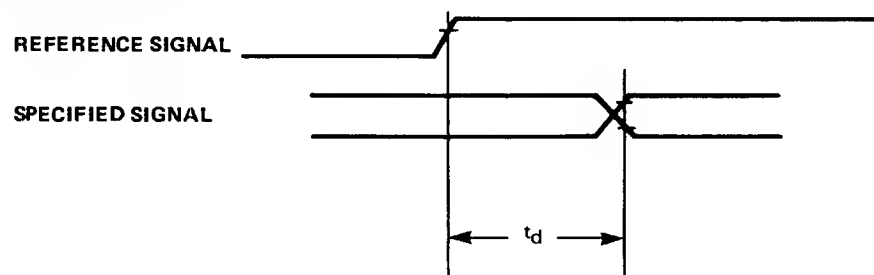
SHC - Short Half Cycle

The Short Half Cycle refers to the time period when SCLK- is high.

t

D - Delay time

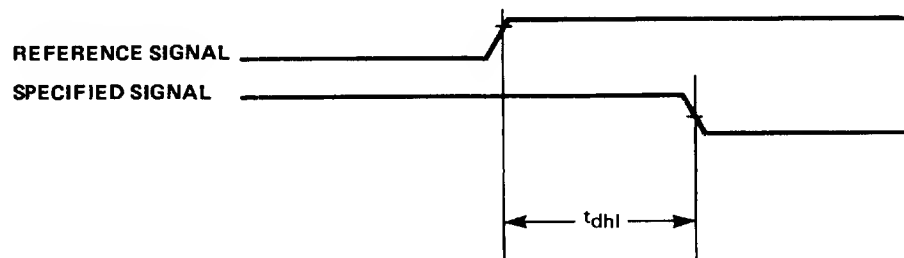
The time interval from a signal edge used as a reference point to the point in time when the specified signal is guaranteed to be stable on the backplane.



t

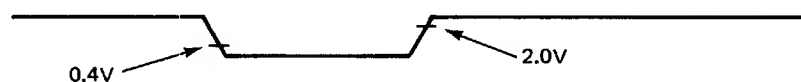
DHL- Delay time high to low

The time interval from a signal edge used as a reference point, to the point in time when the specified signal is guaranteed to be low if in fact it is going low.



NOTE

In these timing diagrams, a high notch is 2.0 volts and a low notch is 0.4 volts as shown below.

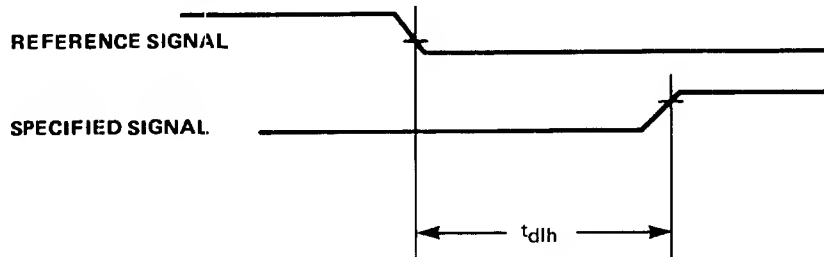


DEFINITION OF TERMS USED IN TIMING SPECIFICATIONS (CONTINUED)

t

DLH- Delay time low to high

The time interval from a signal edge used as a reference time to the point in time when the specified signal is guaranteed to be high if in fact it is going high.



t

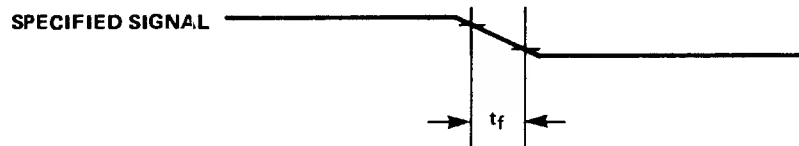
DZ Delay time to high impedance

The time interval from a signal edge used as reference to the point in time when the specified signal will no longer be actively driven.

t

F - Fall time

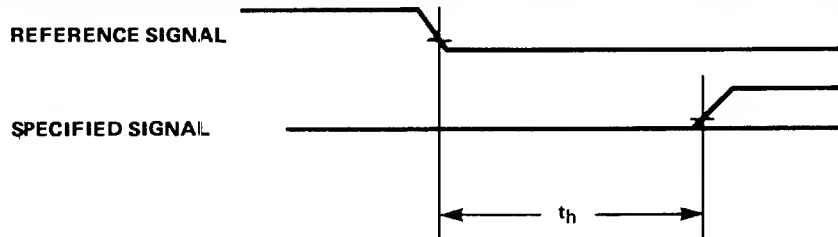
The time interval during which a signal is in transition from high to low.



t

H - Hold time

The period of time during which a specified signal must remain stable at its logic level after a certain reference edge.



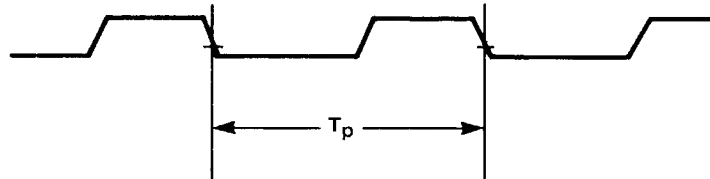
DEFINITION OF TERMS USED IN TIMING SPECIFICATIONS (CONTINUED)

T

p - Period

The duration of one cycle of a periodic signal.

SPECIFIED SIGNAL

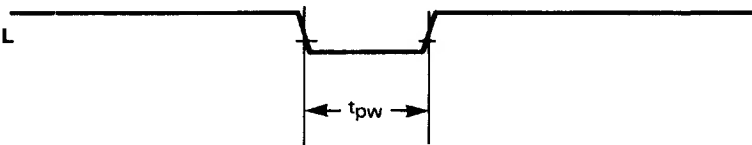


t - Pulse width time

pw

The time interval between the leading and trailing edge of a pulse. Specifically, for a normally high signal, t_{pw} is the time when that signal is low. For a normally low signal, t_{pw} is the time when that signal is high.

SPECIFIED SIGNAL

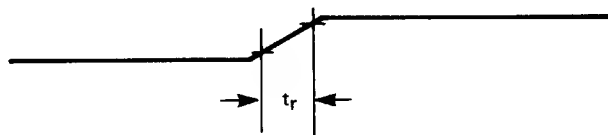


t - Rise time

r

The time interval during which a signal is in transition from low to high.

SPECIFIED SIGNAL



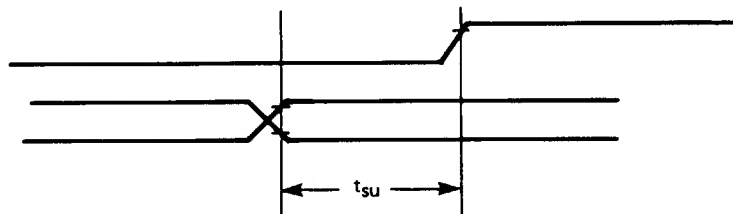
t

su - Set-up time

The time interval a specified signal must be at a stable logic level before a given edge of a reference signal.

REFERENCE SIGNAL

SPECIFIED SIGNAL

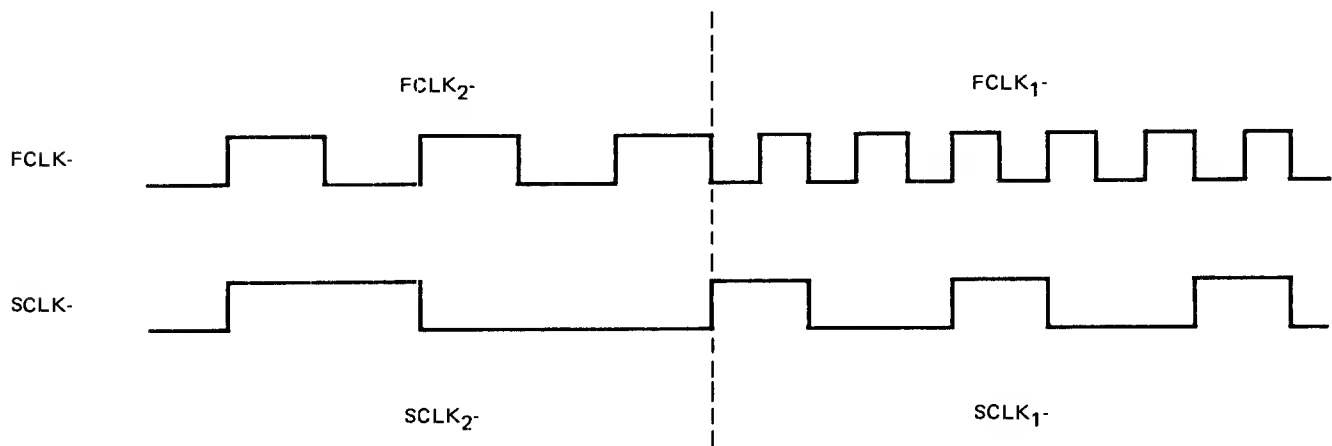


DEFINITION OF TERMS USED IN TIMING SPECIFICATIONS (CONTINUED)

XLM - Expanded Memory
Any memory subsystem of 128 to 512 Kbytes.

6.5.1 DUAL-SPEED CLOCK REFERENCES

FCLK- and SCLK- are dual-speed clocks. Although their nominal frequencies are 22.016 MHz and 4.4032 MHz, respectively, they slow down to half this speed during the assertion of IOGO- on the backplane. All timing references to these clocks, when not specified, are valid for either of the frequencies. When it is necessary to distinguish between the frequencies, the subscript 1 is used for the faster and 2 for the slower frequency.



6.5.2 INTERACTIVE TIMING EXAMPLES

Previous timing examples have shown handshakes or protocols by type of interaction. In actuality, however, transactions may start only to be preempted by other higher priority transactions and held off for an indefinite period of time. Figures 6-12 and 6-13 show various transactions over the backplane which begin, are preempted, and then later are allowed to complete.

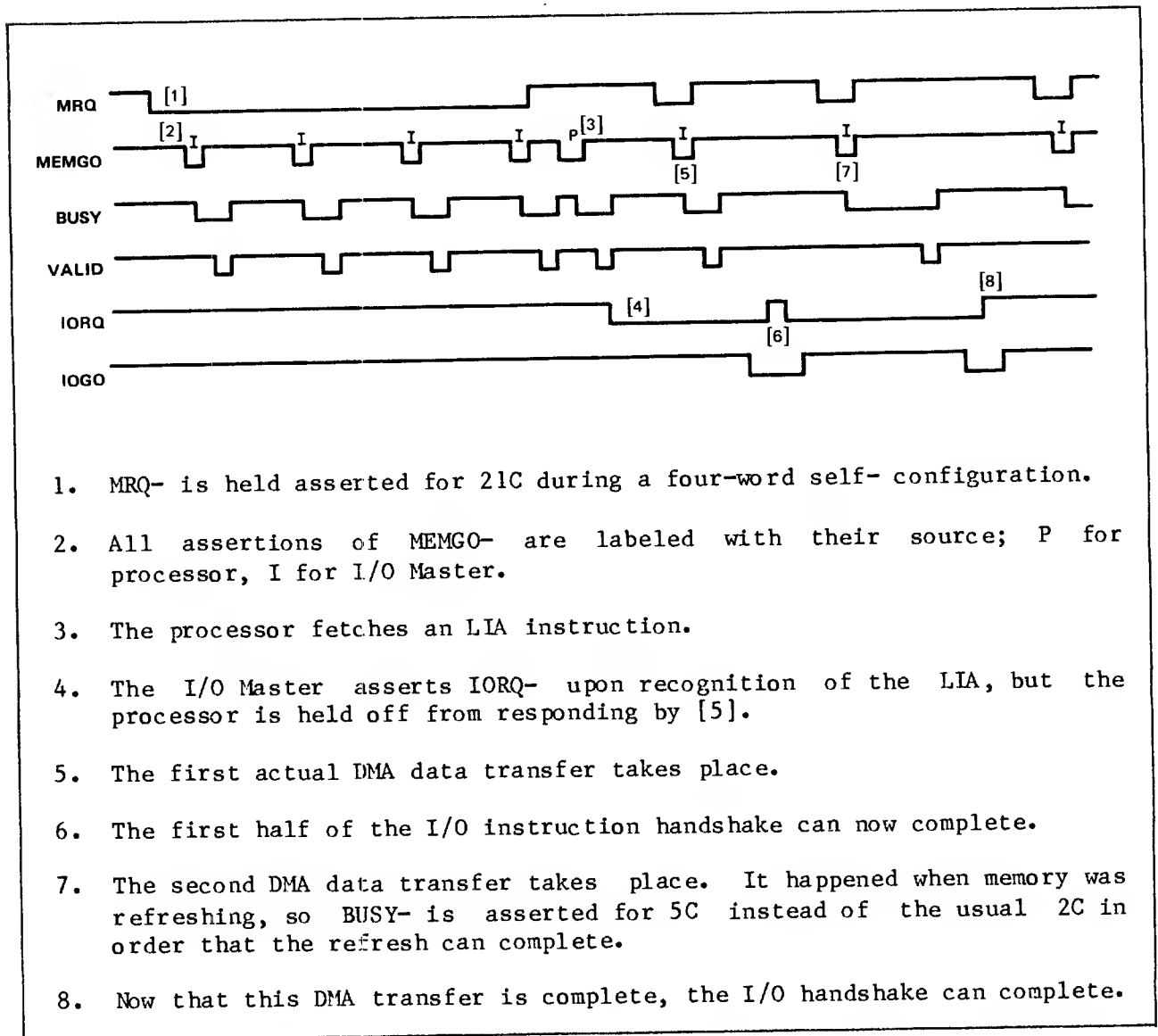
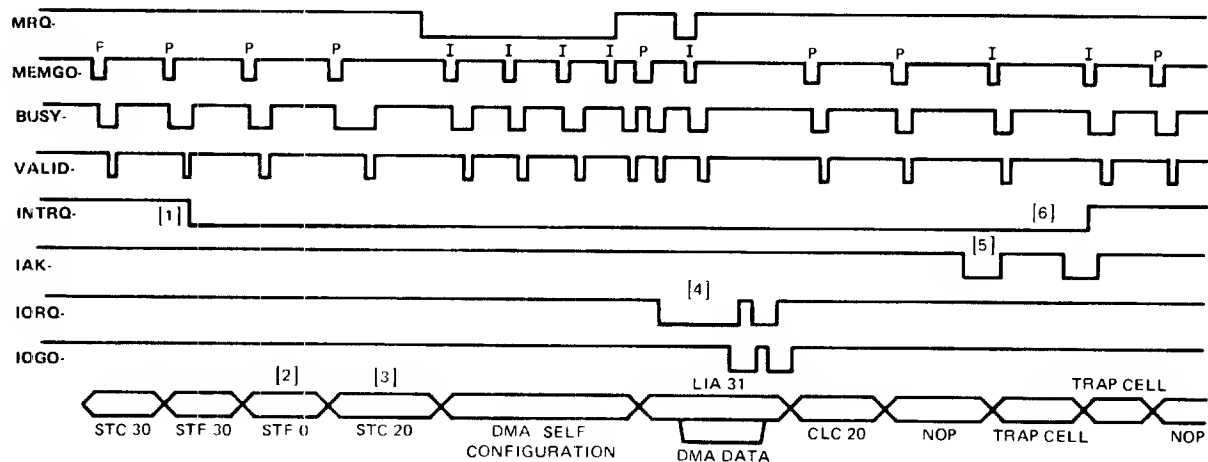


Figure 6-12. Interactive DMA and I/O Instruction Timing



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1. The Flag and Control flip-flops are set, so the I/O Master attempts to interrupt.
2. Interrupt system is turned on with an STF 0 but processor must not respond until after the next instruction if current is an I/O instruction.
3. Self-configuring DMA is started, set up for a one-word transfer.
4. An LIA is executed, interleaved with DMA as in figure 6-12.
5. After the NOP instruction is fetched, the processor can respond to the interrupt caused by Flag 30.
6. The I/O Master does not release INTRQ, because it now also has a DMA completion interrupt pending.

Figure 6-13. Interactive DMA, I/O Instruction, and Interrupt Timing

Table 6-4. Timing Specifications for ABO - 14

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t _{su}	SCLK-↑	Edges that occur during MEMGO		M	0		
t _{su}	SCLK-↑	During Processor MEMGO		XLM	25		
t _{su}	SCLK-↑	During DMA MEMGO		XLM	-20		
t _h	SCLK-↑	Edge that occurs during MEMGO-		M,XLM	67		
t _D	SCLK-↓	Edge that causes MEMGO-↓	I/O				100
t _h	SCLK-↓	Edge that causes MEMGO-↑	I/O		20		
t _{su}	SCLK-↑	Edge that occurs during MEMGO-↓	P		220		
t _h	SCLK-↓	Edge that causes MEMGO-↑	P		20		
t _D	SCLK-↓	1st after BUSY-↑ following MRQ-↑	P				70
t _{DZ}	MRQ-↓	CPU can be held off by MRQ- from any interface	P		10		45
t _{DZ}	SCLK-↓	Due to MRQ-↓	P				95
t _H	SCLK-↑	Edge that causes IAK-↓	P				185
t _{su}	SCLK-↑	Edge that occurs during MEMGO- in interrupt cycle.		P	0		
t _H	SCLK-↑	Same edge		P	100		

Table 6-4. Timing Specifications for AB0 - 14 (Continued)

t _{su}	SCLK-↑	Edge that occurs during MEMGO		AI	-45		
t _h	SCLK-↑	Edge that occurs during MEMGO		AI	106		
t _{su}	SCLK-↑	Edge that occurs during MEMGO in interrupt cycle		AI	-45		
t	SCLK-↓	Edge that causes MEMGO-↑ during interrupt cycle		AI	25		

Table 6-5. Timing Specifications for BUSY-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{DHL}	SCLK-↑	Edge that occurs during MEMGO-	M,XLM		0		44
t_{DLH}	SCLK-↑	2C later if memory was not doing refresh	M,XLM		0		44
t_{DLH}	SCLK-↑	3C-5C later if memory was doing refresh when MEMGO- occurred	M,XLM		0		44
t_{SU}	SCLK-↓	In order to hold off MEMGO-		I/O	5		
t_h	SCLK-↓			I/O	5		
t_{DHL}	SCLK-↑	During MEMGO- for boot ROM access	P				65
t_{DLH}	SCLK-↑	3C later	P				40
t_{su}	SCLK-↓	Any falling edge		P	5		
t_H	SCLK-↓	Same edge		P	10		
t_{pw}		Longer than 2C when doing refresh.	M		2C-50 nsec	2C	5C
t_{pw}		Longer than 2C when doing refresh.	XLM		2C-50 nsec	2C	4C
t_{su}	SCLK-↓	Any falling edge		AI	1		
t_H	SCLK-↓	Same edge		AI	7		

Table 6-6. Timing Specifications for CCLK-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
f	asynchronous	To all other backplane signals	P		14.7441 MHz	14.7456 MHz	14.7471 MHz
Duty cycle			P		30%	50%	

Table 6-7. Timing Specifications for CPUTURN-/COTURN-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
CPUTURN- t DHL	SCLK-↓	That causes MEMGO-↓	P				210
t DHL	SCLK-↓		P				120
CPUTURN- t SU	SCLK-↓	To inhibit MRQ-		I/O	25		
t H	SCLK-↓	Same edge		I/O	-5		
COTURN- t SU	SCLK-↑	Edge that occurs during MEMGO		XLM	90		
t H	SCLK-↑	Edge that occurs during MEMGO		XLM	67		

Table 6-3. Timing Specifications for CRS-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{pw}	asynchronous			M	20		
t_{pw}				XLM	1C		
t_{pw}	SCLK-↓			I/O	1C		
t_{SU}				I/O	-30		
t_{DHL}	SCLK-↓	No concurrent DMA	P				35
t_{DHL}	SCLK-↓	End of DMA	P				117
t_{DLH}	Next SCLK-↓		P				50

Table 6-9. Timing Specifications for DB0 - 15

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_D	SCLK- \uparrow	During MEMGO-		M			23
t_D	SCLK- \uparrow	During MEMGO		XLM			4
t_h	SCLK- \uparrow	Same edge		M,XLM	90		227
t_{SU}	SCLK- \uparrow	That causes VALID- \uparrow	M		126		
t_{SU}	SCLK- \uparrow	That causes VALID- \uparrow	XLM		20		
t_H	SCLK- \uparrow	That causes VALID- \uparrow	M,XLM		91		
t_{SU}	VALID- \uparrow	All cases	M,XLM		50		
t_h	VALID- \uparrow	Same edge	M,XLM		50		
t_D	SCLK- \downarrow	Edge that causes MEMGO- \downarrow (DMA)	I/O				140
t_H	SCLK- \downarrow	Edge that causes MEMGO- \uparrow (DMA)	I/O		35		
t_D	SCLK- \downarrow	First SCLK- \downarrow after IOGO- \downarrow * (I/O instruction)	I/O				315
t_H	SCLK- \uparrow	Third SCLK- \uparrow during IOGO- (I/O instruction)	I/O		65		
t_{su}	VALID- \uparrow	DMA read		I/O	50		
t_H	VALID- \uparrow	DMA read		I/O	50		180
t_{su}	SCLK- \downarrow	Second SCLK- \downarrow * during IOGO- (I/O instr)		I/O	10		
*Provided IOGO- \downarrow met 10-nsec set-up time to previous SCLK- \uparrow .							

Table 6-9. Timing Specifications for DB0 - 15 (Continued)

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_H	SCLK- \uparrow	Third SCLK- \uparrow * during IOGO- (I/O instr)		I/O	40		227
t_{SU}	SCLK- \uparrow	Edge that causes VALID- \uparrow (memory read)		P	20		
t_H	SCLK- \uparrow	Same edge (memory read)		P	15		
t_{su}	SCLK- \uparrow	Second SCLK- \uparrow after SCLK- \downarrow which causes IORQ- \uparrow (I/O instr)		P	20		
t_H	SCLK- \uparrow	Same edge (I/O instr)		P	15		227
t_{D1}	SCLK- \uparrow 1	Edge that causes MEMGO- \downarrow (memory write)	P				120
t_H	SCLK- \downarrow	Edge that causes MEMGO- \uparrow (memory write)	P		25		
t_D	SCLK- \uparrow	Edge that precedes SCLK- \downarrow which causes IOGO- \downarrow (I/O write)	P		30		110
t_H	SCLK- \uparrow	Edge that precedes SCLK- \downarrow which causes IOGO- \uparrow (I/O write)	P		15		
t_D	SCLK- \downarrow	During VALID- (boot ROM fetch)	P				50
t_{D2}	SCLK- \downarrow 2	Following an I/O handshake	P				210
*Provided IOGO- \downarrow met 10-nsec set-up time to previous SCLK- \uparrow .							

Table 6-9. Timing Specifications for DB0 - 15 (Continued)

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_h	SCLK-↓	Edge that follows VALID-↑ (boot ROM fetch)	P		20		
t_D	SCLK-↓	First after BUSY-↑ following MRQ-↑	P				120
t_{DZ}	MRQ-↓	Assertion of MRQ- will cause CPU to stop driving DB	P		20		65
t_{DZ}	SCLK-↓	Due to MRQ-↓	P				145
t_D	SCLK-↓	During VALID- (A/B instr fetch)	P				110
t_H	SCLK-↓	First after VALID-↑ (A/B instr fetch)	P		20		
t_D	SCLK-↑	That occurs during MEMGO		AI			40
t_H	SCLK-↑	Same edge		AI	90		
t_{su}	SCLK-↑	That causes VALID-↑		AI	0		
t_H	SCLK-↑	Same edge		AI	15		
t_{su}	SCLK-↑	Second after SCLK-↓ which causes IORQ-↑ during I/O instr		AI	0		
t_H	SCLK-↑	Same edge			15		

Table 6-10. Timing Specifications for FCLK-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
T _P				M	36		
T _P				XLM	45		
f				M			27.7778 MHz
f				XLM			22.0171 MHz
f ₁	While IOGO- is high		P		22.0149 MHz	22.016 MHz	22.0171 MHz
duty cycle ₁	While IOGO- is high		P		29%	50%	71%
f ₂	While IOGO- is low		P		11.0074 MHz	11.008 MHz	11.0086 MHz
duty cycle ₂	While IOGO- is low		P		41%	50%	59%
T _P				AI	45		
f				AI			22.0171 MHz

Table 6-11. Timing Specifications for IAK-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	SCLK- \uparrow			I/O	10		
t_H	SCLK- \uparrow	Same edge		I/O	25		
t_{PW}				I/O	2C		3C
t_{SU}	SCLK- \downarrow	To inhibit MRQ		I/O	25		
t_H	SCLK- \downarrow	Same edge		I/O	0		
t_{D1}	SCLK- \downarrow 1		P				55
t_{D2}	SCLK- \uparrow 2	Following an I/O handshake	P				145
t_H	SCLK- \downarrow	First after BUSY- \downarrow	P		15		
t_D	SCLK- \downarrow	First after BUSY- \uparrow following MRQ- \uparrow	P				60
t_{DLH}	MRQ- \downarrow		P		10		55
t_{DLH}	SCLK- \downarrow	Due to MRQ- \downarrow	P				90
t_{SU}	SCLK- \uparrow			AI	3		
t_H	SCLK- \uparrow	Same edge		AI	20		
t_{PW}				AI	2C		
t_{pw}				XLM	1C		

Table 6-12. Timing Specifications for ICHID-/ICHOD-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
ICHID- t SU	SCLK-↓	Second SCLK-↓* during IAK-		I/O	10		
ICHID- t H	SCLK-↓	Third SCLK-↓* during IAK-		I/O	50		
t D	Asynch- ronous	ICHID-↓ to ICHOD-↓	I/O			5	7.5
ICHOD- t DHL	SCLK-↑	Edge that causes INTRQ-↓	I/O				200
ICHOD- t H	IAK-↑	ICHOD- is held low during the entire assertion of IAK-	I/O		SHC		
ICHOD- t DHL	IAK-↓		P				50
ICHOD- t H	IAK-↑		P		0		

Table 6-13. Timing Specifications for INTRQ-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t DHL	SCLK-↓		I/O				200
t DLH	SCLK-↓	Third SCLK- after IAK-↓*	I/O				300
t su	SCLK-↓			P	15		
t H	IAK-↓			P	0		

*Provided IAK- met 10-nsec set-up time to previous SCLK-↑.

Table 6-14. Timing Specifications for IOGO-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	SCLK- \uparrow	During IORQ-		I/O	10		
t_h	SCLK- \uparrow	Same edge		I/O	25		
t_{pw}		3 \uparrow of SCLK-		I/O	2C + LHC		
t_{SU}	SCLK- \downarrow	To inhibit MRQ		I/O	25		
t_H	SCLK- \downarrow	Same edge		I/O	0		
t_{DHL}	SCLK- \downarrow		P				50
t_{DLH}	SCLK- \uparrow	Second SCLK- \uparrow after SCLK- \downarrow that caused IORQ- \uparrow	P				40
t_{DLH}	SCLK- \uparrow	Second SCLK- \uparrow after SCLK- \downarrow that caused IORQ- \uparrow		AI			100
t_{DLH}	SCLK- \downarrow	SHC later		AI	5		
t_{DHL}	SCLK- \downarrow	Second after BUSY- \uparrow following MRQ- \uparrow	P				50
t_{DLH}	MRQ- \downarrow		P				50
t_{DLH}	SCLK- \downarrow	Due to MRQ- \downarrow	P				85
t_{su}	SCLK- \uparrow			AI	10		
t_H	SCLK- \uparrow			AI	25		

Table 6-15. Timing Specifications for IORQ-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t DHL1	Data bus valid during VALID-*	1 refers to first handshake request after RNI-↓	I/O				325
t DHL2	SCLK-↓	2 refers to second SCLK-↓ after** IOGO-↓ (double handshake only)	I/O				145
t DHL3	SCLK-↑	SCLK-↑ following SCHID-↑ (3 refers to initial IORQ-↓ on slave cycle)	I/O				45
t DLH	SCLK-↓	First SCLK-↓ after IOGO-↓**	I/O				210
t SU	SCLK-↓	5C+SHC after SCLK-↑ which causes RNI-↑ or VALID-↑		P	50		
t h	SCLK-↓	Same edge		P	10		
t SU	SCLK-↓	1C after edge which caused second assertion of IORQ-		P	50		
t h	SCLK-↓	Same edge		P	10		
t SU	SCLK-↓	Following any release of IORQ		P	50		
t h	SCLK-↓	Same edge		P	10		
<p>* During VALID-, there could be false assertions of IORQ- due to the data bus being in transition. This will not affect system operation, however, because the processor does not check IORQ- until two states after RNI-↑ when IORQ- is guaranteed to be valid.</p> <p>** Provided IOGO-↓ met 10-nsec set-up time to previous SCLK-↑.</p>							

Table 6-15. Timing Specifications for IORQ- (Continued)

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t _{SU}	SCLK-↓	First SCLK-↓ after SCHOD-↓		P	50		
t _h	SCLK-↓	Same edge		P	10		

Table 6-16. Timing Specifications for MCHID-/MCHOD-, MCHODOC-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
MCHID- t _{SU}	SCLK-↓			I/O	5		
MCHID- t _h	SCLK-↓	Same edge		I/O	20		
t _{DHL}		MCHID-↓ to MCHOD-↓	I/O			5	7
MCHOD- t _{DHL}	SCLK-↓	Edge that causes MRQ-↓	I/O				30
MCHODOC- t _{DHL}	SCLK-↓	Edge that causes MRQ-↓	I/O				55
MCHODOC- t _{DLH}	SCLK-↓	Edge that causes MRQ-↑	I/O				165

Table 6-17. Timing Specifications for MEMDIS-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	SCLK-↑	Edge that occurs during MEMGO-		M,XLM	30		
t_h	SCLK-↑	Same edge		M,XLM	0		
t_{DHL}	SCLK-↓	Edge that causes MEMGO-↓	P				30
t_{DHL2}	SCLK-↑ 2	Following an I/O handshake	P				120
t_{DLH}	SCLK-↓	First SCLK-↓ after BUSY-↓	P				30
t_{DHL}	SCLK-↓	First after BUSY-↓ following MRQ-↑	P				30
t_{DLH}	MRQ-↓		P				25
t_{DLH}	SCLK-↓	Due to MRQ-	P				70

Table 6-18. Timing Specifications for MEMGO-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	SCLK-↑			M,XLM	10		
t_h	SCLK-↑	Same edge		M	SHC		215
t_h	SCLK-↑	Same edge		XLM	0		
t_{DHL}	SCLK-↓		I/O				45
t_{DLH}	SCLK-↓	Next edge	I/O		30		110
t_{DHL}	SCLK-↓		P				40
t_{DHL}	SCLK-↑ 2	Following an I/O handshake	P				130
t_{DLH}	SCLK-↓	First SCLK-↓ after BUSY-↓	P				100
t_{DHL}	SCLK-↓	First after BUSY-↑ following MRQ-↑	P				45
t_{DLH}	MRQ-↓		P				95
t_{DLH}	SCLK-↓	MEMGO- aborted by MRQ- from edge which caused MEMGO	P				125
t_{su}	SCLK-↑		AI		4		
t_h	SCLK-↑	Same edge	AI		15		

Table 6-19. Timing Specifications for MLOST-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{rf}			BB				50
t_{su}	PON \uparrow		BB		500 usec		
t_h	PON \uparrow		BB		10 msec		1 sec
t_h	PON \uparrow		SW*		5 msec		
* Processor does not latch MLOST-. During the pretest, the state of this line is used by the software to determine whether or not to initialize memory.							

Table 6-20. Timing Specifications for MP+

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	VALID \uparrow			I/O	0		
t_H	SCLK \uparrow	Second SCLK \uparrow after VALID \uparrow (non-I/O instr). Second SCLK \uparrow after last IOGO \uparrow (I/O instr)		I/O	0		
t_D	SCLK \uparrow	1C+SHC before SCLK \downarrow that causes MEMGO \downarrow	P				205

Table 6-21. Timing Specifications for MRQ-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{DHL}	SCLK-↓		I/O				50
t_{DLH}	SCLK-↓	Edge that causes MEMGO-↑	I/O		30		110
t_{SU}	SCLK-↑			P	30		
t_H	SCLK-↑	Edge that causes BUSY-↓		P	15		
t_{su}	SCLK-↑			AI	4		
t_H	SCLK-↑	Same edge		AI	16		
t_{su}	SCLK-↑	Edge that occurs during MEMGO		XLM	90		
t_H	SCLK-↑	Edge that occurs during MEMGO		XLM	67		

Table 6-22. Timing Specifications for PE-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t _{pw}	asynchronous	1C=227.1 nsec	M		86		
t _{pw}			XLM		60		
t _{DHL}	VALID-↑	Actually caused by edge of FCLK-	M		-71		3
t _{DHL}	VALID-↑		XLM		-40		30
t _{pw}		Must occur during window		I/O	50		
t _{SU}	Start window SCLK-↓	First edge after edge that causes RNI-↓ (instr fetch window)		I/O	0		
t _h	End window SCLK-↑	First edge after VALID-↑ (instr fetch window)		I/O	0		
t _{SU}	Start window SCLK-↓	First edge after edge that causes VALID-↓ (DMA window)		I/O	0		
t _h	End window SCLK-↓	Second edge after edge that causes VALID-↑ (DMA window)		I/O	0		
t _{pw}		Must occur during window		P	50		
t _{su}	Start window SCLK-↓	First edge after VALID-↓		P	0		
t _{su}	End window SCLK-↓	First edge after VALID-↑		P	0		

Table 6-23. Timing Specifications for PFW-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	PON+↓		PS		5 msec		
t_{SU}	PON+↑		PS		10 msec		
t_r, t_f			PS				50
t_{su}	PON+↑			P	50		
t_{su}	PON+↓	Software requires time for power down routine to execute		SW	5 msec		

Table 6-24. Timing Specifications for PON+

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_D		Supplies up and within regulation	PS		50 msec	65 msec	100 msec
t_r, t_f			PS				50 nsec
t_{pw}		Time required to fully initialize CPU chip		P	2C		
t_{pw}				AI	2C		

Table 6-25. Timing Specifications for PS-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
All		Same as data bus requirements for all memory writes		M,XLM			
t_{SU}	SCLK-↓	Edge that causes MEMGO-↓	P				0
t_h	SCLK-↑	First edge after VALID-↑	P		0		

Table 6-26. Timing Specifications for RCLK+

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
f			P		-0.005%	4.403 MHz	+0.005%
duty cycle			P		37%	40%	43%

Table 6-27. Timing Specifications for REMEM-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{su}	SCLK-↑	SCLK- that occurs during MEMGO-		M,XLM	30		
t_h	SCLK-↑	Same edge		M,XLM	0		
t_{DHL}	SCLK-↓		I/O				45
t_{DLH}	SCLK-↓	Next edge	I/O		30		110

Table 6-28. Timing Specifications for RNI-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t _{SU}	SCLK-↓	That occurs during VALID-		I/O	25		
t _H	SCLK-↓	Same edge		I/O	30		
t _{DHL}	SCLK-↑	First edge after MEMGO-↓ from CPU	P				45
t _{DLH}	SCLK-↑	Edge that causes VALID-↑	P				45
t _{pw}			P			2C	
t _{pw}				I/O	1C-t _{su}	1C	
t _{su}	SCLK-↓			AI	4		
t _h	SCLK-↓			AI	11		
t _{pw}				XLM	1C		

Table 6-29. Timing Specifications for SC0 - SC4

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t _D	SCLK-↓	Edge that causes MEMGO-↓	I/O				90
t _H	SCLK-↓	Edge that causes MEMGO^	I/O		20		
t _{su}	SCLK-↑	Edge that occurs during MEMGO-		XLM	35		
t _H	SCLK-↑	Edge that occurs during MEMGO-		XLM	67		

Table 6-30. Timing Specifications for SC5

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{DHL}	SCLK-↓	Edge that causes MEMGO-↓	I/O				80
t_H	SCLK-↓	Edge that causes MEMGO↑	I/O		40		180
t_{su}	SCLK-↑	Edge that occurs during MEMGO-		XLM	56		
t_H	SCLK-↑	Edge that occurs during MEMGO-		XLM	67		

Table 6-31. Timing Specifications for SCHID-/SCHOD-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_D		SCHID-↓ to SCHOD-↓	I/O			5	7.5
SCHOD- t_{DHL}^*	SCLK-↑	Edge that caused SCHID-↑	I/O				25
SCHID- t_{SU}	SCLK-↑			I/O	0		
SCHID- t_H	SCLK-↑	Same edge		I/O	15		
t_{DLH}	SCLK-↑		P				15
t_{DHL}	SCLK-↑	Next edge	P				15

* If a low priority interface asserts SLAVE-, a higher priority interface can get the slave cycle if the higher priority interface lowers SCHOD- at any time up until 1C-169 nsec after the SCLK- which caused SCHID-.

Table 6-32. Timing Specifications for SCLK-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
f_1	While IOGO-- is high		P		-0.005%	4.403	+0.005%
Duty cycle $_1$	While IOGO-- is high		P		33%	40%	47%
t_D	FCLK-↑			M,XLM	1		21
f_2	While IOGO-- is low		P		-0.005%	2.202	+0.005%
Duty cycle $_2$	While IOGO-- is low		P		36%	40%	44%

Table 6-33. Timing Specifications for SLAVE-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{DHL}	SCLK-↑		I/O				45
t_{DLH}	SCLK-↑	First edge after SCHID-↓	I/O				130
t_{SU}	SCLK-↓			P	0		
t_h	SCLK-↑	Edge that causes SCHOD-↑		P	0		

Table 6-34. Timing Specifications for SPRQ-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_H	IAK-↓			P	0		
t_{SU}	SCLK-↓			P	15		

Table 6-35. Timing Specifications for VALID-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{DHL}	SCLK-↑	First SCLK-↑ after BUSY-↓, no refresh. Second to fourth SCLK-↑ after BUSY-↓ with refresh.	M, XLM		0		43
t_{DLH}	SCLK-↑	Second SCLK-↑ after BUSY-↓, no refresh. Third to fifth SCLK-↑ after BUSY-↓, with refresh.	M, XLM		0		43
t_{SU}	SCLK-↓			I/O	10		
t_h	SCLK-↓	Same edge		I/O	30		
t_{SU}	SCLK-↓			P	10		
t_h	SCLK-↓	Same edge		P	10		
t_{DHL}	SCLK-↑	Second SCLK-↑ after BUSY-↓ (boot ROM access)	P				55
t_{DLH}	SCLK-↑	Next edge	P				55
t_{pw}				I/O	1C- t_{su}	1C	
t_{DHL}	SCLK-↑			AI			50
t_{DLH}	SCLK-↑			AI	0		50

Table 6-36. Timing Specifications for WE-

PARAMETER	REFERENCE	NOTES	GUAR BY	REQ'D BY	MIN	TYP	MAX
t_{SU}	SCLK-↑	That occurs during MEMGO		M	0		
T_{SU}	SCLK-↑	That occurs during MEMGO		XLM	25		
t_H	SCLK-↑	Same edge		M,XLM	67		
t_D	SCLK-↓	That causes MEMGO-↓	I/O				100
t_H	SCLK-↓	That causes MEMGO-↑	I/O		20		
t_{D1}	SCLK-↓ 1	That causes MEMGO-↓	P				65
t_{D2}	SCLK-↑ 2	Following an I/O handshake	P				155
t_H	SCLK-↓	That causes MEMGO↑	P		20		
t_D	SCLK-↓	After BUSY-↑ for MRQ-↑	P				70
t_{DZ}	MRQ-↓		P		10		45
t_{DZ}	SCLK-↓	Due to MRQ-↓	P				95
t_H	SCLK-↑	That causes IAK-↓	P				185
t_{SU}	SCLK-↑	That occurs during MEMGO- during inter- rupt cycle		P	0		
t_H	SCLK-↑	Same edge		P	100		

6.6 SIGNAL DEFINITIONS

Table 6-37 lists all L-Series backplane signals. The signals are listed in alphabetical order, along with their definitions, where they originated, where they go, functions, and general timing specifications. Timing values, when given, are nominal. For specific timing values, see tables 6-4 through 6-36.

Table 6-37. Backplane Signal Definitions

(AB0+)-(AB14+)

FULL NAME: Address Bus 0-14 (Tri-state, high true)

DRIVEN BY: The processor card or the I/O Master during a DMA transfer or while receiving interrupt service. (In the case of interrupt service, the card drives AB0 - AB5 with its select code and AB6 - AB14 with zeros.)

RECEIVED BY: Memory and processor card.

FUNCTION: The address bus is used to transfer a 15-bit absolute address to the memory, of which AB0 is the least significant bit. The processor will latch the address in case a parity error or memory protect violation occurs. (Won't check for these during DMA.)

TIMING: The address bus is driven with the assertion of MEMGO- during a DMA transfer and during an interrupt cycle. In addition, the processor drives the address bus and asserts MEMGO when accessing the boot ROM.

NOTE: The default address bus driver is the processor card, which drives the address bus at all times except the following:

- 1) During the assertion of IAK-.
- 2) During the assertion of MRQ-.
- 3) From the assertion of BUSY- until the first SCLK-↓ after the release of BUSY-.

Table 6-37. Backplane Signal Definitions (Continued)

BUSY-	
FULL NAME:	Memory Busy (Tri-state, low true)
DRIVEN BY:	Processor and Memory cards
RECEIVED BY:	Processor and interface cards
FUNCTION:	BUSY- is asserted by the memory to indicate that it is unable to begin a new cycle. BUSY- is asserted by the processor when an instruction is being fetched from the boot ROM.
TIMING:	BUSY- is asserted after the rising edge of SCLK-, following the assertion of MEMGO-. BUSY- is released following the rising edge of SCLK- that precedes the next possible memory cycle by one cycle of SCLK-. BUSY- is asserted by the processor during a boot ROM access.
CCLK-	
FULL NAME:	Communications Clock (low true)
DRIVEN BY:	Processor card
RECEIVED BY:	Interface cards
FUNCTION:	This clock provides a fixed frequency which may be used to drive a state machine, or which may be divided down for baud rate generation.
TIMING:	14.7456 MHz clock with a 50-percent duty cycle.

Table 6-37. Backplane Signal Definitions (Continued)

COTURN-	
FULL NAME:	Coprocessor Turn
DRIVEN BY:	A coprocessor such as a microprocessor interfaced to an L-Series backplane.
RECEIVED BY:	Expanded (XL) Memory Controller
FUNCTION:	Asserted during MRQ to tell the memory card to use the the processor map. COTURN- may be asserted while MRQ- is high to tell the memory card to use the DMA relocation registers.
TIMING:	COTURN must be asserted one state before MEMGO- and released with MEMGO.
CPUTURN-	
FULL NAME:	Processor Turn
DRIVEN BY:	Processor Card
RECEIVED BY:	All interface cards
FUNCTION:	Asserted during RNI- and in addition, in order to signal that the processor card requests backplane priority. The assertion of CPUTURN- inhibits all interface cards from reasserting MRQ- once all current requests are satisfied.
TIMING:	When the processor wants to get out on the backplane for any one of three reasons (accessing memory, acknowledging an interrupt, or participating in an I/O handshake) but is held off by DMA, a counter counts 32 MEMGOs before asserting CPUTURN. CPUTURN stays asserted until the processor starts its transaction on the backplane.

Table 6-37. Backplane Signal Definitions (Continued)

CRS-

FULL NAME: Control Reset (low true)

DRIVEN BY: Processor Card

RECEIVED BY: All cards

FUNCTION: The assertion of CRS- completely resets the I/O system. All of the following will occur:

1. All interface control flip-flops will be cleared.
2. All interface flag flip-flops will be cleared.
3. All pending interrupts will be cleared except power fail.
4. The interrupt system will be turned off.
5. The global register will be disabled.
6. Power fail interrupts will be enabled.
7. Parity interrupts will be enabled.
8. TBC flag and control will be cleared and any pending TBG interrupt will be cleared.
9. Memory protect will be turned off and any pending memory protect interrupts will be cleared (this is only important in the boot mode, where memory protect interrupts are suppressed).
10. Parity valid LED on memory card will be turned on.

In addition, each interface card interprets CRS- to perform its own various test functions.

TIMING: CRS- is asserted for one cycle of SCLK- when a CLC 0 instruction is executed.

Table 6-37. Backplane Signal Definitions (Continued)

(DB0+)-(DB15+)	
FULL NAME:	Data Bus 0-15 (Tri-state, high true)
DRIVEN BY:	Any memory or interface card or the processor card.
RECEIVED BY:	Any memory or interface card or the processor card.
FUNCTION:	DB0 to 15, of which DB0+ is the least significant bit, are used for all system data transfers.
TIMING:	An interface card will drive the data bus during the assertion of MEMGO- on a DMA write. The RAM card drives the data bus on a read cycle for one cycle, during the assertion of VALID-. The processor card drives the data bus with the assertion of MEMGO- on a memory write (STA), with IOGO- on an I/O write (OTA), and with VALID- clocked by start of long half-cycle on A or B fetch or Boot Read.
FCLK-	
FULL NAME:	Fast clock
DRIVEN BY:	Processor card
RECEIVED BY:	Memory card
FUNCTION:	FCLK- is exactly five times the frequency of SCLK- and is used by the memory to synchronize various backplane functions.
TIMING:	FCLK- is a 50-percent duty cycle clock with a maximum frequency of 22.016 MHz. FCLK- is in synchronization with SCLK- such that a positive edge of FCLK- accompanies every transition of SCLK-.

Table 6-37. Backplane Signal Definitions (Continued)

IAK-	
FULL NAME:	Interrupt Acknowledge (low true)
DRIVEN BY:	Processor card
RECEIVED BY:	Any interrupting card
FUNCTION:	Asserted to signal that an interrupt request is about to be serviced and to freeze the interrupt priority chain.
TIMING:	IAK- is asserted by the processor card following the start of the short half cycle of SCLK-. It is held until after the trap cell instruction has commenced. (BUSY-↓ causes IAK-↑.)
ICHID-	
FULL NAME:	Interrupt Chain In Disable (low true)
DRIVEN BY:	The next higher priority card, to whom this signal is ICHOD-.
RECEIVED BY:	All interface cards
FUNCTION:	See ICHOD-
TIMING:	See ICHOD-
NOTE:	See ICHOD-
ICHOD-	
FULL NAME:	Interrupt Chain Out Disable (low true)
DRIVEN BY:	All interface cards, and the processor card (which is the top of the chain).
RECEIVED BY:	The next lower priority card, to whom this signal is ICHID-.
FUNCTION:	Asserted to disable lower priority cards from interrupting. A high on this line keeps interrupt generation enabled. ICHOD- is part of the ICHID-/ICHOD-daisy chain, used to determine interrupt priority.

Table 6-37. Backplane Signal Definitions (Continued)

TIMING:	Asserted by an interface card when its ICHID line goes low, or when its FLAG and CONTROL flip-flops get set. De-asserted when ICHID- goes high, and on either a CLF, CLC or PON+. Asserted by processor card on power fail, memory protect, parity error, UIT or TBG interrupts.
INTRQ-	
FULL NAME:	Interrupt Request (open-collector, low true)
DRIVEN BY:	All interface cards
RECEIVED BY:	Processor card
FUNCTION:	Asserted to signal an interrupt request, and held low until the interrupt gets service, until PON+ goes low, or until a CLC 0 is executed.
TIMING:	Asserted by an interface card when both its CONTROL and FLAG flip-flops are set and its ICHID- signal is high. De-asserted when the CONTROL or FLAG flip-flop is cleared, or 2 cycles after the assertion of IAK- while ICHID- is high.
IOGO-	
FULL NAME:	I/O Handshake Request Acknowledge (low true)
DRIVEN BY:	Processor card
RECEIVED BY:	All interface cards
FUNCTION:	Asserted to signal that the processor card is ready to receive a command or send or receive an operand from an interface card. De-asserted when the transfer has been completed.
TIMING:	Pulled low when the data bus is available for transfers and released as soon as the data has been clocked off the backplane.
NOTE:	For some types of I/O transfers, this signal will participate in a double handshake. See paragraph 6.4.2.

Table 6-37. Backplane Signal Definitions (Continued)

IORQ-	
FULL NAME:	I/O Handshake Request (open collector, low true)
DRIVEN BY:	All interface cards
RECEIVED BY:	Processor card
FUNCTION:	Asserted to signal that an interface requires processor service, and de-asserted when being serviced.
TIMING:	Asserted within 2 cycles after the rising edge of RNI-, or, in slave mode (see paragraph 6.4.8) on the next rising edge of SCLK- after SCHID- goes high. De-asserted to signal that data will be valid on the second rising edge of SCLK-, or during an input, to signal that data has just been latched. See paragraph 6.4.7.
NOTE:	For some types of I/O transfers, this signal will participate in a double handshake. See paragraph 6.4.7.
MCHID-	
FULL NAME:	Memory Chain In Disable (low true)
DRIVEN BY:	The next higher priority card, to whom this signal is MCHOD-.
RECEIVED BY:	All interface cards
FUNCTION:	Asserted to disable initiation of a memory cycle.
TIMING:	MCHID- is asserted a maximum of one cycle after MRQ- goes low. Released as soon as memory cycle of higher priority device is complete.

Table 6-37. Backplane Signal Definitions (Continued)

MCHOD-	
FULL NAME:	Memory Chain Out Disable (low true)
DRIVEN BY:	All interface cards and processor card.
RECEIVED BY:	The next lower priority card, to whom this signal is MCHID-.
FUNCTION:	Asserted to disable all lower priority cards from initiating a memory cycle.
TIMING:	An interface card wanting a DMA cycle asserts MCHOD- at the end of the short half cycle of SCLK-. MCHOD- is de-asserted at the end of the short half cycle, following the assertion of BUSY-. The processor card is the top of this priority chain. MCHOD- is tied high on the processor card.
NOTE:	All cards not using the memory priority chain must connect MCHOD- to MCHID-.
MCHODOC-	
FULL NAME:	Memory Chain Out Disable Open Collector (open collector, low true)
DRIVEN BY:	All interface cards
RECEIVED BY:	Head of priority chain on lower priority stack.
FUNCTION:	Used as look-ahead for the memory priority chain. If any interface card in the higher priority stack asserts MCHODOC-, all interface cards in the lower priority stack will become disabled from initiating a memory cycle.
TIMING:	An interface card wanting a DMA cycle asserts MCHODOC- at the end of the short half cycle of SCLK-. MCHODOC- is released at the end of the short half cycle, following the assertion of BUSY-.
NOTE:	As far as the output of any given interface card is concerned, MCHODOC- is logically identical to MCHOD-.
	The pull-up resistor on this line is located on the 2 by 8 backplane. The two smaller backplane configurations are not large enough to require look-ahead in the memory priority chain, so this line is not terminated in these smaller configurations.

Table 6-37. Backplane Signal Definitions (Continued)

MEMDIS-	
FULL NAME:	Memory Disable (low true)
DRIVEN BY:	Processor card
RECEIVED BY:	Memory card
FUNCTION:	To disable memory during a boot access.
TIMING:	Asserted with MEMGO-.
NOTE:	MEMDIS- is not bussed up and down the backplane, instead, it runs above the SLAVE- chain (see PS- signal).
MEMGO-	
FULL NAME:	Memory Cycle Initiation (open collector, low true)
DRIVEN BY:	Processor and interface cards.
RECEIVED BY:	Memory, processor, and interface cards.
FUNCTION:	Pulled low to signal a memory request and released once service begins.
TIMING:	MEMGO- may be asserted by the card wishing to initiate a memory cycle after the falling edge of SCLK- that follows the release of BUSY-. MEMGO- is released by the processor card after the assertion of BUSY-. MEMGO- is released by an interface card after being held low for one cycle of SCLK-.

Table 6-37. Backplane Signal Definitions (Continued)

MLOST-	
FULL NAME;	Memory Lost (open collector, low true)
DRIVEN BY:	Processor, memory, and battery back-up card
RECEIVED BY:	Processor card
FUNCTION:	MLOST- is asserted by the battery back-up card to indicate that memory power was lost when system power last went down. Memory will then be cleared on the next power up. In a case where there is no back-up supply for the memory, MLOST- can be grounded. This may be accomplished by a switch setting on the processor card which grounds MLOST-, or by a switch setting on the memory card which shorts +5V to +5M and grounds MLOST-.
TIMING:	Asserted as soon as memory power fails. Released 10 msec after the rising edge of PON+.

MP+	
FULL NAME:	Memory Protect (open collector, high true)
DRIVEN BY:	Processor card
RECEIVED BY:	All interface cards
FUNCTION:	MP+ is asserted to indicate that the memory protect system is on. When MP+ is high, all I/O interface cards are inhibited from recognizing I/O instructions. DMA is not affected.
TIMING:	MP+ is asserted after an STC 05 instruction. It is released when IAK- is asserted, but re-asserted if an I/O group instruction is in the trap cell. MP+ is always in the proper state before RNI- is asserted and does not change until the next instruction fetch is initiated.

Table 6-37. Backplane Signal Definitions (Continued)

MRQ-	
FULL NAME:	Memory Request (open collector, low true)
DRIVEN BY:	All interface cards
RECEIVED BY:	Processor card
FUNCTION:	Asserted to indicate that an interface card performing DMA has requested a memory cycle. When MRQ- is low, the processor card is inhibited from requesting a memory cycle.
TIMING:	An interface card wanting a DMA cycle asserts MRQ- at the start of the long half cycle of SCLK-. MRQ- is de-asserted on the falling edge of SCLK- after the assertion of BUSY-.
PE-	
FULL NAME:	Parity Error (open collector, low true)
DRIVEN BY:	Memory card.
RECEIVED BY:	Processor and interface cards.
FUNCTION:	Asserted if last memory read produced a parity error.
TIMING:	PE- is asserted for one short half cycle after the release of VALID-.
PFW-	
FULL NAME:	Power Fail Warning (open collector, low true)
DRIVEN BY:	Power supply
RECEIVED BY:	Processor card and battery back-up card
FUNCTION:	Asserted to signal an AC line voltage failure.
TIMING:	Asserted at least 5 msec before the fall of PON+. Released before the rise of PON+.
NOTE:	The pull-up resistor on this open collector line is located on the processor card.

Table 6-37. Backplane Signal Definitions (Continued)

PON+	
FULL NAME:	Power On (open collector, high true)
DRIVEN BY:	Power supply and processor.
RECEIVED BY:	All cards in system.
FUNCTION:	PON+ is asserted by the power supply shortly after all power supply voltages are stable, to allow time for initialization on individual system cards. It is also pulsed low by a momentary switch located on the processor card in order to reset the computer.
TIMING:	Asserted 1 msec after all power supplies are stable. De-asserted if any supply falls below a tolerable level.

Table 6-37. Backplane Signal Definitions (Continued)

PS-

FULL NAME: Parity Sense

DRIVEN BY: Processor card.

RECEIVED BY: Memory card.

FUNCTION: A high level on PS- causes memory to generate and detect odd parity. A low on PS- causes memory to generate and detect even parity.

TIMING: The level of PS- is selected by flag 5. An STF 5 selects even parity and a CLF 5 selects odd parity.

NOTE: On power up, PS- is set for odd parity. Also note that PS- is not bussed up and down the backplane. Instead, it is sent by the processor card only to the memory card located above it. See figure below.

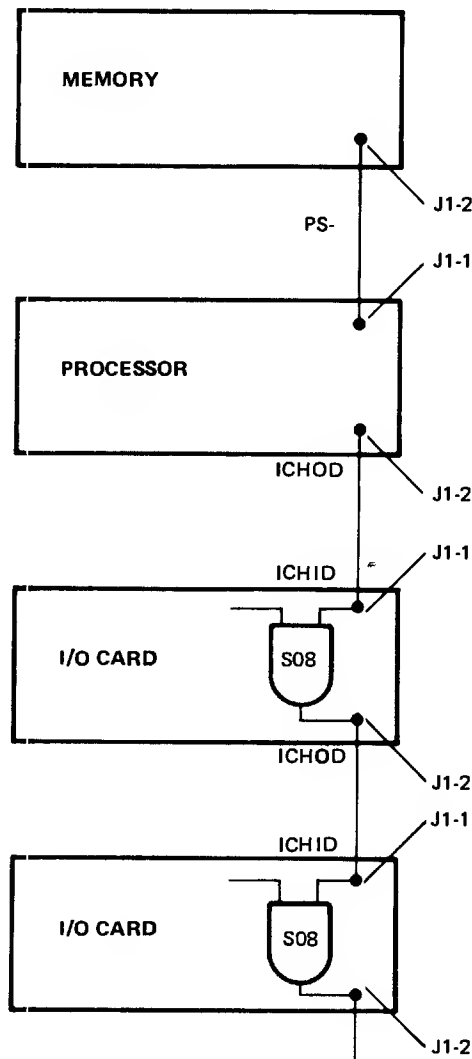


Table 6-37. Backplane Signal Definitions (Continued)

RCLK+	
FULL NAME:	Refresh Clock
DRIVEN BY:	Processor card
RECEIVED BY:	Memory
FUNCTION:	RCLK+ is a fixed frequency clock, in synchronization with SCLK-. RCLK+ is used by the refresh counter on the memory card to determine how often to refresh.
TIMING:	RCLK+ is the complement of SCLK-, when SCLK- has a 227 nsec cycle.
NOTE	
RCLK+ is not bussed up and down the backplane; instead, it is above the MCHOD priority chain.	
REMEM-	
FULL NAME:	Remote Memory (open collector, low true)
DRIVEN BY:	Interface cards
RECEIVED BY:	Memory
FUNCTION:	REMEM- is asserted to indicate that the simultaneous MEMGO- which occurs should initiate a memory cycle with the remote memory. Any memory card in the system should ignore MEMGO- if it occurs with REMEM-.
TIMING:	REMEM- is asserted and released with MEMGO-.

Table 6-37. Backplane Signal Definitions (Continued)

RNI-	
FULL NAME:	Read Next Instruction (low true)
DRIVEN BY:	Processor card.
RECEIVED BY:	All interface cards.
FUNCTION:	RNI- is asserted to indicate that the current memory cycle is a fetch and that an instruction will be on the data bus.
TIMING:	RNI- is asserted with the fetch address. It is released after the start of the short half cycle of SCLK- after VALID- is asserted.
NOTE:	The instruction is to be latched on the trailing (rising) edge of RNI-.
(SC0+) - (SC4+)	
FULL NAME:	Address Extension Bus 0 - 4
DRIVEN BY:	Interface Cards
RECEIVED BY:	XL Memory Controller
FUNCTION:	The SC bus is used by I/O interfaces performing DMA to select one of thirty-two DMA relocation (offset) registers of the XL mapped extended memory controller.
TIMING:	The Address Extension Bus is driven simultaneously with AB0 - AB14.
SC5	
FULL NAME:	Self Configure
DRIVEN BY:	Interface Cards
RECEIVED BY:	XL Memory Contgroller
FUNCTION:	SC5+ is asserted to indicate that DMA self-configuration is occurring. The XL memory controller disables the DMA relocation registers during DMA self-configuration.
TIMING:	SC5+ is driven simultaneously with AB0 - AB14.

Table 6-37. Backplane Signal Definitions (Continued)

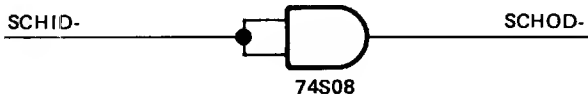
SCHID-	
FULL NAME:	Slave Chain In Disable (low true)
DRIVEN BY:	The next higher priority card, to whom this signal is SCHOD-.
RECEIVED BY:	All interface cards
FUNCTION:	See SCHOD-
TIMING:	See SCHOD-
SCHOD-	
FULL NAME:	Slave Chain Out Disable (low true)
DRIVEN BY:	All interface cards
RECEIVED BY:	The next lower priority card, to whom this signal is SCHID-.
FUNCTION:	SCHOD- is asserted to disable lower priority cards from entering slave mode. SCHOD- is part of the SCHID-/SCHOD- priority chain, used to settle conflicts for slave mode processing (see paragraph 6.4.8).
TIMING:	SCHOD- is asserted with SLAVE-, or if a higher priority card pulls on SCHID-, and is held as long thereafter as it takes the daisy chain to ripple down. Likewise, SCHOD- is released with SLAVE- or SCHID-.
NOTE:	<p>The top of the priority chain is the processor card. Whenever SLAVE- is asserted, and the processor card has completed executing the current instruction, SCHOD- goes high for one cycle of SCLK-.</p> <p>There must be exactly one non-inverting Schottky gate on each card between SCHID- and SCHOD-. Example:</p>
 <pre> graph LR SCHID- --- G1[74S08] G1 --- SCHOD- </pre> <p>The diagram illustrates a non-inverting Schottky gate, specifically a 74S08, used to connect the SCHID- and SCHOD- signals. The gate is represented by a D-shaped symbol with a small circle at the input. The input line is labeled SCHID- and the output line is labeled SCHOD-. The gate is labeled 74S08 below it.</p>	

Table 6-37. Backplane Signal Definitions (Continued)

SCLK-

FULL NAME: Slow clock

DRIVEN BY: Processor card

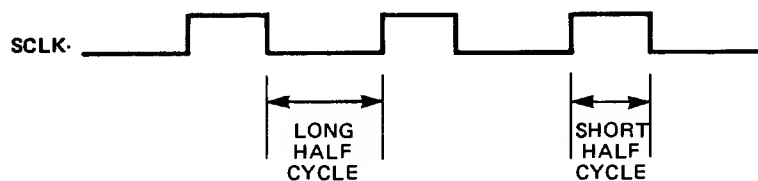
RECEIVED BY: All system cards

FUNCTION: SCLK- is used to synchronize many diverse system signal interactions.

TIMING: SCLK- is a derivative of FCLK. It is generated with a divide-by-5 circuit which produces a signal with a minimum of a 227.1 nsec period and a 40-percent duty cycle.

NOTE 1: In all timing descriptions, the term "short half-cycle" refers to the time (2/5 period) when SCLK- is high. The "long half-cycle" refers to the 3/5 period when SCLK- is low.

So as to minimize clock skew, all cards are required to receive SCLK- into an S240.



NOTE 2: Although SCLK- typically has a 227.1 nsec period, it slows to 454.2 nsec during the assertion of IOGO- on the backplane, in order to permit the processor to handshake with the interface cards.

Table 6-37. Backplane Signal Definitions (Continued)

SLAVE-	
FULL NAME:	Slave Request (open collector, low true)
DRIVEN BY:	Interface cards
RECEIVED BY:	Processor card
FUNCTION:	SLAVE- is asserted to request the processor to enter slave mode, i.e., to force the processor to enter an I/O handshake.
TIMING:	SLAVE- is held asserted until the start of the long half cycle of SCLK- following the release of SCHID-.
SPRQ-	
FULL NAME:	Special Interrupt
DRIVEN BY:	64kByte RAM/ROM/STACK card for HP 1000 A-Series Automation Processor.
RECEIVED BY:	Processor card
FUNCTION:	SPRQ- is asserted in order to request an interrupt. This interrupt has higher priority than I/O interrupts or power fail interrupt. Its priority is only exceeded by parity error and unimplemented instruction trap interrupts.

Table 6-37. Backplane Signal Definitions (Continued)

VALID-	
FULL NAME:	Data Valid (Tri-state, low true)
DRIVEN BY:	Processor and memory cards
RECEIVED BY:	Processor and interface cards
FUNCTION:	VALID- is asserted to signal that the data on the data bus is about to become valid during a memory read cycle.
TIMING:	On a read cycle, the memory will assert VALID- after the rising edge of SCLK- that precedes the appearance of valid data on the backplane by one cycle. VALID- will be held low for one cycle and then released on the rising edge of SCLK- right after data becomes valid. The processor card asserts VALID- during a boot ROM read for one cycle synchronized to the start of the short half cycle. VALID- is also asserted during write.
WE-	
FULL NAME:	Write Enable (Tri-state, low true)
DRIVEN BY:	Any card accessing memory
RECEIVED BY:	Memory card
FUNCTION:	WE- is asserted to signal a memory write, and held high to signal a memory read.
TIMING:	WE- is asserted and released with (AB0+)-(AB14+).

6.7 PARTS LOCATIONS

Parts locations for the backplanes are shown in figures 6-3 through 6-5.

6.8 PARTS LIST

The parts list for the backplanes is shown in table 6-38. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

Table 6-38. Backplane Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	02145-60001	1	1	16-SLOT BACKPLANE	28480	02145-60001
CR1	1902-0939	9	1	DIODE-2NR 5V PD=5W TC=+.06% IR=300UA	11961	1N5908
CR2	1902-0941	3	2	DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
CR3	1902-0941	3		DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
R1	0698-3444	1	1	RESISTOR 316 1% .125W F TC=0+-100	24546	C4-1/8-T0-316H-F
R2	0698-3441	8	1	RESISTOR 215 1% .125W F TC=0+-100	24546	C4-1/8-T0-215R-F
	1251-4573	4	32	CONNECTOR-PC EDGE 25-CONT/ROW 2-ROW8	28480	1251-4573
	1251-5668	0	2	CONNECTOR 10-PIN F POST TYPE	28480	1251-5668
	1251-5670	4	1	CONNECTOR 4-PIN F POST TYPE	28480	1251-5670
	12030-60002	5	1	C.C. BACKPLANE	28480	12030-60002
CR1	1902-0941	3	2	DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
CR2	1902-0939	9	1	DIODE-2NR 5V PD=5W TC=+.06% IR=300UA	11961	1N5908
CR3	1902-0941	3		DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
	1251-4573	4	20	CONNECTOR-PC EDGE 25-CONT/ROW 2-ROW8	28480	1251-4573
	1251-5668	0	2	CONNECTOR 10-PIN F POST TYPE	28480	1251-5668
	1251-5670	4	1	CONNECTOR 4-PIN F POST TYPE	28480	1251-5670
	12032-60001	6	1	C.C. BACKPLANE	28480	12032-60001
CR1	1902-0941	3	2	DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
CR2	1902-0939	9	1	DIODE-2NR 5V PD=5W TC=+.06% IR=300UA	11961	1N5908
CR3	1902-0941	3		DIODE-2NR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
J3	0360-1970	9	1	BARRIER BLOCK R-TERM PC BOARD NYL	89020	888408
	1251-4573	4	10	CONNECTOR-PC EDGE 25-CONT/ROW 2-ROW8	28480	1251-4573

Table 6-39. Manufacturer's Code List

The following code numbers are from the Federal Supply Code for Manufacturers Cataloging Handbooks H4-1 and H4-2, and their supplements.					
CODE NO.	MANUFACTURER	ADDRESS	CODE NO.	MANUFACTURER	ADDRESS
C0633	Aktiebolaget Rifa	Bromma, SE	17856	Siliconix Inc.	Santa Clara, CA 95054
H9027	Schurter A G H	Luzern, SW	18324	Signetics Corp.	Sunnyvale, CA 94086
0003J	Nippon Electric Co.		24546	Corning Glass Works (Bradford)	Bradford, PA 16701
00853	Sangamo Elec. Co. South Carolina Div.	Pickens, SC 29671	27014	National Semiconductor Corp.	Santa Clara, CA 95051
01121	Allen-Bradley Co.	Milwaukee, WI 53204	27777	Varo Semiconductor Inc.	Gardland, TX 75040
01295	Texas Instr Inc. Semiconductor CMPNT Div.	Dallas, TX 75222	28480	Hewlett-Packard Co. Corporate Hq	Palo Alto, CA 94304
0192B	RCA Corp Solid State Div.	Sommerville, NJ 08876	32293	Intersil Inc.	Cupertino, CA 95014
02111	Spectrol Electronics Corp.	City Of Ind, CA 91745	34344	Motorola Inc.	Franklin Park, IL 60131
03508	GE Co. Semiconductor Prod. Dept.	Syracuse, NY 13201	50364	Monolithic Memories Inc	Sunnyvale, CA 94086
04713	Motorola Semiconductor Products	Phoenix, AZ 85062	56289	Sprague Electric Co.	North Adams, MA 01247
07263	Fairchild Semiconductor Div.	Mt. View, CA 94042	75042	TRW Inc. Philadelphia Div.	Philadelphia, PA 19108
11236	CTS Of Berne Inc.	Berne, IN 46711	89020	Amerace Corp Control Prod. Div.	Union, NJ 07086
11961	Semicon Inc.	Burlington, MA 01803	91506	Augat Inc.	Attleboro, MA 02703
13606	Sprague Elect Co. Semiconductor Div.	Concord, NH 03301			

POINT-OF-LOAD REGULATOR	SECTION VII
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7.1 INTRODUCTION

The point-of-load regulator (part no. 02145-60002) in the HP 1000 L-Series computer system provides dc voltages for the HP 7902A Flexible Disc Drive. The input to the point-of-load regulator is a 25-kHz output voltage of the system power supply.

7.2 SPECIFICATIONS

REGULATION:

+5V	+/-5%
+12V	+/-5%
-12V	+/-6%

OUTPUT CURRENT (MAX.):

+5V	4 Amps
+12V	3 Amps
-12V	3 Amps

OVER VOLTAGE PROTECTION: +20%

OVER CURRENT PROTECTION: 5 Amps

7.3 THEORY OF OPERATION

A general discussion of typical circuits that can be used to develop dc voltages from the system power supply's 25-kHz voltage is given in Appendix B of this document.

The schematic diagram of the point-of-load regulator is located at the rear of this section. Transformer T1 receives the 25-kHz voltage from the system power supply and provides three outputs which are rectified and applied to three voltage regulators. The +12-Vdc regulator, U2, does not have a reference input and requires a +15-Vdc input in order to provide a regulated output of +12 Vdc. High-speed zener diode CR11 clamps the output of U2 at +12 Vdc. The circuitry for the +5-Vdc regulated output is essentially the same as that for the +12-Vdc output. (Note that the input to U1 must be +8 Vdc.) Voltage regulator U3, however, does have a reference input and the reference voltage is provided via the divider consisting of resistors R1 and R2. Normally, the voltage supplied by T1 to U3 is -15 Vdc. Zener diode CR9 clamps the output of U3 at -12 Vdc.

7.4 PARTS LOCATIONS

Parts locations for the point-of-load regulator are shown in figure 7-1.

7.5 PARTS LIST

The parts list for the point-of-load regulator is given in table 7-1. Refer to table 6-39 for the names and addresses of manufacturers of the parts.

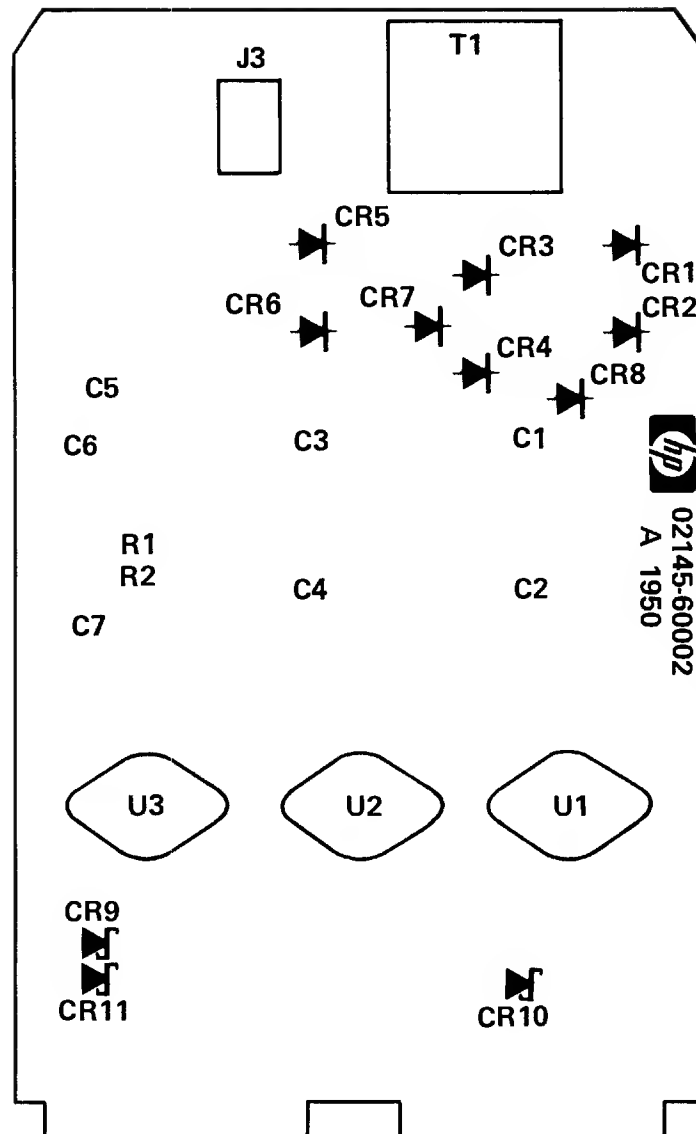
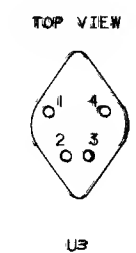
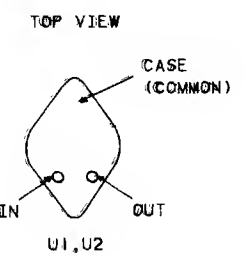
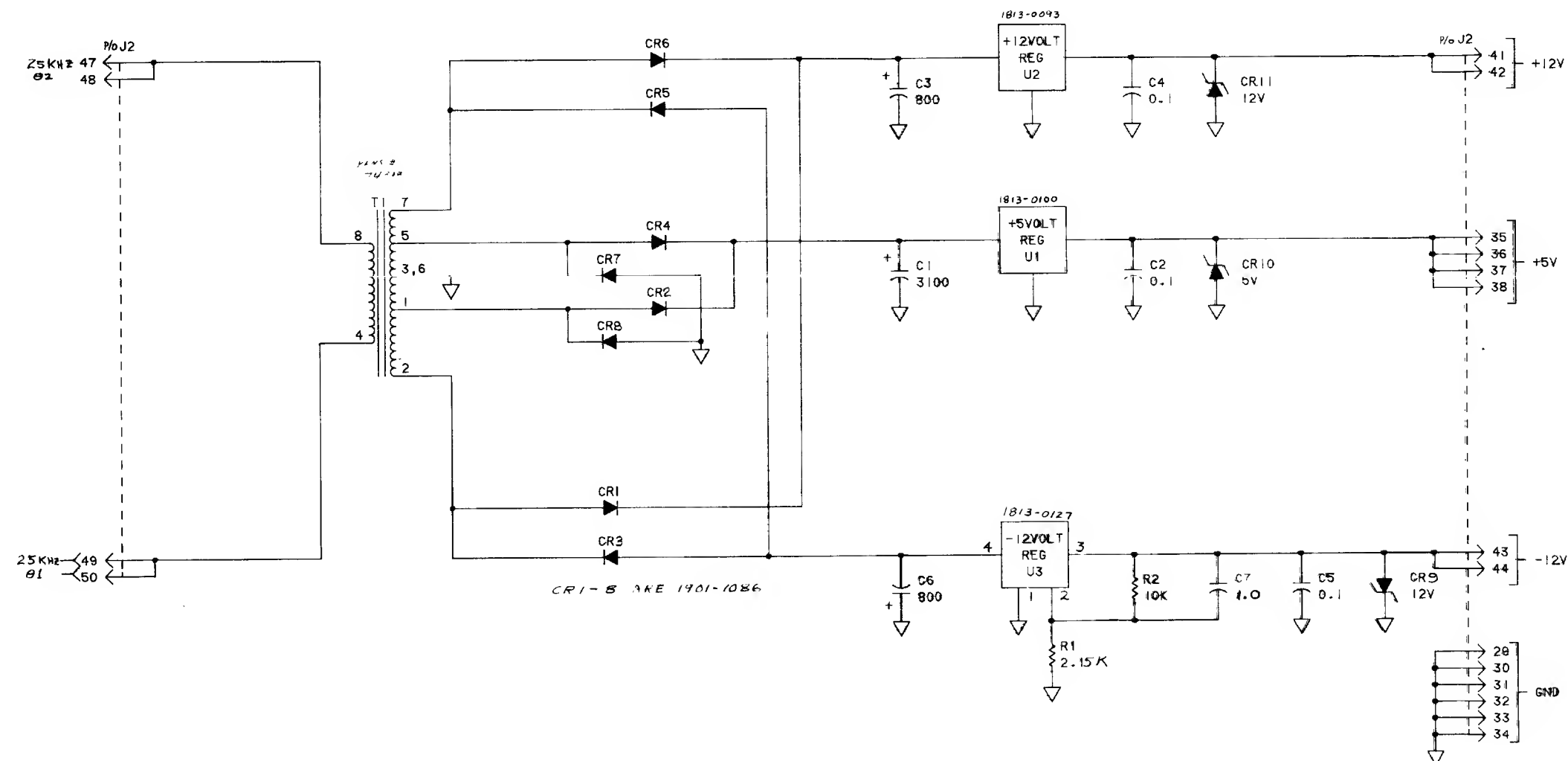


Figure 7-1. Point-of-Load Regulator Parts Locations

Table 7-1. Point-of-Load Regulator Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	02145-00002	2	1	PN7 DP LOAD REGULATOR	28480	02145-00002
C1	0180-2706	9	1	CAPACITOR-FX0 3100UF+75-10% 16VDC AL	00853	300JJ312U016B
C2	0160-4835	7	3	CAPACITOR-FX0 .1UF +=-10% 50VDC CER	28480	0160-4835
C3	0180-2724	3	2	CAPACITOR-FX0 800UF+75-10% 40VDC AL	00853	300HJ801U040B
C4	0160-4835	7		CAPACITOR-FX0 .1UF +=-10% 50VDC CER	28480	0160-4835
C5	0160-4835	7		CAPACITOR-FX0 .1UF +=-10% 50VDC CER	28480	0160-4835
C6	0180-2726	3		CAPACITOR-FX0 800UF+75-10% 40VDC AL	00853	300HJ801U040B
C7	0160-4844	8	1	CAPACITOR-FX0 1UF +80-20% 50VDC CER	28480	0160-4844
CR1	1901-1086	7	8	DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR2	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR3	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR4	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR5	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR6	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR7	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR8	1901-1086	7		DIODE-PWR RECT 50V 5A 200NB	04713	MR820
CR9	1902-0941	3	2	DIODE-ZNR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
CR10	1902-0939	9	1	DIODE-ZNR 5V PD=5W TC=+.06% IR=300UA	11961	1N5908
CR11	1902-0941	3		DIODE-ZNR 12V PD=5W TC=+.084% IR=2UA	11961	1.58E15A
J3	1251-3819	9	1	CONNECTOR 6-PIN M UTILITY	28480	1251-3819
R1	0698-0084	9	1	RESISTOR 2.15K 1% .125W F 7C=0+-100	24546	C4-1/R-T0-2151-F
R2	0757-0442	9	1	RESISTOR 10K 1% .125W F 7C=0+-100	24546	C4-1/R-T0-1002-F
T1	9100-2626	3	1	TRANSFORMER INVERTER, PRI: 14 TURNS	28480	9100-2626
U1	1813-0100	7	1	IC V RGLTR T0-3	07263	UA78H05KC
U2	1813-0093	7	1	IC V RGLTR T0-3	07263	UA78H12KC
U3	1813-0127	8	1		28480	1813-0127



POINT OF LOAD REGULATOR		HEWLETT PACKARD	
TITLE	12000 D/E	02145 - 60002	PART NUMBER
NEXT ASSEMBLY		0-02145 - 60002 - 51	SCALE
FINISH			

EXTENDED MEMORY	SECTION VIII
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8.1 INTRODUCTION

The Expanded Memory hardware, or XL memory, for the 1000 L-Series Computers and Computer Systems consists of three circuit cards, the 12002A, the 12003A, and the 12002B. The 12002A contains the XL memory controller and a 128 Kbyte RAM array. The 12003A is an array board containing a 128 Kbyte RAM array which is controlled by the signals from the 12002A over the frontplane connector. Up to three 12003A cards may be used with the 12002A in order to provide up to 512 Kbytes of main memory in 128 Kbyte increments.

The 12002B is the XL memory controller with a 512 Kbyte RAM array. This high memory density on a card is achieved with the use of 64K RAM chips. The circuit cards are shown in figure 8-1. The 12002A and 12002B are identical in appearance except for jumper placement.

8.2 OVERVIEW

8.2.1 SYSTEM ENVIRONMENT

The system environment of the HP 1000 L-Series Computer system is shown in Section II, figure 2-2. The Extended Memory controller (12002A or 12002B) is subject to the same slot restrictions as the 64 Kbyte 12004A memory card:

- a. The XL memory controller card must be located in the next higher priority slot above the processor card.
- b. No I/O cards may be located above the XL memory controller.

Thus, the memory and processor occupy the highest priority slots in the backplane. These slots do not, however, need to be the highest slots in the backplane. Any slots can be used by the processor and memory as long as no I/O cards are located above the memory card(s). (See Section VI, figure 6-3 for slot priorities.)

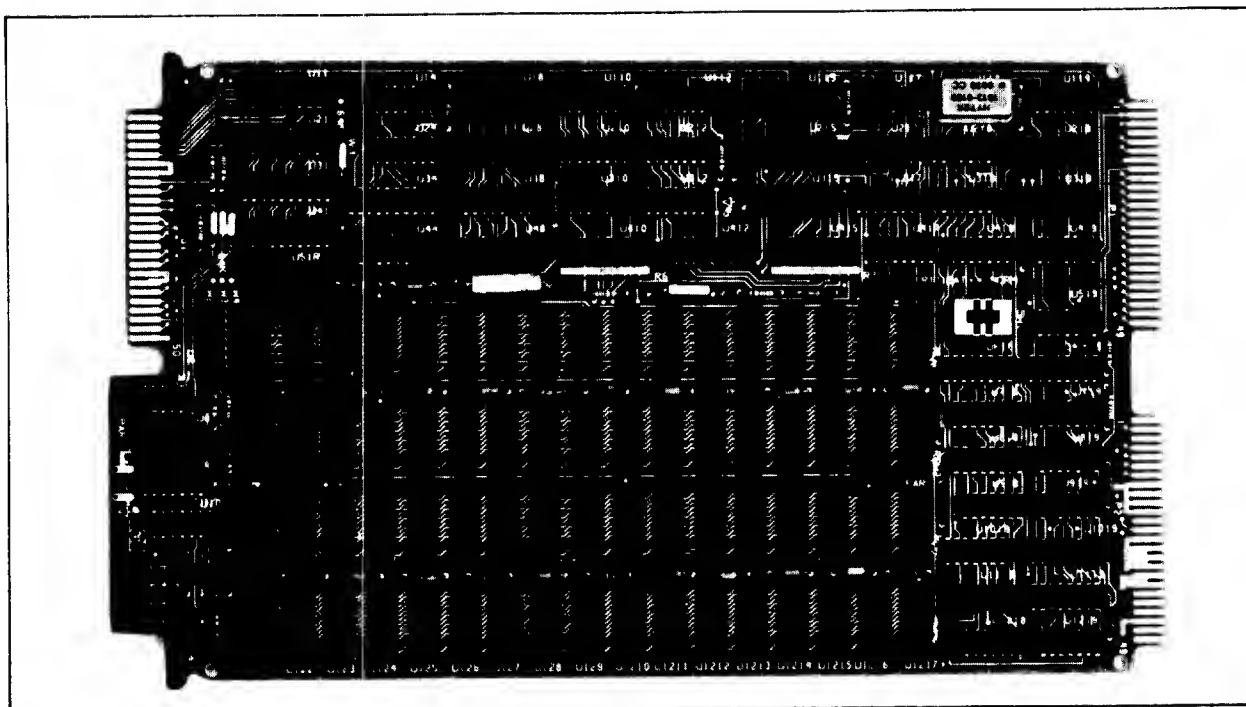


Figure 8-1A. 12002A Memory Card

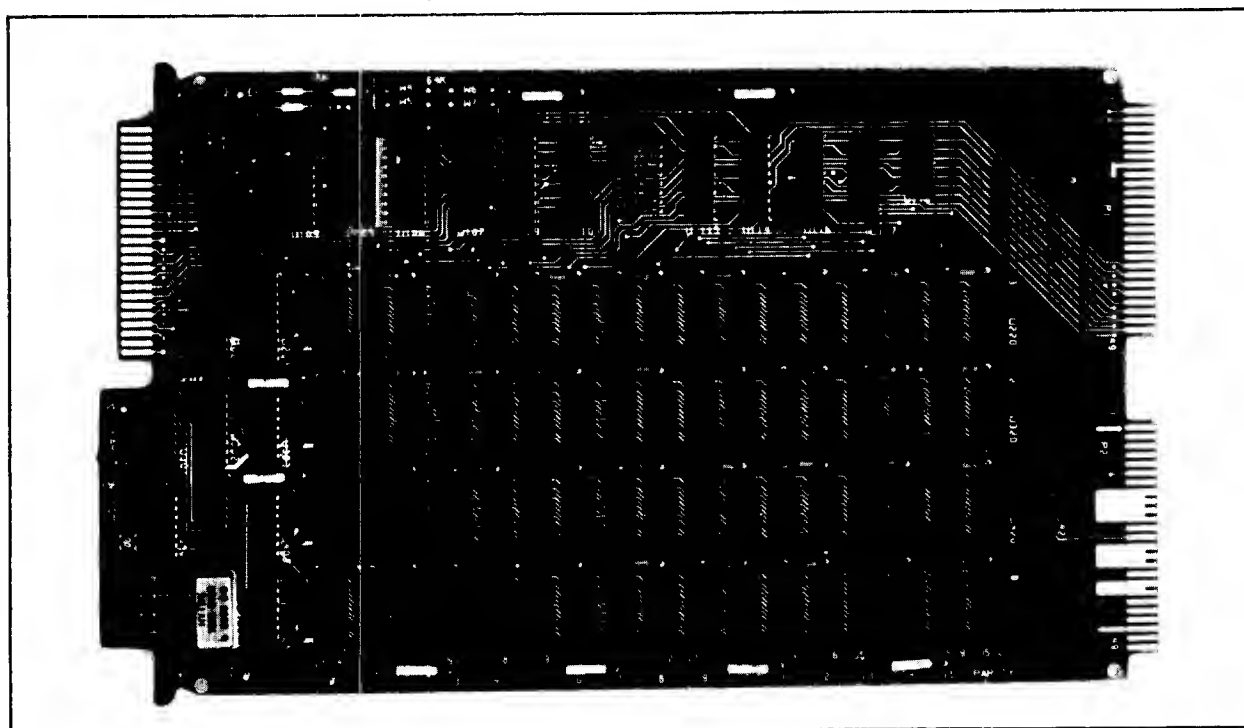


Figure 8-1B. 12003A Memory Card

The XL array cards (12003A) must occupy the backplane slots directly above the XL controller. If multiple array cards are used, they must occupy consecutive slots above the XL controller. When array cards are used, they must be connected to the XL memory controller by a frontplane connector. No modifications are needed to any of the array cards to select their relative position above the XL controller. All array cards operate in any position above the controller.

There are three frontplane connectors available. The 12028A is a two-connector frontplane used with 256 Kbytes of memory (one 12002A and one 12003A). The 12028B is a three-connector frontplane used with 384 Kbytes of memory (one 12002A and two 12003As). The 12028C is a four-connector frontplane used with 512K bytes of memory (one 12002A and three 12003As). The physical limitation of the frontplane connectors require that the XL memory controller and the XL memory array boards be located on the same side of the backplane when a side-by-side backplane, such as in the 2103L box, is used.

8.2.2 BASIC MEMORY OPERATION

The memory in the L-Series is always operating in one of four modes at any time; write cycle, read cycle, refresh cycle, or standby mode.

All memory accesses are either read cycles or write cycles and are initiated by an external device. When the backplane signal MEMGO- is asserted at the rising edge of SCLK-, the memory will initiate a memory access. For all accesses the XL controller card asserts BUSY- on the backplane to prevent other devices from requesting memory access. The controller also asserts VALID- on the backplane for one state at the completion of the access for all read cycles and write cycles. The rising edges of VALID- and BUSY- tell the cards in the system that the memory access has completed.

A read cycle is initiated when the backplane signal MEMGO- is asserted and the signal write enable (WE-) is not asserted at the rising edge of SCLK-. When BUSY- is asserted, the address bus is latched from the backplane and the memory controller starts a memory read cycle. The actual physical memory location accessed is determined by the latched backplane address, the latched extended address bus (SC0-SC4), the contents of the controller's map RAMs, and whether the access was initiated by the processor or by an I/O card.

At the end of the read cycle, the addressed memory card drives the backplane data bus with the requested data. The data is valid on the backplane at the rising edge of VALID-. If a parity error has occurred the controller card will also drive the PE- line on the backplane.

A write cycle is initiated when the backplane signals MEMGO- and Write Enable (WE-) are both asserted at the rising edge of SCLK-. When these conditions are met, the controller will initiate a memory write cycle. BUSY- is asserted, and the controller latches the address and data buses and proceeds to write the data to the correct memory location. The actual physical memory location to be accessed is determined in precisely the same manner as for a

read cycle, described above. VALID- is asserted on the backplane at the completion of the write cycle.

Refresh cycles are always initiated by the memory controller. All cards in the memory system perform a refresh at the same time. The controller card resolves all conflicts between memory accesses and refresh cycles and properly sequences the refreshing of all memory cards.

The memory can perform only one of the above operations at a time. When the memory is not being accessed or refreshed it is in the standby mode.

8.2.3 BASIC MAP CONTROL OPERATIONS

The XL memory is a mapped memory system. The XL controller has the capability of extending the 15-bit backplane address into an 18-bit physical address which can access up to 256K words of main memory.

The XL controller has two basic operating modes for processor memory accesses which are physical mode (unmapped) and logical mode (mapped). When the controller is in physical mode it allows the processor to access only the lowest 32K words in main memory. The exact address accessed is determined by the backplane address bus.

When the controller is in logical mode it allows the processor to access 32K words in memory, but the location of the 32K words in main memory is determined by the backplane address and the contents of the map RAMs.

The controller card contains the logic to recognize instructions which control the operating mode for processor accesses.

I/O accesses typically occur to main memory relative to a Relocation Register. The I/O card selects a specific Relocation Register to use for the IMA transfer. The contents of the Relocation Register have been previously loaded for use by the I/O card. This Relocation Register points to a position in main memory. From this position the I/O card then has access to the next higher 32K word contiguous block of memory. The exact address accessed is determined by the result of the addition of the backplane address to the contents of the selected Relocation Register.

I/O accesses will not occur relative to a Relocation Register under two conditions. If the I/O card asserts the Self Configure line (SC5) on the backplane the I/O transfer will occur to physical memory. If the I/O card drives the extended address bus (SC0-SC4) all low during an access, the transfer will occur to physical memory. In both cases the exact location in physical memory is determined directly by the backplane address bus.

The controller card provides the mechanism to write to the map RAMs located on the controller card. The map RAMs contain the 32 processor maps and the 32 Relocation Registers.

Section 8.3.4 contains a detailed description of the mapping operations on the XL controller.

8.2.4 POWER REQUIREMENTS

The XL memory hardware operates on +5V and +5M voltages only. The worst case power requirements for each card are listed below. The standby power requirements are valid during battery backup operation. The operating power requirements are for full bandwidth memory accessing.

		CURRENT		POWER	
		Operating	Standby	Operating	Standby
12002A	+5V	2.43A	0.00	12.4W	0.0
	+5M	0.63A	0.42A	3.2W	2.1W
12002B	+5V	2.43A	0.00	12.4W	0.0
	+5M	1.00A	0.62A	5.1W	3.2W
12003A	+5V	0.91A	0.00	4.6W	0.0
	+5M	0.46A	0.26A	2.3W	1.3W

8.2.5 POWER SUPPLY CONFIGURATION

The XL memory hardware operates with the power supply and battery backup options to provide the necessary memory voltages to the memory and processor cards. A slide switch, located near the back of the XL controller card, is used to select between NORMAL operation and BATTERY backup operation.

With the slide switch set to NORMAL, the switch connects the +5V voltage trace directly to the +5M voltage trace. This allows operation with no battery backup card in the system. The switch also grounds the MLOST- line on the backplane which signals the processor that memory is not retained during a loss of power.

With the slide switch set to BATTERY backup, the memory voltage +5M is separated from the main voltage +5V, and MLOST- is not grounded. In this configuration it is assumed that the battery backup card is installed in the backplane to provide the +5M voltage to the system backplane. During normal operation with the battery backup card in the backplane, the connection between the memory voltages is made on the battery backup card. Section V of this document contains more information about the battery backup card.

The following is a table of battery backup hold time vs. the XL memory configuration. All times are calculated for the the 12013A battery backup card under worst case conditions over temperature.

BACKUP TIME VERSUS CONFIGURATION

<u>CONFIGURATION</u>		<u>BACKUP TIME</u>
12002A	128K bytes	1 hr 56 min
12002A 12003A (1)	256K bytes	1 hr 23 min
12002A 12002A (2)	384K bytes	1 hr 4 min
12002A 12003A (3)	512K bytes	53 min
12002B	512K bytes	1 hr 29 min

8.2.6 PARITY

The XL memory contains the logic and memory to generate and store a parity check bit during each write cycle at all memory locations and to check for correct parity on each read from memory. The parity circuit, located on the XL controller, monitors the backplane data bus directly without any buffering to ensure correct backplane data parity.

On a write cycle the parity check bit is generated when the backplane data bus is driven by the card accessing memory. The parity bit is then latched and written into memory at the same time the data is written into memory. The controller card also passes the parity bit up the frontplane for an array card to store if the access is to memory on an array card. All memory locations contain a 17th RAM to store the parity bit.

The sense of the parity bit stored in the parity RAM is determined by the PS- line on the backplane. Normally the PS- line on the backplane is deasserted (high) indicating odd parity. When the PS- line is asserted (low) even parity will be stored in the parity RAM.

On a read cycle the parity RAM is accessed along with the row of data RAMs. The parity bit is checked against the parity of the valid backplane data. If the access is from an array card, the parity check bit is available on the frontplane for the controller to use in checking the backplane data parity.

If the parity is in error, the controller card will assert PE- on the backplane for one short half cycle of SCLK-. The memory card will complete the memory cycle and continue to perform memory accesses. It is the responsibility of the card performing the memory read to take appropriate action on a parity error.

Each memory card has a green parity LED. This LED is lit to indicate good parity. If a parity error is encountered, the parity LED on the card generating the bad parity will turn off and stay off until reset.

The parity LED on every XL memory card is reset (turned on) by performing a system power-on (when PON+ is low) or under program control by the execution of a CLC 0 instruction.

8.3 FUNCTIONAL THEORY OF OPERATION

A block diagram of the XL memory controller is shown in figure 8-2. The following section describes the operation of the XL memory system.

8.3.1 BACKPLANE INTERFACE

The XL memory interacts with all the other cards in the computer system through the backplane connectors. This backplane interface contains five groups of signals:

- clocks
- address and data buses
- handshake lines
- control lines
- status lines

CLOCKS (FCLK-, SCLK-, RCLK+)

The FCLK- and SCLK- clock lines are used to synchronize and sequence all memory operations. RCLK+ is used to drive the primary refresh counter which determines when a refresh cycle is required.

ADDRESS and DATA BUSES (A0-A14, SC0-SC4, DO-D

The address bus, extended address bus, and data bus are latched off the backplane on every memory access. The data bus is driven by the selected memory card on a read cycle.

HANDSHAKE LINES (MEMGO-, BUSY-, VALID-, MEMDIS

The main backplane memory handshake signals are MEMGO-, BUSY-, and VALID-. MEMGO- is asserted by the processor card or the I/O cards to request a memory access. The XL controller asserts BUSY- to acknowledge the receipt of MEMGO- and to prevent other devices from requesting memory accesses until the current memory access is complete. No card can assert MEMGO- while BUSY- is asserted. At the end of every memory access the controller will assert VALID- to indicate that the requested data is available on the backplane (for memory reads), or that the data has been written to memory (for memory writes). See figure 8-3 for timing details of these signals.

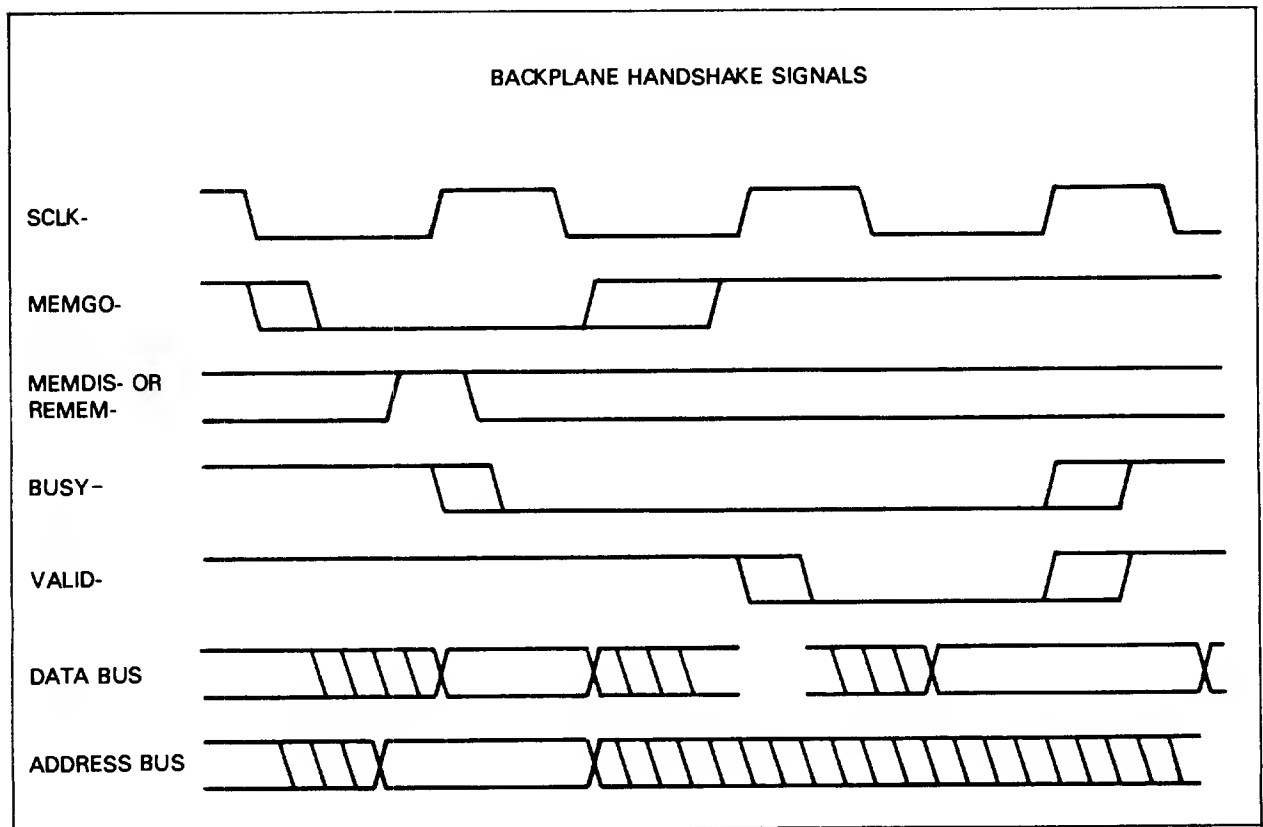


Figure 8-3. Timing of Handshake Signals

The main memory can be inhibited from responding to a memory request by the assertion of either MEMDIS- or REMEM- during the assertion of MEMGO-. MEMDIS- is used by the processor card when it is accessing virtual control panel code or self-test code directly from the ROM on the processor card. During these accesses, the processor card will assert the memory handshake lines BUSY- and VALID- because the controller card is not performing the memory access. REMEM- is asserted by I/O cards when accessing remote memory. Figure 8-3 shows the timing of the inhibit signals.

CONTROL LINES (MRQ-, RNI-, IAK-, COTRN-, CRS)

These five lines control operations on the XL controller card. MRQ- and COTRN- are used by the controller to distinguish between processor accesses and I/O accesses. MRQ- is asserted by all I/O cards when requesting memory access. When MRQ- is asserted with MEMGO-, the controller card will use the Relocation Register selected by the I/O card in performing the memory access. If MRQ- is not asserted with MEMGO-, the controller card will use the processor maps in performing the access. COTRN- can be used to invert the effect MRQ- has in determining the type of access to perform. When COTRN- is asserted with MRQ- the controller will perform the access as if it were a processor access. When COTRN- is asserted without MRQ- the controller will process the access as if it were an I/O access.

RNI- is asserted by the processor card to signify that the current memory access is the fetch of an instruction. This line is used on the controller to aid in recognizing the mapping control instructions used by the controller.

IAK- is asserted by the processor to acknowledge an interrupt. This signal has the effect of resetting the controller's mapping state machines to an unmapped, physical state. This allows the processor to execute the interrupt service routine program which resides in physical memory. CRS-, control reset, is driven by the processor to hard reset the I/O system. This line also has the effect of resetting the controller's mapping state machines to an unmapped, physical state.

STATUS LINES (PS-, MP+, PON+, PE-, MLOST-)

These five lines are backplane status lines. PS- indicates the current sense of the parity system. When PS- is deasserted (high), the controller will generate and store odd parity. When asserted (low), the controller will generate and store even parity.

MP+ is asserted by the processor to indicate that the memory protect fence within the processor card is enabled. This line, when enabled, is used by the controller to prevent a cross store instruction from writing data into main memory or into the controllers map RAMS. This prevents a user's mapped program from destroying system memory or the system maps.

PON+ is driven high by the power supply when the backplane voltages are within specification. This line is used as a clear line on the memory controller. When deasserted, this line causes a hard clear of all the non-refresh logic on the controller, and allows only refresh cycles to occur on the memory cards. No memory requests will be serviced while the PON+ line is low.

PE- is the parity error line on the backplane. The memory controller asserts this line if a parity error is detected during a read cycle. See section 8.2.6 for more details.

MLOST- is an open collector line driven low by the controller card, the processor card, or the battery backup card when the system is not configured to sustain battery backup voltages on a power outage. This line indicates to the processor on a power-up whether the memory voltages have been sustained, thereby preserving the contents of main memory. When the BATTERY backup/NORMAL switch on the controller card is set to NORMAL, the MLOST- line is asserted (grounded) to indicate that memory will be lost if power is interrupted. When the battery switch is set to BATTERY backup, the state of the MLOST- line is determined by the processor and battery backup cards.

8.3.2 MEMORY TIMING AND CONTROL LOGIC

The memory timing and control logic provides the interface between the backplane signals and the main memory dynamic RAM chips. This logic generates the signals required to 1) control the access and refresh of the dynamic RAMs, 2) supply the correct backplane handshake signals, and 3) provide the frontplane control signals.

In a typical memory access the first function of the controller after receiving MEMGO- is to assert BUSY- on the backplane to prevent other devices from requesting memory cycles. One FCLK period later, the control logic latches the backplane address bus, extended address bus, and the data bus into S/LS373 transparent latches. The parity generator circuitry, composed primarily of two S280s, uses the backplane data bus to generate a parity check bit. This check bit is also clocked into a flip-flop at the same time and then routed to the parity RAMs for storage.

The control circuitry presents the lower bits of the address to all the RAMs in the memory system. A small delay is then required for the mapping logic to generate the upper bits of the physical address. The control logic decodes the upper address bits to determine which one row of RAMs on which memory card will be accessed. This selected row then receives a row address strobe (RAS) signal and a column address strobe (CAS) signal. On a write cycle the latched data bus is presented to the RAMs and the RAM write line is asserted. The data is then written into the addressed memory location. On a read cycle the RAM write line is not asserted and the data stored in the addressed RAMs is read.

The control circuitry enables the backplane data bus drivers on memory read cycles, and the requested data is then driven on the system backplane. The parity circuitry checks the parity of the data against the stored parity bit. On a miscompare, the PE- line will be asserted signaling a parity error, and the parity LED circuit will set and turn off the LED.

VALID- is asserted on the backplane on all memory accesses to signal the end of the cycle. BUSY- and VALID- are then both deasserted enabling further memory accesses.

The control logic also manages the sequencing of refresh signals to the RAMs. When refresh cycles and memory cycles coincide, this logic arbitrates the

cycles allowing one to complete before starting the other. During a refresh cycle the correct row refresh address is presented to the RAMs and a "RAS only" cycle is initiated.

8.3.3 MEMORY REFRESH LOGIC

The main memory on the XL controller and XL array boards use dynamic Random Access Memory chips. These dynamic RAMs require periodic refreshing to ensure data retention. The XL controller arbitrates conflicts between refresh cycles and memory access cycles and initiates the refreshing of all memory in the system.

The controller card contains the primary refresh counter which is used to count RCLK cycles on the backplane. When 68 RCLK cycles have occurred, the counter indicates to the control logic that a refresh cycle is needed. This allows all memory to be refreshed within the required period.

During a refresh cycle, the control logic on each card presents a refresh address to the RAMs and a "RAS only" cycle occurs. This cycle refreshes one row of memory within the RAM chips. At the completion of the cycle, the refresh address counter is incremented by one to prepare for the next refresh cycle. All 128 rows (or 256 rows on the 12002B) of the RAM are guaranteed to be refreshed in a period of 2 milliseconds (or 4 milliseconds on the 12002B).

Memory accesses can occur asynchronously with respect to refresh cycles. An uninhibited refresh cycle requires 2 SCLK periods to complete. When a refresh cycle is required at the same time a memory access is requested, the refresh cycle occurs first immediately followed by the memory cycle. Logic on the controller card latches the necessary backplane information needed to do the memory access, and starts the backplane handshake signals. The actual access occurs after the refresh cycle completes. From the backplane this memory cycle appears to take 5 SCLK periods; two for the refresh and three for the memory access.

When a memory cycle is requested during the second half of a refresh cycle, the necessary backplane information is latched and the memory cycle is started when the refresh cycle completes. This memory cycle takes 4 SCLK cycles to complete.

When a refresh cycle is requested during a memory cycle, the refresh cycle is postponed until the third cycle of the memory access. The first cycle of the refresh is overlaid on the third cycle of the memory access to reduce the potential interference between memory cycles and refresh cycles. This allows an effective one-cycle refresh cycle during heavy memory accessing. A memory cycle is not lengthened when a refresh is requested during a memory cycle, and requires its normal 3 SCLK cycles to complete.

8.3.4 MEMORY MAPPING OPERATION

The mapping circuitry on the XL memory controller contains the logic necessary to extend the address range of the L-Series computer from 32K words (available on the 12004A) to 256K words. To achieve this addressing capability requires an address bus width of 18 bits. To generate an 18-bit address, the XL controller performs an address mapping. The 18-bit memory address is only available on the frontplane connector of the XL memory cards and not on the computer backplane.

The controller card logic contains the map RAMs used in extending the addressing range of the system. There are 32 map locations (processor maps) used when the processor is accessing memory, and 32 map locations (Relocation Registers) used when the I/O cards are accessing memory. These map RAMs are 'memory mapped' in the computers address space. Memory locations 100-137 address the 32 processor maps, and locations 140-177 address the 32 I/O Relocation Registers. The map RAMs contain a copy of the lower 8 bits of memory locations 100-177. When a write is performed to main memory at locations 100-177 a copy of the data is also stored into the map RAMs. This data is then used in generating the 18-bit address used in the XL memory.

The XL controller has four separate methods of generating an 18-bit address: two methods for processor memory accesses, and two methods for I/O accesses. The controller logic senses the state of MRQ- on the backplane to determine whether the access is initiated by the processor card or by an I/O card.

All processor accesses, although identical on the backplane, occur when the XL controller is operating in one of two modes: physical (unmapped) or logical (mapped). The mode used for processor accesses is controlled by logic on the controller card. This logic recognizes and executes backplane instructions which instruct the control logic when to operate in physical or logical mode. All processor memory accesses while the controller is in physical mode allow the processor to access the lowest 32K words of physical memory only. Processor memory accesses while the controller is in logical mode allow the processor to access 32K words of memory. The location of this logical memory in physical memory is determined by the contents of the map RAMs on the controller card.

When the controller is operating in physical mode the 18-bit address is obtained by appending three "0" bits to the front of the 15-bit backplane address. This allows access to the lowest 32K words in main memory.

When the controller is operating in the logical mode the controller's map RAMs help determine the 18-bit address. Main memory locations 100-137 are reserved for the processor maps. The map RAMs on the controller contain a copy of the lower 8 bits of these 32 locations. Each of the 32 map locations corresponds to a 1K word block in logical memory.

The map at location 100 corresponds to the first 1K of logical program memory. The map location at 137 corresponds to the last 1K of logical program memory. The physical memory which responds to a logical address is determined by the contents of the corresponding map location. The map at location 100 points to the 1K page of physical memory that will respond to logical addresses in the range 00000-01777, or the first 1K page of logical program memory. The map at location 101 points to the 1K page of physical memory that will respond to the logical address in the range 02000-03777, or the second page of logical program memory, etc.

The 18-bit address is generated by mapping the 5 most significant bits of the backplane address (A10-A14) into the controller's map RAMs. These address bits select one location of the map RAMs which produces an 8-bit output. These 8 bits determine which page in the entire memory will respond to that page of logical address. The 8 bits from the map RAMs are appended to the low 10 bits of the backplane address (A0-A9) to produce the required 18-bits. Figure 8-4 shows how this address is generated.

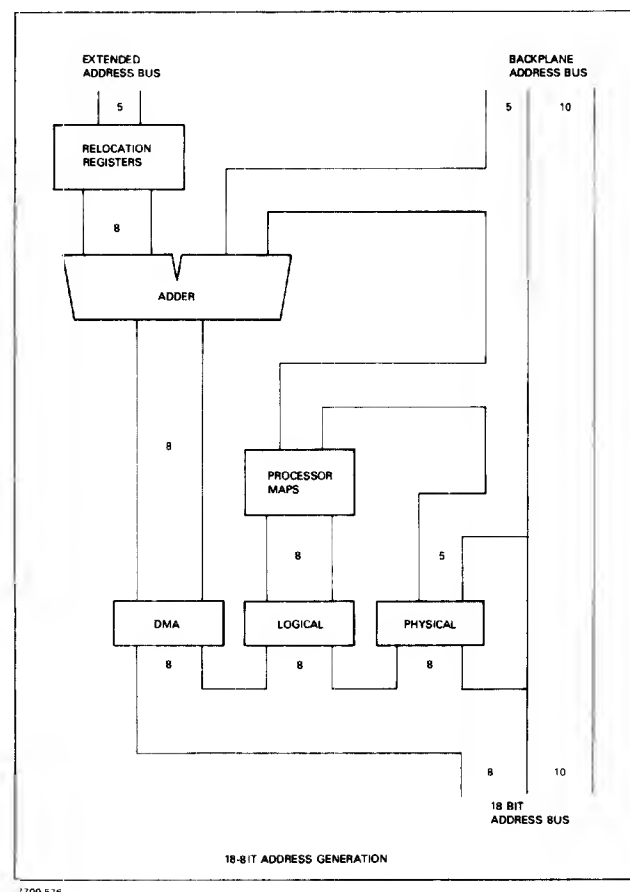


Figure 8-4. Methods Of Address Generation

The controller card contains three state machines which determine the mode of operation, and therefore, which method to use for generating an 18-bit address for processor accesses. Logic on the controller card recognizes instructions to control these state machines. There are six mapping control instructions that are recognized by the XL controller logic in order to determine the state of mapping for processor accesses. They are:

- 1- STC 11 enable logical mode after the completion of the next JMP instruction
- 2- CLC 11 enable physical mode after the completion of the next JMP instruction
- 3- CLC 13 immediately invoke an override of logical mode and force operation in physical mode
- 4- STC 13 immediately suspend the override of logical mode and resume operation in the mode defined by 1 and 2 above
- 5- XST temporarily toggle the state of mapping to perform a cross store instruction (XST 104413)
- 6- XLD temporarily toggle the state of mapping to perform a cross load instruction (XLD 104213)

In addition to the above mapping control instructions, the state of mapping is also affected by the backplane signals PON+, IAK-, and CRS-. When IAK- or CRS- are asserted or when PON+ is deasserted the state machines are immediately reset to an unmapped, physical state.

The cross load and cross store instructions are interpreted by the processor to be double load and double store instructions (DLD, DST). A memory controller state machine determines when to toggle the state of mapping to allow the load or store to occur in the alternate state. Only the A-register is cross loaded or cross stored before the state of mapping is returned to its original state. No indirect addresses are allowed in the DEF for these two instructions unless the indirect is through either the A or B register which then contains a direct address.

I/O accesses to memory occur through two mechanisms on the XL controller. The access is either to physical memory, which accesses the lowest 32K words of main memory only, or the access is to main memory relative to an offset or Relocation Register.

The L-Series I/O cards have the capability of driving the backplane extended address bus (SC0-SC4). This bus is actively driven by an I/O card during all I/O accesses to main memory.

I/O accesses to physical memory occur when either the Self Configure bit

(SC5-) is asserted or when an I/O card drives the extended address bus all low during an access. The exact location in physical memory is then determined directly by the backplane address bus. The 18-bit address is obtained by appending three '0' bits to the front of the backplane address as is done for processor accesses to physical memory. This allows access to the lowest 32K words of memory.

Accesses to memory relative to a Relocation Register occur when neither of the above two conditions are met. To generate an 18-bit address, the XL controller uses the extended address bus (SC0-SC4) to determine which Relocation Register to use for the I/O transfer. The 32 Relocation Registers are located in main memory locations 140-177. The Relocation Register at location 141 is selected when the extended address bus is 01. The Relocation Register at location 177 is selected when the extended address bus is 37. The Relocation Registers are 8 bits wide and point to a page boundary in main memory. The specific page is determined by the contents of the Relocation Register. If a Relocation Register contains 000 it will point to the lowest page in memory. If the Relocation Register contains 377 it will point to the highest page in memory.

The Relocation Register is used as a base pointer from which the I/O card has access to the next higher 32K words. The exact page in memory to be accessed is determined by adding the five most significant bits of the backplane address bus (A10-A14) to the 8-bit Relocation Register. The entire 18-bit address is then generated by appending these 8 bits to the 10 least significant bits of the backplane address bus. Figure 8-4 shows the generation of this address.

A method exists in the XL controller logic to allow I/O accesses which are accompanied by the assertion of SC5- to select a Relocation Register for use in the transfer and not to be forced to access only physical memory. This capability is provided as a diagnostic aid to assist in testing the operation of the memory controller. The execution of a STC 13,C will mask off the effect of the SC5 line and allow I/O operating under diagnose mode-three to test the Relocation Register circuitry. The execution of either a STC 13 or a CLC 13 will reset this mask. The mask is also reset by IAK-, PON+, or CRS-.

The processor maps and I/O Relocation Registers are locations 100-177 in main memory. The map RAMs actually contain a copy of the lower 8 bits of these memory locations. The map RAMs at these locations can be written by the processor only when the controller is in the physical mode. Processor writes to locations 100-177 while the controller is in the logical mode will write to main memory but will not write to the map RAMs. Memory reads from locations 100-177 will always produce the data stored in main memory and not the data in the map RAMs. The data stored in the map RAMs is only used by the controller logic when determining the extended address bits. The map RAMs can also be written by an I/O card using Relocation Register 140 and addressing memory locations 100-177.

8.3.5 MAPPING CONTROL LOGIC

The mapping control logic on the XL controller centers around three PAL (programmable array logic) devices. Internally these devices are an AND-OR array of gates which are programmed to the required combinational logic patterns.

The first device, PAL14H4 (instruction decoder), monitors the backplane data bus and is programmed to recognize the seven instructions which control the state of mapping on the controller. These seven instructions are encoded on three of the PALs output lines and feed directly to the second device, PAL16R8. A portion of PAL14H4 assists in preventing a cross store instruction from writing data into memory when MP+ is enabled.

The second device, PAL16R8 (state machine), contains all of the state machines used to determine the state of mapping. This PAL has eight internal flip/flops which are fed by its AND-OR array. The inputs to this PAL are the three encoded instruction lines from the first PAL, two backplane data bus lines, and three control lines. The two data bus lines assist the state machines in resolving indirect addresses and in distinguishing the STC 13 and STC 13,C instructions. The three control lines 1) distinguish instructions from data, 2) distinguish processor accesses from I/O accesses, and 3) reset all the state machines.

The third device, PAL12L6 (address path enable), contains the logic to control and enable the correct address paths in determining the 18-bit address for physical, logical, and I/O accesses to memory. This PAL also determines when the map RAMs are being written into and controls the flow of data into them.

8.3.6 FRONTPLANE SIGNALS

A frontplane connector is used to connect the 12003A array cards to the 12002A controller. This connector carries the control signals and the 18-bit frontplane address required for expanded memory operation. A list of the signals on the frontplane connector is shown in Figure 8-5.

PIN	SIGNAL	SIGNAL	PIN
1	GND	GND	2
3	A10-	A11-	4
5	A12-	A13-	6
7	A14-	A15-	8
9	A16-	A17-	10
11	A18-	A19-	12
13	MIO	MO0	14
15	MI1	MO1	16
17	A0+	A1+	18
19	A2+	A3+	20
21	A4+	A5+	22
23	A6+	A7+	24
25	GND	GND	26
27	A8+	A9+	28
29	SPARE 1	SPARE 2	30
31	PAR-	RAS-	32
33	WRITE+	DRIVE-	34
35	MI2	MO2	36
37	MI3	MO3	38
39	LATCH+	CASEN-	40
41	PDSBL-	PCK-	42
43	COUNT+	XTND-	44
45	REF+	ACK-	46
47	+5V	+5V	48
49	GND	GND	50

Figure 8-5. Expanded Memory Frontplane Signals

These signals can be grouped into four types:

- address lines
- memory board configure lines
- control lines
- array board response lines

ADDRESS LINES (A0-A19)

The frontplane contains 20 dedicated address lines, the lower 18 of which are used by the XL controller. These lines determine which word of the 256K words in main memory is being accessed.

MEMORY BOARD CONFIGURE LINES (MIO-MI3,M00-M

These four chained lines are used by each array card to determine which position within the memory array the card occupies. This tells the array card to which 64K word block of address space it will respond. The 12002A controller card always responds to addresses representing the lowest 64K word block in memory. The M00-M03 lines driven by the controller tell the array card directly above the controller to respond to the second 64K word block. This array card adds to the M00-M03 count and passes it up to the next array card. Each array card uses the MIO-MI3 lines to determine its location in memory space, and uses the M00-M03 lines to tell the next higher card its position in memory space.

CONTROL LINES (PAR-,RAS-,WRITE+,DRIVE-,LATCH+,C

The eight control lines passed up the frontplane are generated on the XL controller card and used on both the controller card and all the array cards to control memory accessing and refreshing on each card. These lines are as follows:

1. LATCH- is the control signal used on all memory cards to latch the backplane address bus and data bus.
2. WRITE+ is asserted when the current memory access is a write cycle.
3. PAR- is the parity bit generated for the backplane data on a write cycle. This bit is stored into memory along with the data.
4. RAS- is a control line used to start the access of the memory RAMs on read, write and refresh cycles.
5. CASEN- is used to allow the memory to perform a complete memory access on memory reads and writes. This line is not enabled for refresh cycles.
6. DRIVE- controls the output data bus drive buffers. When asserted, the memory card containing the memory location being read will allow the data bus drivers on its card to drive the backplane.
7. REF+ is asserted during a memory refresh cycle.
8. COUNT+ signals the refresh row address counter to count to the next address.

RESPONSE LINES (PDSBL-,PCK-,XTND-,ACK-)

These four open collector lines are driven by the array card responding to the memory access. They are the following:

1. PCK- is the parity check bit of the addressed memory location. It is used by the controller to determine whether a parity error has occurred.
2. ACK- is driven by an array card to signal the controller that a memory card is responding to the address. If no ACK- is received, the controller will drive the backplane data bus.
3. XTND- and PDSBL- are for use by a ROM array card to extend the memory cycle (allowing for the use of slower access PROMs) and to disable the generation of a parity error by the controller card if no parity check bit is available.

8.3.7 ARRAY BOARD CONTROL AND TIMING LOGIC

The 12003A array board contains the logic to access and refresh the RAM array on the card. This logic uses the frontplane signals to direct the timing of the signals on the card.

Each array card latches the data from the backplane and drives the backplane data bus directly. The memory address is obtained from the frontplane connector. The address decoding circuitry determines whether the card is being accessed and which row of RAMS on the card corresponds to the address. If the card is to be accessed, the control logic will assert ACK- on the frontplane to tell the controller that an array card is responding to the memory location. The control logic then uses the frontplane signals to sequence the assertion of the row address strobe (RAS) and column address strobe (CAS) lines.

On write cycles the parity check bit is obtained over the frontplane connector and presented to the parity RAM. The backplane data bus is latched on the array card and presented to the data RAMs. On a read cycle the array card drives the backplane data bus directly. The parity check bit is read from the parity RAM and returned to the controller card for checking against backplane parity. If a parity error is detected, the array card will see PE- asserted on the backplane and will know that the access was from its array and will extinguish its parity LED.

8.4 DETAILED THEORY OF OPERATION

The following paragraphs contain the detailed theory of operation for the XL memory controller. Refer to the schematic diagrams (drawing numbers D-12002-90003-51, D-12002-90003-52, and D-12003-60001-51) located at the rear of this section as necessary. Figures 8-6A, 8-6B, and 8-6C are detailed timing diagrams including many of the signals discussed in this section.

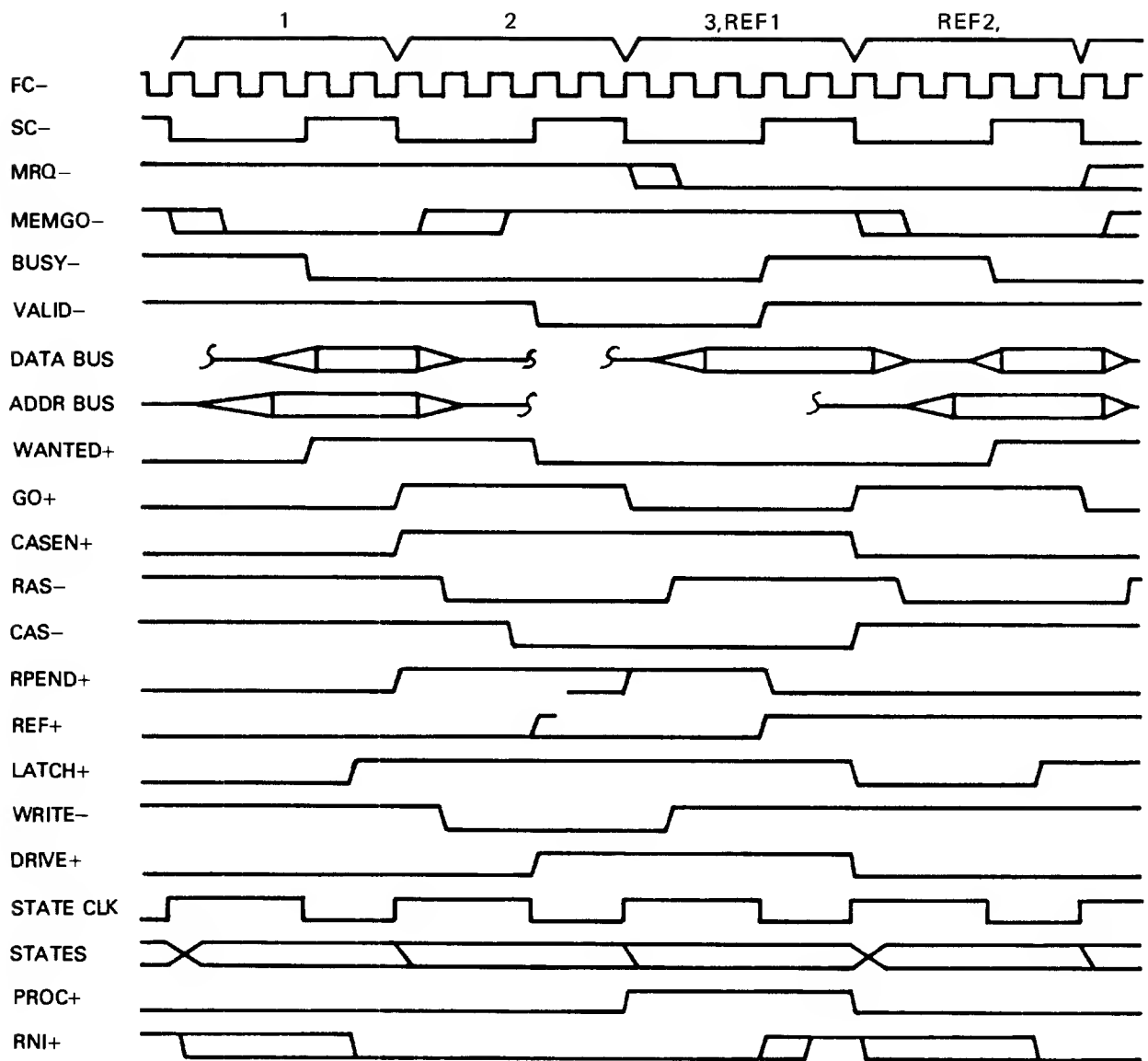


Figure 8-6A. Timing Diagram For 3-Cycle Access

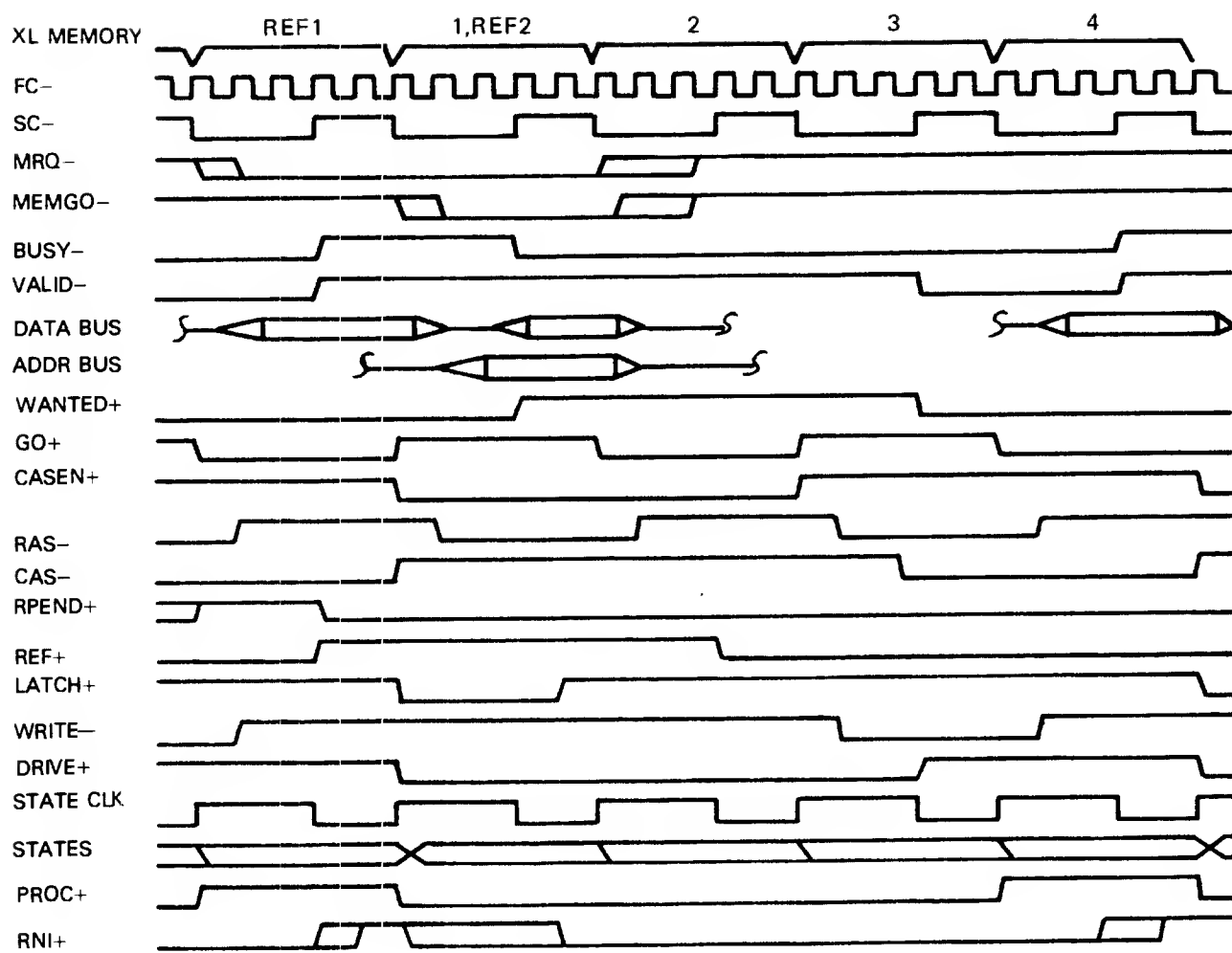


Figure 8-6B. Timing Diagram For 4-Cycle Access

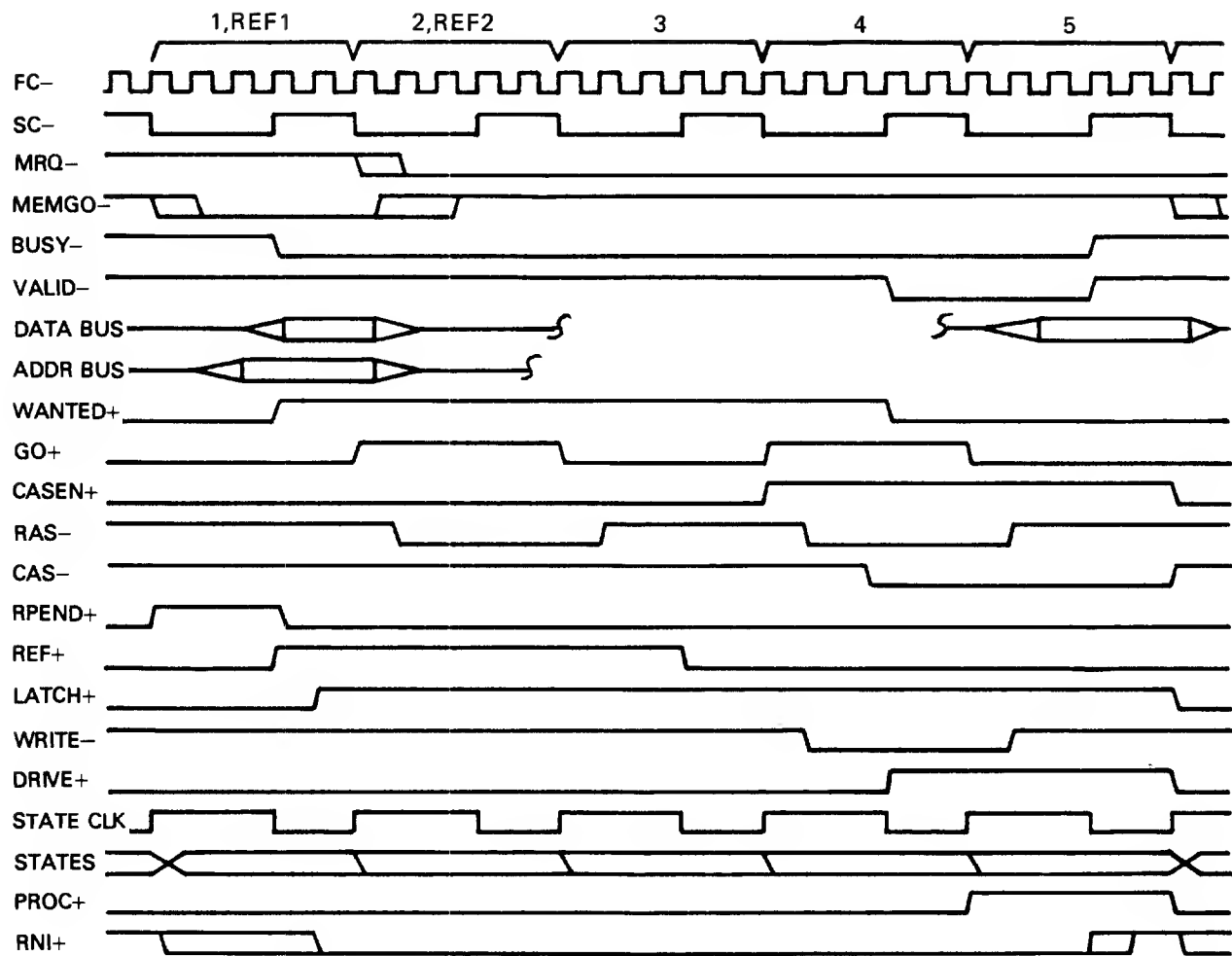


Figure 8-6C. Timing Diagram For 5-Cycle Access

8.4.1 MEMORY CONTROL LOGIC

To perform a memory access, the requesting device asserts MEMGO- on the backplane. On the XL controller card this signal is received at U719-12 where it is qualified with both MEMDIS- and REMEM- to ensure that main memory access is requested.

If the conditions are met at the falling edge of SCLK+ the memory card will start a memory cycle. The WANTED flip-flop (U1119-9) becomes set to start the sequence of timing signals required for accessing the RAMs. At the same edge of SCLK+ the BUSY flip-flop (U718-9) also gets set and starts the backplane handshake sequence. The BUSY+ signal at U718-9 enables the S240 (U1019-1) to drive the backplane BUSY- line.

The WANTED+ signal performs four functions: 1) it inhibits a refresh cycle from occurring during the memory access by disabling gate U1118-10; 2) it enables the GO flip-flop (U818-9) to become set which will then allow the RAS control signal to reach the selected row of RAMs; 3) it enables the CASEN flip-flop (U618-5) to become set which will then allow the CAS control signal to reach the RAMs; 4) it qualifies the enabling of the backplane data bus drivers (U317-12).

When the BUSY flip-flop becomes set, it enables the LATCH flip-flop (U618-9) to set at the next falling edge of FCLK+. The LATCH signal is used by the controller and the array cards to latch the address bus, extended address bus, the WE- bit, and the data bus off the backplane. This signal is routed to the LS/S373 transparent latch gates which control the flow of the backplane buses. When LATCH+ is asserted the backplane information is frozen at the outputs of the latches. This signal also clocks the READ flip-flop (U117-9) which saves the read/write backplane signal WE-.

The GO+ signal is asserted for one SCLK period when either a memory access is requested or when a refresh cycle is required. The GO+ signal allows the RAS+ flip-flop (U818-5) to set. The RAS+ (Row Address Strobe) signal is also one SCLK period long and is interpreted by the RAMs to mean the row address bits at the RAMs address pins are now valid. The delay from the setting of the WANTED flip-flop to the setting of the RAS flip-flop is required to allow 1) the row address to become valid at the RAM address pins, and 2) to allow the decode logic to determine which one row of RAMs in the XL memory will receive a RAS pulse.

The 18-bit address generated by the mapping logic is presented to four gates on the controller: U21, U31, U7, and U310-6. Gate U310-6 receives the two most significant bits of the 18-bit address. These two bits are used to determine whether memory on the XL controller card or memory on one of the array cards is to be accessed. U310-6 will go low when both A16+ and A17+ are low. This enables the 12002A to respond to the lower 128 Kbytes in memory address space. When U310-6 is asserted the outputs of U7 will become active. Gate U7 is a 2-to-4 bit decoder. The two inputs (A14 and A15 on the 12002A)

determine which one row of RAMs on the card is to be accessed. The outputs of U7 are fed thru U9 and are presented to the RAS drivers, U10. During a memory access, only one of the drivers will be enabled to pass the RAS signal from the RAS flip-flop. When a refresh cycle occurs, the REF- line will enable all outputs of U9 and all the RAS drivers will be enabled allowing all RAMs to be refreshed.

On the 12002B the four jumpers, W1-W4, are loaded in their alternate positions marked as 64K. These jumpers direct the flow of the four most significant address bits A14-A17. Jumper W4 permanently enables the controller card to respond to all address locations by enabling U7. All main memory is contained on the 12002B controller card.

The CASEN flip-flop (U618-5) is allowed to set during all memory accesses, but is not allowed to set during a refresh cycle. The CASEN signal enables the CAS- (Column Address Strobe) signal to reach all the RAMs. This signal is interpreted by the RAMs to mean the column address bits at the RAMs address pins are now valid.

The CASEN- signal becomes inverted at U417-12 and then allows the CAS flip-flop (U218-9) to clock at the correct time as determined by the outputs of the delay line (U118). The delay line works with U819-8, U819-6, and the CAS flip-flop to allow the following sequence of events:

- 1) present the row address to the RAMs by enabling U21 (S240)
- 2) provide a RAS- pulse to the selected row of RAMs through U10 (S37)
- 3) present the column address to the RAMs by enabling U31 (S240)
- 4) provide a CAS- pulse to the RAMs through U6 (S37)

The CASEN flip-flop provides the signal to reset the WANTED flip-flop (through U918-11), and to set the VALID flip-flop. The VALID- signal is asserted on the backplane through U1019 (S240) for one SCLK period. The rising edge of VALID- signals the other cards in the backplane that the data bus is valid. The VALID and BUSY flip-flops both reset at the same time completing the memory handshake.

The backplane signal PON+ is used on the controller card to hold many of the flip-flops in a known state. When the backplane voltages are out of regulation, the power supply will drive PON+ low. This signal is inverted twice on the controller card (U1118-4 and U1019-9) and is used to reset flip-flops on the card. This puts the controller into a known state when power is first applied to the system backplane.

When the battery backup card is installed in the backplane, the +5M memory voltage will be powered by the battery card to sustain main memory. The switch, SW1, on the controller card should be positioned to the BATtery

position to allow the battery backup card to drive the +5V and +5M voltage lines separately.

When PON+ is deasserted under these conditions, the BPON+ signal on the controller will only allow refresh cycles to occur and will prevent any external cards from accessing memory by resetting the WANTED flip-flop (U1119-9). This retains memory for use when power is reapplied to the backplane.

8.4.2 MEMORY REFRESH LOGIC

To guarantee that memory is retained within the RAM chips a refresh cycle is required every 68 RCLK cycles. The primary refresh counter, LS390 (U1218), determines when a refresh cycle is required by counting RCLK edges received through U1118-13. When 68 cycles have occurred the output of U1219-8 goes high which clears the counter.

During each count cycle, the RPEND (refresh pending) flip-flop gets one clock pulse. The REF flip-flop (U1119-5) and the COUNT flip-flop (U919-5) then set at the first opportunity when there is not a memory access occurring. The REF and COUNT signals do the following: 1) allow U41 (LS240) to present the next refresh address to the RAMs; 2) allow U9 (S00) to enable RAS to occur to all RAMs; 3) allow the GO flip-flop (U818-9) to set thus allowing the RAS flip-flop (U818-5) to set generating a RAS- pulse to the RAMs; 4) prevent the CASEN flip-flop (U618-5) from setting; and 5) clock the refresh address counter U8 (LS373).

The refresh address counter (U8) determines which row of cells within the RAM chips is to be refreshed. This counter counts through all rows within the required 2 milliseconds.

Under normal operation a memory cycle takes three SCLK periods and a refresh cycle takes two periods. When both a refresh cycle and a memory access are requested during the same time, gates U1118-10 and U1118-1 determine the correct sequencing of the two operations.

Memory refresh cycles can coincide with memory access cycles in three situations. When refresh is required at the same edge of SCLK that a memory access is requested (REF+ flip-flop gets set at the same time as the WANTED flip-flop) the refresh cycle will occur first followed by the memory access. The refresh cycle will take two SCLK periods and the memory access will take three SCLK periods to give a total access time of five SCLK periods under this condition. The backplane handshake signal BUSY- will be asserted when the memory access is requested and will stay asserted through both the refresh cycle and the memory access. BUSY- is then asserted for two SCLK periods longer than a normal memory cycle (see Figure 8-6C).

When a refresh cycle is required one SCLK before a memory access, the memory access will start at the completion of the refresh cycle. A memory access under these conditions will take four SCLK periods to complete and BUSY- will

be asserted for one SCLK period longer than a normal memory cycle (see Figure 8-6B).

When a refresh cycle is required during a memory cycle, the memory cycle will complete as usual. The refresh cycle will start during the last SCLK period of the memory access and take two SCLK periods. The length of assertion of the BUSY- signal will not be affected in this case (see Figure 8-6A).

8.4.3 MAPPING CONTROL LOGIC

The mapping control logic includes the logic to recognize the specific mapping control instructions, determine the state of operation of the XL controller, and enable the correct address path for the specific memory access.

8.4.3.1 INSTRUCTION RECOGNITION LOGIC

To implement mapping, the XL controller recognizes instructions which determine the specific mode of operation. On the controller U317-8, U312-6, U318-13, and most of U315 (PAL14H4) monitor the backplane data bus for the specific mapping instructions. Three outputs of PAL14H4 contain an encoded version of the mapping instructions. Below is a table defining the output combinations for each instruction and a description of the function of each instruction.

<u>PAL14H4 OUTPUTS</u>			<u>INSTRUCTION</u>	
E2	E1	E0		
0	0	0	Any instruction other than those listed below	
0	0	1	JMP	
0	1	0	XLD	Used to cross load data from the alternate state
0	1	1	XST	Used to cross store data from the alternate state
1	0	0	STC 11	Used to enable operation in logical mode
1	0	1	CLC 11	Used to enable operation in physical mode
1	1	0	STC 13	Used to suspend the override of logical mode
1	1	1	CLC 13	Used to invoke an override of logical mode

Note that the distinction between STC 13 and STC 13,C is made in U215 (PAL16R8).

The three encoded outputs from PAL14H4 are fed directly to PAL16R8 (U215) and

are used to determine the next state of the state machines within PAL16R8.

8.4.3.2 MAPPING CONTROL STATE MACHINES

To implement the mapping functions, the XL controller contains four state machines to determine the mode of operation. The state machines reside within U215 (PAL16R8). This PAL contains an internal AND-OR gate array and eight internal flip-flops with a common clock (U215-1).

PAL16R8 has eight signal inputs:

PCYCLE+ (U215-3) is a line used to differentiate I/O memory accesses from processor memory accesses. This line is generated at U117-6 and is asserted for one SCLK period at the completion of a processor-initiated memory access.

RST- (U215-4) is a reset line to the state machines within the PAL. This line is asserted when either IAK- or CRS- are asserted or when PON+ is deasserted on the backplane. This line has the effect of immediately resetting all state machines within the PAL to an unmapped, physical state.

DB9+ (U215-9) is the backplane data bus line used to distinguish between the STC 13 and STC 13,C instructions.

RN1L+ (U215-8) is a latched version of the backplane RNI- (Read Next Instruction) signal which signifies that the current memory access is an instruction fetch.

E2, E1, E0 (U215-5,-6,-7) are the encoded version of the mapping instructions recognized by the controller.

DB15+ (U215-2) is a backplane data bus line used by the state machines to determine direct/indirect memory fetches and allows for the resolution of indirect addresses.

The first state machine within PAL16R8 uses outputs Y1-, Y2-, and Y3- (U215-15,-17,-18). This state machine determines the basic physical/logical operating mode of the controller from the STC 11 and CLC 11 instructions. Below is a table of the six states of this state machine.

PAL16R8			<u>STATE</u>	<u>STATE DESCRIPTION</u>
<u>Y1-</u>	<u>Y2-</u>	<u>Y3-</u>		
1	1	1	A	Physical mode, reset state
1	1	0	B	Received STC 11 (enable mapping) instruction, prepare to change to logical mode on next JMP
1	0	1	C	Received an indirect JMP instruction, stay in this state until the indirect is resolved
0	1	0	D	Logical mode, operating under mapped condition
0	1	1	E	Received CLC 11 (disable mapping) instruction, prepare to change to physical mode on next JMP
0	0	1	F	Received an indirect JMP instruction, stay in this state until the indirect is resolved

Note that output Y1- determines the actual mode of operation: Y1- is high for physical operation, Y1- is low for logical operation.

The second state machine within PAL16R8 uses outputs Y4-, Y5-, Y6- (U215-19,-14,-13). This state machine determines when to toggle the state of mapping for the cross store (XST) and cross load (XLD) instructions. The XST and XLD instructions are recognized by the processor to be double store (DST) and double load (DLD) instructions. The processor will load or store the A and B registers during these instructions. The controller card will only toggle the state of mapping for the first of the loads or stores (the A register). Thus, the XLD and XST instructions are a single single cross load or cross store.

Below is a table of the six states of this state machine and a description of each state.

PAL16R8			STATE	STATE DESCRIPTION
OUTPUTS				
Y4--	Y5--	Y6--		
1	1	1	A	Idle mode, waiting for instruction.
1	1	0	B	Received XLD instruction.
0	1	1	C	Have received one more processor memory access to get the DEF for the XLD instruction, can now toggle state of mapping.
1	0	1	D	Have cross loaded or cross stored the data from the A register into memory, can now return the state of mapping to previous state
1	0	0	E	Received XST instruction
0	0	0	F	Have received one more processor memory access to get the DEF for the XST instruction, can now toggle state of mapping.

Note that output Y4-- determines when to toggle the state of mapping.

To prevent the store of the B register into memory during a XST instruction (the second store of the double store instruction) a portion of PAL14H4 (U315) is used to prevent the memory from being written to. During state D, when the A register has been cross stored, WDSBL+ (U315-17) will be asserted to prevent the processor from writing into memory. Additionally, PAL14H4 will also prevent the XST instruction from writing the A register to memory if Memory Protect (MP+) on the backplane is asserted. This prevents a users program from cross storing data into restricted areas of memory. During states E and F PAL14H4 will assert the WDSBL+ line to prevent all cross stores when MP+ is asserted.

The third state machine within PAL16R8 uses output Y7- (U215-16). This state machine determines when to force operation in physical mode, overriding the mode determined by the first state machine. This state machine recognizes the STC 13 and CLC 13 instructions, and will assert the OVRD+ line as shown below.

PAL16R8		
<u>OUTPUTS</u>	<u>STATE</u>	<u>STATE DESCRIPTION</u>
Y7-		
0	A	Received STC 13 instruction or the RST signal, normal operating mode, no override in effect
1	B	Received CLC 13 instruction, override in effect, operation forced to be in physical mode

The fourth state machine within PAL16R8 uses output MASK+ (U215-12), and determines when to mask the effect of the Self-Configure bit (SC5-). The Self-Configure line will normally force I/O accesses to occur to physical memory and not to use a Relocation Register. If a STC 13,C is executed, the MASK+ line is asserted which will allow the I/O card to select a Relocation Register to use in the transfer and not be limited to physical memory only. This mode is reset by executing either a STC 13 or a CLC 13 instruction or by the RST line. This feature is included as a diagnostic aid to be used when operating under diagnose mode three.

<u>PAL16R8</u>		
<u>OUTPUTS</u>	<u>STATE</u>	<u>STATE DESCRIPTION</u>
<u>MASK+</u>		
0	A	Received STC 13, CLC 13 or RST signal, normal operating mode, no masking
1	B	Received STC 13,C instruction, mask of Self Configure bit in effect

8.4.3.3 ADDRESS PATH ENABLE LOGIC

The XL controller has three separate methods of generating the required 18-bit address; one method for physical addresses, one method for logical addresses, and another method for DMA accesses. In all cases the lower 10 bits of the backplane address bus are left unmodified.

During accesses to physical memory, the upper eight bits of the 18-bit address bus are generated by appending three "0" bits to the front of the five upper backplane address bits (A10-A14). This is accomplished by U44 (S240).

During processor accesses to logical memory, the upper eight bits are determined by the contents of the two map RAMs (U18 and U28) which are addressed by the upper five bits of the backplane address bus through U110. These map RAMs contain an 8-bit wide word which is appended to the lower 10 bits of the backplane address by U34 (S240) to generate the 18-bit address.

During I/O accesses to memory using a Relocation Register, the upper eight bits of the 18-bit address are generated by adding the 8-bit Relocation Register, stored in the map RAMs and selected by the extended address bus (U112), to the upper five bits of the backplane address bus (A10-A14). Adder chips U14 and U24 perform this addition and U11 (S240) enables the 8-bit result.

PAL12L6 (U115) is used to control the flow of the address paths on the controller card. The inputs to PAL12L6 are listed below:

1. DMACC+ (U115-12) is the line which indicates whether the access is from the processor card or from an I/O card.
2. WDSBL+ (U115-5) is asserted to disable a write to memory from occurring during a cross store instruction. The second store of the XST instruction is always disabled. The first write is disabled if MP+ is asserted on the backplane.
3. READL+ (U115-1) is a latched version of the backplane write enable (WE-) signal.
4. SELFC+ (U115-11) is the line indicating that the I/O access is a self-configure access and therefore accesses physical memory only.
5. RR140+ (U115-8) is a line indicating that an I/O card has selected Relocation Register 140 to use in the memory transfer. All transfers using this Relocation Register will be forced to access physical memory. This is to ensure that all code written for the L-Series computer using the 12004A memory card will be compatible with expanded memory.
6. LBUSY+ (U115-19) and RAS- (U115-6) are timing control signals which define the assertion window for some of the PAL outputs.
7. PHYS+ (U115-9) is the line which indicates whether the processor is operating in physical or logical mode.
8. U115-2, U115-7, U115-3, U115-4 are address lines which are used in deciding when a write to memory should also write to the controllers map RAMs (which are memory mapped at locations 100 - 177 in main memory).

The six outputs of PAL12L6 are described below:

1. LOGICAL- is a signal which enables the address paths required for an access to occur to logical mode. Asserted during a processor access in logical memory.
2. DMARR- is a signal which enables the address paths required for an access to occur to memory via a Relocation Register. Asserted during an I/O access when SELFC+ and RR140 are not asserted.
3. PHYSICAL- is a signal which enables the address paths required for an access to occur to physical memory. Asserted during a processor access in physical mode, or an I/O access when either SELFC+ or RR140+ is asserted.
4. MAPW- is a line which controls the writing of data into the map RAMs. It is asserted for a processor access in physical mode to locations 100-177 or an I/O access to physical memory 100-177.
5. MAPEN- is a line which enables U38 (LS244) to present the lower eight bits of the data bus to the map RAMs.

6. WRITE- is a line which is asserted during all I/O writes to memory and during all processor writes to memory that are not disabled by WDSBL+.

8.4.4 ARRAY CARD CONTROL LOGIC

The array card, 12003A, contains a subsection of the control logic on the controller card. The array card uses the frontplane signals generated on the controller card to direct operation of the array (see Figure 8-5).

The array card latches the backplane data bus directly off the backplane. The LATCH+ signal is directed to the LS373 transparent latches (U114, and U117). These latches drive the RAMs on the array card with the backplane data. The 18-bit address is available to the array card over the frontplane connector. The controller drives the address throughout the entire memory access so no latching is required on the array card. Buffers U107, U109, and U203 receive the address.

Each array card uses the upper two bits of the 18-bit address to determine whether it is being selected. The card compares these two bits against the M10-M13 address chained lines. The M10-M13 lines are driven by the memory card immediately below, and determine the address range the array card will respond to. Each array card uses an adder (U105) to alter the M10-M13 lines and sends out M00-M03 lines to the next higher array card. When a positive compare is made by gates U104 and U106, the BOARD+ line on the selected array card will be asserted and will enable the control signals to pass to the RAMs.

The RAS- line is received into U503 and is used to start the sequence of timing signals required to access the RAMs. The delay line (U502) and the flip-flop (U402-5) are used to generate the timing for the RAS and CAS signals to the RAMs.

A two-to-four decoder (U202) uses address lines A14 and A15 to determine which one row of RAMs on the card is to be accessed. The outputs of this gate are fed through U302 and enable one of the RAS drivers in U303.

If the access to the array card is a read, the frontplane DRIVE- signal will combine with the BOARD+ signal to enable the data bus drivers on the card (U113 and U116) to drive the backplane data bus with the requested data. The parity check bit stored with the data is returned over the frontplane through the open collector gate (U301-3) to the controller for checking against the parity of the backplane data bus parity.

REF+ and COUNT+ are used on the array card to enable the refreshing of the RAMs. Each array card contains a refresh counter which keeps track of the rows needing to be refreshed on each card. When a refresh is required the refresh address is presented to the RAMs through U110. The refresh counter is then updated for the next refresh cycle.

8.4.5 PARITY CIRCUITRY

Two S280 parity generator chips (U418 and U419) on the controller card are used to generate a parity bit on all write cycles and to check parity on all read cycles.

During write cycles, the S280s determine the backplane parity bit while the backplane data bus is still actively driven by the device performing the memory write. The parity bit, determined by EX-ORing the even sum outputs (U418-5 and U419-5) from the S280s, is clocked into the PARITY flip-flop (U218-5) with the LATCH+ signal. The parity bit is then presented to the parity RAMs for storage along with the data bits.

On a read cycle the S280s monitor the backplane data bus, which is driven by the XL memory. The parity of the backplane data bus is compared against the parity check bit available on U318-3. The parity of the backplane data should always be the same as the sense of the parity check bit. This is checked at the output of U519-3 (ERROR), which should always be low if no error has occurred. If an error occurs, the ERROR signal is gated on the backplane as PE- by U217-6, an open collector gate. This PE- signal will also turn off the parity LED on the controller card (through U1018-8, U310-8, and U310-11) if memory on the controller card was selected.

8.5 PARTS LOCATIONS

Parts locations for the extended memory cards are shown in figure 8-7 and in figure 8-8, where figure 8-7 is for the 12002A and 12002B cards and figure 8-8 is for the 12003A card.

8.6 PARTS LISTS

The parts lists for the cards are provided in tables 8-1 and 8-2, where table 8-1 is for the 12002A and 12002B and table 8-2 is for the 12003A. The 12002A and 12002B cards are identical except for the type of RAM; therefore, the same parts list is given for both with the RAM part number differences indicated.

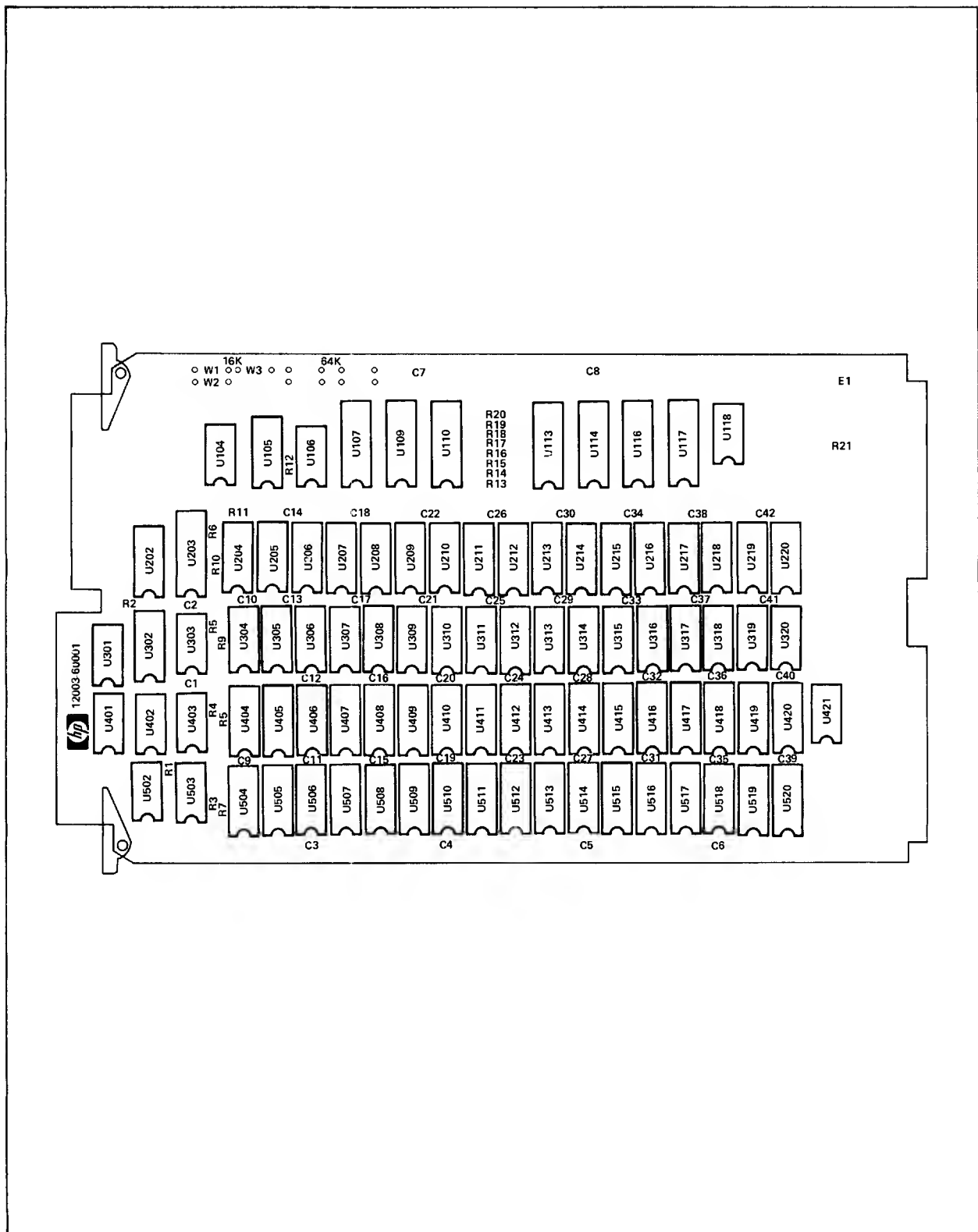


Figure 8-7. 12002A and 12002B Parts Locations

Table 8-1. 12002A and 12002B Memory Parts List (Continued)

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
	12002-60001	0	1	AUTO SEQUENCING ASSEMBLY	28480	12002-60001
C1	0160-4842	6	34	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C2	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C3	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C4	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C5	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C6	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C7	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C8	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C9	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C9	0180-0137	6		CAPACITOR-FXD 100UF+20% 10VDC TA	56289	150D107X0010R2
C10	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C10	0180-0393	6		CAPACITOR-FXD 39UF+10% 10VDC TA	56289	150D396X9010R2
C11	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C12	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C13	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C14	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C15	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C16	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C17	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C18	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C19	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C20	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C21	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C22	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C23	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C24	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C25	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C26	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C27	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C28	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C29	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C30	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C31	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C32	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C33	0160-4842	6		CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
C34	0160-4842	6	1	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
CR1	1990-0485	5		LED-VISIBLE LUM-INT=000UCD IF=30MA-MAX	28480	5082-4984
E1	0360-1682	0	2	TERMINAL-STUD SGL-TUR PRESS-MTG	28480	0360-1682
E2	0360-1682	0		TERMINAL-STUD SGL-TUR PRESS-MTG	28480	0360-1682
R1	0698-3447	4	13	RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R2	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R3	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R4	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R5	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R6	1810-0280	8	2	NETWORK-RES 10-SIP10.0K OHM X 9	01121	210A103
R7	1810-0280	8		NETWORK-RES 10-SIP10.0K OHM X 9	01121	210A103
R8	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R9	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R10	0757-0294	9		RESISTOR 17 8 1% .125W F TC=0+-100	19701	MF4C1/R-T0-17R8-F
R11	1810-0278	4	2	NETWORK-RES 10-SIP3.3K OHM X 9	01121	210A332
R12	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R13	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R14	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R15	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R16	0698-3447	4	1	RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R17	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R18	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R19	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R20	0683-2215	1		RESISTOR 220 5% .25W FC TC=0-400/+600	01121	CB2215
R21	0698-3435	0	1	RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R22	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R23	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R24	0698-3435	0		RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R25	0698-3447	4		RESISTOR 422 1% .125W F TC=0+-100	24546	C4-1/8-T0-422R-F
R26	0698-3435	0	1	RESISTOR 38 3 1% .125W F TC=0+-100	24546	C4-1/8-T0-38R3-F
R27	1810-0278	4		NETWORK-RES 10-SIP3.3K OHM X 9	01121	210A332
S1	3101-0642	5	1	SWITCH-SL DPDT MINTR 5A 125VAC/DC PC	28480	3101-0642
U6	1820-1450	7	2	IC BFR TTL S NAND QUAD 2-INP	01295	SN74S37N
U7	1820-1072	9		IC DCDR TTL S 2-T0-4-LINE DUAL 2-INP	01295	SN74S139N
U8	1820-1989	7		IC CNTR TTL LS BIN DUAL 4-BIT	07263	74LS393PC
U9	1820-0681	4		IC GATE TTL S NAND QUAD 2-INP	01295	SN74S00N
U10	1820-1450	7		IC BFR TTL S NAND QUAD 2-INP	01295	SN74S37N

Table 8-1. 12002A and 12002B Memory Parts List (Continued)

Reference Designation	HP Part Number	C	Qty	Description	Mfr Code	Mfr Part Number
U11	1820-1633	8	6	IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U14	1820-1871	6	2	IC ADDR TTL S BIN FULL ADDR 4-BIT	01295	SN74S283N
U18	5180-0126	E	2	IC-MAPPER	28480	5180-0126
U21	1820-1633	8		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U24	1820-1871	6		IC ADDR TTL S BIN FULL ADDR 4-BIT	01295	SN74S283N
U28	5180-0126	E		IC-MAPPER	28480	5180-0126
U31	1820-1633	E		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U34	1820-1633	E		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U38	1820-2024	3	1	IC DRVR TTL LS LINE DRVR OCTL	01295	SN74LS244N
U41	1820-1917	1	1	IC BFR TTL LS LINE DRVR OCTL	01295	SN74LS240N
U44	1820-1633	E		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U48	1820-2102	E	3	IC LCH TTL LS D-TYPE OCTL	01295	SN74LS373N
U51	1810-0533	4	1	NETWORK-RES 16-DIP33 0 OHM X 8	28480	1810-0533
U61						
U62						
U63						
U64						
U65						
U66						
U67						
U68						
U69						
U81						
U82						
U83						
U84						
U85						
U86						
U87						
U88						
U89						
U101						
U102						
U103						
U104						
U105						
U106						
U107						
U108						
U109						
U110	1820-1641	8	2	IC DRVR TTL LS BUS DRVR HEX 1-INP	01295	SN74LS365AN
U112	1820-1676	6	2	IC LCH TTL S D-TYPE OCTL	01295	SN74S373N
U115	5180-0128	1	1		28480	5180-0128
U117	1820-1112	8	2	IC FF TTL LS D-TYPE POS-EDGE-TRIG	01295	SN74LS74AN
U118	1813-0199	4	1		28480	1813-0199
U119	1820-1206	1	1	IC GATE TTL LS NOR TPL 3-INP	01295	SN74LS27N
U121						
U122						
U123						
U124						
U125						
U126						
U127						
U128						
U129						
U210	1820-1641	8		IC DRVR TTL LS BUS DRVR HEX 1-INP	01295	SN74LS365AN
U212	1820-0683	6	2	IC INV TTL S HEX 1-INP	01295	SN74S04N
U215	5180-0129	1	1	IC-STATE MACH	28480	5180-0129
U217	1820-0689	2	1	IC GATE TTL S NAND DUAL 4-INP	01295	SN74S22N
U218	1820-0693	0	1	IC FF TTL S D-TYPE POS-EDGE-TRIG	01295	SN74S74N
U219	1820-2102	8		IC LCH TTL LS D-TYPE OCTL	01295	SN74LS373N
U310	1820-0681	4		IC GATE TTL S NAND QUAD 2-INP	01295	SN74S00N
U312	1820-1275	4	1	IC GATE TTL S NOR DUAL 5-INP	01295	SN74S260N
U315	5180-0127	9	1	IC-INST ENC	28480	5180-0127
U317	1820-0685	8	1	IC GATE TTL S NAND TPL 3-INP	01295	SN74S10N
U318	1820-1322	2	2	IC GATE TTL S NOR QUAD 2-INP	01295	SN74S02N
U319	1820-1676	9		IC LCH TTL S D-TYPE OCTL	01295	SN74S373N
U410	1820-1624	7	2	IC BFR TTL S OCTL 1-INP	01295	SN74S241N
U412	1820-2102	8		IC LCH TTL LS D-TYPE OCTL	01295	SN74LS373N
U415	1820-1624	7		IC BFR TTL S OCTL 1-INP	01295	SN74S241N
U417	1820-0683	9		IC INV TTL S HEX 1-INP	01295	SN74S04N
U418	1820-1638	3	2	IC GEN TTL S PAR GEN 9-BIT	01295	SN74S280N
U419	1820-1638	3		IC GEN TTL S PAR GEN 9-BIT	01295	SN74S280N
U502	1813-0189	2	1	IC MISC TTL S	0791F	HY-5002
U519	1820-0694	9	1	IC GATE TTL S EXCL-OR QUAD 2-INP	01295	SN74S86N

Table 8-1. 12002A and 12002B Memory Parts List

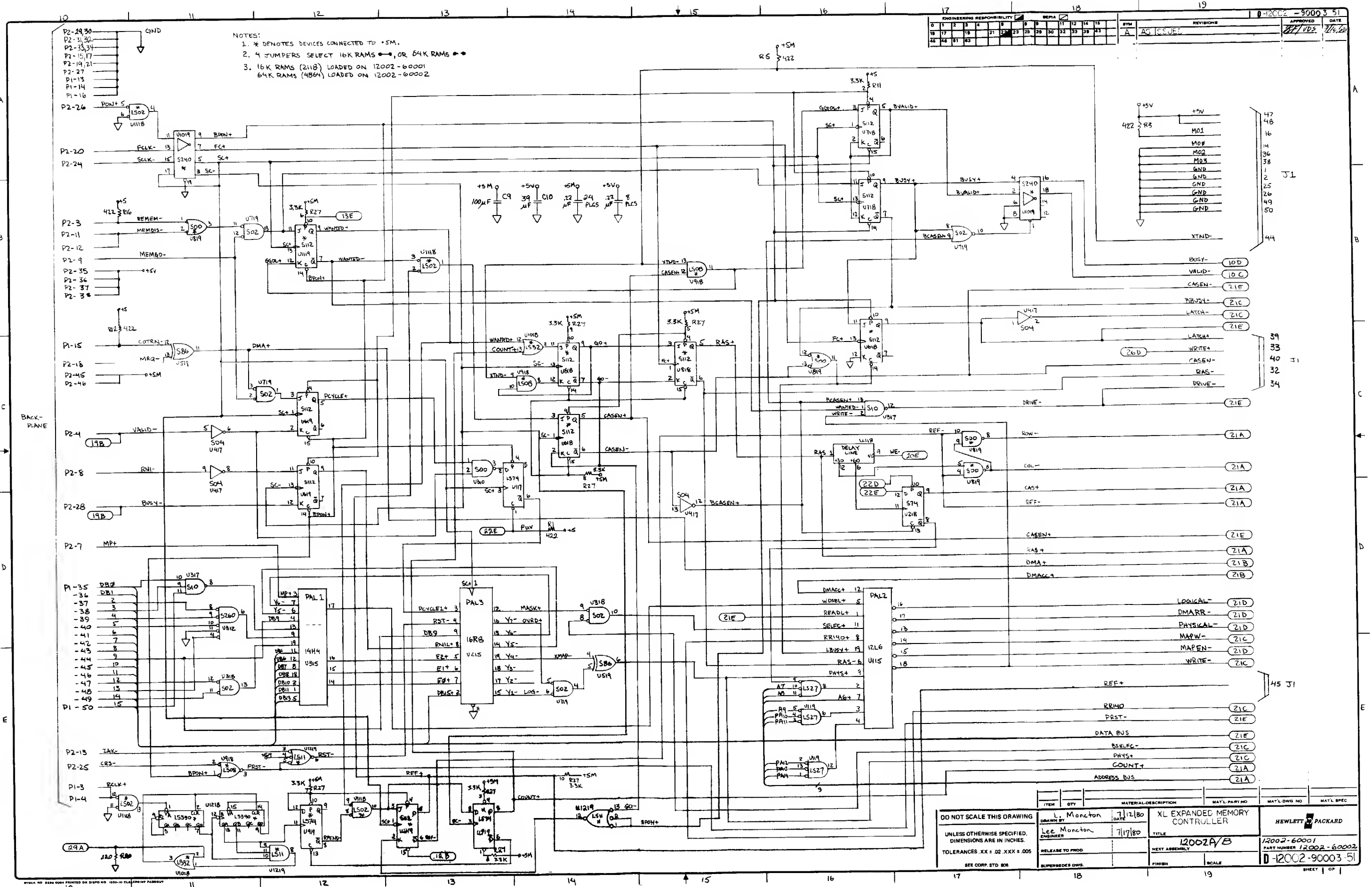
Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
U610 U611 U612 U613 U614	*					
U615 U616 U617	*					
U618 U619	1820-0629	0	5	IC FF TTL 5 J-K NEG-EDGE-TRIG	01295	5N74S112N
	1820-0629	0		IC FF TTL 5 J-K NEG-EDGE-TRIG	01295	5N74S112N
U718 U719 U810 U811 U812	1820-0629	0		IC FF TTL 5 J-K NEG-EDGE-TRIG	01295	5N74S112N
	1820-1322	2		IC GATE TTL 5 NOR QUAD 2-INP	01295	5N74S02N
	*					
U813 U814 U815 U816 U817	*					
U818 U819 U918 U919 U1010	1820-0629	0		IC FF TTL 5 J-K NEG-EDGE-TRIG	01295	5N74S112N
	1820-0681	4		IC GATE TTL 5 NAND QUAD 2-INP	01295	5N74S00N
	1820-1201	6	1	IC GATE TTL 5 AND QUAD 2-INP	01295	5N74LS08N
	1820-1112	8		IC FF TTL 5 D-TYPE POS-EDGE-TRIG	01295	5N74LS74AN
	*					
U1011 U1012 U1013 U1014 U1015	*					
U1016 U1017 U1018 U1019 U1118	1820-1208	3	1	IC GATE TTL 5 OR QUAD 2-INP	01295	5N74LS32N
	1820-1633	8		IC BFR TTL 5 INV OCTL 1-INP	01295	5N74S240N
	1820-1144	6	1	IC GATE TTL 5 NOR QUAD 2-INP	01295	5N74LS02N
U1119 U1210 U1211 U1212 U1213	1820-0629	0		IC FF TTL 5 J-K NEG-EDGE-TRIG	01295	5N74S112N
	*					
U1214 U1215 U1216 U1217 U1218	*					
	1820-1991	1	1	IC CNTR TTL 5 DECD DUAL 4-BIT	01295	5N74LS390N
U1219	1820-1203	8	1	IC GATE TTL 5 AND TPL 3-INP	01295	5N74LS11N
W1 W2 W3 W4	8159-0005	0	4	WIRE 22AWG W PVC 1X22 80C	28480	8159-0005
	8159-0005	0		WIRE 22AWG W PVC 1X22 80C	28480	8159-0005
	8159-0005	0		WIRE 22AWG W PVC 1X22 80C	28480	8159-0005
	8159-0005	0		WIRE 22AWG W PVC 1X22 80C	28480	8159-0005
	0403-0289	3	2	EXTR-PC BD RED POLYC .063-BD-THKNS	28480	0403-0289
	7120-6830	9	1	LABEL-USA	28480	7120-6830
	*		68			
	1480-0116	8	2	PIN-GRV .062-IN-DIA .25-IN-LG STL	28480	1480-0116
<p>* The 12002A (part no. 12002-60001) and 12002B (part no. 12002-60002) are identical except for the IC parts in the above lists which are described with the asterisk (*) footnote reference. These IC parts are as follows:</p> <p>12002A: HP Part Number 5180-0121, Qty = 68</p> <p>12002B: HP Part Number 5180-0133, Qty = 68</p>						

Table 8-2. 12003A Memory Parts List

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
A2	12003-60001	1	1	PCA-XL MEMO	20480	12003-60001
C1						
C8	0180 0374	3	8	CAPACITOR-FXD 100F+-10% 20VDC TA	56189	150D106X9020D2
C9						
C42	0160-4842	6	34	CAPACITOR-FXD .22UF +80-20% 50VDC CER	28480	0160-4842
CR1	1990-0485	5	1	LED-VISIBLE LUM-INT=000UCD IF=30MA-MAX	28480	5082-4984
R1	1810-0277	3	2	NETWORK-RES 10-SIP2.2K OHM X 9	01121	210A222
R2	0698-3447	4	1	RESISTOR 422 1% .125W F TC=0+100	24546	C4-1/8-T0-422R-F
R3						
R6	0757-0316	6	4	RESISTOR 42.2 1% .125W F TC=0+100	24546	C4-1/8-T0-42R2-F
R7						
R10	0698-3435	8	4	RESISTOR 38.3 1% .125W F TC=0+100	24546	C4-1/8-T0-38R3-F
R11	0757-0294	9	9	RESISTOR 17.0 1% .125W F TC=0+100	19701	MF401/8-T0-17R8-F
R12	1810-0277	3		NETWORK RES 10-SIP2.2K OHM X 9	01121	210A222
R13						
R20	0757-0294	9		RESISTOR 17.0 1% .125W F TC=0+100	19701	MF401/8-T0-17R8-F
R21	0603-2215	1	1	RESISTOR 320 5% .125W FC TC=-400/+600	01121	CB2215
U104	1820-0694	9	1	IC GATE TTL S EXCL-OR QUAD 2-INP	01295	SN74S86N
U105	1820-1441	6	1	IC ADDR TTL LS BIN FULL ADDR 4 BIT	01295	SN74LS203N
U106	1820-0691	6	1	IC GATE TTL S AND-OR-INV	01295	SN74S64N
U107	1820-1633	8	3	IC DFR TTL S INV OCTL 1-INP	01295	SN74S240N
U109	1820-1633	8		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U110	1820-1517	1	1	IC BFR TTL LS LINE DRVR OCTL	01295	SN74LS240N
U113	1820-1624	7	2	IC BFR TTL LS OCTL 1-INP	01295	SN74S241N
U114	1820-2102	8	2	IC LCH TTL LS D-TYPE OCTL	01295	SN74LS373N
U116	1820-1624	7		IC DFR TTL S OCTL 1-INP	01295	SN74S241N
U117	1820-2102	8		IC LCH TTL LS D-TYPE OCTL	01295	SN74LS373N
U118	1820-1989	7	1	IC CNTR TTL LS DIN DUAL 4-BIT	07263	74LS393PC
U202	1820-1072	9	1	IC DCDR TTL S 2 TO 4-LINE DUAL 2-INP	01295	SN74S139N
U203	1820-1633	8		IC BFR TTL S INV OCTL 1-INP	01295	SN74S240N
U204	5180-0121	3	60		28480	5180-0121
U205	5180-0121	3			28480	5180-0121
U206	5180-0121	3			28480	5180-0121
U207	5180-0121	3			28480	5180-0121
U208	5180-0121	3			28480	5180-0121
U209	5180-0121	3			28480	5180-0121
U210	5180-0121	3			28480	5180-0121
U211	5180-0121	3			28480	5180-0121
U212	5180-0121	3			28480	5180-0121
U213	5180-0121	3			28480	5180-0121
U214	5180-0121	3			28480	5180-0121
U215	5180-0121	3			28480	5180-0121
U216	5180-0121	3			28480	5180-0121
U217	5180-0121	3			28480	5180-0121
U218	5180-0121	3			28480	5180-0121
U219	5180-0121	3			28480	5180-0121
U220	5180-0121	3			28480	5180-0121
U301	1820-0682	5	1	IC GATE TTL S NAND QUAD 2-INP	01295	SN74S03N
U302	1820-1015	8	1	IC MUXR/DATA-SLU TTL S 2 TO 1-LINE QUAD	01295	SN74S158N
U303	1820-1450	7	2	IC DFR TTL S NAND QUAD 2-INP	01295	SN74S37N
U304	5180-0121	3			28480	5180-0121
U305	5180-0121	3			28480	5180-0121
U306	5180-0121	3			28480	5180-0121
U307	5180-0121	3			28480	5180-0121
U308	5180-0121	3			28480	5180-0121
U309	5180-0121	3			28480	5180-0121
U310	5180-0121	3			28480	5180-0121
U311	5180-0121	3			28480	5180-0121
U312	5180-0121	3			28480	5180-0121
U313	5180-0121	3			28480	5180-0121
U314	5180-0121	3			28480	5180-0121
U315	5180-0121	3			28480	5180-0121
U316	5180-0121	3			28480	5180-0121
U317	5180-0121	3			28480	5180-0121
U318	5180-0121	3			28480	5180-0121
U319	5180-0121	3			28480	5180-0121
U320	5180-0121	3			28480	5180-0121
U401	1820-1197	9	1	IC GATE TTL LS NAND QUAD 2-INP	01295	SN74S00N
U402	1820-0693	8	1	IC FF TTL S D-TYPE POS EDGE-TRIG	01295	SN74S74N
U403	1820-1450	7		IC BFR TTL S NAND QUAD 2-INP	01295	SN74S37N
U404	5180-0121	3			28480	5180-0121
U405	5180-0121	3			28480	5180-0121

Table 8-2. 12003A Memory Parts List (Continued)

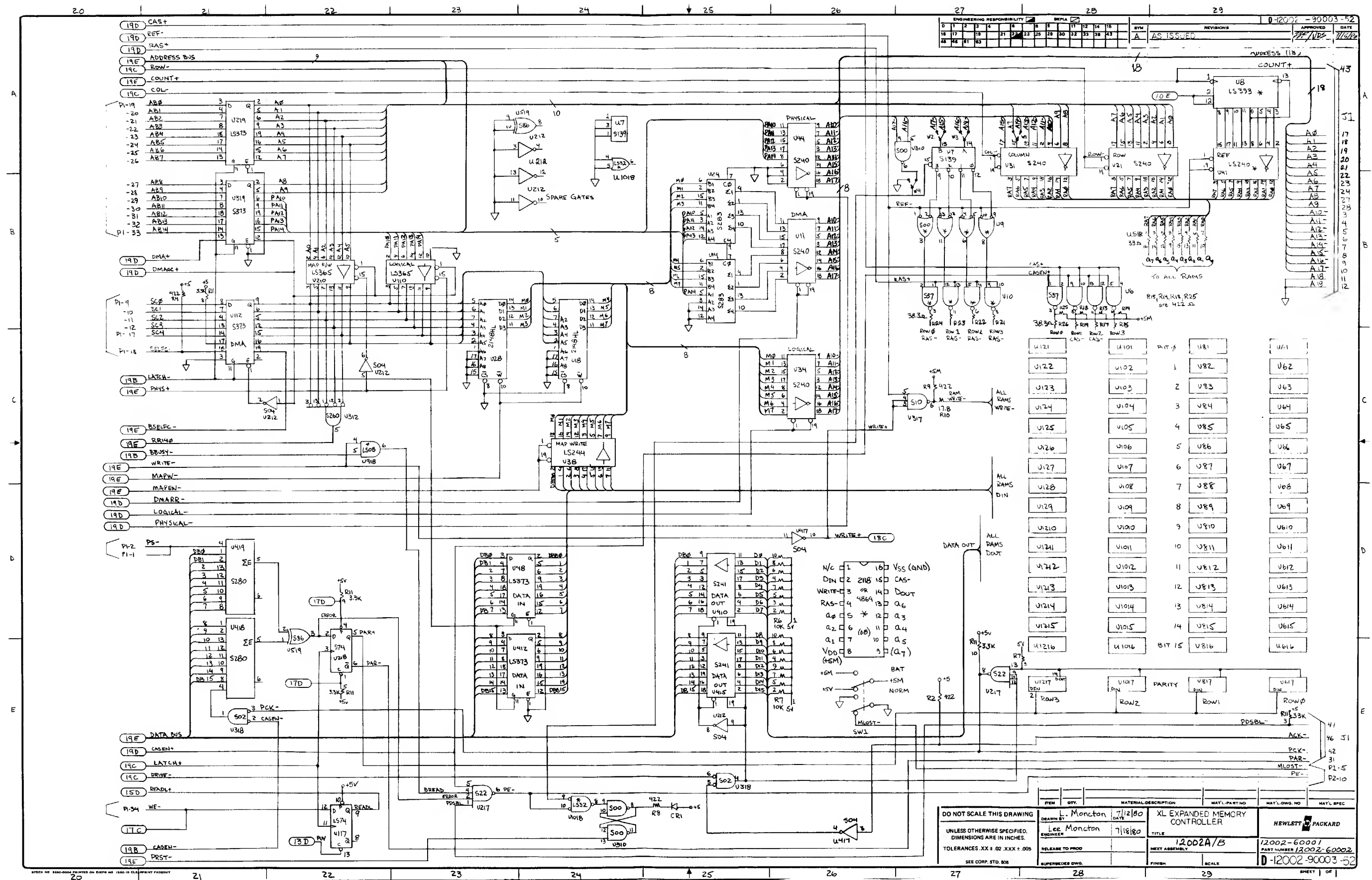
Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code	Mfr Part Number
U406	5180-0121	3			28480	5180-0121
U407	5180-0121	3			28480	5180-0121
U408	5180-0121	3			28480	5180-0121
U409	5180-0121	3			28480	5180-0121
U410	5180-0121	3			28480	5180-0121
U411	5180-0121	3			28480	5180-0121
U412	5180-0121	3			28480	5180-0121
U413	5180-0121	3			28480	5180-0121
U414	5180-0121	3			28480	5180-0121
U415	5180-0121	3			28480	5180-0121
U416	5180-0121	3			28480	5180-0121
U417	5180-0121	3			28480	5180-0121
U418	5180-0121	3			28480	5180-0121
U419	5180-0121	3			28480	5180-0121
U420	5180-0121	3			28480	5180-0121
U421	1820-1414	3	1	IC GATE TTL LS NAND TPL 3 INP	01295	SN74LS12N
U503	1820-0681	4	1	IC GATE TTL S NAND QUAD 2 INP	01295	SN74S00N
U504	5180-0121	3			28480	5180-0121
U505	5180-0121	3			28480	5180-0121
U506	5180-0121	3			28480	5180-0121
U507	5180-0121	3			28480	5180-0121
U508	5180-0121	3			28480	5180-0121
U509	5180-0121	3			28480	5180-0121
U510	5180-0121	3			28480	5180-0121
U511	5180-0121	3			28480	5180-0121
U512	5180-0121	3			28480	5180-0121
U513	5180-0121	3			28480	5180-0121
U514	5180-0121	3			28480	5180-0121
U515	5180-0121	3			28480	5180-0121
U516	5180-0121	3			28480	5180-0121
U517	5180-0121	3			28480	5180-0121
U518	5180-0121	3			28480	5180-0121
U519	5180-0121	3			28480	5180-0121
U520	5180-0121	3			28480	5180-0121
W1 - W3	B159-0005	0	3	WIRE 22AWG W PVC 1X22 80C	28480	B159-0005
* HP PART NO. 5180-0121 16,384X1 DYNAMIC RAM						

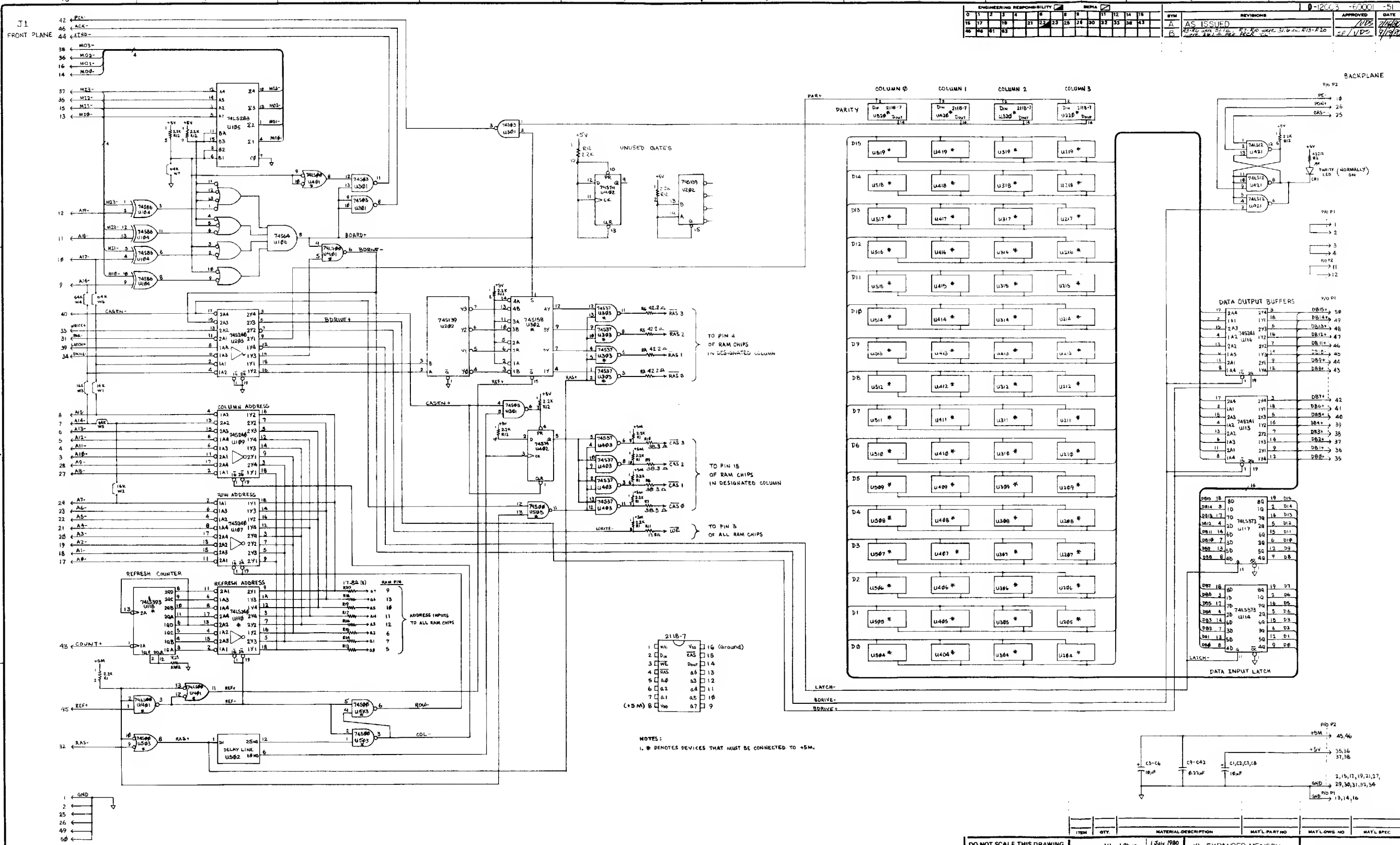


- NOTES:
1. * DENOTES DEVICES CONNECTED TO +5M.
 2. 4 JUMPERS SELECT 16K RAMS *OR 64K RAMS *
 3. 16K RAMS (2118) LOADED ON 12002-60001
64K RAMS (4864) LOADED ON 12002-60002

ENGINEERING RESPONSIBILITY										REVISIONS										APPROVED	DATE
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22
21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40	41	42
43	44	45	46	47	48	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63	64
A										AS ISSUED										1/1/80	1/1/80

BACK-PLANE





ENGINEERING RESPONSIBILITY															
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32
33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48

REV	DATE	BY	CHKD	APP'D	DATE
1	10/1/80	Albert Chun			
2	10/3/80	Albert Chun			

REV	DATE	BY	CHKD	APP'D	DATE
1	10/1/80	Albert Chun			
2	10/3/80	Albert Chun			

ITEM	QTY	MATERIAL DESCRIPTION	MAT'L PART NO	MAT'L QTY NO	MAT'L SPEC
DO NOT SCALE THIS DRAWING					
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.					
TOLERANCES: XX ± .02, XXX ± .005					
SEE CORP. STD. 006					
DESIGNED BY	Albert Chun	DATE	10/1/80		
ENGINEER	Albert Chun	DATE	10/3/80		
RELEASE TO PROD.					
SUBMITTER'S QWS					
TITLE	XL EXPANDED MEMORY ARRAY CARD				
NEXT ASSEMBLY	12003A				
FINISH					
SCALE					
PART NUMBER	D-12003-60001-51				

SELF-TEST, LOADER, AND VCP PROGRAMS	APPENDIX A
-------------------------------------	------------

This appendix contains a listing of the self-test, loader, and the Virtual Control Panel programs contained in the HP 12001B processor card ROM.

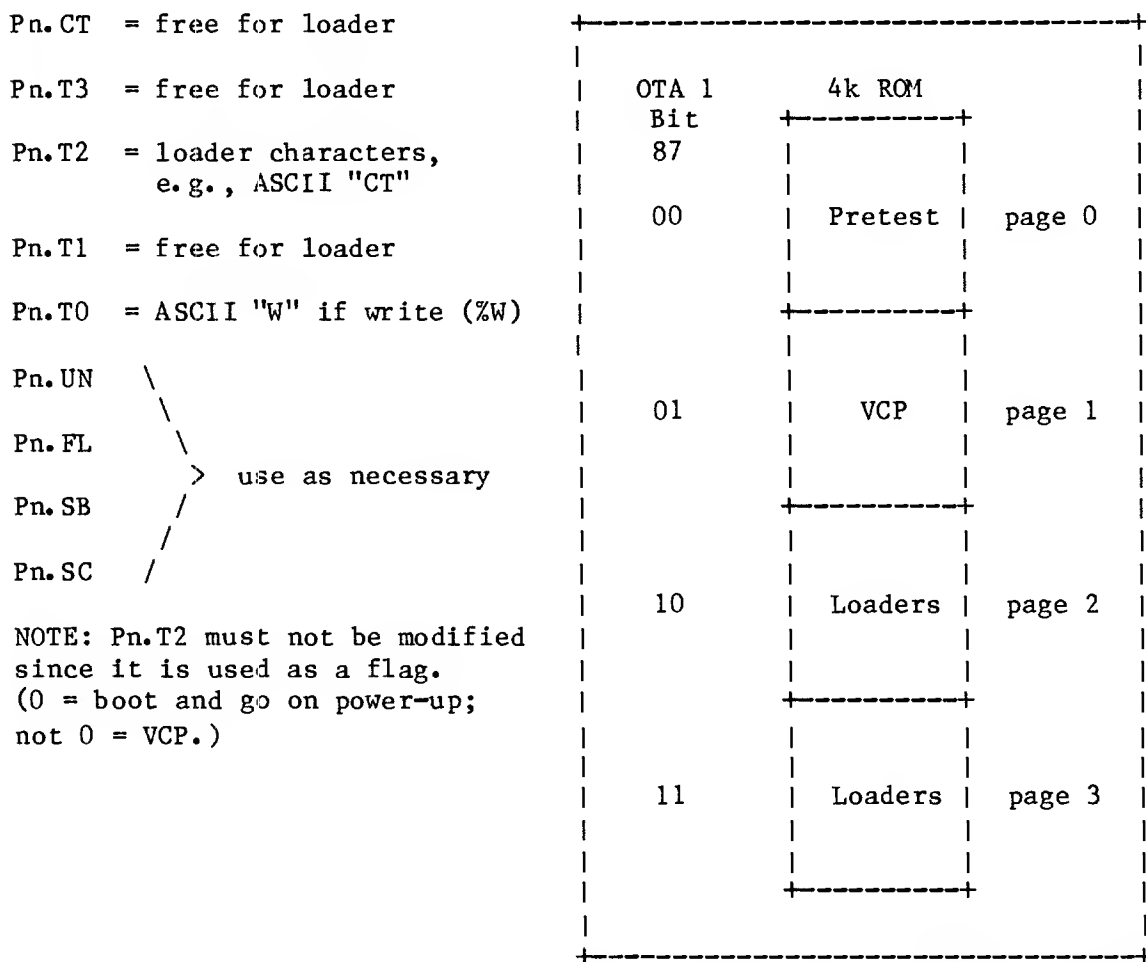
The 4k ROM code is identified by HP part numbers 5180-0123 and 5180-0124 contained in ICs PTST-LB and PTST-HB, respectively. (The obsolete 2K ROM code is identified by HP part numbers 5090-1624 and 5090-1625). Refer to figure A-1 for the 4k ROM program layout.

It is suggested that users who create their own loaders implement them in PROM on the HP 12008A PROM Storage Module.

A user who intends to change the processor ROM code for any reason should keep in mind the following points.

1. A method was developed using standard coding to allow access to both RAM and ROM. The RAM area is necessary for storage and the ROM area is for instructions and constants. This method is referred to as A addressable and B addressable. If the instruction is A addressable, data is returned from ROM; if B addressable, the data is read from RAM. At the beginning of the ROM code listing is a reference for instructions and ROM versus RAM.
2. The ROM code space is not addressed as continuous pages but 1k pages that overlay the same 1k of RAM area (see figure A-1). This is done so that programs on any page can access the same storage area. The control bits for page selection are bit 7 and 8 with an OT* 1. The OT* also controls the processor LED's. When crossing over pages the area on both pages must be considered. Also, the listing is assembled starting at 4000 octal but the program can be set to execute on any 1k page.
3. The common storage area was set up for the last 64 words a 1K page. These are used by all three sections. When using these storage locations, make sure there is no interference or destruction of data from another area. This is important when writing loaders. This storage area can be on either the base page (page 0) for a computer with extended memory or the last page for a computer with only 32k words.
4. The area at the end of each page must be the same to allow a break to enter and go to the VCP code correctly.

5. The JSB usage is set up so that a JSB goes to the ROM area above the common storage area and there it is followed by a JMP routine. Note that this allows doubling up of address space and does not waste ROM area. The normal NOP used for the return address is used in ROM as the JMP instruction for the previous JSB.
6. All loaders must use the JSB S.SC call to set up the parameters for a load. This includes the select code, file number, unit, and subchannel. The file number is stored on the I/O chip in register 25 octal and is used for continuation (sequential) loads.
7. The temporary storage areas are set up at the same 1k address space, allowing cross communication between pages. When writing a loader, the storage areas are used as follows, where n in Pn is the page number:



NOTE: Pn.T2 must not be modified since it is used as a flag.
(0 = boot and go on power-up;
not 0 = VCP.)

Figure A-1. Processor ROM Code Layout

The following pages contain an example 4k ROM listing. ROM firmware is subject to change; therefore, later versions will contain minor differences from this listing. (Note: There is a Cross Reference Symbol Table at the end of the listing.)

*

```

0001          ASMB,A,B,L,C          4K VERSION OF PROCESSOR PROMS
0003 00000          ORG 0
0004* *****
0005* * (C) COPYRIGHT HEWLETT-PACKARD COMPANY 1980. ALL RIGHTS *
0006* * RESERVED. NO PART OF THIS PROGRAM MAY BE PHOTOCOPIED, *
0007* * REPRODUCED OR TRANSLATED TO ANOTHER PROGRAM LANGUAGE WITHOUT *
0008* * THE PRIOR WRITTEN CONSENT OF HEWLETT-PACKARD COMPANY. *
0009* *****
0010*
0011* SOURCE: 24397-18001
0012*
0013*
0014*
0015* THE PROGRAMS IN THIS LISTING ARE IN THE FOLLOWING ORDER
0016*
0017* I. PRETEST (FOR CPU, MEMORY, AND I/O) PAGE 0
0018* II. VIRTUAL CONTROL PANEL (VCP) PAGE 1
0019* III. BOOT LOADERS PAGE 2 & 3
0020*
0021* DURING THE EXECUTION OF THE PROM PROGRAM THE FOLLOWING
0022* INSTRUCTION RULES APPLY FOR ACCESSING ROM VERSUS RAM:
0023*
0024* AND >
0025* XDR >
0026* IOR > OPERAND IS
0027* LDA > FROM ROM ONLY
0028* CPA >
0029* ADA >
0030*
0031* ISZ >
0032* ADB > OPERAND IS
0033* LDB > FROM RAM ONLY
0034* CPR >
0035*
0036* JSR > RETURN ADDRESS IS WRITTEN TO RAM
0037* JMP ,I> ADDRESS IS FROM RAM
0038* STA/B > ALWAYS WRITTEN TO RAM
0039*
0040* ALL EAU INSTRUCTIONS GENERATE ROM ENABLE FOR THE SECOND WORD
0041* AND ALL OPERANDS ARE FROM ROM.
0042*
0043* THE RULE IS: ROM ENABLE = FETCH + (READ . IR11-) + EAU

```

```

0045*      CPU STATUS IS OBTAINED BY A LIA/B 1
0046* SW 1  BIT 8 = ROOT SELECT 0
0047*      2      9 = ROOT SELECT 1
0048*      3     10 = ROOT SELECT 2
0049*      4     11 = ROOT SELECT 3
0050*      5     12 = SELECT ALTERNATE VCP DRIVER
0051*      6     13 = RESERVED
0052*      -     14 = MEMORY LOST (LOW TRUE)
0053*      8     15 = INTERRUPT MASK BIT 1 FOR PROCESSOR BOARD
0054*
0055*          SWITCH 7 IS RESERVED ON THE PROCESSOR FOR INT/EXT CLOCK
0056*
0057*
0058*      CPU CONTROL OUTPUT BY AN OTA/B 1
0059*      BIT 0-7 = STATUS LIGHT 0-7

```



```

0061 04000          ORG 4000B
0062                SUP
0063 00000          A    EQU 0          A-REG. REFERENCE
0064 00001          B    EQU 1          B-REG. REFERENCE
0065 04000          P0   EQU *          PAGE 0 REFERENCE
0066 00001          CPUT EQU 1          CPU STATUS REGISTER
0067 00030          DR   EQU 30B        DRIVER SC FOR DATA I/O
0068 00031          CTL  EQU 31B        " " " CONTROL
0069 00032          STS  EQU 32B        " " " STATUS
0070*
0071*      I.  PRETEST
0072*      THE PRETEST IS USED TO VERIFY EXECUTION OF THE BASIC
0073*      INSTRUCTIONS USED IN THE BOOT LOADERS.  THE ASSUMPTION IS
0074*      MADE THAT THE JMP INSTRUCTION IS FUNCTIONAL AND WILL BE
0075*      USED TO STOP EXECUTION.  THE PRETEST IS NOT INTENDED TO
0076*      BE A COMPLETE CHECK OF THE CPU BUT ONLY THAT THE INSTRUCTIONS
0077*      USED IN THE BOOT ARE FUNCTIONAL SO THAT A BOOT LOAD MAY BE
0078*      POSSIBLE.
0079*
0080 04000 000000  ZERO  NOP            CONSTANT
0081 04001 004000  REV   OCT 4000      REVISION LEVEL  4K VERSION

0083*      ENTRY POINT AFTER POWER UP SELFTEST SEQUENCE
0084 04002 024100  OCT 24100          MOVE TO START OF PRE-TEST
0085 04003 026514  JMP MTST+2          START WITH MEMORY
0086 04004 026711  JMP IPF            POWER FAIL INTERRUPT SO STOP
0087 04005 026652  JMP IPRTY          PARITY ERROR INTERRUPT
0088 04006 026460  JMP ITPG           TBG INTERRUPT
0089 04007 000000  NOP                IGNORE INTERRUPT
0090 04010 000000  NOP
0091                REP 7              ILLEGAL INTERRUPT LOCATIONS
0092 04011 027470  JMP ILINT
0092 04012 027470  JMP ILINT
0092 04013 027470  JMP ILINT
0092 04014 027470  JMP ILINT
0092 04015 027470  JMP ILINT
0092 04016 027470  JMP ILINT
0092 04017 027470  JMP ILINT

```

0094		REP 48	I/O INTERRUPTS
0095	04020 027317	JMP IOINT	
0095	04021 027317	JMP IOINT	
0095	04022 027317	JMP IOINT	
0095	04023 027317	JMP IOINT	
0095	04024 027317	JMP IOINT	
0095	04025 027317	JMP IOINT	
0095	04026 027317	JMP IOINT	
0095	04027 027317	JMP IOINT	
0095	04030 027317	JMP IOINT	
0095	04031 027317	JMP IOINT	
0095	04032 027317	JMP IOINT	
0095	04033 027317	JMP IOINT	
0095	04034 027317	JMP IOINT	
0095	04035 027317	JMP IOINT	
0095	04036 027317	JMP IOINT	
0095	04037 027317	JMP IOINT	
0095	04040 027317	JMP IOINT	
0095	04041 027317	JMP IOINT	
0095	04042 027317	JMP IOINT	
0095	04043 027317	JMP IOINT	
0095	04044 027317	JMP IOINT	
0095	04045 027317	JMP IOINT	
0095	04046 027317	JMP IOINT	
0095	04047 027317	JMP IOINT	
0095	04050 027317	JMP IOINT	
0095	04051 027317	JMP IOINT	
0095	04052 027317	JMP IOINT	
0095	04053 027317	JMP IOINT	
0095	04054 027317	JMP IOINT	
0095	04055 027317	JMP IOINT	
0095	04056 027317	JMP IOINT	
0095	04057 027317	JMP IOINT	
0095	04060 027317	JMP IOINT	
0095	04061 027317	JMP IOINT	
0095	04062 027317	JMP IOINT	
0095	04063 027317	JMP IOINT	
0095	04064 027317	JMP IOINT	
0095	04065 027317	JMP IOINT	
0095	04066 027317	JMP IOINT	
0095	04067 027317	JMP IOINT	
0095	04070 027317	JMP IOINT	
0095	04071 027317	JMP IOINT	
0095	04072 027317	JMP IOINT	
0095	04073 027317	JMP IOINT	
0095	04074 027317	JMP IOINT	
0095	04075 027317	JMP IOINT	
0095	04076 027317	JMP IOINT	
0095	04077 027317	JMP IOINT	

0097* THE FOLLOWING INSTRUCTIONS CHECK THE CPU CHIP ONLY

0098*

0099	04100	002701	START	CLA,CCE,RSS	A=000000	B=XXXXXX	E=1	O=X	+SKP	
0100	04101	026101		JMP *	RSS FAILED					
0101	04102	006440		CLP,SEZ	A=000000	B=000000	E=1	O=X	-SKP	
0102	04103	002102		CLE,SZA	A=000000	B=000000	E=0	O=X	+SKP	
0103	04104	026104		JMP *	CCE-SEZ OR CLA-SZA FAILED					
0104	04105	003041		CMA,SEZ,RSS	A=177777	B=000000	E=0	O=X	-SKP	
0105	04106	006202		CME,SZB	A=177777	B=000000	E=1	O=X	+SKP	
0106	04107	026107		JMP *	CCE OR CLB-SZB FAILED					
0107	04110	007040		CMB,SEZ	A=177777	B=177777	E=1	O=X	-SKP	
0108	04111	006003		SZB,RSS						+SKP
0109	04112	026112		JMP *	CME OR CMB FAILED					
0110	04113	050001		CPA B						-SKP
0111	04114	002414		CLA,SLA,INA	A=000001	B=177777	E=1	O=X	+SKP	
0112	04115	026115		JMP *	CMA-CPA B-SLA,INA FAILED					
0113	04116	002002		SZA						-SKP
0114	04117	002020		SSA						+SKP
0115	04120	026120		JMP *	INA OR SSA FAILED					
0116	04121	006400		CLB	A=000001	B=000000	E=1	O=X		
0117	04122	003420		CCA,SSA	A=177777	B=000000				-SKP
0118	04123	002003		SZA,RSS						+SKP
0119	04124	026124		JMP *	CCA-SSA OR SZA,RSS FAILED					
0120	04125	000010		SLA						-SKP
0121	04126	002131		CLF,SSA,SLA,RSS	A=177777	B=000000	E=0	O=X	+SKP	
0122	04127	026127		JMP *	SLA OR SSA,SLA,RSS FAILED					
0123	04130	102101		STO	A=177777	B=000000	E=0	O=1		
0124	04131	102201		SOC						-SKP
0125	04132	102301		SOS						+SKP
0126	04133	026133		JMP *	STO-SOC-SOS FAILED					
0127	04134	103101		CLO	A=177777	B=000000	E=0	O=0		
0128	04135	102301		SOS						-SKP
0129	04136	102201		SOC						+SKP
0130	04137	026137		JMP *	CLO-SOS-SOC FAILED					

*

0132	04140	063573	LDA ALT1	A=125252	B=000000	E=0	O=0	
0133	04141	006003	SZB,RSS					
0134	04142	050001	CPA B					+SKP
0135	04143	026143	JMP *	CPA B OR CLB-SZB,RSS	FAILED			
0136	04144	053573	CPA ALT1					-SKP
0137	04145	070001	STA B	A=125252	B=125252	E=0	O=0	
0138	04146	063573	LDA ALT1					
0139	04147	054000	CPB A					+SKP
0140	04150	003401	CCA,RSS	A=177777	B=125252	E=0	O=0	+SKP
0141	04151	026151	JMP *	CPA-STA-CPR	FAILED			
0142	04152	013572	AND ALTO	A=052525	B=125252	E=0	O=0	
0143	04153	053572	CPA ALTO					-SKP
0144	04154	002001	RSS					+SKP
0145	04155	026155	JMP *	AND-CPA	FAILED			
0146	04156	013573	AND ALT1	A=000000	B=125252	E=0	O=0	
0147	04157	002002	SZA					+SKP
0148	04160	026160	JMP *	AND	FAILED			
0149	04161	063544	LDA B24	A=000024	B=125252	E=0	O=0	
0150	04162	033572	IOR ALTO	A=052525	B=125252	E=0	O=0	
0151	04163	053572	CPA ALTO					-SKP
0152	04164	003401	CCA,RSS	A=177777	B=125252	E=0	O=0	+SKP
0153	04165	026165	JMP *	XOR	FILED			
0154	04166	023573	XOR ALT1	A=052525	B=125252	E=0	O=0	
0155	04167	053572	CPA ALTO					-SKP
0156	04170	002440	CLA,SEZ	A=000000	B=125252	E=0	O=0	+SKP
0157	04171	026171	JMP *	IOR-XOR	FAILED			
0158	04172	043573	ADA ALT1	A=125252	B=125252	E=0	O=0	
0159	04173	053573	CPA ALT1					-SKP
0160	04174	002040	SEZ					+SKP
0161	04175	026175	JMP *	CLA OR ADA	FAILED			
0162	04176	043572	ADA ALTO	A=177777	B=125252	E=0	O=0	
0163	04177	102301	SOS					-SKP
0164	04200	003002	CMA,SZA	A=000000	B=125252	E=0	O=0	+SKP
0165	04201	026201	JMP *	ADA	FAILED			
0166	04202	003440	CCA,SEZ	A=177777	B=125252	E=0	O=0	+SKP
0167	04203	026203	JMP *	ADA	FAILED			
0168	04204	043567	ADA M1	A=177776	B=125252	E=1	O=0	
0169	04205	053570	CPA M2					-SKP
0170	04206	002041	SEZ,RSS					+SKP
0171	04207	026207	JMP *	ADA	FAILED			
0172	04210	102301	SOS					-SKP
0173	04211	002101	CLE,RSS	A=177776	B=125252	E=0	O=0	+SKP
0174	04212	026212	JMP *	ADA	FAILED			
0175	04213	034000	ISZ A	A=177777	B=125252	E=0	O=0	-SKP
0176	04214	034000	ISZ A	A=000000	B=125252	E=0	O=0	+SKP
0177	04215	026215	JMP *	ISZ	FAILED			

*

0179	04216	063566	LDA B100K	A=100000	B=125252	E=0	O=0	
0180	04217	043567	ADA M1	A=077777	B=125252	E=1	O=1	
0181	04220	102201	SOC					-SKP
0182	04221	002141	SEZ,CLE,RSS	A=077777	B=125252	E=0	O=1	+SKP
0183	04222	026222	JMP *	ADA FAILED				
0184	04223	103101	CLO	A=077777	B=125252	E=0	O=0	
0185	04224	002004	JNA	A=100000	B=125252	E=0	O=1	
0186	04225	053566	CPA B100K					-SKP
0187	04226	002040	SEZ					+SKP
0188	04227	026227	JMP *	ADA FAILED				
0189	04230	060001	LDA B	A=125252	B=125252	E=0	O=1	
0190	04231	053573	CPA ALT1					-SKP
0191	04232	103301	SOS C	A=125252	B=125252	E=0	O=0	+SKP
0192	04233	026233	JMP *	B-REG. WAS MODIFIED				

0194* THE FOLLOWING SEQUENCE IS USED TO CHECK

0195* JSR, JMP X,I, AND STA X,I

0196*

0197	04234	062255	LDA PTJPR	GET RETURN IN B-REG.
0198	04235	064000	LDB A	CHANGE HANDS
0199	04236	014000	JSR 0	
0200	04237	026237	JMP *	JSR FAILED
0201	04240	052254	PTRT0 CPA PTDF1	CORRECT RETURN ADDRESS?
0202	04241	002301	CCE,RSS	YES
0203	04242	026242	JMP *	NO
0204	04243	062253	LDA PTDF0	SET PAGE ADDRESS
0205	04244	173533	STA B1,I	PUT IT IN B-REG. INDIRECTLY
0206	04245	050001	CPA B	
0207	04246	162253	LDA PTDF0,I	
0208	04247	006004	INB	
0209	04250	052256	CPA PTJMP	INDIRECT OK?
0210	04251	024000	JMP 0	YES EXECUTE B-REG.
0211	04252	026252	JMP *	
0212	04253	000256	PTDF0 DEF **3-P0	
0213	04254	000237	PTDF1 DEF PTRT0-P0-1	
0214	04255	026240	PTJPR JMP PTRT0	
0215	04256	124001	PTJMP JMP 1,I	

*

			B-REG.	E	A-REG.
0217	04257	063574	LDA SRGP1		
0218	04260	064000	LDB A	1000100100100111	1
0219	04261	063575	LDA SRGP2		1 1001100000100000
0220	04262	005025	BLS,ERR	1100100100100111	0
0221	04263	005661	ELB,CLE,BRS	1100100100100111	0
0222	04264	001124	ARS,ALR		0 0001100000100000
0223	04265	005026	RLS,ELB	0100100100100111	0
0224	04266	005523	ERR,RBP	0100100100100111	0
0225	04267	001720	ALF,ALS		0 1000010000000010
0226	04270	005124	BRS,BLR	0100100100100110	0
0227	04271	001330	RAR,SLA,ALS		0 0000010000000010
0228	04272	005221	RBL,BRS	1100100100100110	0
0229	04273	002300	CCE		1
0230	04274	001726	ALF,ELA		0 1000000001000001
0231	04275	001522	ERA,RAL		1 1000000001000000
0232	04276	005427	BLR,BLF	0010010011000001	1
0233	04277	001122	ARS,RAL		1 1000000001000001
0234	04300	005220	RBL,BLS	0001001100000100	1
0235	04301	001135	ARS,SLA,ERA		0 1110000000010000
0236	04302	026302	JMP *	SLA FAILED	
0237	04303	001623	ELA,RAR		1 0110000000010000
0238	04304	005327	RHR,BLF	1001100000100000	
0239	04305	002040	SEZ	CHECK E-REG.	
0240	04306	001460	ALR,CLF,ALS		0000000001000000
0241	04307	053576	CPA SRGP3		
0242	04310	102201	SUC		
0243	04311	026311	JMP *	SRG INST A-RFG.	
0244	04312	060001	LDA B	CHANGE HANDS	
0245	04313	053575	CPA SRGP2		
0246	04314	006640	CLB,SEZ,CMF		
0247	04315	026315	JMP *	SRG INST B-REG.	

*

0249	04316	102101	STO	START WITH 0 SET			
0250	04317	063600	LDA BEAUS	SET B=130272			
0251	04320	064000	LDB A	AND			
0252	04321	063577	LDA AEAUS	A=076310	E=1		
0253	04322	101021	ASR 1	A=037144	B=154135	E=1	O=0
0254	04323	102301	SOS				
0255	04324	100117	RRL 15	A=066056	B=117462	E=1	O=0
0256	04325	100022	ASL 2	A=130270	B=176311	E=1	O=1
0257	04326	102201	SOC				
0258	04327	101100	RRR 16	A=176311	B=130270		
0259	04330	100041	LSL 1	A=174622	B=060561		
0260	04331	101025	ASR 5	A=107714	B=001413		O=0
0261	04332	053601	CPA ASR.0	CHECK PRLIMINARY RESULTS			
0262	04333	102201	SOC				
0263	04334	026334	JMP *	EAU SHIFT FAILED			
0264	04335	101040	LSR 16	A=01413	B=0		
0265	04336	006002	SZB	INSURE B WAS CLEARED			
0266	04337	026337	JMP *	WASN'T EAU SHIFT FAILED			
0267	04340	102101	STO				
0268	04341	100020	ASL 16	A=0	B=001413		
0269	04342	102301	SOS				
0270	04343	100026	ASL 6	A=0	B=041300		
0271	04344	102201	SOC				
0272	04345	101100	RRR 16	A=041300	B=0		
0273	04346	053602	CPA ASR.1	FINAL OK?			
0274	04347	006002	SZB				
0275	04350	026350	JMP *	NO EAU SHIFT FAILED			
0276	04351	063565	LDA B76K	A=076000	B=XXXXXX	E=X	O=X
0277	04352	102101	STO				O=1
0278	04353	100200	MPY B6412	A=154000	B=003120	E=X	O=0
0279	04355	102201	SOC				
0280	04356	026356	JMP *	O WAS NOT CLEARED BY MPY			
0281	04357	100400	DIV ALT1	A=166416	B=020264		
0282	04361	100200	MPY MU2	A=156224	B=002046		
0283	04363	100400	DIV B7777	A=041161	B=007405		
0284	04365	100101	RRL 1	A=102342	B=017012		
0285	04366	100200	MPY ALT0	A=024412	B=15336		
0286	04370	100400	DIV B76K	A=125507	B=142412		
0287	04372	100200	MPY ALT1	A=161446	B=016075		
0288	04374	102101	STO				O=1
0289	04375	100400	DIV DV4	A=126760	B=006606		
0290	04377	053605	CPA RESUA	RESULT IN A			
0291	04400	102201	SOC	O=0			
0292	04401	026401	JMP *	MPY OR DIV FAILED			
0293	04402	101100	RRR 16	CHANGE HANDS			
0294	04403	053606	CPA RESUB	RESULT IN B			
0295	04404	026406	JMP ++2				
0296	04405	026405	JMP *	MPY OR DIV ERROR			
0297	04406	100400	DIV B1	TRY OVER FLOW			
0298	04410	102301	SOS	WAS IT ?			
0299	04411	026411	JMP *	NO			
0300	04412	100400	DIV ZERO	TRY ZERO TO SET OVER FLOW			
0301	04414	102301	SOS	WAS IT ?			
0302	04415	026415	JMP *	NO			

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0304* BASIC I/O ON CPU BOARD

0305*

0306	04416	106705	CLC 5	TURN OF PARITY SYSTEM
0307	04417	002404	CLA,JNA	INDICAT (IF POSSIABLE) IN IO TEST
0308	04420	102601	OTA CPUT	
0309	04421	063572	LDA ALTO	CHECK OT* AND LI*
0310	04422	064000	LDB A	CHANGE HANDS
0311	04423	063573	LDA ALT1	AND VIOLATION - PARITY REGISTERS
0312	04424	102605	OTA 5	
0313	04425	107607	OTB 7,C	
0314	04426	002400	CLA	
0315	04427	103507	LIA 7,C	
0316	04430	106505	LIB 5	
0317	04431	020001	XOR B	
0318	04432	003000	CMA	
0319	04433	001665	ELA,CLF,ERA	
0320	04434	002002	SZA	SHOULD COME OUT ZERO
0321	04435	027466	JMP PROER	OT* LI* FAILED (OR REGISTER 5.7)
0322	04436	102300	SFS 0	CHECK INTERRUPT FF
0323	04437	102200	SFC 0	
0324	04440	027466	JMP PROER	INTERRUPT FF ERROR
0325	04441	102202	SFC 2	CHECK GLOBAL REG.
0326	04442	102302	SFS 2	SHOULD BE OFF (FLAG SET)
0327	04443	027466	JMP PROER	GLOBAL REG. ERROR
0328	04444	107706	CLC 6,C	INSURE TBG IS OFF
0329	04445	102100	STF 0	TURN ON INTERRUPTS
0330	04446	102200	SFC 0	CHECK IT
0331	04447	102300	SFS 0	
0332	04450	027466	JMP PROER	INTERRUPTS NOT ON

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0334	04451	106501	LIB CPUT	SAVE TBG MASK BIT
0335	04452	102600	OTA 0	CLEAR INTERRUPT MASK
0336	04453	102604	OTA 4	CLEAR INTERRUPT REGISTER
0337	04454	103706	STC 6,C	TRY TIME BASE TIC
0338	04455	002006	INA,SZA	NOW WAIT FOR TIC
0339	04456	026455	JMP *-1	
0340	04457	027466	JMP PROER	LONG ENOUGH NOW ERROR
0341*				
0342	04460	103100	ITBG CLF 0	TURN OF INTERRUPTS
0343	04461	107706	CLC 6,C	TURN OFF TIC
0344	04462	102504	LIA 4	CHECK CENTRAL INTERRUPT
0345	04463	053540	CPA B6	WAS IT THE TBG?
0346	04464	102206	SFC 6	FLAG SHOULD STAY CLEAR
0347	04465	027466	JMP PROER	NOT SO ERROR (OR CIR NOT = 6)
0348	04466	102501	LIA CPUT	
0349	04467	002020	SSA	DID IT STAY CLEAR?
0350	04470	027466	JMP PROER	NO PROCESSOR ERROR
0351	04471	063534	LDA B2	NOW SET MASK BIT
0352	04472	102600	OTA 0	
0353	04473	102501	LIA CPUT	GET MASK BIT
0354	04474	002021	SSA,RSS	DID IT SET
0355	04475	027466	JMP PROER	NO THEN ERROR
0356	04476	002400	CLA	NOW RESTORE MASK BIT
0357	04477	006021	SSB,RSS	
0358	04500	102600	OTA 0	IT WAS ORIGINALLY CLEAR
0359	04501	102501	LIA CPUT	CHECK TO SKIP MEMORY AND I/O TESTS
0360	04502	001727	ALF,ALF	
0361	04503	013542	AND B17	
0362	04504	053540	CPA B6	GO STRAIGHT TO VCP?
0363	04505	002001	RSS	
0364	04506	026512	JMP MTST	NO DO IT ALL
0365	04507	002400	CLA	
0366	04510	102603	OTA 3	CLEAR PREGISTER
0367	04511	027757	JMP DONE	GO TO VCP SECTION

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0369*      START MEMORY ACCESS FOR FIRST TIME
0370*      CLEAR MEMORY IF IT WAS LOST DURING POWER DOWN
0371*      AND CHECK MEMORY BUT DON'T DESTROY ANY DATA IF NOT LOST
0372*
0373 04512 102501 MTST LIA CPUST      GET CPU STATUS
0374 04513 001600      ELA          SAVE VCP TEST FLAG
0375 04514 002020      SSA          WAS MEMORY SAVED ANYWAY
0376 04515 002300      CCE          YES
0377 04516 106704      CLC 4        TURN OFF THE WORLD
0378 04517 063534      LDA B2       INDICATE IN MEMORY TEST
0379 04520 102601      OTA CPUST
0380*
0381*      ENABLE BREAK MODE DUPING PRETEST
0382*
0383 04521 063532      LDA VCPD      ASSIGN BREAK ADDRESS TO I/O
0384 04522 103603      OTA 3,C      INCASE BREAK IS ENTERED
0385 04523 006400      CLB          NOW VERIFY THE OUTPUT
0386 04524 107503      LIB 3,C      GET IT BACK
0387 04525 006002      SZB          IF NOTHING THEN OK
0388 04526 050001      CPA B        DO THEY AGREE
0389 04527 026532      JMP *+3
0390 04530 063537      LDA B5       ERROR SO REPORT IT
0391 04531 027476      JMP IOER
0392 04532 062537      LDA POJPO     GET RETURN AFTER REENABLE
0393 04533 064000      LDB A
0394 04534 062540      LDA POCL2    GET REENABLE
0395 04535 102702      STC 2        DISABLE ROMS
0396 04536 024000      JMP 0        NOW EXECUTE REENABLE
0397*
0398 04537 026541      POJPO JMP POC00
0399 04540 106702      POCL2 CLC 2
0400*
0401 04541 006400      POC00 CLB      CLEAR PARITY ADDRESS
0402 04542 107607      OTB 7,C      IT'S SAVED IN MP REG.
0403 04543 063534      LDA B2       SET STARTING ADDRESS
0404 04544 103101      MTST0 CLO    INDICATE FIRST TIME NO ERRORS
0405 04545 102705      STC 5        TURN ON PARITY DETECTION INTERRUPT
0406 04546 006440      CLB,SEZ     IF MEMORY WAS LOST SKIP LOADING DATA
0407 04547 164000      LDB A,I      GET CURRENT CONTENTS
0408 04550 007000      CMB         COMPLEMENT THE DATA
0409 04551 174000      STB A,I      PUT IT BACK IN THE LOCATION
0410 04552 154000      CPB A,I     DID IT STORE?
0411 04553 007001      CMB,RSS     YES - COMPLEMENT DATA BACK
0412 04554 026560      JMP MTSTE    NO - REPORT ERROR
0413 04555 174000      STB A,I      RESTORE ORIGINAL DATA
0414 04556 154000      CPB A,I     DID IT RESTORE?
0415 04557 026700      JMP MTST1    YES - MOVE TO NEXT ADDRESS

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0417* MEMORY ERROR ROUTINE

0418*

0419	04560	106705	MTSTE CLC 5	TURN OFF PARITY INTERRUPTS
0420	04561	102200	SFC 0	CHECK IF MAPPED
0421	04562	102711	STC 11B	YES TURN THEM BACK ON
0422	04563	026564	JMP *+1	
0423	04564	164000	LDB A,I	GET MEMORY DATA
0424	04565	106711	CLC 11B	TURN OFF MAPS
0425	04566	102301	SOS	IF PARITY ERROR THEN FAILURE
0426	04567	007002	CMB,SZB	CHECK IF END OF MEMORY
0427	04570	026576	JMP *+6	NOT SO ERROR
0428	04571	070001	STA B	SAVE ORIGINAL ADDRESS
0429	04572	013560	AND B1777	MASK UPPER PAGE BITS
0430	04573	002003	SZA,RSS	WAS IT ON PAGE BOUNDARY?
0431	04574	027002	JMP MTST3	YES - ASSUME END OF MEMORY
0432	04575	060001	LDA B	NO - RESTOR ORIGINAL ADDRESS
0433	04576	102200	SFC 0	CHECK IF IN EXTENDED MEMORY
0434	04577	026642	JMP EMERP	YES REPORT IT AS SUCH
0435	04600	070001	STA B	PUT ADDRESS IN B REG
0436	04601	063572	LDA ALTO	START WITH ALTERNATING PATTERN
0437	04602	101100	RRR 16	SWAP A & B
0438	04603	174000	STB A,I	STORE TEST PATTERN
0439	04604	164000	LDB A,I	GET IT BACK
0440	04605	101100	RRR 16	SWAP A & B
0441	04606	023572	XOR ALTO	ELIMINATE GOOD BITS
0442	04607	002002	SZA	WAS THERE ANY BAD BITS?
0443	04610	026617	JMP *+7	YES - DISPLAY IT
0444	04611	063573	LDA ALT1	USE OPPOSITE PATTERN
0445	04612	101100	RRR 16	SWAP A & B
0446	04613	174000	STB A,I	STORE TEST PATTERN
0447	04614	164000	LDB A,I	GET IT BACK
0448	04615	101100	RRR 16	SWAP A & B
0449	04616	023573	XOR ALT1	ELIMINATE GOOD DATA
0450	04617	103101	CLO	SET FOR UPPER LOWER ADDRESS
0451	04620	005200	RBL	SAVE UPPER/LOWER 16K BIT
0452	04621	006020	SSB	
0453	04622	102101	STO	UPPER HALF
0454	04623	101100	RRR 16	SWAP A & B
0455	04624	002401	CLA,RSS	START WITH BIT 0
0456	04625	002004	INA	COUNT FOR BIT POSITION
0457	04626	053543	CPA B20	END OF BIT CHECK
0458	04627	026635	JMP *+6	YES - MUST BE PARITY
0459	04630	004075	CLE,SLB,ERB	NO CHECK FOR BIT AND ROTATE REGISTER
0460	04631	026633	JMP *+2	BAD BIT SO DISPLAY IT
0461	04632	026625	JMP *-5	NO SO TRY NEXT BIT
0462	04633	006002	SZB	CHECK IF MULTI BIT ERROR
0463	04634	033543	IOR B20	YES
0464	04635	102201	SOC	CHECK FOR UPPER LOWER
0465	04636	033546	IOR BITS	IT'S UPPER
0466	04637	001727	ALF,ALF	PUT DATA IN UPPER HALF
0467	04640	033534	IOR B2	INDICATE MEMORY ERROR
0468	04641	027500	JMP DSPLY	DISPLAY THE ERROR

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0470*      EXTENDED MEMORY ERROR DISPLAY
0471*
0472  04642 064137  EMERR LDB 137B      GET 16K BLOCK ADDRESS
0473  04643 060001      LDA B
0474  04644 001121      ARS,ARS      DIVIDE BY 16
0475  04645 001121      ARS,ARS
0476  04646 013545      AND B37      MASK OFF UPPER BITS
0477  04647 001727      ALF,ALF      PUT IT IN UPPER HALF
0478  04650 033540      IOR B6      ADD EXTENDED MEMORY SECTION
0479  04651 027500      JMP DSPLY     GO DISPLAY IT
0480*
0481*      PARITY INTERRUPT ROUTINE
0482*      A SOFT ERROR WILL NO CAUSE CPU TO STOP
0483*
0484  04652 106705  TPRTY CLC 5      TURN OFF PARITY DETECTION
0485  04653 002020      SSA          PARITY TEST?
0486  04654 027014      JMP MTST4     YES END OF MEMORY TEST
0487  04655 102201      SOC          WAS THERE A PREVIOUS ERROR
0488  04656 026560      JMP MTSTE     YES REPORT FAILURE
0489  04657 102101      STO          INDICATE PARITY ERROR
0490  04660 107507      LIB 7,C      WAS THERE A PREVIOUS ADDRESS
0491  04661 006002      SZB          ??
0492  04662 026671      JMP *+7      YES PREVIOUS ADDRESS SKIF UPDATE
0493  04663 102300      SFS 0       IS THIS EXTENDED
0494  04664 026670      JMP *+4      NO
0495  04665 064137      LDB 137B     YES GET BLOCK ADDRESS
0496  04666 107607      OTB 7,C      UPDATE ERROR
0497  04667 026671      JMP *+2
0498  04670 103607      OTA 7,C      NO SO SAVE THIS ONE
0499  04671 102200      SFC 0       CHECK IF MAPS WERE ON
0500  04672 102711      STC 11B     YES THEN RESTOR THEM
0501  04673 026674      JMP *+1     AND TURN THEM ON
0502  04674 006400      CLB          CLEAR DATA
0503  04675 074004      STB 4       AND RESTART CONDITION
0504  04676 174000      STB A,I     WRITE GOOD PARITY
0505  04677 026545      JMP MTST0+1  TRY IT AGAIN

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0507	04700	102204	MTST1	SFC 4	IS POWER GOING DOWN?
0508	04701	026715		JMP MTST2	NO
0509	04702	002400		CLA	CLEAR INCASE NO RESPONSE TO I/O
0510	04703	103507		LIA 7,C	YES CHECK IF THERE
0511	04704	002003		SZA,RSS	WAS A PARITY ERROR
0512	04705	026710		JMP *+3	NO
0513	04706	102105		STF 5	YES - CHANGE PARITY SENSE
0514	04707	174000		STB A,I	WRITE AN ERROR
0515	04710	103105		CLF 5	PUT PARITY BACK
0516	04711	102304	IPF	SFS 4	WAIT FOR POWER TO GO DOWN
0517	04712	026711		JMP *-1	
0518	04713	107700		CLC 0,C	TURN OFF MACHINE
0519	04714	024002		JMP 2	DIDN'T GO ALL THE WAY SO RESTART
0520	04715	034000	MTST2	ISZ A	MOVE TO NEXT LOCATION
0521	04716	064000		LDR A	SAVE ADDRESS
0522	04717	002021		SSA,RSS	END OF MEMORY TEST?
0523	04720	026544		JMP MTST0	NO
0524	04721	102200		SFC 0	CHECK IF MAPPED
0525	04722	026766		JMP MTSTM	YES
0526	04723	064137		LDR 137B	SAVE MAP REGISTER
0527	04724	002400		CLA	SET MAP TO POINT TO SAME PAGE
0528	04725	070137		STA 137B	
0529	04726	063557		LDA B1776	GET UPPER ADDRESS
0530	04727	033565		IOR B76K	
0531	04730	102711		STC 11B	ENABLE MAPS
0532	04731	026732		JMP *+1	TURN THEM ON
0533	04732	174000		STB A,I	SAVE MAP
0534	04733	002004		INA	
0535	04734	106713		CLC 13B	TEMP DISABLE MAPS
0536	04735	067777		LDB P0.CT	
0537	04736	007000		CMB	
0538	04737	102713		STC 13B	REENABLE
0539	04740	174000		STB A,I	
0540	04741	106713		CLC 13B	
0541	04742	063557		LDA B1776	
0542	04743	033565		IOR B76K	
0543	04744	057777		CPB P0.CT	DID IT GO INTO BASE PAGE?
0544	04745	013560		AND B1777	YES THEN USE BASE PAGE THERE ARE MAPS
0545	04746	164000		LDB A,I	RESTOR MAPS
0546	04747	074137		STR 137B	
0547	04750	006400		CLR	
0548	04751	053557		CPA B1776	WAS THERE MAPS
0549	04752	026754		JMP *+2	
0550	04753	027002		JMP MTST3	NO
0551	04754	102100		STF 0	YES - THEN INDICATE MAPS TEST
0552	04755	063540		LDA B6	INDICATE EXTENDED MEMORY TEST
0553	04756	102601		OTA CPUTST	PUT IT ON LEDS
0554	04757	064137		LDB 137B	SAVE MAP
0555	04760	077776		STB P0.T3	
0556	04761	063546		LDA B40	START WITH LOWEST MAPPED PAGE
0557	04762	070137		STA 137B	
0558	04763	063565		LDA B76K	AND ADDRESS FOR CORRECT MAPPING
0559	04764	102713		STC 13B	ENABLE MAPS
0560	04765	026544		JMP MTST0	

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0562	04766	106711	MTSTM	CLC	11B	
0563	04767	106713		CLC	13B	DISABLE MAPPING
0564	04770	064137		LDB	137B	CHECK IF END OF MEMORY
0565	04771	034137		ISZ	137B	MOVE TO NEXT BLOCK
0566	04772	060001		LDA	B	
0567	04773	006400		CLB		
0568	04774	053553		CPA	B377	IS IT?
0569	04775	027002		JMP	MTST3	YES
0570	04776	063565		LDA	B76K	NO - DO NEXT ONE
0571	04777	102711		STC	11B	RE-ENABLE MAPPING
0572	05000	102713		STC	13B	
0573	05001	026544		JMP	MTST0	
0574*						
0575	05002	060001	MTST3	LDA	B	NOW TEST PARITY DETECTION
0576	05003	033566		IOR	B100K	
0577	05004	064002		LDB	2	GET DATA
0578	05005	102105		STF	5	CHANGE PARITY SENSE
0579	05006	074002		STB	2	ESTABLISH BAD PARITY
0580	05007	103105		CLF	5	REVERSE SENSE
0581	05010	102705		STC	5	ENABLE PARITY
0582	05011	064002		LDB	2	READ BAD PARITY
0583	05012	063534		LDA	B2	INTERRUPT SHOULD OCCUR
0584	05013	026560		JMP	MTSTF	IT DIDN'T SO ERROR

*

0586	05014	074002	MTST4	STB 2	RESTORE GOOD PARITY TO LOCATION 2
0587	05015	102200		SFC 0	IF MAPPED
0588	05016	063566		LDA B100K	SET P=77777
0589	05017	005600		ELB	SAVE MEM LOST FLAG
0590	05020	043567		ADA M1	BACK ADDRESS UP ONE
0591	05021	005500		ERB	
0592	05022	001665		ELA,CLE,ERA	CLEAR BIT 15
0593	05023	107507		LIR 7,C	GET PARITY ADDRESS
0594	05024	006002		SZR	SET MEMLOST IF PARITY ERROR
0595	05025	002101		CLF,RSS	AND DISPLAY THE PARITY ADDRESS
0596	05026	064000		LDR A	OTHERWISE DISPLAY MEMORY SIZE
0597	05027	106603		OTB 3	
0598	05030	006400		CLB	CLEAT MP REG
0599	05031	107607		OTB 7,C	
0600	05032	102300		SFS 0	CHECK FOR MAPS
0601	05033	027042		JMP MTST5	NO MAPS
0602	05034	064137		LDB 137B	INDICATE HIGHEST MAP
0603	05035	060001		LDA B	
0604	05036	103607		OTA 7,C	
0605	05037	067776		LDB P0.T3	RESTOR MAP REGISTER
0606	05040	074137		STB 137B	
0607	05041	002400		CLA	
0608	05042	103100	MTST5	CLF 0	RESET THINGS
0609	05043	102704		STC 4	REFNABLE ALSO
0610	05044	013565		AND B76K	SAVE PAGE
0611	05045	070001		STA B	
0612	05046	033532		IOR VCPD	SET VCP ADDRESS
0613	05047	103603		OTA 3,C	FOR BREAK
0614	05050	060001		LDA B	
0615	05051	033053		IOR *+2	PUT SELF ON PAGE
0616	05052	124000		JMP A,I	
0617	05053	001054		DEF *+1-P0	
0618	05054	063531		LDA IOLP	SET POINTER FOR I/O TABLE
0619	05055	030001		IOR B	ADD PAGE
0620	05056	073773		STA P0.T0	
0621	05057	002004		INA	
0622	05060	073774		STA P0.T1	SAVE PAGE ADDRESS
0623	05061	103507		LIA 7,C	GET MEMORY SIZE
0624	05062	107607		OTB 7,C	SAVE PAGE ADDRESS
0625	05063	003006		CMA,INA,SZA	DECREMENT BLOCK
0626	05064	003000		CMA	
0627	05065	001727		ALF,ALF	PUT IN UPPER PORTION
0628	05066	001323		RAR,RAR	
0629	05067	073772		STA P0.A	OF A REGISTER
0630	05070	104200		DLD REV	SET REVISION
0631	05072	073771		STA P0.B	IN B REGISTER

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0633*      START OF I-O INTERFACE CHIP TESTS
0634*
0635*      USE DIAG. MODE 1 TO BUILD A SELECT CODE TABLE
0636*
0637 05073 063535      LDA B3      INDICATE IN IO INTERFACES
0638 05074 102601      OTA CPUT      INSURE GLOBAL REGISTER IS OFF
0639 05075 102102      STF 2      SET TEST MODE 1 (PROIRIETY RESPONSE)
0640 05076 002404      CLA,INA      GIVE MODE TO CHIPS
0641 05077 102602      OTA 2      INCASE OF NO RESPONSE
0642 05100 002400      IOL0 CLA
0643 05101 037773      ISZ P0.T0
0644 05102 067773      LDB P0.T0      GET TABLE POINTER
0645 05103 170001      STA B,I      SET END OF TABLE
0646 05104 102502      LIA 2      GET SELECT CODE
0647 05105 002003      SZA,RSS      ANY SELECT CODE
0648 05106 027134      JMP ION0      NO END-OF-IO CHIPS
0649 05107 013547      AND SCM      YES - USE SELECT CODE ONLY
0650 05110 170001      STA B,I      PUT IT IN TABLE
0651 05111 001665      FLA,CLE,FRA
0652 05112 043571      ADA M20      SUBTRACT 20B
0653 05113 002020      SSA      IS IT A VALID SELECT CODE?
0654 05114 027132      JMP IOF4      NO - INDICATE ERROR 4 ON LEDS
0655 05115 067774      LDB P0.T1      CHECK FOR DUPLICATE SELECT CODES
0656 05116 060001      LDA B
0657 05117 064000      IOL1 LDB A      CHANGE HANDS
0658 05120 057773      CPB P0.T0      END OF TABLE?
0659 05121 027100      JMP IOL0      YES MOVE TO NEXT IO CHIP
0660 05122 164000      LDB A,I      GET SC FROM TABLE
0661 05123 005665      ELB,CLE,FRB
0662 05124 157773      CPB P0.T0,I      IS IT THE SAME AS THE NEW SC?
0663 05125 027130      JMP *+3      YES - DUPLICATE SELECT CODES ERROR 3
0664 05126 002004      INA
0665 05127 027117      JMP IOL1      NO DO NEXT ENTRY
0666*
0667 05130 063535      LDA B3
0668 05131 027476      JMP IOFR
0669 05132 063536      IOE4 LDA B4
0670 05133 027476      JMP IOER

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0672*      CHECK IF ANY SELECT CODES DID NOT RESPOND TO MODE 1
0673*      IF THEY DIDN'T PRIORITY CHAIN IS BROKEN
0674*
0675 05134 102102 TON0 STF 2      INSURE GLOBAL REGISTER IS OFF
0676 05135 002400      CLA      TURN OFF DIAGNOSE MODE
0677 05136 102602      OTA 2
0678 05137 063542      LDA B17   START WITH FIRST SELECT CODE -1
0679 05140 073777      STA P0.CT
0680 05141 037777 TOL2 ISZ P0.CT  MOVE TO NEXT SC
0681 05142 067774      LDR P0.T1 CHECK IF IN TABLE
0682 05143 060001      LDA B     CHANGE HANDS
0683 05144 164000 TOL3 LDB A,I   GET SC FROM TABLE
0684 05145 006003      SZB,RSS   END OF TABLE?
0685 05146 027154      JMP ION1  YES
0686 05147 005665      FLB,CLE,FRB
0687 05150 057777      CPR P0.CT NO IS SC IN TABLE?
0688 05151 027141      JMP IOL2  YES
0689 05152 002004      INA
0690 05153 027144      JMP IOL3   NO MOVE TO NEXT ENTRY
0691 05154 067777 TON1 LDB P0.CT  GET SC
0692 05155 060001      LDA B     CHANGE HANDS
0693 05156 053551      CPA R100  END OF SC'S
0694 05157 027167      JMP ION2  YES
0695 05160 102602      OTA 2     NO TRY IT
0696 05161 002400      CLA
0697 05162 102502      LIA 2
0698 05163 002003      SZA,RSS   DID IT COME BACK?
0699 05164 027141      JMP IOL2  NO MOVE TO NEXT ONE
0700 05165 063534      LDA B2    YES - INDICATE ERROR 2
0701 05166 027476      JMP IOFR

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0703* CHECK INDIVIDUAL I/O CHIPS

0704*

0705	05167	167774	TON2	LDB PO.T1,J	START IO CHECK WITH FIRST ENTRY
0706	05170	002400		CLA	
0707	05171	006003		SZB,RSS	WERE THERE ANY ENTRIES?
0708	05172	027476		JMP IOER	NO IO CHIPS PRESENT ERROR 0
0709	05173	067774		LDB PO.T1	GET SC TABLE POINTER
0710	05174	077773		STB PO.T0	SET POINTER
0711	05175	167773	IOL4	LDB PO.T0,I	GET SELECT CODE
0712	05176	006103		CLF,SZB,RSS	END OF TABLE?
0713	05177	027354		JMP TON3	YES CKECK FOR BREAK ENABLE
0714	05200	005623		ELB,RBR	SAVE SELF TEST FLAG
0715	05201	107602		OTB 2,C	SET THE GLOBAL REGISTER AND ENABLE IT
0716	05202	002400		CLA	CLEAR INCASE NO RESPONSE
0717	05203	102502		LIA 2	GET GLOBAL REG.
0718	05204	050001		CPA B	DID IT COME BACK?
0719	05205	002001		RSS	
0720	05206	027474		JMP IOESC	NO DISPLAY SELECT CODE WITH ERROR
0721	05207	002041		SEZ,RSS	DOES THIS INTERFACE HAVE SELFTEST?
0722	05210	027225		JMP ION2A	NO - THEN DONT WAIT
0723	05211	063571		LDA M20	YES THEN WAIT 10 SECONDS FOR SELF TEST
0724	05212	102230		SFC DR	
0725	05213	027221		JMP *+6	
0726	05214	034001		ISZ B	
0727	05215	027212		JMP *-3	
0728	05216	034000		ISZ A	
0729	05217	027212		JMP *-5	
0730	05220	027474		JMP IOESC	TIME OUT SO FRROR
0731	05221	103530		LIA DR,C	GET SELF TEST STATUS AND CLEAR THE FLAG
0732	05222	002070		SSA	WAS IT GOOD?
0733	05223	000010		SLA	
0734	05224	027474		JMP IOESC	NU SO ERROR

*

0736	05225	063572	TON2A LDA ALTO	USE ALTERNATING PATTERN
0737	05226	102623	OTA 23B	TO CHECK I/O CHIP BUS UPPER
0738	05227	001300	RAR	AND OPPOSITE PATTERN
0739	05230	102624	OTA 24B	FOR I/O CHIP BUS LOWER
0740	05231	007400	CCB	CLEAR INCASE NO RESPONSE
0741	05232	002400	CLA	
0742	05233	102625	OTA 25B	SET FILE # TO 0 INCASE OF AUTO EXECUTION
0743	05234	102523	LIA 23B	READ PATTERNS BACK
0744	05235	106524	LIB 24B	
0745	05236	005200	RBL	
0746	05237	050001	CPA B	DO PATTERNS AGREE
0747	05240	006401	CLB,RSS	YES
0748	05241	027474	JMP IOESC	NO - I/O CHIP BUS ERROR
0749	05242	102624	OTA 24B	REVERSE PATTERN AND
0750	05243	001300	RAR	CHECK BUS AGAIN
0751	05244	102623	OTA 23B	
0752	05245	102524	LIA 24B	
0753	05246	106523	LIB 23B	
0754	05247	005200	RBL	
0755	05250	050001	CPA B	DO PATTERNS AGREE?
0756	05251	102230	SFC 30B	YES CHECK FLAG
0757	05252	027474	JMP IOESC	BUS OR FLAG ERROR
0758	05253	102130	STF 30B	SET THE I O FLAG
0759	05254	102230	SFC 30B	DID IT GET SET?
0760	05255	102330	SFS 30B	
0761	05256	027474	JMP IOESC	NO I/O FLAG ERROR
0762	05257	103130	CLF 30B	NOW CLEAR IT
0763	05260	102330	SFS 30B	DID IT GET CLEARED
0764	05261	102230	SFC 30B	
0765	05262	027474	JMP IOESC	NO I/O FLAG ERROR
0766*				
0767	05263	106723	CLC 23B	RESET DMA MACHINE

*

0769* CHECK DMA AND INTERRUPTS

0770*

0771	05264	103507	LIA 7,C	GET PAGE NO.
0772	05265	033352	IOR DMACF	INCLUDE DMA ADDRESS
0773	05266	102620	OTA 20P	PASS IT TO SELF CONFIGURATION REG
0774	05267	073761	STA DMA+1	AND PLACE IN TRIPLET
0775	05270	063351	LDA DMACW	GET DMA CONTROL WORD
0776	05271	073760	STA DMA	
0777	05272	063353	LDA DMACW+2	AND COUNT
0778	05273	073762	STA DMA+2	
0779	05274	063541	LDA B7	DISABLE SRQ INTERRUPTS
0780	05275	102602	OTA 2	
0781	05276	103720	STC 20P,C	DO SELFCONFIGURATION
0782	05277	102324	SFS 24R	DID IT COMPLETE
0783	05300	027474	JMP IOFSC	NO SO ERROR
0784	05301	102521	LIA 21R	CHECK CONTROL WORD
0785	05302	053351	CPA DMACW	
0786	05303	002001	RSS	
0787	05304	027474	JMP IOESC	BAD SO ERROR
0788	05305	102523	LIA 23B	CHECK COUNT
0789	05306	053353	CPA DMACW+2	
0790	05307	002001	RSS	
0791	05310	027474	JMP IOESC	NO GOOD SO ERROR
0792	05311	063535	LDA B3	NOW USE DIAG. MODE 3
0793	05312	102602	OTA 2	
0794	05313	102100	STF 0	TURN ON INTERRUPTS
0795	05314	002006	INA,SZA	WAIT FOR IT
0796	05315	027314	JMP *-1	
0797	05316	027474	JMP IOESC	NO GOOD
0798*				
0799	05317	102202	IOINT SFC 2	IS THIS A LEGAL INTERRUPT
0800	05320	027470	JMP ILINT	NO ILLEGAL
0801	05321	102504	LIA 4	CHECK CENTRAL INTERRUPT
0802	05322	106502	LIB 2	AGAINST GLOBAL REGISTER
0803	05323	050001	CPA B	WEILL?
0804	05324	002001	RSS	
0805	05325	027474	JMP IOESC	CARD ERROR
0806	05326	103507	LIA 7,C	GET BLOCK ADDRESS
0807	05327	033331	IOR **2	PUT SELF BACK ON PAGE
0808	05330	124000	JMP 0,I	
0809	05331	001332	DEF **1-P0	

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0811 05332 103507      LIA 7,C      GET ADDRESS AGAIN
0812 05333 033352      TOR DMACF
0813 05334 043537      ADA B5      MOVE TO CONFIGURATION ADDRESS
0814 05335 064000      LDB A
0815 05336 057762      CPB DMA+2    DID IT STORE
0816 05337 102274      SFC 24B     AND DID IT TURN OFF
0817 05340 027474      JMP IOESC    NO SO ERROR
0818 05341 102523      LIA 23B     CHECK COUNT IS ZERO
0819 05342 002002      SZA
0820 05343 027474      JMP IOFSC
0821 05344 107720      CLC 20B,C    INSURE DMA IS OFF
0822 05345 107721      CLC 21B,C
0823 05346 037773      ISZ P0.T0    MOVE TO NEXT ENTRY
0824 05347 037772      ISZ P0.A     COUNT THIS I/O CARD
0825 05350 027175      JMP IOL4    AND DO IT

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0826*

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0827 05760             DMA EQU 1760B+P0
0828 05351 000200      DMACW OCT 200
0829 05352 001760      DMACF DEF DMA-P0
0830 05353 177775      DEC -3

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0832* CHECK THAT ONLY ONE INTF. HAS A BREAK ENABLE

0833* NONE IS OK

0834*

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0835 05354 063534      ION3 LDA B2      USE DIAGNOSE MODE 2
0836 05355 067774      LDR P0.T1     SET POINTER FOR SELECT CODE
0837 05356 077773      STB P0.T0
0838 05357 006400      CLB
0839 05360 077775      STB P0.T2     CLEAR SC FLAG
0840 05361 102102      STF 2         TURN OFF GLOBAL REGISTER
0841 05362 102602      OTA 2
0842 05363 002400      IOL5 CLA        CLEAR IN CASE OF NO RESPONSE
0843 05364 102502      LIA 2         GET PARAMETERS
0844 05365 002002      SZA          DONE WITH I O
0845 05366 027371      JMP ION4      NO
0846 05367 102602      OTA 2         TURN OFF DIAG.MODE 2
0847 05370 027402      JMP ION5      YES NOW CHECK IF VCP OR LOADER
0848 05371 001710      ION4 ALF,SLA  CHECK BREAK FNABLE BIT
0849 05372 027375      JMP *+3
0850 05373 037773      ISZ P0.T0     MOVE TO NEXT ONE
0851 05374 027363      JMP IOL5
0852 05375 002744      CLA,SEZ,CCE,INA WAS THERE A PREVIOUS ONE
0853 05376 027476      JMP IOER     YES SO ERROR 1
0854 05377 067773      LDB P0.T0    NO OK SAVE THIS ONE
0855 05400 077775      STB P0.T2
0856 05401 027363      JMP IOL5     NOW TRY NEXT ONE

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0858	05402	067775	ION5	LDB PO.T2	CHECK IF THERE IS ONE
0859	05403	077773		STR PO.T0	
0860	05404	006003		SZB,RSS	WAS THERE ONE?
0861	05405	027455		JMP ION6	NO THEN SKIP ALL TEST
0862	05406	167773		LDB PO.T0,I	CHECK VCP CARD
0863	05407	006020		SSB	IF IT HAS A SELF TEST FORGET IT
0864	05410	027455		JMP ION6	IT DOES
0865	05411	107602		OTB 2,C	NO OUTPUT IT AND ENDABLE
0866	05412	002404		CLA,INA	NOW USE DIAGNOSE MODE TO GET ID
0867	05413	102602		OTA 2	
0868	05414	102502		LIA 2	
0869	05415	013550		AND IDM	USE ONLY ID
0870	05416	002002		SZA	IS IT A TIC
0871	05417	027455		JMP ION6	NO SKIP TEST
0872	05420	102501		LIA CPUT	SAVE %T FLAG
0873	05421	107700		CLC 0,C	RESET DIAGNOSE MODE 7
0874	05422	107602		OTB 2,C	REESTABLISH GLOBAL REGISTER
0875	05423	006404		CLB,INB	RESTORE %T FLAG
0876	05424	006004		INB	
0877	05425	002021		SSA,RSS	
0878	05426	006400		CLB	
0879	05427	106600		OTB 0	
0880	05430	002404		CLA,INA	ESTABLISH DIAG ON CARD
0881	05431	102632		OTA STS	
0882	05432	063572		LDA ALTO	
0883	05433	102630		OTA DR	USE ALTO
0884	05434	063561		LDA B3004	TELL IT TO TRANSMITT
0885	05435	102631		OTA CTL	
0886	05436	103730		STC DR,C	START TRANSMISSION
0887	05437	006400		CLB	
0888	05440	002400		CLA	SET FOR TIMEOUT
0889	05441	102230		SFC DR	CHECK FLAG
0890	05442	027447		JMP *+5	NOW CHECK DATA
0891	05443	002006		INA,SZA	TIMED OUT?
0892	05444	027441		JMP *-3	NO
0893	05445	102632		OTA STS	CLEAR DIAGNOSE MODE ON CARD
0894	05446	027474		JMP IOESC	AND REPORT ERROR
0895	05447	106632		OTB STS	CLEAR DIAGNOSE MODE
0896	05450	103530		LIA DR,C	GET DATA
0897	05451	023572		XOR ALTO	NOW CHECK DATA
0898	05452	013553		AND B377	ONLY LOWER BYTE
0899	05453	002002		SZA	
0900	05454	027474		JMP IOESC	NO GOOD
0901*					
0902	05455	002400	ION6	CLA	CLEAR DIAGNOSE MODE
0903	05456	102602		OTA 2	
0904	05457	106501		LIB CPUT	CHECK IF VCP TEST
0905	05460	006021		SSB,RSS	
0906	05461	027757		JMP DONE	NO NORMAL EXIT
0907	05462	107700		CLC 0,C	RESET THE WORLD
0908	05463	102600		OTA 0	YES CLEAR TEST FLAG
0909	05464	063554		LDA B207	AND RETURN TO VCP
0910	05465	027761		JMP DONE+2	

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0912*      ERROR REPORTING TO PROCESSOR LEDS
0913*
0914  05466 002404  PROER CLA,INA      INDICATE PROCESSOR ERROR
0915  05467 027500          JMP DSPLY
0916*
0917  05470 102504  ILINT LIA 4B      GET CENTRAL INTERRUPT REGISTER
0918  05471 001727          ALF,ALF    PUT IT IN DATA
0919  05472 002004          INA        INDICATE ILLEGAL INTERRUPT
0920  05473 027500          JMP DSPLY
0921*
0922  05474 167773  IOESC LDB P0.T0,I  GET SELECT CODE FOR DISPLAY
0923  05475 060001          LDA B      CHANGE HANDS
0924  05476 001727  IOER  ALF,ALF    PUT DATA IN UPPER HALF
0925  05477 033535          IOR B3     INDICATE IO TEST ERROR
0926*
0927*      DISPLAY LOWER BYTE (SECTION)
0928*      THEN UPPER BYTE (DATA )
0929*      THEN BACK TO LOWER BYTE
0930*
0931  05500 070001  DSPLY STA B        SAVE DATA AND SECTION
0932  05501 002300          CCF        SET TO DO SECOND PART
0933  05502 013552          AND B177
0934  05503 102601          OTA CPUST
0935  05504 034000          ISZ A
0936  05505 027504          JMP *-1
0937  05506 034000          ISZ A
0938  05507 027506          JMP *-1
0939  05510 034000          ISZ A
0940  05511 027510          JMP *-1
0941  05512 034000          ISZ A
0942  05513 027512          JMP *-1
0943  05514 002041          SEZ,RSS
0944  05515 027522          JMP PRTL P
0945  05516 060001          LDA B
0946  05517 001767          ALF,CLE,ALF
0947  05520 033551          IOR BIT6
0948  05521 027502          JMP DSPLY+2  UPPER HALF DATA
0949  05522 102501  PRTL P LIA CPUST   CHECK IF LOOP
0950  05523 001727          ALF,ALF
0951  05524 013541          AND B7
0952  05525 002003          SZA,RSS     ??
0953  05526 026713          JMP TPF+2   YES LOOP ON ERROR
0954  05527 060001          LDA B
0955  05530 027501          JMP DSPLY+1

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0957* CONSTANTS

0958*

0959	05531	001677	IOLP	DEF	P0.CT-77B-P0-1	
0960	05532	001763	VCPO	DEF	POVCP-P0	START OF RFP ONLY ON THIS PAGE
0961	05533	000001	B1	OCT	1	
0962	05534	000002	B2	OCT	2	
0963	05535	000003	B3	OCT	3	
0964	05536	000004	B4	OCT	4	
0965	05537	000005	B5	OCT	5	
0966	05540	000006	B6	OCT	6	
0967	05541	000007	B7	OCT	7	
0968	05542	000017	B17	OCT	17	
0969	05543	000020	B20	OCT	20	
0970	05544	000024	B24	OCT	24	
0971	05545	000037	B37	OCT	37	
0972	05546	000040	B40	OCT	40	
0973	05547	100077	SCM	OCT	100077	
0974	05550	077000	IDM	OCT	077000	ID ONLY NO SC OR REV.
0975	05551	000100	B100	OCT	100	
0976	05552	000177	B177	OCT	177	
0977	05553	000377	B377	OCT	377	
0978	05554	000207	B207	OCT	207	
0979	05555	000604	B604	OCT	604	
0980	05556	001000	B1000	OCT	1000	
0981	05557	001776	B1776	OCT	1776	
0982	05560	001777	B1777	OCT	1777	
0983	05561	003004	B3004	OCT	3004	
0984	05562	006412	B6412	OCT	6412	
0985	05563	007777	B7777	OCT	7777	
0986	05564	036000	B16K	OCT	36000	
0987	05565	076000	B76K	OCT	76000	
0988	05566	100000	B100K	OCT	100000	
0989	05567	177777	M1	OCT	-1	
0990	05570	177776	M2	OCT	-2	
0991	05571	177760	M20	OCT	-20	
0992	05546		RIT5	EQU	B40	
0993	05551		RIT6	EQU	B100	
0994	05572	052525	ALT0	OCT	052525	
0995	05573	125252	ALT1	OCT	125252	
0996	05574	104447	SRGP1	OCT	104447	1000100100100111
0997	05575	114040	SRGP2	OCT	114040	1001100000100000
0998	05576	000100	SRGP3	OCT	000100	0000000001000000
0999	05577	076310	AEAUS	OCT	076310	
1000	05600	130272	BEAUS	OCT	130272	
1001	05601	107714	ASR.0	OCT	107714	
1002	05602	041300	ASR.1	OCT	041300	
1003	05603	143746	MU2	OCT	143746	
1004	05604	123746	DV4	OCT	123746	
1005	05605	126760	RESUA	OCT	126760	
1006	05606	006606	RESUB	OCT	006606	
1007*						
1008	05607		FOP0	EQU	*	END OF PAGE 0
1009	05757			ORG	5757B	
1010	00150		RAP0	EQU	*-FOP0	

PAGE 0028 #01

* HP 1000 L/20-SERIES PRETEST PAGE 0

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1012*      CROSS OVER TO OTHER PAGE
1013*
1014 05757 063555 DONE LDA B604      GET SWITCH FOR LOADER PAGE 3
1015 05760 006400      CLR
1016 05761 102601      OTA CPUST     MAKE SWITCH
1017 05762 024100      JMP 100B      LOOP ON PRETEST IF ERROR
1018*
1019*      BREAK ENTRY POINT (SAME ON ALL PAGES)
1020*
1021 05763 103105 POVCP CLF 5        INSURE PARITY SENSE
1022 05764 106713      CLC 13B      DISABLE MAPPING
1023 05765 103300      OCT 103300   SFS 0,C CHECK INTERRUPTS
1024 05766 027772      JMP *+4      THERE OFF
1025 05767 073772      STA P0.A      SAVE THE A REG.
1026 05770 003400      CCA          INDICATE INTS ON
1027 05771 027774      JMP *+3
1028 05772 073772      STA P0.A
1029 05773 002400      CLA
1030 05774 073764      STA P0.I
1031 05775 063554      LDA B207      GET SWITCH TO VCP PAGE
1032 05776 102601      OTA CPUST     MAKE SWITCH
1033 05777 027763      JMP POVCP     LOOP IF ERROR
1034*
1035*      COMMON STORAGE LOCATIONS
1036*
1037 05777      P0.CT EQU 1777B+P0
1038 05776      P0.T3 EQU 1776B+P0
1039 05775      P0.T2 EQU 1775B+P0
1040 05774      P0.T1 EQU 1774B+P0
1041 05773      P0.T0 EQU 1773B+P0
1042 05772      P0.A  EQU 1772B+P0
1043 05771      P0.B  EQU 1771B+P0
1044 05770      P0.E  EQU 1770B+P0
1045 05767      P0.O  EQU 1767B+P0
1046 05766      P0.GF EQU 1766B+P0
1047 05765      P0.M  EQU 1765B+P0
1048 05764      P0.I  EQU 1764B+P0
1049 05763      P0.EM EQU 1763B+P0
1050 05762      P0.DF EQU 1762B+P0
1051 05761      P0.UN EQU 1761B+P0
1052 05760      P0.FL EQU 1760B+P0
1053 05757      P0.SB EQU 1757B+P0
1054 05756      P0.SC EQU 1756B+P0
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1056	06000		ORG 6000B	
1057	06000	P1	EQU *	PAGE 1 REFERENCE
1058*				
1059	06000	000000	NOP	SPACE HOLDERS
1060	06001	000000	NOP	B REG.
1061	06002	124000	JMP A,I	RETURN FROM DIAGNOSE MODE READS
1062	06003	000000	NOP	
1063	06004	000000	NOP	POWER FAIL INT
1064	06005	000000	NOP	PARITY ERROR
1065	06006	000000	NOP	TBG
1066	06007	000000	NOP	MP
1067	06010	000000	NOP	UIT

1069* III. ASCII FRONT PANEL PROGRAM

1070*

1071	06011	077771	VCP	STB P1.B	SAVE B-REG.
1072	06012	002440		CLA,SEZ	
1073	06013	003400		CCA	
1074	06014	073770		STA P1.E	SAVE E-REG.
1075	06015	102201		SOC	
1076	06016	003401		CCA,RSS	
1077	06017	002400		CLA	
1078	06020	073767		STA P1.O	SAVE O-REG.
1079	06021	002400		CLA	SET IF NO RESPONSE TO LIA 2
1080	06022	102502		LIA 2	GET GLOBAL REG.
1081	06023	102302		SFS 2	IS GLOBAL REGISTER ENABLED?
1082	06024	033434		IOR .100K	ADD BIT 15 IF TURNED ON
1083	06025	073766		STA P1.GF	SAVE GLOBAL FLAG
1084	06026	006400		CLB	
1085	06027	102102		STF 2	DISBLE GLOBAL REGISTER
1086	06030	106602		OTB 2	INSURE DIAG. MODE IS DISABLED
1087	06031	063426		LDA .2100	SAVE DATA ON SECOND PAGE
1088	06032	164000		LDB A,I	
1089	06033	077773		STB P1.T0	
1090	06034	007400		CCB	NOW MAKE LOCATION -1
1091	06035	174000		STB A,I	
1092	06036	064100		LDB 100B	NOW SAVE MAP DATA
1093	06037	077774		STB P1.T1	
1094	06040	002404		CLA,INA	POINT MAP TO SECOND PAGE
1095	06041	070100		STA 100B	
1096	06042	102713		STC 13B	RE ENABLE MAPS
1097	06043	064100		LDB 100B	GET DATA
1098	06044	006021		SSB,RSS	IF NEGATIVE THEN MAPS ON
1099	06045	006400		CLB	OTHERWISE MAPS OFF
1100	06046	106711		CLC 11B	NOW TURN MAPPING OFF
1101	06047	026050		JMP *+1	DO IT
1102	06050	077763		STB P1.EM	SAVE FLAG
1103	06051	063426		LDA .2100	NOW RESTOR DATA AND MAP REG.
1104	06052	067773		LDB P1.T0	DATA
1105	06053	174000		STB A,I	
1106	06054	067774		LDB P1.T1	AND MAP
1107	06055	074100		STB 100B	

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1109	06056	063404	VCP0	LDA .207	INDICATE IN VCP
1110	06057	102601		OTA CPUT	
1111	06060	017743		JSR RP.SC	SET FOR SYSTEM CONSOLE
1112	06061	107723		CLC 23B,C	TURN OFF DMA
1113	06062	106532		LIB STS	CLEAR BREAK FLAG
1114	06063	005226		RBL,ELB	PUT BREAK BIT IN E REG.
1115	06064	107503		LIB 3,C	GET SINGLE CYCLE FLAG BIT
1116	06065	102503		LIA 3	SET M = TO P-1
1117	06066	006061		SEZ,SSB,RSS	IF HALT ONLY
1118	06067	043435		ADA .M1	
1119	06070	001665		ELA,CLE,ERA	
1120	06071	073765		STA P1.M	
1121	06072	005665		ELB,CLF,FRB	CLEAR SINGLE
1122	06073	107603		OTB 3,C	
1123	06074	063337		LDA DFI	OUT PUT BASIC REGISTERS
1124	06075	073762		STA P1.DF	
1125	06076	102502		LIA 2	GET GLOBAL REG
1126	06077	053410		CPA .20	NORMAL CONSOLE
1127	06100	026111		JMP VCP1	YES - SKIP DS CLEAN UP
1128	06101	002006		INA,SZA	ALLOW TIME FOR SET UP
1129	06102	026101		JMP *-1	
1130	06103	062107		LDA CSVCP	NOW CLEAN UP DS CARD
1131	06104	017746		JSB CS.FT	
1132	06105	026206		JMP PRST	NO MORE TRY RESETING THE COMPUTER
1133	06106	017745		JSR CS.CM	TELL CARD TO GO INTO VCP MODE
1134	06107	067400	CSVCP	OCT 67400	
1135	06110	026741		JMP CRLF	
1136	06111	063425	VCP1	LDA .1000	SET TRANSMITT
1137	06112	102632		OTA STS	TAKE IT OUT OF DIAG MODE
1138	06113	102631		OTA CTL	
1139	06114	102630		OTA DR	TRANS. A NULL
1140	06115	103730		STC DR,C	
1141	06116	002400		CLA	
1142	06117	002007		INA,SZA,RSS	
1143	06120	026206		JMP PRST	TIMED OUT SO RESET COMPUTER
1144	06121	102330		SFS DR	
1145	06122	026117		JMP *-3	
1146	06123	026741		JMP CRLF	

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1148	06124	103503	EXITS	LIA 3,C	SET SINGLE CYCLE FLAG
1149	06125	033434		IOR .100K	
1150	06126	103603		OTA 3,C	
1151	06127	006401		CLB,RSS	
1152	06130	007400	EXIT	CCB	SET RUN
1153	06131	077773		STB P1.T0	
1154	06132	102503		LIA 3	GET RUN (SINGLE CYCLE) ADDRESS
1155	06133	073774		STA P1.T1	
1156	06134	063423		LDA .377	SET VCP FLAG AND PROG IN EXC.
1157	06135	102601		OTA CPUST	
1158	06136	003500		CCA,CLE	
1159	06137	102624		OTA 24B	
1160	06140	102603		OTA 3	CLEAR AUTO FLAG
1161	06141	102102		STF 2	TURN OFF GLOBAL REG.
1162	06142	067766		LDB P1.GF	GET GLOBAL REG. AND FLAG
1163	06143	005621		ELB,BRS	MOVE FLAG TO E REG.
1164	06144	006002		SZB	DID GR HAVE A VALUE
1165	06145	106602		OTB 2	
1166	06146	002040		SEZ	
1167	06147	103102		CLF 2	TURN IT ON IF PREVIOUSLY ON
1168	06150	067770		LDB P1.E	SET UP E-REG.
1169	06151	005500		FRB	
1170	06152	103101		CLO	
1171	06153	067767		LDR P1.0	AND O-REG.
1172	06154	006020		SSB	
1173	06155	102101		STO	
1174	06156	067764		LDB P1.1	REVERSE INTERRUPT SENSE
1175	06157	007000		CMR	
1176	06160	077764		STR P1.I	
1177	06161	067763		LDB P1.EM	AND MAP FLAG
1178	06162	007000		CMB	
1179	06163	077763		STR P1.EM	
1180	06164	067772		LDR P1.A	RESTORE A & B REGISTERS
1181	06165	060001		LDA B	
1182	06166	067771		LDR P1.B	
1183	06167	037773		ISZ P1.T0	SINGLE CYCLE?
1184	06170	026177		JMP EXITN	YES
1185	06171	037763		ISZ P1.EM	WAS EXTENDED MEMORY ON?
1186	06172	102711		STC 11B	YES THEN TURN IT ON
1187	06173	037764		ISZ P1.I	
1188	06174	102100		STF 0	TURN ON INTERRUPTS
1189	06175	102702		STC 2	TURN OFF ROM
1190	06176	127774		JMP P1.T1,I	START EXECUTION
1191	06177	037763	EXITN	ISZ P1.EM	WAS EXTENDED MEMORY ON?
1192	06200	102711		STC 11B	YES TURN IT ON
1193	06201	037764		ISZ P1.I	
1194	06202	102100		STF 0	
1195	06203	106703		CLC 3	
1196	06204	102702		STC 2	
1197	06205	127774		JMP P1.T1,I	

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1199*

1200	06206	107700	PRST	CLC 0,C	GENERATE CRS
1201	06207	002400		CLA	CLEAR INTERRUPTS
1202	06210	073764		STA P1.I	
1203	06211	102600		OTA 0	AND MASK REGISTER
1204	06212	073763		STA P1.EM	AND MAPPS
1205	06213	067766		LDB P1.GF	CLEAR GLOBAL REG. ENABLE
1206	06214	005665		ELB,CLE,ERB	
1207	06215	077766		STR P1.GF	
1208	06216	026056		JMP VCP0	
1209*					
1210	06217	063403	CLMEM	LDA .2	GET STARTING ADDRESS
1211	06220	006400		CLB	
1212	06221	106603		OTB 3	CLEAR P REGISTER
1213	06222	174000		STB A,I	CLEAR MEMORY
1214	06223	154000		CPB A,I	DID IT STORE?
1215	06224	002005		INA,RSS	YES
1216	06225	026206		JMP PRST	NO THEN END OF MEMORY
1217	06226	002021		SSA,RSS	DONE ALL OF MEMORY
1218	06227	026222		JMP *-5	NO DO NEXT LOCATION
1219	06230	102711		STC 11B	TURN MAPS ON AND
1220	06231	026232		JMP *+1	
1221	06232	106713		CLC 13B	
1222	06233	063413		LDA .40	NOW CLEAR EXTENDED MEMORY
1223	06234	070137	CLM0	STA 137B	
1224	06235	102713		STC 13B	
1225	06236	063432		LDA .76K	LAST PAGE
1226	06237	007400		CCB	IS MAPPING THERE
1227	06240	174000		STB A,I	
1228	06241	106713		CLC 13B	
1229	06242	154000		CPB A,I	??
1230	06243	026264		JMP CLM2	NO
1231	06244	102713		STC 13B	
1232	06245	006400		CLB	
1233	06246	174000	CLM1	STB A,I	
1234	06247	164000		LDB A,I	CHECK IF STORED
1235	06250	006002		SZB	
1236	06251	026264		JMP CLM2	NO THEN END OF MEMORY
1237	06252	002004		INA	
1238	06253	002021		SSA,RSS	
1239	06254	026246		JMP CLM1	
1240	06255	106713		CLC 13B	DISABLE MAPS
1241	06256	064137		LDB 137B	MOVE TO NEXT PAGE
1242	06257	101100		RRR 16	
1243	06260	053423		CPA .377	END OF MEMORY?
1244	06261	026264		JMP *+3	
1245	06262	002004		INA	NO MOVE TO NEXT LOCATION
1246	06263	026234		JMP CLM0	
1247	06264	106713	CLM2	CLC 13B	DISABLE MAPS
1248	06265	006400		CLB	
1249	06266	174000		STB A,I	
1250	06267	074137		STR 137B	CLEAR MAPS
1251	06270	026206		JMP PRST	YES NOW PRESET THE REST

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1253	06271	063423	EXECU	LDA .377	INDICATE
1254	06272	102601		OTA CPUST	PROGRAM IN EXECUTION
1255	06273	003400		CCA	
1256	06274	102603		OTA 3	CLEAR AUTO FLAG
1257	06275	006400		CLB	NO PARAMETERS
1258	06276	102702		STC 2	TURN OFF ROM
1259	06277	024002		JMP 2	AND START PROGRAM AT LOCATION 2

1261	06300	017747	LOAD	JSB IN1C	GET NEXT CHR FOR LOADER TYPE
1262	06301	001727		ALF,ALF	
1263	06302	073775		STA P1.T2	
1264	06303	017747		JSB IN1C	
1265	06304	067775		LDB P1.T2	
1266	06305	030001		IOR R	
1267	06306	073775		STA P1.T2	
1268	06307	103503		LIA 3,C	GET CURRENT PAGE
1269	06310	013432		AND .76K	MASK LOWER BITS
1270	06311	033430		IOR .1700	ADD POINTER
1271	06312	073762		STA P1.DF	SAVE IT
1272	06313	006500		CLB,CLE	
1273	06314	174000		STR A,I	CLEAR LOCATION
1274	06315	001200		RAL	MAKE IT BYTE ADDRESS
1275	06316	073776		STA P1.T3	SAVE IT
1276	06317	063441		LDA .N20	SET MAX INPUT
1277	06320	073777		STA P1.CT	
1278	06321	017754		JSB IN.N	
1279	06322	067773		LDB P1.T0	CHECK IF LOAD AND GO
1280	06323	101100		RRR 16	SWAP REGISTERS
1281	06324	053354		CPA SL	IS IT A LOAD ONLY
1282	06325	026360		JMP LOAD2	YES
1283	06326	053362		CPA SW	IS THIS A WRITE
1284	06327	026360		JMP LOAD2	YES THEN NO FILE NAME
1285	06330	101100		RRR 16	NO SWAP REGISTERS AGAIN
1286	06331	073773		STA P1.T0	SAVE CHR
1287	06332	053406		CPA .15	IF RETURN ONLY
1288	06333	026365		JMP LOADC	THEN DEFAULT
1289	06334	026341		JMP LOAD1	PROCESS THE CHR

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1291	06335	017747	LOAD0	JSB IN1C	GET A CHARACTER
1292	06336	073773		STA P1.T0	SAVE IT
1293	06337	053406		CPA .15	END OF INPUT?
1294	06340	026365		JMP LOADC	YES DO BOOT
1295	06341	067776	LOAD1	LDB P1.T3	PUT CHR IN BUFFER
1296	06342	004065		CLE,ERB	ADDR. UPPER/LOWER
1297	06343	060001		LDA B	CHANGE HANDS
1298	06344	164000		LDB A,I	
1299	06345	047773		ADB P1.T0	
1300	06346	002041		SEZ,RSS	
1301	06347	005727		BLF,BLF	
1302	06350	174000		STB A,I	
1303	06351	006400		CLB	CLEAR NEXT LOCATION
1304	06352	002004		INA	
1305	06353	174000		STB A,I	
1306	06354	102101		STO	INDICAT TEXT HAS STARTED
1307	06355	037776		ISZ P1.T3	
1308	06356	037777		ISZ P1.CT	OVER
1309	06357	026335		JMP LOAD0	NO DO ANOTHER CHR
1310	06360	101100	LOAD2	RRR 16	SWAP REGISTERSLT
1311	06361	053406		CPA .15	WAS IT A CR?
1312	06362	002401		CLA,RSS	YES PROCEED
1313	06363	026735		JMP INQ!?	NO
1314	06364	073762		STA P1.DF	
1315	06365	063415	LOADC	LDA .6412	DO CRLF
1316	06366	017751		JSB OUT2C	
1317	06367	107700		CLC 0,C	
1318	06370	067775		LDB P1.T2	GET ASCII CHARACTERRS
1319	06371	027760		JMP CRSP3	GO TO LOADERS
1320*					
1321	06372	006002	LDRTN	SZB	VCP START?
1322	06373	026056		JMP VCP0	YES
1323	06374	017743		JSB RP.SC	RESET GLOBAL REG
1324	06375	053410		CPA .20	NORMAL CONSOLE?
1325	06376	026402		JMP *+4	YES
1326	06377	062107		LDA CSVCP	GET VCP MODE COMMAND
1327	06400	017746		JSB CS.FT	NO - THEN TELL DS TO GO INTO VCP MODE
1328	06401	026056		JMP VCP0	ERROR
1329	06402	063376	LDRTC	LDA \$LC	CHCK IF LOAD COMPLETE OR ERROR
1330	06403	067755		LDB P1ERR	GET FLAG
1331	06404	006002		SZB	
1332	06405	026410		JMP *+3	ERROR
1333	06406	017751		JSB OUT2C	OUTPUT RESULTS
1334	06407	026737		JMP INQLF	
1335	06410	063377	LD RTE	LDA \$ER	INDICATE ERROR
1336	06411	017751		JSB OUT2C	
1337	06412	063413		LDA .40	AND SPACE
1338	06413	017752		JSB OUT1C	
1339	06414	067755		LDB P1ERR	NOW ERROR ADDRESS
1340	06415	000040		CLE	FULL 16 BITS
1341	06416	017753		JSB OUT.N	
1342	06417	026737		JMP INQLF	

1344* SET UP MAPS

1345*

1346	06420	017754	MAPST	JSB IN.N	GET STARTING MAP
1347	06421	053406		CPA .15	IS THAT RIGHT?
1348	06422	026424		JMP *+2	
1349	06423	026735		JMP INQ!?	NO
1350	06424	067774		LDB P1.T1	YES
1351	06425	063417		LDA .100	
1352	06426	174000		STB A,I	
1353	06427	002004		INA	
1354	06430	053470		CPA .140	
1355	06431	026737		JMP INQLF	
1356	06432	006004		INB	
1357	06433	026426		JMP *-5	
1358*					
1359	06434	107700	PTST	CLC 0,C	RESET SYSTEM
1360	06435	063403		LDA .2	
1361	06436	102600		OTA 0	SET VCP PRETEST FLAG BIT
1362	06437	002400		CLA	
1363	06440	027761		JMP CRSP3+1	DO IT

1365	06441	067762	INQ	LDB P1.DF	CHECK FOR FIRST ENTRY
1366	06442	006003		SZB,RSS	
1367	06443	026461		JMP INQ.	
1368	06444	160001		LDA B,I	GET PARAMETER
1369	06445	006004		INB	MOVE TO NEXT
1370	06446	053344		CPA DFL.	END OF TRANSFER
1371	06447	006400		CLB	YES
1372	06450	077762		STR P1.DF	
1373	06451	067763		LDB P1.EM	CHECK IF MAPS ARE ON
1374	06452	006003		SZB,RSS	
1375	06453	026456		JMP *+3	NO
1376	06454	053344		CPA ST	YES - IF DISPLAYING T THEN USE U
1377	06455	063356		LDA \$U	
1378	06456	073773		STA P1.TO	SAVE CHARACTER
1379	06457	017752		JSB OUT1C	OUTPUT PARAMETER
1380	06460	026543		JMP INQ.1	NOW PRINT THE VALUE
1381	06461	002400	INQ.	CLA	TELL DS TO TRANSMITT AND GET A BUFFER
1382	06462	017744		JSB CS.TR	ONLY IF IT IS REALLY DS
1383	06463	017747		JSB IN1C	NOW GET INPUT
1384	06464	073773		STA P1.TO	SAVE FIRST CHARACTER
1385	06465	053363		CPA \$%	CONTROL FUNCTION?
1386	06466	002001		RSS	
1387	06467	026517		JMP INQ.0	NO
1388	06470	017747		JSB IN1C	GET NEXT CHARACTER
1389	06471	073773		STA P1.TO	SAVE THE CHR
1390	06472	053357		CPA \$R	IS THIS A RUN COMMAND?
1391	06473	026130		JMP EXIT	YES
1392	06474	053360		CPA SS	IS THIS A SINGLE CYCLE?
1393	06475	026124		JMP EXITS	YES
1394	06476	053340		CPA SP	IS THIS A PRESET?
1395	06477	026206		JMP PRST	YES
1396	06500	053352		CPA SC	CLEAR MEMOPY?
1397	06501	026217		JMP CLMEM	YES
1398	06502	053346		CPA SE	EXECUTE AT 4
1399	06503	026271		JMP EXECU	YES
1400	06504	053354		CPA SL	LOAD?
1401	06505	026300		JMP LOAD	YES
1402	06506	053342		CPA SB	BOOT (LOAD AND GO)?
1403	06507	026300		JMP LOAD	YES
1404	06510	053362		CPA SW	WRITE
1405	06511	026300		JMP LOAD	YES
1406	06512	053343		CPA \$M	MAP SET UP?
1407	06513	026420		JMP MAPST	YES
1408	06514	053344		CPA ST	SELF TEST?
1409	06515	026434		JMP PTST	YES
1410	06516	026735		JMP INQ!?	NONE SO ERROR

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1412	06517	053357	INQ.0	CPA SR	I/O REGISTERS
1413	06520	002001		RSS	YES
1414	06521	026527		JMP **6	NO
1415	06522	017747		JSB IN1C	GET NEXT NUMBER
1416	06523	067773		LDB P1.T0	NOW PUT THFM TO GETHER
1417	06524	005727		BLF,BLF	
1418	06525	030001		IOR B	
1419	06526	073773		STA P1.T0	SAVE IT
1420	06527	102502		LIA 2	CHECK IF DS
1421	06530	053410		CPA .20	
1422	06531	026543		JMP INQ.1	NO
1423	06532	067773	INQ#	LDB P1.T0	YES ECHO CHR
1424	06533	060001		LDA B	
1425	06534	001727		ALF,ALF	
1426	06535	013422		AND .177	
1427	06536	002002		SZA	OUTPUT UPPER?
1428	06537	017752		JSB OUT1C	YES
1429	06540	067773		LDB P1.T0	
1430	06541	060001		LDA B	
1431	06542	017752		JSB OUT1C	NOW LOWER

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1433	06543	063413	INQ.1	LDA .40	OUTPUT A SPACE
1434	06544	017752		JSB OUT1C	
1435	06545	067773		LDB P1.TC	GET CHARACTER AGAIN
1436	06546	060001		LDA B	CHANGE HANDS
1437	06547	000040		CLE	
1438	06550	067772		LDB P1.A	
1439	06551	053341		CPA SA	IS IT A-REG. ?
1440	06552	026745		JMP CH.OK	YES
1441	06553	067771		LDB P1.B	
1442	06554	053342		CPA SB	IS IT B-REG. ?
1443	06555	026745		JMP CH.OK	YES
1444	06556	106503		LIR 3	
1445	06557	053340		CPA SP	IS IT P-REG. ?
1446	06560	026745		JMP CH.OK	YES
1447	06561	107507		LIR 7,C	
1448	06562	053361		CPA SV	IS IT THE VIOLATION REG.?
1449	06563	026745		JMP CH.OK	YES
1450	06564	106504		LIR 4	
1451	06565	053352		CPA SC	IS IT THE CENTRAL INTERRUPT REG.?
1452	06566	026745		JMP CH.OK	YES
1453	06567	067770		LDB P1.E	
1454	06570	053346		CPA SE	IS IT E-REG. ?
1455	06571	026744		JMP CH.OK-1	YES
1456	06572	067767		LDB P1.O	
1457	06573	053347		CPA SO	IS IT O-REG. ?
1458	06574	026744		JMP CH.OK-1	YES
1459	06575	067764		LDB P1.I	
1460	06576	053350		CPA SI	IS IT INTERRUPT STATUS ?
1461	06577	026744		JMP CH.OK-1	YES
1462	06600	067763		LDB P1.EM	
1463	06601	053351		CPA SK	EXTENDED MEMORY FLAG
1464	06602	026744		JMP CH.OK-1	YES
1465	06603	067766		LDB P1.GF	
1466	06604	053345		CPA SG	IS IT GLOBAL-REG. ?
1467	06605	026745		JMP CH.OK	YES
1468	06606	067765		LDB P1.M	
1469	06607	053343		CPA SM	IS IT MEMORY ?
1470	06610	026745		JMP CH.OK	YES
1471	06611	005100		BRS	CHECK IF A OR B ADDRESSABLE
1472	06612	006003		SZB,RSS	
1473	06613	026627		JMP INQ.2	YES
1474	06614	167765		LDB P1.M,I	
1475	06615	053344		CPA ST	IS IT DATA FROM MEMORY
1476	06616	026745		JMP CH.OK	YES
1477	06617	067765		LDB P1.M	GET ADDRESS
1478	06620	102711		STC 11B	TURN ON MAPS
1479	06621	026622		JMP *+1	ENABLE THEM
1480	06622	164001		LDB R,I	GET DATA
1481	06623	106711		CLC 11B	NOW TURN THEM OFF
1482	06624	026625		JMP *+1	
1483	06625	053356		CPA SU	CROSS MAP LOAD?
1484	06626	026745		JMP CH.OK	YES

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1486* CHECK FOR I/O REGISTERS

1487*

1488	06627	067766	INQ.2	LDB P1.GF	GET GLOBAL REGISTER
1489	06630	107602		OTR 2,C	YES SET IT UP AND ENABLE IT
1490	06631	006400		CLB	CLEAR INCASE NO RESPONSE
1491	06632	106502		LIB 2	CHECK IF THERE IS A CARD
1492	06633	006003		SZB,RSS	
1493	06634	026715		JMP INQRX	NO CARD SO ERROR
1494	06635	006400		CLB	
1495	06636	106500	LIB	LIB 0	GET INTERRUPT MASK
1496	06637	053401		CPA SRM	IS THIS IT?
1497	06640	026733		JMP INQ.3	YES
1498	06641	106520		LIB 20B	GET SELF-CONFIGURATION REGISTER
1499	06642	053364		CPA SR0	IS THIS IT?
1500	06643	026733		JMP INQ.3	YES
1501	06644	106521		LIB 21B	GET CONTROL REGISTER
1502	06645	053365		CPA SR1	IS THIS IT?
1503	06646	026733		JMP INQ.3	YES
1504	06647	106522		LIB 22B	GET ADDRESS REGISTER
1505	06650	053366		CPA SR2	IS THIS IT?
1506	06651	026733		JMP INQ.3	YES
1507	06652	106523		LIB 23B	GET COUNT REGISTER
1508	06653	053367		CPA SR3	IS THIS IT?
1509	06654	026733		JMP INQ.3	YES
1510	06655	053370		CPA SRD	DATA REGISTER
1511	06656	026726		JMP INQRD	YES
1512	06657	053371		CPA SRC	CONTROL REGISTER
1513	06660	026730		JMP INQRC	YES
1514	06661	053372		CPA SRS	STATUS REGISTER
1515	06662	026732		JMP INQRS	YES
1516	06663	006404		CLB,INB	GET READY FOR DIAG. MODE 1
1517	06664	053373		CPA SRI	IS IT?
1518	06665	026717		JMP INQDM	YES
1519	06666	006004		INB	HOW ABOUT DIAG.2
1520	06667	053374		CPA SRX	DIAG. MODE 2?
1521	06670	026717		JMP INQDM	YES
1522	06671	006400		CLB	CHECK FLAGS
1523	06672	102220		SFC 20B	SELF DMA?
1524	06673	006004		INB	
1525	06674	005723		BLF,RBR	MOVE OVER 3
1526	06675	102221		SFC 21B	
1527	06676	006004		INB	
1528	06677	005723		BLF,RBR	
1529	06700	102222		SFC 22B	
1530	06701	006004		INB	
1531	06702	005723		BLF,RBR	
1532	06703	102223		SFC 23B	
1533	06704	006004		INB	
1534	06705	005723		BLF,RBR	
1535	06706	102224		SFC 24B	
1536	06707	006004		INB	
1537	06710	005723		BLF,PBR	
1538	06711	102230		SFC 30B	
1539	06712	006004		INB	
1540	06713	053375		CPA SRF	FLAGS REQUEST?

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1541	06714	026733	JMP INQ.3	YES
1542	06715	017743	INQRX JSB RP.SC	RESET GLOBAL REGISTER
1543	06716	026735	JMP INQ!?	NONE SO ERROR
1544	06717	102502	INQDM LIA 2	GET SELECT CODE
1545	06720	013416	AND .77	
1546	06721	032636	IOR LIB	BUILD LIA INSTRUCTION FOR SELECT CODE
1547	06722	106602	OTB 2	OUTPUT DIAGNOSE MODE
1548	06723	064000	LDB A	
1549	06724	014000	JSB 0	EXECUTE INSTRUCTION
1550	06725	026733	JMP INQ.3	DIASPLAY DATA
1551	06726	106530	INQRD LIB 30B	GET DATA REGISTER
1552	06727	026733	JMP INQ.3	
1553	06730	106531	INQRC LIB 31B	GET CONTROL REGISTER
1554	06731	026733	JMP INQ.3	
1555	06732	106532	INQRS LIB STS	GET STATUS REGISTER
1556	06733	017743	INQ.3 JSB RP.SC	RESET GLOBAL REGISTER
1557	06734	026745	JMP CH.OK	
1559	06735	063400	INQ!?	NONE OF THE ABOVE
1560	06736	017751	JSB OUT2C	THEN TELL OPERATOR
1561	06737	002400	INQLF CLA	
1562	06740	073762	STA P1.DF	DON'T CONTINUE STRING
1563	06741	063415	CRLF LDA .6412	CARRIAGE RETURN LINE FEED
1564	06742	017751	JSB OUT2C	
1565	06743	026441	JMP INQ	
1567	06744	002300	CCE	ONLY ONE DIGIT
1568	06745	017753	CH.OK JSB OUT.N	OUTPUT NUMBER OUTPUT
1569	06746	067762	LDB P1.DF	CHECK IF STRING OUTPUT
1570	06747	006002	SZB	
1571	06750	026441	JMP INQ	YES
1572	06751	077776	STB P1.T3	CLEAR INC-DEC FLAG

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1574	06752	017744	JSB CS.TR	TELL DS TO XMIT AND GET BUFFFFR
1575	06753	017754	JSB IN.N	INPUT A NUMBER
1576	06754	053406	CPA .15	IS THAT ALL?
1577	06755	026765	JMP ST.N	YES
1578	06756	053355	CPA \$N	INCREMENT MEMORY LOCATION?
1579	06757	027072	JMP ST.NO	YES CHECK IF T ENTRY
1580	06760	053353	CPA \$D	DECREMENT MEMORY LOCATION
1581	06761	027072	JMP ST.NO	YES
1582	06762	102201	SOC	WAS THERE A NUMBER?
1583	06763	026735	JMP INQ!?	NO
1584	06764	026464	JMP INQ.+3	YES
1585	06765	067773	ST.N LDB P1.T0	GET ORIGINAL CHARACTER
1586	06766	060001	LDA B	CHANGE HANDS
1587	06767	067774	LDB P1.T1	GET DATA THAT WAS INPUT
1588	06770	102301	SOS	ANY INPUT?
1589	06771	026741	JMP CRLF	NO GO ASK FOR SOME
1590	06772	006042	SEZ,\$ZB	IF ONLY ONE CHARACTER
1591	06773	007400	CCB	AND A 1 THEN -1 FOR WORD
1592	06774	053361	CPA \$V	WAS IT THE VIOLATION REG.
1593	06775	107607	OTB 7,C	YES
1594	06776	053352	CPA \$C	WAS IT THE CENTRAL INTERRUPT
1595	06777	106604	OTB 4	YES
1596	07000	053341	CPA \$A	WAS IT A-REG. ?
1597	07001	077772	STB P1.A	YES
1598	07002	053342	CPA \$B	WAS IT B-REG. ?
1599	07003	077771	STB P1.B	YES
1600	07004	053346	CPA \$E	WAS IT E-REG. ?
1601	07005	077770	STB P1.E	YES
1602	07006	053347	CPA \$O	WAS IT O-REG. ?
1603	07007	077767	STB P1.O	YES
1604	07010	053350	CPA \$I	WAS IT THE INTERRUPT SYSTEM?
1605	07011	077764	STB P1.I	YES
1606	07012	053351	CPA \$K	MAPS ON/OFF
1607	07013	077763	STB P1.EM	YES
1608	07014	053345	CPA \$G	WAS IT THE GLOBAL-REG. ?
1609	07015	077766	STB P1.GF	YES
1610	07016	067774	LDB P1.T1	RESTOR B REG
1611	07017	053344	CPA \$T	WAS IT MEMORY DATA CHANGE?
1612	07020	177765	STB P1.M,I	YES
1613	07021	053356	CPA \$U	CROSS MAP?
1614	07022	002001	RSS	
1615	07023	027033	JMP *+8	
1616	07024	060001	LDA B	
1617	07025	067765	LDB P1.M	GET ADDRESS
1618	07026	102711	STC 11B	TURN ON MAPS
1619	07027	027030	JMP *+1	ENABLE THEM
1620	07030	170001	STA R,I	
1621	07031	106711	CLC 11B	MAPS OFF
1622	07032	027064	JMP ST.NA	CONTINUE
1623	07033	005665	ELB,CLE,ERB	CAN'T HAVE AN INDIRECT M OR P REG.
1624	07034	053343	CPA \$M	WAS IT MEMORY ADDRESS?
1625	07035	077765	STB P1.M	YES
1626	07036	053340	CPA \$P	WAS IT PROGRAM ADDRESS?
1627	07037	106603	OTB 3	YES

1629* CHECK I/O REG.

1630*

1631	07040	067766	LDB P1.GF	GET GLOBAL REG
1632	07041	107602	OTB 2,C	
1633	07042	067774	LDB P1.T1	RESTOR B
1634	07043	053401	CPA SRM	INTERRUPT MASK REGISTER?
1635	07044	106600	OTB 0	YES
1636	07045	053364	CPA SR0	SELF-CONFIGURATION REG.?
1637	07046	106620	OTB 20B	YES
1638	07047	053365	CPA SR1	CONTROL REG.?
1639	07050	106621	OTB 21B	YES
1640	07051	053366	CPA SR2	ADDRESS?
1641	07052	106622	OTB 22B	YES
1642	07053	053367	CPA SR3	COUNT?
1643	07054	106623	OTB 23B	YES
1644	07055	053370	CPA SRD	DTTA REGISTER
1645	07056	106630	OTB 30B	YES
1646	07057	053371	CPA SRC	CONTROL REGISTER
1647	07060	106631	OTB 31B	YES
1648	07061	053372	CPA SRS	STATUS REGISTER
1649	07062	106632	OTB STS	YES
1650	07063	017743	JSB RP.SC	RESET GLOBAL REG.
1651	07064	067773	ST.NA LDB P1.T0	RESTOR A AND B REG
1652	07065	060001	LDA B	CHANGE HANDS
1653	07066	067776	LDB P1.T3	CHECK IF INC-DEC FLAG SET
1654	07067	006002	SZR	
1655	07070	027106	JMP ST.N1	YES
1656	07071	027123	JMP ST.N2	PRINT RESULT

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1658	07072	067773	ST.N0	LDB P1.T0	CHECK IF ENTRY IS A T?
1659	07073	073776		STA P1.T3	SET INC-DEC FLAG
1660	07074	101100		RRR 16	CHANGE HANDS
1661	07075	053344		CPA ST	IS IT?
1662	07076	027104		JMP *+6	
1663	07077	053356		CPA SU	
1664	07100	027104		JMP *+4	
1665	07101	053343		CPA SM	
1666	07102	002001		RSS	
1667	07103	026735		JMP INQ!?	
1668	07104	102201		SOC	ANY NUMBER?
1669	07105	026765		JMP ST.N	YES STORE NUMBER
1670	07106	101100	ST.N1	RRR 16	
1671	07107	007400		CCB	DECREMENT?
1672	07110	047765		ADB P1.M	GET MEMORY LOCATION
1673	07111	053353		CPA SD	DECREMENT?
1674	07112	027115		JMP *+3	YES
1675	07113	067765		LDB P1.M	NO INCREMENT
1676	07114	006004		INB	YES
1677	07115	101100		RRR 16	SWAP HANDS
1678	07116	053402		CPA .1	IF ONE USE 777777
1679	07117	063433		LDA .77NK	
1680	07120	002020		SSA	CANT GO INDIRECT
1681	07121	063403		LDA .2	START WITH 2 AGAIN
1682	07122	073765		STA P1.M	RESTORE M
1683	07123	102501	ST.N2	LIA CPUST	SKIP CRLF IF DS
1684	07124	001710		ALF,SLA	
1685	07125	026532		JMP INQ#	
1686	07126	063415		LDA .6412	CARRIAGE RETURN LINE FEED
1687	07127	017751		JSB OUT2C	
1688	07130	026532		JMP INQ#	DO NEXT LOCATION

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1690	07131	002400	IN%N	CLA	CLEAR NUMBER
1691	07132	073774		STA P1.T1	
1692	07133	103101		CLO	CLEAR NUMBER FLAG
1693	07134	017747	IN%NO	JSB IN1C	GET A CHARACTER
1694	07135	053406		CPA .15	IS THAT ALL?
1695	07136	127754		JMP IN.N,I	YES
1696	07137	064000		LDB A	CHANGE HANDS
1697	07140	013421		AND .170	NO CHECK IF IT'S A NUMBER
1698	07141	053414		CPA .60	IS IT?
1699	07142	027145		JMP *+3	YES
1700	07143	060001		LDA B	CHANGE HANDS
1701	07144	127754		JMP IN.N,I	RETURN
1702	07145	060001		LDA B	CHANGE HANDS
1703	07146	013405		AND .7	NO MASK OFF UPPER BITS
1704	07147	067774		LDB P1.T1	GET PREVIOUS INPUT
1705	07150	001640		ELA,CLF	SAVE E AND CLEAR IT
1706	07151	005666		ELB,CLF,ELB	POSITION BIT
1707	07152	004066		CLE,ELB	NEXT BIT
1708	07153	000065		CLE,ERA	RESTOR E
1709	07154	030001		IOR B	ADD NEW INPUT
1710	07155	073774		STA P1.T1	SAVE RESULT
1711	07156	102101		STO	SET NUMBER FLAG
1712	07157	027134		JMP IN%NO	DO ANOTHER CHARACTER
1714	07160	003441	OUT%N	CCA,SEZ,RSS	
1715	07161	063436		LDA .M6	SET COUNT FOR OUTPUT
1716	07162	073777		STA P1.CT	
1717	07163	002404		CLA,INA	SET MASK FOR BIT 15
1718	07164	005200	OUTNO	STB	POSITION BITS
1719	07165	077774		STB P1.T1	SAVE RESULT
1720	07166	010001		AND B	MASK OFF UNWANTED BITS
1721	07167	033414		IOR .60	MAKE IT AN ASCII NUMBER
1722	07170	017752		JSB OUT1C	OUTPUT THE NUMBER
1723	07171	067774		LDB P1.T1	GET NEXT NUMBER
1724	07172	005222		RBL,RBL	POSITION IT
1725	07173	063405		LDA .7	GET MASK
1726	07174	037777		ISZ P1.CT	IS THAT ALL THE CHARACTERS?
1727	07175	027164		JMP OUTNO	NO DO NEXT CHARACTER
1728	07176	063413		LDA .40	OUTPUT A SPACE
1729	07177	017752		JSB OUT1C	
1730	07200	127753		JMP OUT.N,I	RETURN

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1733	07201	102501	IN1C%	LIA CPUST	CHECK WHICH CARD
1734	07202	001710		ALF,SLA	
1735	07203	027217		JMP IN1C0	
1736	07204	063335		LDA TCCWI	GET INPUT CONTROL WORD
1737	07205	102631		OTA CTL	
1738	07206	017750		JSB I.0	GET DATA
1739	07207	013422		AND .177	MASK UPPER BYTE
1740	07210	053422		CPA .177	WAS IT A DELETE?
1741	07211	026735		JMP INQ!?	YES
1742	07212	073751		STA OUT2C	SAVE CHARACTER
1743	07213	017752		JSB OUT1C	ECHO IT
1744	07214	067751		LDB OUT2C	RESTOR CHR
1745	07215	060001		LDA B	
1746	07216	127747		JMP IN1C,I	RETURN
1747	07217	017745	IN1C0	JSB CS.CM	ASK FOR INPUT
1748	07220	061000		OCT 61000	
1749	07221	013423		AND .377	USE LOWER BYTE
1750	07222	127747		JMP IN1C,I	RETURN
1751*					
1752	07223	073747	OU%2C	STA IN1C	SAVE A-REG.
1753	07224	001727		ALF,ALF	
1754	07225	017752		JSB OUT1C	OUTPUT UPPER HALF
1755	07226	067747		LDB IN1C	
1756	07227	060001		LDA B	CHANGE HANDS
1757	07230	017752		JSB OUT1C	OUTPUT LOWER HALF
1758	07231	127751		JMP OUT2C,I	RETURN
1759*					
1760	07232	013423	OU%1C	AND .377	MASK UPPER HALF OFF
1761	07233	106501		LIB CPUST	CHECK WHICH INTERFACE
1762	07234	005710		BLF,SLB	
1763	07235	027244		JMP *+7	DS TYPE
1764	07236	013423		AND .377	MASK UPPER HALF
1765	07237	064000		LDB A	CHANGE HANDS
1766	07240	063336		LDA TCCWO	GET OUTPUT CONRTOL WORD
1767	07241	102631		OTA CTL	
1768	07242	017750		JSB I.0	OUTPUT IT
1769	07243	127752		JMP OUT1C,I	
1770	07244	033431		IOR .60K	DS PUT BYTE REQUEST
1771	07245	064000		LDB A	
1772	07246	017750		JSB I.0	
1773	07247	127752		JMP OUT1C,I	
1774*					
1775	07250	106630	I%0	OTR DR	OUTPUT DATA
1776	07251	103730		STC DR,C	START TRANSFER
1777	07252	102230	I%0.0	SFC DR	DATA READY?
1778	07253	027261		JMP I%0.1	YES
1779	07254	102532		LIA STS	CHECK IF BREAK WAS ENTERED
1780	07255	001200		RAL	IT'S BIT 14 OF STATUS
1781	07256	002020		SSA	
1782	07257	026206		JMP PRST	IT WAS HIT
1783	07260	027252		JMP I%0.0	
1784	07261	102530	I%0.1	LIA DR	GET DATA
1785	07262	127750		JMP I.0,I	RETURN

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1787	07263	102102	RP%SC	STF 2	TURN OFF GLOBAL REGISTER
1788	07264	002400		CLA	
1789	07265	102602		OTA 2	TURN OFF DIAGNOSE MODE
1790	07266	102501		LIA CPUST	GET COMPUTER STATUS
1791	07267	001710		ALF,SLA	CHECK WHICH VCP SC
1792	07270	027273		JMP *+3	
1793	07271	063410		LDA .20	STANDARD SO 20
1794	07272	027274		JMP *+2	
1795	07273	063412		LDA .24	ALTERNATE (DS)
1796	07274	103602		OTA 2,C	LOAD AND ENABLE GLOBAL REGISTER
1797	07275	127743		JMP RP.SC,I	RETURN
1798*					
1799	07276	106501	CS%TR	LIB CPUST	CHECK IF DS
1800	07277	005710		BLF,SLB	
1801	07300	002001		RSS	
1802	07301	127744		JMP CS.TR,I	NO JUST RETURN
1803	07302	001727		ALF,ALF	PUT REQUEST IN UPPER BYTE
1804	07303	033423		IOR .377	ADD RUB OUT
1805	07304	017751		JSB OUT2C	
1806	07305	017745		JSB CS.CM	TELL CARD TO TRANSMITT
1807	07306	060400		OCT 60400	
1808	07307	017745		JSB CS.CM	NOW ASK FOR A BUFFER
1809	07310	061400		OCT 61400	
1810	07311	127744		JMP CS.TR,I	RETURN
1811*					
1812	07312	067745	CS%CM	LDB CS.CM	GET COMMAND
1813	07313	160001		LDA R,I	
1814	07314	064000		LDB A	
1815	07315	017750		JSB I.O	
1816	07316	037745		ISZ CS.CM	
1817	07317	064000		LDB A	
1818	07320	127745		JMP CS.CM,I	
1819*					
1820	07321	102630	CS%FT	OTA DR	
1821	07322	103730		STC DR,C	
1822	07323	063442		LDA .N64	GET TIME OUT
1823	07324	102230		SFC DR	
1824	07325	027333		JMP *+6	
1825	07326	034001		ISZ B	
1826	07327	027324		JMP *-3	
1827	07330	034000		ISZ A	
1828	07331	027324		JMP *-5	
1829	07332	127746		JMP CS.FT,I	RETURN TIME OUT
1830	07333	037746		ISZ CS.FT	NO SKIP TIME OUT
1831	07334	127746		JMP CS.FT,I	

*

1833* CONSTANTS

1834*

1835 07335 002400 TCCWI OCT 002400

1836 07336 001000 TCCWO OCT 001000

1837*

1838 07337 007340 DFL DEF *+1

1839 07340 000120 SP OCT 120

1840 07341 000101 SA OCT 101

1841 07342 000102 SB OCT 102

1842 07343 000115 SM OCT 115

1843 07344 DFL. EQU *

1844 07344 000124 ST OCT 124

1845 07345 000107 SG OCT 107

1846 07346 000105 SE OCT 105

1847 07347 000117 SO OCT 117

1848 07350 000111 SI OCT 111

1849 07351 000113 SK OCT 113

1850 07352 000103 SC OCT 103

1851 07353 000104 SD OCT 104

1852 07354 000114 SL OCT 114

1853 07355 000116 SN OCT 116

1854 07356 000125 SU OCT 125

1855 07357 000122 SR OCT 122

1856 07360 000123 SS OCT 123

1857 07361 000126 SV OCT 126

1858 07362 000127 SW OCT 127

1859 07363 000045 S% OCT 45

1860 07364 051060 \$R0 ASC 1,R0

1861 07365 051061 \$R1 ASC 1,R1

1862 07366 051062 \$R2 ASC 1,R2

1863 07367 051063 \$R3 ASC 1,R3

1864 07370 051104 \$RD ASC 1,RD

1865 07371 051103 \$RC ASC 1,RC

1866 07372 051123 \$RS ASC 1,RS

1867 07373 051111 \$RI ASC 1,RI

1868 07374 051130 \$RX ASC 1,RX

1869 07375 051106 \$RF ASC 1,RF

1870*

1871 07376 046103 \$LC ASC 1,LC

1872 07377 042522 \$EP ASC 1,EP

1873 07400 020477 \$! ? ASC 1,! ?

1874 07401 051115 \$RM ASC 1,PM

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1876 07402 000001 .1 OCT 1
1877 07403 000002 .2 OCT 2
1878 07404 000207 .207 OCT 207
1879 07405 000007 .7 OCT 7
1880 07406 000015 .15 OCT 15
1881 07407 000017 .17 OCT 17
1882 07410 000020 .20 OCT 20
1883 07411 000021 .21 OCT 21
1884 07412 000024 .24 OCT 24
1885 07413 000040 .40 OCT 40
1886 07414 000060 .60 OCT 60
1887 07415 006412 .6412 OCT 6412
1888 07416 000077 .77 OCT 77
1889 07417 000100 .100 OCT 100
1890 07420 000140 .140 OCT 140
1891 07421 000170 .170 OCT 170
1892 07422 000177 .177 OCT 177
1893 07423 000377 .377 OCT 377
1894 07424 000604 .604 OCT 604
1895 07425 001000 .1000 OCT 1000
1896 07426 002100 .2100 OCT 2100
1897 07427 001777 .1777 OCT 1777
1898 07430 001700 .1700 OCT 1700
1899 07431 060000 .60K OCT 60000
1900 07432 076000 .76K OCT 76000
1901 07433 077777 .77NK OCT 77777
1902 07434 100000 .100K OCT 100000
1903 07435 177777 .M1 OCT -1
1904 07436 177772 .M6 OCT -6
1905 07437 177766 .M12 OCT -12
1906 07440 177760 .M20 OCT -20
1907 07441 177754 .N20 DEC -20
1908 07442 177700 .N64 DEC -64
1909*
1910 07443 EQU1 EQU * END OF PAGE 1
1911*
1912 07743 ORG 7743B
1913 00300 RAP1 EQU *-FDP1 REMAINING AREA FOR PAGE 1
1914 07743 000000 RP.SC NOP
1915 07744 027263 CS.TR JMP RP%SC
1916 07745 027276 CS.CM JMP CS%TR
1917 07746 027312 CS.FT JMP CS%CM
1918 07747 027321 IN1C JMP CS%FT
1919 07750 027201 I.O JMP IN1C%
1920 07751 027250 OUT2C JMP I%O
1921 07752 027223 OUT1C JMP OU%2C
1922 07753 027232 OUT.N JMP OU%1C
1923 07754 027160 IN.N JMP OUT%N
1924 07755 027131 P1ERR JMP IN%N
1925 07756 000000 NOP
1926 07757 000000 NOP

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1928*      CROSS OVER TO LOWER PAGE
1929*
1930 07760 063424 CRSP3 LDA .604
1931 07761 102601      OTA CPUT
1932 07762 026372      JMP LDPTN      RETURN FROM LOADER
1933*
1934*      VCP BREAK ENTRY POINT (SAME ON ALL PAGES)
1935*
1936 07763 103105      CLF 5          INSURE PARITY SENSE
1937 07764 106713      CLC 13B       DISABLE MEMORY MAPS
1938 07765 103300      OCT 103300    SFS 0,C CHECK INTERRUPTS
1939 07766 027772      JMP *+4       THERE OFF
1940 07767 073772      STA P1.A      SAVE THE A REG.
1941 07770 003400      CCA          INDICATE INTS ON
1942 07771 027774      JMP *+3
1943 07772 073772      STA P1.A
1944 07773 002400      CLA
1945 07774 073764      STA P1.I
1946 07775 063404      LDA .207      INSURE UPPER PAGE
1947 07776 102601      OTA CPUT
1948 07777 026011      JMP VCP       CONTINUE FRONT PANNEL ROUTINE
1949*
1950*      COMMON STORAGE
1951*
1952 07777      P1.CT EQU 1777B+P1
1953 07776      P1.T3 EQU 1776B+P1
1954 07775      P1.T2 EQU 1775B+P1
1955 07774      P1.T1 EQU 1774B+P1
1956 07773      P1.T0 EQU 1773B+P1
1957 07772      P1.A EQU 1772B+P1
1958 07771      P1.B EQU 1771B+P1
1959 07770      P1.E EQU 1770B+P1
1960 07767      P1.O EQU 1767B+P1
1961 07766      P1.GF EQU 1766B+P1
1962 07765      P1.M EQU 1765B+P1
1963 07764      P1.I EQU 1764B+P1
1964 07763      P1.EM EQU 1763B+P1
1965 07762      P1.DF EQU 1762B+P1
1966 07761      P1.UN EQU 1761B+P1
1967 07760      P1.FL EQU 1760B+P1
1968 07757      P1.SR EQU 1757B+P1
1969 07756      P1.SC EQU 1756B+P1

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1971	10000		ORG 10000B	
1972	10000	P2	EQU *	PAGE 2 REFERENCE
1973*				
1974*			CONTINUATION LOAD	
1975*				
1976*			RAM USER CODE MUST SET GLOBAL REGISTER	
1977*				
1978*	LDA 400B		SET CORRECT PAGE	
1979*	OTA 1		FOR CONTINUATION LOAD	
1980*	CLA,INA(CCE)		INDICATE DISC CALL BACK + SUSPEND	
1981*	CLC 2		ENABLE ROM	
1982*	JSB 1		GO TO DRIVER	
1983*	...		HPIB BUS ADDRESS	
1984*	...		DEVICE UNIT NO. (HEAD FOR 7906)	
1985*	...		ABSOLUTE STARTING SECTOR	
1986*	...		CYLINDER OFFSET	
1987*				
1988	10000 000000		NOP	
1989	10001 000000		NOP	
1990	10002 107700		CLC 0,C	TURN OFF THE WORLD
1991	10003 103102		CLF 2	RE ENABLE GLOBAL REGISTER
1992	10004 000000		NOP	IGNORE POWER FAIL
1993	10005 000000		NOP	IGNORE INH
1994	10006 000000		NOP	IGNORE PARITY ERRORS
1995	10007 000000		NOP	IGNORE MEMORY PROTECT
1996	10010 000000		NOP	IGNORE UNIMPLEMENTED INST.
1997*				
1998	10011 053104		CPA #1	IS THIS A DISC CALL BACK
1999	10012 026015		JMP *+3	
2000	10013 102702		STC 2	NO RETURN TO CALLER
2001	10014 124001		JMP B,I	
2002*				
2003	10015 063140		LDA #404	SET LEDS
2004	10016 102601		OTA CPUST	
2005	10017 060001		LDA B	
2006	10020 164000		LDB A,I	GET BUS ADDRESS
2007	10021 077757		STB P2.SB	SAVE IT
2008	10022 002004		INA	
2009	10023 164000		LDB A,I	GET UNIT NO.
2010	10024 077761		STB P2.UN	SAVE IT
2011	10025 002004		INA	
2012	10026 164000		LDB A,I	GET ABSOLUTE SECTOR COUNT
2013	10027 077760		STB P2.FL	SAVE IT
2014	10030 002004		INA	
2015	10031 164000		LDB A,I	GET CYLINDER OFFSET
2016	10032 077741		STB P2C+1	SAVE IT
2017	10033 002400		CLA	
2018	10034 073773		STA P2.T0	NO WRITE
2019	10035 073775		STA P2.T2	AUTO EXECUTE (NOT VCP)
2020	10036 002004		INA	
2021	10037 073762		STA P2.DF	CLEAR SUSPEND FLAG INDICATE CONT.
2022	10040 003440		CCA,SEZ	NO RETRIES (SUSPEND REQUEST?)
2023	10041 073762		STA P2.DF	SET SUSPEND FLAG
2024	10042 073777		STA P2.CT	
2025	10043 026064		JMP DCLD1	EXECUTE LOADER

2027	10044	060001	LDP2	LDA B	CHANGE HANDS
2028	10045	053104		CPA #1	DISC LOADER
2029	10046	026052		JMP DCLD.	YES
2030	10047	002404		CLA,INA	NO DEVICE
2031	10050	073755		STA P2ERR	
2032	10051	027757		JMP RTNP3	NONE OF THE ABOVE SO ERROR
2034*	HP-IB DISC LOADER				
2035*					
2036	10052	063152	DCLD.	LDA #M40	SET RETRY COUNTER
2037	10053	067775		LDB P2.T2	CHECK IF VCP
2038	10054	006002		SZB	IF IT IS FROM VCP THEN
2039	10055	063145		LDA #M2	ALLOW ONE RETRY
2040	10056	073777		STA P2.CT	
2041*					
2042	10057	067760		LDB P2.FL	MPY FILE BY 256
2043	10060	005727		BLF,BLF	
2044	10061	077760		STR P2.FL	
2045	10062	002400		CLA	CLEAR CYLINDER OFFSET
2046	10063	073741		STA P2C+1	
2047	10064	017752	DCLD1	JSB DCFR	SET ERROR RETURN ADDRESS
2048	10065	026324		JMP DCERX	
2049	10066	017742		JSB DC.IN	INITIALIZE AND GET DISC TYPE
2050*					
2051*	DETERMINE IF L OR XL				
2052*					
2053	10067	067742		LDB DC.IN	SETUP PAGE
2054	10070	060001		LDA B	CHECK FOR PAGE
2055	10071	013142		AND #76K	ONLY UPPER ADDRESS
2056	10072	002003		SZA,RSS	
2057	10073	026106		JMP DCLMP	NEW MAPPED
2058	10074	023142		XOR #76K	MAKE COUNT
2059	10075	033112		IOR #100	AND DO A 32K-64 WORD TRANSFER
2060	10076	067743		LDB DC.RW	OLD SYSTEM SO CHANGE CYLINDER NO.
2061	10077	077754		STB P2.HC	
2062	10100	006700		CLB,CCE	AND CLEAR HEAD SECTOR
2063	10101	077753		STB P2.ST	
2064	10102	005500	DCLD2	ERR	SET BIT 15 FOR NON MAPPED
2065	10103	017743		JSB DC.RW	READ OR WRITE DATA
2066	10104	073755		STA P2ERR	CLEAR ERROR
2067	10105	027757		JMP RTNP3	RETURN TO PAGE 3

2069	10106	067773	DCLMP LDR P2.T0	CHECK IF READ OR WRITE
2070	10107	060001	LDA B	
2071	10110	053156	CPA S2W	IF W WAS ENTERED THEN WRITE
2072	10111	026113	JMP **2	
2073	10112	026147	JMP DCLM.	
2074	10113	064101	LDB 101B	SAVE MAP LOCATION
2075	10114	106624	OTB 24B	IN THE I/O CHIP
2076	10115	002400	CLA	
2077	10116	070101	STA 101B	
2078	10117	067772	LDB P2.A	GET A REGISTER DATA
2079	10120	102711	STC 11B	FNABLE MAPS
2080	10121	026122	JMP **1	TURN THEM ON
2081	10122	063121	LDA #2000	GO TO MAPPED PAGE
2082	10123	174000	STB A,I	
2083	10124	002004	INA	
2084	10125	106713	CLC 13B	DISABLE MAPS
2085	10126	067771	LDB P2.B	
2086	10127	102713	STC 13B	RE ENABLE MAPS
2087	10130	174000	STB A,I	
2088	10131	106711	CLC 11B	
2089	10132	026133	JMP **1	
2090	10133	106524	LIR 24B	RESTOR MAP REG.
2091	10134	074101	STB 101B	
2092	10135	067772	LDB P2.A	CHECK IF MAPPED WRITE OR OLD STYLE
2093	10136	006020	SSB	
2094	10137	026251	JMP DCLMW	OLD STYLE
2095	10140	060001	LDA B	
2096	10141	067771	LDB P2.B	
2097	10142	006002	SZB	COUNT PARTIAL
2098	10143	002004	INA	
2099	10144	043150	ADA #M11	
2100	10145	002021	SSA,RSS	OVER 8?
2101	10146	026251	JMP DCLMW	YES THEN OLD STYLE

*

2103	10147	063067	DCLM. LDA TR1K	GET COUNT FOR 1K -64
2104	10150	006700	CLB,CCF	NON MAPPED
2105	10151	005500	ERB	
2106	10152	017743	JSB DC.RW	NOW READ IT
2107	10153	003400	CCA	NO MORE RETRIES
2108	10154	073777	STA P2.CT	
2109	10155	067760	LDB P2.FL	ADD 8 SECTRS
2110	10156	060001	LDA B	
2111	10157	043111	ADA @10	
2112	10160	073760	STA P2.FL	
2113	10161	017742	JSB DC.IN	REEINITIALIZE BUSS
2114	10162	067760	LDB P2.FL	MOVE FILE COUNT BACK
2115	10163	060001	LDA B	
2116	10164	043147	ADA @M10	
2117	10165	073760	STA P2.FL	
2118	10166	063070	LDA TR31K	COUNT FOR 31K TRANSFER
2119	10167	064000	LDB A	
2120	10170	017743	JSB DC.RW	READ IT
2121	10171	064101	LDB 101B	SAVE MAP
2122	10172	077743	STB DC.RW	
2123	10173	002400	CLA	
2124	10174	070101	STA 101B	MAP PAGE 1 TO PAGE 0
2125	10175	102711	STC 11B	TURN ON MAPPING
2126	10176	026177	JMP *+1	ENABLE THEM
2127	10177	063122	LDA @2101	TRY MAPPING INCASE XL BOOT AND L MEM.
2128	10200	007400	CCB	
2129	10201	174000	STB A,I	
2130	10202	063121	LDA @2000	
2131	10203	164000	LDB A,I	SHOULD GET PHY. LOC. 0
2132	10204	101100	RRR 16	SWAPP A & B
2133	10205	006004	INB	MOVE TO PHY. LOC. 1
2134	10206	164001	LDB B,I	
2135	10207	106711	CLC 11B	TURN MAPS OFF
2136	10210	026211	JMP *+1	
2137	10211	034101	ISZ 101B	DID IT STORE
2138	10212	026224	JMP DCLMU	NO THEN XL BOOTX ON L MEMORY
2139	10213	073772	STA P2.A	SAVE A & B
2140	10214	077771	STB P2.B	

2142	10215	002021	SSA,RSS	IS THIS OLD OR NEW?
2143	10216	026255	JMP DCLM1	NEW
2144	10217	106501	DCLM0 LIB CPUST	CHECK IF MEMLOST IS UP
2145	10220	005600	ELB	
2146	10221	063131	LDA @40	THEN
2147	10222	006020	SSR	
2148	10223	026322	JMP DCLMX+1	CAN'T LOAD
2149	10224	063136	DCLMU LDA @1700	OK THEN MOVE SAVE AREA
2150	10225	073742	STA DC.IN	USE AS STORAGE
2151	10226	033142	IOR @76K	AND EXECUTION TO LAST PAGE
2152	10227	167742	LDB DC.IN,I	
2153	10230	174000	STB A,I	
2154	10231	037742	ISZ DC.IN	
2155	10232	002004	INA	
2156	10233	002021	SSA,RSS	
2157	10234	026227	JMP *-5	
2158	10235	103503	LIA 3,C	RESET BREAK ADDRESS
2159	10236	033142	IOR @76K	
2160	10237	103603	OTA 3,C	
2161	10240	063142	LDA @76K	NOW MOVE EXECUTION TO THAT ADDRESS
2162	10241	032243	IOR *+2	
2163	10242	124000	JMP A,I	
2164	10243	000244	DEF *+1-P2	
2165	10244	063142	LDA @76K	UPDATE STRING POINTER
2166	10245	067762	LDB P2.DF	
2167	10246	006002	SZB	IF NOT ZERO
2168	10247	044000	ADB A	
2169	10250	077762	STB P2.DF	
2170	10251	017742	DCLMW JSB DC.IN	RE INITIALIZE BUS
2171	10252	063112	LDA @100	DO 32K - 64 WORDS
2172	10253	006700	CLB,CCE	SET FOR NORMAL DMA TRANSFER
2173	10254	026102	JMP DCLD2	GO DO IT
2174	10255	067743	DCLM1 LDB DC.RW	RESTORE MAP LOCATION
2175	10256	074101	STB 101B	
2176	10257	002003	SZA,RSS	ANY MORE BLOCKS?
2177	10260	026321	JMP DCLMX	NO
2178	10261	067771	LDB P2.B	RESTORE B REG
2179	10262	006002	SZB	MUST BE A MAPPED FILE
2180	10263	002004	INA	IF PARTIAL THEN DO ONE MORE FULL ONE
2181	10264	043144	ADA @M1	MOVE IT BACK ONE
2182	10265	070001	STA B	
2183	10266	043147	ADA @M10	CHECK IF OLD GENERATOR TYPE
2184	10267	002021	SSA,RSS	IF OVER 8
2185	10270	026217	JMP DCLM0	YES THEN MOVE TO OTHER PAGE

2187	10271	002400		CLA	
2188	10272	073740		STA P2C	CLEAR MAP POINTER
2189	10273	060001		LDA B	RESTORE A REG.
2190	10274	043144	DCLM2	ADA @M1	
2191	10275	002020		SSA	
2192	10276	026321		JMP DCLMX	
2193	10277	102624		OTA 24R	SAVE BLOCK COUNT
2194	10300	102525		LIA 25B	SET NEXT FILE NUMBER
2195	10301	002004		INA	
2196	10302	102625		OTA 25B	MOVED TO NEXT FILE
2197	10303	067760		LDB P2.FL	POINT TO NEXT FILE AREA
2198	10304	060001		LDA B	
2199	10305	043066		ADA @D256	
2200	10306	073760		STA P2.FL	
2201	10307	017742		JSB DC.IN	SET UP BUS
2202	10310	067740		LDB P2C	UPDATE MAPF POINTER
2203	10311	060001		LDA B	
2204	10312	043131		ADA @40	NEXT 32K BLOCK
2205	10313	073740		STA P2C	SAVE IT
2206	10314	070001		STA B	AND PASS IT AS A PARAMETER
2207	10315	002400		CLA	
2208	10316	017743		JSB DC.RW	READ DATA
2209	10317	102524		LIA 24R	CHECK IF DONE
2210	10320	026274		JMP DCLM2	
2211	10321	002400	DCLMX	CLA	
2212	10322	073755		STA P2FRR	
2213	10323	027757		JMP RTNP3	
2214*					
2215*					
2216	10324	067755	DCERRX	LDB P2ERR	SAVE CURRENT ERROR
2217	10325	063111		LDA @10	START ALL OVER
2218	10326	073755		STA P2ERP	
2219	10327	037777		ISZ P2.CT	CHECK IF RETRY
2220	10330	026064		JMP DCLD1	YES
2221	10331	077755		STB P2ERP	RESTOR ERROR
2222	10332	027757		JMP RTNP3	RETURN TO PAGE 3
2223*					
2224*	INITIALIZE BUS				
2225*					
2226	10333	063111	DC%IN	LDA @10	SET ERROR 10
2227	10334	073755		STA P2ERR	
2228	10335	017747		JSB PHI	
2229	10336	070200		OCT 070200	PHI ON-LINE
2230	10337	017747		JSB PHI	
2231	10340	060063		OCT 060063	REN,IFC,WRITE,FLUSH FIFO
2232	10341	063065		LDA N250	ABOUT A 1 MILLISEC DELAY
2233	10342	002006		INA,SZA	
2234	10343	026342		JMP *-1	
2235	10344	073776		STA P2.T3	CLEAR HEAD NUMBER
2236	10345	017751		JSB PHIFL	FLUSH PHI FIFO'S

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2238*      READ AND SET DISC TYPE
2239*
2240 10346 037755      ISZ P2ERR      SET ERROR 11
2241 10347 017745      JSB PHI.L      TELL PHI TO LISTEN WITH
2242 10350 000537      OCT 537        A SECONDARY OF UNTALK
2243 10351 067757      LDB P2.SB     BUILD SECONDARY WITH HPIB ADD
2244 10352 060001      LDA B
2245 10353 033071      IOR TLK
2246 10354 033072      IOR LSN
2247 10355 017750      JSB HPIB
2248 10356 017747      JSB PHI
2249 10357 001002      OCT 1002
2250 10360 017746      JSB PHI.I      GET DISC TYPE
2251 10361 001727      ALF,ALF
2252 10362 073745      STA PHI.L      SAVE DATA
2253 10363 017746      JSB PHI.I
2254 10364 067745      LDB PHI.L      ADD PREVIOUS BYTE
2255 10365 044000      ADB A
2256 10366 077743      STR DC.RW     SAVE DISC TYPE
2257*
2258*      DO A UNIVERSAL DEVICE CLEAR AND
2259*      READ STATUS
2260*
2261 10367 037755      ISZ P2ERR      SET ERROR 12
2262 10370 017744      JSB PHI.T      PHI TALK
2263 10371 000424      OCT 424        UNIVERSAL DEVICE CLEAR
2264 10372 017744      JSB PHI.T      PHI TLK
2265 10373 000550      OCT 550
2266 10374 017747      JSB PHI
2267 10375 000003      OCT 3          READ STATUS
2268 10376 067761      LDB P2.UN
2269 10377 060001      LDA B
2270 10400 033113      IOR BIT9      ADD BIT9
2271 10401 017750      JSB HPIB      PASS IT TO CARD
2272 10402 017745      JSB PHI.L      PHI LSN
2273 10403 000550      OCT 550
2274 10404 017747      JSB PHI
2275 10405 001003      OCT 1003      TRANSFER 3 BYTES
2276 10406 017746      JSB PHI.I      GET BYTE
2277 10407 037755      ISZ P2ERR      SET ERROR 13
2278 10410 002002      SZA          CHECK FOR ERROR
2279 10411 127752      JMP DCFR,I    YES RETURN WITH AN ERROR
2280 10412 017746      JSB PHI.I      SKIP NEXT BYTE
2281 10413 017746      JSB PHI.I      READ DISC TYPE
2282 10414 001300      RAR          ELIMINATE BIT 0
2283 10415 013126      AND @17       USE 4 BITS FOR ID
2284 10416 073751      STA PHIFL     SAVE FOR CONVERSION

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2286*      TAKE DISC TYPE AND CONVERT TO DISC PARAMETERS
2287*
2288 10417 063075      LDA DCTYP      GET POINTER TO DISC TYPE
2289 10420 073745      STA PHI.L
2290 10421 067743      LDB DC.RW      RETRIEVE DISC TYPE
2291 10422 060001      LDA B
2292 10423 053117      CPA @204      MINI FLOPPY?
2293 10424 026471      JMP DTYPE      YES
2294 10425 037745      ISZ PHI.L      NO MOVE TO NEXT TYPE
2295 10426 053116      CPA @201      88020 FLOPPY
2296 10427 026471      JMP DTYPE
2297 10430 037745      ISZ PHI.L
2298 10431 053104      CPA @1        7910 FIXED DISC
2299 10432 026471      JMP DTYPE
2300 10433 037745      ISZ PHI.L      MOVE TO NEXT ENTRY
2301 10434 053106      CPA @3        INTEGRATED DISC CONTROLLER?
2302 10435 026443      JMP *+6        YES
2303 10436 063132      DTYER LDA @60    DISC NOT IDENTIFIED
2304 10437 067760      LDB P2.FL      CHECK IF FILE NO. IS ZERO
2305 10440 006002      SZB            IF SO THEN GO AHEAD
2306 10441 026322      JMP DCLMX+1    NO RETURN ERROR
2307 10442 026457      JMP DCFM       USE CYLINDER MODE
2308 10443 067751      LDB PHIFL      GET ID FROM CONTROLLER
2309 10444 060001      LDA B
2310 10445 053104      CPA @1        7920?
2311 10446 026457      JMP DCFM       YES DO FILE MASK FIRST
2312 10447 037745      ISZ PHI.L
2313 10450 053106      CPA @3        7925?
2314 10451 026457      JMP DCFM       YES DO A FILE MASK FIRST
2315 10452 037745      ISZ PHI.L
2316 10453 002002      SZA            7906?
2317 10454 026436      JMP DTYER
2318 10455 007400      CCB
2319 10456 077776      STB P2.T3      INDICATE UNIT = HEAD
2320*
2321*      SEND FILE MASK
2322*
2323 10457 037755      DCFM ISZ P2ERR    SET ERROR 14
2324 10460 017744      JSB PHI.T      SEND FILE MASK TO 7906
2325 10461 000550      OCT 550
2326 10462 017747      JSB PHI
2327 10463 000017      OCT 17         SET FILE MASK
2328 10464 063114      LDA @1005      ENABLE AUTO TRACK INCREMENT AND SPARING
2329 10465 067776      LDB P2.T3      IS THIS A 7906?
2330 10466 006003      SZB,RSS
2331 10467 033105      IOR @2        NO THEN CYLINDER MODE
2332 10470 017750      JSB HPIB

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2334*      CONVERT FILE NO. TO CYLINDER-HEAD-SECTOR
2335*
2336 10471 067745 DTYPE LDB PHI.L      GET POINTER
2337 10472 160001      LDA B,I          SET NO. OF SECTRS PER TRACK
2338 10473 013135      AND @377        GET SECTRS PER TRACK
2339 10474 003004      CMA,INA         MAKE IT NEG
2340 10475 073753      STA P2.ST        SAVE IT
2341 10476 160001      LDA B,I          SET NO. OF HEADS PER CYLINDER
2342 10477 001727      ALF,ALF
2343 10500 013126      AND @17
2344 10501 003004      CMA,INA
2345 10502 073754      STA P2.HC
2346 10503 160001      LDA B,I          SET OLD STYLE OF FILE / CYLINDER
2347 10504 001700      ALF
2348 10505 013126      AND @17
2349 10506 003004      CMA,INA
2350 10507 073774      STA P2.T1        SAVE AS COUNT
2351 10510 067760      LDB P2.FL
2352 10511 101050      LSR 8
2353 10512 002400      CLA
2354 10513 040001      ADA B
2355 10514 037774      ISZ P2.T1
2356 10515 026513      JMP *-2
2357 10516 073743      STA DC.RW        SAVE LODF STYLE
2358 10517 002400      CLA
2359 10520 067760      LDB P2.FL        NOW GET NO SECTRS
2360 10521 077774      STB P2.T1
2361 10522 047753      ADB P2.ST
2362 10523 006020      SSR
2363 10524 026527      JMP *+3
2364 10525 002004      INA
2365 10526 026521      JMP *-5
2366 10527 067774      LDB P2.T1        REMAINDER IS THE SECTOR OFF SET
2367 10530 077753      STB P2.ST        SAVE IT
2368 10531 064000      LDB A           NOW GET NUMBER OF CYLINDERS
2369 10532 002400      CLA
2370 10533 077774      STB P2.T1
2371 10534 047754      ADB P2.HC
2372 10535 006020      SSR
2373 10536 026541      JMP *+3
2374 10537 002004      INA
2375 10540 026533      JMP *-5
2376 10541 073754      STA P2.HC        SAVE CYLINDER
2377 10542 067774      LDB P2.T1        NOW ADD HEAD TO SECTR WORD
2378 10543 005727      BLF,BLF
2379 10544 047753      ADB P2.ST
2380 10545 077753      STB P2.ST
2381 10546 127742      JMP DC.IN,I     NOW RETURN

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2383*      SEEK  READ/WRITE  DSJ
2384*
2385  10547 000066  DC*RW CLE,ELA  MPY COUNT BY 2 FOR BYTE COUNT
2386  10550 102623      OTA 23B  PASS COUNT TO INTERFACE
2387  10551 103101      CLO      SET READ
2388  10552 060001      LDA B
2389  10553 067773      LDB P2.TO  NOW CHECK IF WRITE
2390  10554 101100      RRR 16
2391  10555 053156      CPA S2W  IS IT A WRITE?
2392  10556 102101      STO      YES
2393  10557 063074      LDA DCDCW  GET DMA CONTROL WORD
2394  10560 006021      SSB,RSS  IS THIS MAPPED
2395  10561 002004      INA      YES USE MAP REGISTER 1
2396  10562 102301      SOS      READ / WRITE
2397  10563 033115      IOP @200  READ
2398  10564 102621      OTA 21P  PASS IT TO DMA
2399  10565 060001      LDA R      STARTING ADDRESS
2400  10566 006021      SSB,RSS  IS THIS ADDRESS OR MAPPED
2401  10567 006400      CLR      MAPPED THEN 0 ADDRESS
2402  10570 106622      OTB 22B
2403  10571 064141      LDR 141B  SAVE MAP CONTENTS
2404  10572 077742      STB DC.IN
2405  10573 106521      LIB 21B  NEED MAPPING?
2406  10574 004010      SLB
2407  10575 070141      STA 141B  YES-NOW SET MAP
2408  10576 063125      LDA @15  SET ERROR 15
2409  10577 073755      STA P2ERR
2410  10600 017744      JSB PHI.T  PHI TLK
2411  10601 000550      OCT 550  SECONDARY
2412  10602 017747      JSB PHI
2413  10603 000002      OCT 2    SEEK
2414  10604 067776      LDB P2.T3  CHECK FOR UNIT HEAD SWAP
2415  10605 060001      LDA B
2416  10606 006400      CLB
2417  10607 002003      SZA,RSS  IS THERE A SWAP
2418  10610 067761      LDR P2.UN  NO - GET UNIT
2419  10611 060001      LDA B
2420  10612 017750      JSB HP1B
2421  10613 067754      LDR P2.HC  SET UPPER CYLINDER
2422  10614 047741      ADR P2C+1  ADD CYLINDER OFFSET
2423  10615 060001      LDA B
2424  10616 001727      ALF,ALF
2425  10617 013135      AND @377
2426  10620 017750      JSB HP1B
2427  10621 067754      LDB P2.HC  GET CYLINDER NUMBER
2428  10622 047741      ADR P2C+1  ADD CYLINDER OFFSET
2429  10623 060001      LDA B      SET LOWER CYLINDER
2430  10624 013135      AND @377
2431  10625 017750      JSB HP1B

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2433	10626	067753	LDB P2.ST	SET HEAD
2434	10627	060001	LDA B	
2435	10630	001727	ALF,ALF	
2436	10631	013135	AND #377	
2437	10632	067776	LDB P2.T3	CHECK FOR UNIT HEAD SWAP
2438	10633	006002	SZB	
2439	10634	067761	LDB P2.UN	
2440	10635	030001	IOR B	
2441	10636	017750	JSB HPIB	
2442	10637	067753	LDB P2.ST	SET SECTOR
2443	10640	060001	LDA B	
2444	10641	013135	AND #377	
2445	10642	033113	IOR BIT9	SET SECTOR + EOI
2446	10643	017750	JSB HPIB	

2448* READ OR WRITE

2449*

2450	10644	037755	ISZ P2ERR	SET ERROR 16
2451	10645	017744	JSB PHI.T	PHI TLK
2452	10646	000550	OCT 550	SECONDARY
2453	10647	102201	SDC	READ OR WRITE?
2454	10650	026654	JMP *+4	
2455	10651	017747	JSB PHI	
2456	10652	000005	OCT 5	READ
2457	10653	026656	JMP *+3	
2458	10654	017747	JSB PHI	
2459	10655	000010	OCT 10	WRITE
2460	10656	067761	LDB P2.UN	GET UNIT
2461	10657	060001	LDA B	
2462	10660	033113	IOR BIT9	ADD EOI
2463	10661	017750	JSB HPIB	PASS IT TO CARD
2464	10662	102301	SOS	READ OR WRITE?
2465	10663	026667	JMP *+4	
2466	10664	017744	JSB PHI.T	WRITE
2467	10665	000540	OCT 540	
2468	10666	026675	JMP *+7	
2469	10667	017745	JSB PHI.L	PHI LSN
2470	10670	000540	OCT 540	SECONDARY
2471	10671	017747	JSB PHI	
2472	10672	001400	OCT 1400	UNCOUNTED XFER
2473	10673	017747	JSB PHI	
2474	10674	060040	OCT 60040	TELL PHI TO INPUT

2476* SET UP DAM TRANSFER AND START IT

2477*

2478	10675	063073	LDA CMDF	SET PHI FOR DMA INPUT BYTE PACKED
2479	10676	102201	SOC	
2480	10677	001665	ELA,CLE,ERA	MAKE IT OUTPUT
2481	10700	102631	OTA CTL	
2482	10701	103721	STC 21B,C	START DMA
2483	10702	037755	ISZ P2ERR	SET ERROR 17
2484	10703	063151	LDA @M20	
2485	10704	073747	STA PHI	START TIME OUT
2486	10705	034000	DCLO ISZ A	
2487	10706	026717	JMP DCSFS	
2488	10707	037747	ISZ PHI	
2489	10710	026717	JMP DCSFS	
2490	10711	107721	CLC 21B,C	SHUT DOWN DMA
2491	10712	067742	LDR DC.IN	RESTORE MAP DATA
2492	10713	102521	LIA 21B	WAS THIS MAPPED
2493	10714	000010	SLA	
2494	10715	074141	STB 141B	YES RESTOR 141
2495	10716	127752	JMP DCFR,I	TIMED OUT SO ERROR
2496	10717	102323	DCSFS SFS 23B	IS IT READY
2497	10720	026705	JMP DCLO	NO CHECK TIME OUT
2498	10721	107721	CLC 21B,C	YES SHUT DOWN THE REST OF DMA
2499	10722	067742	LDR DC.IN	RESTORE MAPP
2500	10723	102521	LIA 21B	WAS THIS MAPPED?
2501	10724	000010	SLA	
2502	10725	074141	STB 141B	YES RESTOR 141
2503	10726	037755	ISZ P2ERR	SET ERROR 20
2504	10727	102222	SFC 22B	CHECK FOR PARITY ERROR
2505	10730	127752	JMP DCER,I	YES SO ERROR
2506	10731	037755	ISZ P2ERR	SET ERROR 21
2507	10732	062756	LDA UNL	GET UNLISTEN
2508	10733	102201	SOC	ONLY IF IT'S A WRITE
2509	10734	017750	JSB HPIB	YES OUTPUT IT
2510	10735	102301	SOS	
2511	10736	017751	JSR PHIFL	FLUSH PHI FIFOS
2512*				
2513*	DSJ REQUEST			
2514*				
2515	10737	037755	ISZ P2ERR	SET ERROR 22
2516	10740	017745	JSB PHI.L	PHI LSN
2517	10741	000560	OCT 560	SECONDARY (DSJ)
2518	10742	017747	JSB PHI	
2519	10743	001001	OCT 1001	COUNTED XFER OF 4
2520	10744	017746	JSB PHI.I	GET BYTE
2521	10745	037755	ISZ P2ERR	SET ERROR 23
2522	10746	002002	SZA	WAS THERE AN ERROR
2523	10747	127752	JMP DCER,I	REPORT ERROR
2524	10750	127743	JMP DC.RW,I	RETURN

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2526*      TELL PHI TO TALK AND DISC TO LISTEN
2527*      AND PASS A SECONDARY
2528*
2529 10751 017747 PHI&T JSB PHI
2530 10752 031002      OCT 31002      PHI OUTPUT COMMAND
2531 10753 017747      JSB PHI
2532 10754 000537      OCT 537        UNT
2533 10755 017747      JSB PHI
2534 10756 000477 UNL   OCT 477        UNL
2535 10757 017747      JSB PHI
2536 10760 000536      OCT 536        CTLR LSN
2537 10761 067757      LDB P2.SB      GET DISC ADDRESS
2538 10762 060001      LDA B
2539 10763 033072      IOR LSN        ADD LISTEN BIT
2540 10764 017750      JSB HPIB
2541 10765 067744      LDB PHI.T
2542 10766 160001      LDA B,I        GET DATA
2543 10767 017750      JSB HPIB      PASS IT TO CARD
2544 10770 037744      ISZ PHI.T      ADJUST RETRUN
2545 10771 127744      JMP PHI.T,I    RETURN
2546*
2547*      TELL PHI TO LISTEN AND DISC TO TALK
2548*      AND PASS A SECONDARY
2549*
2550 10772 017747 PHI&L JSB PHI
2551 10773 031002      OCT 31002      PHI OUTPUT COMMAND
2552 10774 017747      JSB PHI
2553 10775 000537      OCT 537        UNT
2554 10776 017747      JSB PHI
2555 10777 000477      OCT 477        UNL
2556 11000 017747      JSB PHI
2557 11001 000476      OCT 476        CTLR LSN
2558 11002 067757      LDB P2.SB      GET DISC ADDRESS
2559 11003 060001      LDA B
2560 11004 033071      IOR TLK        ADD TALK BIT
2561 11005 017750      JSB HPIB
2562 11006 067745      LDB PHI.L
2563 11007 160001      LDA B,I        GET DATA
2564 11010 017750      JSB HPIB      PASS IT TO CARD
2565 11011 037745      ISZ PHI.L      ADJUST RETRUN
2566 11012 127745      JMP PHI.L,I    RETURN
2567*
2568 11013 063054 PHI&I LDA PIN      GET INPUT COMMAND
2569 11014 017750      JSB HPIB      PASS IT TO CARD
2570 11015 017747      JSB PHI
2571 11016 100000      OCT 100000     TELL CARD TO INPUT
2572 11017 102530      LIA DR        AND THEN GET DATA
2573 11020 013135      AND @377      MASK OFF UPPER BYTE
2574 11021 127746      JMP PHI.I,I    RETURN

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2576	11022	067747	PHI%	LDR PHI	
2577	11023	160001		LDA R,I	GET DATA
2578	11024	102630		OTA DR	PASS IT TO CARD
2579	11025	103730		STC DR,C	PASS TO PHI
2580	11026	037747		ISZ PHI	ADJUST RETURN
2581	11027	127747		JMP PHI,I	AND RETURN
2582*					
2583	11030	102630	HPTB%	OTA DR	
2584	11031	103730		STC DR,C	
2585	11032	063145		LDA @M2	WAIT FOR IT
2586	11033	034001		ISZ B	
2587	11034	027040		JMP *+4	
2588	11035	034000		ISZ A	
2589	11036	027040		JMP *+2	
2590	11037	127752		JMP DCFR,I	WAITED LONG ENOUGH
2591	11040	102330		SFS DR	
2592	11041	027033		JMP *-6	
2593	11042	127750		JMP HPIB,I	
2594*					
2595	11043	063073	PHIF%	LDA CMDF	ENABLE FLAG
2596	11044	102631		OTA CTL	
2597	11045	017747		JSB PHI	
2598	11046	060043		OCT 60043	FLUSH OUTBOUND FIFO
2599	11047	017747		JSB PHI	
2600	11050	031002		OCT 31002	
2601	11051	017747		JSB PHI	
2602	11052	000537		OCT 537	TELL DISC TO SHUT UP
2603	11053	017747		JSB PHI	
2604	11054	031004	PIN	OCT 31004	SET FLAG WHEN FIFO HAS DATA
2605	11055	063073		LDA CMDF	GET FLAG ENABLE
2606	11056	102631		OTA CTL	
2607	11057	063151		LDA @M20	SET MAX LOOP
2608	11060	002006		INA,SZA	
2609	11061	102330		SFS DR	ANY DATA
2610	11062	127751		JMP PHIFI,I	NO EXIT
2611	11063	103730		STC DR,C	YES EMPTY IT
2612	11064	027060		JMP *-4	TRY AGAIN
2613*					
2614	11065	177406	N250	DEC -250	1 MS DELAY COUNT
2615	11066	000400	@D256	DEC 256	
2616	11067	176100	TR1K	OCT 176100	
2617	11070	102000	TR31K	OCT 102000	
2618	11071	000500	TLK	OCT 500	
2619	11072	000440	LSN	OCT 440	
2620	11073	103004	CMDF	OCT 103004	
2621	11074	060000	DCDCW	OCT 60000	
2622	11075	011076	DCTYP	DEF *+1	OLD ** HEADS PER CYL / SECTORS PER TRA
2623	11076	101020		OCT 101020	8 2/16 MIN1 FLOPPY
2624	11077	051036		OCT 051036	5 2/30 88010-20
2625	11100	041040		OCT 041040	4 2/32 7910
2626	11101	022460		OCT 022460	2 5/48 7920
2627	11102	014500		OCT 014500	1 9/64 7925
2628	11103	060460		OCT 060460	6 1/48 7906

2630* CONSTANTS

2631*

2632	11104	000001	@1	OCT 1
2633	11105	000002	@2	OCT 2
2634	11106	000003	@3	OCT 3
2635	11107	000004	@4	OCT 4
2636	11110	000006	@6	OCT 6
2637	11111	000010	@10	OCT 10
2638	11112	000100	@100	OCT 100
2639	11113		RIT9	EQU *
2640	11113	001000	@1000	OCT 1000
2641	11114	001005	@1005	OCT 1005
2642	11115	000200	@200	OCT 200
2643	11116	000201	@201	OCT 201
2644	11117	000204	@204	OCT 204
2645	11120	000207	@207	OCT 207
2646	11121	002000	@2000	OCT 2000
2647	11122	002101	@2101	OCT 2101
2648	11123	000007	@7	OCT 7
2649	11124	000012	@12	OCT 12
2650	11125	000015	@15	OCT 15
2651	11126	000017	@17	OCT 17
2652	11127	000021	@21	OCT 21
2653	11130	000024	@24	OCT 24
2654	11131	000040	@40	OCT 40
2655	11132	000060	@60	OCT 60
2656	11133	000170	@170	OCT 170
2657	11134	000177	@177	OCT 177
2658	11135	000377	@377	OCT 377
2659	11136	001700	@1700	OCT 1700
2660	11137	037700	@3770	OCT 37700
2661	11140	000404	@404	OCT 404
2662	11141	000604	@604	OCT 604
2663	11142	076000	@76K	OCT 76000
2664	11143	100000	@100K	OCT 100000
2665	11144	177777	@M1	OCT -1
2666	11145	177776	@M2	OCT -2
2667	11146	177772	@M6	OCT -6
2668	11147	177770	@M10	OCT -10
2669	11150	177767	@M11	OCT -11
2670	11151	177760	@M20	OCT -20
2671	11152	177740	@M40	OCT -40
2672	11153	177754	@N20	DEC -20
2673	11154	177700	@N64	DEC -64

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2675*
2676 11155 000123 $2S OCT 123
2677 11156 000127 $2W OCT 127
2678*
2679 11157 060001 P2C% LDA B          SAVE DATA
2680 11160 067741      LDB P2C+1      GET ADDRESS
2681 11161 101100      RRR 16         SWAP A&B
2682 11162 013154      AND @N64
2683 11163 101100      RRR 16         SWAP BACK
2684 11164 007004      CMB,INB        MAKE IT NEGATIVE
2685 11165 047773      ADB P2.T0     NOW ADD STORE ADDRESS
2686 11166 101100      RRR 16         SWAP A&B
2687 11167 002020      SSA           IF NEGATIVE THEN OK
2688 11170 127740      JMP P2C,I      OK STORE CONTENTS
2689 11171 043154      ADA @N64      PAST 64 LOCATIONS?
2690 11172 002020      SSA
2691 11173 037740      ISZ P2C        NO SKIP STORE
2692 11174 127740      JMP P2C,I      RETURN
2693*
2694 11175          EOP2 EQU *          END OF PAGE 2
2695*
2696 11740          ORG 11740H
2697 00543          RAP2 EQU *-EOP2     REMAINING ARFA FOR PAGE 2
2698 11740 000000    P2C  NOP
2699 11741 017741      JSB *          SET CURRENT ADDRESS
2700 11742 027157    DC.IN JMP P2C%    GO CHECK ADDRESS
2701 11743 026333    DC.RW JMP DC%IN
2702 11744 026547    PHI.T JMP DC%RW
2703 11745 026751    PHI.L JMP PHI%T
2704 11746 026772    PHI.I JMP PHI%L
2705 11747 027013    PHI      JMP PHI%I
2706 11750 027022    HPTB  JMP PHI%
2707 11751 027030    PHIFL JMP HPIB%
2708 11752 027043    DCER  JMP PHIF%
2709 11753 067752    P2.ST LDB DCER
2710 11754 006004    P2.HC INB
2711 11755 124001    P2FRR JMP B,I
2712 11756 000000      NOP

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2714*      RETURN TO PAGE 3
2715*
2716 11757 063141 RINP3 LDA @604
2717 11760 007400      CCB
2718 11761 102601      OTA CPUST
2719 11762 026044      JMP LDP2      ENTRY FROM LOADER SECTION
2720*
2721*      RFP ENTRY POINTBREAK ENTRY POINT (SAME ON OTHER PAGE)
2722*
2723 11763 103105 P2VCP CLF 5      INSURE PARITY SENSE
2724 11764 106713      CLC 13B      DISABLE MAPING
2725 11765 103300      OCT 103300    SFS 0,C CHECK INTERRUPTS
2726 11766 027772      JMP *+4      THERE OFF
2727 11767 073772      STA P2.A      SAVE THE A REG.
2728 11770 003400      CCA          INDICATE INTS ON
2729 11771 027774      JMP *+3
2730 11772 073772      STA P2.A
2731 11773 002400      CLA
2732 11774 073764      STA P2.I
2733 11775 063120 P2VC0 LDA @207    INSURE UPPER PAGE
2734 11776 102601      OTA CPUST
2735 11777 027775      JMP P2VC0    LOOP IF ERROR
2736*
2737*      COMMON STORAGE
2738 11777      P2.CT EQU 1777B+P2
2739*
2740 11776      P2.T3 EQU 1776B+P2
2741 11775      P2.T2 EQU 1775B+P2
2742 11774      P2.T1 EQU 1774B+P2
2743 11773      P2.T0 EQU 1773B+P2
2744 11772      P2.A  EQU 1772B+P2
2745 11771      P2.B  EQU 1771B+P2
2746 11770      P2.E  EQU 1770B+P2
2747 11767      P2.D  EQU 1767B+P2
2748 11766      P2.GF EQU 1766B+P2
2749 11765      P2.M  EQU 1765B+P2
2750 11764      P2.I  EQU 1764B+P2
2751 11763      P2.EM EQU 1763B+P2
2752 11762      P2.DF EQU 1762B+P2
2753 11761      P2.UN EQU 1761B+P2
2754 11760      P2.FL EQU 1760B+P2
2755 11757      P2.SB EQU 1757B+P2
2756 11756      P2.SC EQU 1756B+P2

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2758 12000          ORG 12000B
2759 12000          P3   EQU *          PAGE 3 REFERENCE
2760*
2761*
2762*      RE-ENTRY TO LOADERS FOR CONTINUATION
2763*
2764*      CCA
2765*      OTA 1
2766*      CLC 2
2767*      JSB 1
2768*
2769*      THIS SEQUENCE WILL RE-ENABLE THE ROMS AND
2770*      LOAD THE NEXT CONSECUTIVE PROGRAM
2771*
2772 12000 000000      NOP
2773 12001 000000      NOP
2774 12002 107700      CLC 0,C          TURN OFF THE WORLD
2775 12003 002400      CLA              LOAD NEXT PROGRAM
2776 12004 000000      NOP              IGNORE POWER FAIL
2777 12005 000000      NOP              IGNORE PARITY ERRORS
2778 12006 000000      NOP              IGNORE TBG
2779 12007 000000      NOP              IGNORE MEMORY PROTECT
2780 12010 000000      NOP              IGNORE UNIMPLEMENTED INST.
2781 12011 102503      LIA 3            GET FLAG
2782 12012 002021      SSA,RSS          IS IT AUTO MODE?
2783 12013 026020      JMP LDR+2        YES - DO NEXT LOAD
2784 12014 102702      STC 2            NOT CONTINUE SO
2785 12015 124001      JMP B,I          RETURN TO PROGRAM

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2787*      II.  BOOT LOADERS SECTION
2788*      DETERMINE WHICH LOADER TO USE
2789*
2790 12016 107700 LDR   CLC 0,C      RESET THE WORLD
2791 12017 006501      CLB,CLE,RSS
2792 12020 006700      CLB,CCE      SET FOR SEQUENTIAL LOADING
2793 12021 077773      STB P3.T0
2794 12022 077775      STB P3.T2      INDICATE POWER UP BOOTING
2795 12023 077762      STB P3.DF
2796 12024 077756      STB P3.SC
2797 12025 077755      STB P3ERR     CLEAR ANY ERRORS
2798 12026 063547      LDA #604      INDICATE IN LOADER
2799 12027 102601      OTA CPUST
2800 12030 102501      LIA CPUST     GET CPU STATUS
2801 12031 001727      ALF,ALF       POSITION LOADER BITS
2802 12032 002011      SLA,RSS       SPECIAL OPTIONS?
2803 12033 026072      JMP SPCL      YES
2804 12034 002040      SEZ           CONTINUATION?
2805 12035 026224      JMP LDCON     YES
2806 12036 064004      LDB 4         NO CHECK IF THERE IS SOMETHING TO RESTART
2807 12037 006003      SZB,RSS
2808 12040 026043      JMP LDRC      NO THEN LOAD
2809 12041 063522      LDA #4        YES - SO RESTART IT
2810 12042 026127      JMP LDRCX
2811 12043 001310 LDRC  RAR,SLA      DETERMINE BOOT
2812 12044 026062      JMP LDRC1
2813 12045 001310      RAR,SLA
2814 12046 026057      JMP LDRC0
2815 12047 001210      RAL,SLA
2816 12050 026212      JMP LDRER     UNDEFINED LOADER (1)
2817 12051 002041      SEZ,RSS       IF CONT USE CARTRIDGE TAPE
2818 12052 026134      JMP CRSP1     GO TO VIRTUAL CONTROL PANEL
2819 12053 102501      LIA CPUST     GET STATUS
2820 12054 001710      ALF,SLA       IF DS FRONT PANNEL
2821 12055 026553      JMP DSLD      USE THE DS LOADER OTHERWISE (4)
2822 12056 026264      JMP CTLD      GO TO CARTRIDGE TAPE LOAD (0)
2823 12057 001210 LDRCO RAL,SLA
2824 12060 026212      JMP LDRER     UNDEFINED LOADER (3)
2825 12061 026762      JMP RMLD      PROM CARD LOADER (2)
2826 12062 001310 LDRC1 RAR,SLA
2827 12063 026067      JMP LDRC2
2828 12064 001310      RAR,SLA
2829 12065 026212      JMP LDRER     UNDEFINED LOADER (5)
2830 12066 026553      JMP DSLD      DISTRIBUTED LINK LOAD (4)
2831 12067 001310 LDRC2 RAR,SLA
2832 12070 026212      JMP LDRER     UNDEFINED LOADER (7)
2833 12071 027276      JMP DCLD      DISC CARTRIDGE LOAD (6)

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2835	12072	001310	SPCL	RAR,SLA	DETERMINE SPECIAL
2836	12073	026107		JMP SPCL1	
2837	12074	001310		RAR,SLA	
2838	12075	026101		JMP SPCL0	
2839	12076	001310		RAR,SLA	
2840	12077	026212		JMP LDRER	UNDEFINED SPECIAL
2841	12100	026105		JMP TST	LOOP ON PRETEST
2842	12101	001310	SPCL0	RAR,SLA	
2843	12102	026212		JMP LDRER	UNDEFINED SPECIAL
2844	12103	006006		INB,SZB	DELAY BEFORE LOOP
2845	12104	026103		JMP *-1	
2846	12105	002400	TST	CLA	RETURN TO PAGE 0 FOR PRETEST
2847	12106	027761		JMP CRSP2+1	
2848	12107	001310	SPCL1	RAR,SLA	
2849	12110	026114		JMP SPCL2	
2850	12111	001310		RAR,SLA	
2851	12112	026117		JMP EXRM	USER DEFINED EXTENDED ROM
2852	12113	026126		JMP LDRSX-1	START MAC 2250 ROM CODE
2853	12114	001310	SPCL2	RAR,SLA	
2854	12115	026212		JMP LDRER	UNDEFINED SPECIAL
2855	12116	026134		JMP CRSP1	GO TO VIRTUAL CONTROL PANEL
2856*					
2857	12117	063545	EXRM	LDA #377	SET LAST PAGE
2858	12120	070137		STA 137B	AND MAP LAST LOGICAL
2859	12121	106705		CLC 5	TURN OFF PARITY
2860	12122	106704		CLC 4	AND ANY OTHER INTERRUPTS
2861	12123	102711		STC 11B	TURN ON MAPS
2862	12124	003500		CCA,CLE	
2863	12125	001675		ELA,CLE,SLA,ERA	MAKE ADDRESS
2864	12126	062133		LDA RMADR	GO START ROM PROGRAM
2865	12127	007400	LDRSX	CCB	INDICATE PROGRAM IN EXECUTION
2866	12130	106601		OTR CPUST	
2867	12131	102702		STC 2	EXIT LOADER
2868	12132	124000		JMP A,I	
2869	12133	040002	RMADR	OCT 40002	

2871	12134	007401	CRSP1	CCB,RSS	
2872	12135	006400		CLB	
2873	12136	063525		LDA #207	
2874	12137	027761		JMP CRSP2+1	
2876	12140	002400	LDEX	CLA	NO ERRORS
2877	12141	073755		STA P3ERR	
2878	12142	063542		LDA #100	UPDATE MAPS INCASE OF DMA LOAD
2879	12143	164000		LDB A,I	
2880	12144	174000		STB A,I	
2881	12145	002004		INA	
2882	12146	053544		CPA #177	
2883	12147	007401		CCB,RSS	
2884	12150	026143		JMP *-5	
2885	12151	106624		OTB 24B	INDICATE INTERFACE HAS CHANGED
2886	12152	067775		LDB P3.T2	WAS THIS FROM THE VCP?
2887	12153	006003		SZB,RSS	??
2888	12154	026160		JMP *+4	NO
2889	12155	067762		LDB P3.DF	
2890	12156	006003		SZB,RSS	YES - LOAD AND GO?
2891	12157	026135		JMP CRSP1+1	NO RETURN TO VCP
2892	12160	067755		LDB P3ERR	WAS THERE AN ERROR?
2893	12161	006002		SZB	
2894	12162	026212		JMP LDREP	YES THEN REPORT IT
2895	12163	067762		LDB P3.DF	
2896	12164	007002		CMB,SZB	TERMINATE AFTER SECONDARY LOAD?
2897	12165	026177		JMP LDEX0	NO
2898	12166	062176		LDA HLT77	YES SO HALT AFTER LOAD
2899	12167	071700		STA 1700B	
2900	12170	062211		LDA JMP.2	SET CONTINUATION
2901	12171	071701		STA 1701B	
2902	12172	003400		CCA	
2903	12173	006400		CLB	
2904	12174	102702		STC 2	EXIT TO HALT
2905	12175	025700		JMP 1700B	
2906*					
2907	12176	102077	HLT77	HLT 77B	
2908*					
2909	12177	003700	LDEX0	CCA,CCE	NO START PROGRAM
2910	12200	102601		OTA CPUST	INDICATE ALL'S WELL
2911	12201	005500		ERR	MAKE B -1 IF LOAD CALL BACK
2912	12202	007003		CMB,SZB,RSS	
2913	12203	026207		JMP LDEX1	YES
2914	12204	067756		LDB P3.SC	GET INTERFACE USED
2915	12205	060001		LDA B	CHANGE HANDS
2916	12206	067762		LDB P3.DF	INDICATE AUTO BOOT OR POWER UP
2917	12207	102603	LDEX1	OTA 3	SET AUTO FLAG
2918	12210	102702		STC 2	DISABLE PROM
2919	12211	024002	JMP.2	JMP 2	NOW START PROGRAM

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2921	12212	002400	LDRER CLA	CHECK FOR FRONT PANEL
2922	12213	103503	LIA 3,C	
2923	12214	002002	SZA	
2924	12215	026135	JMP CRSP1+1	YES SO GO TO VCP
2925	12216	063547	LDA #604	INDICAT LOAD ERROR
2926	12217	002004	INA	
2927	12220	102601	OTA CPUST	
2928	12221	002006	INA,SZA	DELAY TO SHOW DISPLAY
2929	12222	026221	JMP *-1	
2930	12223	026016	JMP LDP	TRY AGAIN
2931*				
2932*			CONTINUATION LOADING	
2933*				
2934	12224	106503	LDCON LIB 3	IS THERE A VCP REGISTER
2935	12225	006003	SZB,RSS	
2936	12226	026043	JMP LDRC	NO THEN USE DEFAULT SWITCHES
2937	12227	102503	LIA 3	GET DEVICE
2938	12230	001700	ALF	
2939	12231	013524	AND #7	ONLY
2940	12232	002003	SZA,RSS	CARTRIDGE TAPE?
2941	12233	026264	JMP CTLD	YES
2942	12234	053521	CPA #2	PROM LOAD?
2943	12235	026762	JMP RMLD	YES
2944	12236	053522	CPA #4	DISTRIBUTED LINK?
2945	12237	026553	JMP DSLD	YES
2946	12240	053523	CPA #6	DISC LOAD?
2947	12241	027276	JMP DCLD	YES
2948	12242	026212	JMP LDRER	NONE SO ERROR
2949*				
2950*			ENTRY FROM OTHER PAGES	
2951*				
2952	12243	006003	LDRR SZB,RSS	POWER UP?
2953	12244	026016	JMP LDP	YES
2954	12245	006020	SSB	VCP OR LOADER
2955	12246	026142	JMP LDEX+2	RETURN FROM OTHER LOADER PAGE
2956	12247	002504	CLA,CLE,INA	NO ERRORS AND NOT CONTINUATION
2957	12250	073755	STA P3ERR	
2958	12251	060001	LDA B	VCP LOADER SELECTION
2959	12252	067774	LDB P3.T1	GET PARAMETERS
2960	12253	053576	CPA \$3CT	IS IT CATRTIDGE TAPE?
2961	12254	026264	JMP CTLD	YES
2962	12255	053577	CPA \$3RM	IS IT ROM I/O?
2963	12256	026762	JMP RMLD	YES
2964	12257	053600	CPA \$3DC	IS IT DISC CARTRIDGE?
2965	12260	027276	JMP DCLD	YES
2966	12261	053601	CPA \$3DS	DISTRIBUTED LINK?
2967	12262	026553	JMP DSLD	YES
2968	12263	026142	JMP LDEX+2	NONE SO LOAD ERPOR

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2970*      HP-2644/5 CARTRIDGE TAPE LOADER ROUTINE
2971 12264 017743 CTLD JSR S.SC      SET SELECT CODE
2972 12265 000020 #20 OCT 20      DEFAULT SELECT CODE AND FILE
2973 12266 037761      ISZ P3.UN      MAKE UNIT 0 LEFT DRIVE
2974 12267 067760      LDB P3.FL      IF NO FILE # THEN SKIP FIND
2975 12270 006003      SZB,RSS
2976 12271 026325      JMP CTLD.
2977 12272 062542 CTLDF LDA $ESC&      FIND FILE
2978 12273 017754      JSB CTO.W
2979 12274 062543      LDA $.P0
2980 12275 067761      LDB P3.UN
2981 12276 030001      IOR B
2982 12277 017754      JSB CTO.W
2983 12300 067760      LDB P3.FL      GET FILE NUMBER
2984 12301 060001      LDA B
2985 12302 006400      CLB
2986 12303 100400      DIV #12      DIVIDE BY 10
2987 12305 077774      STB P3.T1
2988 12306 032547      IOR $.U0      ADD COMMAND
2989 12307 017754      JSB CTO.W
2990 12310 067774      LDB P3.T1      DO SECOND NUMBER
2991 12311 060001      LDA B
2992 12312 033540      IOR #60      MAKE IT A NUMBER
2993 12313 017753      JSB CTO.B      GIVE IT TO THE TERMINAL
2994 12314 062543      LDA $.P0
2995 12315 033521      IOR #2
2996 12316 017754      JSB CTO.W
2997 12317 062552      LDA SCDC1
2998 12320 017754      JSB CTO.W
2999 12321 017751      JSB CTI.B
3000 12322 053574      CPA $3S      OK?
3001 12323 002001      RSS
3002 12324 026142      JMP LDEX+2      NO
3003 12325 037755 CTLD. ISZ P3ERR      SET ERROR 11
3004 12326 067773      LDB P3.T0
3005 12327 060001      LDA B
3006 12330 053575      CPA $3W      READ OR WRITE
3007 12331 026406      JMP CTDI      WRITE

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*

3009	12332	002400	CLA	CLEAR RECORD FLAG
3010	12333	073760	STA P3.FL	
3011	12334	062542	CTLD0 LDA \$ESCA	OUTPUT "ESC &"
3012	12335	017754	JSB CTO.W	
3013	12336	062543	LDA S.P0	P'2
3014	12337	067761	LDB P3.UN	
3015	12340	030001	IOR R	
3016	12341	017754	JSR CTO.W	
3017	12342	062550	LDA S.S0	
3018	12343	033521	IOR #2	
3019	12344	017754	JSB CTO.W	
3020	12345	062544	LDA SRDC1	R (DC1)
3021	12346	017754	JSB CTO.W	
3022	12347	017750	JSR CTI.W	
3023	12350	060001	LDA B	CHANGE HANDS
3024	12351	052541	CPA CTRS	END OF FILE?
3025	12352	026401	JMP CTLDX	YES
3026	12353	017750	JSB CTI.W	LOAD COUNT WORDS
3027	12354	017751	JSR CTI.B	
3028	12355	063535	LDA #21	TELL TERM. TO TRANSMIT
3029	12356	073760	STA P3.FL	INDICATE RECORD READ
3030	12357	017753	JSB CTO.B	
3031	12360	017751	JSB CTI.B	READ FIRST BYTE
3032	12361	003004	CMA,INA	MAKE COUNT NEG.
3033	12362	073777	STA P3.CT	SAVE COUNT
3034	12363	017751	JSB CTI.B	GET SECOND BYTE
3035	12364	017750	JSB CTI.W	GET LOAD ADDRESS
3036	12365	077773	STR P3.T0	SAVE LOAD ADDRESS
3037	12366	077774	STR P3.T1	AND START CHECKSUM
3038	12367	017750	CTLDL JSB CTI.W	GET DATA
3039	12370	017732	JSB P3C	CHECK FOR MEMORY LIMIT AND STORE IT
3040	12371	047774	ADB P3.T1	ADD TO CHECKSUM
3041	12372	077774	STR P3.T1	
3042	12373	037777	ISZ P3.CT	DONE WITH RECORD
3043	12374	026367	JMP CTLDL	NO
3044	12375	017750	JSB CTI.W	GET CHECKSUM FROM TAPE
3045	12376	057774	CPR P3.T1	DOES CHECKSUM AGREE?
3046	12377	026334	JMP CTLD0	YES DO NEXT RECORD
3047	12400	026142	JMP LDEX+2	NO RETURN WITH ERROR
3048*				
3049	12401	067760	CTLDX LDB P3.FL	WAS THERE A RECORD READ?
3050	12402	006002	SZB	
3051	12403	026140	JMP LDFX	YES ALL'S WELL
3052	12404	037755	ISZ P3ERR	SET FRROR 12
3053	12405	026142	JMP LDEX+2	NO THEN ERROR

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3055	12406	062265	CTDP	LDA #20	SET WRITE ERROR 20
3056	12407	073755		STA P3ERR	
3057	12410	067757		LDB P3.SB	SET ADDRESS
3058	12411	005727		BLF, BLF	
3059	12412	005700		BLF	
3060	12413	077773		STB P3.T0	
3061	12414	063573		LDA BLK	SET NUMBER OF BLOCKS
3062	12415	073776		STA P3.T3	
3063	12416	067776	CTDP0	LDB P3.T3	END OF WRITE
3064	12417	006003		SZB, RSS	
3065	12420	026140		JMP LDEX	YES
3066	12421	062542		LDA \$ESC&	OUTPUT "ESC &
3067	12422	017754		JSB CTO.W	
3068	12423	062543		LDA \$.P0	.P UNIT
3069	12424	067761		LDR P3.UN	
3070	12425	030001		IOR B	
3071	12426	017754		JSB CTO.W	
3072	12427	062545		LDA \$.D1	
3073	12430	017754		JSB CTO.W	
3074	12431	062546		LDA \$34	3 4
3075	12432	017754		JSB CTO.W	
3076	12433	062551		LDA \$WENO	W (ENQ)
3077	12434	017754		JSB CTO.W	
3078	12435	017751		JSB CTI.B	WAIT FOR ACKNOWLEDGE
3079	12436	053523		CPA #6	WAS IT AN ACKNOWLEDGE
3080	12437	002001		RSS	YES
3081	12440	026416		JMP CTDP0	NO TRY BLOCK AGAIN
3082	12441	063573		LDA BLK	SET FOR ONE BLOCK
3083	12442	073777		STA P3.CT	
3084	12443	003004		CMA, INA	
3085	12444	001727		ALF, ALF	PUT POSITIVE COUNT IN UPPER HALF
3086	12445	017754		JSB CTO.W	
3087	12446	067773		LDB P3.T0	GET ADDRESS
3088	12447	060001		LDA B	
3089	12450	073774		STA P3.T1	START CHECKSUM
3090	12451	017754		JSB CTO.W	
3091	12452	067772	CTDPL	LDB P3.A	GET A & B REG
3092	12453	060001		LDA B	
3093	12454	067771		LDB P3.B	
3094	12455	167773		LDR P3.T0, I	GET DATA
3095	12456	060001		LDA B	
3096	12457	047774		ADB P3.T1	ADD DATA TO CHECKSUM
3097	12460	077774		STB P3.T1	
3098	12461	017754		JSB CTO.W	OUTPUT WORD
3099	12462	037773		ISZ P3.T0	MOVE TO NEXT LOCATION
3100	12463	037777		ISZ P3.CT	DONE WITH BLOCK
3101	12464	026452		JMP CTDPL	NO
3102	12465	067774		LDR P3.T1	YES OUTPUT CHECKSUM
3103	12466	060001		LDA B	
3104	12467	017754		JSB CTO.W	
3105	12470	037776		ISZ P3.T3	NO DO ANOTHER BLOCK?
3106	12471	000000		NOP	NO

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3108 12472 063535      LDA #21      OUTPUT DC1
3109 12473 017753      JSB CTO.R
3110 12474 017751      JSB CTI.B      GET RESULTS
3111 12475 053574      CPA S3S      WAS IT GOOD?
3112 12476 026416      JMP CTDPO      YES
3113 12477 026142      JMP LDEX+2      NO

3115 12500 017751      CTI%W JSB CTI.B      GET A BYTE
3116 12501 001727      ALF,ALF      PUT IT IN UPPER HALF
3117 12502 073754      STA CTO.W      SAVE FIRST BYTE
3118 12503 017751      JSR CTI.B      GET LOWER BYTE
3119 12504 067754      LDB CTO.W      GET UPPER BYTE
3120 12505 044000      ADB A      PUT IN B-REG.
3121 12506 127750      JMP CTI.W,I      RETURN
3122*

3123 12507 062537      CTI%R LDA CTCWI      GET INPUT CONTROL WORD
3124 12510 102631      OTA CTL
3125 12511 017752      JSB CTIO      GET DATA
3126 12512 013545      AND #377      MASK OFF UNWANTED BYTE
3127 12513 127751      JMP CTI.B,I      RETURN
3128*

3129 12514 013545      CTO%B AND #377      MASK UPPER HALF OFF
3130 12515 064000      LDB A
3131 12516 062540      LDA CTCWO      GET OUTPUT CONTROL WORD
3132 12517 102631      OTA CTL
3133 12520 017752      JSB CTIO      OUTPUT IT
3134 12521 127753      JMP CTO.R,I      RETURN
3135*

3136 12522 073750      CTO%W STA CTI.W      SAVE A-REG.
3137 12523 001727      ALF,ALF
3138 12524 017753      JSB CTO.B      OUTPUT UPPER HALF
3139 12525 067750      LDB CTI.W
3140 12526 060001      LOA R      CHANGE HANDS
3141 12527 017753      JSR CTO.B      OUTPUT LOWER HALF
3142 12530 127754      JMP CTO.W,I      RETURN
3143*

3144 12531 106630      CTIO% OTB DR      OUTPUT DATA
3145 12532 103730      STC DR,C      START TRANSFER
3146 12533 102330      SFS DR      WAIT FOR IT
3147 12534 026533      JMP *-1
3148 12535 102530      LIA DR      GET DATA
3149 12536 127752      JMP CTIO,I      RETURN
3150*

3151 12537 002400      CTCWI OCT 002400
3152 12540 001000      CTCWO OCT 001000
3153 12541 017015      CTRs OCT 17015
3154 12542 015446      $ESC& OCT 15446
3155 12543 070060      $.PO OCT 70060
3156 12544 051021      $RDC1 OCT 51021
3157 12545 062061      $.D1 OCT 62061
3158 12546 031464      $34 ASC 1,34
3159 12547 072460      $.UO OCT 72460
3160 12550 071460      $.SO OCT 71460
3161 12551 053405      $WENO OCT 53405
3162 12552 041421      $CDC1 OCT 41421

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3164* DISTRIBUTED SYSTEMS LINK LOADER

3165*

3166	12553	017743	DSL D	JSB S.SC	SET SELECT CODE
3167	12554	040024		OCT 40024	DEFAULT SELECT CODE & DEVICE 4
3168	12555	017742		JSB DS.WF	WAIT FOR DS
3169	12556	026142		JMP LDEX+2	TIMED OUT
3170	12557	037755		ISZ P3ERR	MOVE TO 12
3171	12560	037755		ISZ P3ERR	
3172	12561	067773		LDB P3.T0	CHECK IF THIS IS A DUMP
3173	12562	060001		LDA B	CHANGE HANDS
3174	12563	053575		CPA S3W	READ OR WRITE?
3175	12564	026654		JMP DSWR	IT'S A WRITE!!
3176	12565	063732		LDA DSDNL	ASK FOR A DOWN LOAD
3177	12566	017741		JSB DS.FT	WAIT FOR COMPLETION OF REQUEST
3178	12567	026142		JMP LDEX+2	TIMED OUT
3179	12570	037755		ISZ P3ERR	SET ERROR 13
3180	12571	067760		LDB P3.FL	GET FILE NUMBER
3181	12572	107630		OTB DR,C	PASS IT TO THE CARD
3182	12573	017742		JSB DS.WF	WAIT FOR IT TO COMPLETE
3183	12574	026142		JMP LDEX+2	TIMED OUT SO ERROR
3184	12575	007400		CCR	SET TO READ A FRAME
3185	12576	077777		STB P3.CT	(FRAME COUNT TO -1)
3186*					
3187	12577	017740	DSRD	JSB DS.GT	GET WORD COUNT
3188	12600	101050		LSR 8	POSITION COUNT IN B
3189	12601	007007		CMB,INB,SZR,RSS	MAKE COUNT NEG. (DONE?)
3190	12602	026622		JMP DSDUN	YES
3191	12603	077774		STB P3.T1	SAVE COUNT
3192	12604	017740		JSB DS.GT	GET LOAD ADDRESS
3193	12605	077773		STB P3.T0	SAVE LOAD ADDRESS
3194	12606	077776		STB P3.T3	AND START CHECKSUM
3195	12607	017740	DSRDL	JSB DS.GT	GET WORD REQUEST
3196	12610	017732		JSB P3C	CHECK MEMORY LIMIT
3197	12611	047776		ADB P3.T3	ADD TO CHECKSUM
3198	12612	077776		STB P3.T3	
3199	12613	037774		ISZ P3.T1	DONE WITH RECORD
3200	12614	026607		JMP DSPDL	NO
3201	12615	017740		JSB DS.GT	GET CHECKSUM
3202	12616	057776		CFB P3.T3	DOES CHECKSUM AGREE?
3203	12617	026577		JMP DSRD	YES DO NEXT RECORD
3204	12620	063527		LDA #11	SET CHECK SUM ERROR
3205	12621	026626		JMP DSEX	NO RETURN WITH ERROR
3206*					
3207	12622	017740	DSDUN	JSB DS.GT	GET ADDRESS AS FLAG
3208	12623	006003		SZB,RSS	GOOD OR BAD
3209	12624	026140		JMP LDEX	GOOD COMPLETED
3210	12625	063532		LDA #14	
3211	12626	073755	DSEX	STA P3ERR	SET ERROR RETURN
3212	12627	026142		JMP LDEX+2	

*

3214	12630	037777	DS%GT	ISZ P3.CT	TIME FOR NEW FRAME?
3215	12631	026646		JMP DS%G0	NO JUST READ A WORD
3216	12632	063533		LDA #15	SET ERROR 15
3217	12633	073755		STA P3ERR	
3218	12634	062673		LDA DSINR	GET RUFFER REQUEST
3219	12635	017741		JSB DS.FT	GIVE IT TO CARD
3220	12636	026142		JMP LDFX+2	TIMED OUT
3221	12637	037755		ISZ P3ERR	SET ERROR 16
3222	12640	106530		LIB DR	NO GET BUFFER COUNT
3223	12641	060001		LDA B	SAVE COUNT
3224	12642	007004		CMB,INR	MAKE FRAME COUNT NEGATIVE
3225	12643	077777		STR P3.CT	SAVE IT
3226	12644	017741		JSB DS.FT	TELL CARD HOW MUCH TO TRANSFER
3227	12645	026142		JMP LDFX+2	TIMED OUT
3228	12646	063534	DS%G0	LDA #17	SET ERROR 17
3229	12647	073755		STA P3ERR	
3230	12650	017742		JSB DS.wF	WAIT FOR FLAG
3231	12651	026142		JMP LDEX+2	IT DID S7 ERROR
3232	12652	107530		LIB DR,C	OK GET DATA
3233	12653	127740		JMP DS.GT,I	RETURN

```

3235*      THIS ROUTINE DUMPS A MEMORY IMAGE TO A REMOTE COMPUTER
3236*
3237 12654 062265 DSWR LDA #20      SET ERROR 20
3238 12655 073755      STA P3ERR
3239 12656 062761      LDA DSVCP    TELL INTF TO GO INTO VCP MODE
3240 12657 017741      JSB DS.FT
3241 12660 026142      JMP LDEX+2   TIMED OUT
3242 12661 037755      ISZ P3ERR    SET ERROR 21
3243 12662 006400      CLR          SET STARTING ADDRESS
3244 12663 077773      STB P3.T0    SAVE IT
3245 12664 002404 DSWRO CLA,INA     1 PLUS RUBOUT
3246 12665 017736      JSB DS.B     OUTPUT 1 BYTE
3247 12666 063545      LDA #377     NOW RUBOUT
3248 12667 017736      JSB DS.B
3249 12670 017737      JSB DS.CM    TRANSMITT BUFFFR
3250 12671 060400      OCT 60400
3251 12672 017737      JSB DS.CM    ASK FOR BUFFER
3252 12673 061400 DSWNR OCT 61400   ASK FOR BYTE
3253 12674 017737      JSB DS.CM
3254 12675 061000      OCT 61000
3255 12676 053545      CPA #377     CAN IT BE ACCEPTED?
3256 12677 026722      JMP DSWEX    NO SO ERROR
3257 12700 002003      SZA,RSS      DONE?
3258 12701 026140      JMP LDEX     YES
3259 12702 003004      CMA,INA      MAKE IT NEGATIVE
3260 12703 073777      STA P3.CT    SAVE AS COUNTER
3261 12704 067772 DSWR1 LDB P3.A    GET A AND B REGISTERS
3262 12705 060001      LDA B
3263 12706 067771      LDB P3.B
3264 12707 167773      LDB P3.T0,I  GET DATA
3265 12710 060001      LDA B
3266 12711 001727      ALF,ALF
3267 12712 017736      JSB DS.B     TRANSFER CHARACTER
3268 12713 167773      LDB P3.T0,I
3269 12714 060001      LDA B
3270 12715 017736      JSB DS.B
3271 12716 037773      ISZ P3.T0    MOVE ADDRESS UP ONE
3272 12717 037777      ISZ P3.CT    DONE WITH THIS ONE?
3273 12720 026704      JMP DSWR1    NO
3274 12721 026664      JMP DSWRO    YES THEN MOVE TO NEXT TRANSFER
3275*
3276 12722 063536 DSWEX LDA #22     SET ERROR 22
3277 12723 026626      JMP DSEX     RETURN

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3279 12724 013545 DS%B AND #377
3280 12725 033557 IOR #60K DS PUT BYTE REQUEST
3281 12726 017741 JSB DS.FT WAIT FOR FLAG
3282 12727 026142 JMP LDEX+2 TIMED OUT
3283 12730 102530 LIA DR GET DATA
3284 12731 127736 JMP DS.B,I RETURN
3285*
3286 12732 067737 DS%CM LDB DS.CM GET COMMAND
3287 12733 160001 LDA B,I
3288 12734 017741 JSB DS.FT WAIT FOR FLAG
3289 12735 026142 JMP LDEX+2 TIMED OUT
3290 12736 102530 LIA DR GET DATA
3291 12737 037737 ISZ DS.CM
3292 12740 064000 LDB A
3293 12741 127737 JMP DS.CM,I
3294*
3295 12742 102630 DS%FT OTA DR
3296 12743 103730 STC DR,C
3297 12744 063573 LDA BLK GET TIME OUT
3298 12745 102230 SFC DR
3299 12746 026754 JMP *+6
3300 12747 034001 ISZ B
3301 12750 026745 JMP *-3
3302 12751 034000 ISZ A
3303 12752 026745 JMP *-5
3304 12753 127741 JMP DS.FT,I RETURN TIME OUT
3305 12754 037741 ISZ DS.FT NO SKIP TIME OUT
3306 12755 127741 JMP DS.FT,I
3307*
3308 12756 067742 DS%WF LDB DS.WF CHANGE RETURN ADDRESS
3309 12757 077741 STB DS.FT
3310 12760 026744 JMP DS%FT+2 SKIP OUTPUT JUST FLAG
3311*
3312 12761 067400 DSVCP OCT 67400

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*

3314* UV PROM LOADER

3315*

3316	12762	017743	RMLD	JSB S.SC	SET SELECT CODE
3317	12763	020022		OCT 20022	DEFAULT SELECT CODE DEVICE 2
3318	12764	067760		LDB P3.FL	MAKE FILE # NEG
3319	12765	007000		CMB	MAKE NUMBER NEGATIVE
3320	12766	077760		STB P3.FL	SAVE PROGRAM NUMBER
3321	12767	002400		CLA	START WITH FIRST LOCATION IN ROM
3322	12770	073773	RMLD0	STIA P3.T0	SAVE IT
3323	12771	002021		SSA,RSS	IF ADDRESS GOES NEGATIVE THEN NEXT SC
3324	12772	027000		JMP RMLD1	
3325	12773	017735		JSB RMNSC	MOVE TO NEXT SELECT CODETER
3326	12774	067773		LDB P3.T0	GET REMAINING COUNT
3327	12775	060001		LCA B	
3328	12776	001665		ELA,CLE,ERA	ELIMINATE BIT 15
3329	12777	026770		JMP RMLD0	
3330	13000	102631	RMLD1	OTA CTL	PASS ADDRESS TO ROM BOARD
3331	13001	102730		STC DR	READ LOCATION IN ROM
3332	13002	003400		CCA	
3333	13003	102530		LIA DR	GET DATA FROM ROM
3334	13004	073777		STA P3.CT	SAVE COUNT
3335	13005	053563		CPA #M1	END OF PROGRAMS?
3336	13006	027075		JMP RMLD3	YES THEN ERROR RETURN
3337	13007	002021		SSA,RSS	IS THIS EXTENDED LOAD?
3338	13010	027077		JMP RMLD4	YES
3339	13011	003004		CMA,INA	MOVE UP ONE LOCATION
3340	13012	067773		LDB P3.T0	GET PREVIOUS ADDRESS
3341	13013	040001		ADA B	MOVE TO NEXT PROGRAM
3342	13014	043521		ADA #2	
3343	13015	037760		ISZ P3.FL	WAS THIS IT?
3344	13016	026770		JMP RMLD0	NO TRY NEW ONE
3345	13017	102730		STC DR	MOVE TO LOCATION IN MEMORY
3346	13020	102530		LIA DR	
3347	13021	073773		STA P3.T0	SAVE IT
3348	13022	067743		LDB S.SC	CHECK IF ON UPPER PAGE
3349	13023	101100		RRR 16	
3350	13024	013561		AND #76K	
3351	13025	002002		SZA	
3352	13026	027060		JMP RMLD2	YES SHIP CHECK

3354	13027	005121	BRS,RRS	IS ADDRESS GREATER THAN 3
3355	13030	006002	SZB	
3356	13031	027060	JMP RMLD2	YES SKIP MOVF
3357	13032	102501	LIA CPUST	
3358	13033	001200	RAL	
3359	13034	002071	SSA,RSS	
3360	13035	027040	JMP *+3	
3361	13036	063537	RMLDE LDA #40	CAN'T DO IT
3362	13037	026141	JMP LDEX+1	
3363	13040	063550	LDA #1700	SET FROM ADDRESS
3364	13041	073743	STA S,SC	
3365	13042	033561	IOR #76K	
3366	13043	167743	LDB S,SC,I	
3367	13044	174000	STB A,I	
3368	13045	037743	ISZ S,SC	
3369	13046	002004	INA	
3370	13047	002021	SSA,RSS	
3371	13050	027043	JMP *-5	
3372	13051	103503	LIA 3,C	CHANGE BREAK ADDRESS
3373	13052	033561	IOR #76K	
3374	13053	103603	OTA 3,C	
3375	13054	063561	LDA #76K	
3376	13055	033057	IOR *+2	
3377	13056	124000	JMP A,I	
3378	13057	001060	DEF *+1-P3	
3379	13060	102730	RMLD2 STC DR	NOW TRANSFER DATA
3380	13061	102531	LIA CTL	CHECK IT HASN'T ROLLED OVER
3381	13062	002021	SSA,RSS	
3382	13063	027070	JMP *+5	NO - CONTINUE
3383	13064	017735	JSB RMNSC	MOVE TO NEXT SELECT CODE
3384	13065	002400	CLA	START WITH NEW
3385	13066	102631	OTA CTL	ADDRESS ON CARD
3386	13067	027060	JMP RMLD2	
3387	13070	106530	LIB DR	GET DATA
3388	13071	017732	JSB P3C	CHECK IF STORABLE
3389	13072	037777	ISZ P3,CT	END OF TRANSFER
3390	13073	027060	JMP RMLD2	NO
3391	13074	026140	JMP LDEX	YES
3392*				
3393	13075	063530	RMLD3 LDA #12	SET FRROR 12
3394	13076	026141	JMP LDEX+1	

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3396* EXTENDED LOAD

3397*

3398	13077	103730	RMLD4	STC DR,C	MOVE TO PARTIAL
3399	13100	106531		LIB CTL	RESET FLAG SKIP
3400	13101	106631		OTB CTL	
3401	13102	106530		LIB DR	GET PARTIAL
3402	13103	006002		SZB	IS THERE ANY
3403	13104	002004		INA	YES COUNT IT
3404	13105	043567		ADA #M11	IS IT OVER 8
3405	13106	002020		SSA	??
3406	13107	027114		JMP *+5	NO THEN NEW FORMAT
3407	13110	067777		LDB P3.CT	
3408	13111	060001		LDA B	
3409	13112	003004		CMA,INA	
3410	13113	027004		JMP RMLD1+4	
3411	13114	102531		LIA CTL	
3412	13115	043563		ADA #M1	BACK UP ONE
3413	13116	067777		LDB P3.CT	GET PARTIAL
3414	13117	006003		SZB,RSS	IF PARTIAL ONLY THEN OK
3415	13120	027141		JMP RMLD5	
3416	13121	002002		SZA	NOT THEN MUST BE ON CARD BOUNDARY
3417	13122	027075		JMP RMLD3	NOT SO ERROR
3418	13123	037760		ISZ P3.FL	IS THIS THE FILE
3419	13124	027126		JMP *+2	
3420	13125	027157		JMP RMLX	YES THEN LOAD IT
3421	13126	102530		LIA DR	GET PARTIAL
3422	13127	073773		STA P3.T0	SAVE IT
3423	13130	017735		JSB RMNSC	MOVE TO NEXT SELECT CODE
3424	13131	007400		CCB	
3425	13132	047777		ADB P3.CT	
3426	13133	077777		STB P3.CT	
3427	13134	006002		SZB	
3428	13135	027130		JMP *-5	
3429	13136	067773		LDB P3.T0	GET PARTIAL
3430	13137	060001		LDA B	
3431	13140	026770		JMP RMLD0	
3432	13141	106530	RMLD5	LIB DR	PARTIAL ONLY
3433	13142	047773		ADB P3.T0	
3434	13143	060001		LDA B	
3435	13144	037760		ISZ P3.FL	IS THIS THE FILE
3436	13145	026770		JMP RMLD0	NO SKIP IT
3437	13146	002400		CLA	SET STARTING ADDRESS
3438	13147	073773		STA P3.T0	
3439	13150	102530		LIA DR	GET PARTIAL
3440	13151	003004		CMA,INA	MAKE IT NEG
3441	13152	073777		STA P3.CT	
3442	13153	102531		LIA CTL	BACK UP ONE
3443	13154	043563		ADA #M1	
3444	13155	102631		OTA CTL	
3445	13156	027060		JMP RMLD2	GO DO TRANSFER

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3447	13157	103503	RMLX	LIA 3,C	CHECK IF ON BASE PAGE
3448	13160	013561		AND #76K	IF NOT
3449	13161	002002		SZA	
3450	13162	027036		JMP RMLDE	THEN CAN'T DO IT
3451	13163	102530		LIA DR	GET PARTIAL AGAIN
3452	13164	073774		STA P3.T1	SAVE IT
3453	13165	063273		LDA RM1K	TRANSFER BASE PAGE UNDER DMA
3454	13166	006700		CLB,CCE	SET BIT 15
3455	13167	005500		ERR	
3456	13170	017734		JSR RM.TR	MAKE TRANSFER
3457	13171	063274		LDA RM31K	SECOND PORTION COUNT AND ADDRESS
3458	13172	064000		LDB A	
3459	13173	017734		JSR RM.TR	TRANSFER IT
3460	13174	067774		LDB P3.T1	GET PARTIAL
3461	13175	006002		SZB	IF PARTIAL COUNT AS WHOLE
3462	13176	037777		ISZ P3.CT	
3463	13177	006400		CLB	
3464	13200	077732		STB P3C	CLEAR MAP REG
3465	13201	007400	RMLX0	CCB	DECREMENT COUNT
3466	13202	047777		ADB P3.CT	
3467	13203	077777		STB P3.CT	
3468	13204	006002		SZB	
3469	13205	006020		SSB	DONE
3470	13206	026140		JMP LDEX	YES EXIT
3471	13207	017735		JSR RMNSC	NO - MOVE TO NEXT SC
3472	13210	006400		CLB	
3473	13211	106502		LIB 2	CHECK IF THERE
3474	13212	050001		CPA B	
3475	13213	002001		RSS	
3476	13214	027075		JMP RMLD3	NO SO ERROR
3477	13215	067732		LDB P3C	USE MAPS
3478	13216	060001		LDA B	
3479	13217	043537		ADA #40	MOVE UP ONE MAP
3480	13220	073732		STA P3C	SAVE IT
3481	13221	064000		LDB A	
3482	13222	063562		LDA #100K	DO ALL OF IT
3483	13223	017734		JSR RM.TP	
3484	13224	027201		JMP RMLX0	DO NEXT BLOCK

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3486	13225	102623	RM%TR	OTA 23B	PASS COUNT OUT
3487	13226	063272		LDA RMCW	GET CONTROL WORD
3488	13227	006021		SSB,RSS	
3489	13230	002004		INA	
3490	13231	102621		OTA 21B	CONTROL
3491	13232	060001		LDA B	
3492	13233	006021		SSB,RSS	ADDRESS OR MAPPED
3493	13234	006400		CLB	MAPPED SO ADDR 0
3494	13235	106622		OTB 22B	
3495	13236	005665		ELB,CLF,FRB	ELIMINATE BIT 15
3496	13237	106631		OTB 31B	AND CARD ADDRESS
3497	13240	064141		LDB 141B	SAVE MAP CONTENT
3498	13241	077774		STB P3.T1	
3499	13242	103130		CLF DR	AND ANY FLAGS
3500	13243	070141		STA 141B	SET NEW MAP REG
3501	13244	103721		STC 21B,C	START TRANSFER
3502	13245	002400		CLA	
3503	13246	102223		SFC 23B	DONE
3504	13247	027254		JMP *+5	
3505	13250	002006		INA,SZA	
3506	13251	027246		JMP *-3	
3507	13252	063531		LDA #13	TIME OUT
3508	13253	026141		JMP LDEX+1	
3509	13254	106721		CLC 21B	
3510	13255	067774		LDB P3.T1	RESTORE MAP REG
3511	13256	074141		STB 141B	
3512	13257	127734		JMP RM.TR,I	RETURN
3513*					
3514	13260	102502	RM%SC	LIA 2	MOVE TO NEXT SELECT CODE
3515	13261	002004		INA	
3516	13262	053542		CPA #100	NOT OVER
3517	13263	027075		JMP RMLD3	YEP
3518	13264	103602		OTA 2,C	OK
3519	13265	002400		CLA	SEE IF IT IS THERE
3520	13266	102502		LIA 2	
3521	13267	002003		SZA,RSS	
3522	13270	027075		JMP RMLD3	NO SO ERROR
3523	13271	127735		JMP RMNSC,I	OK RETURN
3524*					
3525	13272	040200	RMCW	OCT 40200	STC + INPUT
3526	13273	176100	RM1K	OCT 176100	
3527	13274	102000	RM31K	OCT 102000	
3528	13275	002000	RMADX	OCT 2000	

3530* HP-1B DISC LOADER

3531*

3532	13276	017743	DCLD	JSB S.SC	SET SELECT CODE
3533	13277	062027		OCT 62027	DEFAULT SELECT CODE
3534	13300	006404		CLB,INR	INDICATE DISC ROOT
3535	13301	027760		JMP CRSP2	GO TO OTHER PAGE

*

3537* SET SELECT CODE

3538*

3539	13302	103101	S%SC	CLO	
3540	13303	063521		LDA #2	SET SELECT CODE ERROR
3541	13304	073755		STA P3ERR	
3542	13305	002440		CLA,SEZ	CLEAR FILE NO. (CONTINUE)
3543	13306	027322		JMP S%SC0	YES USE DEFAULT
3544	13307	073760		STA P3.FL	
3545	13310	006003		SZB,RSS	WAS THIS A DEFAULT?
3546	13311	027325		JMP S%SC1	YES
3547	13312	060001		LDA B	NO FILE # ONLY?
3548	13313	013570		AND #M20	MASK OFF FILE
3549	13314	101100		RRR 16	CHANG HANDS
3550	13315	006002		SZB	?
3551	13316	027330		JMP S%SC2	
3552	13317	073760		STA P3.FL	YES FILE ONLY
3553	13320	102101		STO	INDICATE FILE SET
3554	13321	027325		JMP S%SC1	
3555	13322	102503	S%SC0	LIA 3	GET PREVIOUS DATA
3556	13323	002002		SZA	
3557	13324	027327		JMP S%SC2-1	
3558	13325	067743	S%SC1	LDB S.SC	PICK UP DEFAULT SC
3559	13326	160001		LDA R,I	
3560	13327	013554		AND #7777	NO FILE NUMBER
3561	13330	073756	S%SC2	STA P3.SC	SAVE SELECT CODE USED
3562	13331	013540		AND #60	MUST BE OVER 20 OCT
3563	13332	002003		SZA,RSS	
3564	13333	026142		JMP LDEX+2	NOT SO ERROR
3565	13334	067756		LDB P3.SC	RESTOR A REG
3566	13335	060001		LDA B	
3567	13336	013541		AND #77	
3568	13337	103602		OTA 2,C	SET AND ENAGLE GLOBAL REG.
3569	13340	002400		CLA	CHECK FOR RESPONSE
3570	13341	103502		LIA 2,C	
3571	13342	002003		SZA,RSS	
3572	13343	026142		JMP LDEX+2	
3573	13344	067756		LDB P3.SC	
3574	13345	005700		RLF	SET FILE #
3575	13346	074000		STB A	
3576	13347	013534		AND #17	
3577	13350	067760		LDB P3.FL	
3578	13351	002040		SEZ	CONTINUE?
3579	13352	102525		LIA 25B	YES GET FILE #
3580	13353	102201		SOC	ONLY IF NOT PREVIOUSLY SET
3581	13354	101100		RRR 16	IT WAS
3582	13355	073760		STA P3.FL	
3583	13356	002004		INA	MOVE TO NEXT FILE NO
3584	13357	102625		OTA 25B	SET FOR NEXT LOAD

3586	13360	067756	LDB P3.SC	
3587	13361	005700	BLF	
3588	13362	005723	BLF,RBP	MOVET TO BUS ADDRESS
3589	13363	060001	LDA B	
3590	13364	013524	AND #7	
3591	13365	073757	STA P3.SB	AND SET IT
3592	13366	005723	BLF,RBR	
3593	13367	060001	LDA B	
3594	13370	013524	AND #7	
3595	13371	073761	STA P3.UN	UNIT NO
3596	13372	067743	LDB S.SC	GET DEVICE NO.
3597	13373	106624	OTB 24B	SAVE CURRENT PAGE
3598	13374	160001	LDA B,I	
3599	13375	013560	AND #70K	
3600	13376	067756	LDB P3.SC	GET CURRENT DEVICE
3601	13377	101100	RRR 16	
3602	13400	013554	AND #7777	
3603	13401	030001	IOR B	
3604	13402	073756	STA P3.SC	
3605	13403	025404	JMP *+1-P3	PUT SELF ON BASE PAGE
3606	13404	064137	LDB 137B	SAVE MAP FOR CHECK
3607	13405	002400	CLA	
3608	13406	070137	STA 137B	SET TO MAP TO PAGE 0
3609	13407	063561	LDA #76K	
3610	13410	033551	IDR #1776	SET ADDRESS FOR LAST PAGE
3611	13411	102711	STC 11B	ENABLE MAPS
3612	13412	027413	JMP *+1	TURN THEM ON
3613	13413	174000	STR A,I	PUT DATA IN UPPER PAGE
3614	13414	154000	CPR A,I	DID IT STORE?
3615	13415	002005	INA,RSS	YES
3616	13416	027436	JMP S%SC4	NO ONLY 16K
3617	13417	067777	LDB P3.CT	GET NEW DATA
3618	13420	007000	CMB	
3619	13421	174000	STR A,I	TRY CROSS PAGE
3620	13422	106711	CLC 11B	DISABLE MAPS
3621	13423	027424	JMP *+1	TURN THEM OFF
3622	13424	002400	CLA	
3623	13425	057777	CPR P3.CT	DID IT STORE IN BASE PAGE
3624	13426	027433	JMP S%SC3	YES THEN MAPPED SYSTEM
3625	13427	063561	LDA #76K	SET FOR 16K
3626	13430	033432	IOR *+2	
3627	13431	124000	JMP A,I	PUT SELF ON PAGE
3628	13432	001433	DEF *+1-P3	

*

3630	13433	067776	S%SC3	LDR P3.T3	RESTOR LOCATION
3631	13434	074137		STB 137B	
3632	13435	027442		JMP *+5	
3633	13436	063555	S%SC4	LDA #36K	ONLY 16K FOR MAX
3634	13437	033441		IOR *+2	
3635	13440	124000		JMP A,I	
3636	13441	001442		DEF *+1-P3	
3637	13442	013561		AND #76K	USE PAGE
3638	13443	107503		LIB 3,C	GET ON PAGE ADDRESS
3639	13444	101100		RRR 16	
3640	13445	013552		AND #1777	
3641	13446	030001		IOR B	
3642	13447	103603		OTA 3,C	
3643	13450	102524		LIA 24B	GET PREVIOUS ADDRESS
3644	13451	013561		AND #76K	SET FOR MOVE
3645	13452	033550		IOR #1700	
3646	13453	102624		OTA 24B	FROM ADDRESS
3647	13454	063550		LDA #1700	
3648	13455	030001		IOR B	
3649	13456	102626		OTA 26B	TO ADDRESS
3650	13457	102524	S%SC5	LIA 24B	*DO MOVE
3651	13460	164000		LDR A,I	
3652	13461	002004		INA	
3653	13462	102624		OTA 24B	
3654	13463	102526		LIA 26B	
3655	13464	174000		STB A,I	
3656	13465	002004		INA	
3657	13466	102626		OTA 26B	
3658	13467	013552		AND #1777	
3659	13470	002002		SZA	DONE?
3660	13471	027457		JMP S%SC5	NO
3661	13472	067743		LDR S.SC	SET RETURN ADDRESS
3662	13473	060001		LDA B	
3663	13474	013552		AND #1777	
3664	13475	101100		RRR 16	
3665	13476	102526		LIA 26B	
3666	13477	043563		ADA #M1	
3667	13500	013561		AND #76K	
3668	13501	030001		IOR B	
3669	13502	073743		STA S.SC	UPDATE STRING POINTER
3670	13503	013561		AND #76K	
3671	13504	067762		LDR P3.DF	
3672	13505	006003		SZB,RSS	IF NOT DEFINED
3673	13506	027513		JMP *+5	THEN SKIP UPDATE
3674	13507	101100		RRR 16	
3675	13510	013552		AND #1777	
3676	13511	030001		IOR B	
3677	13512	073762		STA P3.DF	
3678	13513	037743		ISZ S.SC	ADJUST RETURN
3679	13514	063526		LDA #10	SET DEVICE ERROR
3680	13515	073755		STA P3ERR	
3681	13516	127743		JMP S.SC,I	AND RETURN

3683* CONSTANTS

3684 13517 001763 VCPD3 DEF P3VCP-P3

3685*

3686	13520	000001	#1	OCT	1
3687	13521	000002	#2	OCT	2
3688	13522	000004	#4	OCT	4
3689	13523	000006	#6	OCT	6
3690	13524	000007	#7	OCT	7
3691	13525	000207	#207	OCT	207
3692	13526	000010	#10	OCT	10
3693	13527	000011	#11	OCT	11
3694	13530	000012	#12	OCT	12
3695	13531	000013	#13	OCT	13
3696	13532	000014	#14	OCT	14
3697	13533	000015	#15	OCT	15
3698	13534	000017	#17	OCT	17
3699	13535	000021	#21	OCT	21
3700	13536	000022	#22	OCT	22
3701	13537	000040	#40	OCT	40
3702	13540	000060	#60	OCT	60
3703	13541	000077	#77	OCT	77
3704	13542	000100	#100	OCT	100
3705	13543	000170	#170	OCT	170
3706	13544	000177	#177	OCT	177
3707	13545	000377	#377	OCT	377
3708	13546	000404	#404	OCT	404
3709	13547	000604	#604	OCT	604
3710	13550	001700	#1700	OCT	1700
3711	13551	001776	#1776	OCT	1776
3712	13552	001777	#1777	OCT	1777
3713	13553	037700	#3770	OCT	37700
3714	13554	007777	#7777	OCT	7777
3715	13555	036000	#36K	OCT	36000
3716	13556	040000	#40K	OCT	40000
3717	13557	060000	#60K	OCT	60000
3718	13560	070000	#70K	OCT	70000
3719	13561	076000	#76K	OCT	76000
3720	13562	100000	#100K	OCT	100000
3721	13563	177777	#M1	OCT	-1
3722	13564	177776	#M2	OCT	-2
3723	13565	177772	#M6	OCT	-6
3724	13566	177770	#M10	OCT	-10
3725	13567	177767	#M11	OCT	-11
3726	13570	177760	#M20	OCT	-20
3727	13571	177740	#M40	OCT	-40
3728	13572	177754	#N20	DEC	-20
3729	13573	177700	BLK	DEC	-64
3730*					
3731	13574	000123	S3S	OCT	123
3732	13575	000127	S3W	OCT	127
3733	13576	041524	S3CT	ASC	1,CT
3734	13577	051115	S3RM	ASC	1,RM
3735	13600	042103	S3DC	ASC	1,DC
3736	13601	042123	S3DS	ASC	1,DS

*

3738	13602	060001	P3C%	LDA B	SAVE DATA
3739	13603	067733		LDB P3C+1	GET ADDRESS
3740	13604	101100		RRR 16	SWAP A&B
3741	13605	013573		AND BLK	
3742	13606	101100		RRR 16	SWAP BACK
3743	13607	007004		CMB,INB	MAKE IT NEGATIVE
3744	13610	047773		ADB P3.T0	NOW ADD STORE ADDRESS
3745	13611	101100		RRR 16	SWAP A&B
3746	13612	002020		SSA	IF NEGATIVE THEN OK
3747	13613	027617		JMP *+4	OK STORE CONTENTS
3748	13614	043573		ADA BLK	PAST 64 LOCATIONS?
3749	13615	002020		SSA	
3750	13616	027627		JMP P3C%0	NO SKIP STORE
3751	13617	060001		LDA B	
3752	13620	067773		LDB P3.T0	CHECK IF A OR B
3753	13621	101100		RRR 16	
3754	13622	002003		SZA,RSS	IS IT A REG REF?
3755	13623	077772		STB P3.A	YEP
3756	13624	053520		CPA #1	HOW ABOUT B REG REF
3757	13625	077771		STB P3.B	
3758	13626	177773		STB P3.T0,I	THEN MEMORY
3759	13627	037773	P3C%0	ISZ P3.T0	MOVE TO NEXT LOCATION
3760	13630	127732		JMP P3C,I	RETURN
3761*					
3762	13631		FOP3	EQU *	END OF PAGE 3
3763*					
3764	13732			ORG 13732B	
3765	00101		RAP3	EQU *-FOP3	REMAINING AREA FOR PAGE 3
3766	13732		DSDNL	EQU *	
3767	13732	161001	P3C	OCT 161001	
3768	13733	017733		JSB *	SET CURRENT ADDRESS
3769	13734	027602	RM.TR	JMP P3C%	GO CHECK ADDRESS
3770	13735	027225	RMNSC	JMP RM%TR	
3771	13736	027260	DS.B	JMP RM%SC	
3772	13737	026724	DS.CM	JMP DS%B	
3773	13740	026732	DS.GT	JMP DS%CM	
3774	13741	026630	DS.FT	JMP DS%GT	
3775	13742	026742	DS.WF	JMP DS%FT	
3776	13743	026756	S.SC	JMP DS%WF	
3777	13744	063750		LDA CTI.W	GET RETURN JUMP
3778	13745	073750		STA *+3	
3779	13746	102702		STC 2	DISABLE ROM
3780	13747	106702		CLC 2	ENABLE ROM
3781	13750	027302	CTI.W	JMP S%SC	
3782	13751	026500	CTI.B	JMP CTI%W	
3783	13752	026507	CTIO	JMP CTI%B	
3784	13753	026531	CTO.B	JMP CTIO%	
3785	13754	026514	CTO.W	JMP CTO%B	
3786	13755	026522	P3FRR	JMP CTO%W	
3787	13756	026140		JMP LDEX	
3788	13757	000000		NOP	

*

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3790*      CROSS OVER TO LOWER PAGE
3791*
3792 13760 063546 CRSP2 LDA #404      BITS FOR PAGE 2 LOADERS
3793 13761 102601      OTA CPUT
3794 13762 026243      JMP LDRR      ENTRY FROM OTHER PAGES
3795*
3796*      RFP ENTRY POINTBREAK ENTRY POINT (SAME ON OTHER PAGE)
3797*
3798 13763 103105 P3VCP CLF 5          INSURE PARITY SENSE
3799 13764 106713      CLC 13B        DISABLE MAPING
3800 13765 103300      OCT 103300     SFS 0,C CHECK INTERRUPTS
3801 13766 027772      JMP *+4        THERE OFF
3802 13767 073772      STA P3.A       SAVE THE A REG.
3803 13770 003400      CCA           INDICATE INTS ON
3804 13771 027774      JMP *+3
3805 13772 073772      STA P3.A
3806 13773 002400      CLA
3807 13774 073764      STA P3.I
3808 13775 063525 P3VC0 LDA #207     INSURE UPPER PAGE
3809 13776 102601      OTA CPUT
3810 13777 027775      JMP P3VC0     LOOP IF ERROR
3811*
3812*      COMMON STORAGE
3813*
3814 13777      P3.CT EQU 1777B+P3
3815 13776      P3.T3 EQU 1776B+P3
3816 13775      P3.T2 EQU 1775B+P3
3817 13774      P3.T1 EQU 1774B+P3
3818 13773      P3.T0 EQU 1773B+P3
3819 13772      P3.A  EQU 1772B+P3
3820 13771      P3.B  EQU 1771B+P3
3821 13770      P3.E  EQU 1770B+P3
3822 13767      P3.O  EQU 1767B+P3
3823 13766      P3.GF EQU 1766B+P3
3824 13765      P3.M  EQU 1765B+P3
3825 13764      P3.I  EQU 1764B+P3
3826 13763      P3.EM EQU 1763B+P3
3827 13762      P3.DF EQU 1762B+P3
3828 13761      P3.UN EQU 1761B+P3
3829 13760      P3.FL EQU 1760B+P3
3830 13757      P3.SR EQU 1757B+P3
3831 13756      P3.SC EQU 1756B+P3
3832*
3833*
3834      END
** NO ERRORS *TOTAL **RTE ASMB 92067-16011**

```

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CROSS-REFERENCE SYMBOL TABLE

#1	03686	03756					
#10	03692	03679					
#100	03704	02878	03516				
#100K	03720	03482					
#11	03693	03204					
#12	03694	02986	03393				
#13	03695	03507					
#14	03696	03210					
#15	03697	03216					
#17	03698	03228	03576				
@#170	03705						
#1700	03710	03363	03645	03647			
#177	03706	02882					
#1776	03711	03610					
#1777	03712	03640	03658	03663	03675		
#2	03687	02942	02995	03018	03342	03540	
#20	02972	03055	03237				
#207	03691	02873	03808				
#21	03699	03028	03108				
#22	03700	03276					
#36K	03715	03633					
#377	03707	02857	03126	03129	03247	03255	03279
@#3770	03713						
#4	03688	02809	02944				
#40	03701	03361	03479				
#404	03708	03792					
@#40K	03716						

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CROSS-REFERENCE SYMBOL TABLE

#6	03689	02946	03079				
#60	03702	02992	03562				
#604	03709	02798	02925				
#60K	03717	03280					
#7	03690	02939	03590	03594			
#70K	03718	03599					
#76K	03719	03350	03365	03373	03375	03448	03609
	03625	03637	03644	03667	03670		
#77	03703	03567					
#7777	03714	03560	03602				
#M1	03721	03335	03412	03443	03666		
R#M10	03724						
#M11	03725	03404					
R#M2	03722						
#M20	03726	03548					
R#M40	03727						
R#M6	03723						
R#N20	03728						
\$!?	01873	01559					
\$%	01859	01385					
\$.D1	03157	03072					
\$.P0	03155	02979	02994	03013	03068		
\$.S0	03160	03017					
\$.U0	03159	02988					
R\$2S	02676						
\$2W	02677	02071	02391				
\$34	03158	03074					
\$3CT	03733	02960					

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CROSS-REFERENCE SYMBOL TABLE

\$3DC	03735	02964			
\$3DS	03736	02966			
\$3RM	03734	02962			
\$3S	03731	03000	03111		
\$3W	03732	03006	03174		
\$A	01840	01439	01596		
\$B	01841	01402	01442	01598	
\$C	01850	01396	01451	01594	
\$CDC1	03162	02997			
\$D	01851	01580	01673		
\$E	01846	01398	01454	01600	
\$ER	01872	01335			
\$ESC&	03154	02977	03011	03066	
\$G	01845	01466	01608		
\$I	01848	01460	01604		
\$K	01849	01463	01606		
\$L	01852	01281	01400		
\$LC	01871	01329			
\$M	01842	01406	01469	01624	01665
\$N	01853	01578			
\$O	01847	01457	01602		
\$P	01839	01394	01445	01626	
\$R	01855	01390	01412		
\$R0	01860	01499	01636		
\$R1	01861	01502	01638		
\$R2	01862	01505	01640		
\$R3	01863	01508	01642		
\$RC	01865	01512	01646		

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SRD	01864	01510	01644				
SRDC1	03156	03020					
SRF	01869	01540					
SRI	01867	01517					
SRM	01874	01496	01634				
SRS	01866	01514	01648				
SRX	01868	01520					
SS	01856	01392					
ST	01844	01376	01408	01475	01611	01661	
SU	01854	01377	01483	01613	01663		
SV	01857	01448	01592				
SW	01858	01283	01404				
SWENQ	03161	03076					
ORG	*** 02696	00003 02758	00061 03764	01009	01056	01912	01971
.1	01876	01678					
.100	01889	01351					
.1000	01895	01136					
.100K	01902	01082	01149				
.140	01890	01354					
.15	01880	01287	01293	01311	01347	01576	01694
@.17	01881						
.170	01891	01697					
.1700	01898	01270					
.177	01892	01426	01739	01740			
@.1777	01897						
.2	01877	01210	01360	01681			
.20	01882	01126	01324	01421	01793		

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.207	01878	01109	01946				
@.21	01883						
.2100	01896	01087	01103				
.24	01884	01795					
.377	01893 01804	01156	01243	01253	01749	01760	01764
.40	01885	01222	01337	01433	01728		
.60	01886	01698	01721				
.604	01894	01930					
.60K	01899	01770					
.6412	01887	01315	01563	01686			
.7	01879	01703	01725				
.76K	01900	01225	01269				
.77	01888	01545					
.77NK	01901	01679					
.M1	01903	01118					
@.M12	01905						
@.M20	01906						
.M6	01904	01715					
.N20	01907	01276					
.N64	01908	01822					
@1	02632	01998	02028	02298	02310		
@10	02637	02111	02217	02226			
@100	02638	02059	02171				
@@1000	02640						
@1005	02641	02328					
@@100K	02664						
@@12	02649						

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@15	02650	02408					
@17	02651	02283	02343	02348			
@@170	02656						
@1700	02659	02149					
@@177	02657						
@2	02633	02331					
@200	02642	02397					
@2000	02646	02081	02130				
@201	02643	02295					
@204	02644	02292					
@207	02645	02733					
@@21	02652						
@2101	02647	02127					
@@24	02653						
@3	02634	02301	02313				
@377	02658	02338	02425	02430	02436	02444	02573
@@3770	02660						
@@4	02635						
@40	02654	02146	02204				
@404	02661	02003					
@@6	02636						
@60	02655	02303					
@604	02662	02716					
@@7	02648						
@76K	02663	02055	02058	02151	02159	02161	02165
@D256	02615	02199					
@M1	02665	02181	02190				

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@M10	02668	02116	02183				
@M11	02669	02099					
@M2	02666	02039	02585				
@M20	02670	02484	02607				
@M40	02671	02036					
@@M6	02667						
@@N20	02672						
@N64	02673	02682	02689				
A	00063	00139	00175	00176	00198	00218	00251
	00310	00393	00407	00409	00410	00413	00414
	00423	00438	00439	00446	00447	00504	00514
	00520	00521	00533	00539	00545	00596	00616
	00657	00660	00683	00728	00814	00935	00937
	00939	00941	01061	01088	01091	01105	01213
	01214	01227	01229	01233	01234	01249	01273
	01298	01302	01305	01352	01548	01696	01765
	01771	01814	01817	01827	02006	02009	02012
	02015	02082	02087	02119	02129	02131	02153
	02163	02168	02255	02368	02486	02588	02868
	02879	02880	03120	03130	03292	03302	03367
	03377	03458	03481	03575	03613	03614	03619
	03627	03635	03651	03655			
AFAUS	00999	00252					
ALT0	00994	00142	00143	00150	00151	00155	00162
	00285	00309	00436	00441	00736	00882	00897
ALT1	00995	00132	00136	00138	00146	00154	00158
	00159	00190	00281	00287	00311	00444	00449
ASR.0	01001	00261					
ASR.1	01002	00273					
B	00064	00110	00134	00137	00189	00206	00244
	00317	00388	00428	00432	00435	00473	00566
	00575	00603	00611	00614	00619	00645	00650
	00656	00682	00692	00718	00726	00746	00755
	00803	00923	00931	00945	00954	01181	01266
	01297	01368	01418	01424	01430	01436	01480
	01586	01616	01620	01652	01700	01702	01709
	01720	01745	01756	01813	01825	02001	02005
	02027	02054	02070	02095	02110	02115	02134
	02182	02189	02198	02203	02206	02244	02269
	02291	02309	02337	02341	02346	02354	02388
	02399	02415	02419	02423	02429	02434	02440

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	02443	02461	02538	02542	02559	02563	02577
	02586	02679	02711	02785	02915	02958	02981
	02984	02991	03005	03015	03023	03070	03088
	03092	03095	03103	03140	03173	03223	03262
	03265	03269	03287	03300	03327	03341	03408
	03430	03434	03474	03478	03491	03547	03559
	03566	03589	03593	03598	03603	03641	03648
	03662	03668	03676	03738	03751		
B1	00961	00205	00297				
B100	00975	00693	00993				
AB1000	00980						
B100K	00988	00179	00186	00576	00588		
AB16K	00986						
B17	00968	00361	00678				
B177	00976	00933					
B1776	00981	00529	00541	00548			
B1777	00982	00429	00544				
B2	00962 00835	00351	00378	00403	00467	00583	00700
B20	00969	00457	00463				
B207	00978	00909	01031				
B24	00970	00149					
B3	00963	00637	00667	00792	00925		
B3004	00983	00884					
B37	00971	00476					
B377	00977	00568	00898				
B4	00964	00669					
B40	00972	00556	00992				
B5	00965	00390	00813				
B6	00966	00345	00362	00478	00552		
B604	00979	01014					
B6412	00984	00278					

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CROSS-REFERENCE SYMBOL TABLE

B7	00967	00779	00951				
B76K	00987 00610	00276	00286	00530	00542	00558	00570
B7777	00985	00283					
BEAUS	01000	00250					
BIT5	00992	00465					
BIT6	00993	00947					
BIT9	02639	02270	02445	02462			
BLK	03729	03061	03082	03297	03741	03748	
CH.OK	01568 01458 01557	01440 01461	01443 01464	01446 01467	01449 01470	01452 01476	01455 01484
CLM0	01223	01246					
CLM1	01233	01239					
CLM2	01247	01230	01236				
CLMEM	01210	01397					
CMDF	02620	02478	02595	02605			
CPUST	00066 00379 01016 01761 02718 02927	00308 00553 01032 01790 02734 03357	00334 00638 01110 01799 02799 03793	00348 00872 01157 01931 02800 03809	00353 00904 01254 01947 02819	00359 00934 01683 02004 02866	00373 00949 01733 02144 02910
CRLF	01563	01135	01146	01589			
CRSP1	02871	02818	02855	02891	02924		
CRSP2	03792	02847	02874	03535			
CRSP3	01930	01319	01363				
CS%CM	01812	01917					
CS%FT	01820	01918					
CS%TR	01799	01916					
CS.CM	01916 01818	01133	01747	01806	01808	01812	01816

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CROSS-REFERENCE SYMBOL TABLE

CS.FI	01917	01131	01327	01829	01830	01831	
CS.TR	01915	01382	01574	01802	01810		
CSVCP	01134	01130	01326				
CTCWI	03151	03123					
CTCWO	03152	03131					
CTDP	03055	03007					
CTDPO	03063	03081	03112				
CTDPL	03091	03101					
CTI%B	03123	03783					
CTI%W	03115	03782					
CTI.B	03782 03115	02999 03118	03027 03127	03031	03034	03078	03110
CTI.W	03781 03136	03022 03139	03026 03777	03035	03038	03044	03121
CTIO	03783	03125	03133	03149			
CTIO%	03144	03784					
CTL	00068 02606 03400	00885 03124 03411	01138 03132 03442	01737 03330 03444	01767 03380	02481 03385	02596 03399
CTLD	02971	02822	02941	02961			
CTLD.	03003	02976					
CTLDO	03011	03046					
CTLDF	02977						
CTLDL	03038	03043					
CTLDX	03049	03025					
CTO%B	03129	03785					
CTO%W	03136	03786					
CTO.B	03784	02993	03030	03109	03134	03138	03141
CTO.W	03785 03016	02978 03019	02982 03021	02989 03067	02996 03071	02998 03073	03012 03075

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CROSS-REFERENCE SYMBOL TABLE

	03077 03142	03086	03090	03098	03104	03117	03119
CTRS	03153	03024					
DC%IN	02226	02701					
DC%RW	02385	02702					
DC.IN	02700 02170	02049 02201	02053 02381	02113 02404	02150 02491	02152 02499	02154
DC.RW	02701 02208	02060 02256	02065 02290	02106 02357	02120 02524	02122	02174
DCDCW	02621	02393					
DCER	02708 02709	02047	02279	02495	02505	02523	02590
DCERX	02216	02048					
DCFM	02323	02307	02311	02314			
DCL0	02486	02497					
DCLD	03532	02833	02947	02965			
DCLD.	02036	02029					
DCLD1	02047	02025	02220				
DCLD2	02064	02173					
DCLM.	02103	02073					
DCLM0	02144	02185					
DCLM1	02174	02143					
DCLM2	02190	02210					
DCLMP	02069	02057					
DCLMU	02149	02138					
DCLMW	02170	02094	02101				
DCLMX	02211	02148	02177	02192	02306		
DCSFS	02496	02487	02489				
DCTYP	02622	02288					
DFL	01838	01123					

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CROSS-REFERENCE SYMBOL TABLE

DFL.	01843	01370					
DMA	00827	00774	00776	00778	00815	00829	
DMACF	00829	00772	00812				
DMACW	00828	00775	00777	00785	00789		
DONE	01014	00367	00906	00910			
DR	00067	00724	00731	00883	00886	00889	00896
	01139	01140	01144	01775	01776	01777	01784
	01820	01821	01823	02572	02578	02579	02583
	02584	02591	02609	02611	03144	03145	03146
	03148	03181	03222	03232	03283	03290	03295
	03296	03298	03331	03333	03345	03346	03379
	03387	03398	03401	03421	03432	03439	03451
	03499						
DS%B	03279	03772					
DS%CM	03286	03773					
DS%FT	03295	03310	03775				
DS%GO	03228	03215					
DS%GT	03214	03774					
DS%WF	03308	03776					
DS.B	03771	03246	03248	03267	03270	03284	
DS.CM	03772	03249	03251	03253	03286	03291	03293
DS.FT	03774	03177	03219	03226	03240	03281	03288
	03304	03305	03306	03309			
DS.GT	03773	03187	03192	03195	03201	03207	03233
DS.WF	03775	03168	03182	03230	03308		
DSDNL	03766	03176					
DSDUN	03207	03190					
DSEX	03211	03205	03277				
DSINR	03252	03218					
DSLQ	03166	02821	02830	02945	02967		
DSPLY	00931	00468	00479	00915	00920	00948	00955

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CROSS-REFERENCE SYMBOL TABLE

DSRD	03187	03203					
DSRDL	03195	03200					
DSVCP	03312	03239					
DSWEX	03276	03256					
DSWR	03237	03175					
DSWR0	03245	03274					
DSWR1	03261	03273					
DTYER	02303	02317					
DTYPE	02336	02293	02296	02299			
DV4	01004	00289					
EMERR	00472	00434					
EOP0	01008	01010					
EOP1	01910	01913					
EOP2	02694	02697					
EOP3	03762	03765					
EXECU	01253	01399					
EXIT	01152	01391					
EXITN	01191	01184					
EXITS	01148	01393					
EXRM	02857	02851					
HLT77	02907	02898					
HPIB	02706	02247	02271	02332	02420	02426	02431
	02441	02446	02463	02509	02540	02543	02561
	02564	02569	02593				
HPIB%	02583	02707					
I%0	01775	01920					
I%0.0	01777	01783					
I%0.1	01784	01778					
I.0	01919	01738	01768	01772	01785	01815	

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CROSS-REFERENCE SYMBOL TABLE

IDM	00974	00869					
ILINT	00917	00092	00800				
IN%N	01690	01924					
IN%NO	01693	01712					
IN.N	01923	01278	01346	01575	01695	01701	
IN1C	01918 01693	01261 01746	01264 01750	01291 01752	01383 01755	01388	01415
IN1C%	01733	01919					
IN1C0	01747	01735					
INQ	01365	01565	01571				
INQ!?	01559 01741	01313	01349	01410	01543	01583	01667
INQ#	01423	01685	01688				
INQ.	01381	01367	01584				
INQ.0	01412	01387					
INQ.1	01433	01380	01422				
INQ.2	01488	01473					
INQ.3	01556 01550	01497 01552	01500 01554	01503	01506	01509	01541
INQDM	01544	01518	01521				
INQLF	01561	01334	01342	01355			
INQRC	01553	01513					
INQRD	01551	01511					
INQRS	01555	01515					
INQRX	01542	01493					
INQ4	00669	00654					
IOER	00924	00391	00668	00670	00701	00708	00853
IOESC	00922 00765 00820	00720 00783 00894	00730 00787 00900	00734 00791	00748 00797	00757 00805	00761 00817

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CROSS-REFERENCE SYMBOL TABLE

IOINT	00799	00095					
IOL0	00642	00659					
IOL1	00657	00665					
IOL2	00680	00688	00699				
IOL3	00683	00690					
IOL4	00711	00825					
IOL5	00842	00851	00856				
IOLP	00959	00618					
ION0	00675	00648					
ION1	00691	00685					
ION2	00705	00694					
ION2A	00736	00722					
ION3	00835	00713					
ION4	00848	00845					
ION5	00858	00847					
ION6	00902	00861	00864	00871			
IPF	00516	00086	00953				
IPRTY	00484	00087					
ITBG	00342	00088					
JMP.2	02919	02900					
LDCON	02934	02805					
LDEX	02876	02955	02968	03002	03047	03051	03053
	03065	03113	03169	03178	03183	03209	03212
	03220	03227	03231	03241	03258	03282	03289
	03362	03391	03394	03470	03508	03564	03572
	03787						
LDEX0	02909	02897					
LDEX1	02917	02913					
LDP2	02027	02719					

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CROSS-REFERENCE SYMBOL TABLE

LDR	02790	02783	02930	02953			
LDRC	02811	02808	02936				
LDRC0	02823	02814					
LDRC1	02826	02812					
LDRC2	02831	02827					
LDRER	02921	02816	02824	02829	02832	02840	02843
	02854	02894	02948				
LDRR	02952	03794					
LDRSX	02865	02810	02852				
LDRTC	01329						
LD RTE	01335						
LDRTN	01321	01932					
LTB	01495	01546					
LOAD	01261	01401	01403	01405			
LOAD0	01291	01309					
LOAD1	01295	01289					
LOAD2	01310	01282	01284				
LOADC	01315	01288	01294				
LSN	02619	02246	02539				
M1	00989	00168	00180	00590			
M2	00990	00169					
M20	00991	00652	00723				
MAPST	01346	01407					
MTST	00373	00085	00364				
MTST0	00404	00505	00523	00560	00573		
MTST1	00507	00415					
MTST2	00520	00508					
MTST3	00575	00431	00550	00569			

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CROSS-REFERENCE SYMBOL TABLE

MTST4	00586	00486					
MTST5	00608	00601					
MTSTE	00419	00412	00488	00584			
MTSTM	00562	00525					
MU2	01003	00282					
N250	02614	02232					
OU%1C	01760	01922					
OU%2C	01752	01921					
OUT%N	01714	01923					
OUT.N	01922	01341	01568	01730			
OUT1C	01921 01729	01338 01743	01379 01754	01428 01757	01431 01769	01434 01773	01722
OUT2C	01920 01742	01316 01744	01333 01758	01336 01805	01560	01564	01687
OUTNO	01718	01727					
P0	00065 00959 01042 01049	00212 00960 01043 01050	00213 01037 01044 01051	00617 01038 01045 01052	00809 01039 01046 01053	00827 01040 01047 01054	00829 01041 01048
P0.A	01042	00629	00824	01025	01028		
P0.B	01043	00631					
P0.CT	01037 00959	00536	00543	00679	00680	00687	00691
@P0.DF	01050						
@P0.E	01044						
@P0.EM	01049						
@P0.FL	01052						
@P0.GF	01046						
P0.I	01048	01030					
@P0.M	01047						
@P0.N	01045						

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CROSS-REFERENCE SYMBOL TABLE

AP0.SB	01053						
AP0.SC	01054						
P0.T0	01041 00711 00922	00620 00823	00643 00837	00644 00850	00658 00854	00662 00859	00710 00862
P0.T1	01040	00622	00655	00681	00705	00709	00836
P0.T2	01039	00839	00855	00858			
P0.T3	01038	00555	00605				
AP0.UN	01051						
P0CL2	00399	00394					
P0C00	00401	00398					
P0JP0	00398	00392					
P0VCP	01021	00960	01033				
P1	01057 01958 01965	01952 01959 01966	01953 01960 01967	01954 01961 01968	01955 01962 01969	01956 01963	01957 01964
P1.A	01957	01180	01438	01597	01940	01943	
P1.B	01958	01071	01182	01441	01599		
P1.CT	01952	01277	01308	01716	01726		
P1.DF	01965 01569	01124	01271	01314	01365	01372	01562
P1.E	01959	01074	01168	01453	01601		
P1.EM	01964 01373	01102 01462	01177 01607	01179	01185	01191	01204
AP1.FL	01967						
P1.GF	01961 01609	01083 01631	01162	01205	01207	01465	01488
P1.I	01963 01605	01174 01945	01176	01187	01193	01202	01459
P1.M	01962 01625	01120 01672	01468 01675	01474 01682	01477	01612	01617
P1.O	01960	01078	01171	01456	01603		

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CROSS-REFERENCE SYMBOL TABLE

@P1.SB 01968

@P1.SC 01969

P1.T0	01956	01089	01104	01153	01183	01279	01286
	01292	01299	01378	01384	01389	01416	01419
	01423	01429	01435	01585	01651	01658	

P1.T1	01955	01093	01106	01155	01190	01197	01350
	01587	01610	01633	01691	01704	01710	01719
	01723						

P1.T2	01954	01263	01265	01267	01318		
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P1.T3	01953	01275	01295	01307	01572	01653	01659
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@P1.UN 01966

P1ERR	01924	01330	01339				
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P2	01972	02164	02738	02740	02741	02742	02743
	02744	02745	02746	02747	02748	02749	02750
	02751	02752	02753	02754	02755	02756	

P2.A	02744	02078	02092	02139	02727	02730	
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P2.B	02745	02085	02096	02140	02178		
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P2.CT	02738	02024	02040	02108	02719		
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P2.DF	02752	02021	02023	02166	02169		
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@P2.F 02746

@P2.EM 02751

P2.FL	02754	02013	02042	02044	02109	02112	02114
	02117	02197	02200	02304	02351	02359	

@P2.GF 02748

P2.HC	02710	02061	02345	02371	02376	02421	02427
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P2.I	02750	02732					
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@P2.M 02749

@P2.O 02747

P2.SB	02755	02007	02243	02537	02558		
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@P2.SC 02756

P2.ST	02709	02063	02340	02361	02367	02379	02380
-------	-------	-------	-------	-------	-------	-------	-------

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CROSS-REFERENCE SYMBOL TABLE

	02433	02442					
P2.T0	02743	02018	02069	02389	02685		
P2.T1	02742	02350	02355	02360	02366	02370	02377
P2.T2	02741	02019	02037				
P2.T3	02740	02235	02319	02329	02414	02437	
P2.UN	02753	02010	02268	02418	02439	02460	
P2C	02698 02428	02016 02680	02046 02688	02188 02691	02202 02692	02205	02422
P2C%	02679	02700					
P2ERR	02711 02227 02483	02031 02240 02503	02066 02261 02506	02212 02277 02515	02216 02323 02521	02218 02409	02221 02450
P2VCO	02733	02735					
@P2VCP	02723						
P3	02759 03815 03822 03829	03378 03816 03823 03830	03605 03817 03824 03831	03628 03818 03825	03636 03819 03826	03684 03820 03827	03814 03821 03828
P3.A	03819	03091	03261	03755	03802	03805	
P3.B	03820	03093	03263	03757			
P3.CT	03814 03225 03425 03623	03033 03260 03426	03042 03272 03441	03083 03334 03462	03100 03389 03466	03185 03407 03467	03214 03413 03617
P3.DF	03827	02795	02889	02895	02916	03671	03677
@P3.E	03821						
@P3.EM	03826						
P3.FL	03829 03318 03577	02974 03320 03582	02983 03343	03010 03418	03029 03435	03049 03544	03180 03552
@P3.GF	03823						
P3.T	03825	03807					
@P3.M	03824						

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CROSS-REFERENCE SYMBOL TABLE

BP3.0	03822						
P3.SB	03830	03057	03591				
P3.SC	03831 03600	02796 03604	02914	03561	03565	03573	03586
P3.T0	03818 03099 03322 03438	02793 03172 03326 03744	03004 03193 03340 03752	03036 03244 03347 03758	03060 03264 03422 03759	03087 03268 03429	03094 03271 03433
P3.T1	03817 03045 03452	02959 03089 03460	02987 03096 03498	02990 03097 03510	03037 03102	03040 03191	03041 03199
P3.T2	03816	02794	02886				
P3.T3	03815 03202	03062 03630	03063	03105	03194	03197	03198
P3.UN	03828	02973	02980	03014	03069	03595	
P3C	03767 03739	03039 03760	03196	03388	03464	03477	03480
P3C%	03738	03769					
P3C%0	03759	03750					
P3ERR	03786 03056 03229	02797 03170 03238	02877 03171 03242	02892 03179 03541	02957 03211 03680	03003 03217	03052 03221
P3VC0	03808	03810					
P3VCP	03798	03684					
PHI	02705 02412 02518 02554 02599	02228 02455 02529 02556 02601	02230 02458 02531 02570 02603	02248 02471 02533 02576	02266 02473 02535 02580	02274 02485 02550 02581	02326 02488 02552 02597
PHI%	02576	02706					
PHI%I	02568	02705					
PHI%L	02550	02704					
PHI%T	02529	02703					
PHI.I	02704 02574	02250	02253	02276	02280	02281	02520

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CROSS-REFERENCE SYMBOL TABLE

PHI.L	02703	02241	02252	02254	02272	02289	02294
	02297	02300	02312	02315	02336	02469	02516
	02562	02565	02566				
PHI.T	02702	02262	02264	02324	02410	02451	02466
	02541	02544	02545				
PHIF%	02595	02708					
PHIFL	02707	02236	02284	02308	02511	02610	
PIN	02604	02568					
PRDER	00914	00321	00324	00327	00332	00340	00347
	00350	00355					
PRST	01200	01132	01143	01216	01251	01395	01782
PRTL	00949	00944					
PTDF0	00212	00204	00207				
PTDF1	00213	00201					
PTJMP	00215	00209					
PTJPR	00214	00197					
PTRT0	00201	00213	00214				
PTST	01359	01409					
QRAPO	01010						
QRAP1	01913						
QRAP2	02697						
QRAP3	03765						
RESUA	01005	00290					
RESUB	01006	00294					
REV	00081	00630					
RM%SC	03514	03771					
RM%TR	03486	03770					
RM.TR	03769	03456	03459	03483	03512		
RM1K	03526	03453					
RM31K	03527	03457					

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CROSS-REFERENCE SYMBOL TABLE

RMADR	02869	02864					
ARMADX	03528						
RMCW	03525	03487					
RMLD	03316	02825	02943	02963			
RMLD0	03322	03329	03344	03431	03436		
RMLD1	03330	03324	03410				
RMLD2	03379	03352	03356	03386	03390	03445	
RMLD3	03393	03336	03417	03476	03517	03522	
RMLD4	03398	03338					
RMLD5	03432	03415					
RMLDE	03361	03450					
RMLX	03447	03420					
RMLX0	03465	03484					
RMNSC	03770	03325	03383	03423	03471	03523	
RP%SC	01787	01915					
RP.SC	01914	01111	01323	01542	01556	01650	01797
RTNP3	02716	02032	02067	02213	02222		
S%SC	03539	03781					
S%SC0	03555	03543					
S%SC1	03558	03546	03554				
S%SC2	03561	03551	03557				
S%SC3	03630	03624					
S%SC4	03633	03616					
S%SC5	03650	03660					
S.SC	03776 03368 03681	02971 03532	03166 03558	03316 03596	03348 03661	03364 03669	03366 03678
SCM	00973	00649					

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CROSS-REFERENCE SYMBOL TABLE

SPCL	02835	02803					
SPCL0	02842	02838					
SPCL1	02848	02836					
SPCL2	02853	02849					
SRGP1	00996	00217					
SRGP2	00997	00219	00245				
SRGP3	00998	00241					
ST.N	01585	01577	01669				
ST.N0	01658	01579	01581				
ST.N1	01670	01655					
ST.N2	01683	01656					
ST.NA	01651	01622					
ASTART	00099						
STS	00069 01649	00881 01779	00893	00895	01113	01137	01555
TCCWI	01835	01736					
TCCWO	01836	01766					
TLK	02618	02245	02560				
TR1K	02616	02103					
TR31K	02617	02118					
TST	02846	02841					
UNL	02534	02507					
VCP	01071	01948					
VCP0	01109	01208	01322	01328			
VCP1	01136	01127					
VCPD	00960	00383	00612				
AVCPD3	03684						
ZERO	00080	00300					

APPLICATION INFORMATION FOR 25 KHz POWER	APPENDIX B
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This appendix provides application information on the 25 kHz sine-wave output of the HP 12035A Power Supply.

Introduction

HP 1000 L-Series Computers and Systems utilize the Model 12035A Power Module as their power supply. An important design factor in the 12035A Power Module is the inversion of 50/60 Hz ac power to a regulated 25 kHz sine wave that is stepped down and rectified to provide the outputs shown in Figure 1. A bonus of this design for the OEM or end user with unique power requirements that are not met by the standard dc voltages is the availability of 25 kHz ac power at the backplane of L-Series card cages, computers, and systems and at a connector on the front of the power module. At the 25 kHz frequency, power transformers and filtering components (capacitors and chokes) can be small and lightweight enough to make possible on-interface power supplies.

Uses of 25 kHz backplane power

25 kHz backplane power can be used when designing special interfaces on the 12010A Breadboard Interface to provide ac input power for compact, lightweight on-interface dc power supplies to meet any of the following requirements:

1. Provision of dc voltages in addition to those supplied by the 12035A Power Module.
2. Provision of dc supplies whose analog grounds are isolated from the computer ground.
3. Provision of multichannel isolated power to digital communication circuits to eliminate ground noise paths and maximize the reliability of serial data transfers.
4. Low voltage, high current power for supplying large arrays of integrated circuits.

Use of 25 kHz power from the power module front connector

25 kHz power is conveniently available from the power module front connector for powering circuits that are separate from the computer or system backplane. Uses might include signal conditioning power to external sensors (such as strain gauges) or power for logic circuits external to the computer backplane. Use of the power module's 25 kHz ac output can eliminate the need for separate, 50/60 Hz power supplies where external power requirements are small, minimizing costs, space requirements, and weight.

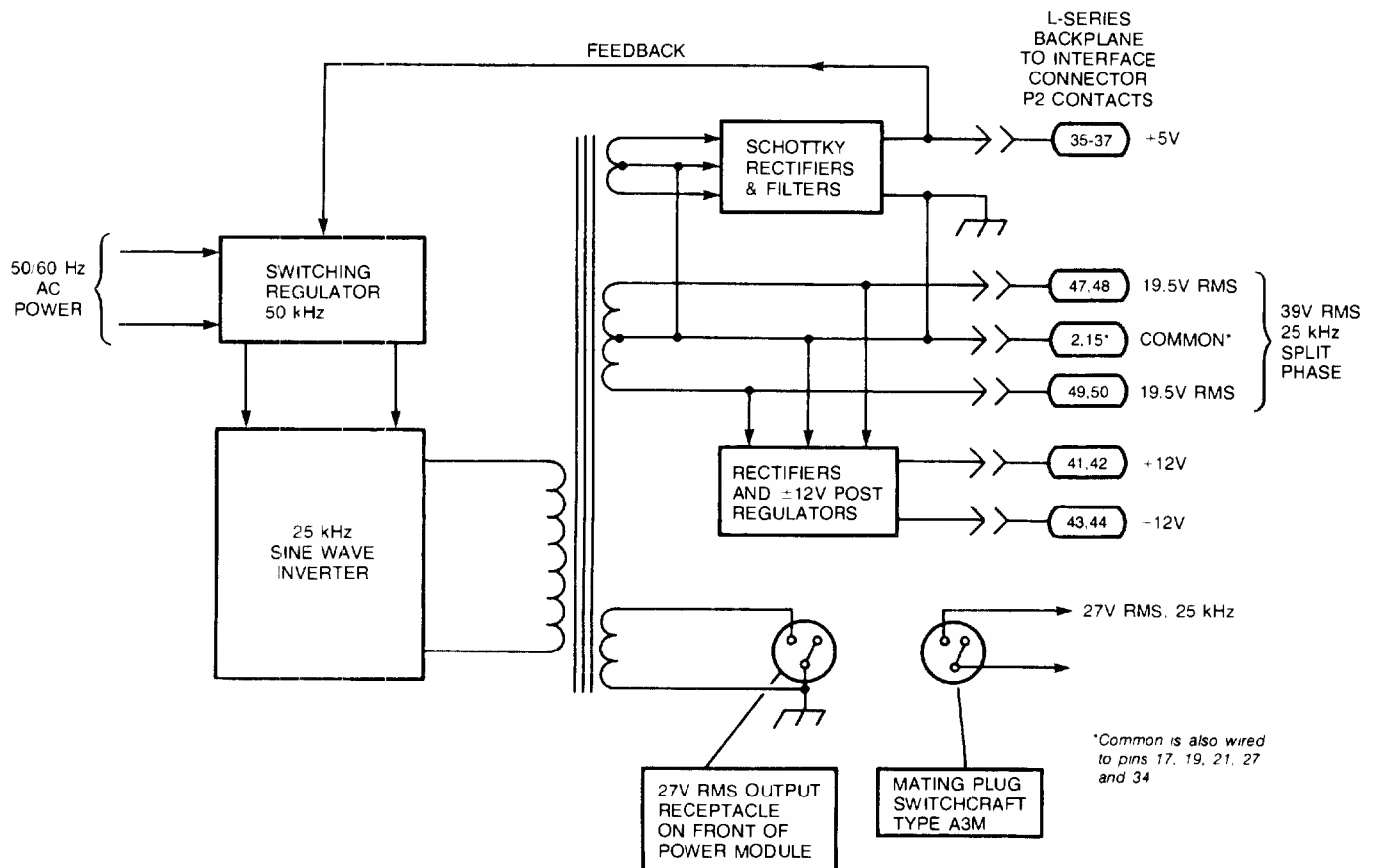


Figure 1. 12035A Power Module, Simplified

25 kHz ac power specifications of the 12035A Power Module

39V rms split-phase backplane output: The power module's output to the backplane of L-Series card cages, computers, and systems includes 39V rms split phase across pins 47/48 and 49/50 of interface card printed circuit plug P2 with a center tap connected to common (pins 2, 15, 17, 19, 21, 27, 29, and 34 of P2), as shown in Figure 1. With respect to common, the voltages at pins 47/48 and 49/50 of plug P2 are 19.5V rms. This backplane output is conveniently available for powering small on-interface dc power supplies.

27V rms front connector output: A separate transformer winding provides a 27V rms single-phase output to a connector on the front of the power module. This output can be used for signal conditioning power to external sensors or for other small external power supply uses. A Switchcraft type A3M plug is the required mating connector for this output.

Regulation: Within $\pm 8\%$ of nominal.

Available power: 25 kHz power available from either output or total available from both outputs depends on usage of dc current from the 12035A Power Module, as follows:

AC Power	+5Vdc	+12Vdc	-12Vdc
70 Watts	25A	4.0A	2.0A

NOTE: Alternate ac power and dc current output combinations are possible within the 250W to 319W maximum total power output, provided that no more than the highest power or current listed above is drawn from any output. However, because of complex thermal interactions within the power module you cannot rely upon directly trading all of the power not used in one or more dc outputs for additional ac power.

On-interface dc power supplies

Non-isolated, series-regulated dc power supply (Use 1 from page 1)

Purpose and basic design. Where additional +7.5V to +12V dc at up to 1 amp is needed for interface circuits, the 25 kHz backplane power can be used to provide a non-isolated positive regulated power supply as shown in Figure 2. The 19.5V rms potential on either side of common provides at least +14.5V dc after rectification and filtering. An adjustable, off-the-shelf, three-terminal integrated circuit voltage regulator, National Semiconductor Series LM117 or equivalent, can be used to set the regulated output voltage within the range of +7.5V to +12V dc. The regulated voltage output is dependent upon the values of resistors R2 and R3. A negative output voltage supply similar to the

positive supply shown in Figure 2 can be made by reversing polarities of the rectifiers and using a negative adjustable regulator, National Semiconductor Series LM137 or equivalent.

Preserving purity of the 25 kHz ac input sine wave. To maintain the purity of the input 25 kHz sine wave, near 180 degree conduction should be provided in the rectification process, which necessitates the use of a choke input filter. This filter also limits the surge current at turn-on if the requirements for L_{min} are met. The equation for L_{min} with a 25% safety factor is given by:

$$L_{min} \text{ (in henries)} = (K/f_s) \times R_L$$

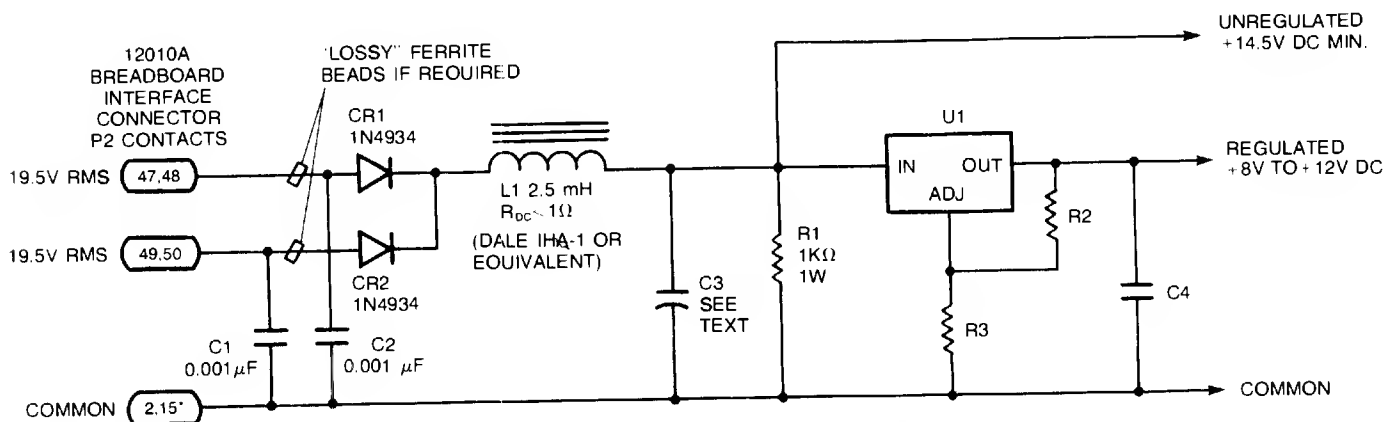
Where: $f_s = 25 \text{ kHz}$

$R_L = \text{Minimum load resistance}$

$K = 0.06 \text{ for full wave rectifiers}$

This implies the need for a minimum load. If the circuits to be powered allow the load current to go to zero, a preloading bleeder resistor is required. The final value of L_{min} would then be determined by the allowed power loss (dissipation) of the preloading resistor. When the L_{min} requirement is met, the surge current will be acceptable and sine wave distortion will be minimized.

Selection of rectifiers. Rectifiers used with 25 kHz input power must be of the fast recovery type with less than 200 nanosecond recovery time. Allowing for possible transients from leakage inductances, overshoot, and MTBF derating, the rectifiers should also have 100V peak inverse voltage rating.



NOTES: U1 is a National Semiconductor type LM117 Series or equivalent adjustable regulator
Values of C4, R2, and R3 should be selected in accordance with instructions in U1 manufacturer's data sheet.

Figure 2. On-interface regulated power supply with up to 1A output using 25 kHz ac input from L-Series backplane

Keeping noise off the 25 kHz ac input lines.

During rectifier recovery, the removal of stored charge in the rectifiers will appear as spikes on the rectifier inputs. These spikes should be suppressed to keep them from travelling along the 25 kHz ac input lines in the backplane. Small 0.001 to 0.1 microfarad ceramic capacitors (C1 and C2 in Figure 2) will usually damp out these spikes, with the required capacitor value dependent upon the magnitude of stored charge being removed. If under-damped ringing is present because of leakage inductance, small ferrite beads, tubes, or toroids can be threaded onto the rectifier leads to provide a "lossy" inductive reactance at high frequencies to effectively dissipate undesirable recovery currents.

Input filtering. The value of C3 is determined by the amount of ripple voltage that can be tolerated at the input of integrated circuit regulator U1. The V_{in} - V_{out} differential of 3 volts must be met for any chosen output voltage as noted in Reference 2. The Ripple factor r for a full-wave rectifier circuit is given by:

$$r = (0.83 / (L_1 \times C_1)) \times 5.76 \times 10^{-6}$$

The case size and construction of capacitor C3 must be capable of conducting the ripple current without excessive dissipation. Ripple current will be at 2 fs and will be sinusoidal when L_{min} requirements are met. The rms ripple current in amps is given by:

$$I_R = V_{RMS} / (4\pi \times f_s \times L_1)$$

Where: V_{RMS} is the input voltage phase to common

$$f_s = 25 \text{ kHz}$$

$$L_1 \geq L_{min}$$

The minimum inductive value of L_1 must be present with the dc current flowing through it over the complete load current range. This requires an inductor with gaps in the magnetic circuit, either fixed or distributed, such as in powdered iron cores, or solenoid-wound inductors over ferrite rods (available from Reference 9)

Regulator dissipation. Since the regulator is a linear series pass type, the difference between the voltage developed across C3

at the regulator input and the desired output at the load current must be dissipated in the regulator. This dissipation is given by:

$$P_{diss} = (V_{in} - V_{out}) \times (I_L + V_{in} I_q)$$

Where: I_q = the quiescent current of the regulator.

Case to junction thermal resistances are given in the regulator manufacturer's data sheet. The dominant thermal resistance will be the case to air stream, which is usually available on heat sink manufacturer's data as a function of air velocity. You can assume a minimum 200 ft/min flow across the board with a maximum air temperature on the exit side of 66°C under worst case conditions. For low power on-card dc supplies, the copper foil on the printed circuit board can be used as a heat sink. However, the suitability of this arrangement should be checked carefully with thermocouples to confirm that the temperature rise of the regulator is not excessive.

Isolated or "floating" dc power supplied (Uses 2 and 3, page 1)

A major advantage of the 25 kHz backplane power is its ease of use for isolated power supplies that can have separate analog grounds, thereby reducing the effects of ground-conducted noise as discussed in References 3 and 4. Isolation is provided by an on-interface transformer, as shown in Figure 3. The use of 25 kHz ac input makes it possible for the isolation transformer to be very small and inexpensive. Toroidal printed circuit mounting types or "P" core (Reference 7)

shielded printed circuit mounting types generally offer the best price-performance combination. However, small E-E types can also be used at lower cost with some sacrifice in electromagnetic and electrostatic shielding. High permeability ferrite materials having low losses at 25 kHz are readily available with matching bobbins and mounting hardware from References 6 through 10.

Primary-to-secondary isolation of both dc and high frequency can be somewhat complex. References 3 and 4 describe single and double shielded transformers. It is possible to achieve high isolation with small ferrite cores and proper inter-winding shield design. Simple copper foil inter-winding shields are relatively inexpensive and are effective in decreasing primary-to-secondary electrostatic coupling at frequencies from 100 Hz to about 100 kHz. For higher frequencies, "link" coupling of two cores or other techniques may be required (Reference 3, p 117).

The ground isolation provided by the multi-channel +10V power supply circuits depicted in Figure 3 eliminates errors caused by ground-induced noise. In analog voltage measurement applications, power supply isolation minimizes common mode noise, improving measurement accuracy. With respect to digital data transmission uses, power supply isolation allows data terminals to operate at greater distances from the local system with fewer data errors than would otherwise be possible. When the power supply is not isolated, noise in the 50/60 Hz mains power distribution and grounding system supplying the computer can cause current noise loops that degrade signal integrity.

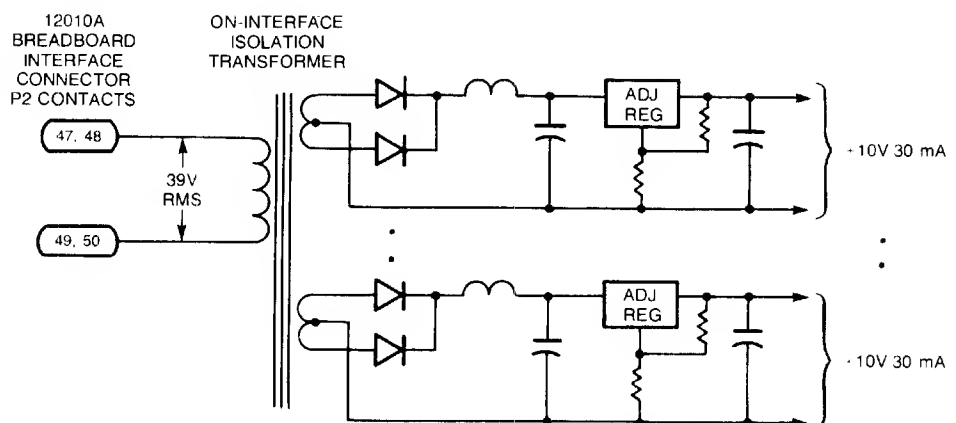


Figure 3. Multiple, isolated, on-interface +10V/30 mA power supplies

High-efficiency, on-interface
low-voltage, high current power
supply (Use 4, page 1)

Heat dissipation is often the main factor limiting the current output of on-interface power supplies. This is particularly true for lower voltage, high current supplies, such as required for many digital integrated circuit families. For example, at the +5V used for TTL families of integrated logic circuits, even the dissipation of the rectifiers can be a significant 14% to 20% of total power, because of the inherent 0.7V to 1.0V forward drop across silicon rectifiers, and heat sinking may be required at 3-5 Amp currents. Use of hot carrier or Schottky junction rectifiers, which have a lower forward drop presenting a power loss of only 4%-5% of the total power output, have peak inverse voltage ratings that are suitable for lower voltage power supplies and may not require heat sinks because of their lower power dissipation.

At low output voltages, the 2-3 volt drop required across most three-terminal adjustable integrated circuit series regulators for proper regulation can account for 40%-60% of the total power output, which is lost in the regulator and must be

dissipated. Regulator heat sinking becomes difficult for even 1-3 Amp current outputs and impossible for the higher current levels that larger three-terminal regulators are able to pass. Because of these efficiency and dissipation problems, a more efficient circuit approach has evolved, as shown in Figure 4.

The circuit of Figure 4 uses a driven switching regulator for more efficient delivery of low voltage, high current output. This circuit regulates on the basis of the conduction angle of the pulsating rectified, unfiltered dc from the on-interface Schottky rectifiers. The result is efficiencies of 70%-85% with 1 Amp to 5 Amp loads. The duty cycle control is uniform over the half sine wave and the instantaneous energy is low at the switching transitions, which minimizes waveform distortion and RFI emission. Because the regulator operates on the incoming frequency as a driven circuit, it also eliminates the generation of other frequencies that would be a problem if an on-interface switching regulator integrated circuit were used. The circuit of Figure 4 eliminates sum and difference noise frequencies and a host of non-repetitive noise problems, while optimizing efficiency.

External supplies using
25 kHz power from the
power module front
connector

Power supplies for logic circuits or sensor signal conditioning circuits external to the computer or system card cage can also use 25 kHz power from the 12035A Power Module as the primary ac input. In fact, ac input power to the logic circuits power supply for the flexible disc in HP 1000 L-Series Systems is taken from the front 25 kHz connector of the 12035A Power Module. Similar use can be made by the OEM or end user in systems assembled from HP 1000 L-Series components. It is important to note, however, that physical clearance for the mating plug is not sufficient in the 2103L (box) Computer to permit use of 25 kHz power from the power module front connector in that configuration.

The design of 25 kHz-driven external power supplies is essentially the same as for on-interface power supplies, as previously discussed. However, less-stringent space constraints can be expected to simplify layout and make heat dissipation easier in the external supplies, so less design effort should be required to achieve the desired result.

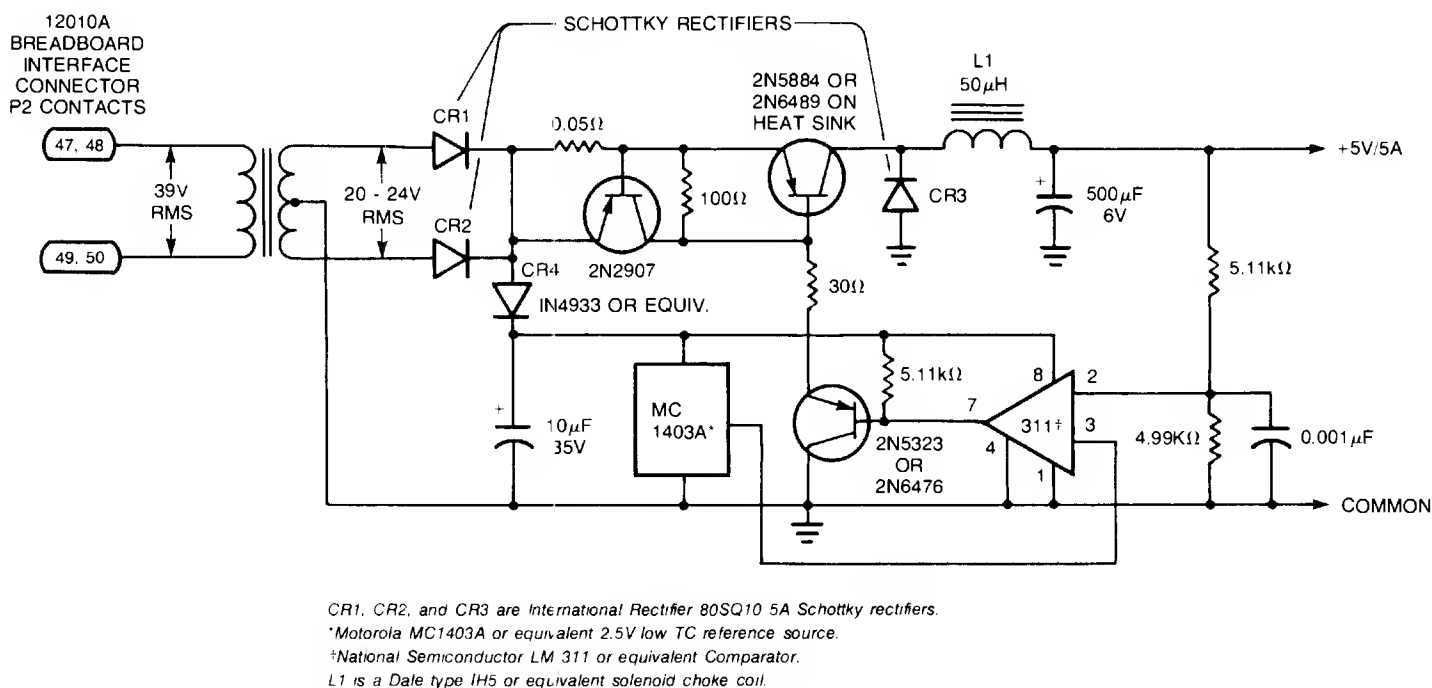


Figure 4. High efficiency on-interface, low voltage, high current 25 kHz driven switching power supply

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